

ÉCOLE DE TECHNOLOGIE SUPÉRIEURE  
UNIVERSITÉ DU QUÉBEC

THESIS PRESENTED TO  
ÉCOLE DE TECHNOLOGIE SUPÉRIEURE

IN PARTIAL FULFILLMENT OF THE REQUIREMENTS FOR  
THE DEGREE OF DOCTOR OF PHILOSOPHY  
Ph.D.

BY  
Sabeur LAFI

A NEW HARDWARE ABSTRACTION-BASED RADIOFREQUENCY DESIGN  
METHODOLOGY: FOUNDATIONS AND CASE STUDIES

MONTREAL, NOVEMBER 15, 2016

© Copyright Sabeur Lafi, 2016 All rights reserved

© Copyright

Reproduction, saving or sharing of the content of this document, in whole or in part, is prohibited. A reader who wishes to print this document or save it on any medium must first obtain the author's permission.

**BOARD OF EXAMINERS**

THIS THESIS HAS BEEN EVALUATED  
BY THE FOLLOWING BOARD OF EXAMINERS

Mr. Ammar Kouki, Thesis Supervisor  
Département de Génie Électrique at École de technologie supérieure

Mr. Jean Belzile, Thesis Co-supervisor  
Département de Génie Électrique at École de technologie supérieure

Mr. Roger Champagne, Chair, Board of Examiners  
Département de Génie Logiciel at École de technologie supérieure

Mr. Claude Thibeault, Member of the jury  
Département de Génie Électrique at École de technologie supérieure

Mr. Roni Khazaka, External Evaluator  
Electrical and Computer Engineering Department at McGill University

THIS THESIS WAS PRESENTED AND DEFENDED  
IN THE PRESENCE OF A BOARD OF EXAMINERS AND THE PUBLIC  
SEPTEMBER 16, 2016  
AT ÉCOLE DE TECHNOLOGIE SUPÉRIEURE



## ACKNOWLEDGMENTS

First and foremost, I would like to express my sincerest and deepest gratitude to my supervisor Prof. Ammar Kouki for his continuous and generous support of my PhD studies and research. I immensely appreciate his understanding, motivation and patience as well as his efforts for providing me with the required resources and an excellent atmosphere for doing my research. I also acknowledge his vast expertise, and immense knowledge, which added considerably to my graduate experience. His valuable guidance and advices helped me in all my research activities and throughout the writing process of this thesis.

Besides my advisor, I would like to thank my co-supervisor Prof. Jean Belzile for his constant encouragement, insightful guidance, and continuous support all over my graduate studies and research. I particularly appreciate his significant contribution to this research work and his focused comments that enhanced the quality of my text.

I extend my gratitude to the rest of my thesis committee: Prof. Roger Champagne, Prof. Claude Thibeault, and Prof. Roni Khazaka, for their encouragement, insightful comments, and kind acceptance to evaluate my PhD work.

My sincere thanks goes also to Mr. Frank Ditore, Mr. Rulon Vandyke, and all the Alpharetta-based team of Keysight Technologies Inc., for offering me an extended summer internship in 2012 and leading my work on diverse exciting projects.

I also acknowledge the generous financial support of LACIME (Laboratoire de Communications et d'Intégration de la Microélectronique), the BREM (Bureau du Recrutement Étudiant et de la Mobilité de l'ÉTS), and CREER (Centre de Recherche En Électronique Radiofréquence) in conjunction with FQRNT (Fonds de Recherche du Québec – Nature et Technologies).

Last but not the least, I thank all my fellow labmates at LACIME and in particular, Ahmed Elzayet, for his valuable comments and remarks. I am also grateful to LACIME staff for providing an excellent work atmosphere.

Finally, I would like to thank my parents and family for their faithful encouragement, unceasing support and best wishes and in particular, I must acknowledge the role of my wife and best friend, Fatma, without whose love, devotion and understanding, I would not have finished this thesis.

# **NOUVELLE MÉTHODOLOGIE BASÉE SUR L'ABSTRACTION MATÉRIELLE POUR LA CONCEPTION RADIOFRÉQUENCE: BASES ET ÉTUDES DE CAS**

Sabeur LAFI

## **RÉSUMÉ**

Les dispositifs de communication sans fils connaissent une croissance soutenue due au succès et à la popularité des téléphones portables auprès du grand public. De plus, l'émergence d'applications et services mobiles semble accroître les attentes du consommateur concernant les performances et les fonctionnalités des prochaines générations d'appareils sans fils. En outre, la multitude des normes de télécommunications, l'encombrement du spectre électromagnétique et les interférences complexifient la conception des systèmes radios. Pour réduire cette complexité, des avancées ont été enregistrées au niveau des technologies, des outils et des processus de conception de la partie numérique de la radio. Toutefois, bien que plusieurs technologies prometteuses soient en cours de mise au point au niveau de la partie radiofréquence, les améliorations des approches de conception et des outils qui y sont associés reçoivent beaucoup moins d'attention. Ce travail vise à pallier à ce déficit en s'attaquant particulièrement aux problématiques de productivité et de collaboration entre concepteurs des systèmes radiofréquences ainsi qu'à l'automatisation des tâches de conception.

Pour atteindre cet objectif, nous cherchons à explorer une approche de conception réduisant la dépendance aux détails physiques et élevant le niveau d'abstraction de manière à découpler la fonctionnalité à concevoir de la technologie d'implémentation. De ce fait, nous proposons dans cette thèse une nouvelle approche de conception des circuits et systèmes radiofréquences se basant sur l'abstraction matérielle. Dans un premier lieu, nous présentons une revue critique des approches actuelles. Ensuite, nous détaillons les concepts de l'approche proposée, notamment son cycle de conception, la stratégie d'abstraction matérielle qui lui est associée et la matrice Q. Puis, nous finissons ce travail par des études de cas où nous essayons de valider les concepts susmentionnés.

**Mots-clés:** méthodologie de conception radiofréquence, abstraction matérielle, matrice Q, modélisation en SysML, vérification de cohérence, transformation de modèles



# **A NEW HARDWARE ABSTRACTION-BASED RADIOFREQUENCY DESIGN METHODOLOGY: FOUNDATIONS AND CASE STUDIES**

Sabeur LAFI

## **ABSTRACT**

The need for radio systems is in growth due to the particular success of cellular and wireless devices. On the one hand, the emergence of new applications and services raises consumer expectations regarding future radio systems' performance. On the other hand, radio design is becoming more challenging due to multi-standard functionality, spectrum crowdedness and harsh operating environments. In order to keep pace with the emerging requirements, notable advances have taken place in digital design either in implementation technologies or in design approaches and tools. On the radiofrequency side, many promising technologies are being developed to enhance radio systems capability but little interest is dedicated to the improvement of design approaches and tools. To bridge this gap, several design challenges should be addressed especially in terms of productivity, design collaboration, automation and reuse as well as ensuring better technology insertion.

To tackle all these challenges, it is necessary to ameliorate the design approaches, overcome technology-dependence and raise the abstraction level in today's radiofrequency design practice in order to decouple the radio functionality from the underlying technology. In the light of this observation, we dedicate this thesis to the elaboration of a new radiofrequency design methodology based on hardware abstraction. Its first section investigates the limitations of current RF design tools and approaches. The following one presents an alternative framework that tackles the issues of automation, design collaboration and reuse. The proposed framework is based on a comprehensive abstraction strategy that combines intensive modeling activity and handful abstraction mechanisms to enable higher design automation and agility. The last section is dedicated to the validation of the proposed framework through selected case studies.

**Keywords:** RF design methodology, hardware abstraction, Q-matrix, functional description, SysML modeling, coherence verification, model-to-model transformation



## TABLE OF CONTENTS

	Page
INTRODUCTION .....	1
CHAPTER 1 BACKGROUND .....	9
1.1 Introduction.....	9
1.2 Back to the Beginnings of Wireless and Mobile Communications .....	10
1.2.1 Historical Perspective .....	10
1.2.2 Evolution of Wireless and Mobile Communications.....	11
1.3 Future Trends in Wireless and Mobile Communications and Subsequent Impact on Technology and Design Approaches and Tools .....	17
1.3.1 Trends in Wireless and Mobile Communications.....	17
1.3.2 Impact on Technology and Design Approaches and Tools .....	20
1.4 Challenges in Wireless and Mobile Radio Design .....	29
1.5 Conclusion .....	38
CHAPTER 2 COMPARATIVE STUDY OF COMMON DESIGN APPROACHES ...	43
2.1 Introduction.....	43
2.2 Common Design Approaches and Future Requirements in Design Tools .....	44
2.2.1 Common Design Approches .....	44
2.2.2 Future Requirements in Design Tools .....	47
2.3 Lessons to be learned from Current Design Practice.....	48
2.3.1 Digital Design .....	49
2.3.2 Analog and Mixed-Signal Design.....	56
2.3.3 RF and Microwave Design .....	60
2.4 Comparative Study of Design Practice through Domains .....	72
2.5 Conclusion .....	77
CHAPTER 3 THE PROPOSED FRAMEWORK FOR RF AND MICROWAVE DESIGN.....	79
3.1 Introduction.....	79
3.2 Scope and Objectives .....	80
3.3 Proposal of a New Framework to Bridge Existing Design Gaps.....	81
3.3.1 A Five-Step Design Scheme .....	82
3.3.2 Functional Description.....	82
3.3.3 Analysis.....	90
3.3.4 Synthesis .....	96
3.3.5 Q-matrix .....	104
3.3.6 Summary View of the Proposed Design Flow.....	122
3.4 Mapping Framework Provisions to Designated Design Challenges.....	124
3.5 Conclusion .....	127

CHAPTER 4	HARDWARE ABSTRACTION-BASED STRATEGY FOR RF AND MICROWAVE DESIGN .....	129
4.1	Introduction.....	129
4.2	Hardware Abstraction in Various Domains.....	130
4.2.1	Definition and Advantages .....	130
4.2.2	Hardware Abstraction in Digital and Mixed-Signal Design.....	133
4.2.3	Hardware Abstraction in Computer Engineering .....	148
4.2.4	Hardware Abstraction in Software Engineering.....	153
4.2.5	Hardware Abstraction in Other Domains .....	178
4.3	Proposed RF and Microwave Hardware Abstraction Strategy.....	180
4.3.1	Scope and Objectives.....	180
4.3.2	Basic Definitions.....	181
4.3.3	Functional Description of RF and Microwave Systems: Black-Box Model.....	182
4.3.4	Abstraction Levels, Viewpoints and Views.....	196
4.3.5	Transition between Abstraction Levels .....	210
4.4	Application to RF and Microwave Design .....	229
4.5	SysML Profile for RF Devices .....	233
4.5.1	RF Stereotypes.....	234
4.5.2	Coherence Rules and Requirements .....	240
4.5.3	Profile Extension and Usage.....	248
4.6	Integration of RF and Microwave Hardware Abstraction Strategy in the Proposed Design Framework.....	251
4.7	Provision of the RF and Microwave Hardware Abstraction Strategy within the Proposed Design Framework.....	254
4.8	Conclusion .....	258
CHAPTER 5	VALIDATION OF THE PROPOSED FRAMEWORK THROUGH SELECTED CASE STUDIES.....	261
5.1	Introduction.....	261
5.2	Practical Implementation of the Proposed Framework.....	262
5.3	Case Studies.....	267
5.3.1	Frequency Selection Device .....	267
5.3.2	Power Attenuation Device .....	361
5.3.3	Frequency Translation Device .....	392
5.4	Conclusion .....	423
CONCLUSION.....		425
APPENDIX I	HISTORY AND ADVANTAGES OF MODERN ELECTRONIC DESIGN AUTOMATION TOOLS.....	433
APPENDIX II	OVERVIEW OF SYSTEMS MODELING LANGUAGE.....	439
APPENDIX III	SUMMARY OF EQUATIONS AND FORMULAS USED IN CASE STUDIES.....	451

LIST OF REFERENCES.....461



## LIST OF TABLES

	Page
Table 1.1	Strengths and weaknesses in digital, analog/mixed-signal and RF/microwave design.....40
Table 1.2	Strengths and weaknesses in digital, analog/mixed-signal and RF/microwave design (Table 1.1 cont'd).....41
Table 2.1	Comparison between bottom-up and top-down design approaches.....47
Table 2.2	Comparison of some characteristics of digital, analog/mixed-signal and RF/microwave domains.....74
Table 2.3	Comparison of digital, analog/mixed-signal and RF/microwave design practice.....78
Table 3.1	Summary of the properties that the intended RF design framework is expected to support.....81
Table 3.2	An example of XML structure to capture the SysML model of Figure 3.4.....89
Table 3.3	Relationships between bandpass filter parameters given in Figure 3.6 .....94
Table 3.4	An example of coherence rules to validate a typical RF filter functional description.....94
Table 3.5	A selection of RF filter integrity control rules .....94
Table 3.6	Overview of the Q-matrix XML data structure.....111
Table 3.7	How the proposed framework addressed the requirements expressed in Table 3.1 .....126
Table 4.1	Views are associated to viewpoints and models .....172
Table 4.2	RF systems can be viewed as black-boxes with inputs and outputs .....185
Table 4.3	RF and microwave systems can be modeled using response functions .....188
Table 4.4	Atomic components' layer is composed of atomic components (i.e., RF indivisible devices).....201
Table 4.5	Examples of equation-based transformations for T- and $\pi$ -pad attenuators design.....215

Table 4.6	Variable weights $X_i$ are estimated based on property constraints .....	224
Table 4.7	Performance details of two candidate design solutions for the GPS bandpass filter of Figure 3.4 .....	226
Table 4.8	Calculation of the objective function for each candidate design solution.....	227
Table 4.9	Comparison between the proposed abstraction strategy for RF/microwave design and those adopted for MDE/MDA, digital, analog and mixed-signal design .....	256
Table 4.10	How the proposed hardware abstraction helps the framework in tackling the requirements given in Table 3.1 .....	257
Table 5.1	List of case studies .....	270
Table 5.2	Typical bandpass filter requirements for a 450-MHz satellite radio.....	275
Table 5.3	List of bandpass filter value properties as presented in the bdds of Figure 5.10 and 5.11 .....	282
Table 5.4	List of bandpass filter port value properties as presented in the bdd of Figure 5.10 .....	283
Table 5.5	Relationships between bandpass filter parameters given in Figure 5.24 .....	297
Table 5.6	Main filter electrical consistence rules.....	297
Table 5.7	Bandpass filter PIM-level design constraints rules .....	299
Table 5.8	Bandpass filter integrity control rules .....	299
Table 5.9	Black-box model: performance summary of the four filter prototypes .....	305
Table 5.10	Constant weights and property constraints for each decision variable .....	307
Table 5.11	Objective function calculations for each filter prototype.....	310
Table 5.12	PIM-to-PSM transformation (target platform: LC/distributed lines).....	311
Table 5.13	Overview of the intra-view transformation for granularity refinement .....	316
Table 5.14	Electrical models for non-ideal inductors and capacitors .....	319
Table 5.15	List of inductors found in the technology library during automated technology mapping .....	326

Table 5.16	List of capacitors found in the technology library during automated technology mapping .....	327
Table 5.17	Comparison of PCB areas required to hold the generated platform models.....	333
Table 5.18	Lowpass filter specifications .....	343
Table 5.19	List of lowpass filter value properties (port value properties are not considered) .....	346
Table 5.20	Relationships between lowpass filter value properties given in Figure 5.54 .....	349
Table 5.21	A PIM to PSM transformation for stepped-impedance lowpass filters .....	352
Table 5.22	A PIM-to-PSM transformation based on open-end circuit stubs .....	353
Table 5.23	Calculations resulting from the stepped-impedance-based (PIM-to-PSM) transformation.....	354
Table 5.24	Main properties of the RO3006 substrate .....	354
Table 5.25	Lowpass stepped-impedance filter PM form factor .....	355
Table 5.26	Calculations resulting from the open-end stub-based transformation.....	359
Table 5.27	Lowpass open-end stub-based filter PM form factor .....	360
Table 5.28	Typical specifications of a 3-dB RF attenuator.....	362
Table 5.29	List of values of « Attenuator » block.....	367
Table 5.30	List of values of each « Port » block.....	368
Table 5.31	Relationships between attenuator parameters given in Figure 5.71 .....	372
Table 5.32	Attenuator integrity control rules .....	372
Table 5.33	PIM-to-PSM transformation for T and $\Pi$ resistive attenuators.....	375
Table 5.34	Values of resistors for T and $\Pi$ attenuators.....	375
Table 5.35	T attenuator initial resistors.....	384
Table 5.36	$\Pi$ attenuator initial resistors .....	384
Table 5.37	T attenuator alternative resistors .....	385

Table 5.38	$\Pi$ attenuator alternative resistors.....	386
Table 5.39	Form factor of initial and refined PIMs for both T and $\Pi$ attenuators .....	387
Table 5.40	Intra-view transformation used for the attenuators' PSM granularity refinement.....	388
Table 5.41	Mixer specifications .....	392
Table 5.42	List of mixer value properties as presented in the corresponding bdds .....	396
Table 5.43	List of mixer port value properties as enumerated in the SysML models.....	397
Table 5.44	Mixer PIM-level design constraints rules .....	401
Table 5.45	Common relationships between mixer parameters given in Figure 5.87 .....	403
Table 5.46	Mixer integrity control rules .....	403
Table 5.47	Passive diode mixer PIM-to-PSM transformation .....	407
Table 5.48	Rat-race Mixer PIM to PSM transformation.....	407
Table 5.49	Generated PSMs: Summary of both mixer PSMs performance characteristics.....	413
Table 5.50	Generated PSMs: Objective function calculations for each filter prototype.....	413
Table 5.51	Properties of the synthesized rat-race microstrip sections (RO3006 substrate) .....	414
Table 5.52	List of suitable diode parts found in the technology library .....	415
Table 5.53	List of inductor parts found in the technology library during automated technology mapping .....	417
Table 5.54	List of capacitor parts found in the technology library during automated technology mapping.....	417
Table 5.55	Comparison of the performance of the three PSM prototypes.....	418
Table 5.56	Technology mapped PSM: Objective function calculations for each rat-race mixer prototype .....	419

## LIST OF FIGURES

	Page
Figure 1.1	A non-exhaustive list of milestones in telecommunications history .....12
Figure 1.2	A comparison between the first handheld mobile phone and a recent smartphone .....14
Figure 1.3	Evolution of wireless and mobile standards.....16
Figure 1.4	User expectations can be derived into technology and design requirements.....21
Figure 1.5	Radio-communication technology is evolving at a growing pace .....28
Figure 1.6	A typical multimode, multi-band handset block diagram .....29
Figure 1.7	iPhone 4 PCB Layout: (a) Front Panel: Front-End components (b) Back Panel: Baseband components .....30
Figure 1.8	A typical multi-standard multi-mode multi-band baseband chip: Qualcomm MDM9615M baseband modem used in iPhone 5 .....31
Figure 1.9	Interaction between design constraints, methodologies and abstraction levels .....31
Figure 1.10	Design domains .....32
Figure 1.11	Challenges in RF design can be fully or partially related to either the design flows or tools in use .....37
Figure 2.1	An overview of EDA history .....49
Figure 2.2	Typical design flow for digital circuits .....53
Figure 2.3	Typical analog design flow using Cadence commercial package.....57
Figure 2.4	Typical analog and mixed-signal design cycle including common EDA tools in use .....59
Figure 2.5	Main disciplines related to RF design .....61
Figure 2.6	Overview of some technologies of which typical components in a direct-conversion transceiver are made .....63

Figure 2.7	Intermodulation and nonlinearity: (a) Output power compression and intermodulation distortion in RF amplifier (b) RF mixer spurious products.....	64
Figure 2.8	Multiple antagonistic parameters are tuned in RF design.....	65
Figure 2.9	Common trade-offs encountered in RF passives design.....	66
Figure 2.10	The traditional RF design space is subdivided into two domains (i.e., electrical and physical) with two corresponding representations (i.e., system and circuit).....	67
Figure 2.11	Typical RF design scheme and some EDA tools in use for each design stage.....	68
Figure 2.12	EDA tools from Agilent Technologies.....	70
Figure 2.13	EDA tools from Applied Wave Research.....	71
Figure 3.1	The design flow consists of five distinct design stages.....	83
Figure 3.2	A filter can be modeled in a variety of ways.....	85
Figure 3.3	Typical specifications of a GPS L1 RF filter.....	87
Figure 3.4	An example of SysML model for a RF filter: (a) the package diagram (b) the value types package (c) the block definition diagram of the filter (d) the requirements diagram.....	88
Figure 3.5	Functional description is based on high-level modeling.....	90
Figure 3.6	Parameters relationships graph corresponding to the GPS bandpass filter of Figure 3.4.....	93
Figure 3.7	Example of coherence rules to validate a RF filter functional description: (a) A warning results from a rule that detects a minor consistency issue, while (b) an error indicates a major incoherence that makes the design not feasible.....	95
Figure 3.8	Example of system-level analyses related to the GPS L1 bandpass filter (considering a 3-dB ripple): (a) ideal filter network (b) transmission and reflection magnitude, (c) phase and (d) group delay.....	97
Figure 3.9	“Analysis” step includes “Coherence Verification” and system-level “Performance Simulation”.....	98

Figure 3.10	Illustration of the granularity refinement concept: (a) and (b) RF amplifier structures, (c) and (d) RF duplexer structures .....	99
Figure 3.11	Granularity concept applied to the GPS L1 bandpass filter: (a) four lumped-component elements or (b) two resonators .....	100
Figure 3.12	Some technology parameters required for (a) lumped-component (b) microstrip and (c) coaxial-cable circuits' implementation .....	102
Figure 3.13	The layout corresponding to microstrip coupled-line realization of the GPS L1 bandpass filter: (a) microstrip physical dimensions (considering a FR-4 substrate), (b) the layout produced using Agilent ADS and (c) its performance simulation using Momentum .....	103
Figure 3.14	Synthesis allows nested granularity refinement and technology mapping in order to build ready-for-manufacturing implementations from an elaborated functional description .....	104
Figure 3.15	Linking the different design stages with the Q-matrix to handle data exchange .....	107
Figure 3.16	Conventions used in a typical two-port RF network where $F1 \neq F2$ .....	108
Figure 3.17	Generalized Q-matrix is a function of frequency, power, temperature and time .....	110
Figure 3.18	The file consists of various data blocks composing data of different sources .....	112
Figure 3.19	Q-matrix data blocks from different data sources .....	112
Figure 3.20	Hierarchical structure of a data block .....	113
Figure 3.21	Examples of data blocks usage and possibilities of metadata extensibility ...	114
Figure 3.22	A usage example showing how the Q-matrix XML structure captures passive device's linear response: (a) RF filter model, (b) its corresponding Q-matrix and (c) data representation .....	116
Figure 3.23	VCO's Q-matrix XML structure: (a) A voltage-controlled oscillator model, (b) its formal Q-matrix, (c) an example of a VCO circuit.....	117
Figure 3.24	VCO's Q-matrix XML structure (cont'd): (a) the configuration section and (b) the data section (limited to only two points of control and output voltages) .....	118

Figure 3.25	Q-matrix XML structure is also able to capture amplifier I-V data: (a) Amplifier model, (b) its corresponding Q-matrix and (c) an example of an amplifier circuit .....	120
Figure 3.26	Q-matrix XML structure is also able to capture amplifier I-V data: The data file corresponding to the amplifier model of Figure 3.25 .....	121
Figure 3.27	The proposed framework for RF and microwave design .....	123
Figure 4.1	Every abstraction level corresponds to a new representation (i.e., model)....	134
Figure 4.2	The five abstraction levels in digital circuit design correspond to five abstraction views subdivided into three distinct design domains .....	137
Figure 4.3	The three-domain five-abstraction-level Gajski-Kuhn's Y-chart .....	138
Figure 4.4	A digital functionality design changes its representation when it gradually goes through the behavioral, structural and physical domains .....	141
Figure 4.5	A top-down design flow mapped to the abstraction levels and design domains of Gajski-Kuhn's Y-chart results in a back and forth top-down process.....	142
Figure 4.6	Raising the abstraction levels allowed more complex device models .....	142
Figure 4.7	Design automation tools, IC technologies and design methodologies in microelectronics have evolved jointly with abstraction levels.....	143
Figure 4.8	Higher abstraction levels enable the design of more complex chips .....	143
Figure 4.9	Notable differences between abstraction levels in digital and analog/mixed-signal design.....	145
Figure 4.10	A specific simulation type corresponds to each abstraction levels in analog/mixed-signal design.....	146
Figure 4.11	An example of how abstraction levels are applied to analog/mixed-signal design: A differential operational amplifier design starts as HDL description at functional level and ends with a useful layout at circuit level .....	147
Figure 4.12	Each abstraction level corresponds to simulation type that is more time- consuming but accurate from higher to lower levels .....	148
Figure 4.13	The hardware abstraction layer plays a mediation role between the operating system (and user applications) and the physical hardware .....	150

Figure 4.14	Modern networks were built upon a layered architecture based on OSI and TCP/IP networking models .....	151
Figure 4.15	Modern databases use at least three abstraction levels to manage the stored data and control the interaction of users with them.....	152
Figure 4.16	Evolution of abstraction levels in programming languages .....	156
Figure 4.17	Impact of abstraction level rise on productivity and code reuse: (a) from one source for one system architecture to one model to multiple hardware/software platforms (b) Source code reuse started with functions and evolved towards domain models .....	158
Figure 4.18	The modular programming paradigm subdivides a software system into independent, shared and reusable components .....	159
Figure 4.19	Abstraction through objects and classes: (a) real-world objects and (b) how they are modeled using a UML class diagram.....	162
Figure 4.20	MDE enables the use of automated model-to-model transformation tools to enhance the automation of design steps .....	167
Figure 4.21	The model-driven architecture defines two types of models at different abstraction levels.....	169
Figure 4.22	In MDE/MDA, a meta-model abstracts a model which itself abstracts a real-world reality .....	171
Figure 4.23	Automation process in MDE/MDA framework encompasses four abstraction levels and three model-to-model transformations.....	175
Figure 4.24	Model-to-Model transformation in MDE/MDA .....	175
Figure 4.25	Model-to-Model transformation: (a) PIM to PSM transformation and (b) transformation bridges.....	176
Figure 4.26	An example of PIM to PSM mapping: (a) UML to C# Transformation (b) The same PIM (i.e., UML models) is transformed into three PSMs (corresponding to three different source code representations) given the relevant platform specifications .....	177
Figure 4.27	An excerpt of the UML profile for software radios: a logical-physical channel stereotype abstracts devices that provide analog communications (e.g., RF) .....	179
Figure 4.28	A black-box view considers a RF system as an entity which is defined by its inputs/outputs and its response function.....	183

Figure 4.29	SysML black-box model of a RF system .....	192
Figure 4.30	The block diagram of a UMTS FDD transceiver .....	193
Figure 4.31	SysML allows the expression of different aspects in RF systems: (a) package diagram (b) the transceiver's associated block definition diagram .....	194
Figure 4.32	SysML allows the expression of different aspects in RF systems (cont'd): (a) the receiver's internal block diagram (b) the duplex filter specifications (c) the duplex filter requirements diagram .....	195
Figure 4.33	Four abstraction levels are considered in the proposed RF hardware abstraction strategy: System, module, circuit and atomic components.....	200
Figure 4.34	The atomic layer is composed of "leaf" electrical devices whose functions are not indivisible .....	201
Figure 4.35	An example of how the different abstraction levels are considered in a typical RF system .....	205
Figure 4.36	A viewpoint corresponds to an abstract design perspective while a view specifies a representation (i.e., model) which complies with that design perspective .....	207
Figure 4.37	Four abstraction views are associated to four abstraction viewpoints and four abstraction levels.....	209
Figure 4.38	Two transformations are defined to move from system requirements throughout implementation .....	210
Figure 4.39	Cross- and intra-view transformations .....	214
Figure 4.40	Granularity is all about the level of detail within an abstraction view: (a) the system is composed of seven blocks (b) one of these seven blocks can be broken up into eight other parts.....	216
Figure 4.41	A system-level model of a direct-conversion receiver can be partitioned in modules in different ways of different granularity levels .....	217
Figure 4.42	Two examples of granularity level expressed using SysML block definition diagram: (a) An amplifier is considered as whole [Granularity level = 1] (b) An amplifier is considered as an assembly of amplification, matching, and biasing networks [Granularity level = 4].....	219
Figure 4.43	Reversible platform-specific model for resistive attenuators.....	220

Figure 4.44	Granularity refinement: (a) Unbalanced to balanced T and (b) $\pi$ attenuator transformations .....	222
Figure 4.45	An example of overriding a default constraint property using a new equation for the calculation of variable weights.....	225
Figure 4.46	The four abstraction views can be mapped to traditional passive RF filters design steps .....	229
Figure 4.47	An example of transformation scheme for operational amplifier design.....	232
Figure 4.48	The proposed profile extends SysML standard (version 1.4) with specific constructs that are intended for RF domain .....	234
Figure 4.49	The package diagram describing the structure of and the relationships within the proposed SysML profile.....	236
Figure 4.50	The stereotype of a RF device is a basic SysML block having specific compartments for RF modeling.....	237
Figure 4.51	At the functional level, RF stereotypes are hierarchically structured .....	241
Figure 4.52	A SysML bdd depicting a generic view of RF stereotypes.....	242
Figure 4.53	N-port network stereotype.....	243
Figure 4.54	Value properties of linear devices.....	244
Figure 4.55	Value properties of nonlinear devices.....	245
Figure 4.56	Common units and dimensions used in RF design are part of the Value Types package to avoid ambiguity .....	246
Figure 4.57	Common requirements and testcases required for RF devices design .....	247
Figure 4.58	The constructs of the proposed SysML profile are subject to extension and modification .....	249
Figure 4.59	An active bandpass filter block extends and reuses “Low-noise Amplifier” and “BandpassBandstop” stereotypes.....	250
Figure 4.60	A tunable bandpass filter extends and reuses the block “BandpassBandstop” .....	251
Figure 4.61	Streamlining the proposed design framework with the RF/microwave abstraction strategy.....	254

Figure 4.62	Introducing granularity refinement at PIM-level to enhance design space exploration and at PSM-level to improve physical implementation .....	254
Figure 4.63	Streamlining the proposed design framework with the RF/microwave abstraction strategy .....	255
Figure 5.1	Detailed flowchart of the proposed design framework .....	268
Figure 5.2	A detailed filter design flowchart extracted from the design framework .....	269
Figure 5.3	This package diagram gives an overview of the filter's SysML RM/PIM models .....	272
Figure 5.4	The filter's PSM consists of an ideal resonators' network.....	272
Figure 5.5	A distributed-line layout artwork is a potential filter PM model .....	272
Figure 5.6	Model-to-model transformations convert RM/PIM to PSMs and PSMs into PMs.....	273
Figure 5.7	The main parameters of a RF bandpass filter.....	274
Figure 5.8	An overview of filter RM/PIM models developed in SysML.....	277
Figure 5.9	A filter is a two-port linear device .....	278
Figure 5.10	Linear device detailed block definition diagram.....	279
Figure 5.11	Generic filter detailed block definition diagram .....	280
Figure 5.12	Value types captured in a bdd for the filter's RM/PIM models.....	281
Figure 5.13	Detailed filter requirements diagram.....	281
Figure 5.14	The bandpass filter might be explicitly associated to its requirements and testcases .....	282
Figure 5.15	The bandpass filter coherence rules package consists of four interrelated sub-packages .....	285
Figure 5.16	Electrical consistence rules illustrated in a parametric diagram .....	286
Figure 5.17	Integrity control rules captured using in a parametric diagram .....	287
Figure 5.18	Parametric diagram has multiple uses (a) PIM-level design constraints, (b) Mapping of equations' parameters .....	288
Figure 5.19	Overview of the RM/PIM's XML description file.....	289

Figure 5.20	The XML description corresponding to the “Filter Definition” package .....	290
Figure 5.21	The XML description corresponding to the “Filter Requirements” package .....	291
Figure 5.22	The XML description corresponding to the “Value Types” package .....	292
Figure 5.23	The XML description corresponding to the “Coherence Rules” package .....	293
Figure 5.24	A snippet from the created Q-matrix showing initial electrical data item at 420 MHz.....	294
Figure 5.25	Bandpass filter parameters relationships graph.....	298
Figure 5.26	Bandpass filter coherence verification report.....	300
Figure 5.27	PIM analysis: Attenuation and group delay for Butterworth prototype.....	302
Figure 5.28	PIM analysis: Attenuation and group delay for Chebyshev type I prototype .....	303
Figure 5.29	PIM analysis: Attenuation and group delay for Bessel prototype.....	304
Figure 5.30	PIM analysis: Attenuation and group delay for Elliptic prototype .....	305
Figure 5.31	Transformation (step 2): (a) the LC model and its (b) frequency response ...	312
Figure 5.32	Generation of lumped-component filter circuit topology: (a) series and (b) parallel resonators .....	313
Figure 5.33	PSM evolution: (a) transformation output ( $N = 5$ ) (b) refined ( $N = 6$ ) and (c) technology-mapped ( $N = 6$ ).....	314
Figure 5.34	The frequency response of the PSM resulting from step 3 of the PIM-to-PSM transformation ( $N = 5$ ) .....	315
Figure 5.35	Granularity refinement: transformation of (a) series and (b) parallel resonators.....	317
Figure 5.36	The frequency response of the optimized design solution after PSM granularity refinement .....	318
Figure 5.37	Technology files: (a) Lumped components (b) Microstrip substrate .....	320
Figure 5.38	Technology mapping report: (a) Inductors (b) Capacitors.....	322
Figure 5.39	Technology mapping report: Transmission lines synthesis .....	323

Figure 5.40	The PSM's frequency response after technology mapping.....	328
Figure 5.41	First candidate solution (optimization round 1) .....	329
Figure 5.42	First candidate solution (optimization round 2) .....	330
Figure 5.43	Platform model (first optimized PSM): (a) 2D layout (b) 3D layout top and (c) bottom views.....	331
Figure 5.44	Platform model (second optimized PSM): (a) 2D layout (b) 3D layout top and (c) bottom views.....	332
Figure 5.45	Frequency response of the PM model (PSM-to-PM transformation output).....	334
Figure 5.46	Overview of the QBlocks added to the Q-matrix throughout the filter's design process .....	335
Figure 5.47	The Q-matrix centralizes design data, which allows for example to make performance comparisons throughout the design process.....	336
Figure 5.48	An overview of Q-matrix QBlocks evolution throughout the design cycle .....	339
Figure 5.49	The evolution of the filter models throughout the design cycle.....	340
Figure 5.50	Simulation techniques versus filter models and design viewpoints.....	341
Figure 5.51	Using two cross-view transformations, the same lowpass filter PSM is derived into two separate platform models .....	342
Figure 5.52	Typical parameters of a lowpass filter .....	345
Figure 5.53	The requirements diagram of the lowpass filter.....	346
Figure 5.54	Lowpass filter parameters relationships graph.....	348
Figure 5.55	Lowpass filter coherence verification report.....	350
Figure 5.56	Black-box model frequency response: Chebyshev Type I approximation ....	351
Figure 5.57	First PSM: The stepped-impedance lowpass filter.....	354
Figure 5.58	First PSM after technology mapping .....	355
Figure 5.59	Lowpass filter stepped-impedance platform model: (a) transformed, (b) first- and (c) second-round optimizations.....	356

Figure 5.60	Frequency response of the stepped-impedance lowpass prototype in key design steps.....	357
Figure 5.61	Second PSM: The open-end stub lowpass filter.....	358
Figure 5.62	Second PSM after technology mapping.....	358
Figure 5.63	Lowpass filter open-end stub-based platform model: (a) transformed, (b) best optimization round.....	360
Figure 5.64	Frequency response of the open-end stubs lowpass prototype in key design steps.....	361
Figure 5.65	Overview of the Qblocks added to the filter's Q-matrix through the design cycle.....	362
Figure 5.66	Comparison between the performance of the stepped-impedance and open-end stub-based filter prototypes in different design stages.....	363
Figure 5.67	Attenuator functional description overview: RM/PIM packages.....	365
Figure 5.68	The detailed attenuator's block definition diagram.....	366
Figure 5.69	The main attenuator requirements depicted in the associated SysML diagram.....	369
Figure 5.70	Value Types package.....	370
Figure 5.71	Attenuator's parameters relationships graph.....	371
Figure 5.72	Attenuator coherence verification report.....	374
Figure 5.73	Attenuator black-box model frequency response.....	374
Figure 5.74	A comparison between the T and $\Pi$ attenuators in terms of frequency response and noise levels (at the end of step 1 of the PIM-to-PSM transformation).....	377
Figure 5.75	PIM-to-PSM transformation: (a) T and (b) $\Pi$ attenuators.....	378
Figure 5.76	Technology mapping: (a) T and (b) $\Pi$ attenuators.....	379
Figure 5.77	A comparison between the T and $\Pi$ attenuators in terms of frequency response and noise levels (at the end of step 2 of the PIM-to-PSM transformation).....	380
Figure 5.78	A comparison between the T and $\Pi$ attenuators in terms of frequency response and noise levels (initial technology mapping).....	381

Figure 5.79	Intra-view transformation: (a) series (b) shunt.....	382
Figure 5.80	A comparison between the T and $\Pi$ attenuators in terms of frequency response and noise levels (after granularity refinement) .....	383
Figure 5.81	Resulting PM: (a) T and (b) $\Pi$ attenuator layouts.....	385
Figure 5.82	Resulting PM after granularity refinement: (a) T and (b) $\Pi$ attenuator layouts.....	386
Figure 5.83	A comparison between the T and $\Pi$ attenuators in terms of frequency response and noise levels (Final PM 1).....	389
Figure 5.84	A comparison between the T and $\Pi$ attenuators in terms of frequency response and noise levels (final PM after granularity refinement) .....	390
Figure 5.85	Noise data is supported in the Qmatrix through metadata .....	391
Figure 5.86	A mixer makes a frequency translation.....	392
Figure 5.87	Mixer package diagram.....	393
Figure 5.88	Three-port network detailed block definition diagram .....	394
Figure 5.89	Mixer is a nonlinear frequency conversion device (Figure 5.88 cont'd) .....	395
Figure 5.90	Summary of mixer requirements.....	398
Figure 5.91	Coherence rules: PIM-level design rules .....	399
Figure 5.92	Mixer value types package.....	401
Figure 5.93	Mixer parameters relationships graph.....	402
Figure 5.94	Mixer coherence verification report.....	405
Figure 5.95	Black-box model frequency response .....	406
Figure 5.96	PSM topology: passive (a) single-ended diode and (b) rat-race mixer .....	408
Figure 5.97	Voltage waves: (a) Single-ended and (b) rat-race diode mixer.....	409
Figure 5.98	(a) Output versus input power and (b) conversion gain of both mixers.....	410
Figure 5.99	Output Spectrum: (a) Single-ended and (b) rat-race diode mixer .....	411
Figure 5.100	Output Third-Intercept Point: (a) Single-ended and (b) rat-race diode mixer.....	412

Figure 5.101	Technology mapping results for (a) capacitor and (b) inductor elements.....	416
Figure 5.102	Conversion gain of the generated PSMs after technology mapping .....	419
Figure 5.103	Platform Model: Layout of the final rat-race mixer .....	420
Figure 5.104	The Q-matrix stores both linear and nonlinear data.....	421
Figure 5.105	The Q-matrix stores data that can be interpreted in different ways .....	422



## LIST OF ABBREVIATIONS

3D	Three-Dimensional
3GPP	Third-Generation Partnership Project
AC	Alternate Current
ADC	Analog-to-Digital Converter
ADS	Advanced Design System
AMS	Analog-Mixed Signal
API	Application Programming Interface
ASIC	Application-Specific Integrated Circuit
AWR	Applied Wave Research
BAW	Bulk Acoustic Wave
BGA	Ball Grid Array
CAGR	Compound Annual Growth Rate
CANCER	Computer Analysis of Nonlinear Circuits, Excluding Radiation
CMOS	Complementary Metal-Oxide Semiconductor
CR	Cognitive Radio
DAC	Digital-to-Analog Converter
DC	Direct Current
EDA	Electronic Design Automation
EDGE	Enhanced Data Rates for GSM Evolution
ESL	Electronic System-Level
FSM	Finite-State Machine
GDSII	Graphic Database System II
GPP	General-Purpose Processor
GPRS	General Packet Radio Service
GPS	Global Positioning System
GSM	Global System for Mobile Communications
HDL	Hardware Description Language
HSPA	High-Speed Packet Access
HTCC	High-Temperature Co-fired Ceramic

IC	Integrated Circuit
ICT	Information and Communication Technology
IEEE	Institute of Electrical and Electronics Engineers
IF	Intermediate Frequency
IP	Internet Protocol
IPs	Intellectual Properties
ITU	International Telecommunication Union
LAN	Local Area Network
LEF	Library Exchange Format
LNA	Low-Noise Amplifier
LTCC	Low-Temperature Co-fired Ceramic
LTE	Long-Term Evolution
LVS	Layout versus Schematic
M2M	Machine-to-Machine
MCM	Multi-chip Module
MIMO	Multiple-Input Multiple Output
MMIC	Monolithic Microwave Integrated Circuits
MOSIS	Metal-Oxide Semiconductor Implementation Service
MTTF	Mean Time To Failure
NGN	Next-Generation Network
NI	National Instruments
OASIS	Open Artwork System Interchange Standard
OEM	Original Equipment Manufacturer
OFDM	Orthogonal Frequency Division Multiplexing
OMG	Object Management Group
PA	Power Amplifier
PAN	Personal-Area Network
PCB	Printed-Circuit Board
PGA	Pin Grid Array
PIM	Platform-Independent Model

PM	Platform Model
PSM	Platform-Specific Model
QoS	Quality of Service
RAM	Random Access Memory
RAN	Radio Access Network
RF	Radiofrequency
RFFE	RF Front-End
RFIC	RF Integrated Circuit
SAW	Surface Acoustic Wave
SDR	Software-Defined Radio
SiP	System in Package
SOI	Silicon-On-Insulator
SPICE	Simulation Program with Integrated Circuit Emphasis
SPP	Single-Purpose Processor
SWaP	Size, Weight and Power
SysML	Systems Modeling Language
TCAD	Technology Computer-Aided Design
TTM	Time-to-Market
UMA	Unlicensed Mobile Access
UMB	Ultra-Mobile Broadband
VHDL	Very High-Speed Integrated Circuits Hardware-Description Language
VNA	Vector Network Analyzer
VNI	Visual Networking Index
VoIP	Voice-over-IP
WIF	Wireless Innovation Forum
WiMAX	Worldwide Interoperability for Microwave Access
WLAN	Wireless Local Area Network
XML	Extensible Markup Language



## INTRODUCTION

The need for radio systems is growing due to the particular success of consumer communication services. The wide adoption of cellular and wireless systems in the last decades is particularly driving the Information and Communication Technology (ICT) market, giving birth to new applications and services (e.g., machine-to-machine, over-the-top services, etc.) and fueling the increasing convergence between fixed- and mobile-broadband communications (ITU, 2013). Naturally, end-user expectations in terms of quality of service are evolving. At affordable costs, it is expected that future radio systems provide higher data rates and lower power consumption in increasingly harsher radio environments where spectrum is getting more crowded and regulations are becoming tougher (Costa-Perez et al., 2013; Nortel, 2008).

In order to keep pace with the emerging requirements, the challenges that should be addressed are related to implementation technology and radio design flows. On technology level, most future radios will be built with multi-standard, multi-band and multimode transceivers to provide a seamless connectivity to various mobile and wireless networks (Chia et al., 2008). This requires higher processing capability for baseband stages and more robust radiofrequency (RF) front-ends in order to support multiple communication standards and accommodate various radio transmission scenarios. Higher levels of miniaturization and integration are also needed to keep the form factor within an acceptable range for consumers. In addition, all this should have a very low-energy-consumption profile. Remarkable efforts are being deployed in both industry and academia in order to come up with relevant solutions that effectively address these issues. However, is this enough to leverage the encountered challenges? While several new technologies are being developed to enhance radio systems capability (i.e., the “what-to-do”), less interest is dedicated to design approaches and tools (i.e., the “how-to-do”) improvement.

On radio design level, there are particularly tangible disparities between digital baseband and RF front-end design cycles. In digital design, it is possible to integrate very complex circuits during a reasonable timeframe. Digital designers have adopted a structured design approach that is backed by a set of tools allowing the automation of most design steps from concept to

prototype (Rabaey, Chandrakasan et Nikolic, 2002). This approach builds up the circuit hierarchically: it is considered as a collection of modules. Each module is a collection of cells and each cell is composed of some transistors and lumped components. Each module or cell implements a logical functionality and can be reused as much as required. Thus, the design effort is reduced. The main concept behind this useful representation is hardware abstraction. Every component is used as black-box model. At each abstraction level, the designer deals only with the models available at that level. Given enough data about their functionality, the designer can use these models without knowing their internal structure. The characteristics of their underlying components are virtually masked. Complexity is thus reduced and mastered. These paradigms led to the implementation of mature digital design tools, which played a key role in rising design productivity via modeling and automation (Rabaey, Chandrakasan et Nikolic, 2002).

On the contrary, the classic RF design scheme still starts at circuit level, and is mostly manual and very technology-dependent (Warwick et Mulligan, 2005). It presents various discontinuities between design stages and lacks formal communication rules between the different developers involved in the same RF design project. Consequently, the exchange of data and collaboration abilities are still limited (Viklund, 2005). Actually, the conventional design flow is too costly, long and not amenable for easy technology insertion. Design reuse is also limited. The changes and corrections of the design according to new specifications are often expensive and time-consuming. Final system integration is tedious, risky and slow particularly when different technologies are involved in the system architecture. Despite recent notable advances, most RF tools are not specialized enough to handle multi-technology and multi-domain issues. There is a lack of tools able to carry out system-level analyses, tackle growing design complexity, support multiple technologies, allow cost-effective co-design especially in mixed-signal context, and ensure reliable formal verification at the different design stages (Dunham et al., 2003; Gielen, 2007). This said, the absence of clear abstraction levels and coherent functional modeling leveraging technology-dependence and enabling automation, is a major hindrance to current RF design practice.

## Research Positioning

To sum up, a major problem is that modern RF design practice does not keep pace with the rising functional, economic and technological demands in wireless communications due to:

- **The lack of a clear and efficient abstraction strategy**

Despite the fact that the major Electronic Design Automation (EDA) players continue to upgrade their toolchains for RF and microwave design, the abstraction effort remains modest compared to what was achieved in both digital and mixed-signal/analog domains. The dependence from technology is still very prevalent. In addition to the issue of design reuse, the impact of the tools on automation and productivity is concrete. Very little automation is available for designers except for few traditional devices (e.g., filters synthesis). Furthermore, it becomes harder to integrate the RF and microwave design into a bigger multi-disciplinary system design.

- **The lack of modern end-to-end design flows**

Nowadays, the design of a complete RF/microwave front-end requires often more than one tool. The design is generally fragmented throughout the different system-, circuit- and physical-level tools. The transition between these tools is frequently carried out using industry de facto and proprietary data file formats. There is regularly loss of accuracy and design details due to the incompatibilities between and the lacks of these tools. Moreover, the project management is difficult since there is little coherent ways to communicate between the various involved designers and teams. Specifications changes and design corrections are not reflected immediately, which often causes inconsistencies. Additionally, significant portions of design are handcrafted. Technology insertion is difficult. The creation of custom models (either high- or low-level) is very limited. The interaction with simulation tools, mostly proprietary, is often inadequate. APIs enabling co-simulation and multi-domain simulations are often limited. Accordingly, the design and simulation of an entire communication system (including baseband parts) is difficult due to the absence of necessary mappings between both domains (e.g., frequency vs. time, DC/AC vs. wave, discrete vs. continuous, etc.).

In addition to RF design issues, there are growing claims particularly from huge system integrators (e.g., aeronautical industry) about RF and microwave system modeling. For instance, aeronautical companies would prefer to be able to trace back all the components of communication systems used onboard of the aircrafts they deliver (not only for safety nor maintainability reasons but also for better design management). In fact, these constructors use modern modeling languages to store all the data about various aircraft systems (e.g., mechanical, hydraulic, etc.). Adding communication systems parts to their database would enable them to enhance their system design and integration practices. For RF and microwave businesses, altering the currently predominant design thinking towards more flexibility, adaptability, reusability and automation will help them to reduce design costs and come up with adequate and rapid solutions for the next-generation communication systems. With a unified design cycle providing higher abstraction levels, EDA vendors would be able to propose integrated design environments enabling multi-domain and multi-disciplinary design.

In the light of these observations, the research dilemma covered in our research work tackles the weaknesses and challenges of today's design practice in RF and microwave domains. The question to which we attempt to answer is: how to establish a flexible design approach that improves productivity, better collaboration and design reuse, and rises the abstraction level to reduce technology dependence and master design complexity?

Getting inspired by the positive impact of hardware abstraction in various engineering domains, we propose in this thesis a new design methodology for RF design that is based on hardware abstraction. The proposed framework tackles primarily the issues of automation, design collaboration and reuse. It consists mainly of a design cycle along with a comprehensive RF hardware abstraction strategy. Being a model-centric framework, it captures every RF system using an appropriate model that corresponds to a given abstraction level and expresses a certain design perspective. It also defines a set of mechanisms for the transition between the models defined at different abstraction levels, which contributes to higher automation throughout the design process.

Nevertheless, this thesis does not aim to provide a complete set of tools or an integrated design environment neither to immediately resolve all the lacks and drawbacks of the existent design approaches and tools. Our primary goal is to propose the foundations of a new framework that serves as a preliminary basis for future developments. For this reason, the main steps of our research methodology are limited to the following:

- Investigate the existent design approaches and techniques used in design domains related to modern radio design (including digital, analog/mixed-signal and RF/microwave);
- Outline the major weaknesses and shortcomings in modern RF design practice;
- Propose a new design methodology for RF/microwave devices that addresses primarily the issues of automation, design collaboration and reuse;
- Propose concepts and mechanisms to raise the abstraction level in RF design;
- Integrate the proposed concepts in a coherent framework; and
- Validate the proposed framework using selected design case studies from real applications.

### **Thesis Layout**

This thesis counts five chapters that can be subdivided into three main sections. The first one investigates the general context to which the current RF design practice belongs. It covers two chapters. The first chapter entitled “*Background*”, presents a historical overview of wireless and cellular mobile communications. Then, it outlines the key trends driving the wireless market as well as the major environmental and technological challenges facing modern radio design. The second, namely “*Comparative Study of Common Design Approaches*”, presents a comprehensive review of today’s design practice. Then, it summarizes the common design approaches in use in RF domain. It also highlights the disparities between the domains related to radio design (i.e., digital, analog/mixed-signal and RF/microwave). Finally, it presents a comparative study of the design practice in these domains.

Composed of two chapters, the second section attempts to tackle the design challenges discussed previously through the detailed presentation of the proposed design framework. Accordingly, the thesis third chapter entitled “*The Proposed Framework for RF/Microwave Design*”, introduces the foundations of a new design cycle for RF devices and systems that is

built around a new data structure (called Q-matrix). New concepts such as functional description, granularity refinement and technology mapping are thoroughly detailed and discussed. In the fourth chapter “*Hardware Abstraction-based Strategy for RF/Microwave Design*”, we elaborate a hardware abstraction strategy for RF and microwave domains in order to define effective and practical ways for raising the abstraction level in RF design practice. We begin this chapter by reviewing the contributions of hardware abstraction in various engineering areas (including digital and mixed-signal design). At this regard, we particularly focus on the abstraction mechanisms used to enhance automation and productivity. Then, we propose the basics of our hardware abstraction strategy. This includes the abstraction levels considered for RF domain, the transition mechanisms between these abstraction levels and high-level modeling artefacts. This chapter ends with the streamlining of the proposed abstraction strategy and the design cycle of the previous chapter in a complete design framework.

The third section is dedicated to case studies which aim to validate the proposed framework. It covers the fifth chapter entitled “*Validation of the Proposed Framework through Selected Case Studies*”. In this regard, the first case study details the design of a bandpass filter. Other radiofrequency functionalities are also presented.

In addition, three appendices complete the five chapters with additional information about specific aspects related to key concepts and notions outlined in this thesis.

## **Papers and Communications**

Lafi, Sabeur, Kouki, Ammar, et Belzile, Jean. 2016a. « A SysML Profile for RF Devices ». *IEEE Systems Journal*.

Lafi, Sabeur, Kouki, Ammar, et Belzile, Jean. 2016b. « On the Role of Hardware Abstraction in Modern Radio Design ». *Circuits and Systems Magazine*.

Lafi, Sabeur, Kouki, Ammar, et Belzile, Jean. 2016c. *Implementation Details of a Hardware Abstraction-Based Design Methodology for Radiofrequency Circuits – Examples of Linear Devices*.

Lafi, Sabeur, Kouki, Ammar, et Belzile, Jean. 2016d. *Implementation Details of a Hardware Abstraction-Based Design Methodology for Radiofrequency Circuits – Examples of Nonlinear Devices*.

Lafi, Sabeur, Kouki, Ammar, et Belzile, Jean. 2014. « Enhancing Automation in RF Design Using Hardware Abstraction ». In *Computational Intelligence in Analog and Mixed-Signal (AMS) and Radio-Frequency (RF) Circuit Design*, sous la dir. de Springer. Vol. II, pp. 439-469. Germany: Springer.

Lafi, Sabeur, Ammar, Kouki et Jean Belzile. 2011. « A New Hardware Abstraction-Based Framework to Cope with Analog Design Challenges ». In *IEEE 23rd International Conference on Microelectronics*. (Tunisia, December 2011).

Lafi, Sabeur, Elzayat, Ahmed, Kouki, Ammar, et Belzile, Jean. 2011. « A RF Hardware Abstraction-Based Methodology for Front-End Design in Software-Defined Radios ». In *European Conference on Communications Technologies and Software-Defined Radios*. (Brussels, June 2011).

Lafi, Sabeur, Champagne, Roger, Kouki, Ammar, et Belzile, Jean. 2008b. « Modeling Radiofrequency Front-End Using SysML: a Case Study of a UMTS Transceiver ». In *First International Workshop on Model-Based Architecting and Construction of Embedded Systems*. (Toulouse, September 2008).

Lafi, Sabeur, Kouki, Ammar, et Belzile, Jean. 2008a. « A Hardware Abstraction Framework for Bridging RF Front-Ends Design Issues in Open Wireless Architectures ». In *World Wireless Congress*. (California, May 2008).

### **Other Papers and Contributions**

Lafi, Sabeur, Ditore, Frank, et Vandyke, Rulon. 2013. « System-Level Design of an LTE TDD Tri-band Receiver ». In *Electronic Design Innovation Conference*. (China, March 2013).

Lafi, Sabeur, Kouki, Ammar, Belzile, Jean, et Ghazel, Adel 2007b. « Towards a Coherent Framework for Automated RF Front-Ends Design Using Hardware Abstraction ». In *IEEE IST Mobile and Wireless Communications Summit*. (Budapest, July 2007).

Lafi, Sabeur, Kouki, Ammar, Belzile, Jean, et Ghazel, Adel 2007a. « A Framework for Coherent Functional Description and Hardware Abstraction in RF Front-Ends ». In *Software-Based Components Workshop*. (Washington DC, March 2007).



## **CHAPTER 1**

### **BACKGROUND**

#### **1.1 Introduction**

Telecommunication systems have seen a tremendous evolution during the last two centuries. This is particularly true for radio-based technologies such as wireless and mobile communications. In addition to architectures and fabrication technologies, the way wireless and mobile radios are designed has also evolved. Furthermore, the advent of digital signal processing had significantly improved radio technologies. It opened the door for many new applications. However, it did not really mark the end of the analog era since wireless and mobile devices still need to use radio waves. On the contrary, signal processing has contributed to the mitigation of some radiofrequency impairments.

Compared to the other parts of the radio (such as baseband), the RF front-end represents a relatively small part in a modern radio. Paradoxically, its design process is often longer and tougher. This is mainly due to the slow evolution of the way its components are designed which does not allow designing them at the same pace as their digital counterparts. This double-paced reality exhibits itself on different levels such as tools, design yield and time. Given these observations and the focus of this thesis on RF and microwave radio design approaches, this first chapter reviews the general background of radio communications, investigates the current trends in wireless and mobile market and discusses the resulting challenges in radio design with a specific focus on RF front-ends. Thus, this study aims at showing how radio design has evolved and what factors have affected both technologies and design tools during the last decades. Therefore, we start by presenting a historical perspective of radio design. Then, we give an overview of the current and future trends in wireless and mobile communications. Next, we outline the some outstanding challenges facing radio design with an emphasis on RF front-ends. Finally, we attempt to put the spotlight on the shortcomings of existing design tools and approaches with the purpose of understanding what changes should be made in order to make future radio design more efficient.

## **1.2 Back to the Beginnings of Wireless and Mobile Communications**

Modern wireless and mobile devices such as tablets and smartphones are built upon traditional radio technologies. In fact, a wireless device consists of two main blocks. The first is called ‘modem’. It consists of the baseband circuitry in charge of digital signal processing. This block is commonly assembled with additional digital processing capabilities that are dedicated for user applications such as power management and data storage. The second is the radiofrequency front-end (also called radio air interface). It is composed of analog circuitry allowing over-the-air communication using radio waves. Despite the fact that most modern wireless and mobile devices are digital, the first radios were fully analog. In this first section, we go back to the early years of radio communications in order to highlight the evolution of technologies, standards and mechanisms that make up today’s communication frameworks.

### **1.2.1 Historical Perspective**

In 1888, the German physicist Heinrich Rudolf Hertz proved empirically the existence of radio waves. He conducted for the first time an experiment, which concluded that Maxwell’s equations are founded. A few years later, Guglielmo Marconi made the first radio transmission. This achievement opened the way for radio and TV broadcast in 1906 and 1925 respectively. Radio technology at that time was actually primitive. Power amplifiers were cumbersome vacuum tubes. Transmitters radiated tremendous amounts of power in the air while receivers used huge antennas. This was particularly visible in radar systems developed in the early 1940s.

The invention of the transistor in 1947 had a significant impact on radio technologies. In the 1950s, most efforts were deployed to investigate different transistor structures and develop robust fabrication processes. Consequently, transistors contributed to the miniaturization of communication systems and enabled satellite and aerospace applications that emerged in the 1960s. The 1970s were marked by notable advances in computer networking and the emergence of digital integrated circuits (e.g., microprocessors and memory). In the 1980s, several operators around the world launched commercial mobile phone services. The

emergence of Internet in the 1990s was accompanied by the first digital mobile communication and wireless networking standards. The widespread adoption of these technologies was followed during the first decade of the 2000s by a sustained convergence of Internet services, mobile communication and wireless networking. Nowadays, fixed and mobile communication infrastructure is evolving towards a global network providing more services and mobility for users. Recent achievements in miniaturization and integration offers consumers various multi-standard handheld wireless and mobile devices (e.g., tablets and smartphones).

In summary, today's consumer wireless devices are the fruit of more than a century of continuous progress in radio-communication technologies. It seems founded to consider that three major breakthroughs have significantly boosted radio technologies: the Marconi transmitter, the transistor and the Nyquist-Shannon sampling theorem. To outline the various developments that took place in between, Figure 1.1 shows some outstanding milestones in the history of telecommunications.

### **1.2.2 Evolution of Wireless and Mobile Communications**

Since the 1960s, a myriad of radio applications have been emerging to provide communication services for numerous domains (e.g., military, aerospace, consumer, industry, transportation, etc.) with different requirements (especially in terms of battery life, quality of service, SWaP<sup>1</sup> and security). This remarkable evolution was mostly application-oriented. As new application emerge, new communication standards are drafted and new spectrum is allocated for it. Nevertheless, most efforts are usually dedicated for the development of new technologies to accommodate the emerging application. Subsequent technology challenges are mainly addressed by three major players: (i) designers in both industry and academia who are continuously experimenting new ideas to leverage increasingly tougher specifications, (ii) semiconductor foundries who develop new fabrication processes to implement new

---

<sup>1</sup> SWaP stands for Size, Weight and Power.

functionalities and (iii) tool vendors who suggest new hardware and software frameworks for the design, optimization and verification of new radio systems.

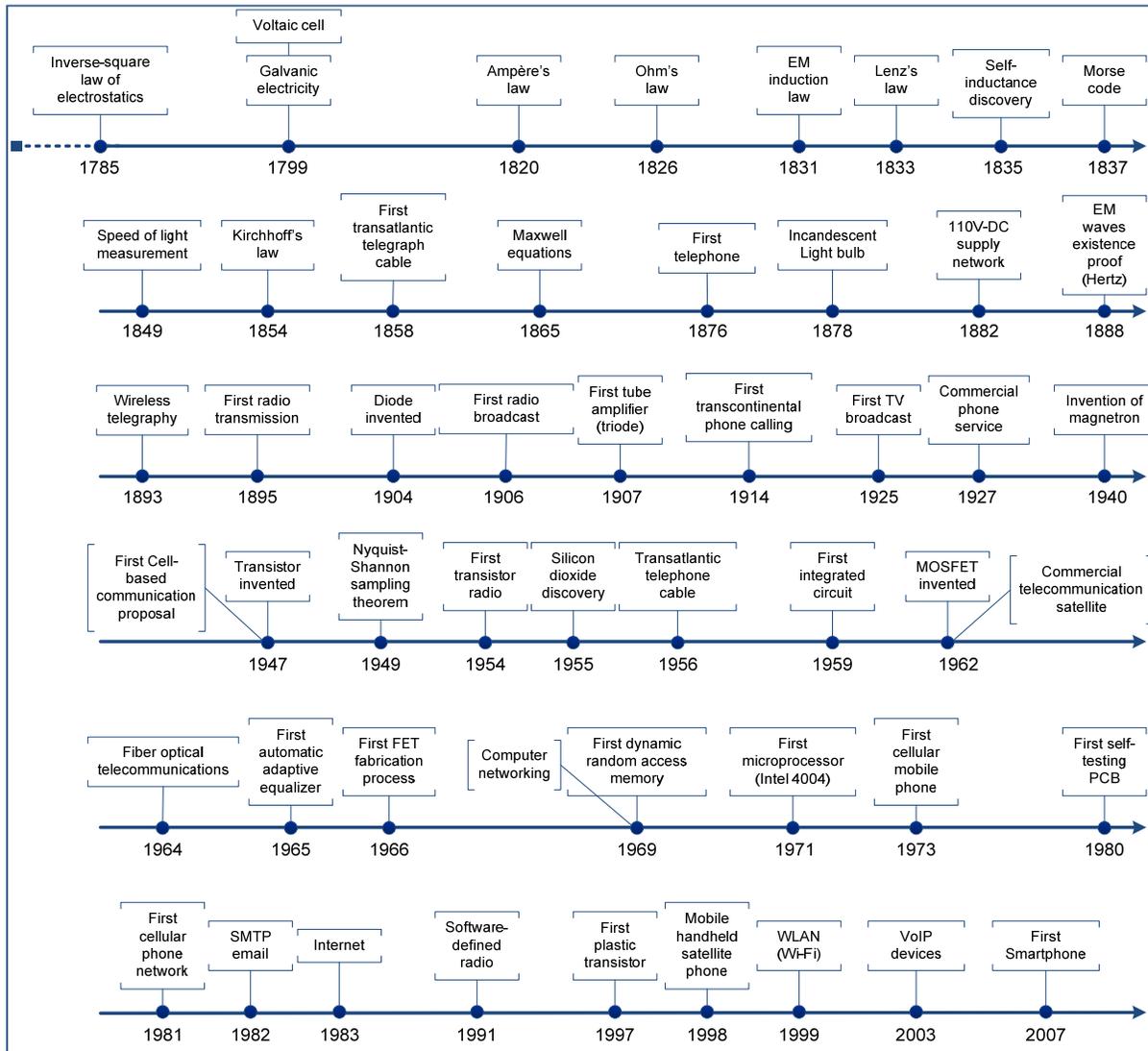


Figure 1.1 A non-exhaustive list of milestones in telecommunications history

For example, the need for wireless networking appeared in the early 1990s with the sustained progress of Internet to which access was almost exclusively done using wired networks. The first wireless standard (namely IEEE 802.11a) was adopted in 1999. It was led and commercialized by the Wi-Fi Alliance (under the acronym “Wi-Fi”, unofficial short of

Wireless Fidelity). The upper part of the 2.4-GHz ISM<sup>2</sup> band was allocated by the ITU for the new standard. Since then, designers have been building, integrating and deploying Wi-Fi solutions using various software and hardware tools (such as mixed-signal design environments, wireless network planning tools, etc.). Nowadays, almost all consumer devices include Wi-Fi chips. The need for higher data rates, more users per hotspot and less radio interferences lead to new Wi-Fi standards and new radio spectrum to be allocated henceforth, in the 5.8-GHz ISM band.

Similarly, the evolution in mobile communications and last-mile wireless technologies was application-oriented. The progress of technology, standardization and spectrum allocations went hand in hand (Pehkonen et al., 2001). In mobile communications history, there are two major eras: the first started in the late 1940s with the Mobile Telephone Service (MTS). It was a pre-cellular half-duplex cumbersome and fully analog system. Its technology allowed only a limited number of users to communicate. Despite technological upgrades, it was expensive and unreliable. The second era of mobile communications started in the early 1990s with the emergence of the first digital mobile phones. Advances in design and fabrication technologies allowed smaller form factors, longer battery life, and higher numbers of users (i.e., which is often equivalent to lower operation costs). To illustrate the changes that took place between these eras, Figure 1.2 shows a comparison between the first handheld mobile phone and a recent smartphone. The weight decreased by a factor of 10 and the size by an average factor of 20 within less than 40 years. The talk time depending mostly on the battery life, has increased significantly. In addition, these devices are not comparable in terms of functionality. The first mobile phone, fully analog, was used only for voice calls while the second, digital in the most part, provides a combination of several services. For example, it offers geo-location services, seamless connectivity to various networks (e.g., Wi-Fi, Bluetooth) and plenty of personal applications (e.g., gaming).

---

<sup>2</sup> ISM (industrial, scientific and medical) refers to the radio spectrum bands dedicated for unlicensed industrial, scientific and medical applications.

This remarkable evolution results from advances in circuit design, fabrication processes, components miniaturization, power management techniques, etc. The transition from fully analog to mixed-signal design (i.e., cohabitation between digital and analog/RF circuitry) has allowed more flexibility and interoperability since digital integrated circuits can be controlled by software. Several analog functionalities were moved to the digital domain which provided valuable gains in area and power. However, despite this progress, the analog/RF part in a mobile phone remains the most challenging.



Figure 1.2 A comparison between the first handheld mobile phone and a recent smartphone

Besides the technological advances in mobile radios, cellular-communication standards have known a remarkable progress. This evolution was commonly subdivided into “generations”. After the primitive mobile networks (also called 0G) and the first generation of analog mobile

networks in the 1980s, the second generation of mobile standards came with digital cell phones. The Global System for Mobile Communications (GSM) is the most globally deployed standards. At its beginnings, it allowed an average data rate of 13 kbps which was roughly enough for a decent voice call. This standard was later augmented by successive upgrades to enhance its quality of service (e.g., GPRS<sup>3</sup>, EDGE<sup>4</sup>). By the early 2000s, the third generation of cellular-communication standards had emerged (e.g., the Universal Mobile Telecommunications System, UMTS for short) offering better data rates (around 2 Mbps). This was followed by several upgrades and extensions to enhance the data rate and provide IP-over-the-air services (e.g., HSPA<sup>5</sup>, LTE<sup>6</sup>). The fourth generation brings with LTE-A (i.e., LTE Advanced) higher downlink peak data rates that may reach 1 Gbps. In roughly two decades, cellular-communication standards multiplied useful data rates by a factor of 105. This was possible due to growing spectrum allocation. It is also due to adaptive signal processing and robust digital design. Despite the fact that techniques such as diversity, amplifier linearization and dynamic power control have contributed to make RF front-ends more suitable for higher data rates, this part of the cell-phone remains the most refractory for progress due to multiple reasons that will be detailed in the following sections.

Likewise, microwave backhaul systems as well as wireless last-mile and wireless local networks have evolved on many levels. Technically speaking, they took part in the same technologies either digital or RF/microwave used for cellular communications. New spectrum

---

<sup>3</sup> GPRS (General Packet Radio Service) is an upgrade of GSM networks providing typical bit rates around 80 kbps.

<sup>4</sup> EDGE (Enhanced Data Rates for GSM Evolution) is an upgrade of GSM networks which allowed bit rates up to 400 kbps depending on the used modulation.

<sup>5</sup> HSPA (High-Speed Packet Access) is an extension of 3G mobile communication networks allowing bit rates up to 42 Mbps. It was followed by HSPA+ providing peak data rates up to 168 Mbps.

<sup>6</sup> LTE (Long-Term Evolution) is a standard for high-speed data mobile communications.

bands were allocated (e.g., U-NII<sup>7</sup>) and various standards and upgrades were drafted (e.g., WiMAX<sup>8</sup>, Flash-OFDM<sup>9</sup>, iBurst<sup>10</sup>).

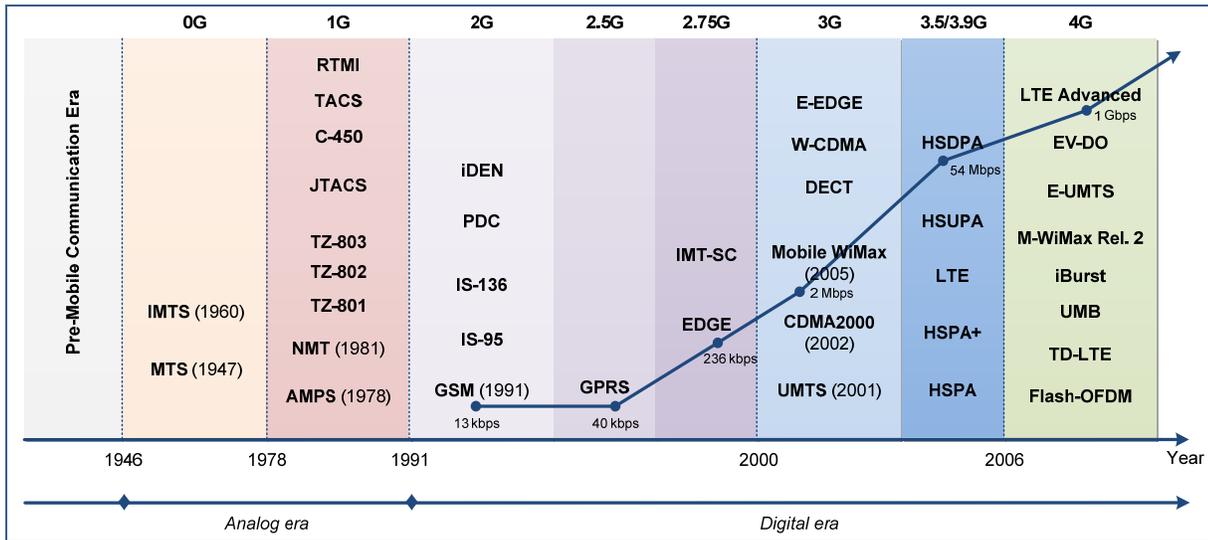


Figure 1.3 Evolution of wireless and mobile standards

To conclude, Figure 1.3 presents the timeline of the common wireless and mobile communication standards. It shows particularly the sustained growth of data rates since the advent of digital communication devices. This growth<sup>11</sup> is bound to continue in the near future (Cisco, 2015). Advances in digital signal processing and analog/RF technologies combined with the active standardization effort and the allocation of more spectrum bands have fueled this growth. Nevertheless, in the last years, there is a growing fear of spectrum scarcity (Chapin et Lehr, 2011; Petz, 2012). The radio environment is being more harsh (due to various factors:

<sup>7</sup> U-NII (Unlicensed National Information Infrastructure) covers three non-contiguous frequency bands laying from 5.15 GHz to 5.825 GHz and was allocated for new wireless services.

<sup>8</sup> WiMAX (Worldwide Interoperability for Microwave Access) is a wireless standard for last-mile wireless broadband access. It was standardized in the IEEE 802.16 family.

<sup>9</sup> FLASH-OFDM (Fast Low-latency Access with Seamless Handoff Orthogonal Frequency Division Multiplexing) is a technology designed for the delivery of broadband Internet services in mobile environments.

<sup>10</sup> iBurst (also known as HC-SDMA, High Capacity Spatial Division Multiple Access) is a wireless broadband technology with vehicular mobility support and was standardized in 2006 as IEEE 802.20 (Mobile Broadband Wireless Access).

<sup>11</sup> "Global mobile data traffic grew 69 percent in 2014. Global mobile data traffic reached 2.5 exabytes per month at the end of 2014, up from 1.5 exabytes per month at the end of 2013. (...) Monthly global mobile data traffic will surpass 24.3 exabytes by 2019." (Cisco, 2015, p. 1)

propagation conditions, growing interferences, etc.) which leads to tougher radio specifications. In the light of these remarks, it becomes obvious that continuing this growth in wireless and mobile communications will require the industry to face multiple challenges. Consequently, what are the major trends in today's industry and what solutions would be adopted (on both technology and design levels) to tackle these challenges?

### **1.3 Future Trends in Wireless and Mobile Communications and Subsequent Impact on Technology and Design Approaches and Tools**

According to ITU, the Information and Communication Technology (ICT) market (including mobile and wireless industry) is one of the most vibrant and dynamic markets worldwide (ITU, 2013). The prior success of wireless and mobile communications marked particularly by a sustained growth of infrastructure and subscriptions is the key driver of this market. However, this success may turn out to a major constraint since that the consumer is expecting higher quality of service and better user experience at lower costs. It seems obvious that the key of success in this field remains a good matching of market trends with relevant enabling technologies in shorter timeframes. In this section, we attempt to examine this topic by highlighting the trends in wireless and mobile communications and modestly assessing their impact on technology and design approaches.

#### **1.3.1 Trends in Wireless and Mobile Communications**

The emergence of new applications and services has been a key driver of wireless and mobile industry for decades. For instance, first mobile phones allowed voice calls only. Then, digital technologies brought data services in addition to voice. The growing capabilities of digital processing enabled multimedia applications and the progress of data rates allowed mobile Internet. This evolution is bound to continue (Cisco, 2015). We discuss hereafter the future trends in wireless and mobile communications from three different angles: user demands, regulatory and standardization frameworks and enabling technologies.

**a) User-driven trends and market shift**

Network operators are working to provide consumers with better user experience (Nortel, 2008). This includes the provision of higher data rates, enhanced mobility, improved security and better support of diverse application and traffic types (Costa-Perez et al., 2013). This effort results in increased number of subscriptions and a market shift. In fact, ITU estimates that the mobile-broadband subscriptions increased by 21% between 2010 and 2013. It also expects the cellular subscriptions to reach 6.84 billion by the end of 2013 (ITU, 2013). The increase in mobile broadband subscriptions is expected to continue. The availability of broadband services has led to the emergence of new services, applications and paradigms (e.g., machine-to-machine communications, converged services, cloud services, over-the-top services like VoIP, cooperative intelligent systems, etc.) (Costa-Perez et al., 2013; ITU, 2013). This evolution outlines a market shift that requires the wireless and mobile industry to adapt its products to a constantly changing operation environment at affordable costs. In this regard, one can particularly think about the underlying technology issues related for example, to RF front-end design and operation.

**b) Regulatory, spectrum management and standardization trends**

The growth of fixed and mobile broadband services requires more frequency bands but is facing regulatory challenges. Most current spectrum management policies are administrative-oriented (ITU, 2013). Being an increasingly scarce commodity, regulatory organizations should change their policies for more efficient use of RF resources (ITU, 2013; Petz, 2012). The spectrum should be market-oriented and its fragmentation should be minimized in order to accommodate more mobile and wireless services. There is a tendency to foster this standpoint (e.g., allocation of U-NII bands for wireless services, use of TV white spaces to locally take part of spectrum fragmentation, etc.). Technically, the implementation of such approaches requires advanced spectrum sensing and radio awareness techniques (e.g., cognitive radio). However, such techniques are still at infancy because of RF design limitations

especially in complex radio environments (e.g., Dynamic Frequency Selection<sup>12</sup> for U-NII bands in some countries) (Petz, 2012; Steenkiste et al., 2009).

Furthermore, regulatory issues become more challenging when it comes to global effort. Inter-organization cooperation to ensure network / service convergence is required but not always easy to concretize (Costa-Perez et al., 2013; MobileInfo; Nokia Siemens Networks, 2011). The effort is mostly focus on the development of new standards. However, this does not fully resolve all the issues.

### **c) Core technology and network infrastructure trends**

During the last few years, consumers are moving to use mobile from fixed networks (Roman Friedrich, 2006). The Cisco Visual Networking Index expects that mobile data traffic will grow at a 66% CAGR<sup>13</sup> from 2012–2017 which is three times faster than the growth of global IP fixed traffic during the same period (Cisco, 2013). With this sustained increase of fixed and mobile data traffic, communication networks will continue to grow in terms of infrastructure and capacity (Costa-Perez et al., 2013). Furthermore, the emergence of new applications and the growth of mobile traffic are imposing two major trends. The first is the convergence of different technologies and services. It aims to provide end users with a complementary set of services independently from the network. For example, one can use seamlessly a fixed wired/wireless, a mobile network or both for a voice call (e.g., the Unlicensed Mobile Access<sup>14</sup>). The second trend is the migration to all-IP networks (Markova, 2009; Nortel, 2008).

To face this sustained growth and remarkable changes in networks, the wireless and mobile industry is facing at least two challenges. The first is related to the core technology

---

<sup>12</sup> Dynamic Frequency Selection (DFS) is a mechanism elaborated to allow unlicensed radios to use the 5-GHz frequency bands initially allocated for some radar systems. To avoid interference, DFS imposes to unlicensed radios the sensing of radio environment and the detection of radar presence before actually starting to communicate. Briggs, Mark. 2010. « Dynamic Frequency Selection (DFS) and the 5-GHz Unlicensed Band ».

<sup>13</sup> CAGR (Compound Annual Growth Rate) is the geometric mean of year-over-year growth rate.

<sup>14</sup> The Unlicensed Mobile Access (UMA) is a technology that allows seamless access to GSM, GPRS and EDGE mobile services using unlicensed spectrum technologies such as Wi-Fi and Bluetooth. Yan Zhang, Laurence T. Yang, Jianhua Ma. 2008. *Unlicensed Mobile Access Technology: Protocols, Architectures, Security, Standards and Applications*. CRC Press.

enhancements. It is about providing new technology solutions for better hardware performance (particularly in RF front-ends), smaller form factor and less power consumption.

The second is related to network infrastructure. In fact, capacity increase is often bounded due to the limitations of radio access networks. Microwave backhaul solutions still require various enhancements such as efficient interference management and coordination tools, better antenna technologies and frequency planning mechanisms, etc. Radio access networks require capacity improvements in order to cope with traffic explosion. Low-cost equipment is needed for cost efficiency. Energy savings are extremely important to reduce operation costs (Costa-Perez et al., 2013).

### **1.3.2 Impact on Technology and Design Approaches and Tools**

The wireless and mobile marketplace trends reflect a growing need for higher-data-rate, lower-cost and longer-battery-life devices. From engineering standpoint, these expectations can be derived into technology and design requirements (see Figure 1.4). For example, providing consumers with higher-data-rate devices needs more spectrum allocation (i.e., devices should support more frequency bands), more processing capability and more robust RF front-ends. This implies higher levels of miniaturization and integration, better power management, etc. Moreover, designers should have enabling design tools and approaches to take part of technology advances and leverage higher design complexity in shorter timeframes.

Actually, the wireless and mobile communications are evolving at quicker pace and this tendency is expected to continue in the next few years (see Figure 1.5). Consequently, the industry needs not only to deliver better products but also to reduce the time-to-market in order to face the growing economic pressure. To do so, they should focus two key enablers: innovating implementation technologies and relevant design tools and approaches. With regard to this assumption, is wireless and mobile industry having such (i) technologies and (ii) design tools to meet today's market demands? This question is what we aim to examine in this section.

### a) Technology

Nowadays, most modern consumer wireless devices (and mobile phones) provide connectivity to various communication networks. They are implemented as multi-standard, multi-band and multi-mode transceivers. A similar handset is composed of three main parts (see Figure 1.6 and Figure 1.7). The first is the baseband block which consists of various application-specific integrated circuit (ASIC) in charge of baseband signal processing. The second is the RF front-end which is composed of a set of RF devices (e.g., filters, amplifiers, oscillators, etc.) used for radio communications. In addition to all these components, generic processors, memory chips and dedicated components (e.g., sensors, cameras, etc.) are dedicated for user applications (e.g., video capture, gaming, etc.) and system management (e.g., operating system, power control, data storage, etc.).

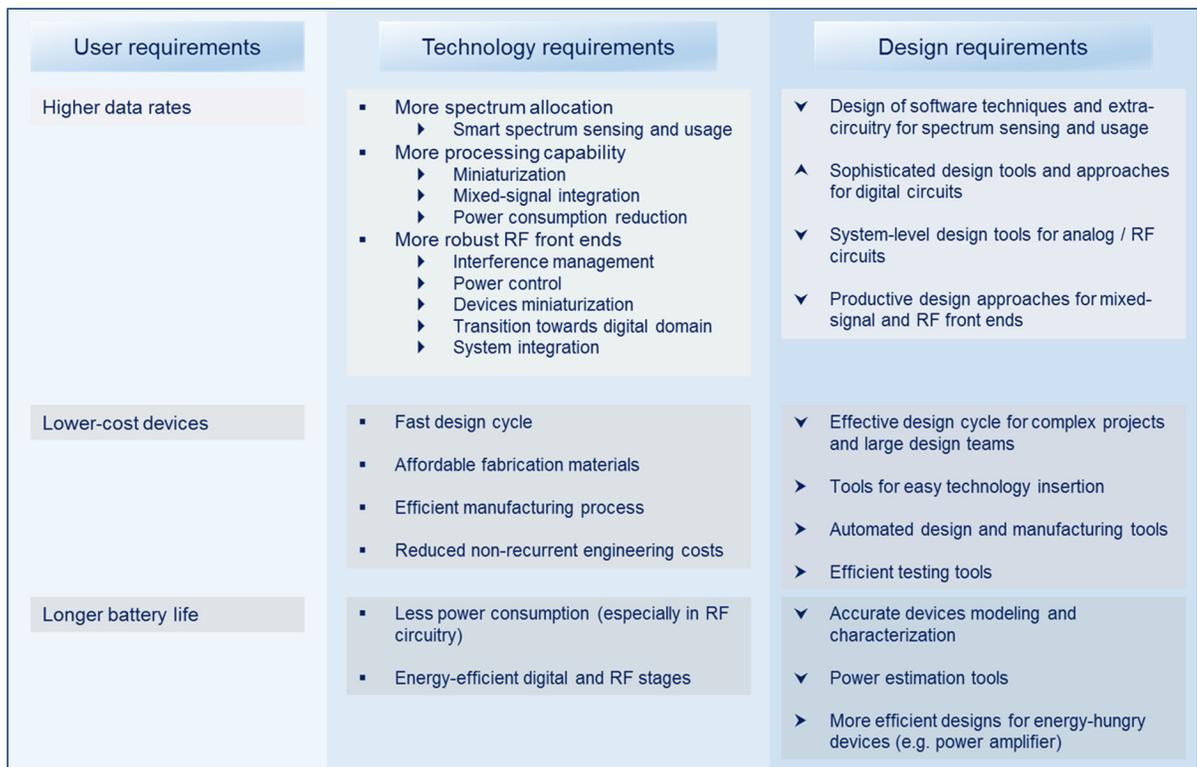


Figure 1.4 User expectations can be derived into technology and design requirements

If the wireless and mobile industry is currently able to deliver relatively satisfactory handsets, there are however various challenges to address at different levels in order to cope with the emerging demands:

## **1. Hardware performance**

Hardware performance (in terms of either baseband processing capability or RF/analog robustness) is becoming more critical than ever. In addition to user applications, increasingly harsh radio environment (e.g., multipath, fading and interferers), spectrum crowdedness and inherent radio impairments (e.g., nonlinearities) require more signal processing capability and RF front-end reliability. Furthermore, to ensure good hardware performance, the handset should have an excellent sensitivity in reception while in transmission, it should be able to select the best configuration that maximizes the quality of service and optimizes the usage of its resources (especially battery charge). Current radio systems suffer from various shortcomings particularly at the RF front-end level. For instance, LTE smartphones are hampered by fundamental limitations in the RF front-end that cannot be overcome with traditional RF technology (Gianesello, 2012; Mobile Europe, 2012). Power amplification is typically an outstanding issue in such handsets. Apple iPhone 5 does not support all frequency bands because there is neither sufficient transmission power nor enough board space to accommodate all the required power amplifiers (Gianesello, 2012; Mobile Europe, 2012).

To address all these issues, some innovative techniques are emerging. Efficient CMOS as well as switched-mode power amplifiers may be suitable for chip integration and low-consumption handsets (Andrew, 2011; Gianesello, 2012; Mobile Europe, 2012). Cognitive radio addresses the issues related to the shortages/crowdedness of the spectrum. To increase the data rate, diversity techniques may also help (e.g., Multi-Input/Multi-Output or MIMO).

## **2. Device's complexity and form factor**

At system level, the count of functional blocks in a typical handset is relatively limited compared to devices in use few decades ago. In fact, the number of components on a mobile phone board was about 300 in 1999 and around 100 in 2002 (Pulsford, 2002). Over the years, this continuous reduction of components' count (especially discrete passives) has contributed to significantly reduce devices' form factor (see Figure 1.5). Nevertheless, in the last years, the form factor of wireless and mobile devices is slightly growing after it reached a minimum at the early 2000s. There are two reasons for this. On the one hand, the emergence of mobile

Internet and gaming requires handsets with larger screens and better resolutions<sup>15</sup>. On the other hand, serious limitations in the RF front-end (e.g., no broadband antennas) caused the duplication of RF circuitry. In most cases, each supported communication standard has its dedicated baseband and RF/microwave circuitry (this is depicted in Figure 1.6 and Figure 1.7). On the baseband level, the reduction of the form factor comes at the cost of higher complexity. But this is possible due to sophisticated design tools and technology maturity. For instance, Figure 1.8 shows an ASIC chip that implements five communication standards. This chip recently used in Apple iPhone 5 replaces at least three chips that were previously integrated within Apple iPhone 4. In RF and microwave side, reducing the form factor of RF/microwave components is difficult because it is limited by the laws of physics (e.g., electrical length). However, numerous promising solutions are being tested. Among them, the use of Micro-electromechanical Systems (MEMS) seems encouraging for both miniaturization and reconfigurability. In addition, broadband and compact antennas can be achieved using advanced tunable antennas. There is also a tendency to export bandwidth problems from RF to digital domains. In this regard, software-defined radio is a good candidate particularly with the notable advances in analog-to-digital and digital-to-analog converters.

### **3. Miniaturization and integration**

A baseband integrated circuit (IC) contains hundreds of millions of devices combined in a very small silicon area. The component count increases while the fabrication process minimum feature size continues to decrease (see Figure 1.5). Nevertheless, a typical RF board contains few dozens of components that are often cumbersome and power consuming. Paradoxically, it is easier to integrate millions of digital components rather than a handful of RF/microwave devices.

---

<sup>15</sup> Between 2000 and 2010, the average display size of a handset has increased by approximately 60%. Korhonen, Kaisa. 2011. « Predicting Mobile Device Battery Life ». Aalto University, Finland.

There are various reasons behind this situation:

- Digital ICs are integrated using the same technology (i.e., CMOS<sup>16</sup>) while RF designers use a mix of technologies (some RF devices such as duplexers, switches and power amplifiers are off-chip and cannot be integrated within the same substrate (Hansen, 2003));
- Digital fabrication processes shrink down faster than it occurs in the analog and RF/microwave side;
- Passive and discrete components represent more than 80% of the chip area (Pulsford, 2002). The use of passives is cheap and provides good performance but these components are difficult to miniaturize and integrate. Reducing the subsequent area penalty is a significant headache for designers.

Achieving more integration allows the implementation of more functionalities but is often related to the increase of noise, parasitic effects and cross-talks. This is particularly true in the case of mixed-signal design where digital and analog circuitry is combined in the same chip (Ferragina et al., 2005; Masoumi et al., 2001). Digital circuits typically create noise that interferes with analog circuitry performances. Packaging is another challenge to cope with due to the heat dissipation issues that occurs due to higher density.

Hopefully, new integration techniques are emerging to tackle these issues. For example, technologies such as High-Temperature/Low-Temperature Co-fired Ceramic (HTCC/LTCC) allow effective multi-layer integration. System-on-Chip (SoC) is considered an efficient solution for heat dissipation and may be prevalent in the design of future radios (Nokia Siemens Networks, 2011). The Post-Silicon Tuning (PST) was thought to enhance the reliability and robustness of ICs by minimizing the mismatches and parasitic effects due to process scaling (Li et al., 2007).

---

<sup>16</sup> CMOS (Complementary Metal-Oxide-Semiconductor) is a technology for the implementation of both digital and analog integrated circuits. Its major advantages are the low-static power consumption and good immunity to noise.

#### 4. Power consumption and energy efficiency

Transmitting less power in wireless and mobile communications means longer battery life for handheld devices, less inband blockers for other users and less power consumption for base-stations. At the side of end-user, a significant proportion of the battery charge is consumed by the RF front-end (and especially the power amplifier). Approximately, 30 to 40% of the battery charge is consumed by the RF front-end against 20% by the baseband processors (Irmer et Chia, 2009). According to (Hubbard, 2012), the average consumption of baseband processors in smartphones has doubled between 2009 and 2011 while the RF front-end consumes 11% more energy in 2011 than it was in 2009. Referring to the number of devices in a baseband processor and a RF front-end, the power consumption per device has grown less in the former than the latter.

Besides, the duplication of RF components in current multi-standard handsets does not only increase the device's form factor (i.e., the required board area increases) but also raises its power consumption and degrades its performance (i.e., isolation, insertion loss, noise and heat dissipation become critical design issues). Furthermore, the battery charge capacity did not grow significantly in the last decades. For instance, the charge of Lithium-ion batteries (i.e., the most used battery type in modern handsets) increased by a factor of three in 15 years (see Figure 1.5) while the average handset power consumption almost doubled in only two years (Hubbard, 2012). The gap between the amount of energy required for a handset and the available battery charge has been growing (Korhonen, 2011; Micallef, 2013).

At the operator side, cellular networks represent over 90% of ICT sector energy consumption. Specifically, the power consumption of base-stations accounts for around 75% of the overall network energy consumption (Guo, 2011). In addition to its environmental effects<sup>17</sup>, the

---

<sup>17</sup> The estimates indicate that the ICT sector is responsible for 2 to 4% of the global carbon emissions. The power consumption related to network and equipment operation counts for 40 to 60% of this volume, which is bound to double by 2020. Vereecken, W., W. Van Heddeghem, M. Deruyck, B. Puype, B. Lannoo, W. Joseph, D. Colle, L. Martens et P. Demeester. 2011. « Power Consumption in Telecommunication Networks: Overview and Reduction Strategies ». *Ieee Communications Magazine*, vol. 49, n° 6, p. 62-69.

subsequent economic impact<sup>18</sup> is significant. For operators, the least power the network consumes the least money they pay for the energy bill<sup>19</sup> (Micallef, 2013).

Accordingly, reducing power consumption and developing more energy-efficient RF front-ends allow an extended talk time for battery-powered handsets and lower operation costs for network operators. To achieve that goal, most of efforts were focalized on improving power amplifiers efficiency. This technique has proven until recently substantial gains. In recent smartphones, a rule of thumb indicates that a 1% improvement in power amplifier's efficiency results in approximately 35 mAh gain in battery charge and around 50mm<sup>2</sup> reduction in the device's form factor (Hubbard, 2012). At this regard, recent low-consumption reduced-noise technologies (e.g., high-voltage GaAs HBT<sup>20</sup> and GaN substrates) may be used to fabricate not only power amplifier but also other energy-hungry RF components (e.g., oscillator, switch, etc.) (Andrew, 2011; Ashbaugh, 2009; Lidow, 2013).

### **b) Design Approaches and Tools**

Keeping pace with the market demands includes the enhancement of not only technologies but also the design process of wireless and mobile handsets. This process covers various design tasks such as analysis, implementation, integration and verification of both baseband and analog/RF blocks. In each step of the design process, designers use software and/or hardware tools in order to achieve various design tasks.

For analysis, designers need system-level tools to enhance design space exploration. This implies the availability of high-level models for all involved components. Implementation requires continuous update of technology libraries. It needs also tools for effective system partitioning in order to easily derive the specifications of the functionalities to be designed and

---

<sup>18</sup> The energy cost incurred by fixed and mobile network operators are 30% and 90% respectively. Koutitas, George, et Panagiotis Demestichas. 2010. « A review of energy efficiency in telecommunication networks ». *Telfor journal*, vol. 2, n° 1, p. 2-7.

<sup>19</sup> Emerging technologies allow energy cost savings up to 20%. Lange, C., D. Kosiankowski, A. Betker, H. Simon, N. Bayer, D. von Hugo, H. Lehmann et A. Gladisch. 2014. « Energy Efficiency of Load-Adaptively Operated Telecommunication Networks ». *Journal of Lightwave Technology*, vol. 32, n° 4, p. 571-590.

<sup>20</sup> HBT stands for "Hetero-junction Bipolar Transistor" which is a type of bipolar junction transistor. It can handle signals with frequencies up to several hundreds of GHz.

implemented separately. In addition to yield and performance optimization tools currently in use, designers need at this step new tools for power estimation and form factor optimization. Next, system integration allows the assembly of the various digital, analog and RF subsystems. In this step, designers need a myriad of tools for floorplanning, placement and routing.

Finally, verification is an important step in the product design cycle. It aims to ensure that the wireless and mobile device meets the initial specifications and delivers the intended performance. Designers use numerous software and hardware tools to carry out design verification and performance assessment. Regarding software tools, high-level and automated tools assist digital designers with this time-consuming task (Wang, Chang et Cheng, 2009). However, available tools for analog/RF designers are often limited (Berkley Design Automation, 2009).

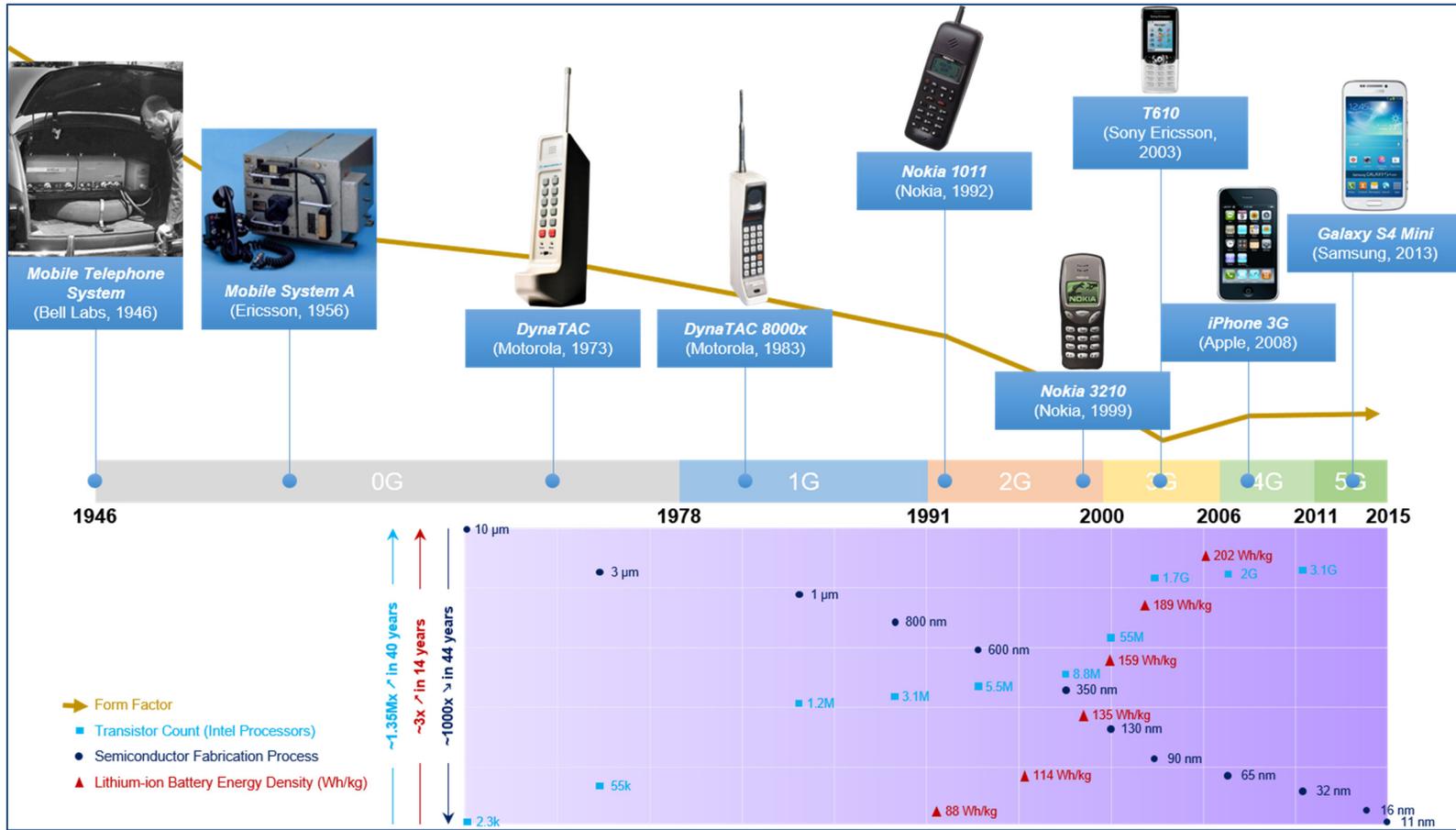


Figure 1.5 Radio-communication technology is evolving at a growing pace  
 Data compiled from Anderson (2009); Intel (2013a; 2013b)

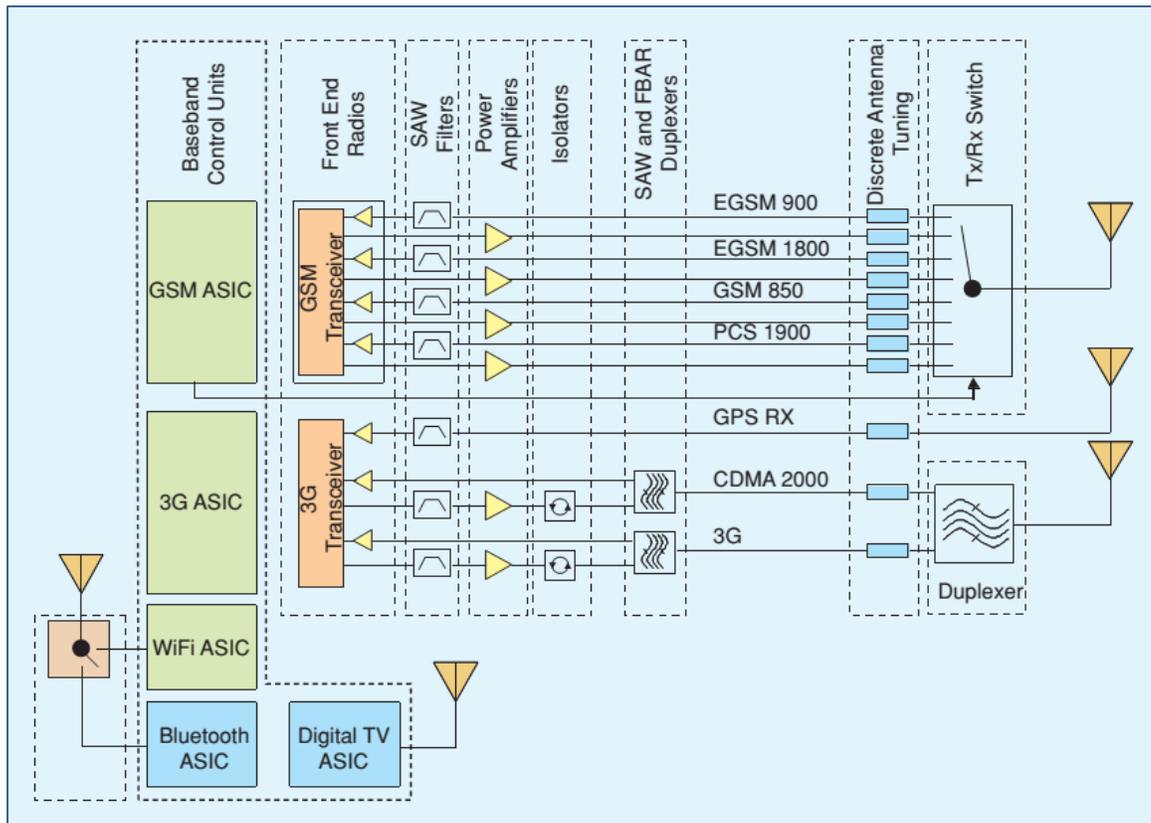


Figure 1.6 A typical multimode, multi-band handset block diagram  
Taken from Chia et al. (2008, p. 61)

#### 1.4 Challenges in Wireless and Mobile Radio Design

To comply with demanding marketplace requirements and manage growing radio environment constraints, the wireless and mobile industry should come up with good trade-offs to leverage three antagonistic factors: performance, time-to-market and cost. This includes primarily the reduction of non-recurrent engineering costs, the improvement of fabrication processes and the acquisition of latest design tools and approaches. All these aspects are closely tied to the design space where skills and knowledge may be less productive if there is no coherent design methodology in action and backed by a set of relevant design tools and flows. Such design methodology is meant to create a concrete separation between the functional and physical design levels. More abstraction at the functional level reduces increasing design complexity while pushing implementation into more detail masters physical effects due to continuously shrinking technology. Consequently, the design tools should allow designers to navigate

throughout the various design tasks and manage the different design representations (e.g., functional, schematic, physical, etc.) in a discontinuity-free design flow. In this sense, increasing the range between functional and physical levels and filling the gap between them with suitable design methodology and tools enhances the design practice and enables better design exploration results (see Figure 1.9) (Kundert et al., 2000).

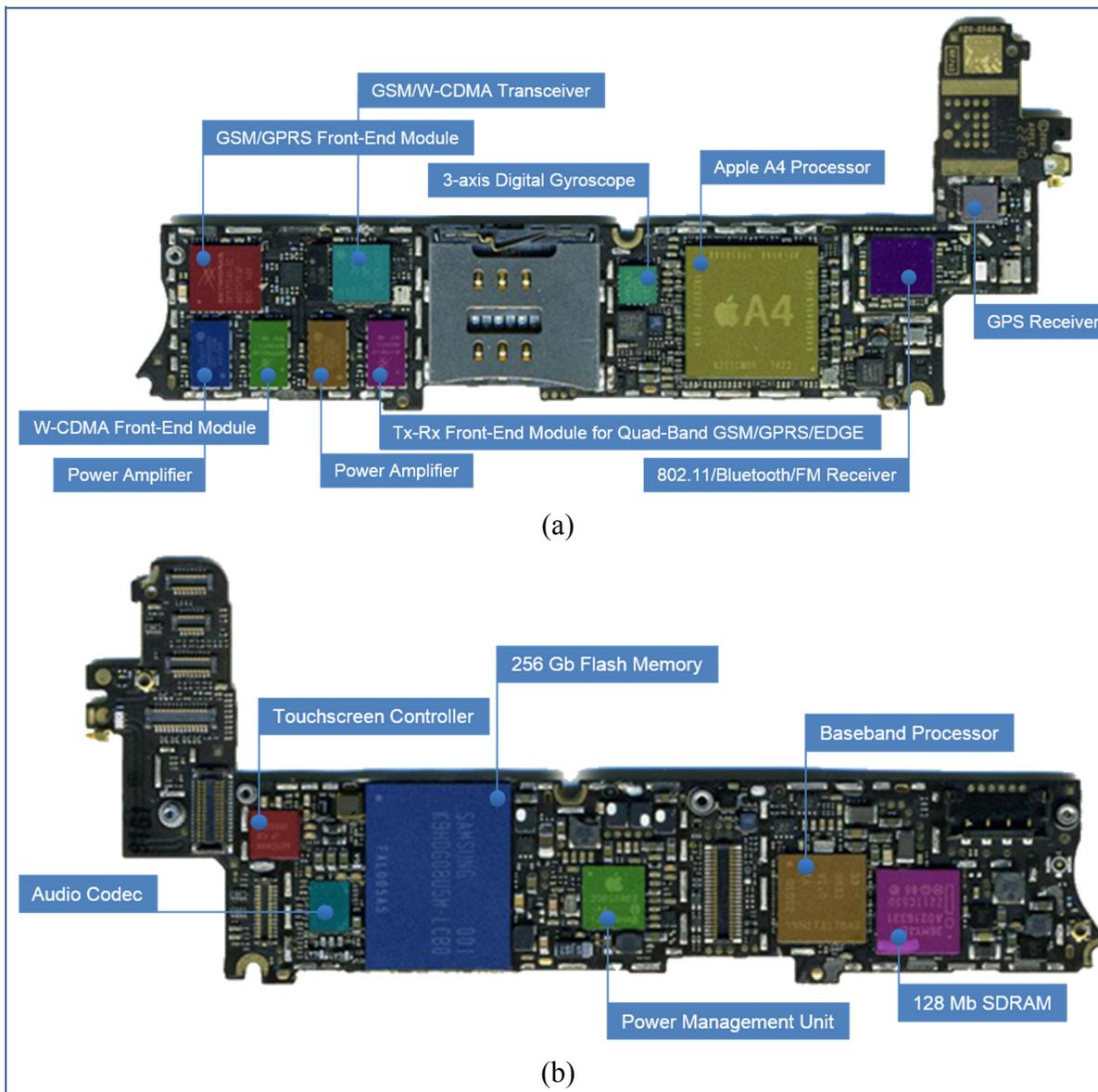


Figure 1.7 iPhone 4 PCB Layout: (a) Front Panel: Front-End components (b) Back Panel: Baseband components  
Board photos courtesy of UBM TechInsights 2012

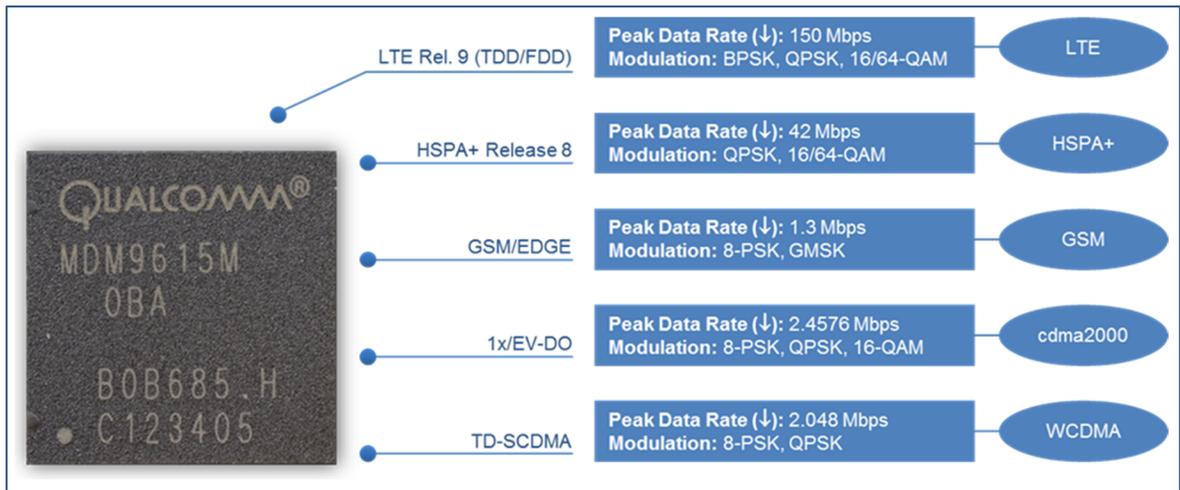


Figure 1.8 A typical multi-standard multi-mode multi-band baseband chip: Qualcomm MDM9615M baseband modem used in iPhone 5  
Chip photo courtesy of www.ifixit.com 2012

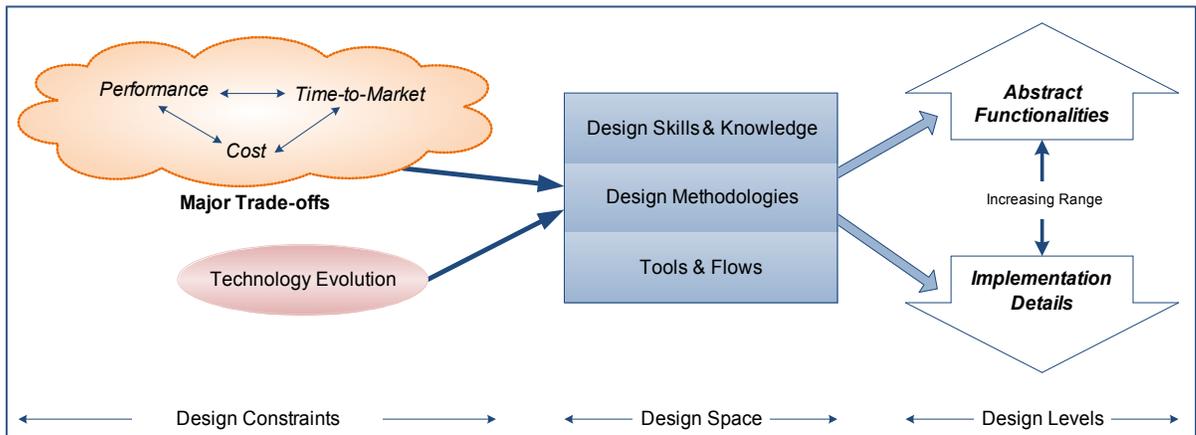


Figure 1.9 Interaction between design constraints, methodologies and abstraction levels  
Adapted from Kundert et al. (2000, p. 1561)

Generally, radio design starts with system partitioning which consists of identifying the components and functionalities that should be implemented within each design domain. Most baseband components are digital and implemented within the digital domain. The RF front-end encompasses components from both analog and RF and microwave domains. Moreover, design domains may also overlap. Signal converters are the typical building blocks that involve elements working in different domains (see Figure 1.10).

Considering this mix of components and devices, designers should address not only the challenges within each design domain but also those caused by the integration of mixed-signal blocks. In this section, we present an overview of the design challenges in digital, analog and RF/microwave domains.

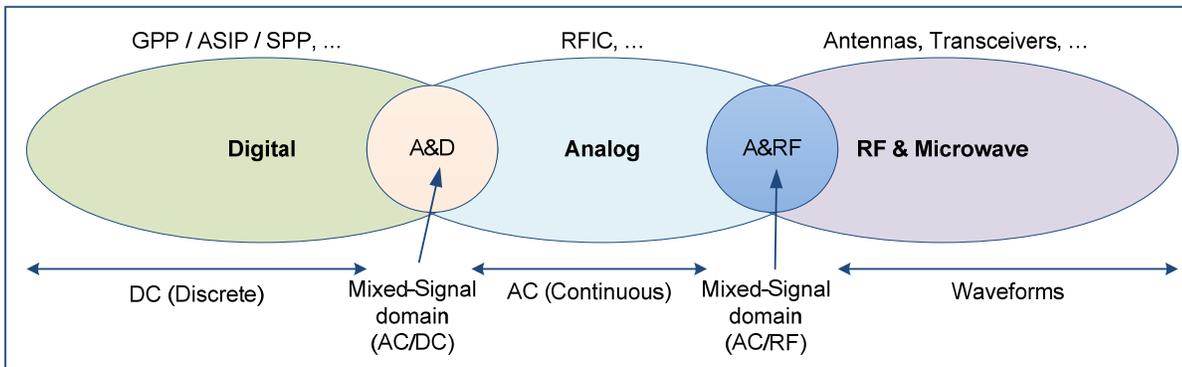


Figure 1.10 Design domains

In baseband digital signal processing, design tools and approaches are relatively mature. Designers work mostly at high levels of abstraction. Tools allow good automation capability which leverages design complexity and help designers focusing more on the functional solution rather than the implementation physics. The main challenges in baseband are related to the development of new techniques and algorithms for signal processing (e.g., Multi-user diversity (Jiang, Zhuang et Shen, 2005), resources allocation and scheduling (Irmer et Chia, 2009; Lang Tong, 2002), power management (Chen, 2009b), reconfigurability (Masselos K., Blionas S. et T., 2002; Muck et al., 2007; Parizi et al., 2006), cross-layer design (Chen, Low et Doyle, 2011; Shakkottai, Rappaport et Karlsson, 2003; Song et Li, 2005)). Keeping pace with the evolving fabrication processes is also important. This includes for example, the continuous upgrade of design tools, the development of system-level models for the newest technologies and the enhancement of the verification techniques.

At the analog/mixed-signal and RF/microwave front-end levels, challenges related to design flows and tools are various and critical. Some of them are related to the former, others are related to the latter while a third set is pertaining to both (see Figure 1.11):

### a) Design flows

Analog/mixed-signal and RF/microwave technologies have significantly evolved during the last decades. However, most designers still start building RF front-ends at the circuit level. This traditional approach was effective in the past because RF circuits and technologies were relatively simple. However, today there is a common consensus that RF designers lack effective design flows to overcome the growing complexity of RF circuits (Chang et Kundert, 2007; Iniewski, 2007). At this regard, various issues should be resolved:

- Technology dependence: RF designers deal with high frequencies. This requires multiple design skills and exposure to a wide variety of different technologies at the same time. The absence of effective system-level models pushes designers to work with circuit-level models that makes technology the actual guide for the design. This absence of higher levels of abstraction hinders the effort of design space exploration, reduces automation capability and limits design reuse;
- Completeness: There is a lack of complete design flows for numerous RF/microwave fabrication processes (e.g., SiP integration). This incompleteness is marked especially by the absence of relevant design tools to accomplish various design tasks;
- Design concurrency: Most of RF/microwave designers still start building their systems at the circuit level. That is a bottom-up design approach where tasks are carried out serially. In this approach, the design time cannot be reduced by applying design concurrency. Furthermore, there are no formal techniques or specialized tools to interface between design stages. This is commonly done manually which increases design flaws and errors that may be prohibitively expensive in time and money (particularly at the end of the design cycle);
- Design collaboration: Starting design at the circuit level causes discontinuities in the design cycle. In addition, designers tend to work in isolation from each other and communication is generally poor. This may cause design flaws that are time-consuming and expensive to correct;
- Co-design: According to (Wang, Stroud et Touba, 2008), 80% of digital chips contain analog/RF circuitry. Digital and analog/RF circuits are built and tested in different domains (time and frequency domains respectively). There is a lack in co-design approaches that

allow the simultaneous interaction between digital and analog/RF designers (i.e., mixed-signal design and verification);

- Cost and TTM: Poor communication between designers, manual interfacing between design stages, absence of design and verification tools and limited design concurrency cause design re-spins to correct errors. On the contrary to digital circuits which succeed a first pass test, RF circuits require multiple passes which raises design costs and increase time-to-market (Hansen, 2003).

## **b) Tools**

Design tools are the cornerstone of every design process. Designers use these tools for the implementation, verification and performance assessment of wireless and mobile systems. Despite recent advances (Cheng et al., 2010), design tools currently in use in RF/microwave design suffer from various lacks and limitations:

- Multi-technology support: RF designers require tools that support different process technologies at different levels. These tools should provide the feature of simulating a mix of technologies at system-level (Park, Hartung et Dudek, 2007);
- Specifications validation: On the contrary, to digital design, tools used in RF domain do not include the feature of specifications validation due to the lack of executable models (Warwick et Mulligan, 2005);
- Modeling accuracy: Most tools (especially those used in RFIC design) suffer from the lack in modeling accuracy, which affects the design quality. For example, models used for passives and substrates are poor because they do not include parasitic effects (Dunham et al., 2003). Another example is MOSFET<sup>21</sup> circuit simulation which still suffers from linearity issues and noise inaccuracies due to the inappropriate modeling of MOS devices (Andriana Voulkidou, Stylianos Siskos et Noulis, 2012);
- Functional and physical verification: This aims to detect any design defects and errors. Functional-level verification attempts to test the conformity of the design to the initial

---

<sup>21</sup> MOSFET (Metal-oxide-semiconductor field-effect transistor) denotes a family of transistors used for switching and power amplification.

specifications at system level while physical-level verification checks if there are any circuit-level defects, violation to design rules, etc. Some studies state that more than the half of the development time is nowadays dedicated to verification. Additionally, as technology shrinks verification time increases (Foster, 2012). However, most analog/RF tools lack features for functional-level verification while physical-level one depends generally on tools and available technology libraries;

- Tool specialization: Due to the complexity of RF design, tools do what they are best at. Specific technologies (e.g., Silicon-on-Insulator) require specialized tools rather than generic solutions lacking enough accuracy and dedicated features for particular technologies (McMahon, 2009);
- Simulation issues: Most tools suffer from three main problems: (i) lack of high-level simulation of digital and RF blocks to determine the circuit specifications (ii) poor circuit-level simulation accuracy of nonlinear circuits and (iii) lack of accurate computation of some devices parameters (e.g., oscillator phase noise) (Leenaerts, Gielen et Rutenbar, 2001; Wambacq et al., 2001). For the first problem, the analysis of complex modulation schemes at system level is still difficult to do and most simulation tools do not provide fast and correct performance data (Leenaerts, Gielen et Rutenbar, 2001). Furthermore, RF simulators work well with individual blocks but still work poorly on algorithmic-based blocks and heterogeneous systems (e.g., digital, analog and RF) (Kundert, 2005). For the second issue, the simulation of nonlinear devices (particularly in large-signal domain) in a reasonable time and with enough accuracy is still a major challenge in RF design (Dutton, 1997; Hartin et Yu, 2006; Zhiping et al., 1999). Regarding the third issue, most simulation tools provide little accurate estimates of some system-critical parameters such as phase noise (Bizzarri, Brambilla et Gajani, 2011; Wambacq et al., 2001). In addition, simulation tools capability is often surpassed. The multi-domain simulation is often done by co-simulation where two or more tools are used to evaluate the design performance. For instance, the integration of power amplifiers and voltage-controlled oscillators require co-simulation in order to estimate the performance in both electric and electro-magnetic levels. Co-simulation is often error-prone and time-consuming;

- Automation: RF design is costly and time-consuming for not only the frequent design spins needed to complete a design but also because most design steps are manual. Little RF tools provide automated design support;
- Tools interaction and design data: Most tools lack the ability to interact with other tools particularly those providing a different type of analysis (e.g., electromagnetic field solvers, noise and cross-coupling analyzers) (Dunham et al., 2003). The ability of exchanging models and design data between different tools of different vendors is generally limited. Old file formats (often limited and not uniformly supported by all the tools) are in use to export data and layouts;
- Versioning and design reuse: The lack of an incremental top-down design approach makes versioning and design reuse very difficult to do (Saleh et al., 2003). This is particularly true for RF domain where most tools do not include such ability.

In addition to software tools used in radio design, hardware tools are used to test the manufactured system and measure its physical performance parameters. This step aims also to validate its electrical behavior and unveil any malfunctions. Various test instruments are available for digital and analog/RF designers. However, many challenges are still present with in this area. In fact, correlation between digital/analog and RF signals is challenging and critical for correct radio operation (Akretch, 2012). Although mixing RF circuitry and digital/analog devices causes signal integrity issues, verification still takes place separately in time-domain for digital designs and frequency-domain for analog/RF ones. In this regard, there is a lack of cross-domain test and measurement tools that can be used for mixed-signal designs. But, some advances have emerged in the last years (e.g., mixed-domain oscilloscope (Akretch, 2012)). Furthermore, the performance of test instruments should exceed the unit under test. The accuracy requisites have increased because performance requirements of wireless and mobile systems have significantly increased (Poole, 2013). This has led to the emergence of small-form-factor, multi-application and high-speed test instruments. The use of reconfigurable hardware, software-defined radio and new test techniques (I/Q modulators/demodulators, direct-conversion receivers, etc.) as well as the massive use of

software-based real-time processing and the advances in data converters are promising a new generation of test and measurement tools (Poole, 2013).

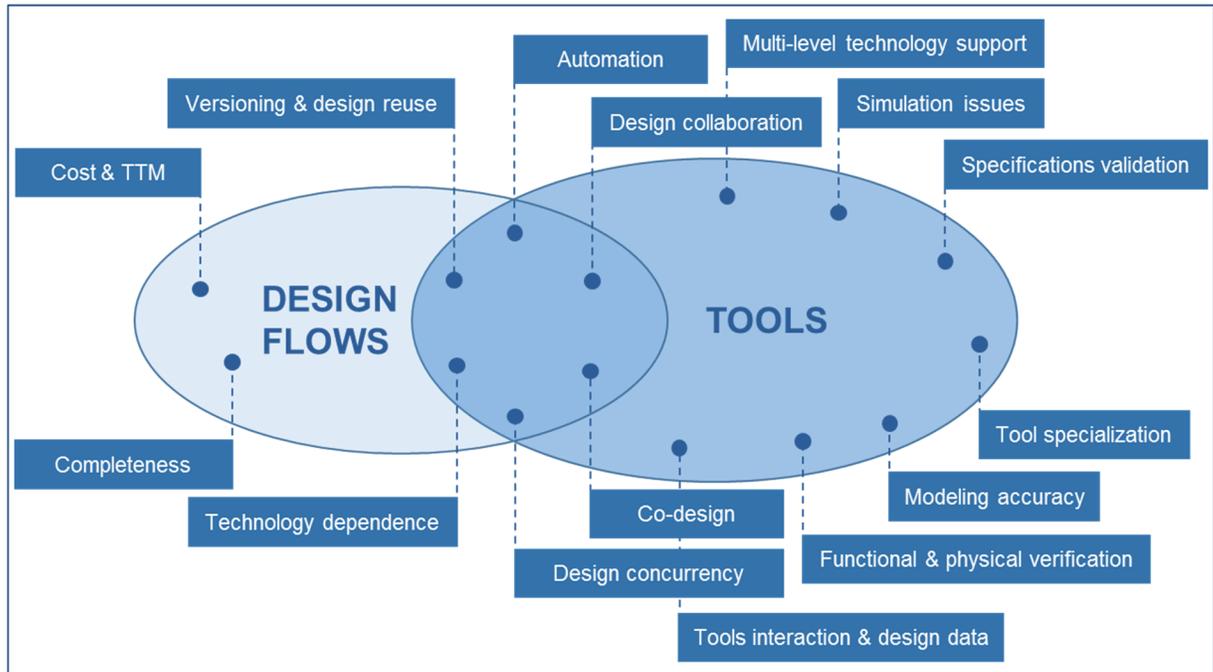


Figure 1.11 Challenges in RF design can be fully or partially related to either the design flows or tools in use

In summary, the wireless and mobile industry is facing outstanding challenges to meet market demands. The mature design practices currently in use in baseband allow digital designers to adapt to the emerging requirements. They only require the latest technology models and new techniques and algorithms for optimal baseband operation in order to generate a new generation of designs. The design approaches they are using are agile enough to support easy technology insertion and tools upgrades. By opposition, analog/mixed-signal and RF/microwave designers are facing tougher constraints due to the limited capability of most design tools in use and the absence of effective design approaches allowing fast design and verification of analog/mixed-signal and RF/microwave circuits. To summarize the current status in digital, analog and RF/microwave domains, Table 1.1 and Table 1.2 give an overview of the assets and shortcomings in terms of emerging technologies and design tools regarding the current and future design challenges.

## 1.5 Conclusion

Radio communications have seen a tremendous evolution during the last two centuries. The pace of this evolution was accelerated in the recent years due to the notable progress in communication standards, advances in semiconductors as well as the advent of new design and fabrication technologies. In this first chapter, we presented a historical perspective of this evolution. We outlined the fact that technological developments, standardization efforts and spectrum allocations were the basic mechanics that allowed the early radio communications to evolve towards today's wireless and mobile systems. Then, we presented the main trends driving this evolution on the levels of market, technology and regulations. We concluded that the success of wireless and mobile devices during the last decades is fueling the emerging demands, especially in terms of QoS, cost and battery life. Next, we discussed the readiness of the wireless and mobile industry and the impact of the increasingly tougher market demands on current technologies and design tools.

In summary, this background review results in the following observations:

- Facing the emerging demands is not only bound to the evolution of technologies and fabrication processes, it is also tied to the design approaches and tools in use;
- There is a clear and increasing gap between digital and analog/RF design, especially in terms of tools and design flows;
- Even if the tools and design approaches currently used by digital designers are mature, this may be difficult to maintain in the near future because of the convergence between digital circuitry and analog/RF circuitry in the same device. Mixed-signal design tools either hardware or software are not as advanced however;
- It becomes obvious that RF and microwave domains are lacking effective design approaches and tools that are required to keep pace with market demands.

Most actors in both industry and academia focus on technological issues in their attempt to meet the requirements of the next-generation wireless and mobile devices. Many efforts are deployed to enhance power amplifiers efficiency, to broaden antenna bandwidth and reduce nonlinearities, etc. The emphasis is mostly set on “what to do” but little interest is dedicated to

“how to do”. This first chapter highlighted the importance of radio design issues as well as the need to address them along with emerging technology issues. The second chapter will look closer and deeper at design methodologies and tools. The main purpose is to establish a comparative study of the various design domains and summarize the pros and cons pertaining to design practice within each of them.

Table 1.1 Strengths and weaknesses in digital, analog/mixed-signal and RF/microwave design

Challenges	Strengths and Weaknesses			
	Digital	Analog/Mixed-Signal	RF/Microwave	
<b>Market:</b> <ul style="list-style-type: none"> <li>▪ Cost pressure</li> <li>▪ Market shift</li> </ul>	+	Relatively reduced time-to-market due to fast and robust design processes Large-scale manufacturing Generic solutions (i.e., software-based processing)	Acceptable level of abstraction (algorithmic, macro, circuit) + behavioral models IP reuse for some components (LNA, VCO, ...) EDA tools integration + standard data interfaces	
	-		Abstraction should be pushed further Design tools and flows do not allow fast design process Multiple costly iterations are required	Design tools and flows do not allow fast design processes (time-consuming and risky) System-level design tools are limited
<b>Regulatory:</b> <ul style="list-style-type: none"> <li>▪ Spectrum management</li> <li>▪ Standardization effort</li> </ul>	+	Standard operation is mostly ensured using software	Relatively mature RFIC technology for FEM development	New standards are emerging Better spectrum management techniques
	-	Advanced techniques for baseband signal processing are required Regulatory policies should become market-oriented rather than service-oriented (elaborated from administrative standpoint) Inter-organization cooperation is required for interoperability and convergence		More complex RF front-ends
<b>Core technology:</b> <ul style="list-style-type: none"> <li>▪ Hardware performance</li> <li>▪ Power management</li> <li>▪ Applications and services</li> </ul>	+	Mature design tools Fabrication processes is continuously shrinking critical dimensions More functionalities are integrated Supply voltage is decreasing Mature design methodologies and tools	New integration technologies RFICs are increasingly offering customizable solutions	New radio technologies (e.g., software-defined radio, cognitive radio, MIMO, GaN, MEMS) New substrates and fabrication materials (i.e. mechanically flexible and low-power operation) Availability of mature EM simulation tools New integration technologies (e.g., SoC, MCM, SiP, die-on-board)
	-	Chips are externally clocked which limits their effective speed Mixed-signal co-design Packaging Parasitics	Mixed-signal co-design Design verification (i.e., physical, functional) Miniaturization and integration Tools specialization	Devices characterization and modeling (i.e., accuracy, predictability, ...) Components miniaturization System integration Non-linearity and harmonics

Challenges		Strengths and Weaknesses		
		Digital	Analog/Mixed-Signal	RF/Microwave
		Some solutions are energy-hungry		Mix of fabrication technologies Each communication standard requires a dedicated front-end module
<i>Network:</i> <ul style="list-style-type: none"> <li>▪ <i>Radio access</i></li> <li>▪ <i>Convergence and virtualization</i></li> <li>▪ <i>Capacity</i></li> </ul>	+	Integration of analog circuitry in digital chips Standard IPs		New radio technologies for over-the-top services (e.g., last-mile wireless technologies such as FSO) Emerging interoperable technologies (e.g., Generic access network such as Unlicensed Mobile Access, UMA)
	-	Verification of mixed circuitry Cross-layer design issues Complexity of end-to-end solutions Some solutions are energy-hungry		Each wireless network requires one or many dedicated front-end modules
	Multi-site network governance and management			
<i>Quality of Service (QoS):</i> <ul style="list-style-type: none"> <li>▪ <i>User experience</i></li> <li>▪ <i>Security</i></li> </ul>	+	Performance is increasing not only due to Moore's law but also thanks to hardware parallelism and pipelining IPs for critical missions are available Software correction of analog and RF impairments		Better power amplifier efficiency Diversity support Better spectral efficiency
	-	Security is mostly software-dependent Generic solutions may not suit for high-performance applications	Resistance to radio environment impairments	Resistance to radio environment impairments

Table 1.2 Strengths and weaknesses in digital, analog/mixed-signal and RF/microwave design (Table 1.1 cont'd)



## CHAPTER 2

### COMPARATIVE STUDY OF COMMON DESIGN APPROACHES

#### 2.1 Introduction

The growing success of wireless and mobile services resulted in the emergence of various radio design challenges. To address them, new implementation and manufacturing technologies are being developed. However, little interest is dedicated to how these technologies are put together. Most designers focus more on technology solutions (i.e., “what-to-do”) rather than which approaches and tools may be used to assemble these technologies (i.e., “how-to-do”) in an optimal timeframe. This is particularly true in analog/RF design.

As discussed in the previous chapter, this tendency resulted in an increasing gap between digital and analog/RF design practices. Added to the emerging need for relevant mixed-design tools and approaches, the evolution of radio design depends henceforth not only on technologies but also on available design frameworks. Consequently, the improvement of design methodologies and tools becomes as important as the enhancement of implementation technologies for future radio design.

The third chapter of this thesis presents a proposal of a new design framework for RF/microwave circuits. Before doing so, we look closer and deeper at current design approaches in the different domains related to radio design. Due to the relatively limited literature documenting design methodologies particularly in RF/microwave domain, this review aims to establish a strong understanding of design frameworks in use in the different design domains. It also aims to elaborate a comparative study of these design approaches. The goal is to identify and retain the best design practices as well as to identify their major shortcomings.

We start this chapter by highlighting the traditional design approaches and the future requirements in terms of design tools. Then, we review the design practice in digital,

analog/mixed-signal and RF/microwave domains. Finally, we present a comparative study of their strength and weakness going forward.

## **2.2 Common Design Approaches and Future Requirements in Design Tools**

Throughout the design process of a radio system, various digital, analog and RF/microwave blocks are individually designed and tested. Depending on the available tools and the fabrication technologies in use, designers may use diverse approaches to implement each radio subsystem. Every approach is characterized by a given design flow. A design flow is a combination of steps and tasks through which the radio system goes at each design stages (e.g., specifications, analysis, synthesis, validation, performance simulation, implementation, verification and test, etc.). This design flow also determines the sequence in which these steps are carried out as well as the design tools used in each stage. We present, in the following, an overview of the common design approaches. We also highlight the tools requirements related to future design practice.

### **2.2.1 Common Design Approches**

Traditionally, there are two prevalent design approaches: bottom-up and top-down design methodologies. Other approaches were also derived from one or both of them (e.g., performance/constraint-driven design).

#### **a) Bottom-up design flow**

The bottom-up design flow starts with the design of individual blocks that are assembled to form a more complex block. These blocks are gradually combined to form the final system. In practice, each individual block is implemented all the way to the lowest available abstraction level (e.g., transistor-level in analog ICs) according to a set of specifications. Next, the block is tested and verified separately. Finally, all blocks are gathered, assembled and verified together. The entire system ends up generally with the lowest abstraction level representation (Kundert, 2006). The bottom-up design flow is effective for small designs. However, as design size increases, some integration and performance problems also appear (Kundert et Chang, 2005):

- After assembly, verification process is hard because simulations are time-consuming. Errors found at system assembly are too difficult and expensive to fix. This situation may cause delays in the project and requires several prototyping spins;
- Errors in communication between different designers may be critical once the system is assembled;
- Expensive steps such as the system-level verification and test are performed serially. This is coupled to a poor communication strategy between designers increases significantly the design cost and time.

#### **b) Top-down design flow**

The top-down design flow starts with the whole system concept and then recursively breaks it down into smaller pieces, easy to implement, test and validate. The design level at which this approach starts is referred to as the system level (Frevert et al., 2006). At top-level, the architecture is defined as a block diagram that is refined and optimized to meet the specifications. The specifications of the underlying blocks are then derived from system-level architecture simulation. Once all blocks and sub-blocks are individually designed and verified, the overall system is assembled and verified against the original requirements.

This said; top-down design emerged to address the issue of performance degradation caused by bottom-up design flows. It allows an architectural exploration step that figures out most potential system solutions. However, it does not include efficient verification schemes. This issue may stretch the design time and increase its cost due to unwanted but mandatory multiple iterations. Furthermore, while top-down design enhances productivity by easing team work and communication from upper to lower levels, this design approach may add discontinuities in the design flow leading to blocks implementations that are incompatible with the system-level architecture (Kundert et Chang, 2005). To address these issues, various changes were proposed to improve the design approach. For instance, (Kundert, 2006) proposed a top-down design and verification flow that systematically proceeds from the highest level (e.g., system-level architecture) to the lowest-level (e.g., transistor-level representation) to a full verification of each design level before moving upward or downward. This aims to reduce any design flaws

or incompatibilities and to improve the communication between designers, particularly those located at different sites.

### c) Comparison between bottom-up and top-down design flows

The bottom-up design methodology is mostly adopted by analog and RF/microwave designers because they still start their design at the circuit level. On the contrary, the top-down design approach is frequently adopted by digital designers because it is a hierarchical methodology based on the “*divide and conquer*” concept. Each of the design approaches has its own advantages and limitations. The main advantage of the bottom-up design approach is accuracy of device characterization while its major shortcoming is complexity management. Similarly, the top-down design approach is characterized by the effectiveness of design space exploration while it generally suffers from verification process efficiency. Table 2.1 presents a comparison between the two design approaches.

To take advantage of the strengths of both approaches, various mixes were proposed. For example, (Frevert et al., 2006) proposed a hybrid design flow commonly known as the “V” diagram, which combines a top-down design flow with a bottom-up verification process. The top-down flow proceeds with the design from the system-level through the transistor-level while the bottom-up verification process starts at the layout level and proceeds up to the highest levels.

For performance-critical applications, the performance-driven design<sup>22</sup> was proposed (Gielen et Rutenbar, 2000). This approach consists of the alternation of a top-down flow, used in design, and a bottom-up flow, used in verification at all design stages. At each level, the system is subdivided into sub-blocks to be implemented (i.e., topology selection). These sub-blocks are sized, optimized and verified against the performance specifications (i.e., specification translation). Once the sub-blocks are assembled at the same level, the new assembly is verified (i.e., layout generation and extraction). This approach ensures that the designed sub-blocks meet always the performance constraints before going further in the design flow.

---

<sup>22</sup> It is also called constraint-driven design approach.

Table 2.1 Comparison between bottom-up and top-down design approaches

<b>Criteria</b>	<b>Bottom-up design</b>	<b>Top-down design</b>
<i>Design complexity</i>	small to average designs	relatively complex designs
<i>System-level verification</i>	at the end of design cycle	at the beginning of the design cycle
<i>Design team size</i>	small to average	large
<i>Design verification</i>	effective (at the circuit / layout level)	poor
<i>Design space exploration</i>	limited	satisfactory
<i>Cost of error / fault fix</i>	high (i.e. time and money)	depends on the design level
<i>Major causes for design re-spins</i>	<ul style="list-style-type: none"> <li>– System-level verification</li> <li>– Design changes (due to unreliable communications)</li> <li>– Discontinuities in the design level</li> </ul>	<ul style="list-style-type: none"> <li>– Major design changes</li> </ul>
<i>Tolerance to design changes</i>	limited	average to satisfactory (depending on the design level)
<i>Communications between design teams</i>	poor	good (better than in bottom-up design methodology)
<i>Device model accuracy</i>	good (based on actual circuit characterization)	limited

### 2.2.2 Future Requirements in Design Tools

Design approaches require the use of design tools in order to help designers achieve most design tasks. Software design tools have appeared at the early 1960s. At the beginning, they were rudimentary. However, the advances in software development and computer processing capabilities had a significant impact on the progress of design tools. Gradually, a distinct discipline, namely Electronic Design Automation (EDA), has emerged. Today, software tools are essential to all designers. Added to test and measurement instruments, these tools compose a tool chain that is necessary for a productive and effective design cycle (see APPENDIX I, p. 433 to learn more about EDA role in modern design).

However despite the remarkable advances in EDA tools (see Figure 2.1 for an overview of EDA history), there is still a need for further improvements<sup>23</sup> particularly in analog/mixed-

---

<sup>23</sup> See section 1.4 for more highlights about challenges to address in terms of design tools.

signal and RF/microwave design tools. The emerging challenges in radio design require a robust and highly productive design tool chain. Accordingly, (Sangiovanni-Vincentelli, 2003) estimates that future EDA tools should:

- Support design representations with rigorous semantics,
- Be able to tackle complex designs where various trade-offs should be considered,
- Concentrate multi-discipline engineering skills (e.g., microelectronic, RF, mechanical, micro-electromechanical, environmental, etc.),
- Allow efficient collaboration between different design teams,
- Include more robust automated design validation/verification methods,
- Provide a central database that can handle design and manufacturing data throughout the design cycle, and
- Provide more clear abstraction levels with flawless distinction between them (e.g. each layer has its critical parameters) and define an efficient way to move from a layer to another.

In summary, each design domain has its own needs in terms of tool requirements. Tools used by digital designers are more mature than those used by their analog/RF counterparts. If digital design tools should keep the same pace with the advances in technology, tools used in analog, mixed-signal and RF/microwave design are expected to live major changes in order to be able to alleviate various issues (e.g., design complexity, technology insertion, design automation, etc.).

### **2.3 Lessons to be learned from Current Design Practice**

The radio design involves the implementation, fabrication and testing of different blocks. Some of them are digital (e.g., baseband processors), others are analog (e.g., signal converters) and the remaining are RF/microwave (e.g., signal amplifiers). Most of these blocks are implemented and verified separately before being integrated and tested in the phase of final radio assembly. Different design approaches and tools are used to design and manufacture each of these blocks. This reflects the differences between design practices in each design domains. With the increasing need for smaller form factors along with more integrated functionalities,

there is a tendency to embed digital circuitry in analog and RF chips and vice-versa. This mix of technologies and domains has been influencing the way these radios are designed.

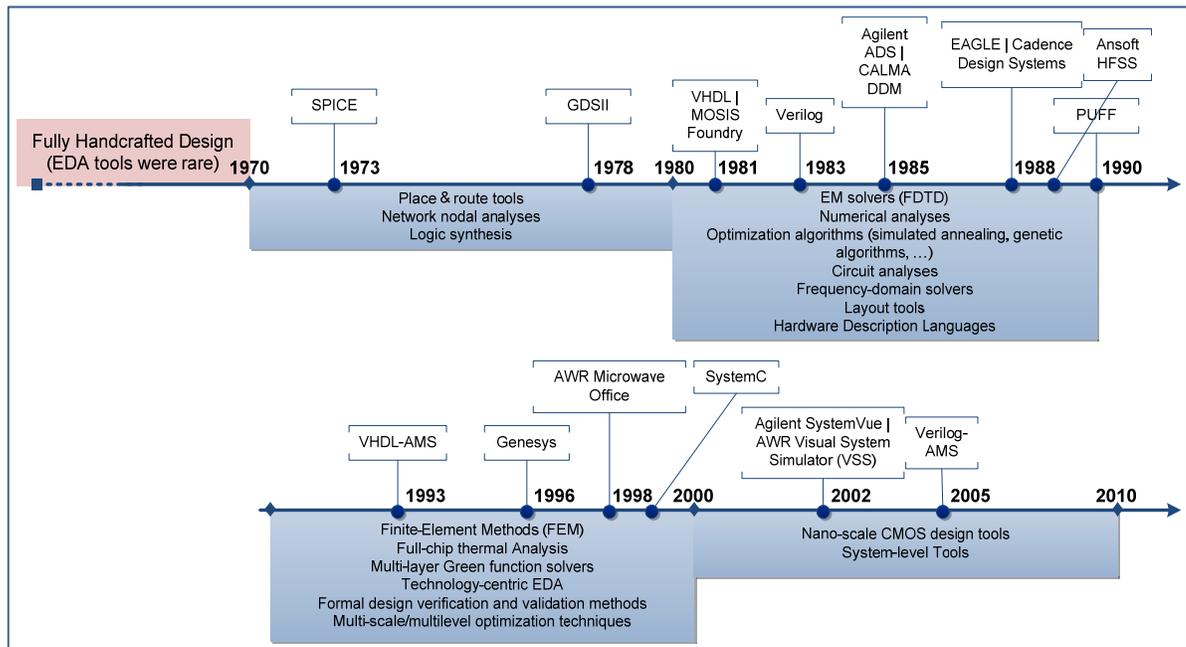


Figure 2.1 An overview of EDA history

In this section, we are interested in the current design practice in each design domain. First, we present common design philosophies in digital, analog/mixed-signal and RF/microwave domains. The specificities of RF/microwave design will be particularly highlighted. Then, we make a comparative study between design practices in these design domains.

### 2.3.1 Digital Design

Digital circuits are nowadays prevalent in wireless and mobile radios. In addition to baseband processing, user applications and the devices' operating system use digital circuitry to run. In the early days of digital design, circuits were primitive and handcrafted. Nowadays, digital circuits are among the most complex chips in wireless and mobile devices. Even if recent

studies (e.g., (Chien et Karamcheti, 2013)) claim that the Moore's law<sup>24</sup> is reaching its limit, it is expected that digital chips complexity will continue to rise in the next few years. Besides, digital designers can leverage growing complexity thanks to the hierarchical design approach they use and tool's support of high abstraction levels.

A typical digital design flow consists of various design stages that start with specifications and end with the packaged chip. The nomenclature of each step and the tasks to be undertaken in each of them may vary in the industry due to different factors (e.g., tool vendors, involved technologies, etc.). Hereafter, we present the common design stages (see Figure 2.2) to give a global perspective of the top-down design approach used in digital design (Sherwani, 2012):

1. **System Specification:** the design process of a digital device/system starts with the elaboration of its specifications. It represents the design entry. It gathers the requirements and constraints that should be met by the final product. Specifications often include performance indicators (e.g., speed), functionality details, and SWaP requirements. Technology considerations (e.g., fabrication, design techniques) may be also defined in specifications;
2. **Functional/Architectural Design:** depending on the system's complexity, this step may be subdivided into two consecutive design stages: architectural and functional. In the first one, the basic architecture of the system is defined along with the corresponding specifications (e.g., performance, SWaP, etc.). The resulting architecture presents the subsystems' blocks and how they are interconnected and/or meant to interact. The purpose of the functional design is to identify the system's functional units. Individual blocks specifications and their interconnections to its environment are also defined. In both designs, a special attention is given to the system's behavioral aspects (in terms of architecture, inputs, outputs and timing related to each unit). Behavioral models are used to provide a full description of the system without specifying the internal structure of each unit or its implementation

---

<sup>24</sup> Moore's law is an empirical observation stated by Gordon E. Moore (Intel co-founder) in 1965 and expects the number of transistors on integrated circuits to double approximately every 12 months. Moore, Gordon E. 2006. « Cramming more components onto integrated circuits, Reprinted from Electronics, volume 38, number 8, April 19, 1965, pp. 114 ». *IEEE Solid-State Circuits Newsletter*, vol. 3, n° 20, p. 33-35. This observation was later extended to other devices (e.g., memory).

- technology. These models allow an early estimation of the system's performance and the detection of any structural/functional defects;
3. **Logic Design:** In this step, the internal structure and operation of each functional unit is derived and tested. For example, the control flow, arithmetic and logic operations are particularly verified. Hardware description languages (HDL) are commonly used to provide a thorough description of each unit using Boolean expressions and relevant timing information. The logic is simulated and verified to avoid design errors and ensure its conformity to the functional design. Boolean optimizations can take place in order to achieve smaller design. High-level synthesis tools may be used to automatically derive design logic directly from behavioral models (i.e., functional/architectural levels);
  4. **Circuit Design:** In this step, logic gates and Boolean expressions are converted into circuits. Electrical components are carefully selected to meet performance and SWaP requirements. Intensive circuit simulation is used to validate the timing response of circuits and ensure the correctness of the design. The output of this step is a detailed diagram including all the electrical elements (e.g., cells, transistors, lumped components, etc.) and the way they are interconnected (i.e., netlist). Some EDA tools provide the capability of automatically generating a circuit-level representation (including the schematic and the netlist) from the logic description. This is commonly called logic synthesis;
  5. **Physical Design:** the physical layout is generated from the circuit design in this step. The netlist and the circuit components are converted into geometric shapes and represented according to the process design rules. The geometric patterns express how exactly elements should be physically implemented and interconnected. Fabrication materials and layers are commonly color-coded. In physical design, designers focus particularly on how to place the different functional blocks while minimizing the physical area (i.e., floorplanning). They should take into account how these blocks should be interconnected without violating design rules neither degrading the overall performance (i.e., place and route). Once these tasks are accomplished, an operation called "*Layout versus Schematic*" (LVS) begins. It consists of extracting a new schematic from the implemented layout and comparing it to the original one to ensure design correctness. This operation takes place jointly with another one, namely "*Design Rule Check*" (DCR), which checks whether the physical

layout meets the process design guidelines (e.g., maximum allowed spacing between objects, etc.). Physical design is a very complex and labor-intensive stage. It encompasses various validation and verification tasks to ensure that the layout is correct. Some EDA tools enable either automated or semi-automated generation of the layout directly from logic (i.e., Layout synthesis). The productivity gain from automation is generally acquired at the price of some penalties (e.g., additional silicon area and performance degradation). Thus, performance and area-sensitive designs are mostly manually optimized to address the automatic layout synthesis limitations;

6. Fabrication: after layout optimization and verification, the design is exported as a data file (e.g., Gerber<sup>25</sup>, GDSII<sup>26</sup>, etc.) and used to generate a photolithographic mask for each physical layer of the chip. These masks are used during the fabrication process to identify which materials should be deposited on the wafer and what areas should be etched. The fabrication process requires sophisticated tools and skills to produce defect-void chips. Before launching large-scale chip production, some prototypes are manufactured and carefully tested;
7. Packaging: the design is manufactured on a wafer of several chips. The chips are then separated and tested to ensure that they meet the initial specifications. Finally, chips intended to be used on PCBs are packaged using various mounting technologies (e.g., Pin Grid Array (PGA) and Ball Grid Array (BGA)). However, those used in multi-chip modules (MCMs) are not packaged.

---

<sup>25</sup> Gerber is an open file format used as a de facto industry standard for the description and exchange of PCB structures.

<sup>26</sup> GDSII (short of Graphic Design System II) is a database file format used to exchange integrated circuits artworks.

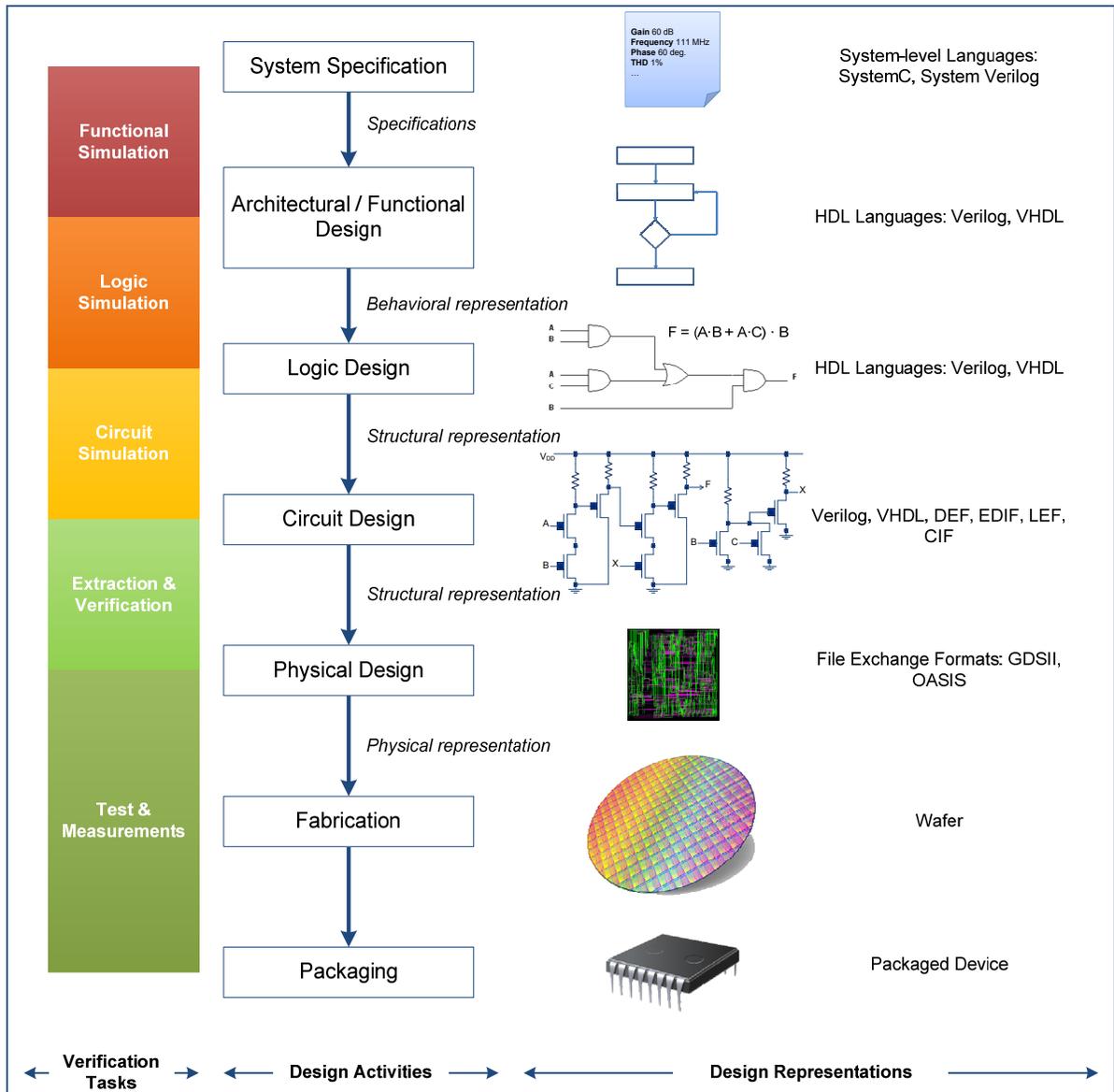


Figure 2.2 Typical design flow for digital circuits  
Adapted from Balkir, Dündar et Ögrenci (2003); Sherwani (2002)

Three prevalent techniques are often used in digital design. The first is called programmable logic. It is based on pre-fabricated matrices of transistors, metallization connections and routing wires. The designer implements functional blocks that are automatically synthesized into transistor-level circuits. Then, these circuits are physically implemented by anti-fuse and switching operations. This technique is relatively inexpensive and timesaving but provides less flexibility in terms of design optimization (i.e., speed, area, power consumption). The second

technique is called full-custom design. It consists of designing all the functionalities from the scratch. This results in a highly optimized performance and reduced area device but also a costly, labor-intensive and time-consuming design cycle. To accommodate moderate-requirement applications, a third technique, namely semicustom design, is used. It consists of using ready-to-use well-designed functional blocks (i.e., standard cells) and focus on building efficient interconnections between them instead of building all the functionalities from the ground up. This reduces design time and cost and provides devices with good performance (Chen, 2009a).

Digital designers have succeeded in handling increasing design complexity due to the design approach they adopted during the last decades. This approach, namely hierarchical design, is an incremental “divide and conquer” process that is amenable for automation. In this approach, a circuit is considered as a collection of modules. Each module is a collection of sub-blocks (commonly designated as cells). Each sub-block implements a given functionality that can be reused as much as required. Thus, the design effort is reduced. This design fashion is enabled by a core concept in digital design: *hardware abstraction*<sup>27</sup> (Rabaey, Chandrakasan et Nikolic, 2002). To understand how important this concept, let us go back to the circuit-level where designers deal almost exclusively with electrical models of components. It is all about a physical representation of the device. In very complex designs, one cannot manage the parameters of millions of transistors at the same time. To avoid this issue, logical blocks were created to represent collections of circuits. The functionality of each logical block is defined using Boolean equations. That is a structural representation. However, with the sustained increase of design complexity, this representation became limited. For this reason, behavioral representation was presented. It consists of a high-level description of both device’s structure and behavior. The device’s structure consists of defining the immediate composing modules (e.g., interfaces) while the behavioral description defines the interaction between them (e.g., timing, operations schedule, etc.). Hardware description languages (e.g., VHDL, Verilog) are used to carry out this high-level description (see Figure 2.2). Thus, increasing the abstraction

---

<sup>27</sup> The concept of “hardware abstraction” is developed in section 4.2 of chapter 4.

level masks the complexity of the underlying blocks without sacrificing the accuracy of their actual response.

In summary, the main advantages of this hierarchy of abstraction levels are complexity reduction, design automation and reuse (Rabaey, Chandrakasan et Nikolic, 2002). In fact, at each abstraction level, the designer deals only with the models available at that level. Given enough data about their functionality, the designer can use these models without knowing their internal structure. The characteristics of their underlying components are virtually masked. Complexity is thus reduced and mastered. Moreover, logical functionalities can be easily derived from behavioral models. Similarly, they can also be transformed easily into physical circuits (given relevant technology inputs). Then, it is possible to automate the transition between all these abstraction levels. In addition, hardware abstraction results in modular functionalities, arranged as simple as possible. They are thought to encompass fine characterization at local level and provide a regular behavior and modular structure at system level. All this enables the easy reuse of them in future designs without significant changes.

This said, digital designers face various challenges particularly in full-custom designs where a relatively considerable workforce is involved. For example, design partitioning which consists in breaking up the chip into small units that can be implemented separately by different teams is sometimes a major design management issue. If this partitioning is successful, it results in substantial time and cost reduction. Nevertheless, if it fails, this may enlarge the design process. The management of specifications and design changes especially during the latest phases of design cycle is also challenging. The exchange of design data throughout the different design stages is also important. Fortunately, the hierarchical design approach enabled the development of mature design tools that can reduce the impact of these issues. Modern tools were also developed to enhance design space exploration, automate most design tasks and enable a repetitive validation process.

### 2.3.2 Analog and Mixed-Signal Design

By opposition to their digital counterparts, analog circuits handle continuous analog signals whose frequency ranging from DC up to few hundreds of megahertz. Phase-locked loops (PLL), operational amplifiers, active filters and some radiofrequency integrated circuits (RFICs<sup>28</sup>) are examples of typical analog circuits.

Pure analog designs often use technologies where behavioral models are absent. Then, designers start at circuit level. Specifications are commonly so generic, which makes the design space exploration an important phase. Designers should make various trade-offs in order to come up with an initial solution that may be optimized later. Next, it is derived into a circuit whose topology is captured in a schematic (i.e., schematic capture). At this step, the designer interconnects elementary elements (e.g., transistors, resistors, etc.) to build up the selected topology. For each individual element in the schematic, its properties are specified (e.g., transistor width-to-length ratio). To reduce circuit complexity and make the circuit topology more understandable for teammates, designers identify a bench of components that can build individual functionalities and create a new symbol for them. This new symbol (i.e., module) is a sort of “artificial black-box” having a number of inputs and outputs and virtually hiding the underlying circuit details. This task is often repeated recursively. Nevertheless, higher levels simulators unfold these “black boxes” in order to carry out a variety of simulations.

In the following, Figure 2.3 presents some key steps of the previously mentioned design philosophy. This example depicts a bottom-up design flow using a commercial EDA framework for analog and mixed-signal design (namely Cadence<sup>29</sup>). As shown in Figure 2.3, the design starts with specifications describing the functionality and the requirements that the final product should meet (e.g., area, power, delay, etc.). Then, the designer selects an initial circuit topology that is captured in a schematic.

---

<sup>28</sup> The term “radiofrequency (RF)” in RFIC indicates that this category of circuits is used in RF applications and commonly integrated on RF boards.

<sup>29</sup> Cadence refers to a suite of EDA tools for analog and mixed-signal design that are developed and maintained by Cadence Design Systems Inc.

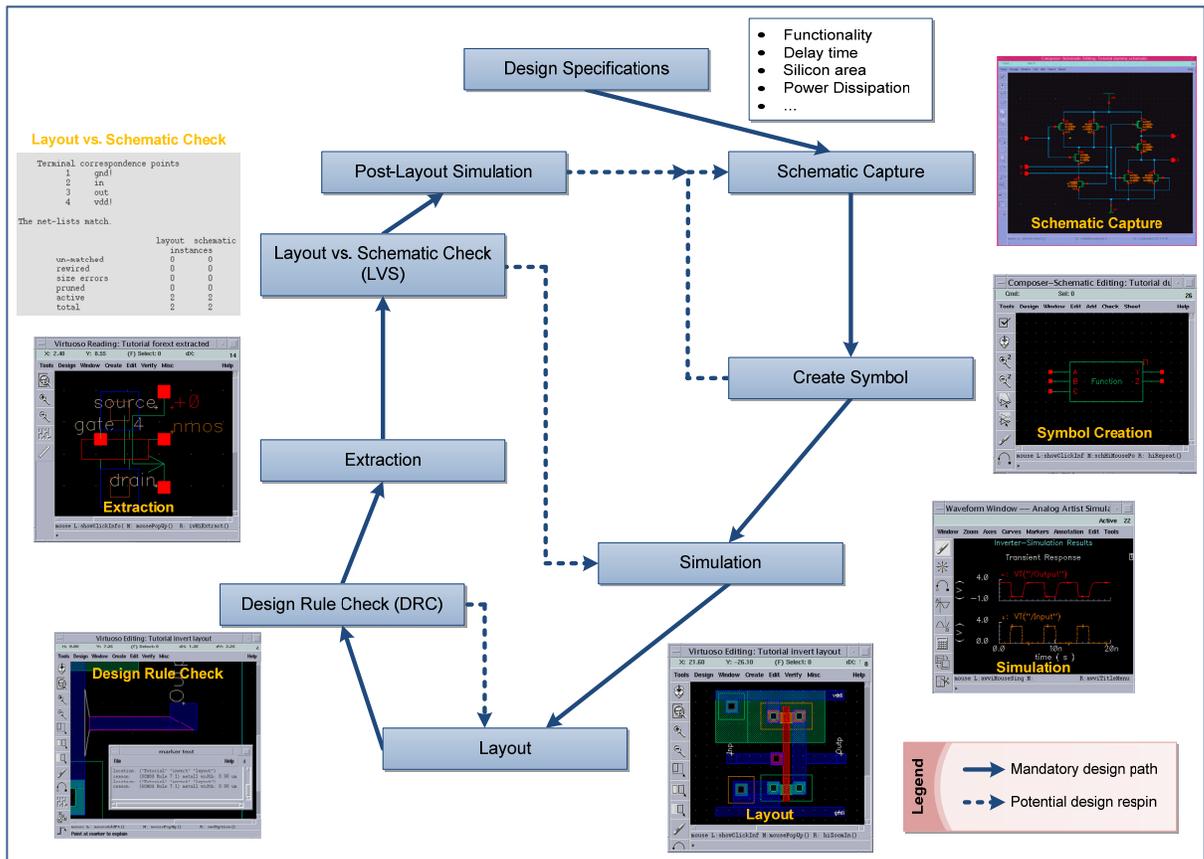


Figure 2.3 Typical analog design flow using Cadence commercial package  
Adapted from Cadence Design Tools Tutorial (2010)

Before moving forward with the design, various simulations are made at the transistor level in order to reveal any errors in schematic capture and evaluate the circuit's operation performance. If the results are not satisfactory, the designer modifies its circuit and repeats simulations until the performance gets close to the requirements. If so, most designers proceed to the circuit optimization by fine-tuning the physical properties of schematic's individual elements. Generally, this operation aims to enhance the circuit's performance, reduce its area or/and its power consumption.

The next step is the layout generation. This layout can be either generated automatically or created manually. Using the layout editor, the designer creates the geometric shapes corresponding to each circuit element. Various considerations (e.g., positioning of layers, used materials, etc.) should be taken into account in order to produce a flawless layout. At the end of this delicate process, the designer runs the "Design Rules Check" test in order to ensure that

the layout does not violate the fabrication process guidelines. Cadence reports the eventual errors to the designer who should modify the layout in order to resolve the detected issues.

Once the layout is completed, the designer uses a netlist extraction tool to obtain a realistic representation of the device that takes into account the parasitic effects and other technology considerations. Based on this netlist, the circuit simulation gives a good approximation of the final device's performance. This netlist is also used in the "Layout-versus-Schematic" test in order to check if the extracted and the original netlists are equivalent. If so, the designer is confident that the device's layout matches with the schematic. However, this is not a guarantee that the intended device's performance is met. For this reason, the last step before manufacturing is the post-layout simulation. It uses the generated layout and the extracted netlist in order to assess the real performance of the device. This assessment takes into account the parasitics and points out any critical glitches in the device.

As indicated in Figure 2.3 (see dashed lines), these steps are carried out iteratively in order to correct design errors and optimize the device's performance. The design is exported for prototype manufacturing. After fabrication, the device is tested in realistic conditions to evaluate its actual performance and whether it presents any defects.

Since the early 2000s, embedding analog circuitry in digital chips became an overwhelming tendency. According to (Cadence Design Systems, 2002), it was expected that 40% of developed wafers in 2002 were analog/mixed-signal. In 2006, (Rutenbar, 2006) states that 75% of digital chips included analog content. Joining analog and digital circuitry on the same chip has multiple advantages such as the integration of more functionality in reduced area and lower costs.

The development of mixed-signal circuits has been carried out using silicon-based technologies (e.g., BiCMOS, Bipolar, etc.) since digital and analog circuitry are integrated on the same substrate. Silicon technologies allow good scaling capabilities which enabled the use of digital-like design flows to develop embedded analog parts. Nonetheless, the difference in nature between digital and analog circuits (e.g., digital blocks are noise-immune while analog ones are very noise-sensitive) affected the abstraction hierarchy used for analog circuitry. For

example, there is no logic nor gate abstraction levels in analog design because analog circuits cannot be described using Boolean equations. Instead, these abstraction levels were replaced by a new abstraction level called macros (De Smedt et Gielen, 1999). Consequently, the hardware description languages used for behavioral modeling of analog circuits are different from digital ones. Designers use languages such as VHDL-AMS and Verilog-A. Other system-level languages are also used in industry (e.g., SystemC).

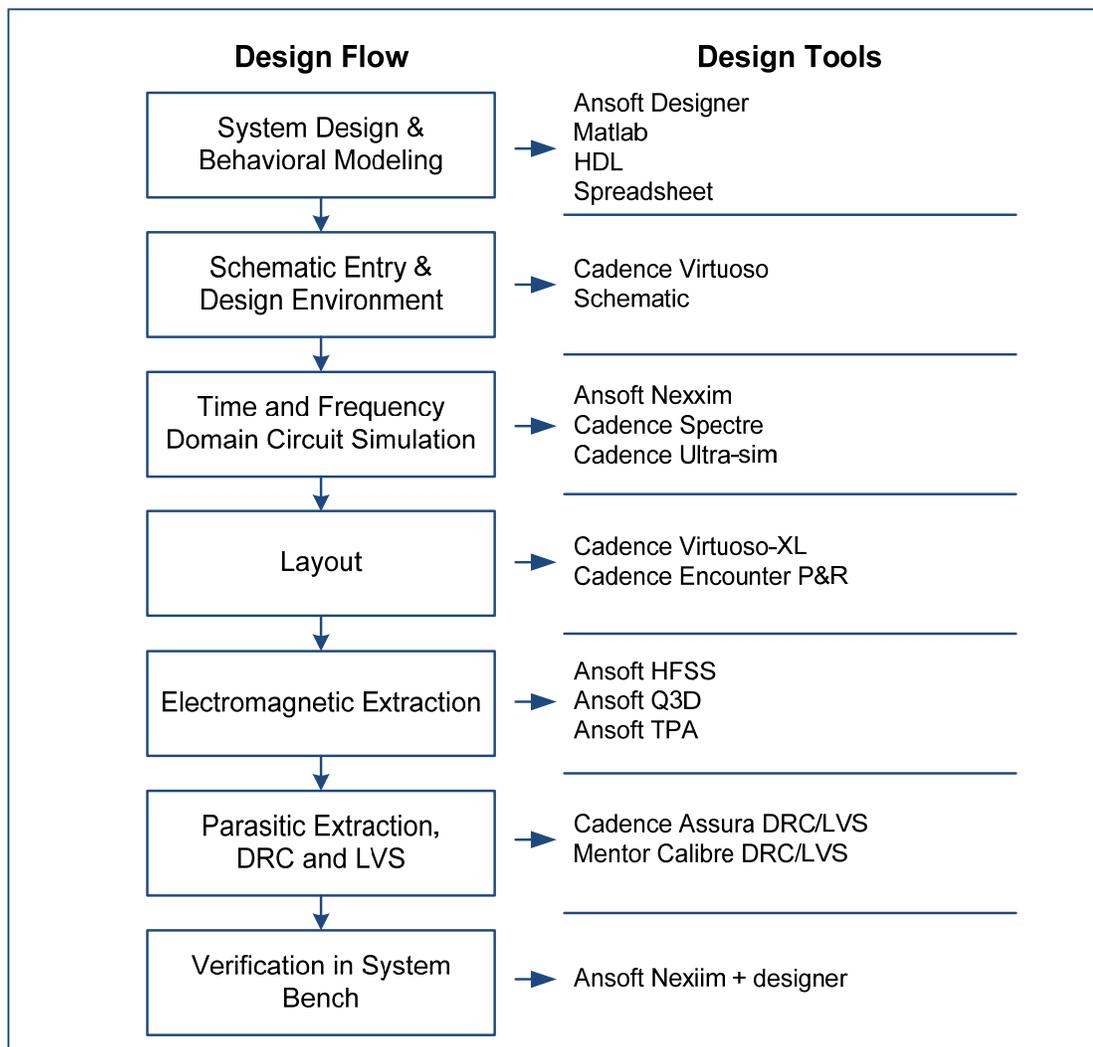


Figure 2.4 Typical analog and mixed-signal design cycle including common EDA tools in use  
Taken from Williams, Wu et Yen (2005, p. 1)

Regarding the design flow adopted for analog circuit design in mixed-signal context, it presents similarities to both traditional digital and analog design flows. As shown in Figure 2.4, a top-down hierarchical design approach starts with behavioral modeling. Once circuit topologies were derived from system-level behavioral models, the design of each circuit is similar to any pure analog device. Figure 2.4 depicts also the EDA tools commonly used in the industry for the development of analog/mixed-signal circuits.

### 2.3.3 RF and Microwave Design

Radio frequencies refer to alternating current (AC) signals whose frequencies are ranging from 30 MHz up to 300 MHz. Microwaves refer to those with frequencies ranging from 300 MHz to 300 GHz. Generally, RF/microwave engineering covers the design of radio front-ends that use radio waves whose frequencies lay in RF and microwave spectrum<sup>30</sup> (Pozar, 2012). In wireless and mobile radios, these RF front-ends make the link between the digital baseband and the immediate radio environment (e.g., base-stations, hotspots, other radios, etc.). The design of the RF front-end is a minor portion of the whole communication system design (Kevenaar et ter Maten, 1999). However, it presents significant challenges at various levels due to the specificities of RF domain. In this section, we start by reviewing the particularities of this domain that contribute in making RF front-end design challenging. Then, we present an overview of the design practice in RF domain.

#### a) Understanding the particularities of RF/microwave domain

RF/microwave engineering is characterized by the following:

- **A meeting point of a variety of experts**

RF/microwave design involves designers from different backgrounds and requires the availability of an expertise in a multitude of fields. Successful RF design is commonly the result of mastering a variety of disciplines (Razavi, 1997; Thompson, 2010). That is mainly

---

<sup>30</sup> For the purposes of text clarity and simplification, we consider in the remaining text only radiofrequencies. However, what applies to the latter in terms of design approaches applies also to microwaves.

bound to acquiring good knowledge and skills in radio environment analysis (e.g., signal propagation), basic communication theory (e.g., signal processing, microwave theory, etc.), design approaches and flows as well as standards and regulations. Figure 2.5 summarizes the different disciplines that directly influence modern RF design.

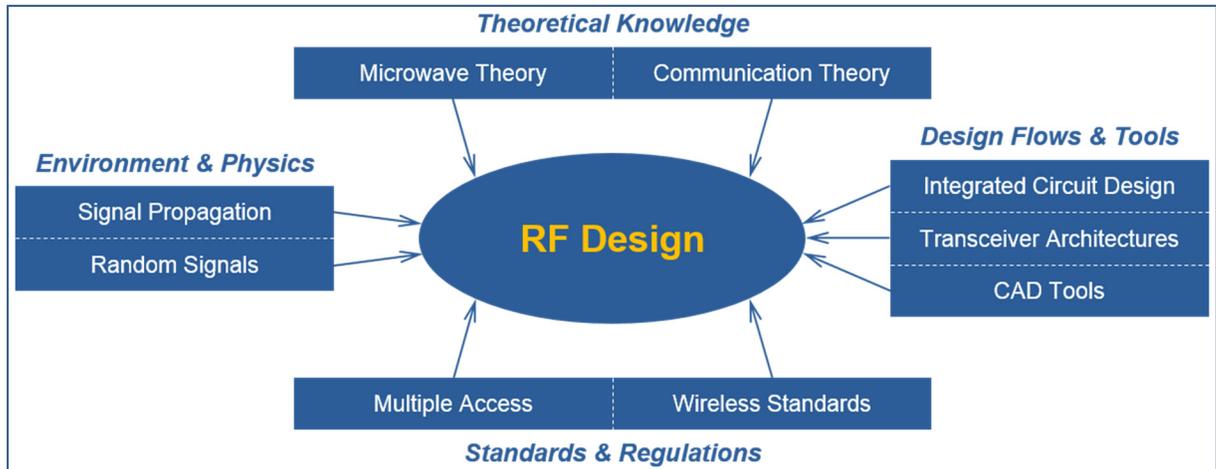


Figure 2.5 Main disciplines related to RF design  
Adapted from Pozar (2012)

- **A field where a single technology can rarely be used alone**

Various RF devices are required to build a working front-end. Components vary depending on the selected architecture<sup>31</sup>. Figure 2.6 shows a typical direct-conversion transceiver block diagram. In this traditional architecture, lowpass and bandpass filters are used to remove unwanted signals. Most filters are passive devices that do not need any DC input to operate. Nevertheless, for performance considerations, most filters used in today's transceivers are Bulk Acoustic Wave (BAW) and Surface Acoustic Wave (SAW) devices. Nevertheless, these devices cannot be integrated in the RF front-end. Oscillators, mixers and amplifiers are solid-state devices that are implemented using a myriad of III-V semiconductors with different physical properties. If modern switches and ADCs/DACs can be integrated on the same

<sup>31</sup> For example, a half-duplex transceiver has an architecture that differs from a full-duplex one. For the latter, a time-division duplex transceiver uses a switch to connect to the antenna while a frequency-division duplex front-end may use a circulator to ensure the continuous connectivity of both the transmitter and the receiver to the antenna.

substrate on which the baseband circuitry is implemented, ferrite-based components (e.g., isolators, circulators) cannot. In most wireless and mobile devices, antennas are passive but cumbersome structures which are hardly integrated in the RF front-end due to their physical dimensions (Robertson et Lucyszyn, 2009; Sorrentino et Bianchi, 2010). This mix of technologies is challenging for a number of reasons (e.g., integration, heat dissipation, etc.) especially when a small form-factor is required.

- **A domain highly sensitive to impairments and nonlinearities**

By opposition to digital circuitry, RF devices are very sensitive to noise, signal distortion and inherent radio impairments. Each RF component adds an amount of noise to the signal. The cumulative value of added noise depends on the way the RF components are mounted. It reduces the transceiver's signal-to-noise ratio, which influences negatively the data rate. Signal distortion occurs due to the imperfections and the nonlinearity of RF devices. For example, a power amplifier crops a signal when its input power lies above its compression point (see Figure 2.7.a). In the presence of multiple tones, nonlinearity of active devices (e.g., mixer, amplifier) produces intermodulation products. These harmonics are unwanted signals that appear in multiple sum and difference frequencies of the original tones (see Figure 2.7.b). In transmission, these unwanted signals pollute the spectrum and interferes with other radios. In reception, some of these harmonics may interfere with desired signals. Poor isolation in transceivers as well as adjacent channel signals are common sources of strong signals that mix with local signals and cause severe inband interferers. Reducing the impact of noise and mitigating the effect of inherent radio impairments is a major challenge in RF design.

- **A discipline of compromises and trade-offs**

RF design is governed by a set of antagonistic system-level parameters. Figure 2.8 shows the "RF Design Hexagon", an assembly of six mutually-dependent variables, having a significant impact on RF design (i.e., frequency, power, DC supply voltage, gain, noise and linearity) (Razavi, 1998). The change of one of them affects the others. For example, increasing input power requires more supply voltage. Depending on frequency, it changes linearity. If linearity changes, the corresponding gain changes too. In addition, more power means increasing noise.

The designer's role is to find the best compromise between the hexagon variables that makes the design not only feasible but also meet the required specifications.

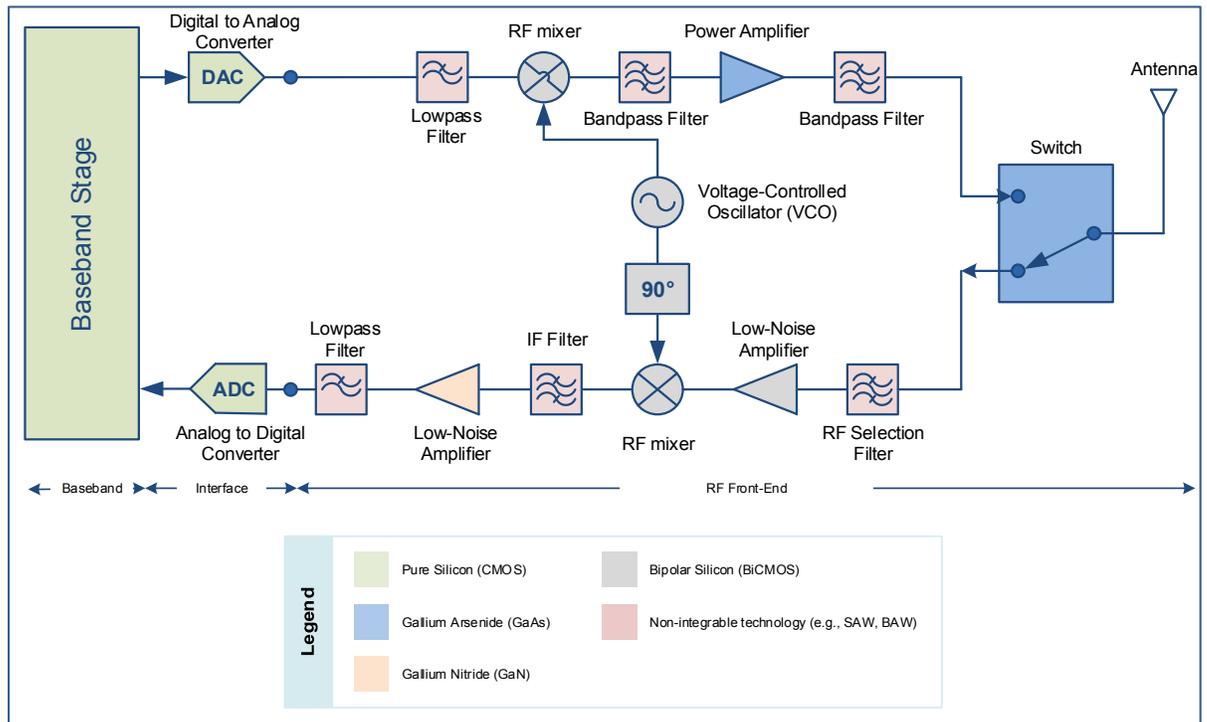


Figure 2.6 Overview of some technologies of which typical components in a direct-conversion transceiver are made

This said, the design of individual RF components, either active or passive, involves often various trade-offs. These trade-offs depend mostly on the functionality and the technology in use. The considerations to consider in a passive circuit (e.g., filter) differs from those in an active one (e.g., amplifier). For instance, a designer should pay attention to insertion loss in the former but to the gain in the latter. Even for the same device, changing the fabrication technology may change the trade-offs to consider. For example, a GaAs HEMT<sup>32</sup> amplifier can operate at very high frequencies and presents a good noise figure but it is energy-hungry and expensive. On the contrary, a GaAs HBT amplifier is cheaper and consumes less energy but is limited in frequency operation and has heat dissipation issues (Ashbaugh, 2009). For

<sup>32</sup> HEMT (short of High-Electron-Mobility Transistor) denotes a family of field-effect transistors.

illustration, Figure 2.9 shows typical trade-offs that most designers should consider in the design of some passive components.

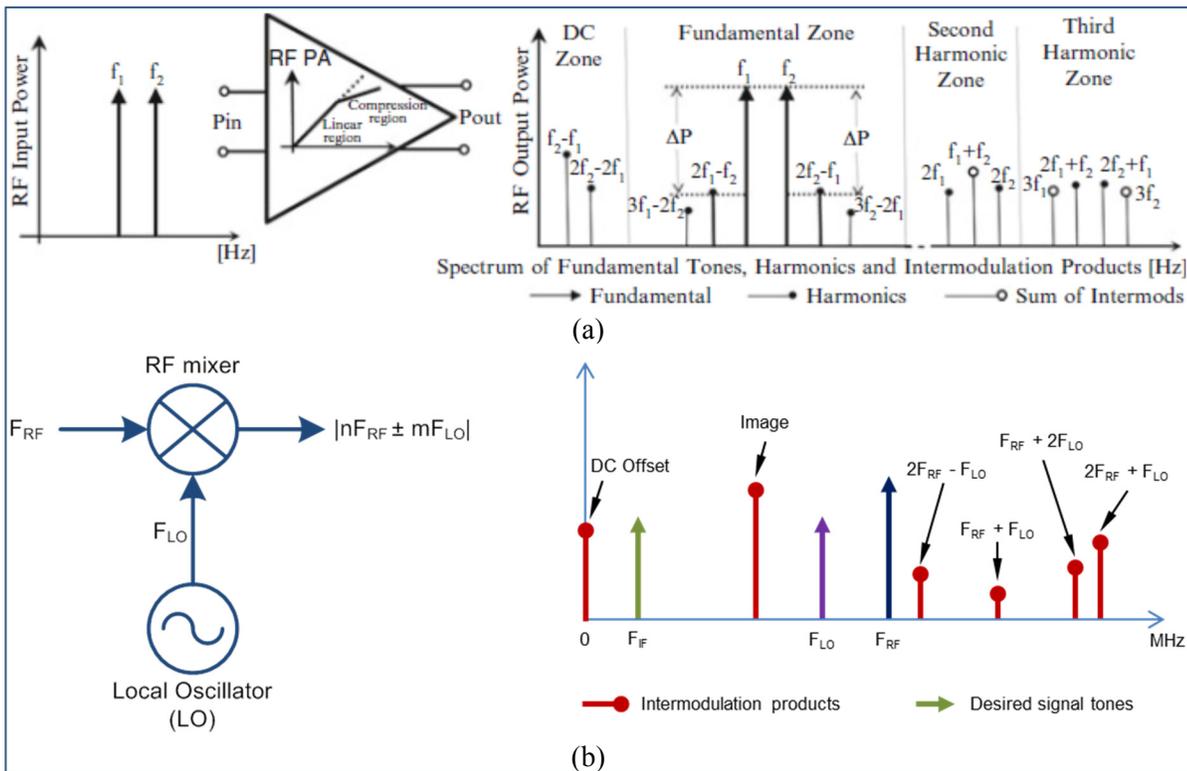


Figure 2.7 Intermodulation and nonlinearity: (a) Output power compression and intermodulation distortion in RF amplifier  
 Taken from El-Khatib, MacEachern et Mahmoud (2012)  
 (b) RF mixer spurious products

Compared to digital and analog/mixed-signal domains, RF design is subject to much more trade-offs, requires an extended expertise and combines a wide range of different technologies having, by nature, a significant impact on the performance of RF components. To overcome these challenges, designers use a myriad of EDA tools within the design approaches they adopted.

**b) Common RF design practice**

RF design is an iterative process that looks for building up a radiofrequency front-end meeting the specifications. This process follows a given design cycle. At each design step, EDA tools might be used for various purposes. In the following, we present the design space in which the

design evolves. Then, we present a typical design cycle for RF design. Finally, we present an overview of the most used EDA tools in this field.

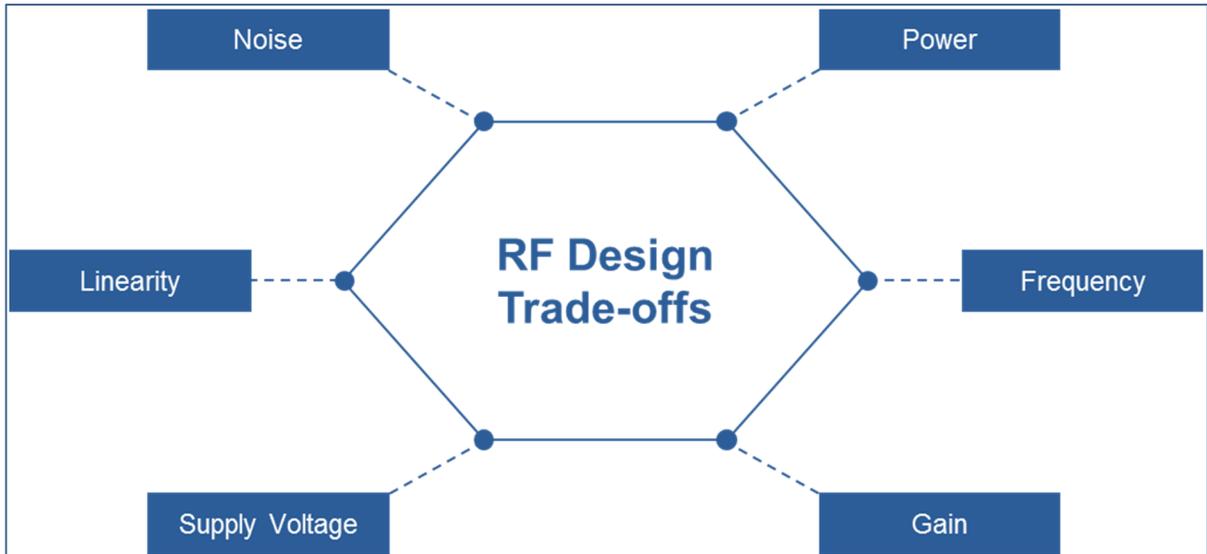


Figure 2.8 Multiple antagonistic parameters are tuned in RF design  
Taken from Razavi (1998)

- **RF design space**

The RF design space is split into four main quadrants (see Figure 2.10). Vertically, two domains can be noticed: (i) electrical, in which the RF components and/or front-ends are described by their electrical properties and (ii) physical, where they are described by their physical properties. Horizontally, there are also two levels: (i) a system-level standpoint where the components and/or front-ends are handled as systems, and (ii) a circuit-level one, more detailed, where these components and/or front-ends are described by their corresponding circuits (Spoto et al., 2006).

Given the specifications, an RF designer begins with the search of a system-level solution that meets the requirements. Some models of components can be used to evaluate the solution. For example, a conventional filter model (e.g., Butterworth, Chebyshev, Bessel, etc.) may represent an RF filter. At system-level, the candidate solution is judged regarding its “system-level” performance (e.g., noise, spurs, link budget, etc.). Once an initial solution is selected, the designer develops the circuits implementing each component. Depending on the

functionality, relevant circuit-level simulations are carried out to assess the performance of each of them. Then, these circuits are converted into physical representations (i.e. layouts). Further simulations are often required for more performance optimization. Finally, the physical structures of all components are combined into a single artwork to form an integrated system<sup>33</sup>.

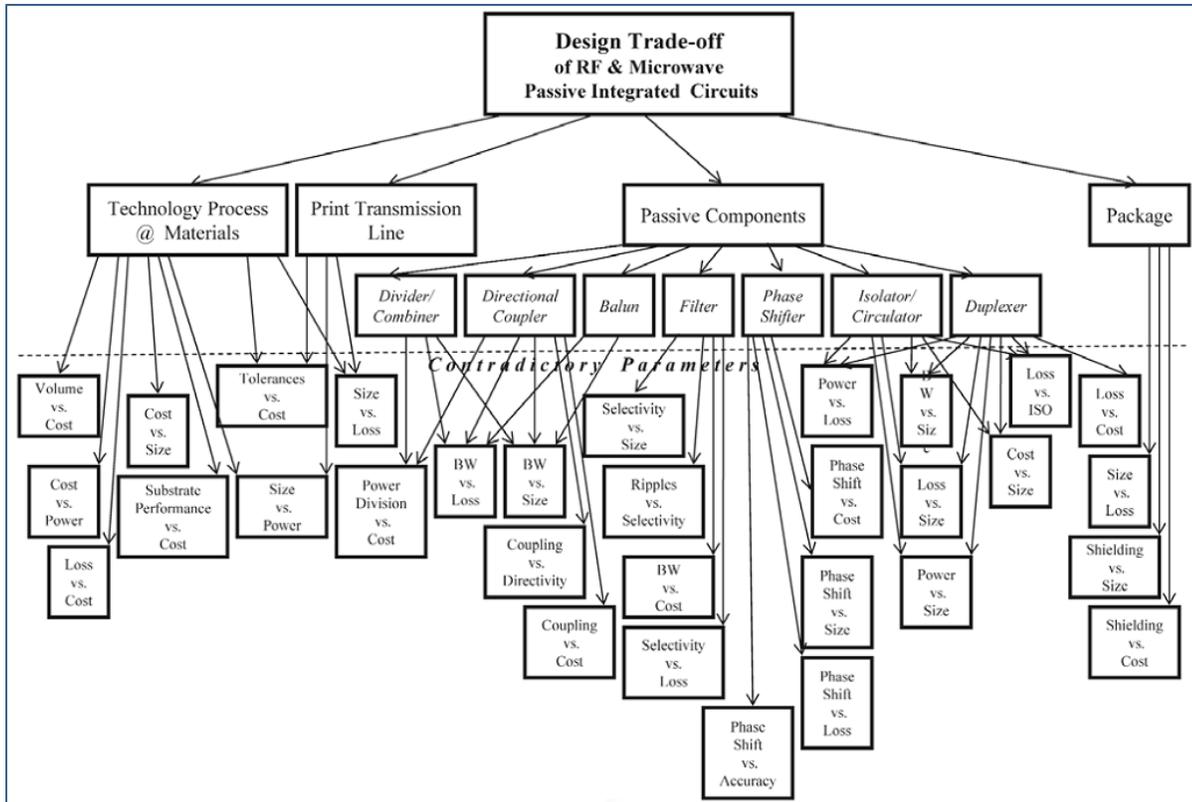


Figure 2.9 Common trade-offs encountered in RF passives design  
Taken from Maloratsky (2010)

- **Typical RF design flow**

Nowadays, there are no clear abstraction levels in RF design due to the prevalence of technology considerations. For example, the definition of “system-level” depends closely on the complexity of the RF system and the target technology. In practice, this results in several ways to design an RF front-ends and components.

<sup>33</sup> Various integration techniques are used in RF design (e.g. system-on-chip aka SoC, system-in-package aka SiP, etc.).

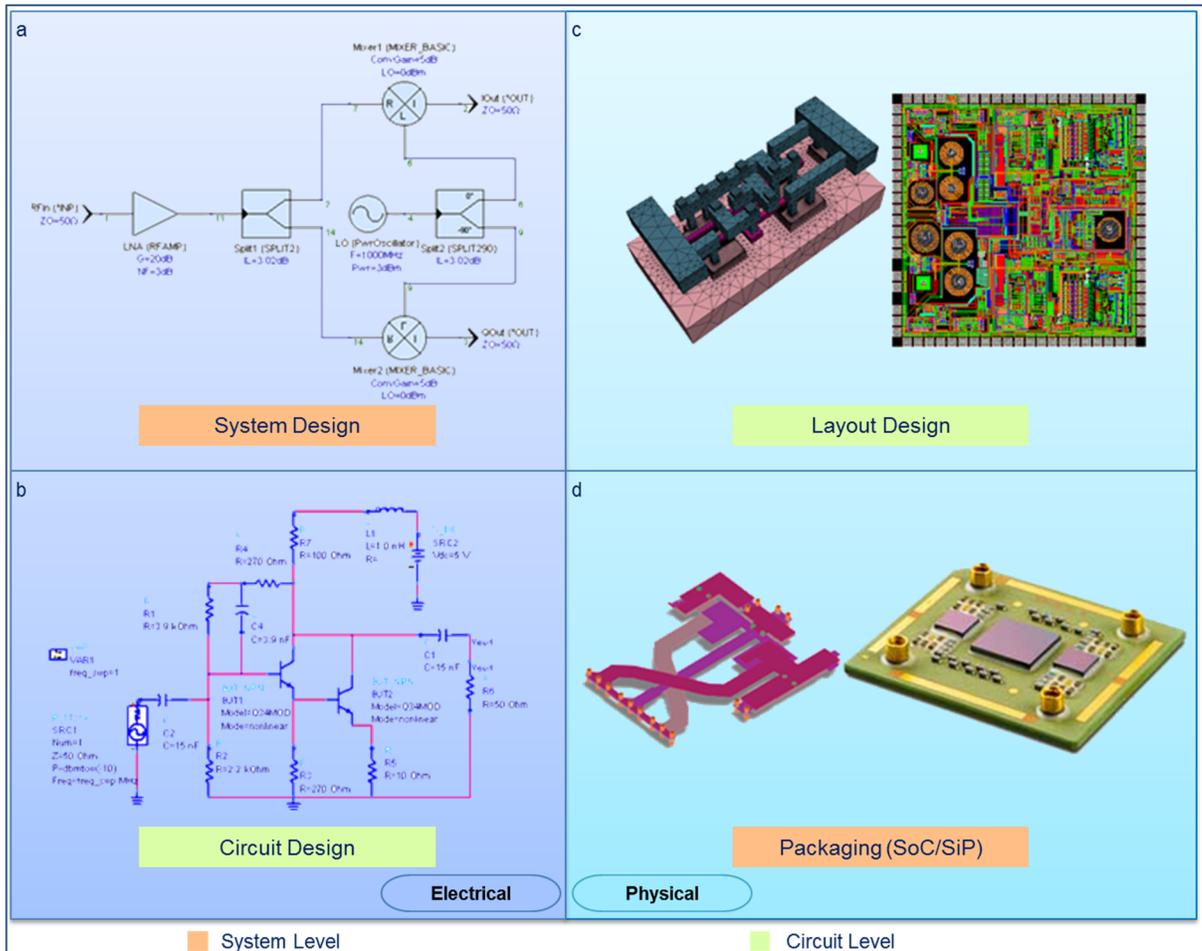


Figure 2.10 The traditional RF design space is subdivided into two domains (i.e., electrical and physical) with two corresponding representations (i.e., system and circuit)  
Adapted from Spoto et al. (2006)

Figure 2.11 shows a typical RF design scheme with common design stages presented. It consists of a mix between top-down and bottom-up design approaches. To make the design process easier, large RF front-ends (e.g., transceivers) are commonly subdivided into smaller blocks. Each block is composed by a single component or a collection of components. Different teams often implement these blocks separately. When possible, they might also be broken down into smaller pieces for more design concurrency. The specifications of each block are derived from the system-level initial solution. For example, the center frequency of an intermediate-frequency (IF) filter is not known in priori because the receiver's architecture determines how many IF filters will be used and how the frequency planning will take place. Once the specifications of each block (generally in text or spreadsheet format) are known,

every designer proceeds with the implementation of the block at the circuit level. It is worth noting that there are almost no formal methods to validate a priori this kind of specifications (Thompson, 2010). At this step, circuits are captured using a schematic capture tool. The circuits consist of the interconnection of RF components (e.g., lumped components, transmission lines, etc.). Each component is generally defined by its model that might be layout-, equation- or file-based. Various simulations are carried out in order to evaluate each component's performance. Linear and noise simulations are the basic analyses that take place to assess passive circuits performance while active devices (e.g., amplifier) require much more intensive analyses (e.g., small-signal, large-signal, harmonic balance, envelope, transient, noise, etc.). Some passive structures such as transmission lines require electromagnetic (EM) analyses known as more accurate than traditional circuit models. Simulation accuracy varies with tools and depends on the component models.

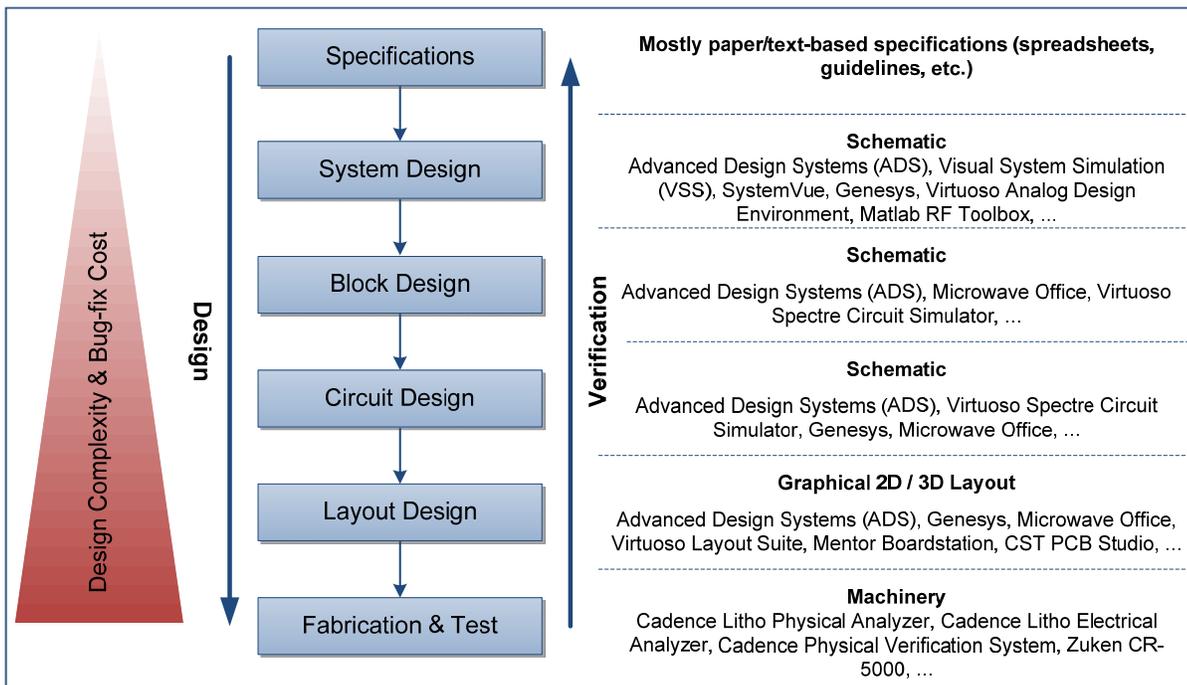


Figure 2.11 Typical RF design scheme and some EDA tools in use for each design stage  
Adapted from González, Rusu et Ismail (2007)

Then, designers use layout tools in order to create the block's corresponding layout. Generally, most optimizations and adjustments take place at this step where various simulation tools might

be used to verify the final design performance (e.g., signal reflection, gain, noise, shielding properties, radiation, etc.).

The next step consists of prototype manufacturing and testing. Sometimes final integration takes place before manufacturing. This happens commonly with passive structures where all components are combined and manufactured together. In other cases, individual components might be entirely developed and tested separately before their integration into the final solution (e.g., SAW filters). Simulated and measured performances rarely match due the inaccuracies in device modeling and simulation tools as well as the variability of fabrication processes. For this reason, most designers consider a margin to compensate any eventual degradation particularly in critical-performance applications. Furthermore, the verification process is iterative. Once an error is detected, the previous step is revisited. These re-spins are time-consuming. The cost of error correction may be prohibitively expensive particularly at advanced design stages such as final integration (Thompson, 2010).

- **EDA tools for RF design**

RF EDA tools have seen remarkable progress during the last two decades. As discussed in (Cheng et al., 2010), existent tools provide designers with valuable features such as:

- Optimization algorithms and tuning options,
- Statistical design options: yield, sensitivity, etc.,
- Support of industry standard file formats (e.g., Touchstone, P2D, GDSII, Gerber, etc.),
- 2D and 3D EM analysis technology,
- Connectivity with test and measurement platforms (e.g., vector network analyzers, waveform generators, etc.),
- Component vendor libraries,
- Wireless standards test benches and design libraries,
- Various design guides and synthesis tools (e.g., filters, oscillators),
- Support of file- and equation-based models,
- Tools for budget, spurs and intermodulation analysis.

Additionally, some design tools support scripting languages and parameterized models to automate some design tasks. Some EDA tools provide sophisticated co-simulation, co-verification and co-design capabilities. Nevertheless, there are no end-to-end tools that cover the design cycle from the specifications through manufacturing and testing (González, Rusu et Ismail, 2007). RF EDA tools suffer from serious shortcomings (see section 1.4).

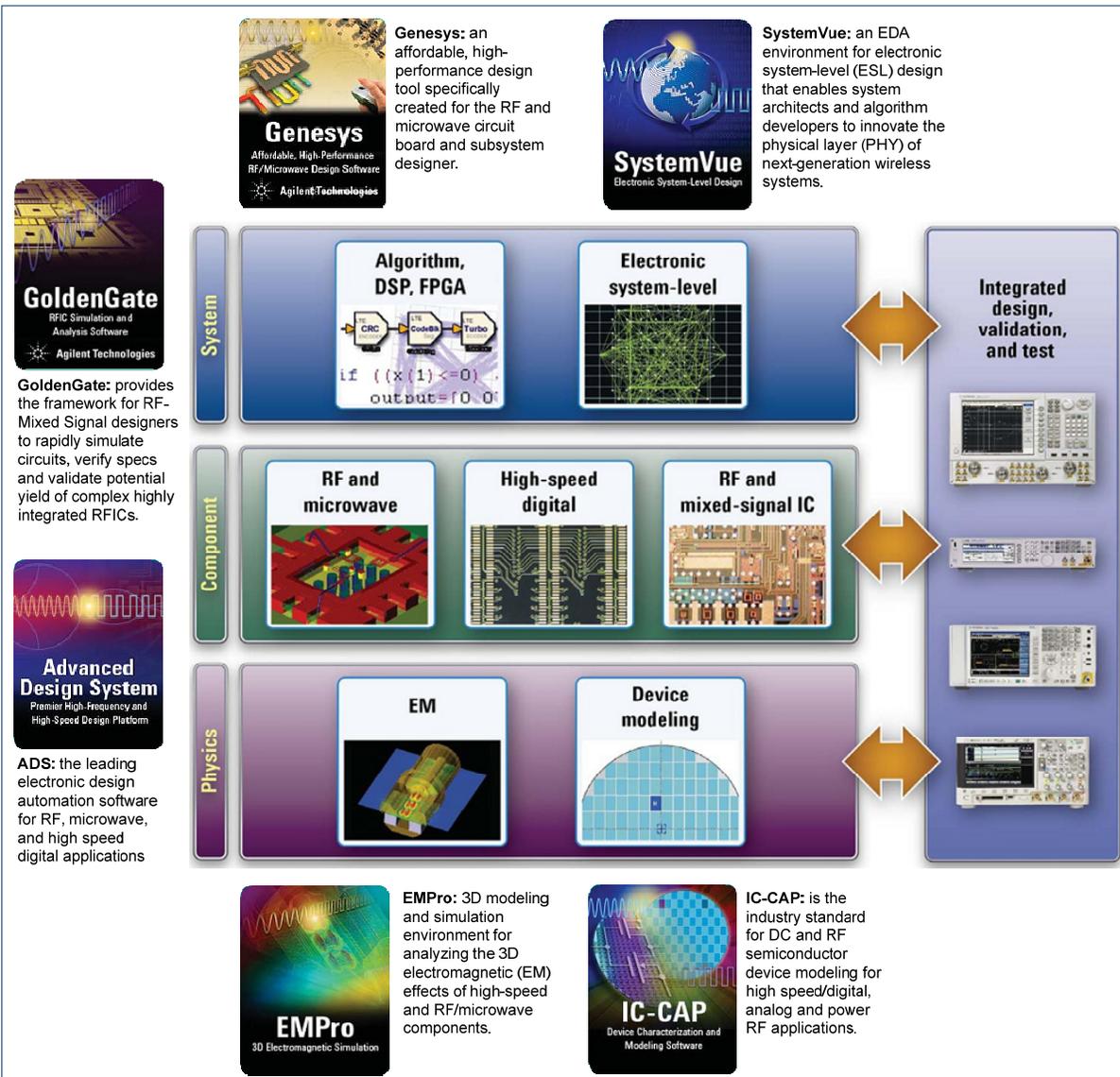


Figure 2.12 EDA tools from Agilent Technologies  
Adapted from Agilent Technologies (2013)

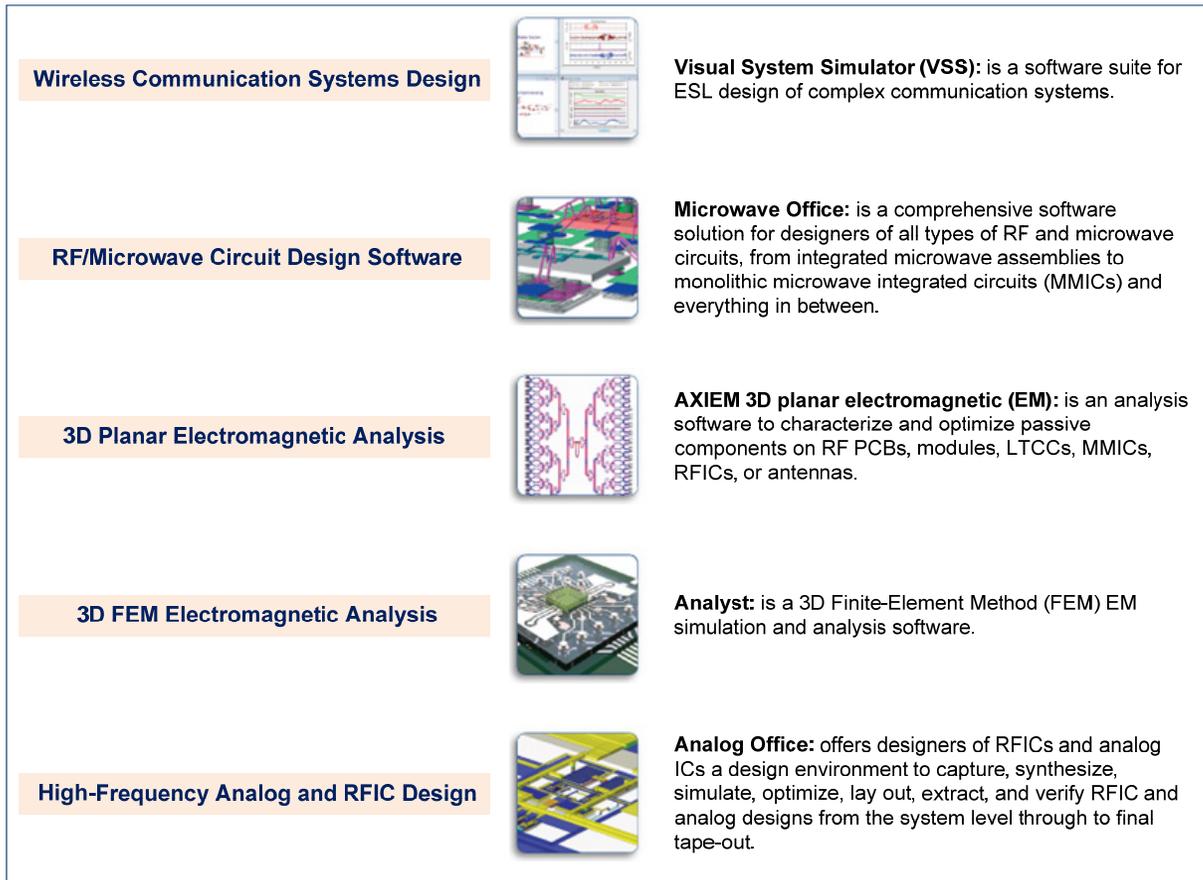


Figure 2.13 EDA tools from Applied Wave Research<sup>34</sup>  
Taken from National Instruments (2013)

Figure 2.11 shows some EDA tools currently used by RF designers at each design level. In addition, Figure 2.12 and Figure 2.13 show respectively two sets of tools developed by two key EDA tool vendors in RF domain. The first is Agilent Technologies<sup>35</sup> that holds around 65% in 2009 (Henke, 2010a; 2010b) and 68% in 2012 (Agilent Technologies, 2013) of the worldwide RF EDA marketplace. It develops EDA tools for system-, component- and device-level design. Advanced Design System (ADS) is the most famous EDA design environment of the company. It enables the design, simulation and layout generation of a wide range of RF

<sup>34</sup> AWR stands for Applied Wave Research. AWR is an American EDA tools editor and vendor. It was acquired by National Instruments (NI) in 2011. Nevertheless, most of its EDA products continue to be marketed as AWR products.

<sup>35</sup> In September 2013, Agilent Technologies had announced the creation of a new company, namely *Keysight Technologies* that will be in charge of developing Agilent's electronic test and measurement business.

devices and systems. It includes various types of linear and nonlinear, time- and frequency-domain simulators (Agilent Technologies, 2013). The second is Applied Wave Research, which is one of the major competitors of Agilent. The company develops Microwave Office, an integrated RF and microwave design software, a competitor product of ADS. Both companies also develop system-level cross-domain design tools (i.e., SystemVue of Agilent and Visual System Simulator of AWR). In addition, they developed various EM analysis and simulation products (e.g., EMPro of Agilent, AXIEM 3D and Analyst of AWR) (Agilent Technologies, 2013; National Instruments, 2013).

## **2.4 Comparative Study of Design Practice through Domains**

As depicted in the previous section, there are various differences between digital, analog/mixed-signal and RF/microwave domains. There are also some disparities regarding the design practice in each of these domains. In this section, we attempt to compare the design practices in terms of design approaches and with the subsequent technology impact.

- **Technology impact through design domains**

Digital chips contain millions of transistors. Analog ones are composed of few hundreds (up to few thousands) of them while RF circuits are composed of only few (tens of) transistors (Grant, 2012). Analog circuits use larger area and are less dense than digital ones (Lavagno, Martin et Scheffer, 2006). This is also true for RF circuits. Hierarchical design approach and mature EDA tools allow digital designers to handle complex chips. However, EDA tools are not fast enough to deal with large analog and RF circuits (Blyler, 2006). Digital designers look for more performance with the smallest possible area and power consumption. On the contrary, their analog counterparts focus more on accuracy while the RF designers are struggling only to get things working properly (Grant, 2012). If digital chips are often implemented using a single technology (i.e., silicon-based), analog (and RF) circuits can be implemented using a variety of fabrication technologies (e.g., Gallium Arsenide aka GaAs, Gallium Nitride aka GaN, etc.). In digital design, a standard design process exists. However, there is a need for integrated tools and design processes that suits better for this mix of technologies in both

analog and RF domains (Viklund, 2005). The required multi-technology support includes the simulation of different technologies at system-level (Park, Hartung et Dudek, 2007).

In addition, moving from a technology process to another in digital design is relatively easy while it is difficult and not cost-effective for both analog and RF domains. One of the reasons behind this situation is the maturity of digital design tools while those used in analog and RF domain are still in their infancy (Hansen, 2003). Furthermore, CMOS scaling<sup>36</sup> brings higher integration and less power consumption in digital domain while it causes significant reduction in dynamic range<sup>37</sup> for both analog and RF circuits (Hansen, 2003). Thus, it is important to provide RF designers with tools to address these issues (Gielen, 2007). Table 2.2 summarizes some characteristics of the three domains from a technological standpoint.

- **Abstraction, Modeling and Device Characterization**

In digital design, there are five abstraction levels that were adopted (i.e., device, circuit, gate, module and system) (Rabaey, Chandrakasan et Nikolic, 2002). It is also common to consider three abstraction levels (i.e. device, circuit/macro, system) for silicon-based analog/mixed-signal designs (Allen et Holberg, 2002). Nevertheless, there are no clear abstraction levels in RF domain. This absence of abstraction contributes to at least two issues: (i) there is no formal way to model components and systems, and (ii) it is not possible to automate the transition between the different abstraction levels.

In fact, if device models are relatively easy to create, use and export in digital design and partially available for silicon-based analog/mixed-signal processes, it is not the same in RF domain. The absence of formal modeling in this domain causes, for example:

- Serious limitations in system-level modeling which hinders early design verification (Dunham et al., 2003),

---

<sup>36</sup> CMOS scaling allows higher speed via the increase of transistor current and smaller area via the increase of the chip's density Hu, Chenming. 1993. « Future CMOS scaling and reliability ». *Proceedings of the IEEE*, vol. 81, n° 5, p. 682-689.

<sup>37</sup> The reduction of supply voltage by 20% decreases the dynamic range by almost 1.6 dB. Hansen, K. 2003. « Wireless RF design challenges ». *2003 Ieee Radio Frequency Integrated Circuits (Rfic) Symposium, Digest of Papers*, p. 3-7.

- Lack of accuracy in system-level simulations and optimizations (Dunham et al., 2003),
- Absence of standard interfaces that enables the interaction either between RF/microwave or cross-domain EDA tools (Viklund, 2005),
- Absence of automated and formal tools for the validation of specifications particularly for complex designs (Warwick et Mulligan, 2005), and
- Limitation of model versioning and reuse.

Table 2.2 Comparison of some characteristics of digital, analog/mixed-signal and RF/microwave domains

<b>Criteria</b>	<b>Digital Design</b>	<b>Analog/Mixed-signal Design</b>	<b>RF/Microwave Design</b>
<i>Signal type</i>	DC	AC	standing waves
<i>Signal form</i>	discrete	continuous	continuous
<i>Prevalence in communication systems</i>	high	low	low
<i>Major design tradeoffs</i>	speed vs. power vs. area	nonlinearity vs. power vs. area	nonlinearity vs. power vs. area
<i>Dynamic range</i>	unlimited	limited by power, noise and nonlinearity	limited by power, noise and nonlinearity
<i>Sensitivity to noise</i>	low	high	high
<i>Fabrication technology</i>	silicon	various technologies including silicon	various technologies
<i>Test and measurements</i>	time-domain	frequency-domain	frequency-domain
<i>Power consumption</i>	low	high	high

Digital design takes advantage from models available at every abstraction level. EDA tools use these models in order to automatically move from a design level to another. For example, the use of hardware description languages allows system-level description of digital systems (e.g., entity/architecture perspective). If the developed models are satisfactory at system level (e.g., in terms of timing), designers can use relevant tools to automatically derive circuit-level implementations. This technique is available for silicon-based analog/mixed-signal designs.

Analog designers use mostly either dedicated hardware description languages such as VHDL-AMS/Verilog-A or conventional programming languages (e.g., SystemC). However, this technique cannot be used in RF design, which limits automation capability in this domain.

This said, technology insertion is valuable for radio design. Digital designers use standard libraries for the simulation of digital circuits. This also happens with analog/mixed-signal and RF designs. However, these libraries are less accurate and more complex than their digital counterparts (Dunham et al., 2003). Technology libraries used for the latter should provide accurate device models (McMahon, 2009). In addition, these libraries should provide complete analog/RF device characterization including its response to the various effects and parasitics (Dunham et al., 2003). All this should take place in a context of technology mix.

- **Readiness for Mixed-Signal Co-Design**

Most Recent radio chips are mixed-signal. (Rutenbar, 2006) estimates that 3 out of 4 digital chips include analog content. (Allen et Holberg, 2002) claims that digital circuitry covers 80% of a typical mixed-signal chip area while the remaining 20% are dedicated for analog circuitry. Furthermore, (Akretch, 2012) argues that mixing RF circuits with their digital and analog counterparts causes signal integrity<sup>38</sup> problems. First, digital circuits are tested in time-domain while analog and RF ones are tested in frequency domain. There is a lack in tools for the correlation between digital and analog/RF signals (Akretch, 2012). Then, a part of the problem is the absence of relevant interfaces across domains (Dunham et al., 2003). This leads to various shortcomings not only in RF/microwave but also in digital and analog domains. In digital design, RF circuits are treated as black boxes where underlying circuits are not detailed and their response is often represented by inaccurate models. Moreover, both digital and analog EDA tools lack the ability of simulating RF circuits. On the one hand, there is a lack of tool integration in these domains (Dunham et al., 2003). On the other hand, specialized RF tools are not the only solution for better mixed-signal design (Viklund, 2005). A schematic-driven

---

<sup>38</sup> Digital circuits are noise-immune while they generate an abundance of noise. Analog and RF circuits are very sensitive to that noise. Blyler, John. 2006. « Analog-RF IP Integration Challenges SoC Designers ». *Chip Design Magazine*. < <http://chipdesignmag.com/display.php?articleId=435> >. Consulté le 26 February 2014.

flow is also not always optimal neither purely layout-driven design is feasible due to RF integration issues (Viklund, 2005). To increase the capability for better mixed-signal design through the different domains, standard interfaces should be developed to enhance mutual understanding between the various design disciplines. An integrated design environment for functional, performance and closed-loop verification across domains and across multiple technologies empowered by comprehensive simulation solutions at different abstraction levels is required (Park, Hartung et Dudek, 2007).

- **Productivity**

The RF front-end is the smallest part in wireless and mobile radios. However, it mobilizes the most of design time and effort. One of the reasons behind this situation is the multiple re-spins and iterations for a first success in both analog/mixed-signal and RF designs (Hansen, 2003; Maloratsky, 2010; Zhang et al., 2004). In fact, complex digital chips can be designed correctly on the first attempt and in only few months while a complex analog chip requires 3 to 4 iterations and up to 18 months (Kundert et al., 2000). More recently, it is assumed to spend 2 to 3 passes for a defect-free analog chip against only one pass for a digital one (Allen et Holberg, 2002). Designers spend 3 to 7 times more effort per transistor in analog than in digital design (Kundert et al., 2000). RF designs require also multiple passes to complete a circuit (Hansen, 2003). Then, it becomes obvious that productivity in digital design is greater than in analog/mixed-signal and RF domain. At this regard, (Kundert et al., 2000) argues that automation and design reuse are among the basic factors to increase design productivity.

In digital domain, a significant portion of design is automated due to the availability of highly specialized set of tools. However, RF design in a traditional design environment is mostly manual (Viklund, 2005). By nature, RF design is highly sensitive to a variety of effects (e.g., parasitics, substrate, packaging, etc.). There are no tools to satisfy all these analyses and at a decent speed (Hansen, 2003). Current tools do what are they best at. Additionally, some errors are caused by the misinterpretation of specifications (frequently due to the use of ambiguous language) (Park, Hartung et Dudek, 2007). The effect of this ambiguity might increase in mixed-signal design because design collaboration is mostly manual or even non-existent at all (Park, Hartung et Dudek, 2007). For all these reasons, there is a growing need in enhancing

automation especially in analog/mixed-signal and RF design (Viklund, 2005) where providing designers with fast and highly-specialized EDA tools is also essential (Blyler, 2006; McMahon, 2009).

Digital designers rely on modeling to reuse designs. IP blocks enable them to produce several versions of their designs and use them for the development of other systems. In analog/mixed-signal domain, IP blocks can also be used (e.g., low-noise amplifiers) (Dunham et al., 2003). However, versioning and reuse is very limited in RF designs.

In summary, digital design is relatively the most developed discipline in radio design. This is due to the well-developed design practice that is particularly empowered by mature tools. The design practice in analog/mixed-signal design evolved during the last years especially for silicon-based technologies where some digital-like concepts were applied. In RF domain, tools have significantly evolved but the design practice has still more room to evolve. There is a growing need for more efforts to be deployed in order to enhance productivity, bring more automation and open this expert-domain for non-expert designers. To conclude, Table 2.3 presents a comparative of design practice in digital, analog/mixed-signal and RF/microwave domains.

## **2.5 Conclusion**

The design practice has significantly evolved in radio design. In this second chapter, we aimed at developing a better understanding of this practice in the different domains pertaining to radio design. Therefore, we started with presenting an overview of design common design approaches used in radio design as well as the future requirements of EDA tools to be used within these approaches. Then, we discussed with some detail the modern design practice in digital, analog/mixed-signal and RF and microwave domains. We concluded the chapter with a comparative study of the design practice within these three domains.

Table 2.3 Comparison of digital, analog/mixed-signal and RF/microwave design practice

<b>Criteria</b>	<b>Digital Design</b>	<b>Analog/Mixed-signal Design</b>	<b>RF/Microwave Design</b>
<i>Design complexity (# transistors)</i>	very high ( $\times 10^9$ )	relatively high ( $\times 10^5$ )	low ( $\times 10^2$ )
<i>Highest abstraction level</i>	algorithmic	behavioral model	schematic
<i>Average passes to prototype</i>	1	3 – 4	3 – 4
<i>Mask cost</i>	very high	high	depending on fabrication process
<i>Use of passive components on board</i>	Limited	high	high
<i>Common design methodology</i>	hierarchical design (top-down)	circuit-based (bottom-up)	circuit-based (bottom-up)
<i>Required designer knowledge</i>	average	advanced	advanced
<i>Automation level</i>	high	limited	absent
<i>CAD tools quality</i>	mature	relatively satisfactory	limited
<i>System-level tools quality</i>	mature	limited	limited
<i>Multi-domain analyses tools</i>	mature	limited	limited
<i>Models accuracy</i>	accurate	average	poor
<i>Design time</i>	low	high	high
<i>Design process</i>	standard/custom	custom	custom
<i>Design process predictability</i>	satisfactory	limited	limited
<i>Migration to a new design process</i>	easy	hard	hard
<i>Design reuse</i>	satisfactory	poor	very poor
<i>Resulting design area</i>	small	average	large

## CHAPTER 3

### THE PROPOSED FRAMEWORK FOR RF AND MICROWAVE DESIGN

#### 3.1 Introduction

The previous section of this thesis was dedicated to the review of modern radio design practice and the various challenges it is facing. In the first chapter, we investigated the background of this discipline. This investigation put into perspective the different aspects related to radio design and the challenges they imply. We concluded that meeting the emerging demands and overcoming the challenges related to radio design requires not only the development of innovative implementation technologies but relevant design approaches and tools. Then, in the second chapter, we examined the design practice within the different domains pertaining to radio design. We attempted to compare digital, analog/mixed-signal and RF/microwave design approaches. Paradoxically, we figured out that even if digital circuits are quite complex and more prevalent in radio systems than analog and RF ones, they are easier and quicker to design and implement. Part of the reason for this is that digital designers benefit from widely adopted structured design approaches and a set of high-level design tools that significantly improve their productivity. The hierarchical design practice and the availability of well-defined abstraction levels have significantly contributed to these achievements. By opposition, in the analog/mixed-signal domain little abstraction and automation are introduced for some technologies. RF design suffers from the lack of abstraction needed to master design complexity and limits dependence towards implementation technologies. The available design flows are still very tied to technology and provide very little design flexibility while most tools in use for RF design provide little automation and suffer from various limitations.

In this two-chapter section we propose a new design scheme for RF devices that addresses the major design issues pointed out in the previous one. In this chapter, we focus primarily on the development of a hierarchical and tool-neutral design approach. Then, we dedicate the next chapter to the definition of an abstraction strategy that fits with the proposed design flow with the purpose of enabling automation of design tasks and easy technology insertion.

### 3.2 Scope and Objectives

In section 1.4, we enumerated some of current challenges and issues related to both design flows and tools used in modern RF domain. These challenges can be roughly classified into five major categories:

1. Productivity: it relates to techniques and mechanisms used in order to minimize the required effort, time and money to get a successful design (e.g., design concurrency, automation, etc.);
2. Design collaboration: it is interested in methods used to improve the communication between different designers (and also the interaction between design tools) and enhance collaborative work within the design cycle (e.g., tools interaction, design data exchange, team collaboration, etc.);
3. Design flexibility: it relates to techniques enabling the reuse of the same design in multiple contexts (e.g., versioning and design reuse);
4. Design accuracy: it is interested in the performance of design tools in terms of precision and correctness (e.g., simulation accuracy, tool specialization, modeling accuracy, etc.);
5. Technology support: it focuses on the mechanisms enabling the management of technology details (e.g., multi-technology support).

The development of future RF front-ends requires these issues to be addressed. We estimate that an effective solution can be an end-to-end integrated design flow that allows hierarchical and collaborative design. In addition, such design flow should define coherent mechanisms enabling handy technology insertion and allowing non-expert designers to easily implement their front-ends. It should also include automation and design concurrency processes for productivity enhancement.

Accordingly, our objective in the following is the development of a new design framework, which is built around a refurbished design flow for the development of RF components. We are particularly interested in the development of the relevant mechanisms and processes that empower the intended design framework with the properties summarized in Table 3.1.

Table 3.1 Summary of the properties that the intended RF design framework is expected to support

Code	Property	Description
P1	Automation	The ability of (semi-)automatically conducting one or many design tasks within the design flow.
P2	Data exchange	The ability of exchanging design data (e.g., models, simulation data, technology information, etc.) in a fully comprehensive manner between the different design steps (with respect to both designers and tools).
P3	Design collaboration	The ability of easing communication, knowledge flow and mutual understanding between teammates in the perspective of endorsing the overall team productivity.
P4	Design concurrency	The capacity of enabling concurrent design tasks where different jobs can be carried out in parallel.
P5	Design consistency	The ability of ensuring the coherency and the correctness of the design.
P6	Design reuse	The capability of using the same design, either in part or in whole, in a new design with minor or no changes.
P7	Technology insertion	The ability of using new technology data and models in design with no or very limited upgrades of the tools in use.
P8	Tools interaction	The capacity of tools to interact, automatically or with minor human assistance, in order to cooperatively carry out intended design tasks.

### 3.3 Proposal of a New Framework to Bridge Existing Design Gaps

Unlike the typical RF design scheme where handling technology often starts at the early design steps (see Figure 2.11), we propose in this section a hierarchical design flow that virtually pushes physical details to the latest design stages. For better illustration, the design flow is presented hereafter incrementally in order to thoroughly describe the different mechanisms and artefacts that are meant to support properties enumerated in Table 3.1.

### 3.3.1 A Five-Step Design Scheme

The proposed design flow consists of five main design steps (see Figure 3.1). The design starts with the component's specifications. These specifications are then analyzed and validated in the "*Analysis*" step. In this phase, the designer carries out a design space exploration seeking for a design solution that meets the given specifications. If an initial solution is found, it is investigated, optimized and implemented in the "*Synthesis*" step considering the relevant technology input. "*Synthesis*" is meant to be automated as much as possible. It results in a ready-to-manufacture design that is fabricated in the next step, namely "*Manufacturing*". Once fabricated, the prototype is submitted for final verification in the last design step, namely "*Tests and Measurements*".

This said, which mechanisms and artefacts might be adopted in order to enable higher automation and design collaboration and alleviate the various previously mentioned challenges?

### 3.3.2 Functional Description

In traditional RF design, specifications are text-based and cannot be validated using specialized tools. This explains in part why designers start by tweaking the physical details of their circuits looking for a suitable design solution. This mostly manual task may take a valuable time with no satisfactory results because the specifications could be neither coherent nor realistic. In this regard, we propose a new concept namely "*Functional Description*". The idea behind this is first, to uncouple the component's function from its underlying physical structure. Then, our ultimate goal is to establish an "executable specifications" process that helps to validate specifications at the early phases of design and figure out any inconsistencies and errors. It is worth noting that the paradigm of executable specifications was introduced in software engineering domain (Cardinal, 2013). Particularly, it was used in agile software development to enable test-driven development where the implementation is constantly checked against the evolving requirements. This concept has been expanding to other engineering fields. For instance, it was used in digital design not only to capture design requirements and constraints

but also to assist system-level functional verification, introduce a mechanism of feedback in order to assess the design quality and produce functionality documentation as the design is progressing (Gajski, Vahid et Narayan, 1994).

In the proposed design flow, “*Functional Description*” is meant to capture the functionality and the properties of the component as well as the design requirements and constraints in a relatively formal fashion. In this regard, we need a mechanism to (i) enable human-readable representation that captures the component’s functional description and (ii) allow its storage and exchange.

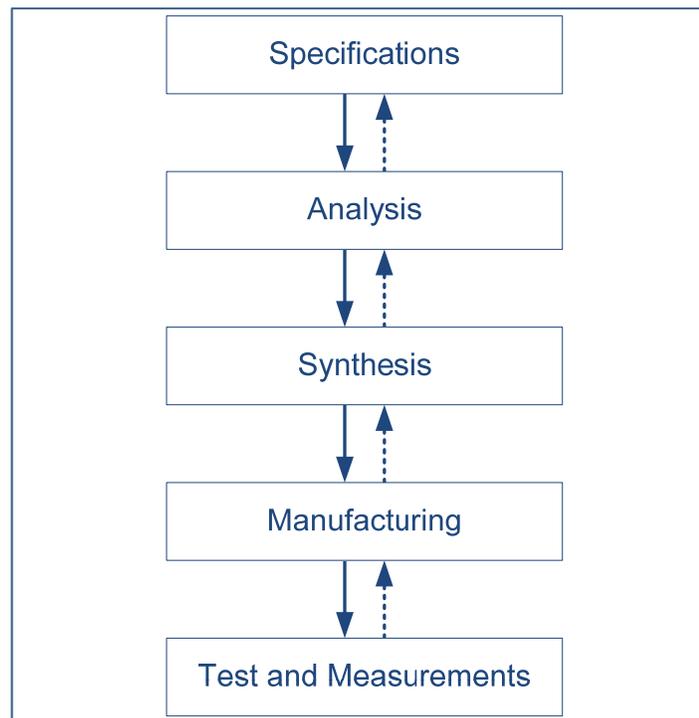


Figure 3.1 The design flow consists of five distinct design stages

- **Modeling RF devices using standard modeling languages**

In practice, “*Functional description*” is a way of modeling RF components. When it comes to modeling, current design frameworks use various techniques to capture the properties of a component. As illustrated in Figure 3.2, modeling a filter can be carried out in a variety of ways. In digital design, a filter can be modeled using a hardware description language (e.g.,

VHDL). Either traditional programming languages (e.g., C++) or custom ones (e.g., SystemC) can also be used to model an analog filter. RF tools use graphical blocks to capture the parameters of a filter at system level (e.g., ADS, SystemVue). All these representations are good to capture the properties of the intended filter. Nevertheless, they may be limited in flexibility. For example, system-level blocks used within ADS and SystemVue are predefined. They cannot be directly altered which may limit the accuracy of the filter model. In addition, the model readability may become limited as the complexity of the filter model grows. It is the case of algorithmic models. Additionally, both representations (either algorithm- or block-based) captures poorly the related requirements (especially text-based).

In 2007, the Object Management Group<sup>39</sup> (OMG) had published the “UML Profile for Software Radio” (OMG, 2007) in which it presented a new way to model baseband, IF and RF components. The OMG uses a general-purpose modeling language, namely the Unified Modeling Language (UML), for the modeling of the different components. UML allows capturing not only the device’s parameters but also its architecture (e.g., hierarchy) and behavior as well as any related business processes and data structures. It provides an intuitive visual representation of the modeled device. Initially, UML was developed for software engineering domain to leverage the issue of specifications complexity in software systems. The idea was to provide engineers with a language allowing specification capture, hierarchical construction, visualization, simulation and documentation (Chonoles et Schardt, 2011). The subsequent benefits of this modeling methodology are significant: easier abstraction of real-world objects, better communication and higher productivity (Chonoles et Schardt, 2011). Various frameworks were built around UML to provide concrete automation (e.g., Executable<sup>40</sup> UML (Fowler, 2004; Starr, 2002)).

---

<sup>39</sup> The Object Management Group is “*an international, open membership, not-for-profit technology standards consortium*” that was founded in 1989. For instance, “*OMG’s modeling standards, including the Unified Modeling Language (UML) and Model Driven Architecture (MDA), enable powerful visual design, execution and maintenance of software and other processes*”. OMG. 1997. « About OMG ». < <http://www.omg.org/gettingstarted/gettingstartedindex.htm> >. Consulté le 24 March 2014.

<sup>40</sup> Executable UML is a software development framework that “*combines a subset of the UML graphical notation with executable semantics and timing rules*” to develop UML models which “*can be run, tested, debugged, and measured for performance.*” Starr, Leon. 2002. *Executable UML: How to Build Class Models*. Prentice-Hall.

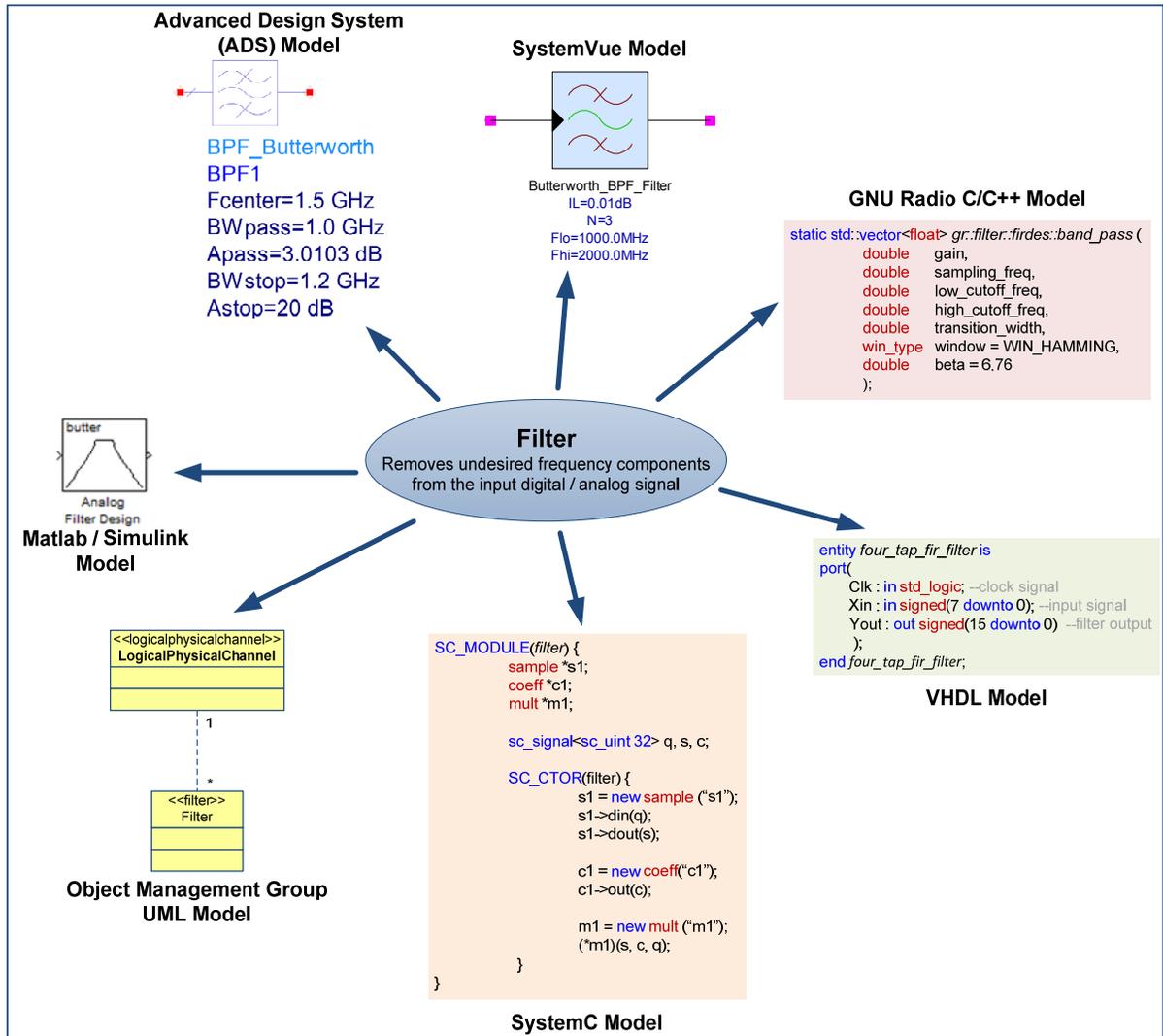


Figure 3.2 A filter can be modeled in a variety of ways

On the one hand, using UML as a modeling language for “*Functional description*” is attractive because:

- Readability: UML combines a rich set of notations allowing hierarchical graphical description of RF devices and systems. This results in good visualization of the device’s functionality and related requirements as well as better communication between designers;
- Richness: UML is rich in diagrams that allow effective multi-level capture of device’s parameters, functionality, structure and behavior. Given appropriate custom semantics, it captures the related requirements. All these aspects can also be documented easily;

- Executability: Given the appropriate semantics and rules, the designer can make the developed models executable that enables early specifications verification, allows system-level simulations, and enhances design space exploration.

On the other hand, using UML as a modeling language for “*Functional description*” can be labor-intensive and confusing at least for two reasons:

- Generalness: UML is a language that was originally developed and optimized for software engineering. Using UML for other domains (including RF design) is possible but may be very limited due to its incapacity to express specific aspects of these domains. For example, it does not support efficiently the modeling of dynamically changing parameters causing the system to behave differently under different configurations (Belloir et al., 2008). It also expresses weakly the relationships between mixed systems composed of different-nature objects (e.g., hardware/software, etc.) (Belloir et al., 2008);
- Overhead: UML does not include a proper diagram to capture requirements. To do so, an extra effort is needed to define a custom UML profile for this purpose. Depending on the semantics in use, associating the device’s models capturing its functionality, properties and structure to the related requirements may be confusing and difficult to manage especially for large designs.

For more information about UML limitations, (Lange, Chaudron et Muskens, 2006) presents a survey of its common defects. Knowing that the provision of UML to systems engineering is limited, the OMG has developed and standardized another modeling language, namely Systems Modeling Language (SysML). SysML is an extension of UML for the specification, analysis, design, and verification of systems in a broad range of engineering fields (OMG, 2013a). It provides graphical representations with flexible and expressive semantics allowing the design of complex engineering systems. As a subset of UML, it redefines seven of its diagrams and adds two new ones (i.e., requirement and parametric diagrams). SysML is smaller and compact and it introduces the concept of views allowing the modeling of the same system from different viewpoints (OMG, 2013a). Furthermore, SysML is compliant with

various standardized data interchange formats (e.g., XML<sup>41</sup>, XMI<sup>42</sup>, AP-233<sup>43</sup>, etc.) which makes models, data and metadata exchange easy (OMG, 2013a).

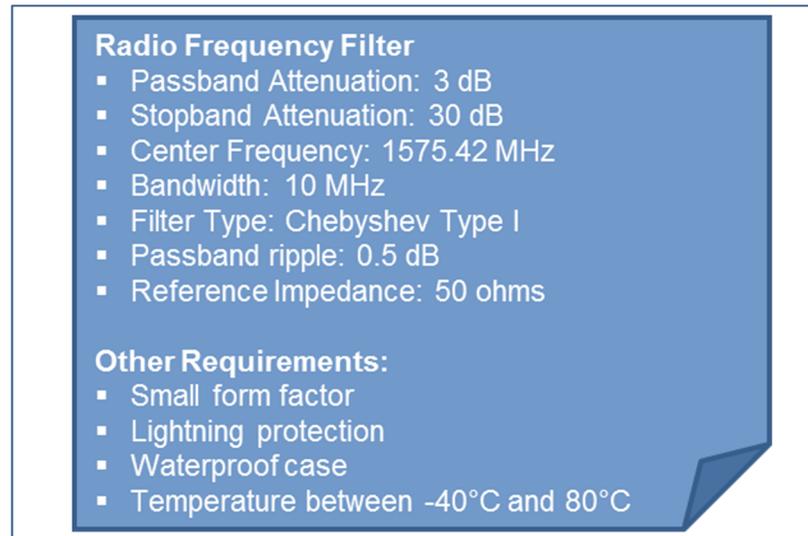


Figure 3.3 Typical specifications of a GPS L1 RF filter

Considering the provision of SysML, we attempted in (Lafi et al., 2008) to model a UMTS transceiver using the different diagrams and concepts provided within the language. This case study allowed us to conclude that SysML is a more suitable modeling language for “*Functional Description*” than UML.

For illustration purposes only, the RF filter whose specifications are given in Figure 3.3, can be described by the SysML model in Figure 3.4. This example is not exhaustive. A complete bandpass filter model is presented in chapter 5.

---

<sup>41</sup> The Extensible Markup Language (XML) is a markup language that was standardized by the World Wide Web Consortium (W3C).

<sup>42</sup> The XML Metadata Interchange (XMI) is an XML-based OMG standard for metadata exchange.

<sup>43</sup> AP-233 (also known as STEP AP-233) is an ISO standard for systems engineering data representation.

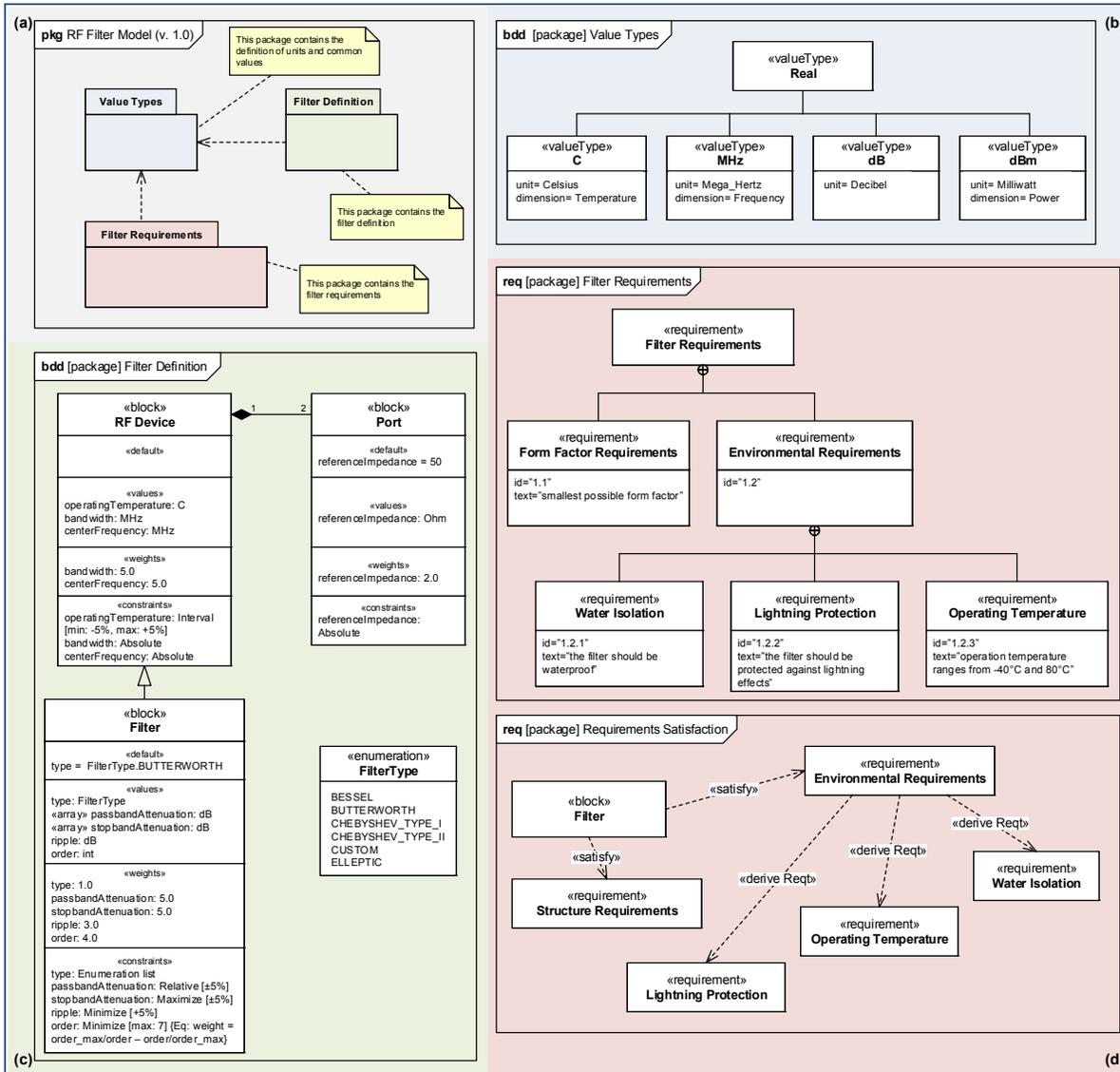


Figure 3.4 An example of SysML model for a RF filter: (a) the package diagram (b) the value types package (c) the block definition diagram of the filter (d) the requirements diagram

- **Exchanging models via standard markup languages**

Using SysML for the modeling of RF devices is particularly appropriate for visual representation and enhances communication between designers. However, to improve tools interaction and ensure better design partitioning for both designers and tools, models should be amenable for storage and exchange. Graphical notations are human-readable but not relevant for machines. For this reason, we thought about adopting one among the simplest and

the most widespread markup languages already supported by SysML, namely the Extensible Markup Language (XML) (W3C, 2013). This standard text format is flexible and easy to use. It is both human- and machine-readable and amenable for storage, exchange and alteration. It gave birth to a very wide variety of custom markup languages used in a myriad of engineering and science fields.

Table 3.2 An example of XML structure to capture the SysML model of Figure 3.4

```

<?xml version="1.0" encoding="UTF-8"?>
<model id="" version="">
  <name></name>
  <description></description>
  <metadata></metadata>
  <structure id="">
    <name></name>
    <blocks>
      <block id="">
        <defaults>
          <default></default>
        </defaults>
        <values>
          <value></value>
        </values>
        <constraints>
          <constraint></constraint>
        </constraints>
      </block>
    </blocks>
    <relationships>
      <relation id="" type="">
        <start></start>
        <end></end>
      </relation>
    </relationships>
  </structure>
  <requirements id="">
    <requirementSet id="">
      <requirement id=""></requirement>
    </requirementSet>
  </requirements>
  <valueTypes id="">
    <valueTypeSet>
      <valueType id=""></valueType>
    </valueTypeSet>
  </valueTypes>
</model>

```

Accordingly, “*Functional Description*” includes two steps (see Figure 3.5): the first is modeling the RF device using SysML language (UML can be used as well). Then, the second step is the conversion of these models into XML description that can be stored and exchanged between tools and designers. Naturally, this XML description can be converted back into SysML if required. To illustrate this idea, Table 3.2 shows a sample of an XML structure

suitable for capturing the SysML model shown in Figure 3.4. It is worth noting that there is no unique way to develop an XML structure that is intended to hold a given model. But to ensure the well-formedness and the validity of that structure, an XML schema<sup>44</sup> can be used.

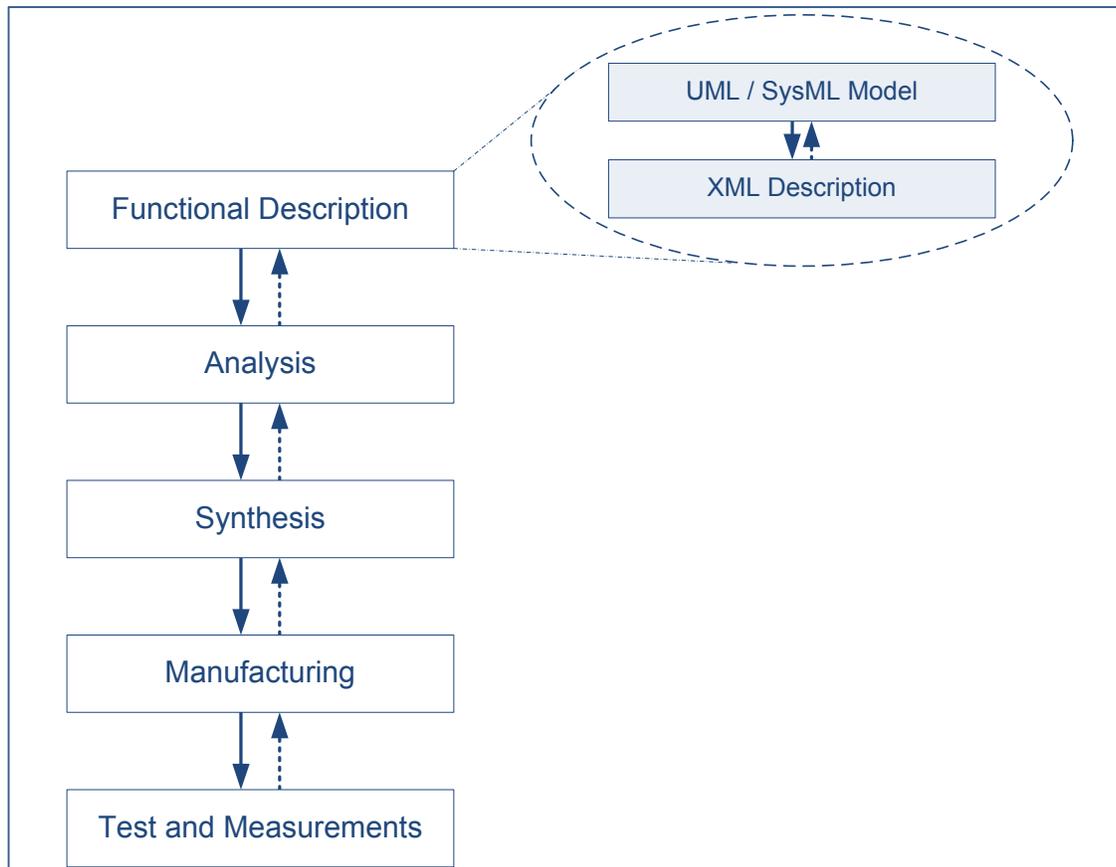


Figure 3.5 Functional description is based on high-level modeling

### 3.3.3 Analysis

Given graphical models amenable for storage and exchange, the next step is “*Analysis*”. Its aim is to (i) validate the functional description resulting from the previous step and (ii) attempt to effectively use this functional description for system-level analyses. This includes for

---

<sup>44</sup> An XML schema is a set of syntactical rules and constraints expressed in a formal language (e.g., The Document Type Definition) in the purpose of ensuring that the XML document conforms to a predefined description in terms of structure and data types.

example, the search of an initial implementation solution that matches, in part or in whole, with the initial functional description.

- **Validating the specifications through “Coherence Verification”**

The process of “*Coherence Verification*” is based on a set of coherence rules that are used to validate the consistency of the functional description. These rules may be embedded within the SysML model or provided as a separate input. It aims to check out the consistency of functional description models (including the associated XML description) and detect any eventual errors at early design stages.

In general, the coherence rules can be subdivided into three main categories:

- Electrical consistence rules: these rules verify the relationships between the different blocks’ values and default values<sup>45</sup> within the SysML models (which express the various parameters of system being designed). If two electrical parameters are assigned to contradictory values, an error is reported. For example, this happens for filters when the ripple value does not correspond to the specified passband attenuation (which makes the filter not feasible because the filter’s ripple should correspond to the minimum required passband attenuation, see detailed explanation in Figure 3.7). To easily figure out the mathematical relationship between the various models’ parameters, we propose to map them using a graph where every couple of parameters are related using an arrow if there is a relationship (i.e., electrical/mathematical) linking them. This mapping results in the Parameters’ Relationships Graph (PRG);
- Functional-level design constraints: these rules are related to the design considerations to make at functional level in order to prevent non-feasible or poor design solutions. For example, a Chebyshev or Elliptic filter with an even order might be refused in a 50-ohm system because it results in an unmatched output that requires an additional matching network to work properly (see Figure 3.7);

---

<sup>45</sup> A value property in SysML semantics represents a quantity parameter that can be assigned a type and a value. Delligatti, Lenny (304). 2013. *SysML Distilled: A Brief Guide to the Systems Modeling Language*, First. Addison-Wesley Professional.

- Integrity control rules: these rules are all about the control of the definition domain, acceptable range and type of each parameter (value property or attribute in SysML models). For example, a power value cannot be negative. If it is assigned to a value of 100 dBW, a warning is reported because that value is very huge and unrealistic.

In addition, we defined two levels of consistency checks in order to quantify any potential inconsistency level:

- Warnings: this level indicates that a coherence rule has detected a minor issue within the provided functional description that can eventually influence the design consistency at later stages;
- Errors: a coherence rule results in an error when it detects a major inconsistency that makes the design practically impossible to implement.

For illustration, the coherence rules corresponding to GPS filter SysML model given in Figure 3.4 are summarized in Tables 3.3, 3.4 – 3.5. Considering the following notations, the electrical consistence rules are elaborated in the PRG shown in Figure 3.6. The corresponding mathematical equations are given in Table 3.3.

$N$	Filter order
$BW$	Bandwidth
$F_0$	Central Frequency
$F_c$	Cutoff Frequency
$F_s$	Stopband Edge Frequency
$\varepsilon$	Ripple factor
$A_p$	Passband Attenuation
$A_s$	Stopband Attenuation
$R$	Filter Selectivity or Rejection
$Z_{ref}$	Reference Impedance

As shown in Figure 3.6, a subset of arrows and graph nodes express a relationship between a subset of value properties (i.e., parameters). For example, the filter's rejection equation (row 1 in Table 3.3) expresses the difference between the stopband attenuation  $A_s$  and the passband

attenuation  $A_p$  at the lower stopband and passband edge frequencies respectively. In the PRG, this relationship is represented using three graph nodes and two red arrows. The arrowheads are oriented towards the nodes of the parameters on the right side of the equation.

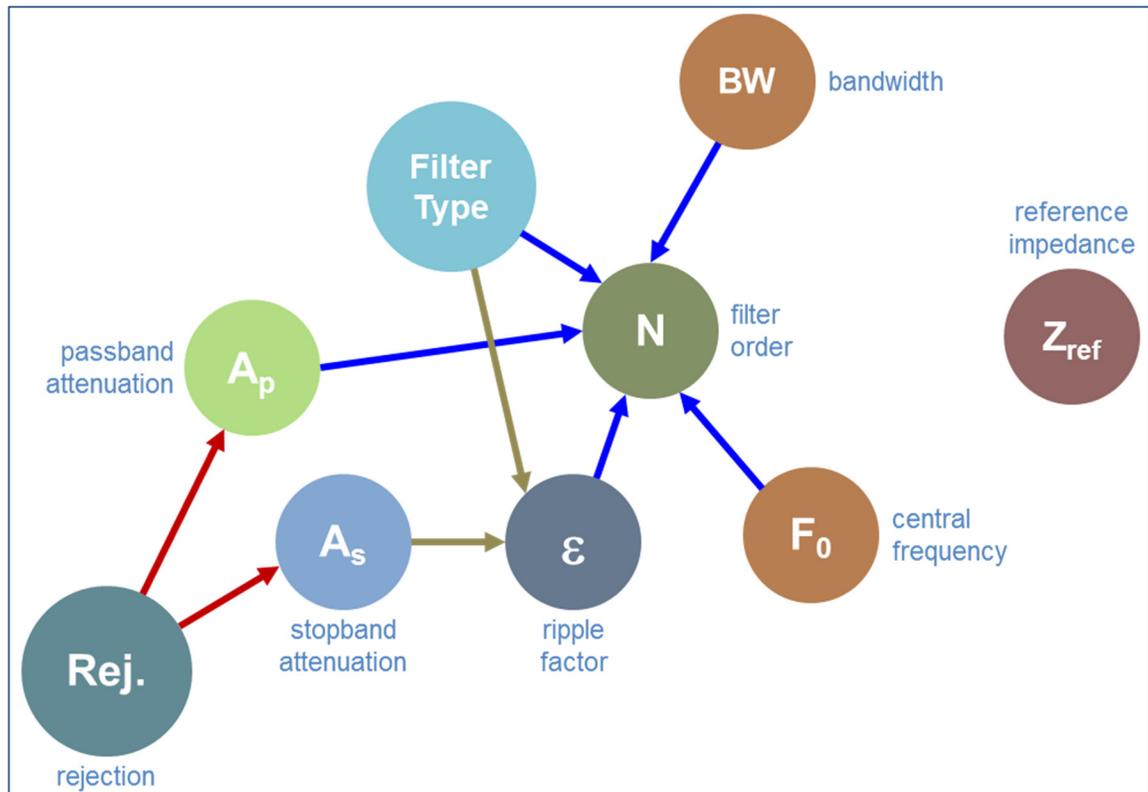


Figure 3.6 Parameters relationships graph corresponding to the GPS bandpass filter of Figure 3.4

Table 3.4 shows two rules that are used to express some functional-level design constraints related to a RF filter functional description. When used to validate the GPS filter model of Figure 3.4, these rules issue a warning and an error respectively as shown in Figure 3.7.

Table 3.3 Relationships between bandpass filter parameters given in Figure 3.6

Arrow Color	Mathematical Relationship	Parameter / Value Property
●	$R = A_s _{F_{sL}} - A_p _{F_{pL}}$	Rejection (filter selectivity)
●	$N = \frac{\log\left(\frac{10^{\frac{A_s}{10}} - 1}{10^{\frac{A_p}{10}} - 1}\right)}{2\log\left(\frac{\omega_s}{\omega_p}\right)}$	Filter Order (Butterworth)
●	$\varepsilon = \frac{1}{\sqrt{10^{\frac{A_s}{10}} - 1}}$	Ripple Factor (Chebyshev)

Table 3.4 An example of coherence rules to validate a typical RF filter functional description

Rule no.	Rule Description	if test fails
1	For a Chebyshev Type I filter whose order ( $N$ ) is an even value, the output impedance ( $Z_{out}$ ) is different from the reference one ( $Z_0$ ).	Warning
2	The specified filter passband attenuation ( $A_p$ ) should be equivalent to a value ( $r$ ) less or equal to the specified ripple ( $r_s$ ). $r _{A_{ps}} \leq r_s \quad (3.1)$	Error

Table 3.5 A selection of RF filter integrity control rules

No.	Rule	if test fails
I.1	$-80 \leq \text{temperatureRange} \leq 100$	Error or Warning
I.2	$0 \leq \text{referenceImpedance} \leq 10^9$	Error or Warning
I.3	$\text{type} \in \{\text{Bessel, Butterworth, Chebyshev Type I, Chebyshev Type II, Custom, Elliptic}\}$	Error
I.4	$\forall i, 0 \leq \text{ripple}[i] \leq 120$	Error or Warning
I.5	$\forall i, 0 \leq \text{passbandAttenuation}[i] \leq 120$	Error or Warning
I.6	$\forall i, 0 \leq \text{stopbandAttenuation}[i] \leq 120$	Error or Warning
I.7	$0 \leq R \leq 120$	Error or Warning
I.8	$N \in \mathbb{N}_+^*$	Error
I.9	$0 \leq F_0 \leq 10^{12}$	Error or Warning
I.10	$0 \leq BW \leq 10^{10}$	Error or Warning

Finally, the integrity control rules defining the range of values accepted for each value parameter of the SysML model are enumerated in Table 3.4.

For Chebyshev Type I filters, at even filter order: (a)

$$\begin{cases} A_p = 3 \text{ dB} \\ A_s = 30 \text{ dB} \end{cases} \Rightarrow N = 2 \Rightarrow Z_{out} = 290.474 \text{ ohms}$$

Filter's output impedance is different from reference one.  
 $Z_{out} \neq 50 \text{ ohms}$

WARNING: Output impedance may not match with the reference impedance

$IL = A_p = 10 \log(1 + \varepsilon^2) \Rightarrow \begin{cases} A_p = IL = 3 \text{ dB} \\ \varepsilon_1 = 0.9976 \end{cases}$  (b)

$$\varepsilon = \sqrt{10^{\frac{r}{10}} - 1} \Rightarrow \begin{cases} r = 0.5 \text{ dB} \\ \varepsilon_2 = 0.3493 \end{cases}$$

$\varepsilon_1 \neq \varepsilon_2 \Rightarrow$ 

ERROR: Specified ripple value cannot be achieved

Figure 3.7 Example of coherence rules to validate a RF filter functional description: (a)<sup>46</sup> A warning results from a rule that detects a minor consistency issue, while (b)<sup>47</sup> an error indicates a major incoherence that makes the design not feasible

- **Enhancing system-level analysis**

One of the goals of functional description is to enhance design space exploration by enabling effective system-level analyses. Given the appropriate tools and depending on the intended functionality, the functional description previously checked for coherence can be immediately

<sup>46</sup>  $A_p$  and  $A_s$  denote the passband and stopband attenuation respectively.  $N$  denotes the filter's order and  $Z_{out}$  denotes the output impedance.

<sup>47</sup>  $\varepsilon$  and  $r$  denote the ripple factor and the specified ripple respectively while  $IL$  and  $A_p$  denote the insertion loss and passband attenuation respectively.

used to carry out a number of analyses that result in an initial design solution. This solution can be a good entry to the following design stages (especially “*Synthesis*”). Nevertheless, at this early step, it should be independent from technology in order to allow more flexibility in the remaining design process.

To illustrate this concept, Figure 3.8.a shows the schematic of an ideal lumped-component (LC) circuit that implements the previously functional description. This LC network is ideal and independent from technology. Figure 3.8.b, c and d show various simulations that can be carried out in order to evaluate its performance. The designer can tune and adjust this solution for an optimized response. It can also be used in the following “*Synthesis*” step in order to take into account more considerations (e.g., technology properties).

In summary, the “*Analysis*” step encompasses two sub-steps as shown in Figure 3.9: “*Coherence Verification*” that validates the functional description and “*Performance Simulation*” that uses the verified functional description to look for a technology-independent design solution.

### 3.3.4 Synthesis

After the validation of specifications and the selection of an initial (i.e., most likely system-level) solution, the designer can undertake the development of a more elaborated implementation that takes into account physical details such as the technology information and constraints (e.g., design rules). This includes the incremental refinement and optimization of the solution as well as the assessment of its performance. To do so, we propose a design stage, namely “*Synthesis*” that is subdivided into three consecutive sub-steps: “*Granularity Refinement*”, “*Technology Mapping*” and “*Performance Simulation*” respectively.

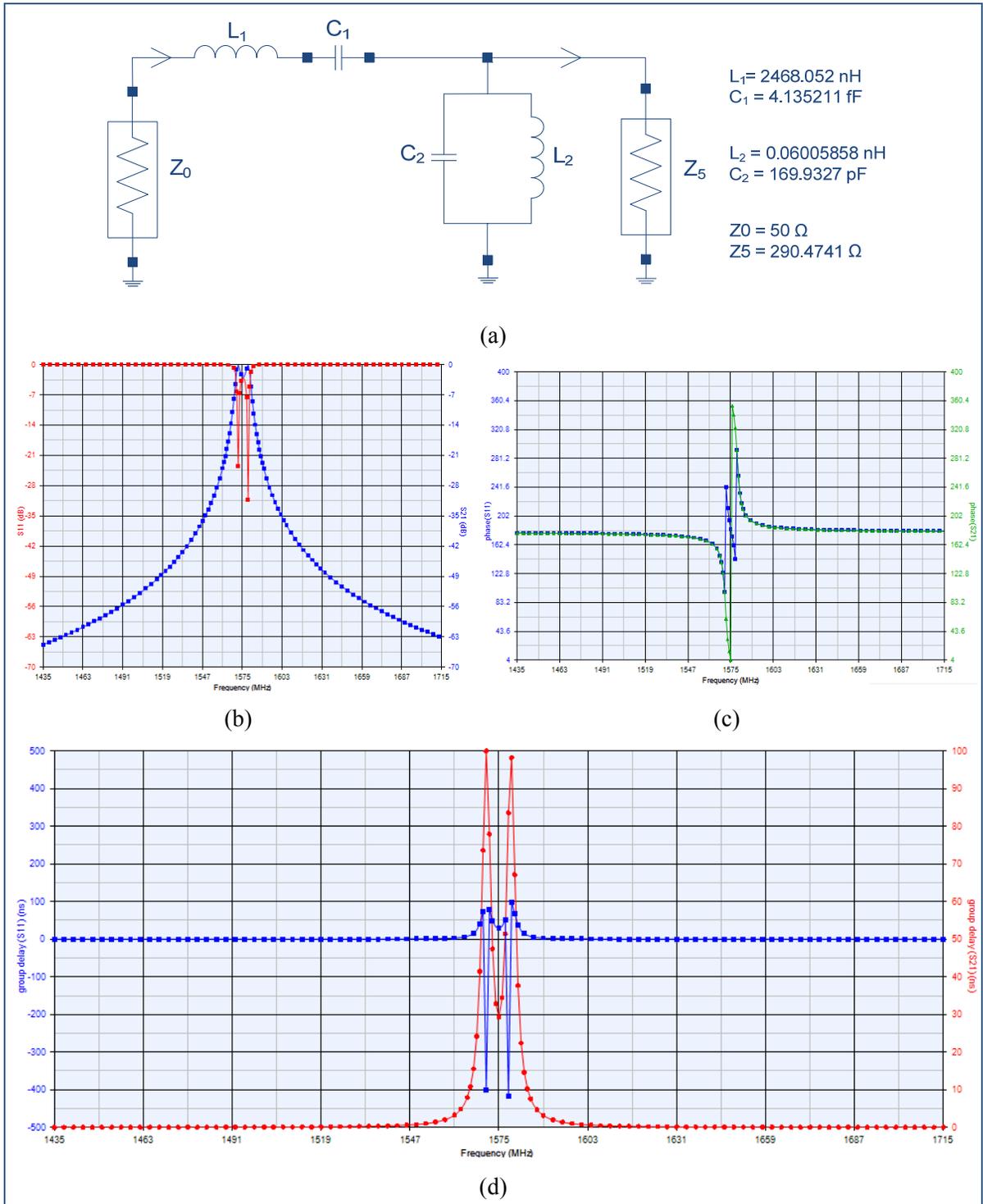


Figure 3.8 Example of system-level analyses related to the GPS L1 bandpass filter (considering a 3-dB ripple): (a) ideal filter network (b) transmission and reflection magnitude, (c) phase and (d) group delay

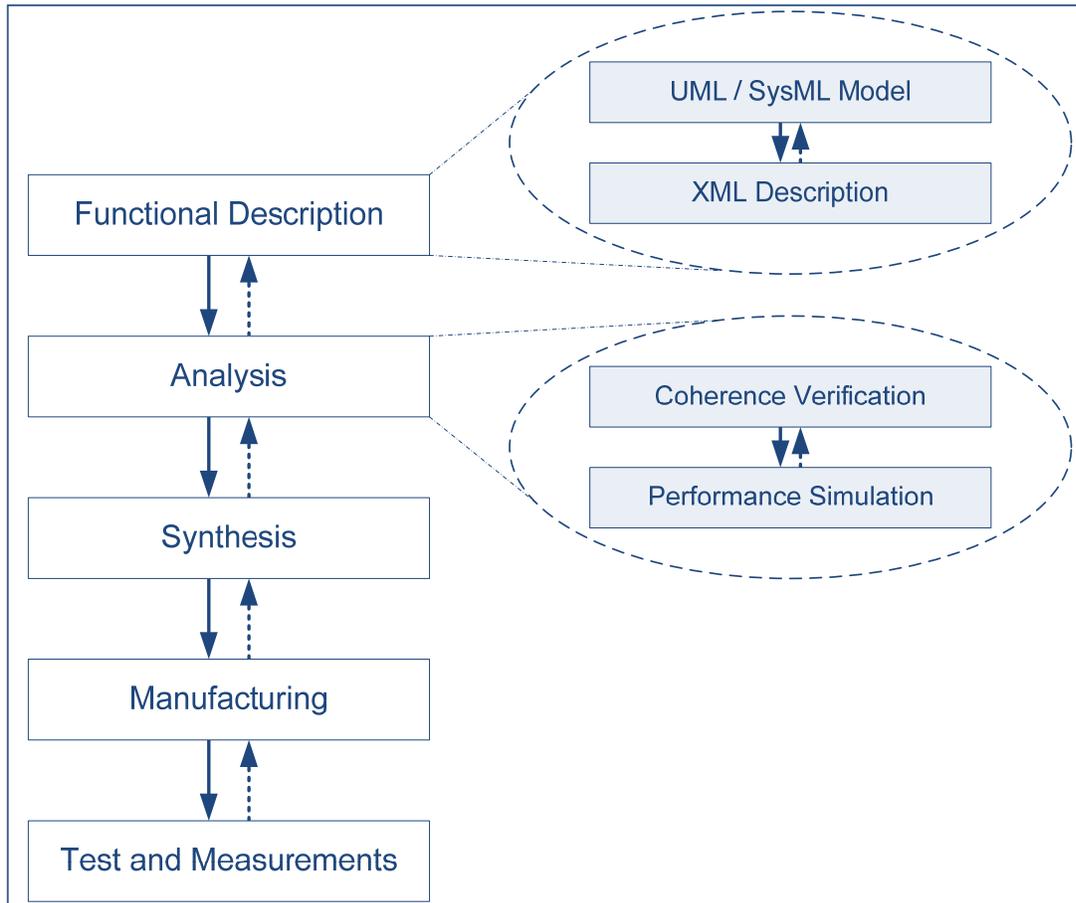


Figure 3.9 “*Analysis*” step includes “*Coherence Verification*” and system-level “*Performance Simulation*”

- **Change of the implementation viewpoint using granularity refinement**

The designer requires often partitioning the system under development into smaller blocks and sub-blocks that can be implemented and verified separately. This technique allows not only to reducing design complexity but also minimizing design time throughout better design concurrency. The way the system under design is partitioned is called granularity level. The concept of granularity defines how a module is broken down into smaller parts. The designer can choose a coarse-grained partitioning in which the module is subdivided into relatively fewer but larger parts. However, a fine-grained partitioning results in more detailed subdivision. To do this, the step of “*Granularity Refinement*” allows the designer to decide about the adequate partitioning of the system under development. In addition, changing the

level of granularity allows changing the design viewpoint that enhances the design space exploration.

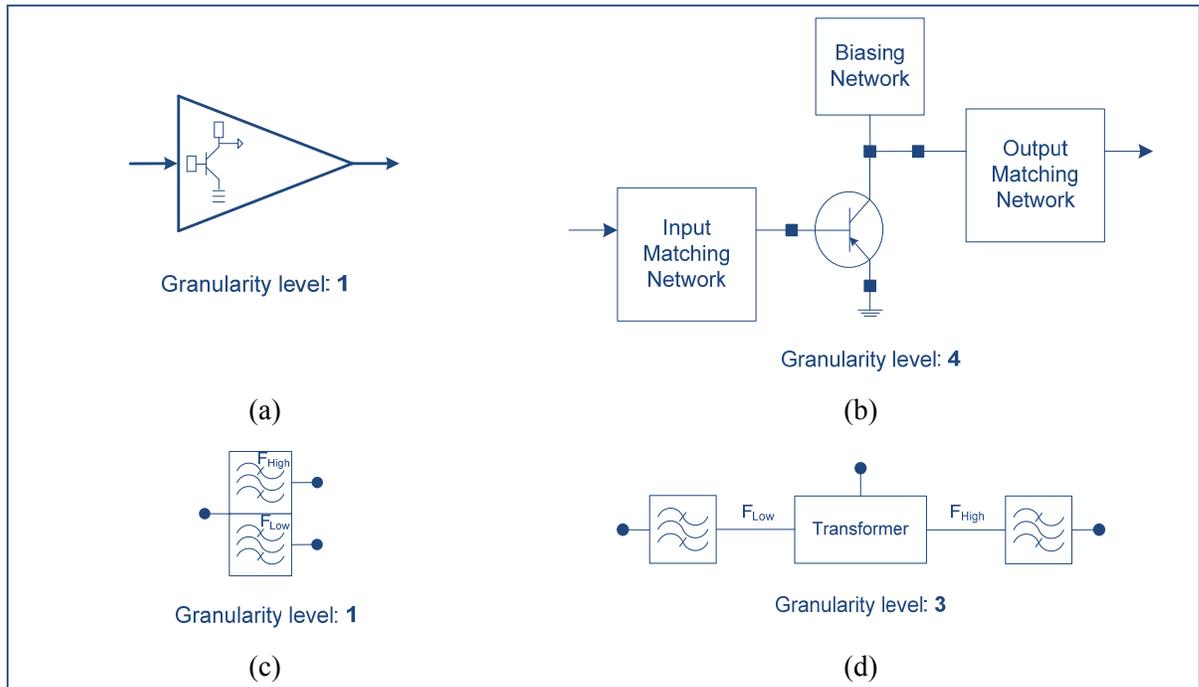


Figure 3.10 Illustration of the granularity refinement concept: (a) and (b) RF amplifier structures, (c) and (d) RF duplexer structures

To illustrate the concept of granularity, Figure 3.10 shows the examples of two granularity levels of an amplifier and a duplexer. The first level corresponds to the whole component (see Figure 3.10.a and Figure 3.10.c) while the second shows four and three blocks that compose the amplifier and duplexer respectively (see Figure 3.10.b and Figure 3.10.d). Considering the GPS L1 bandpass filter, Figure 3.11 shows two ways to partition the filter network. The first consists of considering every lumped component as a standalone block (see Figure 3.11.a). The second subdivides the filter network into two resonators (i.e. a LC structure, see Figure 3.11.b).

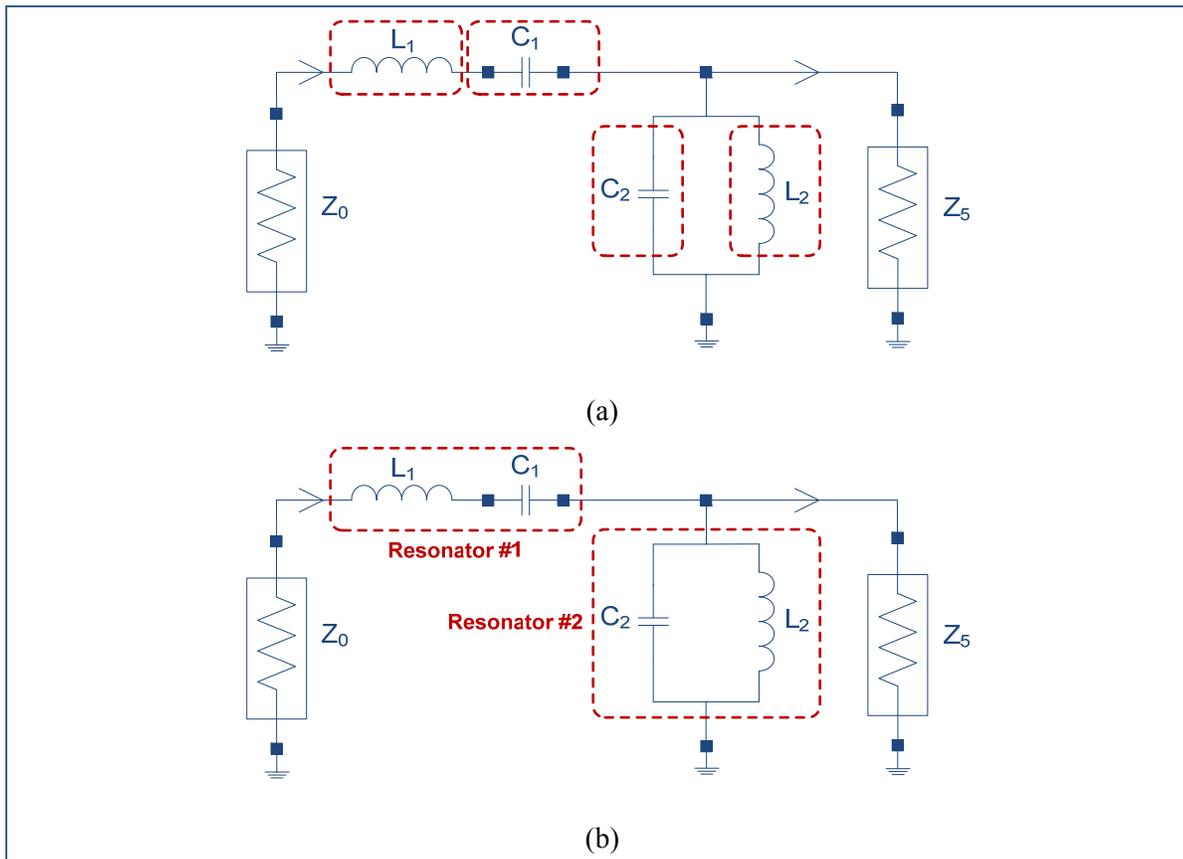


Figure 3.11 Granularity concept applied to the GPS L1 bandpass filter: (a) four lumped-component elements or (b) two resonators

- **Enhancement of technology support via technology mapping**

If uncoupling the functionality from the underlying technology implementation allows efficient system-level functional description and early specifications validation as well as a better design space exploration, it mostly results in an idealistic design that might be unrealizable rather than an effective ready-to-manufacture implementation. To ensure the solution's feasibility, technology details should be taken into account. In the “*Technology Mapping*” step, the designer provides the necessary technology input. For example, ideal lumped components are transformed into real passives using appropriate device characterization libraries. Thus, the parasitic effects present in a resistor (e.g., thin-film resistor model (Vishay, 2009)), a capacitor (e.g., Metal-Insulator-Metal capacitor model (Gruner et al., 2007)) and an inductor (e.g., general inductor model (Green, 2001)) are included in the circuit and considered in performance simulation. Figure 3.12.a shows simplified models for real

resistors, inductors and capacitors (Bahl, 2003; White, 2004). In distributed lines, the designer should include the substrate properties and use the relevant transmission line circuit model. For instance, Figure 3.12.b presents a typical microstrip physical structure along with the substrate properties (e.g., Rogers-3600 substrate). If a coaxial cable is used, typical physical properties to be provided are given in Figure 3.12.c (e.g., RG-58/U) (Shi, Tröltzsch et Kanoun, 2011).

- **Validation of implementation requirements using performance simulation**

Given the technology input, the designer carries out repetitive performance simulations in order to assess the design response and check if it meets the requirements. In general, this operation depends on the accuracy of technology models and the quality of design and simulation tools. This said, after technology mapping, the initial solution often results in a poor performance because of the disparities between ideal and real devices' models. The designer tweaks the various parts of the design in order to optimize its performance. When a satisfactory solution is achieved, a ready-to-manufacture layout is produced.

The previously mentioned GPS L1 bandpass filter was implemented using microstrip transmission lines (considering an FR-4 substrate). The physical dimensions of the microstrip structure corresponding to the initial solution are presented in Figure 3.13.a. Its layout (see Figure 3.13.b) was simulated using ADS electromagnetic solver Momentum. The resulting frequency response is presented in Figure 3.13.c. It is worth noting that the obtained performance is not very good due to technology input (e.g., parasitic effects, circuit models limitations). This structure can be adjusted further in order to provide an adequate performance.

The “*Synthesis*” design stage is conceived to bridge the gap between system-level “*Analysis*” and “*Manufacturing*”. This takes place by the construction of a design solution that matches the system-level one but amenable for fabrication and real-world usage. The construction of this solution goes through a loop that starts with the refinement of the initial design followed by a technology mapping that consists of the provision of technology information and application of design constraints. The design is iteratively optimized and simulated to assess its real performance.

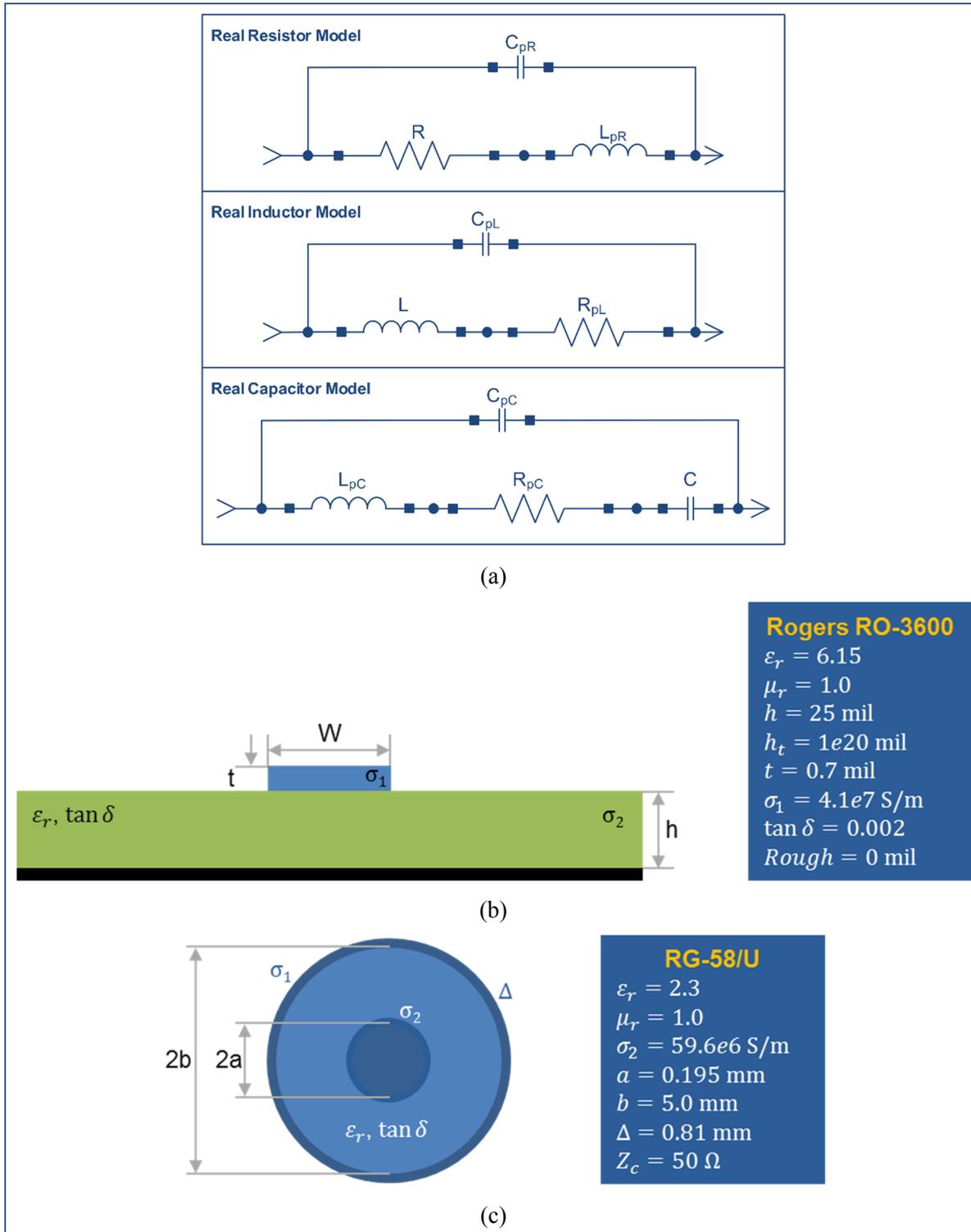


Figure 3.12 Some technology parameters required for (a) lumped-component  
Adapted from White (2004)  
(b) microstrip and (c) coaxial-cable circuits' implementation

As shown in Figure 3.14, when a satisfactory solution is accomplished, it can be manufactured.

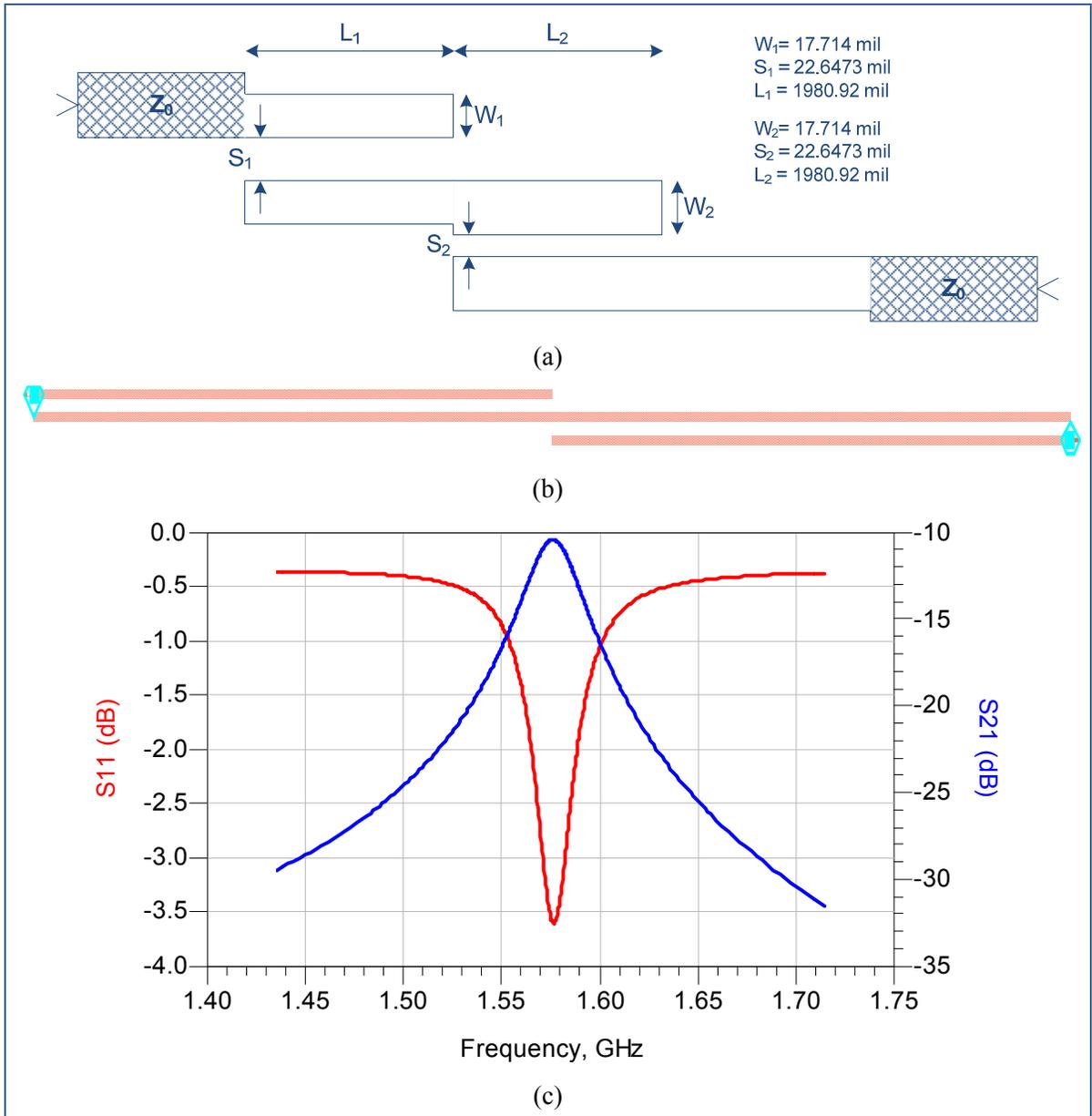


Figure 3.13 The layout corresponding to microstrip coupled-line realization of the GPS L1 bandpass filter: (a) microstrip physical dimensions (considering a FR-4 substrate), (b) the layout produced using Agilent ADS and (c) its performance simulation using Momentum

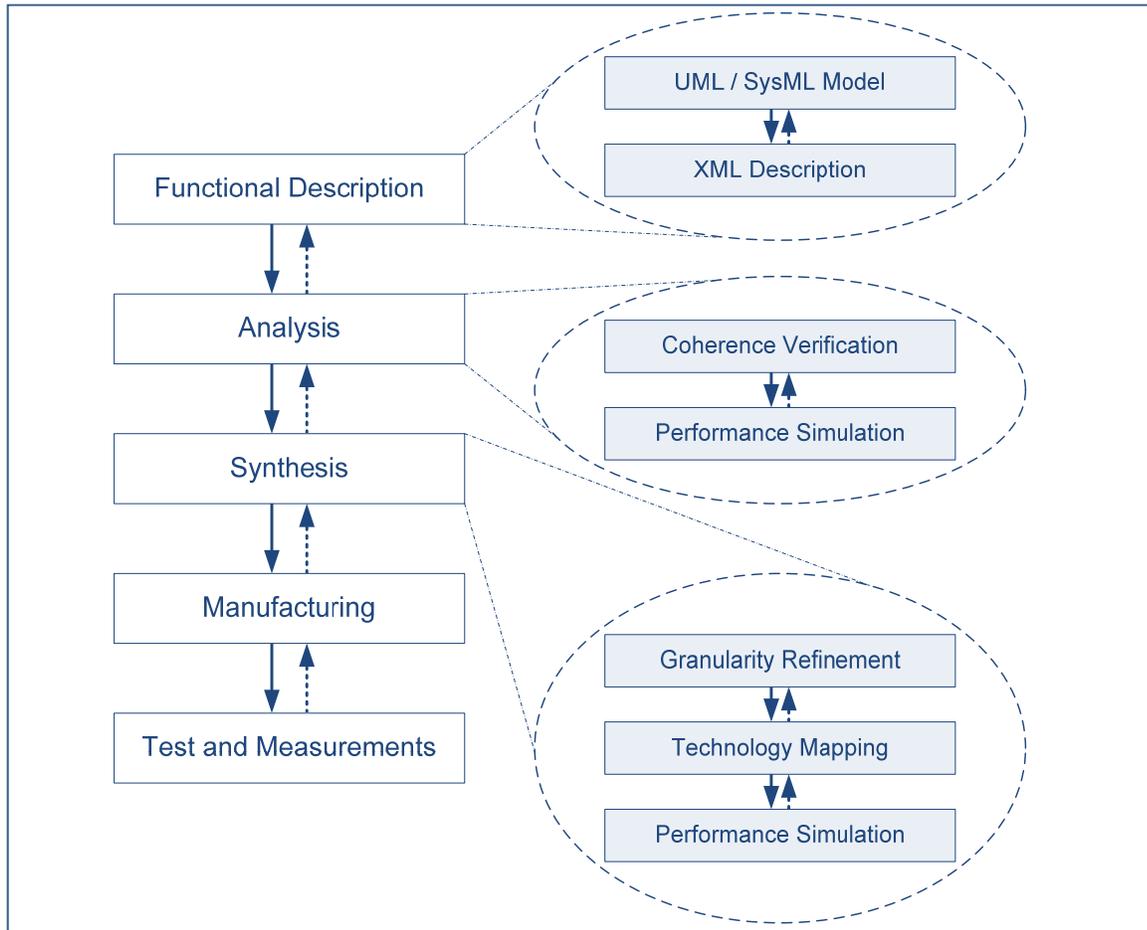


Figure 3.14 Synthesis allows nested granularity refinement and technology mapping in order to build ready-for-manufacturing implementations from an elaborated functional description

### 3.3.5 Q-matrix

The five-step design scheme presented in Figure 3.14 offers a basic design flow for the implementation of RF components. At this step, it provides mechanisms to build and exchange functional descriptions as well as the related models between the different design stages and steps. However, it still lacks an efficient mechanism to exchange design data (especially electrical).

Current commercial design environments use a matrix representation for design data (e.g., Scattering, Impedance, Admittance, Hybrid, Chain, and ABCD matrices, etc.). This technique

is widely adopted in electrical engineering and used not only in EDA tools but also by hardware test and measurement instrumentation. Nevertheless, it suffers from a number of limitations:

- Absence of representation uniformity: Since RF components are of different natures (e.g., linear/nonlinear, passive/active, etc.), there is no unique matrix form to capture the behavior of all of them in a uniform way. For instance, to capture the DC operating points of an amplifier, I-V curves<sup>48</sup> are used while its small-signal transfer parameters (e.g., voltage and current gain, linear noise, etc.) are captured using different types of matrices (including scattering parameters). However, its nonlinear response (e.g., intermodulation products, gain compression, etc.) is captured using various tabular representations;
- Limited representation scope: The matrix representation (especially scattering parameters, aka S-matrix) is limited to the same frequency at all ports. As such components such as mixers are not characterized by S-matrix but rather a mix of reflection, conversion and leakage coefficients. Similarly, sources and oscillators which include DC ports are difficult to capture their response using this technique given that S-matrix is defined only for RF ports;
- A myriad of data file formats: The design of a RF component requires numerous simulations. Most types of simulations are captured in different ways. To exchange this data, a myriad of file formats are used by commercial RF design packages. Some of them are proprietary. Others are standardized. For example, AWR Microwave Office uses DC-IV format files to import and export DC simulation data (National Instruments, 2014). Agilent ADS uses its own TIM files for time-domain data and PDF format for user-defined, piece-wise uncorrelated linear probability density function data (Agilent, 2005). It uses also IMT files for mixer intermodulation product tables, and P2D ones for two-port large-signal power-independent parameters (Agilent, 2005). In addition, both software environments use standardized formats such as Touchstone<sup>49</sup> (for scattering parameters),

---

<sup>48</sup> An I-V curve is a current-voltage characteristic relationship between the electric current and the corresponding voltage respectively measured through and at the edges of an electrical device (e.g. transistor).

<sup>49</sup> Touchstone (aka *SnP* files) is a standard file format for the storage and exchange of n-port network parameters (e.g., S/H/Z/Y) and two-port linear noise.

Citifile<sup>50</sup> and MDIF<sup>51</sup>. Some proprietary variants of the latter are used in both environments (e.g., discrete MDIF in Agilent ADS);

- Fragmented design data: In addition to the relatively high number of file formats for data storage and exchange, there is no unique data format that can be used to capture all the types of electrical data (DC, AC, small- and large-signal, nonlinear, etc.). For instance, the design of a RF amplifier using Agilent ADS requires at least three types of different file formats in order to capture its design data (i.e., MDIF for DC data, Touchstone for small-signal scattering parameters and P2D for nonlinear simulations). In addition, some file formats are limited in number of ports (e.g., Touchstone for noise data, P2D), and independent variables (e.g., Citifile includes frequency and power only). It is extremely tedious to gather data from different origins (e.g., simulation/measurement) in the same data file;
- Poor capture of environment setup: In various situations, the circuit environment configuration is useful to know. For example, large-signal analysis requires the DC biasing currents and voltages to be known. In most file formats, the capture of the environment setup is very limited. For instance, the Touchstone file format captures only the reference impedance value.

Considering all these limitations in current mechanisms for design data exchange, we aim to augment the proposed design scheme with an effective mechanism for proper and tool-neutral design data representation. For this reason, we define a multi-dimensional data structure that captures the electrical behavior of each RF component regardless of its nature, number or types of ports. This mechanism is the Q-matrix. It is intended to link all the design stages and steps. Its multi-layer structure allows the inclusion of data from different origins and scopes. Figure 3.15 shows the design scheme after adding the Q-matrix.

---

<sup>50</sup> CITIfile (Common Instrumentation Transfer and Interchange file) is a standard format for data exchange between computers and instruments. Agilent. 2005. « Using Circuit Simulators ». < <http://cp.literature.agilent.com/litweb/pdf/ads2005a/pdf/cktsim.pdf> >.

<sup>51</sup> MDIF (Measurement Data Interchange Format) is a standardized file format for data exchange.

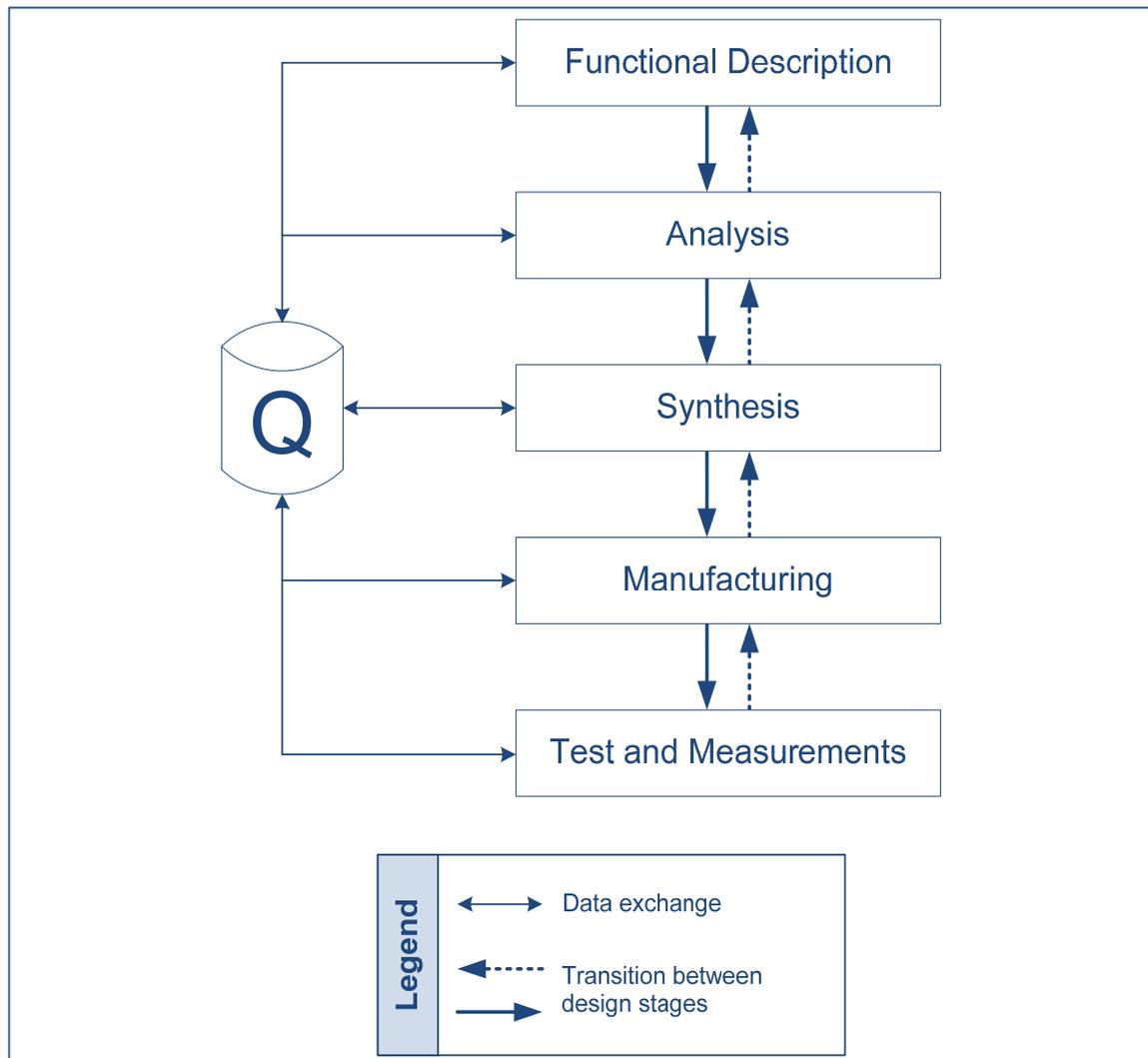


Figure 3.15 Linking the different design stages with the Q-matrix to handle data exchange

### a) Definition and Mathematical Formalism

In the Q-matrix, we retain the matrix representation of circuits in a manner that captures all of a given component's response function but we extend it in the way given in equation (3.2) such that it fits well within our proposed framework. First, we extend the port definition to include DC and control ports. Second, we generalize the definition of the response functions, i.e., reflections and transmissions, between ports to include the frequency of the signal at each port. These extensions lead to the new Q-matrix representation that is defined explicitly as follows:

$$q_{ij} = \frac{b_j|_{f=f_j}}{a_i|_{f=f_i}} \quad (3.2)$$

Where:

$b_j$ : The reflected wave at the  $j^{\text{th}}$  port

$a_i$ : The incident wave at the  $i^{\text{th}}$  port

$f_i$ : Frequency of the signal entering the  $i^{\text{th}}$  port

$f_j$ : Frequency of the signal leaving the  $j^{\text{th}}$  port

According to this definition (i.e. equation (3.2)), the Q-matrix is primarily composed by  $N \times N$  elements ( $q_{ij}$ ) for a  $N$ -port network. Thus, the Q-matrix is a superset extending and encompassing the traditional scattering parameters (see S-matrix definition in (Pozar, 2012)). When the frequency at all ports is the same and not equal to zero, the Q parameters are the same as the scattering parameters. For instance, the Q-matrix corresponding to a two-port network with different operation frequencies at each port (see Figure 3.16) is given by equation (3.3).

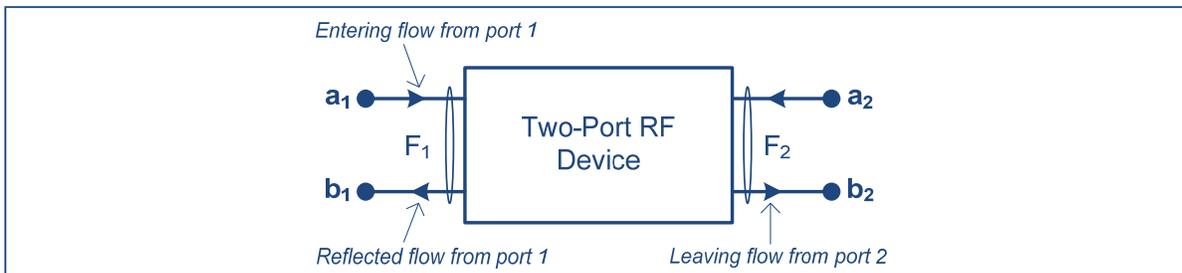


Figure 3.16 Conventions used in a typical two-port RF network where  $F_1 \neq F_2$

$$q = \begin{bmatrix} q_{11} & q_{12} \\ q_{21} & q_{22} \end{bmatrix} = \begin{bmatrix} \frac{b_1|_{f_1}}{a_1|_{f_1}} & \frac{b_1|_{f_1}}{a_2|_{f_2}} \\ \frac{b_2|_{f_2}}{a_1|_{f_1}} & \frac{b_2|_{f_2}}{a_2|_{f_2}} \end{bmatrix} \quad (3.3)$$

The definition given in equations (3.2) and (3.3) generalizes the traditional incident and reflected wave ratios regardless of the operating frequency at each port. However, this is not enough to cover more than one independent variable. For this reason, we introduce a broader definition, that is  $\overline{Q}^{t,T,P,F}$ , given in equation (3.4). It is a sparse matrix that includes the Q-matrix's  $N^2$  basic  $q_{ij}$  elements in function of four independent variables (i.e. frequency, power, temperature and aging time). As shown in Figure 3.17, the extended data structure  $\overline{Q}^{t,T,P,F}$  is construction that is able to hold this multidimensional data.

$$\overline{Q}^{t,T,P,F} = \left[ [q_{ij}]_{N \times N} \right]_{N_t \times N_T \times N_P \times N_F} \quad (3.4)$$

Where:

$t$ : time (aging)

$T$ : Temperature

$P$ : Power

$F$ : Frequency

$N$ : Total number of ports

$N_t$ : Number of time steps

$N_T$ : Number of temperature points

$N_P$ : Number of power points

$N_F$ : Number of frequency points

## b) Data File Format

Given the generalized data structure  $\overline{Q}^{t,T,P,F}$ , the next step is to define a data file format that holds the design electrical data and allows the storage and exchange of a minimum set of environment setup information. For this reason, we have selected again XML to develop that structure. In addition to the reasons we presented in section 3.3.2 to justify the choice of XML, we note that this language is being gradually introduced in state-of-the-art commercial design packages for RF and microwave circuits for data and/or circuit topology exchange (e.g., Agilent Genesys (Agilent, 2010a) and SystemVue (Agilent, 2010b)).

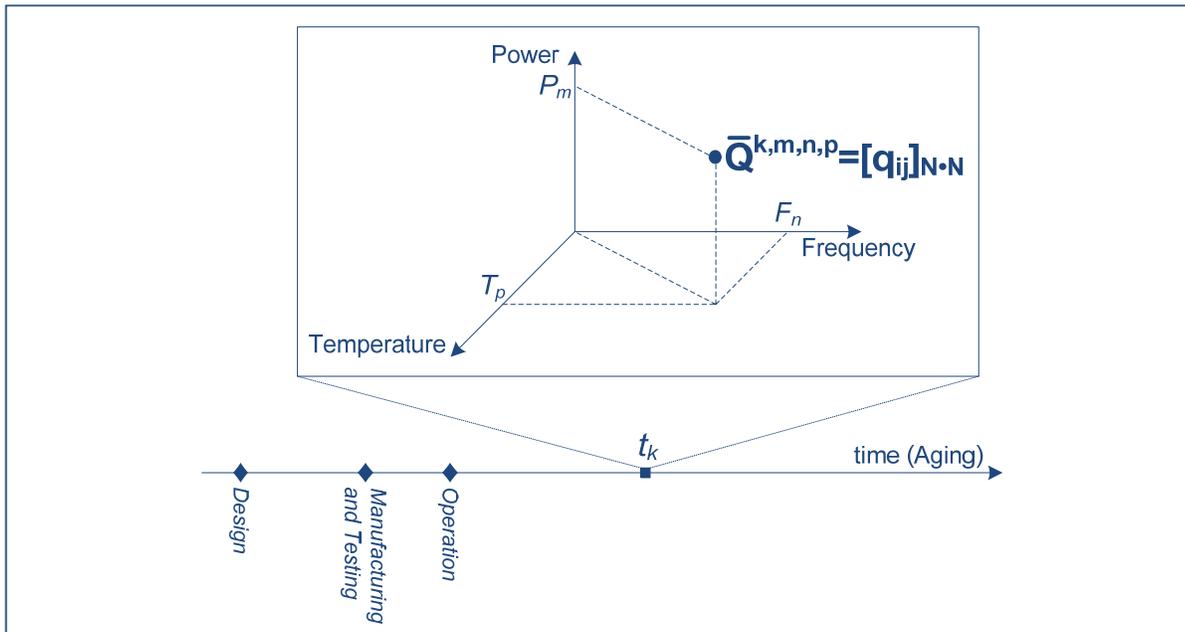


Figure 3.17 Generalized Q-matrix is a function of frequency, power, temperature and time

Table 3.6 depicts the XML structure we used to implement the intended data hierarchy. To enable the storage of data from different sources, we propose a multi-page data file structure. As shown in Figure 3.18 and Figure 3.19, the file is composed of similar data blocks (namely *Qblock*). The structure of these blocks is identical (see Figure 3.20). Their number depends on how much data sources exist throughout the design cycle, test and measurement and operation phases. During the design phase, different designers may share their design data using the same data file. Design data related to different design iterations can also be gathered into the same data file. At each design stage, the corresponding design data can be stored as well. This enables particularly a step-by-step design follow-up. Once the design is manufactured, the test and measurement data can be also stored and then compared to the design data. This data can also be shared with customers who can carry out the device's monitoring during the operation phase. The resulting live data may be useful because it better instructs designers about the potential performance drifts in real-world field operation and thus allows the development of better aging models.

Table 3.6 Overview of the Q-matrix XML data structure

```

<?xml version="1.0" encoding="utf-8"?>
<!-- Q-matrix XML structure version: 1.1 -->
<!-- Author: Sabeur LAFI -->
<Qmatrix>
  <Qblock name="" source="">
    <!-- CONFIGURATION SUBBLOCK -->
    <config>
      <dataType parameter="" format=""></dataType>
      <ports count="">
        <port>
          <name></name>
          <type></type>
          <direction></direction>
          <number></number>
          <refImpedance>
            <refImpedanceUnit></refImpedanceUnit>
            <refImpedanceValue></refImpedanceValue>
          </refImpedance>
        </port>
      </ports>
    </config>
    <!-- DATA SUBBLOCK -->
    <data>
      <aging unit="" value="" src="">
        <operatingTemperature unit="" value="" src="">
          <QdataItem>
            <attachedPorts count="">
              <attachedPortConfig>
                <portNumber></portNumber>
                <frequency unit="" src=""></frequency>
                <power unit="" bandwidthUnit="" bandwidthValue="" src=""></power>
                <dcSources>
                  <control count="">
                    <voltage unit="">
                      <v name="" src=""></v>
                    </voltage>
                    <current unit="">
                      <i name="" src=""></i>
                    </current>
                  </control>
                  <biasing count="">
                    <voltage unit="">
                      <v name="" src=""></v>
                    </voltage>
                    <current unit="">
                      <i name="" src=""></i>
                    </current>
                  </biasing>
                </dcSources>
              </attachedPortConfig>
            </attachedPorts>
            <Qitem name="" src="">
              <xparam></xparam>
              <yparam></yparam>
            </Qitem>
          </QdataItem>
        </operatingTemperature>
      </aging>
    </data>
  </Qblock>
</Qmatrix>

```

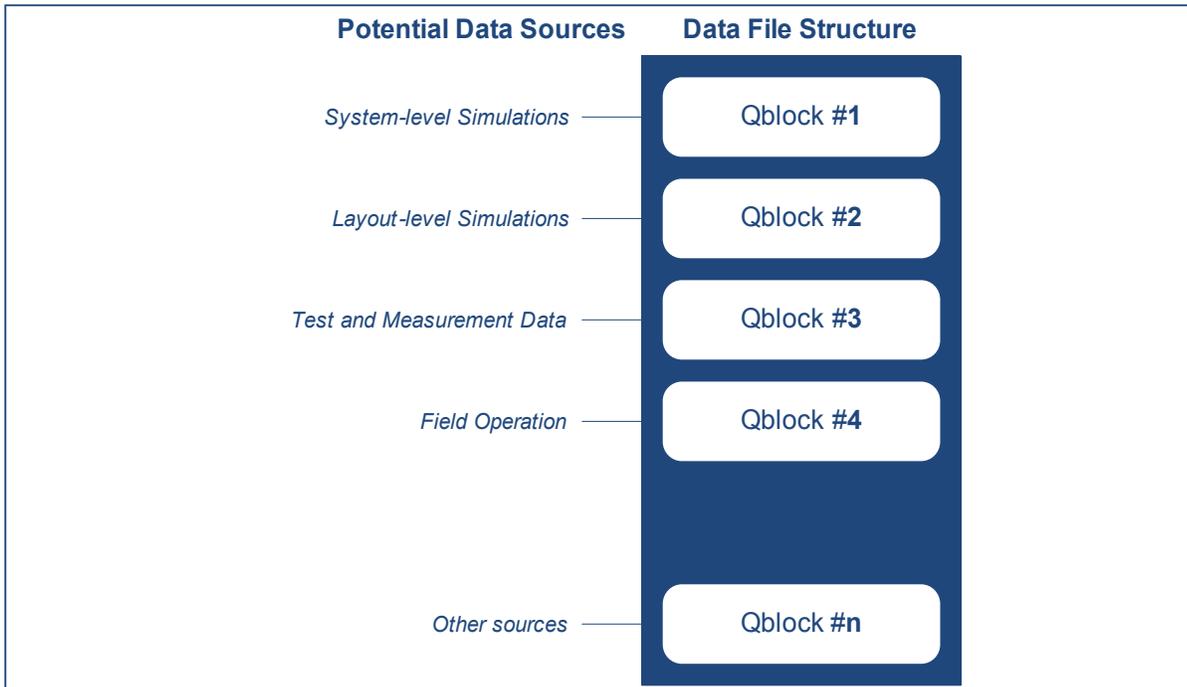


Figure 3.18 The file consists of various data blocks composing data of different sources

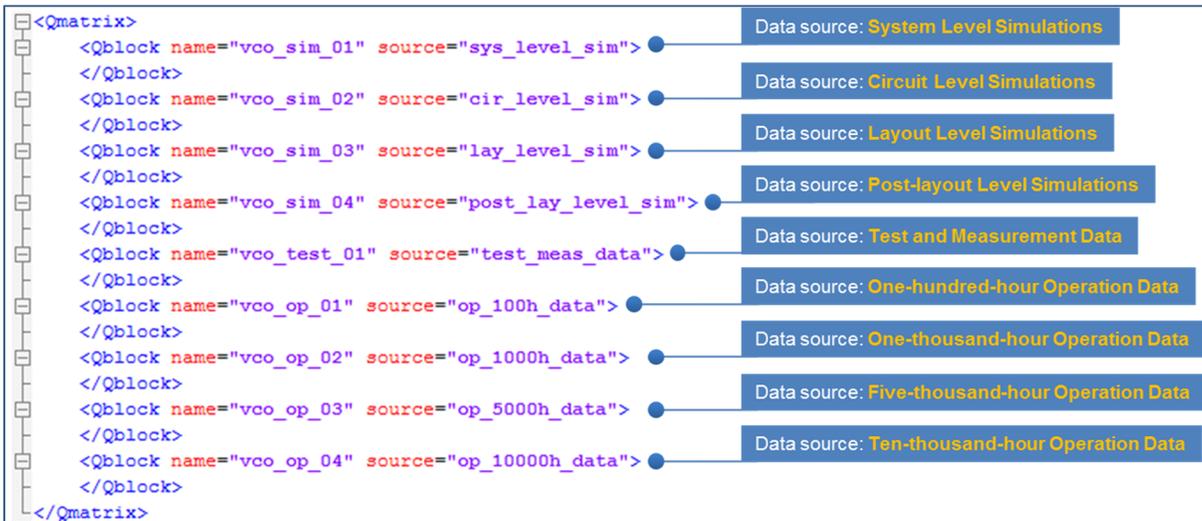


Figure 3.19 Q-matrix data blocks from different data sources

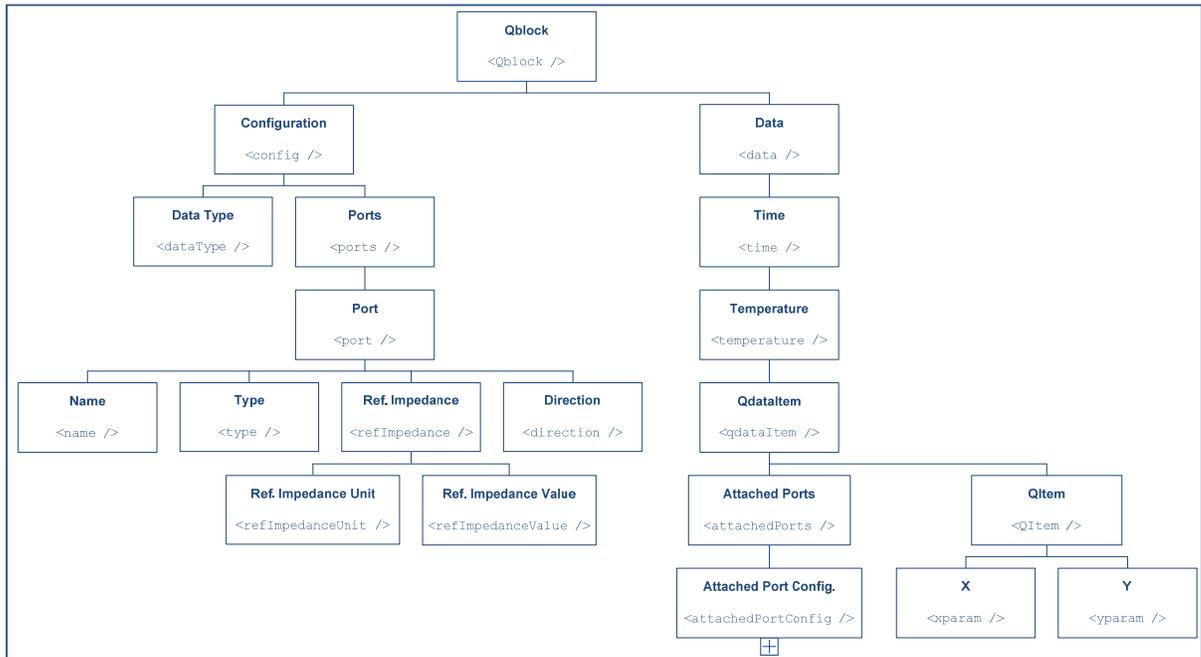


Figure 3.20 Hierarchical structure of a data block

As shown in Figure 3.20, a data block (i.e., *Qblock*) is composed of two sub-blocks. The first is dedicated to configuration. It includes generic information about the design environment (e.g., ports) and the data types. The second sub-block holds data. This sub-block is a nested structure in which the data is presented as a tree. Each tree corresponds to an independent variable. At the leaf, each data item is combined with the attached port configuration. The subsequent advantage is the possibility of capturing various configurations for the same set of independent-variable points. It is worth noting that this structure can be augmented with meta-data<sup>52</sup> tags that can hold useful information about the various configuration and data items. For example, meta-data can be used to capture data timestamp, designer's and project names, instrumentation in use, etc. as well as any useful comments related to that data. Metadata extensibility allows the implementation of numerous data structures that may be specific to some tools and design environments. This allows tool vendors to provide customized features that can be used within their commercial EDA packages without compromising the

<sup>52</sup> Meta-data (also called data about data) are information about one or more aspects of the content. This concept is used in various engineering disciplines to add further information about data and facilitate the access to relevant contents.

standardized format or creating further proprietary file formats. For illustration, Figure 3.21 shows some usage examples of metadata within the Q-matrix XML structure.

```

<Qmatrix>
  <misc>
    <meta name="project name" content="6-GHz MOSFET Voltage-Controlled Oscillator Design" type="text" />
    <meta name="description" content="Design data related to a 6-GHz MOSFET voltage-controlled oscillator" type="text" />
    <meta name="creation date" content="2010/06/06 09:13:05" type="date" format="YYYY/MM/DD hh:mm:ss" />
    <meta name="version" content="1.0" type="version" />
  </misc>
  <Qblock name="vco_sim_01" source="sys_level_01">
    <misc>
      <meta name="description" content="VCO system-level design data" type="text" />
      <meta name="last update" content="2010/06/07 13:57:44" type="date" format="YYYY/MM/DD hh:mm:ss" />
      <meta name="author" content="Sabour Lafi" type="text" />
      <meta name="attached design" content="vco_cir_1.0.dsn" type="text" />
    </misc>
    <!-- Data Follows ... -->
  </Qblock>
  <Qblock name="vco_sim_02" source="sys_level_01">
    <misc>
      <meta name="description" content="VCO phase-noise design data" type="text" />
      <meta name="last update" content="2010/06/08 21:14:17" type="date" format="YYYY/MM/DD hh:mm:ss" />
      <meta name="author" content="Sabour Lafi" type="text" />
      <meta name="attached design" content="vco_cir_1.1.dsn" type="text" />
    </misc>
    <!-- Data Follows ... -->
  </Qblock>
  <Qblock name="vco_sim_03" source="sys_level_01">
    <misc>
      <meta name="description" content="VCO harmonic analysis data" type="text" />
      <meta name="last update" content="2010/06/09 11:23:13" type="date" format="YYYY/MM/DD hh:mm:ss" />
      <meta name="author" content="X Y" type="text" />
      <meta name="attached design" content="vco_cir_1.1.dsn" type="text" />
      <dataset name="noise data" size="1024" data-format="dB">
      </dataset>
    </misc>
    <!-- Data Follows ... -->
  </Qblock>
  <Qblock name="vco_sim_04" source="cir_level_01">
  </Qblock>
</Qmatrix>

```

**Legend**

- Data blocks from different sources
- Data blocks from different designers
- ◆ Different data blocks from the same designer
- ▬ Custom data added in metadata
- ▬ Metadata to add further information about data items

Figure 3.21 Examples of data blocks usage and possibilities of metadata extensibility

### c) Examples of Q-matrix File Format Usage

Since the response of a RF device is often not limited to conventional linear parameters, the Q-matrix file format is expected to support various types of design data. In this section, we present three examples of how the defined XML structure is able to capture linear, small- and large-signal as well as usual DC parameters.

- **Filter frequency response**

Matrix representations (e.g., S/H/Z/Y) are usually used to capture the frequency response of passive devices such as filters, couplers and dividers. Such devices are characterized by the same frequency at the input and output ports. As previously explained, this makes the Q-matrix elements equivalent to the scattering parameters. In this example, we present how the XML data structure captures the scattering parameters of a typical bandpass RF filter model (see Figure 3.22.a) and its corresponding Q-matrix (see Figure 3.22.b). Assuming that its operating frequency is  $F_1$ , the filter's Q-matrix elements are all defined at this frequency. The wave ratios are also homogenous because they all represent quotients of purely RF waves.

As shown in Figure 3.22.c, the configuration section of the XML structure captures useful information about the data type (i.e., scattering parameters) and the data format (i.e., magnitude/angle) as well as the number of ports (i.e., two), their types (i.e., RF) and their reference impedances (i.e.,  $50\Omega$ ). It also identifies their directions (i.e., input and output respectively).

Figure 3.22.d shows how the transmission parameter  $S_{21}$  is captured at the frequency point 1.575 GHz. It is worth noting that the electrical characteristics of the corresponding ports (i.e., port 1 and 2) related to that parameter are also captured. This represents a novelty regarding traditional data file formats because it allows capturing specific conditions in which the data was retrieved. Additionally, what matters the most in this example is the frequency point and the convention in use regarding the input and output ports. The power value is not required (but can be added) since this scattering parameter is a normalized ratio. In other cases (e.g., nonlinear analysis), the value of the power may be mandatory in order to ensure the completeness of the information.

- **Oscillator typical AC response**

The oscillator is a two-port active device that converts the DC current into a RF signal. A voltage-controlled oscillator (VCO) is an oscillator whose output frequency is controlled by an input DC voltage. A typical VCO (see Figure 3.23.a) is captured by the Q-matrix given in Figure 3.23.b.

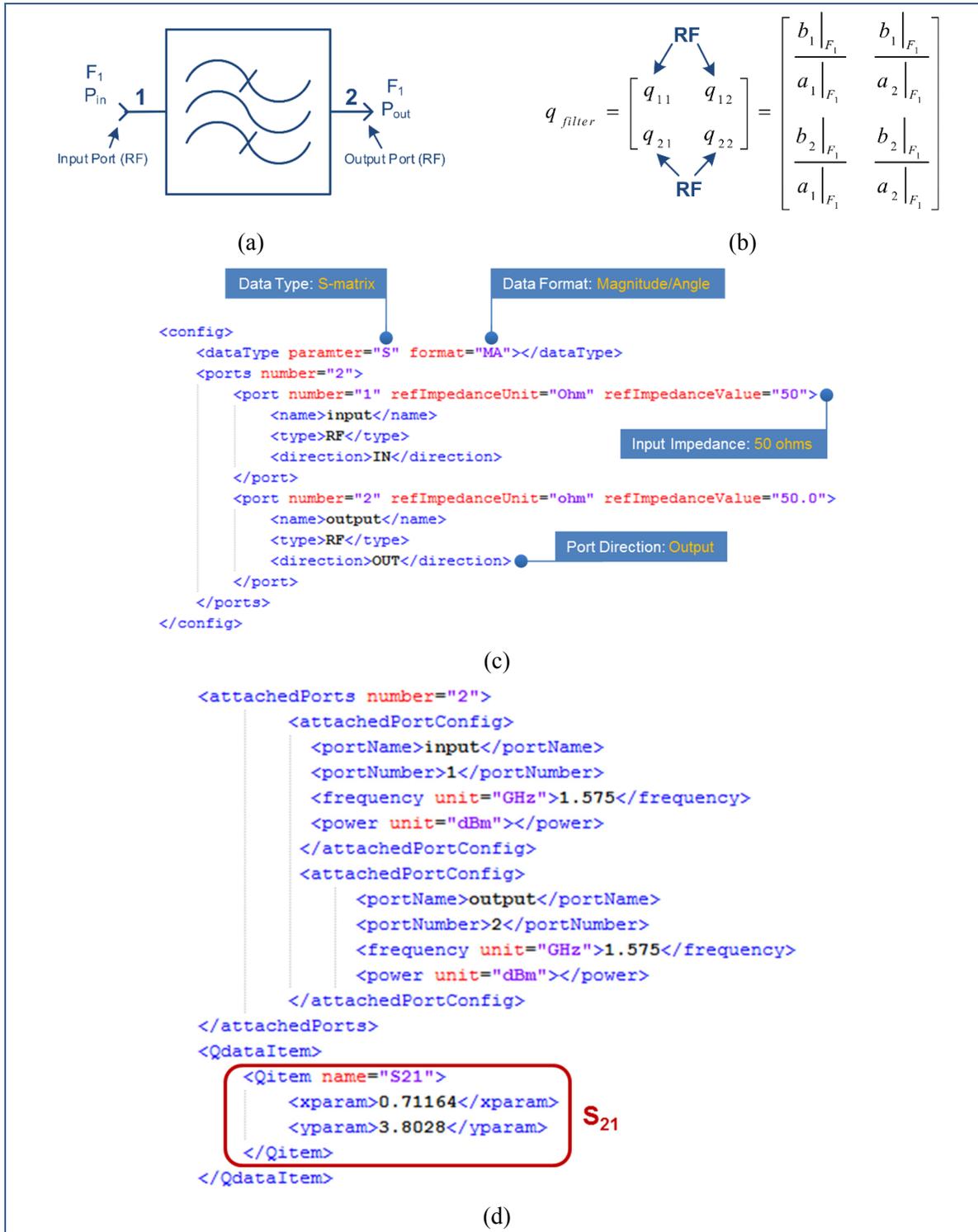


Figure 3.22 A usage example showing how the Q-matrix XML structure captures passive device's linear response: (a) RF filter model, (b) its corresponding Q-matrix and (c) data representation

Unlike the filter's, the presence of an input DC port results in a  $2 \times 2$  Q-matrix where only  $q_{22}$  is purely RF.  $q_{11}$  represents a quotient of locally measured DC voltage magnitudes rather than pure waves ratio. Nevertheless,  $q_{12}$  and  $q_{21}$  are ratios of pure RF wave and DC voltage. These two coefficients can be interpreted as leakage coefficients from DC to RF and RF to DC respectively. This said, Figure 3.23.c shows an example of voltage-controlled circuit based on a BJT<sup>53</sup> transistor (type NPN). The VCO generates an analog signal represented by the voltage  $V_{out}(t) = V_0 e^{j\omega t + \varphi}$ . This output voltage depends on the input small-signal signal  $V_{res}$  as well as the constant biasing voltage  $V_{cc}$ .

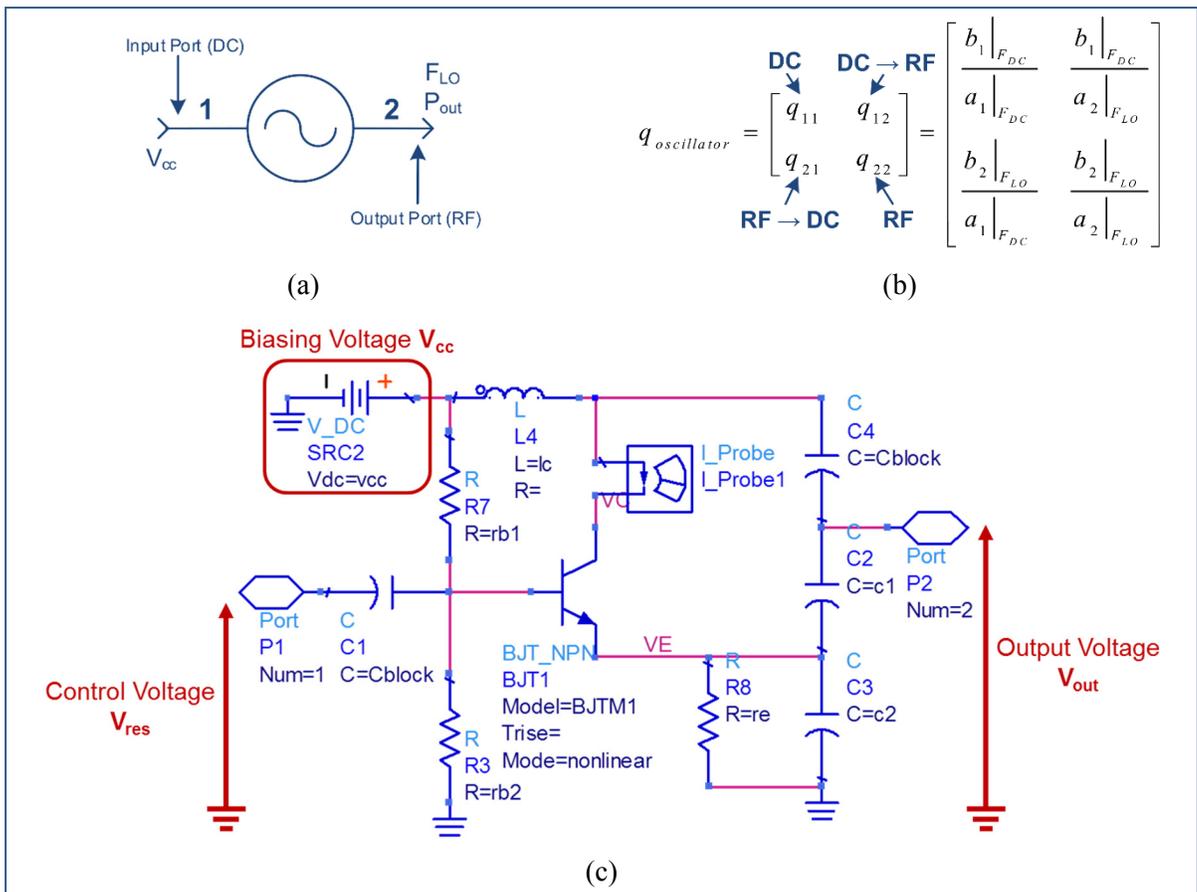


Figure 3.23 VCO's Q-matrix XML structure: (a) A voltage-controlled oscillator model, (b) its formal Q-matrix, (c) an example of a VCO circuit

<sup>53</sup> A Bipolar Junction Transistor (BJT) denotes a family of transistors that operates due to the interaction between three layers of two semiconductor types, one is positively-doped (i.e., P) and the other is negatively-doped (i.e., N).

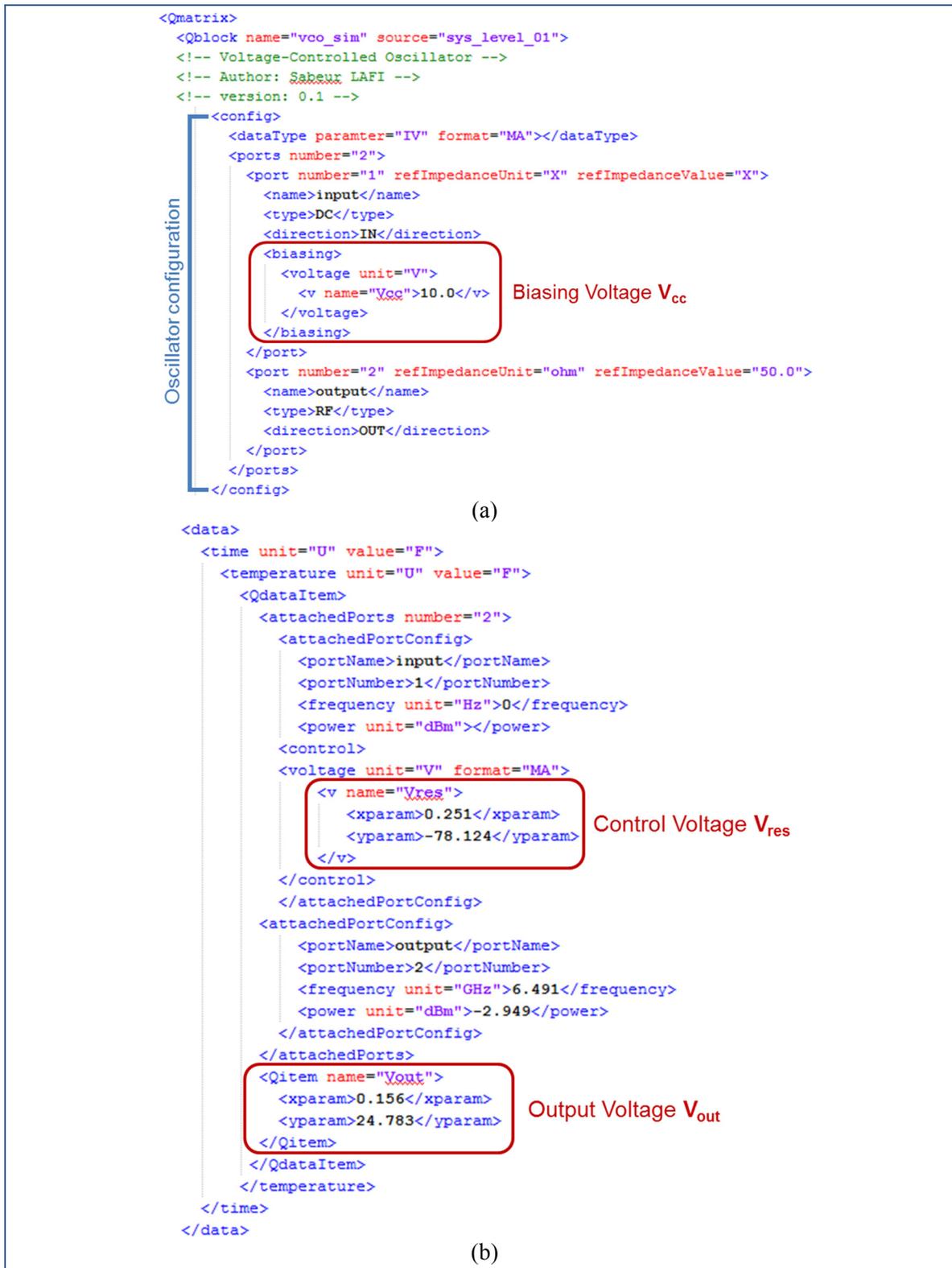


Figure 3.24 VCO's Q-matrix XML structure (cont'd): (a) the configuration section and (b) the data section (limited to only two points of control and output voltages)

Figure 3.24.a depicts the configuration section of the VCO's corresponding data file. It shows for example how the biasing voltage was captured and associated to the input DC port. Figure 3.24.b shows how the relationship between the input small-signal voltage  $V_{res}$  and the output analog signal  $V_{out}$  are captured. The output port's attached configuration shows the measured frequency and power values as well.

- **Amplifier's current-voltage characteristic**

Traditionally, an amplifier is considered as a two-port network. The biasing and DC control ports are often not considered like RF ports. This allows the use of scattering parameters to capture the small- and large-signal behavior of the device. Using the Q-matrix, all the ports can be considered. Figure 3.25.a shows a RF amplifier model with a biasing port and two RF ones. Figure 3.25.b depicts the corresponding Q-matrix. Similarly to the VCO case, the Q-matrix elements are pure wave ratios for RF ports (e.g.,  $q_{22}$ ,  $q_{23}$  and  $q_{33}$ ), DC voltage magnitudes for biasing ports (i.e.,  $q_{11}$ ) and a mix of leakage coefficients from RF to DC and vice versa when the RF and DC ports are involved (e.g.,  $q_{12}$ ). Figure 3.25.c shows an example of amplifier circuit. It is based on a BJT transistor that is biased by a DC supply voltage  $V_{CE}$  and a current source  $I_{BB}$ . These two parameters determine the transistor's operating point represented by the channel's current  $I_C$ . When varying  $V_{CE}$  and  $I_{BB}$ ,  $I_C$  changes. The range swept by these parameters results in the current-voltage characteristic (I-V curves). Figure 3.26 shows how these curves can be captured using the defined file format.

**d) Current usage limitations**

The Q-matrix is primarily a minimalist data structure that was conceived to capture RF devices' electrical parameters. These parameters are limited to device's time/frequency characteristics and do not cover its other properties. For instance, an antenna does not have a corresponding Q-matrix because it is not possible to capture its spatial properties using Q parameters.

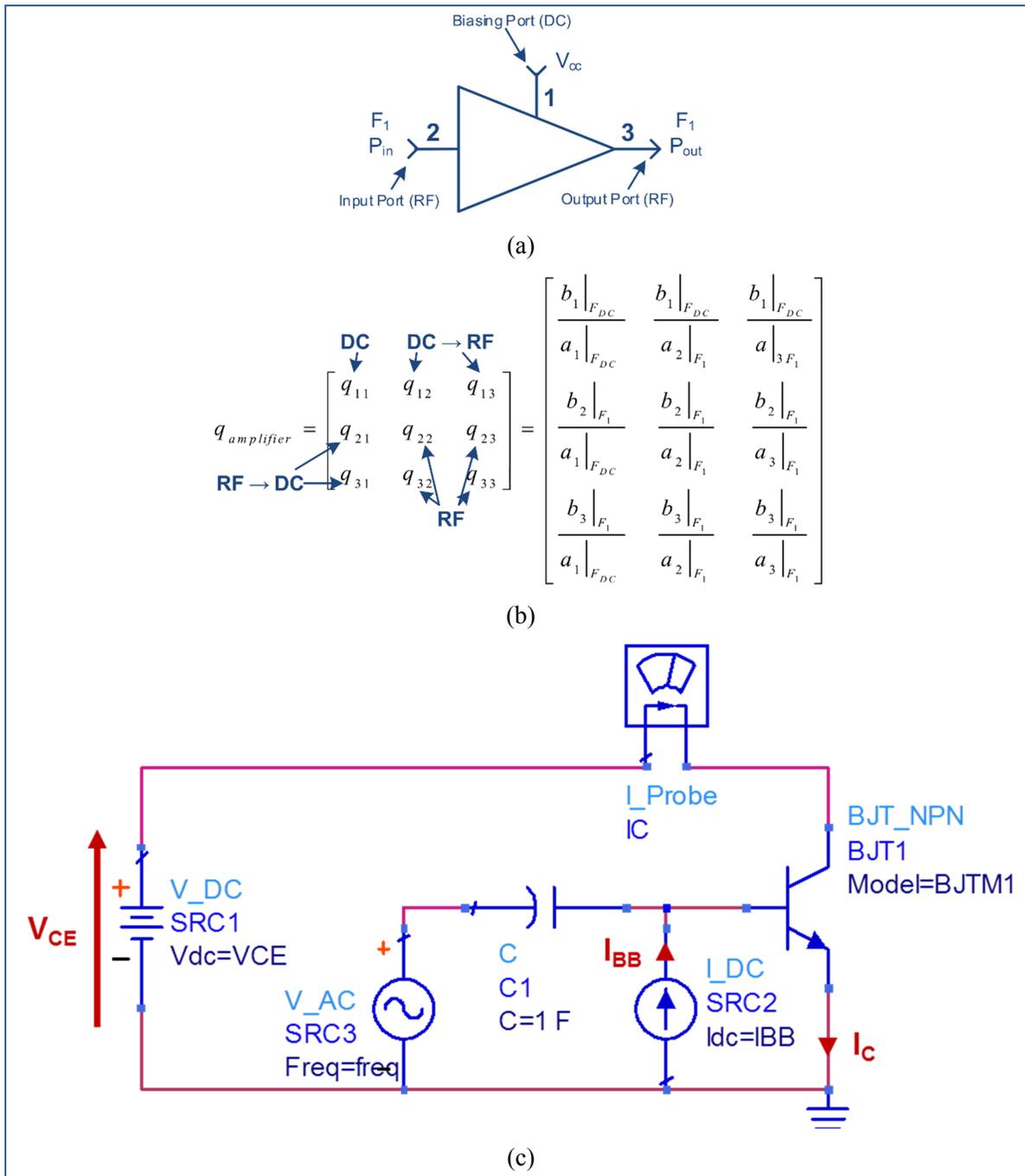


Figure 3.25 Q-matrix XML structure is also able to capture amplifier I-V data: (a) Amplifier model, (b) its corresponding Q-matrix and (c) an example of an amplifier circuit

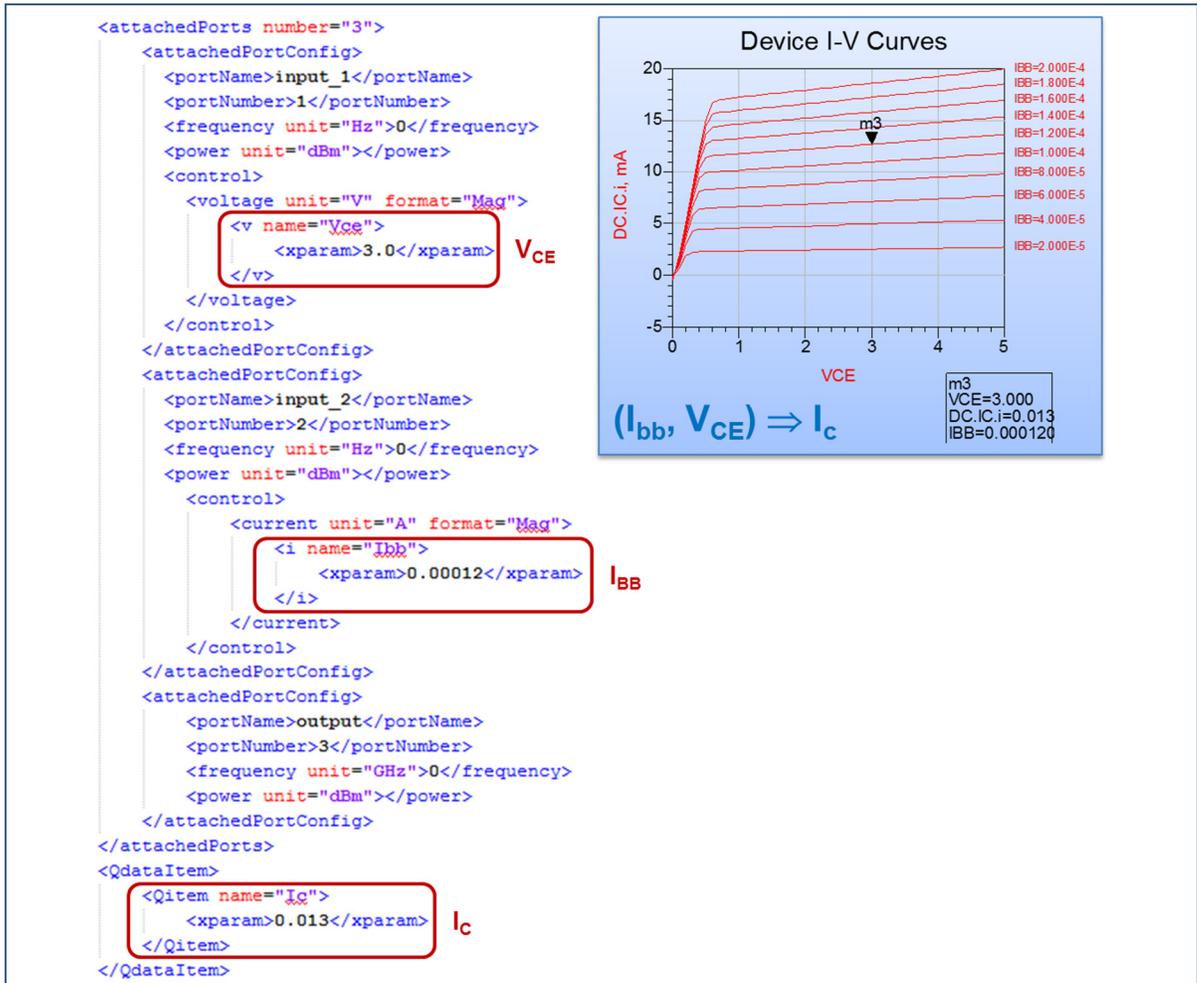


Figure 3.26 Q-matrix XML structure is also able to capture amplifier I-V data:  
The data file corresponding to the amplifier model of Figure 3.25

This said, various challenges should be addressed in order to make the Q-matrix effective and useful. The first is the need to develop tools that implement the corresponding formalism. The second is a wide adoption by the current RF commercial design frameworks and instruments. The adoption of the Q-matrix remains limited because most design frameworks and measurement instruments carry out linear and nonlinear simulations and tests separately. Then, it becomes difficult to consider Q-matrix elements in a mix of DC and RF ports at the same time. This is in fact a limitation of the current Q-matrix paradigm. To resolve this issue, the Q-matrix mathematical formalism should be extended further to derive useful relationships that can be easily and directly used to calculate the Q-matrix elements. Such formalism will be similar to those used in the derivation of the traditional scattering parameters as well as the

newly-introduced X parameters<sup>54</sup> (i.e., nonlinear scattering parameters) which gave birth not only to numerous EDA tools but also to measurement instruments (e.g., Vector Network Analyzer for S parameters and Power Network Analyzer X for X parameters). The derivation of an extended and complete Q-matrix mathematical formalism that could enable its immediate adoption by the industry requires an effort that falls beyond the scope of this thesis. It is an outstanding future work.

### 3.3.6 Summary View of the Proposed Design Flow

In order to address the various design challenges of paragraph 3.2, we have so far defined two main elements:

- A five-step design flow: it consists of a succession of five design stages that start with device's functional description. This allows to capture device's specifications using high-level modeling languages such as SysML/UML and to exchange them using XML. Then, this functional description can be validated in the analysis step where various system-level analyses may take place in the purpose of identifying an initial design solution to begin with. This design solution is used in the synthesis step for further optimization. Design partitioning is leveraged using granularity refinement. Implementation technology and physical details are considered using technology mapping. Once the final solution is optimized, it then can be manufactured and tested;
- The Q-matrix: it is a minimalist data structure for device's electrical properties that allows to store, share and compare design data from the early design stages throughout the device's operation phase. For this purpose, it is associated to a XML-based file data format that can embody any useful design, test or operation relevant information in addition to the Q parameters.

---

<sup>54</sup> X parameters denote a mathematical superset of S-parameters for nonlinear network analysis that is applicable for both small- and large-signal configurations. Verspecht, Jan. 2005. « Large-signal network analysis ». *Microwave Magazine, IEEE*, vol. 6, n° 4, p. 82-92., Verspecht, Jan, et David E Root. 2006. « Polyharmonic distortion modeling ». *Ibid.*, vol. 7, n° 3, p. 44-57.

Naturally, the need for enhancing communication between design stages suggests linking the Q-matrix with the design flow. Since it provides an effective design data centralization mechanism, it finds its place in the heart of this design cycle. At any design stage and in the context of a multi-user design project, designers can use the Q-matrix to store the electrical data related to their assignments, learn about the results obtained for the other parts of the project, include them in their designs if required, etc. This gives them a wide variety of opportunities to share, use, analyze, compare and assess electrical design data using a centralized multi-access mechanism.

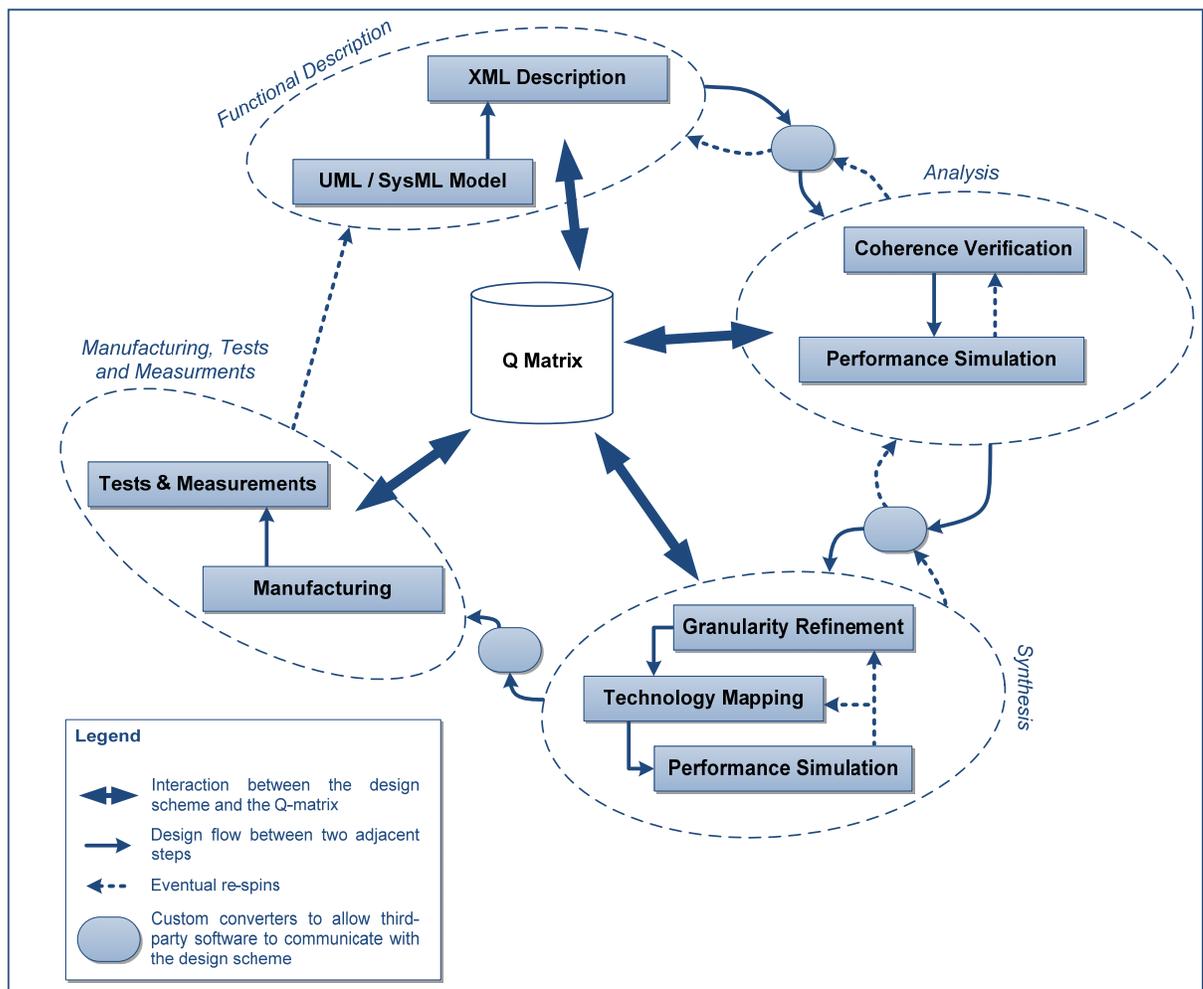


Figure 3.27 The proposed framework for RF and microwave design

As shown in Figure 3.27, the marriage between the design flow and the Q-matrix establishes a tool-neutral end-to-end design framework for RF devices. However, the fundamental changes in design concepts that are proposed in this framework may be incompatible with the current design tools and environments. For this reason, this framework has added specific converters between the different design stages in order to accommodate the various EDA tools currently in use. In fact, these converters allow the support of various data file formats and communication channels (e.g., co-simulation pipes) in order to reduce the incompatibility influence and allow the adoption of a wide range of existent simulation and design tools.

### **3.4 Mapping Framework Provisions to Designated Design Challenges**

The design framework was first proposed to address the design challenges enumerated in Table 3.1. As detailed in Table 3.7, the various mechanisms adopted in this framework are expected to bring contributions at different levels:

- Design flow: it was conceived to link the different design stages and streamline the design effort. Separate design stages and steps allow effective design partitioning and improve significantly collaboration between designers (A, P3) as well as enhancing design concurrency (A, P4). Given relevant design tools, the design flow allows effective design exchange (A, P2), reuse (A, P6) and technology insertion (A, P7) because design models, data and technology information can be provided at the appropriate design step and for the suitable design purpose;
- Functional Description: it is among the major contributions of the proposed design framework. By focusing on high-level modeling and XML storage, collaboration (B, P3), exchange (B, P2) and design reuse (B, P6) become easier because models are expected to be comprehensive and amenable for automation. Being model-centered, functional description brings a higher level of abstraction which allows the use of automated verification approaches for better design consistency (B, P5). However, this step does not influence technology insertion (B, P7) because it is not expected to deal with;
- Analysis: this step significantly enhances design consistency (C, P5). Using the models resulting from the functional description, it uses an approach of coherence verification and

- system-level analysis in order to check if these models are consistent. The use of models and relevant tools at this step allows also for better automation (C, P1);
- Synthesis: it is a concept that was conceived to address two main issues: automation and technology insertion. At this regard, this step embodies two mechanisms for enhancing automation. First, granularity refinement allows the search of the best design solution. Then, automated (or/semi-automated) design-to-manufacture procedures and tools are used for the implementation of this solution. Technology mapping is an intermediate step that is expected to include the relevant technology information;
  - Q-matrix: if design information are provided and exchanged using models, design data are centralized using the Q-matrix. This centralization provides simultaneous access for various designers and tools which enhances design concurrency and collaboration. The storage of multi-source and multi-purpose design data contributes to better design consistency. The XML data structure and metadata provides practical tools for data exchange and reuse. Tools interacts better through the Q-matrix. In addition, the interaction with the Q-matrix is tool-based which improves design automation.

The proposed design framework has brought new concepts in addressing major RF design issues. If analysis (including coherence verification and system-level analysis) and synthesis (including granularity refinement and technology mapping) are amenable for automation due to the algorithms and tools that can be developed to handle the design, these mechanisms use a basic ingredient: models that are developed during the functional description step. The absence of comprehensive and usable models compromises these steps. By opposition to other domains (i.e., digital design, software development, etc.) where the use of models is a habit, high-level modeling is not common in RF design. For this purpose, two issues should be resolved at this regard: effective models development and use. In addition, modeling activity should guarantee design independence from technology (particularly at higher levels of design). At this regard, we propose to deepen our research in hardware abstraction for augmenting the current framework (especially functional description) with mechanisms and concepts that contribute to resolve these issues.



### 3.5 Conclusion

In this chapter, we presented a five-step design scheme that redefines the main steps required for RF front-ends' design. The first step, namely "*Functional Description*", aims to uncouple the RF functionality from physical-level details. To do so, it captures the specifications using expressive modeling languages (e.g., SysML). The next step, namely "*Analysis*", allows validating the developed models using a mechanism of coherence verification. If the models are error-free, various system-level analyses may take place to figure out a suitable initial design solution that meets the specifications. This initial solution is used in the third design step, namely "*Synthesis*", to implement the final solution. This takes place through three sub-steps: The first optimizes the design solution by iterative granularity refinement. The second includes physical considerations in the design. Then, the resulting design is optimized and validated through performance simulations. The step of "*Synthesis*" is meant to provide a ready-to-manufacture design solution to be fabricated and tested in the following design steps (i.e., manufacturing and test and measurements). It is aimed to make the design process as much automated as possible. In the heart of the proposed design cycle, we defined a multi-dimensional data structure, namely Q-matrix, which holds all the electrical design data. On the contrary of existent data structures, the Q-matrix is not only accessible at all the design stages but also accompanies the manufactured design during the operation phase.

Each stage of the proposed design framework includes mechanisms that address some of the shortcomings and drawbacks encountered in today's design practice. By making design model-centric, this framework aims to raise the abstraction level, which allows better design space exploration and higher automation. However, it poses two significant challenges to designers: model development and usage. From practical point of view, designers should be able to develop models at different levels of abstraction and easily use them to derive design solutions. To overcome this practical issue with the proposed design framework, a clear abstraction strategy should be elaborated. Clear abstraction levels for RF circuits should be defined. For each of them, specific models are also dedicated. The next chapter attempts to discuss and resolve this issue.



## CHAPTER 4

### HARDWARE ABSTRACTION-BASED STRATEGY FOR RF AND MICROWAVE DESIGN

#### 4.1 Introduction

In the previous chapter, we presented the foundations of a new design methodology for RF/microwave devices. It consists of a five-step design scheme that starts with functional description. This first stage uses high-level modeling languages to capture the intended system's specifications. The corresponding models are then validated in the following step, namely analysis, which ensures the coherence of the captured specifications and enables the identification of an initial design solution, ideally in a technology-independent manner. This solution is then refined and optimized in the following design stage, namely synthesis, to develop a ready-to-manufacture solution. Various considerations are introduced in this step. For instance, technology details are included via technology mapping. Accordingly, the final layout is produced and verified. Once ready, manufacturing and test tasks can take place. All these design steps are built around the Q-matrix, a centralized tool-neutral data structure that captures the design electrical data throughout all design stages. Added to functional description, the modular Q-matrix enables better design productivity through enhancing design collaboration, concurrency and empowering tools interaction.

As previously mentioned, the proposed design methodology introduced several mechanisms in order to alleviate the main challenges facing modern RF design. In particular, functional description allows for a higher-level of abstraction, which contributes to productivity enhancement and automation improvement. Despite the fact that using high-level modeling for functional description enables the access to higher levels of abstraction, the development and mainly the use of the corresponding models impose significant challenges. First, clear abstraction levels are needed in order to unify the view of RF devices. Then, moving from an abstraction level to another requires formal mechanisms. Finally, the interference of technology considerations within each design stage should be better controlled in order to

avoid premature design loops and maintain an efficient design space exploration. To do so, we propose in this chapter to investigate further the existing strategies of hardware abstraction in the aim of elaborating a coherent abstraction strategy to streamline with the proposed design framework. In the first section of this chapter, we review the abstraction concepts in different engineering domains ranging from digital and mixed-signal design to other engineering domains such as software development. In the light of this review, we propose in the second section a hardware abstraction strategy for RF design. Then, we propose the “SysML profile for RF devices” which provides a modeling template in accordance to the abstraction strategy in order to help designers developing functional descriptions for RF devices and systems. Finally, we streamline the abstraction strategy with the design scheme of chapter 3 within a complete design framework.

## 4.2 Hardware Abstraction in Various Domains

Hardware abstraction is a concept that has proven its usefulness in various engineering domains. In this first section, we present this concept in some detail. Then, we review the hardware abstraction strategy in use in domains close to RF design, namely digital and mixed-signal design. We extend this review to include other successful experiences such as hardware abstraction strategies used in computer engineering and software development.

### 4.2.1 Definition and Advantages

Abstraction is defined by Dictionary.com<sup>55</sup> as “*the act of considering something as a general quality or characteristic, apart from concrete realities, specific objects, or actual instances*”. The psychologists Goldstone and Barsalou assert in (Goldstone et Barsalou, 1998) that “*to abstract is to distill the essence from its superficial trappings*”. The sixth edition of Oxford Dictionary of Computing<sup>56</sup> defines abstraction as “*the principle of ignoring those aspects of a*

---

<sup>55</sup> Dictionary.com (whose website is [www.dictionary.com](http://www.dictionary.com)) is a company that presents itself as a provider of online “*reliable access to millions of English definitions, synonyms, audio pronunciations, example sentences, translations and spelling help through [its] services*”.

<sup>56</sup> The Oxford Dictionary of Computing is a computer science dictionary that is published by the Oxford University Press.

*subject that are not relevant to the current purpose in order to concentrate more fully on those that are*” (Rozenberg et Vaandrager, 1998). Therefore, all these definitions suggest that abstraction is the act of uncoupling the fundamental characteristics of an object from the details of its construction. Thus, its main purpose is presenting a simplified view of a complex reality by hiding its unnecessary attributes and aspects. This is why abstractions can be of various types due to real world complexity. For example, an abstraction may be mathematical in a way that only the equations describing the fundamental characteristics of an object are considered. It can also be physical that the fundamental nature of that object is considered without any other specific attributes (Saitta et Zucker, 2013). In a myriad of disciplines (e.g., art, cognition, vision, etc.), abstraction is often informal because it uses “lossy” mechanisms (e.g., generalization, approximation, etc.) in order to hide irrelevant aspects of a real-world object. The resulting object’s representation is often deprived of useful information. However, rigorous domains, particularly related to engineering (e.g., computer science, artificial intelligence, digital design, etc.) use formal models to make abstraction of objects, systems and programs (Saitta et Zucker, 2013). Modeling introduces the concept of abstraction level that allows recovering the discarded information when required. In this regard, an appropriate model for abstraction should satisfy at least two properties (Saitta et Zucker, 2013):

1. Reasonability: the conceptualization must produce results understandable by and close to those produced by human reasoning, and
2. Automation and usability: the model can be derived into appropriate implementations using suitable tools.

As explicitly presented in (Saitta et Zucker, 2013), the major benefits of abstraction can be summarized as following:

- Simplicity: abstraction reduces complexity by producing an object view as simple as possible;
- Relevance and information control: abstraction is meant to capture only the relevant aspects of an object. This includes the control of the information amount needed to describe that object at a given level of abstraction;

- Granularity: an object can be described at different levels of detail. Consequently, capturing fewer details results in more abstract representations and vice-versa;
- Uncoupling abstract from concrete views: object abstraction provides a distance with its concrete status. The most the concrete status is hidden, the highest the abstraction level is;
- Naming: at a given abstraction level, the object name becomes the synonym of the object properties and attributes accessible at that level of abstraction. This strong semantics allow easier understandability of a complex system;
- Reformulation: an abstraction is not unique which makes it easy to reformulate the same object properties in different formal ways that can be suitable for different scenarios.

In summary, the major benefit of abstraction remains its ability to manage complexity and simplify complicated systems. For this reason, some computer architects consider that *“abstraction is probably the most powerful tool available to managing complexity”* (Archer, Head et Yuan, 1996). This said, most engineering literature uses frequently the term *“Hardware Abstraction Layer”* (HAL) rather than *“Abstraction”* and *“Hardware Abstraction”* (e.g., sensor networks (Handziski et al., 2005), System-on-Chip (Yoo et Jerraya, 2003), etc.) to refer to the adopted abstraction strategies. This is typically related to the layered nature of the systems using this HALs. For instance, HAL is well known and predominant in computer systems because it serves as a logical division that makes the link between software and hardware layers.

As far as the RF design is concerned, we define *“Hardware Abstraction”* in this thesis as *“the concept of masking physical details of hardware, allowing the designer to focus on the RF functionality rather than the details of its implementation”*. Thus, it is a way to describe the functionality without considering the physical implementation details of a communication system. We also use the term *“Hardware Abstraction”* instead of *“Abstraction”* to express the predominant technology-dependent aspects of RF design.

#### 4.2.2 Hardware Abstraction in Digital and Mixed-Signal Design

As mentioned in chapter 1, adding more functionality while reducing chip area and power consumption leads to growing complexity. Managing that complexity is a major challenge in both digital and mixed-signal design. For decades, digital designers have been successful in alleviating their design's complexity due to the hierarchical design approach they adopted for this purpose (Gerez, 1999; Rabaey, Chandrakasan et Nikolic, 2002; Rubin, 1987). That design approach consists of partitioning a complex system into several subparts which are arranged in a given hierarchy. Each level of this hierarchy is arranged in a way that it fully characterizes a given perspective of the design. The details of the lower levels are not needed to functionally describe that perspective. At this regard, hardware abstraction has played an important role for two main reasons. First, it enabled a coherent mechanism to hide the underlying details without losing them. In fact, the characteristics of each component (e.g., structure and behavior) are captured by a black-box view (i.e., commonly called model). The model represents a given functionality and presents all the information required to deal with the component at the next level of hierarchy (Rabaey, Chandrakasan et Nikolic, 2002). Second, it enabled an effective divide-and-conquer process that carefully breaks up the design into smaller pieces making them easier to implement and verify. Each piece corresponds to a model that abstracts the lower levels by creating a new representation of them. This representation is able to fully describe the characteristics of the underlying structure without recalling its composition details (e.g., physical, circuit, logical, etc.). Accordingly, design complexity is then substantially reduced (Rabaey, Chandrakasan et Nikolic, 2002).

##### a) Abstraction levels

To raise the abstraction level in digital design, a new representation (i.e., is associated) should be created for each design viewpoint. In this regard, the nature of digital design (i.e., discrete and linear) and the implementation technologies (i.e., silicon-based) were of great value to designers. First, the physical properties of devices were captured by electrical circuits. Since the digital signals are mainly discrete, these circuits were gathered to create logical gates that can be fully characterized using Boolean equations. Then, these gates can be arranged to build more complex logical functionalities (e.g., multiplexers, adders, multipliers, etc.). These

elementary functionalities can be parts of more complex ones as well. All these representations are in fact equivalent but depict the device at different levels of detail and complexity.

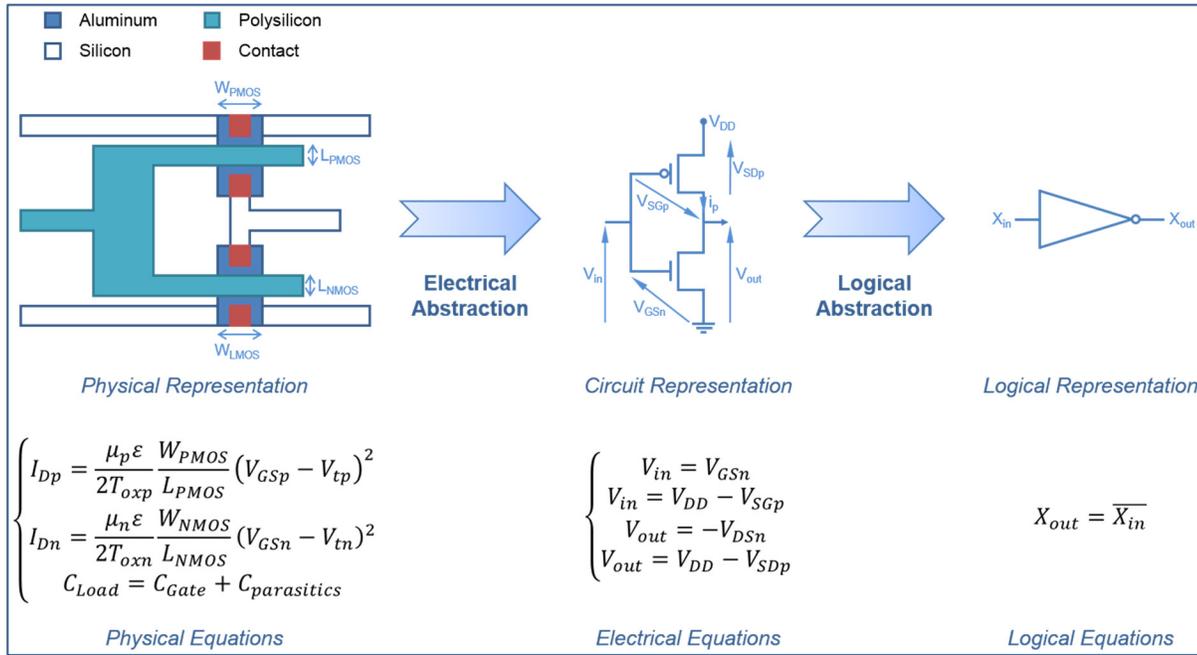


Figure 4.1 Every abstraction level corresponds to a new representation (i.e., model)  
Adapted from Dewey (2000, p. 908)

To illustrate this outstanding paradigm, Figure 4.1 presents three levels of abstraction that are considered in a typical CMOS inverter: the first one depicts the physical representation of a device composed by the interconnection of two PMOS and NMOS transistors. The technological parameters (e.g., parasitic drive capacitance  $C_{Load}$ , transistor dimensions, namely  $W$  and  $L$ , and oxide thickness  $T_{ox}$ ) are well-defined in the equations considered for performance characterization at this level. The first abstraction consists of in considering the circuit representation of the inverter instead of its physical layout (i.e. electrical abstraction). Thus, the physical details of the CMOS inverter are replaced by its electrical model that is characterized by its terminal voltage and current relationships (e.g.,  $V_{in} = f(V_{in}, i_p, V_{DD})$ ). This model reduces the complexity of the physical representation but can also be abstracted by a new representation that simplifies further its electrical information. To do so, it is substituted by a logical representation (i.e., logical abstraction) that describes the inverter as a logical gate

(i.e., in this case a NOT gate). This logical model can be formally characterized using Boolean algebra equations and the related characterizations such as truth tables (Dewey, 2000).

In practice, this paradigm gave birth to five<sup>57</sup> distinct levels of abstraction which are commonly defined as following (see Figure 4.2) (Rabaey, Chandrakasan et Nikolic, 2002):

1. Device: it is the lowest level of abstraction. It gathers the physical components that cannot be conceptually broken further. They are generally considered as the leaves of the design hierarchy. Among the components defined at this level, we count transistors, capacitors and resistors;
2. Circuit: it is the level where devices are assembled in and represented by a block based on their electrical characteristics (e.g., voltage, current). The corresponding abstraction is electrical;
3. Gate: this level abstracts circuits into logical elements that can be defined by Boolean algebra equations and related truth tables. The logical abstraction veils all the underlying physical and electrical information. Signals at this level are no longer continuous. The interaction with the gate is made via discrete-time signals following a given rhythm (i.e., generally controlled by a reference clock) through designated input and output ports;
4. Module: a module is a collection of gates implementing a given functionality (e.g., add, multiply, select, etc.). The corresponding abstraction is functional;
5. System: a system is a collection of modules that should meet given specifications. It is commonly considered as the highest abstraction level since a system can be defined as a “system of systems”. Designers focus mostly on the system’s architecture. The architectural view describes how the underlying modules are interconnected, configured and should interact. High-level algorithms, modeling languages and paradigms are frequently used to describe the system’s architecture (e.g., VHDL, Verilog, Petri nets).

---

<sup>57</sup> In some references (e.g., Xiu, Liming. 2007. *VLSI circuit design methodology demystified: a conceptual taxonomy*. John Wiley & Sons.), only four abstraction levels are considered. The circuit and gate levels are considered as a unique abstraction level that is referred to as “cell level”.

In fact, abstraction levels are practically useful when considered in the context of a design flow. The abstraction levels of Figure 4.2 result into three distinct design domains (see Figure 4.3) (Gerez, 1999):

1. The behavioral domain: in this domain, the design relies on behavioral models. A behavioral model is a black-box view of the part (or collection of parts) under design. It does not make any reference to technology nor needs any physical details as prerequisite to work. This type of models is based on mathematical formalisms, algorithms and/or sequential interaction diagrams (e.g., state machines) in order to define how the modeled part or system works. Its structure defines a set of input and output parameters. The input parameters can be used to provide data (e.g., stimulus, measurements, etc.) to the model and the output parameters make it possible to evaluate the model's response. The accuracy of the model depends on its formal definition and the quality of data that is provided (Arabi et Ali, 2008; Gerez, 1999). Behavioral modeling can be typically used at all abstraction levels. At the physical level, a device can be described by its intrinsic physical parameters. For example, a transistor can be defined by the relationship between its channel current and its gate, drain and source voltages. At circuit level, the relationships between the various voltages and currents can define how a given circuit works. At a logical level, Boolean algebra equations are enough to describe how gates and logic units operate. At higher abstraction levels, algorithms and paradigms can describe the behavior of a system or a collection of subsystems (Gerez, 1999);
2. The structural domain: what matters the most in this domain is the system's (or subsystem's, device's) structure. It is almost exclusively interested in the description of the subsystems (or sub-circuits) composing the system and how they are interconnected together. This structure is commonly represented by algorithms (e.g., "ENTITY" in VHDL and "SC\_MODULE" in SystemC) at the higher abstraction levels (i.e., functional and architectural) or captured in a graphical schematic at the other levels. Generally, a circuit can have one or more behavioral descriptions associated to its structure representation (Gerez, 1999);
3. The physical domain: it is also called the layout domain. Since the final output should be a physical implementation of the system, this domain is interested on how the parts and

subparts identified in the structural domain are physically located and interconnected on a three-dimensional (3D) plane (Gerez, 1999). A layout holds the information about each component's geometric shape (e.g. polygon), composing material (e.g., aluminum, polysilicon), coordinates (i.e., 3D location), and interconnections with other components (e.g., vias) (Dewey, 2000).

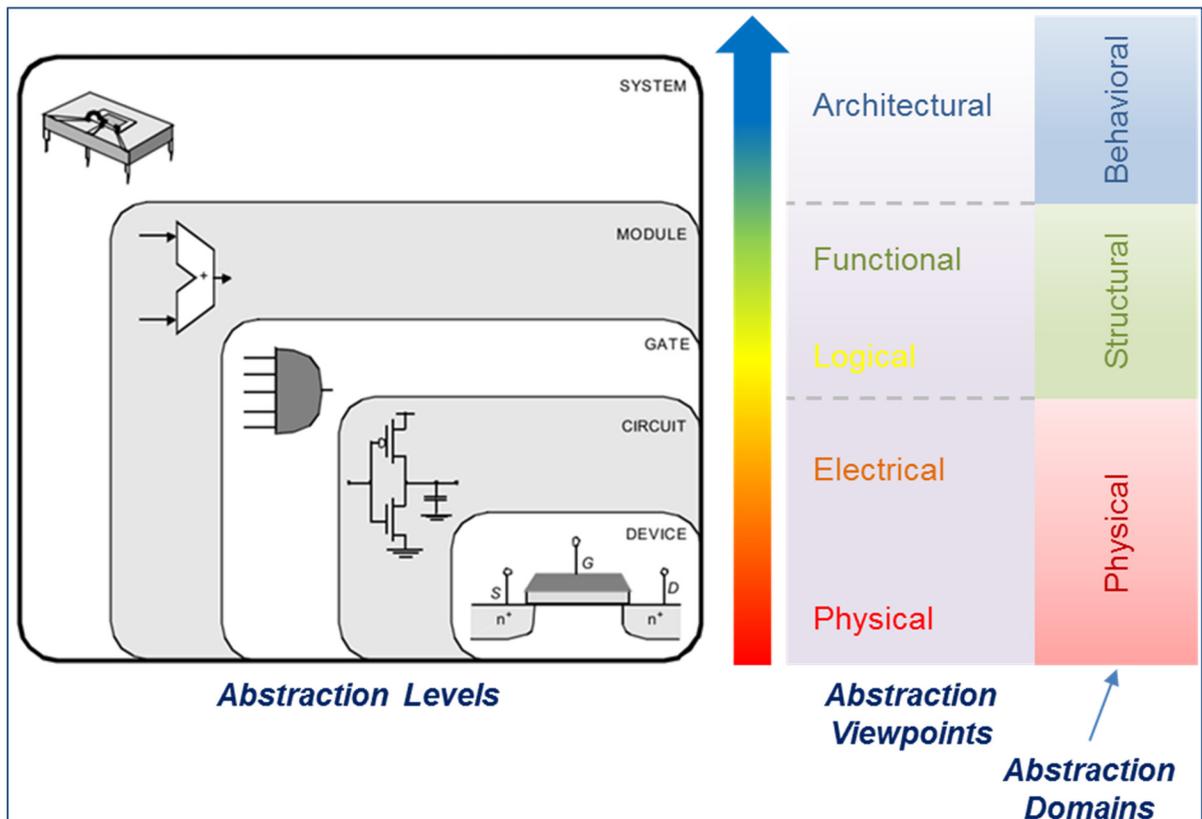


Figure 4.2 The five abstraction levels in digital circuit design correspond to five abstraction views subdivided into three distinct design domains  
Adapted from Dewey (2000); Rabaey, Chandrakasan et Nikolic (2002)

In 1983, these domains and the corresponding abstraction hierarchy were introduced by Gasjki-Kuhn in the “Y-chart” (see Figure 4.3) (Gajski et Kuhn, 1983). This chart is subdivided into three regions crossed by five concentric circles. Each region represents a design domain while the circles represent the different levels of abstraction. The inner one corresponds to the lowest abstraction level, which increases as far as we move away from the center. Moving from an axis to another and from a circle to another expresses how a manual design can be refined on a step-by-step basis. It allows also the identification of the various design choices and trade-

offs by doing a systematic exploration of the design space (Kienhuis et al., 2000). Figure 4.4 illustrates how a simple functionality is represented throughout the Y-chart levels and domains.

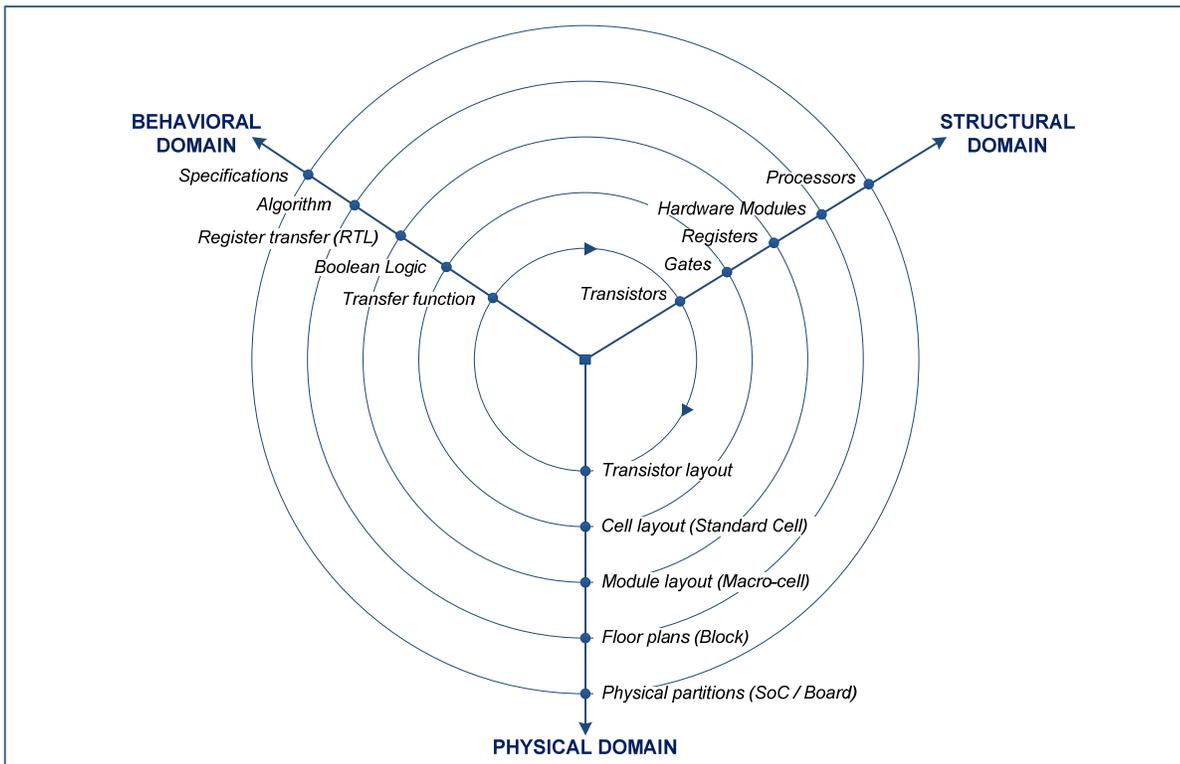


Figure 4.3 The three-domain five-abstraction-level Gajski-Kuhn's Y-chart  
Adapted from Balkir, Dündar et Ögrenci (2003); Gerez (1999); Grout (2008)

Consequently, the top-down design of a digital system at architectural and functional levels is a back and forth flow between the behavioral and structural domains at different levels of abstraction. For instance, if a microprocessor is defined by a set of specifications, its composing hardware modules are captured by an algorithm. Hardware modules are composed of different components such as registers. The interaction between these components is described using register transfer language<sup>58</sup>. Each component consists of a set of gates that are characterized by Boolean logical equations. Each gate is implemented using a set of transistors

<sup>58</sup> Register Transfer Language (RTL) is a language that is used to specify the operations, register communication and timing constraints (i.e., schedule) related to high-level instructions used within a digital circuit.

and low-level devices. These devices are characterized by their respective transfer functions. When it comes to physical implementation, the microprocessor is hierarchically built.

The various components are assembled and connected after relevant placement and routing. This example (depicted in Figure 4.5) shows how the hierarchical top-down design flow, widely adopted in digital design, is practically mapped to the five abstraction levels of a circuit and the related design domains.

### **b) Impact of hardware abstraction on digital design**

In the 1970s, designers were directly tweaking few thousands of transistors. The first microprocessor, namely Intel 4004 counted approximately 2300 transistors (and was fabricated in 1971 using 10-micron manufacturing technology). However, a typical Intel 22nm-processor counts more than 1.4 billion transistors in 2012 (Intel, 2013a). The emergence of new levels of abstraction (e.g., logical abstraction in the 1980s, the functional abstraction in 1990s and the architectural abstraction in early 2000s) had a major impact on the complexity management of digital devices (Figure 4.6 depicts the evolution of abstraction levels between the 1970s and the early 2000s). Raising the abstraction level in digital design resulted in better design methodologies and mature EDA tools used in performing enhanced design space exploration and simplifying the verification tasks at each design step (Lin, 2005). These tools allowed managing growing design complexity and the continuous shrinkage of fabrication technology. This is illustrated in Figure 4.7 that depicts how the EDA tools have evolved over decades in conjunction with IC technology and design methodologies evolution. The evolution tendencies of IC technology and design complexity can also be seen in Figure 1.5.

Moving to higher abstraction levels is effective when it becomes possible to automate, at least most of, the required steps to move backward towards lower ones. In practice, this means that effective enhancements of design and verification tools have taken place in order to alleviate more complex systems. Thus, designers become able to implement higher-density chips (see Figure 4.8).

### c) Particularities of analog and mixed-signal design

The impact of hardware abstraction on complexity reduction and design management in digital domain created a significant interest in analog and mixed-signal design where there is a need for more functionality in reduced area and at low-power consumption. However, there are significant disparities between digital and analog design. If the digital design is all about time-domain, discrete and noise-immune signals, analog designers deal with frequency-domain, continuous and noise-prone circuits.

In addition, the analog circuits suffer from nonlinearity that often requires each one to be tweaked and optimized separately. This adds more complexity in analog design. Mixed-signal systems, where digital and analog circuits are combined, are also complex in nature (see Chapter 1). Since analog/mixed-signal circuits can be implemented using silicon-based technologies (mostly used in digital design), it was possible to develop an analog/mixed-signal abstraction hierarchy similar to what is already available in the digital domain. Four abstraction levels were defined to deal with analog/mixed-signal design (De Smedt et Gielen, 1999; Saleh, Jou et Newton, 1994):

1. Functional: at this level, the analog system is described in terms of mathematical functions using mixed-signal hardware description languages. No conservation laws are defined for each interconnection node (De Smedt et Gielen, 1999). At this level, behavioral simulations are used because the function of the block is known but its detailed structure is not. Transfer functions are used to capture the block's functionality. Interaction between functional blocks is captured using signal flow charts. Specific hardware description languages (e.g., Verilog-A, VHDL-AMS) are generally used for this purpose (Saleh, Jou et Newton, 2013);

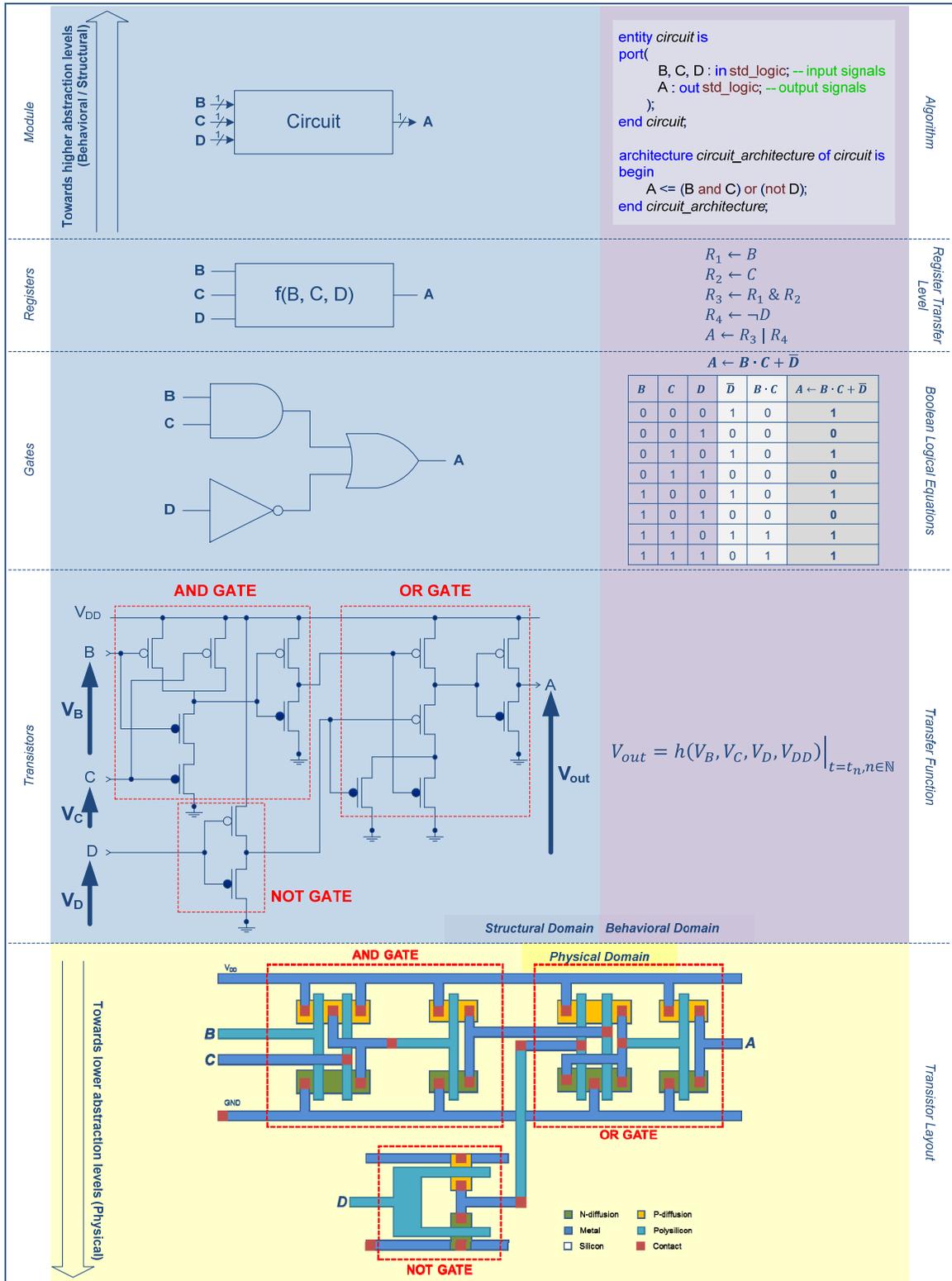


Figure 4.4 A digital functionality design changes its representation when it gradually goes through the behavioral, structural and physical domains

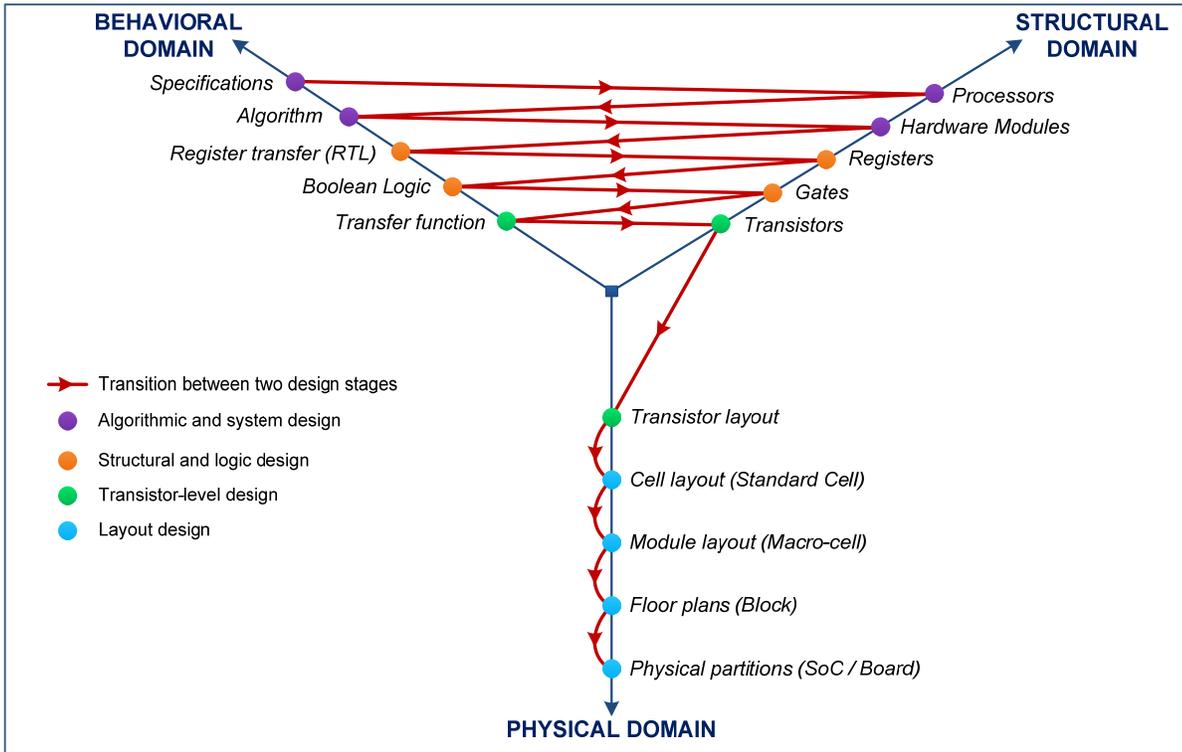


Figure 4.5 A top-down design flow mapped to the abstraction levels and design domains of Gajski-Kuhn's Y-chart results in a back and forth top-down process  
 Taken from Gerez (1999, p. 7)

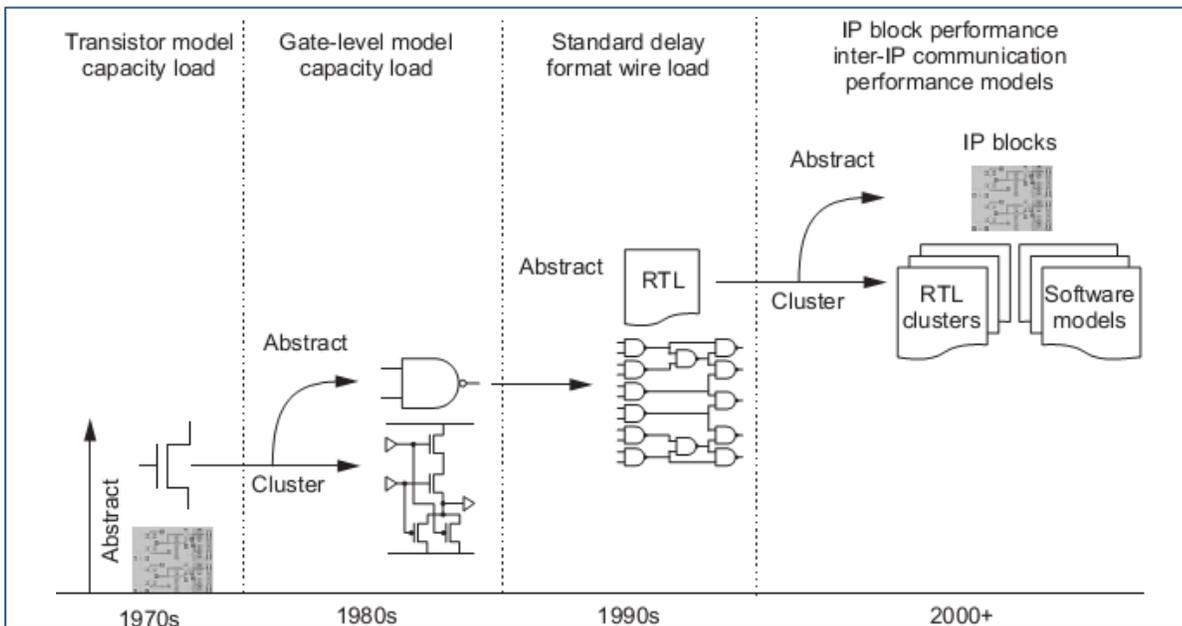


Figure 4.6 Raising the abstraction levels allowed more complex device models  
 Taken from Sangiovanni-Vincentelli (2003, p. 67)

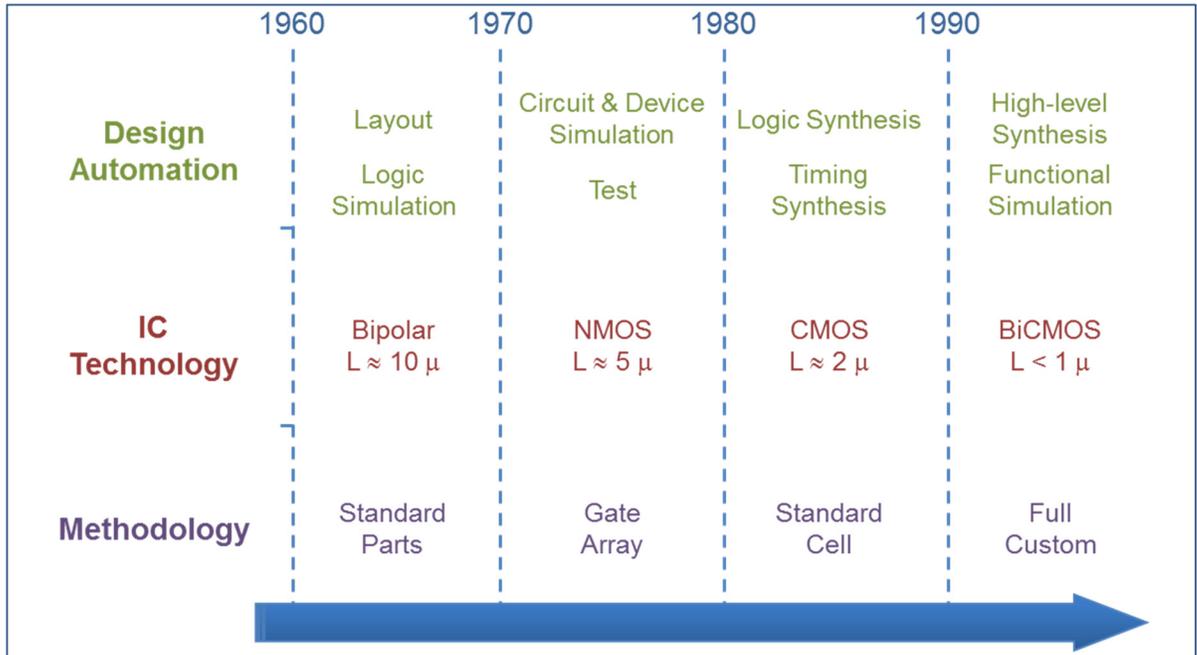


Figure 4.7 Design automation tools, IC technologies and design methodologies in microelectronics have evolved jointly with abstraction levels  
 Taken from Dewey (2000, p. 907)

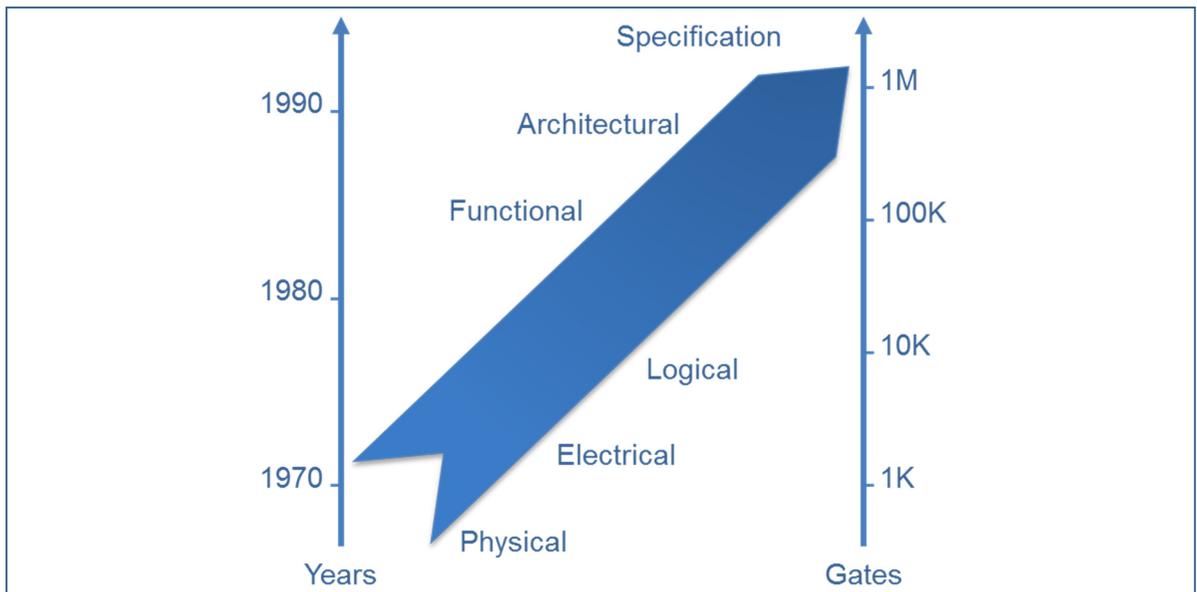


Figure 4.8 Higher abstraction levels enable the design of more complex chips  
 Taken from (Dewey, 2000, p. 908)

2. Behavioral: at this level, the mathematical descriptions are derived into high-level building blocks (e.g., linear transfer functions, signal converters, operational amplifiers, etc.) (De Smedt et Gielen, 1999). The type of simulations associated to this abstraction level is called “Ideal Functional Simulation”. It consists of exclusively considering transfer functions associated to each building block as linear/ideal. The purpose of these simulations is to validate an initial design solution that may be optimized further in the following design steps (Saleh, Jou et Newton, 2013);
3. Macro: at the macro level, the higher level building blocks are derived into electrical circuits composed of elementary components (e.g., transistors, lumped components, current sources, etc.) (De Smedt et Gielen, 1999). The simulations carried out at this level are called “Non-Ideal Functional” because the use models including the first- and second-order details. These models, commonly called macro-models, capture the individual behavior of each building block by putting together a number of (linear and/or nonlinear) elementary components (Saleh, Jou et Newton, 2013);
4. Circuit: it is the lowest abstraction level where the elementary electrical components are replaced by their physical counterparts (De Smedt et Gielen, 1999). Since the circuit representation corresponds to the most detailed abstraction level, electrical simulations are used to carry out extended performance assessment in both time and frequency domains (Saleh, Jou et Newton, 2013).

These abstraction levels are mapped in Figure 4.9 to those adopted in digital design along with the related simulation types. It is worth noting that there is a slight difference in terminology between the two domains. The architectural level in digital design is similar to the functional one in analog/mixed-signal. However, the functional level in the latter is equivalent to the behavioral level in the former. The reason behind this is mostly related to the design practice in both domains. In fact, the architectural level in digital design often leads to the definition of an extended hierarchy of functionalities (i.e., “system of systems”). Nevertheless, in analog/mixed-signal design, the complexity of the system is often limited to a small set of functionalities. In addition, the differences in terminology are related to the types of signals used in both domains (e.g., logical/electrical/physical in digital domain versus macro/circuit in analog/mixed-signal design). Since the notion of time in analog and digital design is not the

same, gate and logic levels in digital domain are replaced by the macro level in analog domain. Figure 4.10 depicts the common abstraction levels in analog/mixed-signal design along with the related simulation types. This illustrates the representation of an analog circuit as well as the required simulations at each abstraction level.

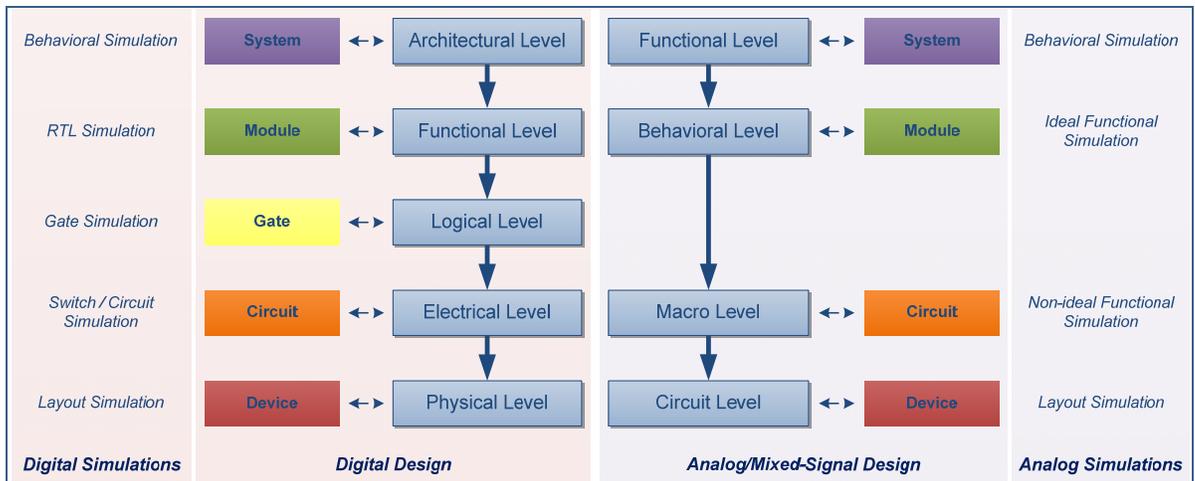


Figure 4.9 Notable differences between abstraction levels in digital and analog/mixed-signal design  
Adapted from De Smedt et Gielen (1999); Saleh, Jou et Newton (2013)

To illustrate further the abstraction philosophy adopted in analog/mixed-signal design, Figure 4.11 shows the representation of a typical operational amplifier in different abstraction levels in analog domain. At the functional level, the operational amplifier is described using an analog/mixed-signal hardware description language (e.g., Verilog A). At the behavioral level, it is represented as a high-level electrical block where its inputs and outputs are emphasized. At macro level, the implementation of this block is detailed at the circuit level where it is replaced by an assembly of elementary elements. At the circuit level, the operational amplifier is represented by its physical layout (Saleh, Jou et Newton, 2013).

Hardware abstraction is of great interest for both digital and analog/mixed-signal designers not only for its capability to manage design complexity but it also reduces the time needed for design verification at each design level. As shown in Figure 4.12, for each central processing unit (CPU) cycle spent at the highest level of abstraction for design simulation, its underlying abstraction level requires 10 to 100 times CPU time to carry out the same simulations (this

observation are based on data published in (Saleh, Jou et Newton, 2013)). However, the accuracy of simulation is better in lower abstraction levels than the highest ones. This confirms again the interest of higher levels where initial design solutions can be easily and rapidly figured out due to enhanced design space exploration. If so, lowering the abstraction level becomes fruitful and provides accurate and rapid final design solutions.

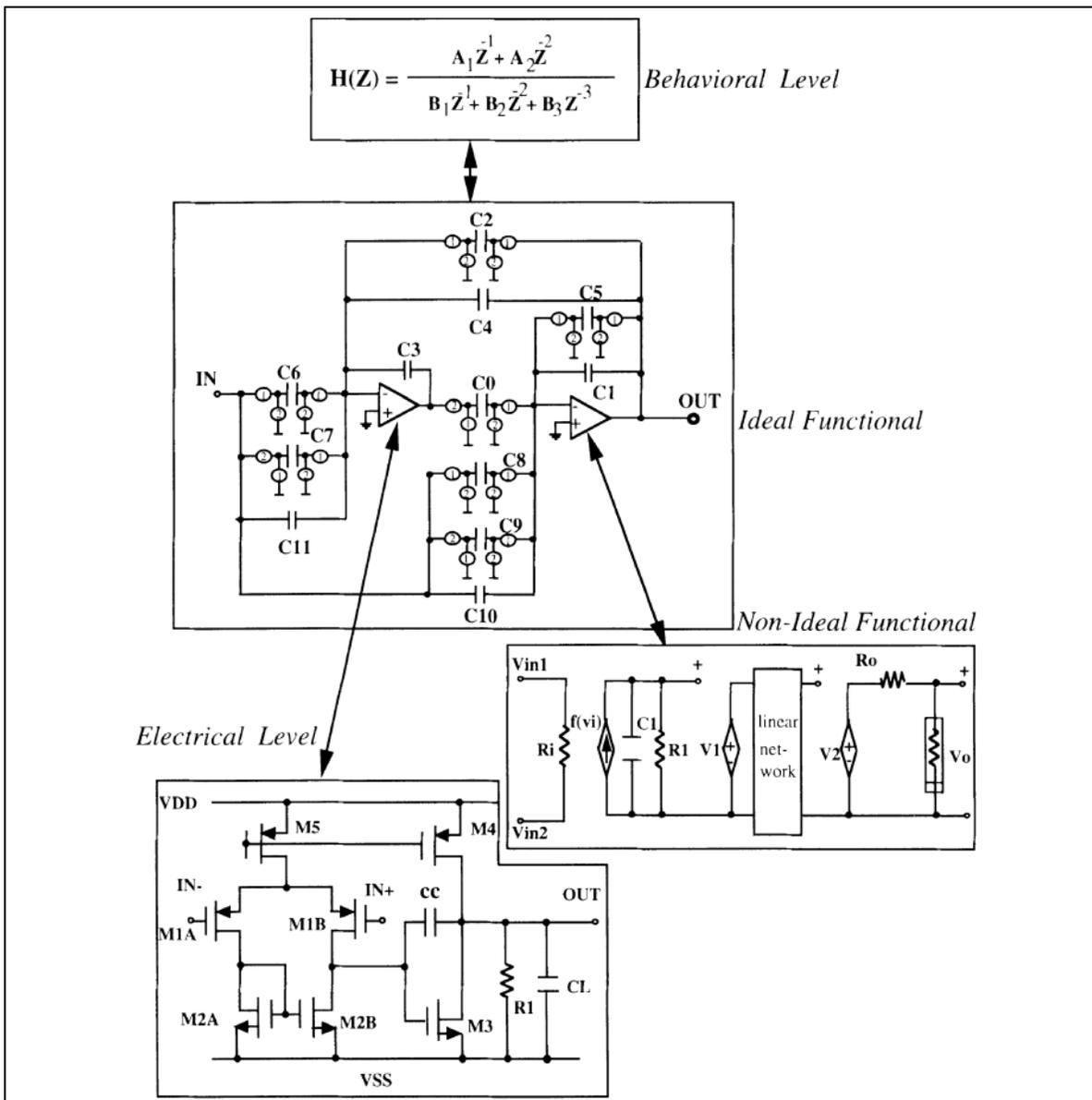


Figure 4.10 A specific simulation type corresponds to each abstraction levels in analog/mixed-signal design  
 Taken from Saleh, Jou et Newton (2013)

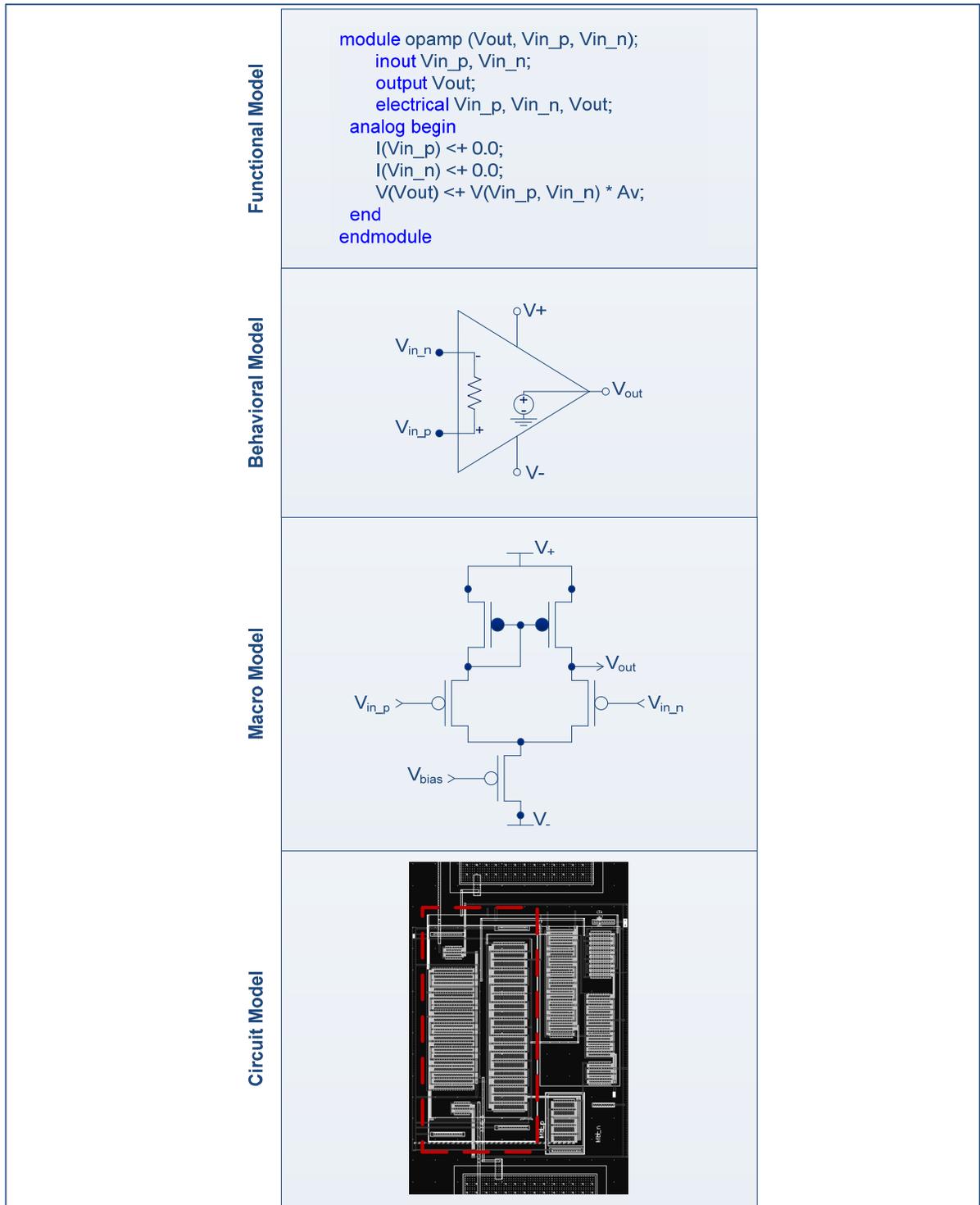


Figure 4.11 An example of how abstraction levels are applied to analog/mixed-signal design: A differential operational amplifier design starts as HDL description at functional level and ends with a useful layout at circuit level

Adapted from CIC (2003)

Layout photo taken from Parihar et Gupta (2009)

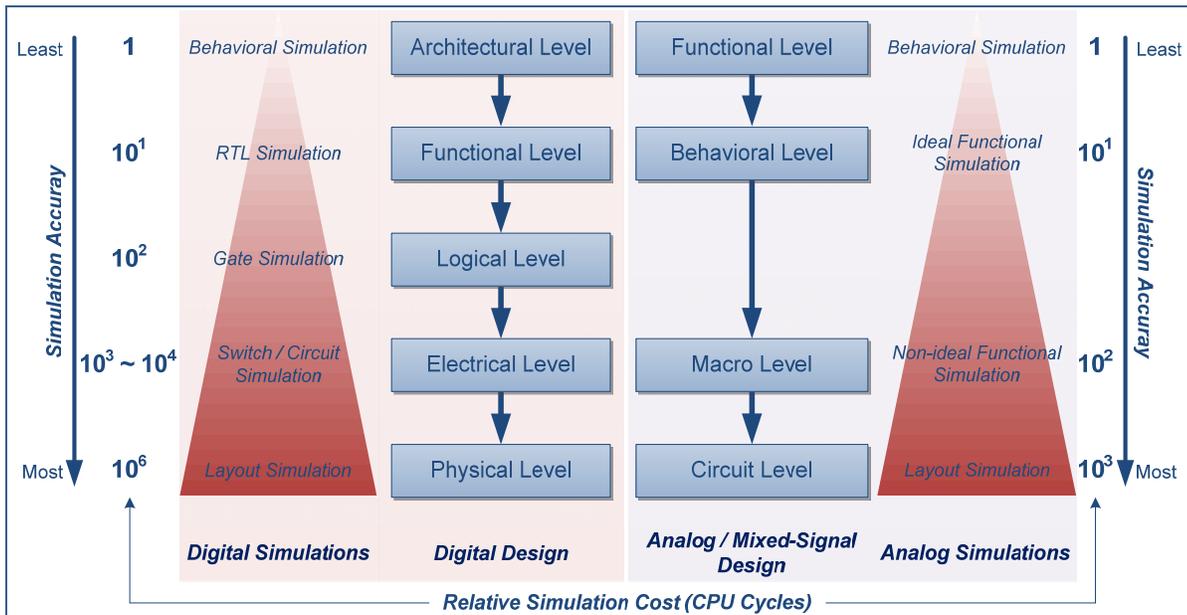


Figure 4.12 Each abstraction level corresponds to simulation type that is more time-consuming but accurate from higher to lower levels  
Adapted from De Smedt et Gielen (1999); Saleh, Jou et Newton (1994)

### 4.2.3 Hardware Abstraction in Computer Engineering

In the previous section, we investigated the hardware abstraction strategies applied to both digital and analog/mixed-signal design as well as their provision and impact on these domains. In order to discover other abstraction strategies, we aim to push this investigation beyond digital and analog/mixed-signal domains. For this reason, we present in the following how hardware abstraction is applied to computer systems and networks. In particular, we review hardware abstraction layers used in operating systems, internetworking and databases. It is worth noting that this review is meant to be as simple and brief as possible for illustration only.

#### a) Operating systems

In computer systems, “*abstraction is the key to managing complexity*” (Abelson, Sussman et Sussman, 1996; Tanenbaum, 2009). Without good abstractions, it would be extremely difficult for programmers to use computers. The direct manipulation of physical hardware (e.g., memory, hard disk, processors, etc.) is a tedious, error-prone and very time-consuming task that requires advanced knowledge and lots of effort. For this reason, computer devices were

abstracted into less complex forms that could be easily and safely manipulated. For example, hard disks and storage devices were abstracted into files and directories. Microprocessors were abstracted into processes and threads while physical memory was abstracted into logical (virtual) memory space (Tanenbaum, 2009). Henceforth, the programmer deals with files, processes and memory spaces instead of the corresponding hardware. To do so, a hardware abstraction layer (HAL) was created in the purpose of unifying manipulation of these logical resources. This HAL requires specific firmware and devices drivers, providers of basic low-level routines and instructions to control hardware, to get access to the required physical resources. In multi-task and multi-user computer systems, an operating system (OS) is needed to organize the concurrent accesses to the HAL. For example, the access to a file is controlled using the OS's file management system in order to ensure data manipulation, storage and integrity. Similarly, processes and memory spaces are also controlled by the OS's kernel in order to ensure data integrity and security as well as the fair and optimized use of the hardware resources. At this level of abstraction, it is possible to run various software applications. Each one of them has its own attached processes and its dedicated virtual memory space. When it needs to use hardware resources, it submits an access request to the operating system. This mechanism is called system calls<sup>59</sup>. The OS also uses various types of interrupts in order to interact with both software and hardware resources. These interrupts, namely software interrupts, are generated by software tools and use the HAL and middleware low-level routines to interact with physical resources. The various hardware devices also interact with other hardware (especially microprocessor) using specific interrupts referred to as hardware interrupt requests.

In this regard, Figure 4.13 shows two perspectives: the first is user-oriented while the second is system-dedicated. The former depicts the interaction between the end-user (whether human or not) with the computer system. The latter shows the different abstraction levels implemented in a typical modern computer system. These two perspectives illustrate the main abstraction

---

<sup>59</sup> System calls provide a uniform and programmable interface to the various services of an operating system. They allow applications to easily get access to the system's hardware and software resources via the OS tools which are in charge of managing and controlling the available resources.

levels that a modern computer system is built around. This said, operating systems are not the only computer components where hardware abstraction was applied. This paradigm was also thoroughly used in a myriad of other components such as networking, database management, artificial intelligence, learning machines, etc.

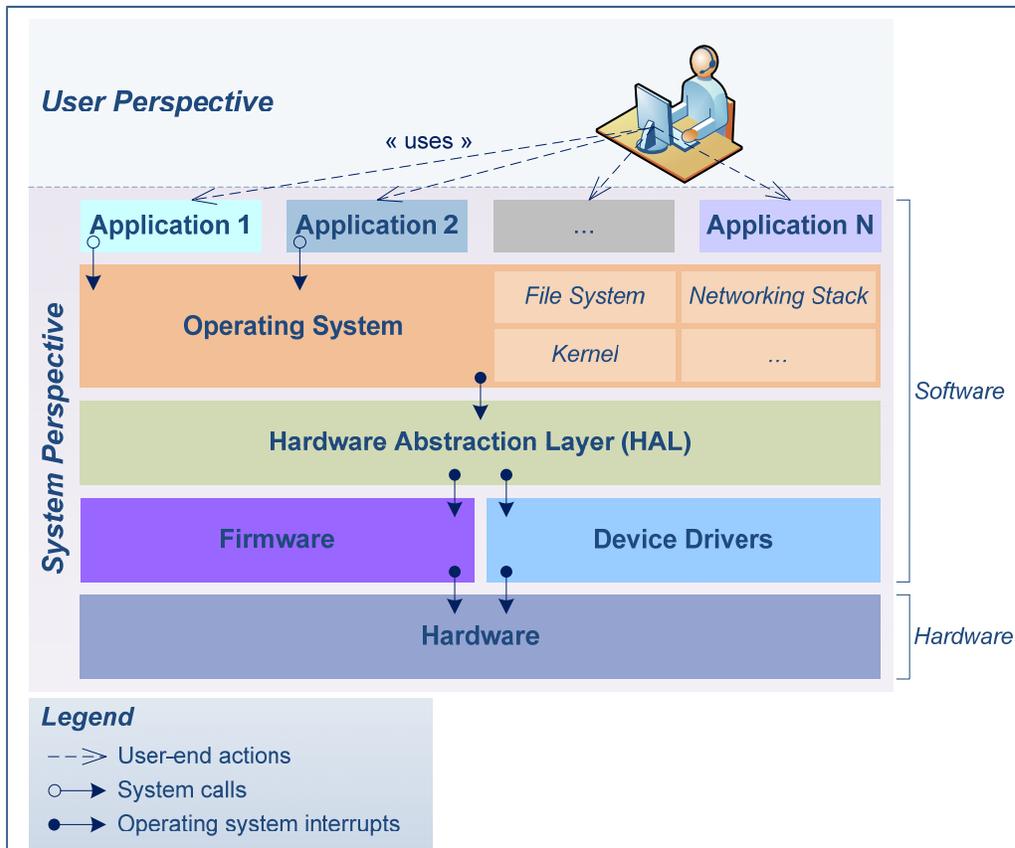


Figure 4.13 The hardware abstraction layer plays a mediation role between the operating system (and user applications) and the physical hardware

## b) Internetworking

With the democratization of personal computers in the early 1980s, one of the major challenges at that era was to interconnect these computers of different architectures, vendors and using different software tools into a single network (or network of networks). In 1984, the ISO released the seven-layer Open Systems Interconnection (OSI) model for networking (see Figure 4.14). This standard architecture was considered as a reference networking model. Each

layer of the OSI model is an abstraction level that encapsulates a certain level of the network complexity (Peterson et Davie, 2003).

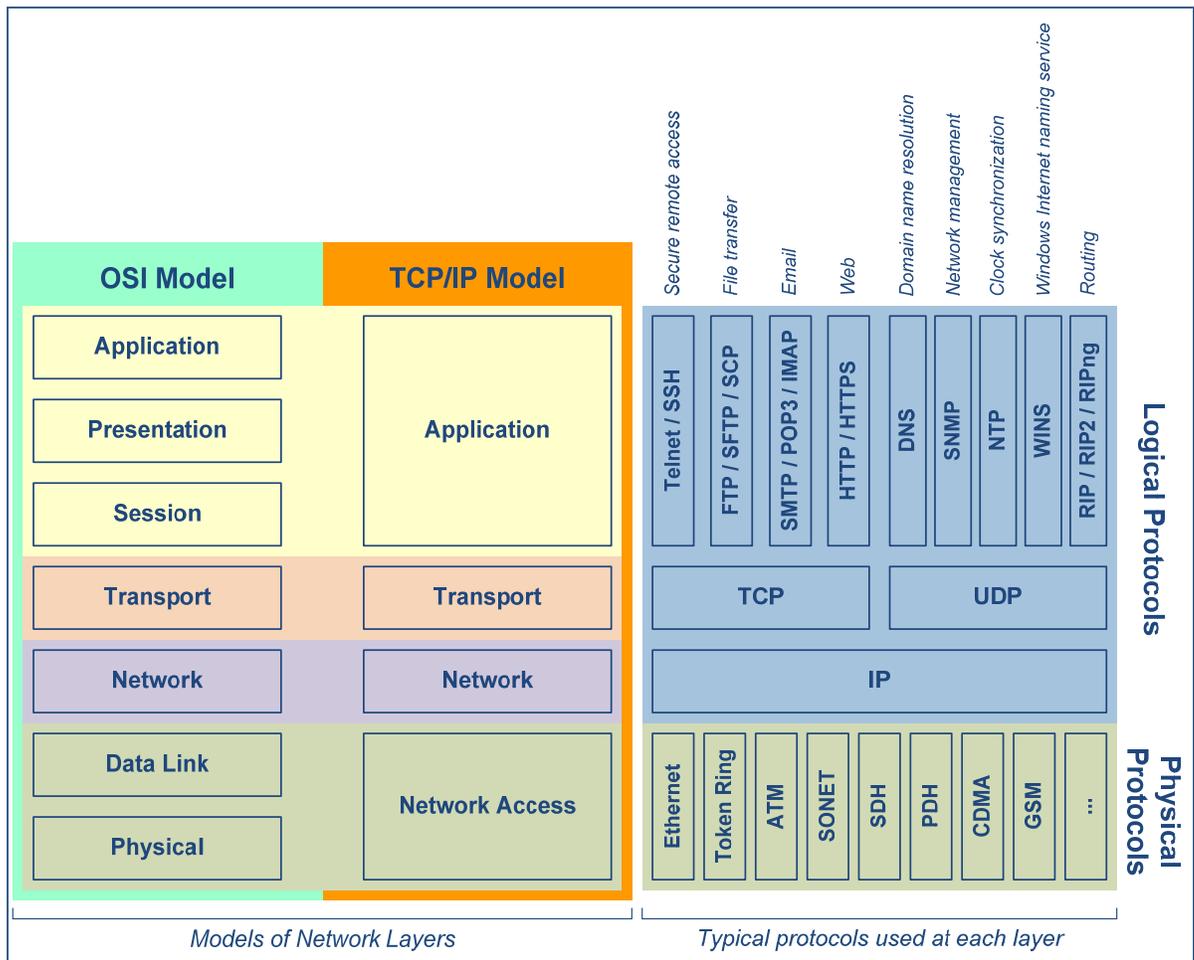


Figure 4.14 Modern networks were built upon a layered architecture based on OSI and TCP/IP networking models  
 Adapted from InetDaemon.Com (2013)

With the emergence of internet, the TCP/IP model was standardized in order to allow global internetworking. It was implemented upon the OSI model, but merged the three layers, (i.e., Application, Presentation, and Session) in a single layer, namely Application. In both OSI and TCP/IP models, one or more protocols are defined at each layer to ensure that the functionality for which that layer was defined is fulfilled. For example, the network layer is in charge of network addressing, data routing between the network hosts. The IP protocol is used (jointly with other protocols such as ICMP, ARP, etc.) to ensure that the data is received from the right

sender or delivered to the right recipient. It does not consider if the received or the sent data is corrupted. The transport layer whose role is to ensure a reliable data communication between the connected hosts ensures both the reliable and the best-effort delivery of data using TCP and UDP protocols respectively.

Figure 4.14 shows a comparison between the OSI and TCP/IP networking models and maps them to the communication protocols in common use. The layered architecture it shows illustrates that the layers are functionally distinguished which allows the encapsulation of the underlying levels and gradually reduces the complexity of the communication procedures (only one set of homogenous issues is resolved at each level).

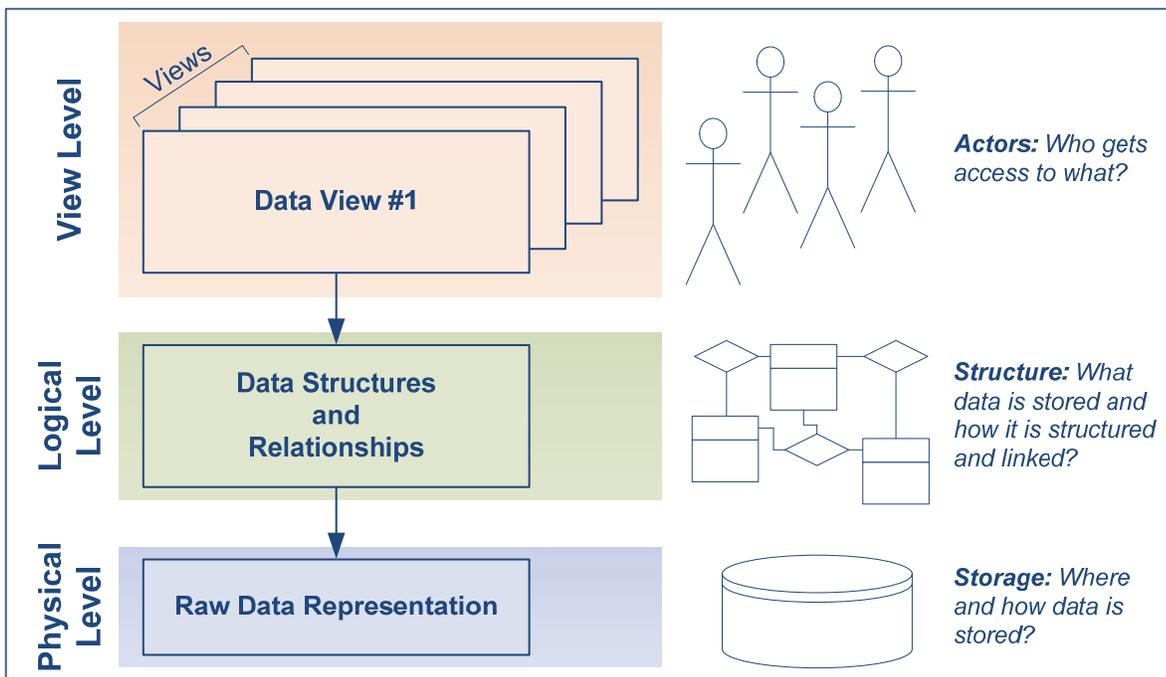


Figure 4.15 Modern databases use at least three abstraction levels to manage the stored data and control the interaction of users with them  
Adapted from Silberschatz, Korth et Sudarshan (2011)

### c) Databases

Ensuring the secure and safe access to multiple format data stored in different locations to various users required the development of three levels of abstraction (Ramakrishnan, 1998; Silberschatz, Korth et Sudarshan, 2011). The first is physical. It is dedicated to how the raw

data is stored, where and how it can be retrieved. At this level, very complex low-level data structures are used to describe the stored data in detail. The second layer is logical. It is less complex than the physical one. It is all about what data is stored in the database and how it is organized. This level uses human-readable and simplified data structures to capture the data entities and the relationships between them. The third abstraction level, namely view level, is the highest. It captures the interaction between the users and the database using the mechanism of view. A view is a set of rules that defines which data structures are accessible by a given user and which operations (e.g., read / write / delete) this user is authorized to conduct. All these abstraction levels are captured in Figure 4.15.

#### **4.2.4 Hardware Abstraction in Software Engineering**

For decades, computer programming has been gradually evolving from hard coding towards higher-level languages. Abstraction has played a key role in this evolution that enabled the development of complex software systems. As shown in Figure 4.16, raising the abstraction level resulted in the emergence of five generations of programming languages:

- Machine Code: The first generation was marked by machine coding using binary language. It was platform-dependent, very tedious, time-consuming and extremely limited in terms of productivity and outcome;
- Assembly Language: The second generation has seen the advent of assembly languages. They are constructed of mnemonic codes which designate the basic processing commands (e.g., ADD for addition operation) of a given machine. The resulting program is converted into binary code using a tool called assembler. This language is easier to learn and use than machine coding but it is not amenable for complex systems development. The developer is in charge of all operations related to the hardware use (e.g., memory access, CPU registers assignment, etc.);
- Structured Languages: To enhance productivity and enable better software portability, the third generation, commonly designated as high-level languages generation, had introduced a new level of abstraction based on data and control structures (Pierce, 2002; Sebesta, 2012). For data abstraction, the concepts of structure and data types allowed the programmer to use both pre- and user-defined data structures to handle information. These

two concepts were merged into a new one: the object. Its major advantage is the possibility of information hiding via encapsulation. For control abstraction, iterative and conditional control flows were introduced. They served to automate controls and minimize code duplication (Pierce, 2002). These abstraction principles enabled new development paradigms that were defined as guidelines for software engineering (e.g., procedural, object-oriented and extreme programming). Specialized tools such as compilers and interpreters were used to transform programs' source code into a platform-specific executable binary code. In addition, depending on the programming language, these tools may allow very useful advanced features such as automated code optimization, garbage collection (i.e., automated dynamic memory management), managed and safe-mode code execution, etc. All these features alleviate the developer tasks and allow the focus more on the program than on the management of the hardware resources;

- Declarative Languages: The declarative programming languages announced the advent of a fourth generation. These languages are intended to describe engineering systems in a way that is similar to the structure of human language. The paradigm behind the declarative languages aims to define computational models from which data structures and control flows can be derived using code generation tools. This additional abstraction level enhances models neutrality and independence from platform specificities. Declarative languages included graphical representations (e.g., using modeling languages such as UML) which can be transformed into source code using relevant tools;
- Problem-Solving Languages: The fifth generation of programming languages are problem solving oriented. It provides advanced capability in using visual and graphical representations to capture the system's behavior, its structure and requirements, etc. The fifth-generation programming languages were designed to fulfill a main goal: the developer identifies problems and the computer solves them. This enables people to build relatively complex systems without having advanced knowledge in programming. In addition, this level of abstraction makes this generation of programming languages suitable for a broader range of fields beyond software engineering. That is why this category of languages is nowadays used in a myriad of other engineering systems (e.g., artificial intelligence, voice recognition, robotics, etc.).

Modern software engineering addresses four major issues: (i) productivity, (ii) portability<sup>60</sup>, (iii) interoperability<sup>61</sup>, and (iv) source code maintenance and reuse (Kleppe, Warmer et Bast, 2003; Mellor et al., 2004). The abstraction principles that have been adopted throughout the various generations of programming languages had a significant impact on software development:

- Hiding platform architecture to enable better portability and interoperability: Raising the abstraction level in programming allowed to gradually separating the software from the platform-specific attributes (e.g., architecture, instructions set, etc.). This did not only enhanced the capability of developers to rapidly and easily implement complex software systems without or with minor focus on hardware details but, it allowed to enhance the portability of programs between different hardware (and/or software) platforms. In addition, data/control abstraction support (and later modeling-centred paradigms) allowed better interaction and interoperability between software systems regardless of hardware and/or software differences;
- Enabling automation for better productivity: The gradual masking of hardware (and software) environments details allowed the use of various automated tools (e.g., assembler, compiler/interpreter, code generator, etc.) which concretely enhanced the productivity of common software development processes. At this regard, Figure 4.17.a shows how assemblers were designed to produce machine code for a single hardware platform while it is nowadays possible to use the same software models to produce executable programs for multiple hardware (and/or software) platforms. Furthermore, developers take advantage of various automated optimization tools (e.g., memory footprint, execution time, etc.) to enhance the quality of software systems. This progress, mainly due to the rise of abstraction levels, saves time and money during the software development process;

---

<sup>60</sup> Portability denotes the ability of using the same software system in different hardware and/or software environments. Hardware commonly involves different computer architectures while software involves generally different operating systems (or even versions of the same operating system).

<sup>61</sup> Interoperability denotes the ability of software systems, eventually of different origins, to co-exist, interact and cooperate with other existing systems. Kleppe, Anneke G., Jos Warmer et Wim Bast. 2003. *MDA Explained - The Model-driven Architecture: Practice and Promise*. Addison-Wesley Longman Publishing Co., Inc., Boston, MA.

- Improving code maintainability and reuse: Software systems, especially complex ones, are error-prone. The detection of their defects and faults may be time-consuming and costly particularly at the operational phase. Raising the abstraction level allowed to automatically generate software documentation and trace back all the source code structures. This allows not only the automation of the software verification process but also easier and quicker detection and correction of its defects during the maintenance phase. Moreover, well-documented and maintained software pieces can be easily reused. In fact, code reuse can be ensured at higher abstraction levels much more than at lower ones. For instance, first structured programming languages allowed the reuse of functions and/or objects while model-centric development processes allow the reuse of much larger software components and frameworks (see Figure 4.17.b).

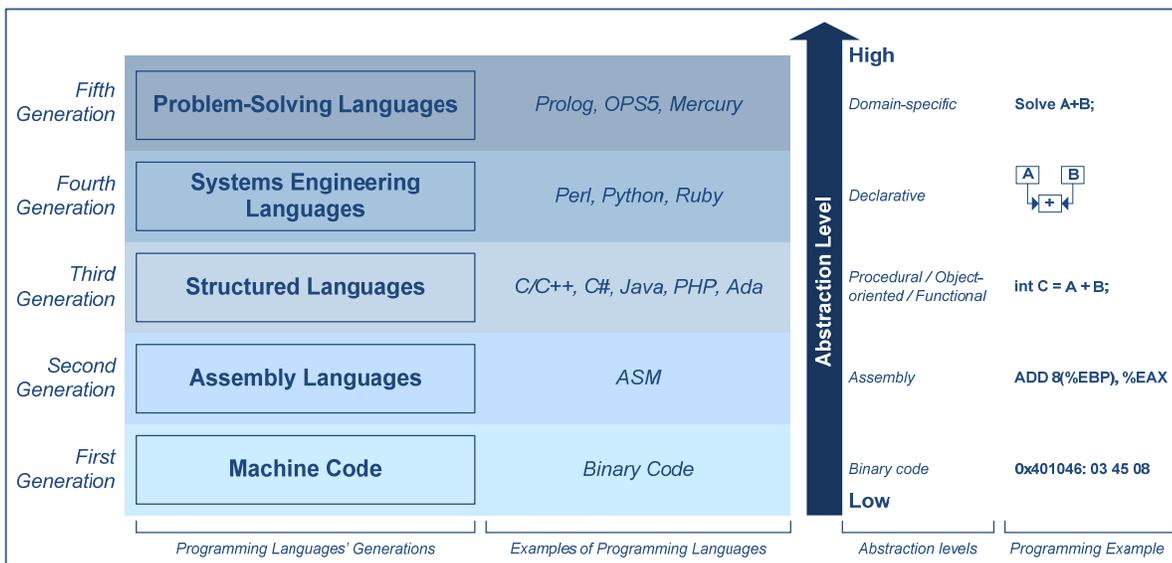


Figure 4.16 Evolution of abstraction levels in programming languages

From a practical standpoint, this section shows so far that the study of hardware abstraction in software engineering is worthy for the subject of this thesis. In fact, both RF design and software development processes address similar issues (in particular productivity enhancement and design maintenance and reuse). At this regard, the impact of hardware abstraction on software engineering is concrete. For this reason, it seems worthy to analyze in more detail the mechanisms used in this domain to address the previously mentioned issues. In the following,

we study some software development paradigms implementing that were used to implement the various abstraction principles (e.g., data/control abstractions) in this field. For illustration purposes, we briefly review how these abstraction concepts were adopted in three popular software engineering paradigms: modular, object-oriented programming and model-driven software development.

### a) Modular Software Development

In modular programming (also assimilated to procedural and functional<sup>62</sup>), the main purpose is to:

- Organize a program as a suite of declarative, typed and imperative statements and instructions,
- Organize large software systems into well-defined, interchangeable, independent, optimized and reusable modules and units, and
- Reduce as much as possible the duplication of data<sup>63</sup> and control flows in software systems (Pierce, 2002).

Therefore, instead of developing a software system as a large monolithic program, it is subdivided into small modules (also functions, procedures) that can be developed and optimized separately. This first abstraction defines the external appearance of each module (i.e., interface) without specifying its internal details. The external appearance can be the types or/and the acceptable range of values related to the inputs and outputs of the module. This is called an abstraction by parameterization (Cornell University, 2011). The unnecessary details about types and values of the module's inputs and outputs can be ignored. This is an abstraction

---

<sup>62</sup> Modular, procedural and functional programming approaches are three similar software development styles derived from a unique paradigm, namely structured programming, which is based on the separation of a software system into small, interchangeable and independent units.

<sup>63</sup> This abstraction principle is stated by Pierce, Benjamin C. 2002. *Types and Programming Languages*. MIT Press. as follows: “*Each significant piece of functionality in a program should be implemented in just one place in the source code. Where similar functions are carried out by distinct pieces of code, it is generally beneficial to combine them into one by abstracting out the varying parts*”. This concept was later used by Schmidt, Douglas C. 2006. « Model-driven engineering ». *Computer*, vol. 39, n° 2, p. 25-31. in object-oriented programming who stated that “*the phrases of any semantically meaningful syntactic class may be named*”.

by specification (Cornell University, 2011). It allows hiding more information about the nature of the exchanged parameters and gives the programmer the ability to use a single module with parameters of different types and contexts. This data abstraction enforces the logical boundaries between the different modules because each module interacts with others using one or many interfaces.

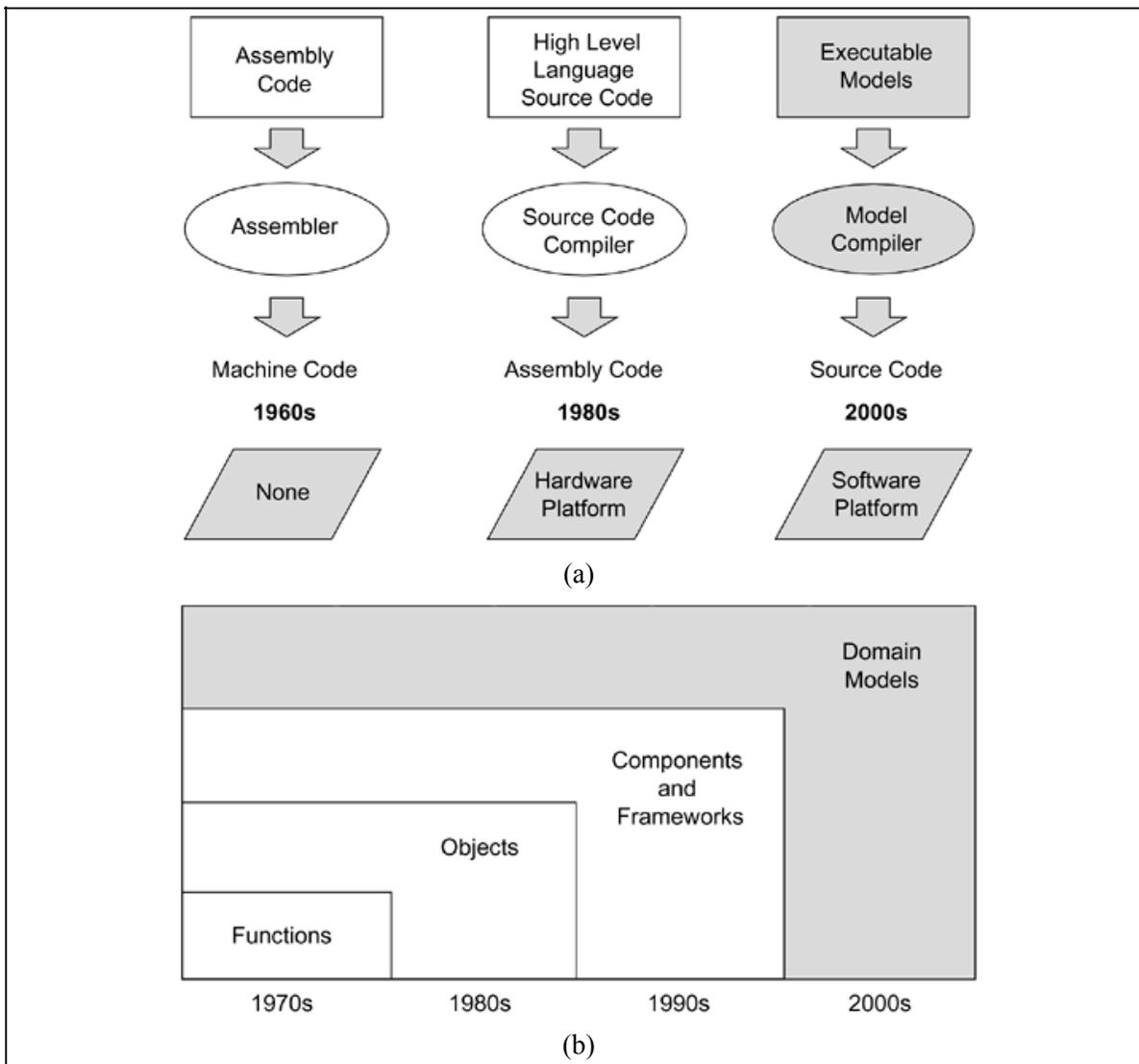


Figure 4.17 Impact of abstraction level rise on productivity and code reuse: (a) from one source for one system architecture to one model to multiple hardware/software platforms (b) Source code reuse started with functions and evolved towards domain models

Taken from Mellor et al. (2004)

Besides, modular programming takes advantages of control abstraction because it implements the basic principles of traditional structured software development process. This results in a hierarchical and granular software system that arranges modules into conditional, iterative and sequenced instructions.

In practice, the concept of modularity implements data and control abstractions in a way that enhances not only productivity (mainly resulting from concurrent development) but also the maintainability and the reuse of modules. For instance, these modules can be implemented into packages and libraries, which can be shared between different software systems and easily reused in future projects (see Figure 4.18).

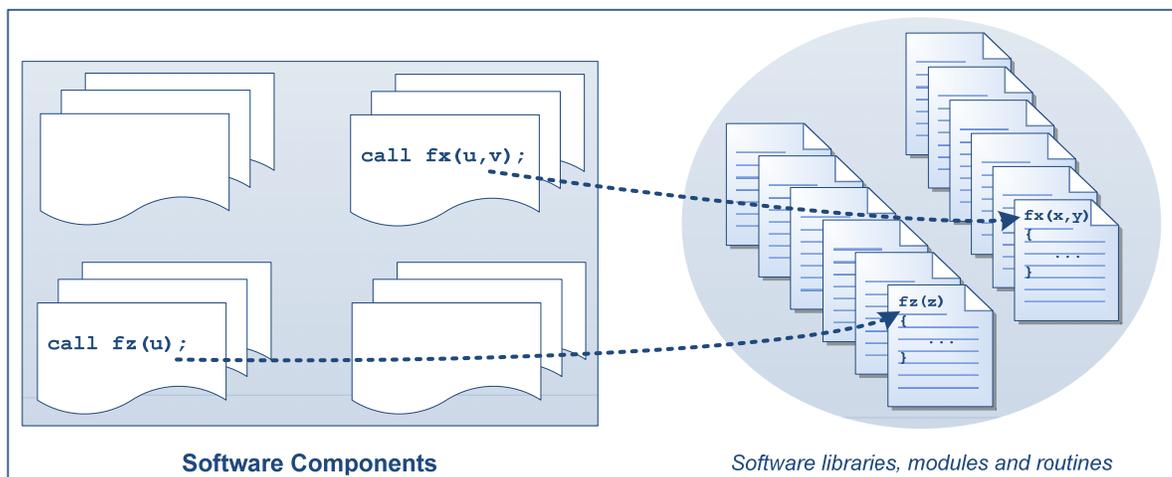


Figure 4.18 The modular programming paradigm subdivides a software system into independent, shared and reusable components

## b) Object-Oriented Programming<sup>64</sup>

The object-oriented approach was introduced as an extension of traditional programming paradigms (e.g., modular programming). On the one hand, it aimed to reduce the coupling<sup>65</sup> between and improve the cohesion<sup>66</sup> within modules in these conventional approaches (Schach, 2002). On the other hand, it was meant to bring more abstraction in order to enhance the maintainability<sup>67</sup> and reusability of large software systems (Kendal, 2011).

To do so, the object-oriented programming approach has defined a fundamental concept, namely object (i.e., practically an instantiation of a class) which is a model that describes the properties (and attributes) of a real-world entity and the operations (and actions) that can be performed on or by that entity (Koffman et Wolfgang, 2006). An object is not only meant to keep the real-world entity relevant features, properties and functions and discard those irrelevant ones but it also allows to control their visibility and their scope as well as the relationships (and the interactions) that the object may have with other objects. To make this concept effective, various abstraction techniques were defined:

- **Data Abstraction: Inheritance, Generalization and Specialization**

An object is an abstraction of a real-world entity. It captures both its intrinsic attributes and behavior. This representation ignores the irrelevant entity details and focuses only on its main characteristics. An object can inherit the properties and operations of one or many other objects. The inherited object (i.e., parent class) is a generalization of the inheriting one (i.e., child class). Generalization allows defining generic objects that have common properties

<sup>64</sup> For extensive information about object-oriented programming principles, the reader may refer to Baldwin, Douglas, et Greg W. Scragg. 2004. *The Object Primer*. Cambridge University Press. and Klump, R. 2001. « Understanding Object-Oriented Programming Concepts ». In *IEEE Power Engineering Society Summer Meeting*. (Vancouver, 15 Jul 2001-19 Jul 2001 ). Vol. 2, p. 1070-1074. < <http://ieeexplore.ieee.org/ielx5/7659/20923/00970207.pdf?tp=&arnumber=970207&isnumber=20923> >.

<sup>65</sup> The concept of coupling refers to the degree of interdependence of a software module with other modules. Schach, Stephen R. 2002. *Object-oriented and Classical Software Engineering*, 6. McGraw-Hill New York.

<sup>66</sup> The concept of cohesion characterizes the degree of interdependence between the elements of the same module. High cohesion results in better software robustness, reliability and reusability *ibid.*. High cohesion often correlates with low coupling and vice versa.

<sup>67</sup> Maintainability is a crucial property in software development because 70% of the cost is incurred during the software usage phase Kendal, Simon. 2011. *Object Oriented Programming Using C#*. Simon Kendal & Ventus Publishing.

(Kendal, 2011). On the contrary, the inheriting object is a specialization of the inherited one. Specialization enables the creation of objects with specific properties from generic ones. In practice, it takes place using the inheritance mechanism and extending the attributes and the behavior of the object. Thus, inheritance removes data and code redundancy. It enables the extensibility and the reusability of objects. In addition, it is possible to define various types of relationships between objects (e.g., generalization, composition, association<sup>68</sup>, dependency<sup>69</sup>, etc.). The semantic of each relationship is determined by the logical link tying the objects in the real world. For instance, generalization translates an “*is a*” relationship (which roughly means that the child object *is a* “copy” of the parent one).

To illustrate these, Figure 4.19.a shows entities from the real world. In Figure 4.19.b, the properties, operations and relationships linking these objects are captured in a class diagram<sup>70</sup>. In this example, a bus, a car or a truck *is a* vehicle. That is a generalization relationship between the bus, the car and the truck objects at one side and the vehicle object at the other one. A vehicle *has a* given number of tires. This is a composition relationship between the vehicle and the tire objects. In addition, speed, weight and color are some of the attributes of a vehicle. Parking, moving forward and backward are some of its operations. These attributes and operations are naturally inherited by the car, the bus and the truck. However, loading and unloading passengers and cargo are specific to the bus and the truck respectively. The transmission type is specific to the car. These additional specificities make the car, the bus and the truck objects a specialization of the vehicle one.

---

<sup>68</sup> Association defines a relationship in which an object A uses an object B as part of its behavior Wong, Stephen, et Dung Nguyen. 2008. *Principles of Object-Oriented Programming*. Connexions (Rice University).

<sup>69</sup> Dependency defines a relationship in which an object A depends on an object B *ibid*.

<sup>70</sup> A Class Diagram is a UML structural diagram that captures the attributes, operations and relationships between objects.

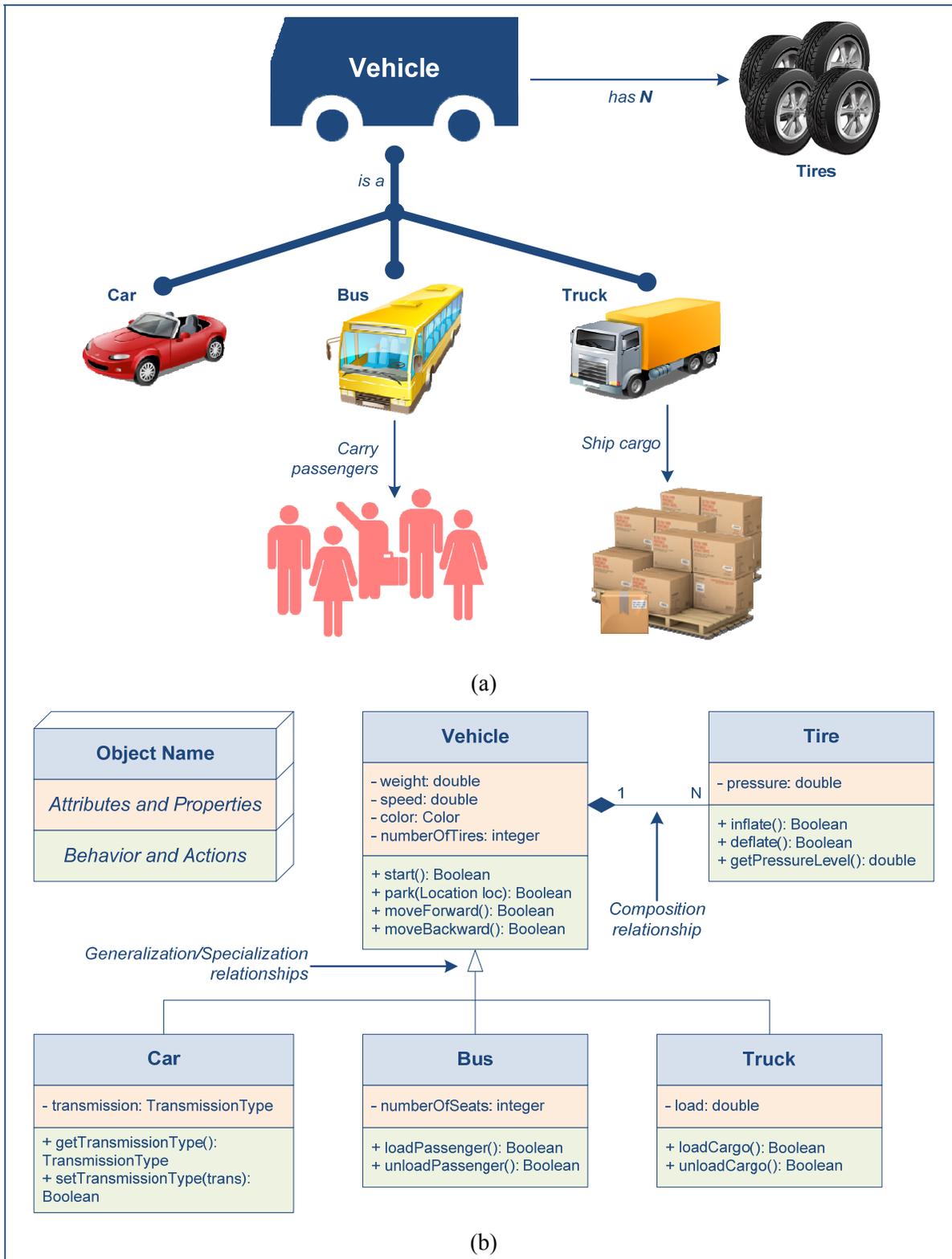


Figure 4.19 Abstraction through objects and classes: (a) real-world objects and (b) how they are modeled using a UML class diagram

- **Control Abstraction (aka Procedural Abstraction): Encapsulation and Polymorphism**

The object-oriented programming approach adopts the principle of separation between what should be achieved by an object (or its attributes/operations) and how it should be achieved (Koffman et Wolfgang, 2006). This principle is implemented through the mechanism of encapsulation (Kendal, 2011). This mechanism consists of hiding both object data (i.e., attributes) and implementation (i.e., operations) and providing an appropriate interface for it. This interface defines which attributes and/or operations are accessible and how they can be used (using access modifiers<sup>71</sup> such as private, protected and public, etc.). Thus, the interaction with the object takes place using its interface that reduces the implementation complexity.

Another important mechanism in control abstraction is polymorphism, which denotes the ability of using an object regardless of its specificities. In practice, this means that the object has more than one type and can be used in multiple contexts without any code duplication. It is defined as an object with abstract attributes and operations to which a specific type is associated during usage. Abstract data types<sup>72</sup> are an example of what can be achieved using the mechanism of polymorphism.

In summary, the concept of object modeling added to the various mechanisms of hierarchy, encapsulation, and polymorphism brought abstraction to a higher level in object-oriented software development processes. The impact of this rise of abstraction level on the various software metrics (especially maintainability and reusability) is concrete. At this regard, it is proven that object-oriented approach results in more maintainable and reusable software systems than the traditional structured software approaches (e.g., modular) (Henry et Lattanzi, 1994; Lee et Chang, 2000).

---

<sup>71</sup> An access modifier sets the accessibility level for object attributes and operations. For example, a “*private*” modifier (minus “-” sign in UML class) grants access only to the attributes and operations while a “*public*” modifier (plus “+” sign in UML class) allows all objects to access that attribute/operation.

<sup>72</sup> An Abstract Data Type (ADT) is a data structure whose type is not explicitly defined. It takes the type of the operation performed in a given context.

### c) Model-Driven Engineering (MDE)

The third-generation programming languages (particularly modular and object-oriented) have raised the level of abstraction of the programming environment which allowed the use of automated tools (such as assemblers, compilers and preprocessors) to automate the generation of executable routines (e.g., machine code) from relatively high-level programming software constructs (e.g., source code, UML diagrams) (Frankel, 2003; Mellor, Balcer et Foreword By-Jacobson, 2002; Schmidt, 2006). This is also due to operating systems which have raised the level of abstraction of the computing platform and hid unnecessary hardware details (Frankel, 2003). Then, compilers do not generate all the required machine code but should henceforth rely on the OS<sup>73</sup> services and routines to partly do this. In addition, special middleware components (e.g., application virtual machines<sup>74</sup>, run-time systems) came into play to enhance code portability between platforms (i.e., using CPU- and OS-independent intermediate code). Over time, the complexity of the underlying software platforms (especially OS services and middleware) has rapidly grown. This, combined to a slow evolution of general-purpose languages towards an effective capture of platform-specific artifacts and expression of specialized domain concepts, has increased the difficulty of porting source code between different (/versions of the same) software platforms. At this regard, modern platforms' complexity reached a ceiling at which the development of large software systems became costly and time-consuming, especially due to the manual code porting, integration and maintenance (Schmidt, 2006). So, if hardware-platform independence was ensured mostly using relevant OS and middleware to enable code execution on various hardware platforms with almost no changes, new paradigms with higher abstraction levels are required to enable the execution of the same source code on different software platforms with no or at least minor changes (i.e., software-platform independence) (Mellor et al., 2004). This new abstraction level is not only expected to mask the growing complexity of existent and emerging software platforms but should also enable the development of expressive software models that can be

---

<sup>73</sup> Paragraph 4.2.3.a explains how software applications use the OS and middleware resources through the mechanism of system calls.

<sup>74</sup> Application Virtual Machines (and run-time systems) are software components that create a (hardware and/or software) platform-independent programming environment to enable the interpretation (or just-in-time compilation) and execution of intermediate code.

mapped at the same time to different environments with no changes. Thus, applications intended for CORBA<sup>75</sup>, client-server relational databases or web platforms are expected to be derived from the same high-level software models (Mellor et al., 2004).

To bridge the gap between the increasing complexity of software (/hardware) platforms and the limitations of third-generation programming paradigms, a new software development methodology, namely Model-Driven Engineering<sup>76</sup> (MDE), has emerged in the early 2000s. MDE is all “*about the use of relevant abstractions that help people focus on key details of a complex problem or solution combined with automation to support the analysis of both the problem and solution (...)*” (Blackburn, 2008, p. 7). To raise further the abstraction level in software engineering, MDE focuses on the creation of models which are close to the problem domain and using more abstract and expressive concepts (Milicev, 2009). It is worth noting that, in MDE, abstraction and modeling are interrelated. On the one hand, MDE considers abstraction as the capability of finding out the commonality in many different observations (i.e., viewpoints) (Brambilla, Cabot et Wimmer, 2012). This implies the ability of generalizing specific features of real-world objects, the classification of these objects into coherent groups and clusters and the aggregation of these them into more complex ones (Brambilla, Cabot et Wimmer, 2012). On the other hand, modeling is the process of representing real-world entities as simplified and understandable representations. At this regard, abstraction helps making the good decisions about what should be captured and what should be removed in a model (Fernandes). From this viewpoint, MDE considers a model as an abstraction of a reality. It is an entity that hides some aspects of this reality while it stresses other ones.

---

<sup>75</sup> CORBA stands for Common Object Request Broker Architecture which is an OMG standard that is intended to facilitate the communication, collaboration and interaction between different platforms regardless of their hardware and software architectures.

<sup>76</sup> Model-Driven Engineering is sometimes referred to as Model-Driven Development (MDD) Teppola, S., P. Parviainen et J. Takalo. 2009. « Challenges in the Deployment of Model Driven Development ». In *Fourth International Conference on Software Engineering Advances*. (Porto 20-25 Sept. 2009 ), p. 15-20. <<http://ieeexplore.ieee.org/ielx5/5298192/5298193/05298434.pdf?tp=&arnumber=5298434&isnumber=5298193> >. In fact, most terms with the prefix “*model-driven*” designate software development approaches based on intensive modeling activity Embley, David W., et Bernhard Thalheim. 2011. *Handbook of Conceptual Modeling: Theory, Practice, and Research Challenges*. Springer.

Since MDE addresses a broad range of problems, it considers that “*everything is a model*” (Bézivin, 2005). This definition suggests that not only the problem can be modeled but also its solution. In practice, every abstraction level and each design step (e.g., specifications, design, implementation, etc.) can be associated to one or many models. To change the abstraction level or move from a design step to another, new models should be derived from those defined at the previous abstraction level (respectively design step). This standpoint is interesting in a sense that a complex system can be developed starting by very-low complexity models which can be gradually refined to include more details through the design cycle. In addition, this does not only help mastering the system’s complexity but also enhances productivity if automated model-to-model transformation is possible. For instance, when MDE is applied to software development, the typical lifecycle illustrated in Figure 4.20, emphasizes the use of automation tools in order to derive the appropriate models required at each design step.

From the beginning, MDE was thought as a generic design approach that is not limited only to software engineering. It defines key abstraction and automation concepts that are amenable for use in various engineering fields. What fueled this tendency is the fact that software systems are increasingly being developed in multi-disciplinary projects. Moreover, this approach is being already used in different areas (e.g., software-defined radio (Trask et al., 2006), voice recognition (Briand, 2005), embedded and real-time systems (David et Nielsen, 2008; Hsiung et al., 2009)). In software engineering, MDE is gaining growing interest. For instance, at least three major initiatives were proposed as guidelines for the practical implementation of model-driven engineering concepts:

1. Model-Driven Architecture (MDA)<sup>77</sup>,
2. Model-Driven Software Development (MDSD)<sup>78</sup>, and

---

<sup>77</sup> For detailed presentation of MDA, the reader may refer to Kleppe, Anneke G., Jos Warmer et Wim Bast. 2003. *MDA Explained - The Model-driven Architecture: Practice and Promise*. Addison-Wesley Longman Publishing Co., Inc., Boston, MA., Frankel, David S. 2003. *Model Driven Architecture: Applying MDA to Enterprise Computing*. John Wiley and Sons. and Poole, John D. 2001. « Model-Driven Architecture: Vision, Standards and Emerging Tools ». In *Workshop on Metamodeling and Adaptive Object Models*. < [http://www.omg.org/mda/mda\\_files/Model-Driven\\_Architecture.pdf](http://www.omg.org/mda/mda_files/Model-Driven_Architecture.pdf) >.

<sup>78</sup> For more information about MDSD, the reader may refer to Völter, Markus, Thomas Stahl, Jorn Bettin, Arno Haase et Simon Helsen. 2006. *Model-Driven Software Development: Technology, Engineering,*

### 3. Domain-Specific Modeling (DSM)<sup>79</sup>.

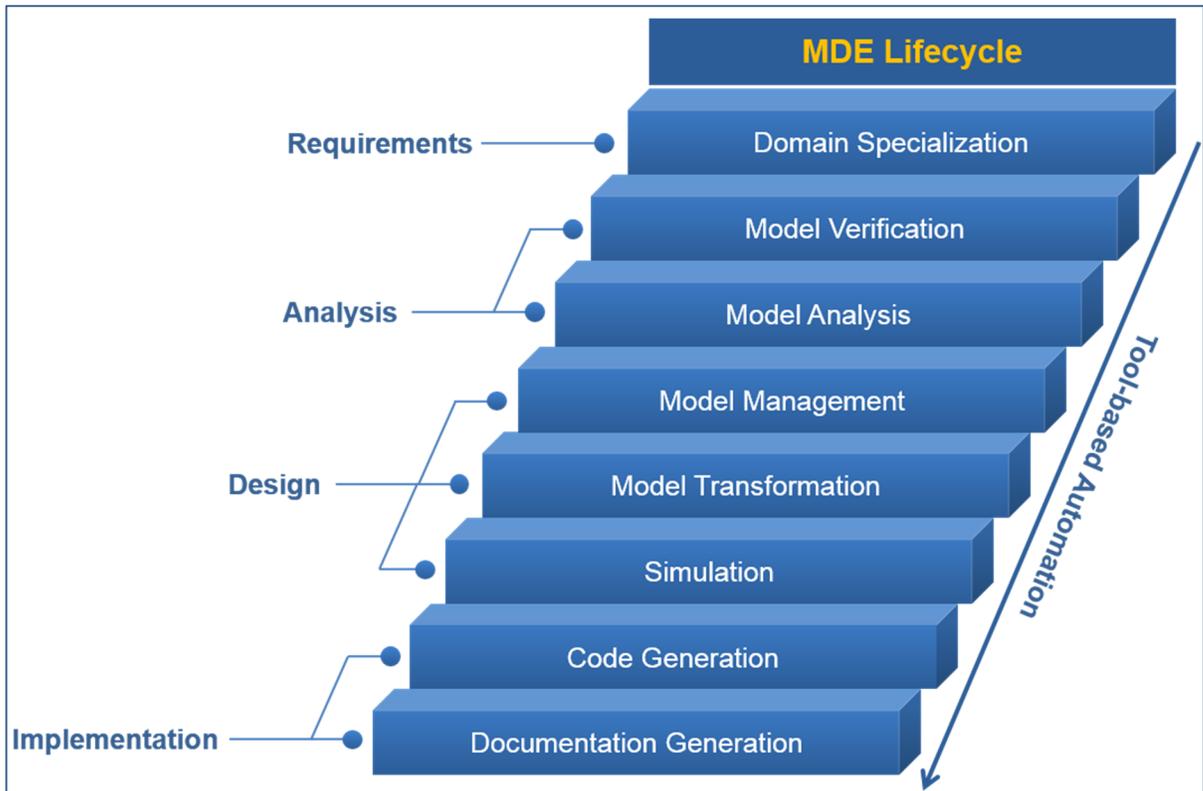


Figure 4.20 MDE enables the use of automated model-to-model transformation tools to enhance the automation of design steps  
Adapted from Blackburn (2008)

In 2001, the OMG proposed the Model-Driven Architecture initiative that was built around a framework of standards<sup>80</sup> that it had been developing for software engineering (OMG, 2001). To illustrate how the key concepts of MDE are used in practice, we consider in the following MDA as a learning base.

---

*Management*. John Wiley and Sons. and Beydeda, Sami, Matthias Book et Volker Gruhn. 2005. *Model-driven software development*, 15. Springer.

<sup>79</sup> For more information about DSM, the reader may refer to Kelly, Steven, et Juha-Pekka Tolvanen. 2008. *Domain-Specific Modeling: Enabling Full Code Generation*. John Wiley and Sons.

<sup>80</sup> Among the standards used for MDA, we note UML/SysML, XMI/XML, CORBA, CCM (CORBA Component Model), MOF (Meta-Object Facility), OCL (Object-Constraint Language), CWM (Common Warehouse Meta-model), etc.

- **Models and Meta-Models**

In MDA, models are the masterpieces in software design cycle. They are used to capture not only the system's structure and behavior but also timing constraints and environment resources (Blackburn, 2008). To represent all these system aspects with respect to abstraction and consistency requirements, models can be (Fernandes):

- Horizontal: if they capture different system aspects which are considered at the same level of abstraction, or
- Vertical: if they describe system aspects that are considered at different levels of abstraction.

From system standpoint, models can be classified into various types (Fernandes):

- State-oriented: to capture the system's dynamic behavior,
- Activity-oriented: to describe the system as a sequence of activities,
- Structure-oriented: to characterize the system's physical structure (including interfaces and ports),
- Data-oriented: to describe the system as a collection of data that is related by their attributes and classifications,
- Heterogeneous: to incorporate a mix of the previous four characteristics.

From platform standpoint, models can be classified into (Frankel, 2003):

- Business/Domain-specific: describes the domain-specific aspects regardless of automation ability,
- System: captures the aspects that can be used to automate domain-specific elements,
- Logical: describes the system's logic including its behavioral and structural aspects,
- Physical: captures the system's physical artifacts and its related environment resources,
- Requirements: captures the same attributes as the logical model but in a computation-independent manner (i.e., no technology aspects are considered),
- Computational: augments to the logical model with additional domain-specific technical information,

- Platform-independent: can be considered as a computational model that is enriched with additional platform-independent technical factors, and
- Platform-specific: is generally derived from a platform-independent model to which platform-specific information are added.

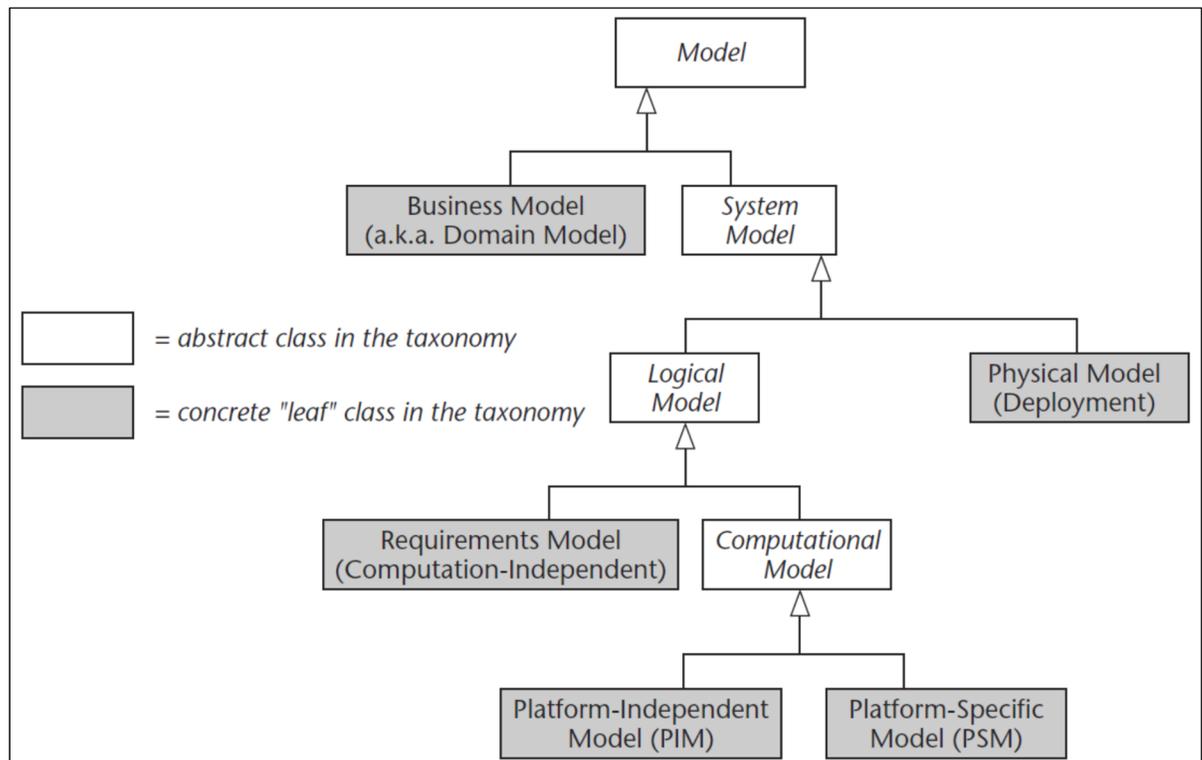


Figure 4.21 The model-driven architecture defines two types of models at different abstraction levels  
Taken from Frankel (2003)

Figure 4.21 shows a hierarchy of these models and depicts the inheritance/generalization relationships between them. As stated in (Frankel, 2003), this hierarchy remains relative and non-definitive because definitions may change with context. This said, only the “leaf” models (grayed rectangles in Figure 4.21) are used in practice. In MDA, the other models are generally not used because they cannot be processed by (transformation) tools (typically due to the lack of technical and/or platform-specific information). This said, models, as simplified representations of reality, should be descriptive, prescriptive, understandable and usable (Brambilla, Cabot et Wimmer, 2012). Furthermore, models should be regularly submitted to consistency checks to validate their understandability and practical usability (Fernandes).

To ensure that models yield a common understanding between all the involved parties (either human- or computer-based), they should comply with common semantics and rules (Mellor et al., 2004). The “language” in which a model is defined is called meta-model. In fact, it is simply a “*model that defines the structure, semantics, and constraints for a family of models*” (Mellor et al., 2004, p. 14). It is a “model of models”.

From an abstraction standpoint, if models are constructed as previously mentioned using the mechanisms of classification, generalization and aggregation, in a way that produces a simple but expressive representation of reality, meta-models that define the guideline semantics of models are themselves another abstraction layer. The example illustrated in Figure 4.22 shows how these concepts can be applied in practice. An immediate (i.e., “first-order”) abstraction of the represented pets is the capture of their individual attributes (e.g., name, species, weight). A more elaborate abstraction of this is the capture of the common attributes among the different first-order representation. This results in a classification of these pets (i.e., captured in a typical class model). So, how to ensure that this class model is understood by everyone in the same way? For this purpose, a meta-model was created to define the relationships between a “class” and a “property” (e.g., generalization, association, etc.). The subsequent interpretation to this hierarchy of abstractions enables everyone to easily understand that a cat “*is a*” pet (i.e., “class”) that “*has a*” given “property” which distinguishes it from the other pets. The reader may note here the same taxonomy we have already presented in Figure 4.19.

In MDA, models can be developed using UML. However, the developer can use any other modeling language for modeling. For instance, domain-specific languages (DSL) are used to capture domain-specific artifacts and particularities that UML cannot explicitly express (Van Deursen, Klint et Visser, 2000). Meta-models are commonly defined using meta-modeling languages (e.g. OMG’s Meta-Object Facility<sup>81</sup>, Query/Views/Transformations<sup>82</sup>).

---

<sup>81</sup> Meta-Object Facility (MOF) is an OMG standard for the creation, manipulation and exchange of interoperable meta-models.

<sup>82</sup> Query/Views/Transformations (QVT) is an OMG standard set of languages for creating query models, views and transformations.

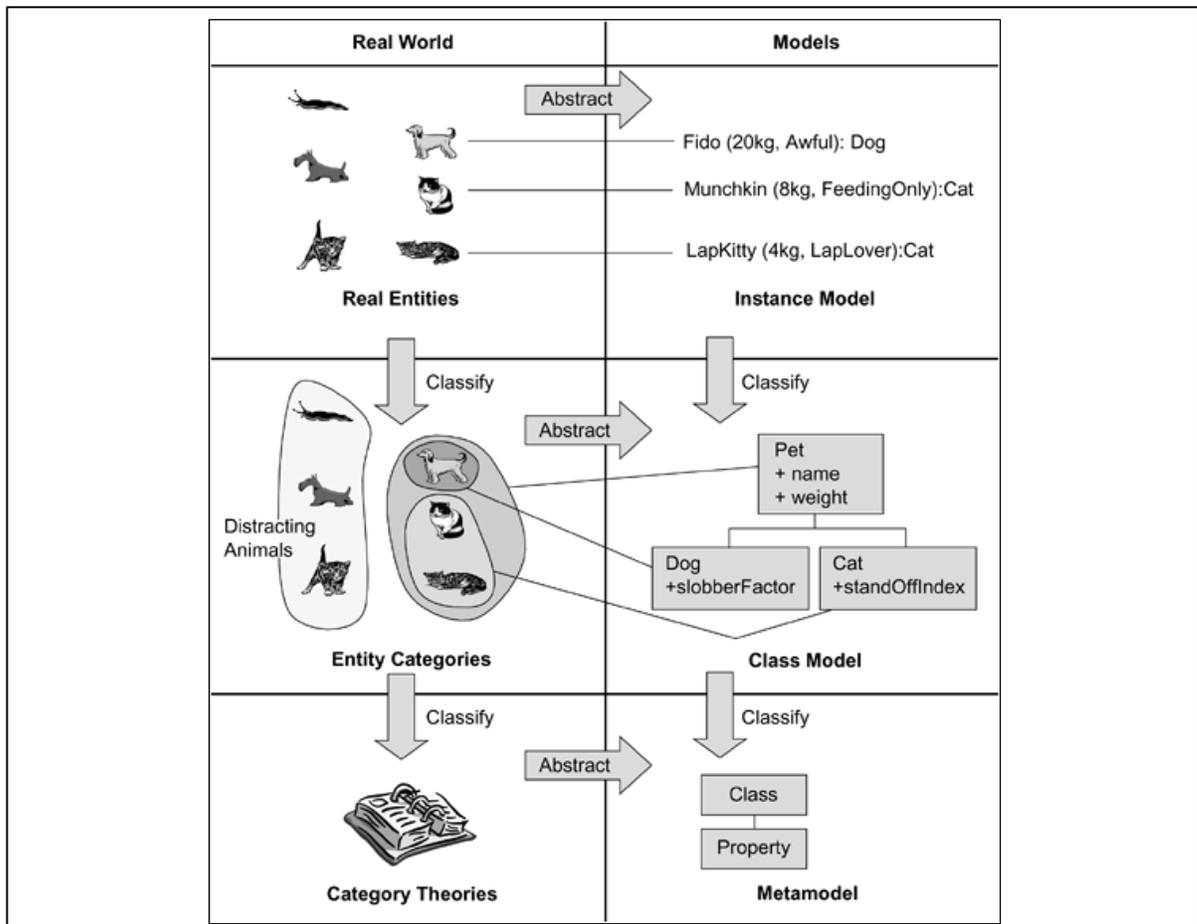


Figure 4.22 In MDE/MDA, a meta-model abstracts a model which itself abstracts a real-world reality  
Taken from Mellor et al. (2004)

In summary, models and meta-models are cornerstones in MDA approach. They are not only used for abstraction and complexity management but also to support automation. They are used for throughout the design cycle for specification, analysis, design, simulation, animation, deployment, operation, maintenance and documentation (Brambilla, Cabot et Wimmer, 2012; Miller, 2003). The creation of models for each of these steps requires changing the view of the system.

- **Views and Viewpoints**

To address the complete software development lifecycle, MDA defines an intensive modeling activity that is based on the principle of architectural separation of concerns (Truyen, 2006). This implies that at each abstraction level the system is viewed from the perspective of different

concerns. This is called a view. Developing models for a given view requires a set of architectural concepts and structural rules that focus on particular concerns within that system (Miller, 2003). The specification of conventions for the use of such concepts and rules is in fact a system abstraction that is commonly called a viewpoint (also development perspective). Thus, each view is associated to a viewpoint.

Table 4.1 Views are associated to viewpoints and models

<b>View</b>	<b>Viewpoint</b>	<b>Model</b>
Computational-Independent View	Computational-Independent Viewpoint	Computational-Independent Model (CIM)
Platform-Independent View	Platform-Independent Viewpoint	Platform-Independent Model (PIM)
Platform-Specific View	Platform-Specific Viewpoint	Platform-Specific Model (PSM)
Platform View	Platform Viewpoint	Platform (/Physical) Model (PM)

MDA defines four distinct viewpoints that are associated to four main views (see Table 4.1):

1. Computational-Independent Viewpoint (CIV): defines domain-specific structuring rules without specifying the structure of the system. A model developed from this viewpoint is called Computational-Independent Model (CIM). A CIM is intended to bridge the gap between domain experts and system designers. It expresses domain-specific requirements (Miller, 2003);
2. Platform-Independent Viewpoint (PIV): focuses on the system's operation rules while hiding the details necessary for a particular platform. Platform-Independent Models (PIMs) are developed from this viewpoint (Miller, 2003);
3. Platform-Specific Viewpoint (PSV): focuses on platform-specific features and artifacts that enable the development of an operating system (Miller, 2003). The related models are called Platform-Specific Models (PSMs);
4. Platform Viewpoint (PV): provides a set of technical concepts representing the different platform services and features (e.g., runtime environment) and how the specified system is

connected to them (Miller, 2003). The related models are called platform (also physical) models.

Views and viewpoints are interrelated. However, to be effective, they require some notions to be defined (mostly depending on the context). For example, we cite:

- Independence: it is defined, in the context of MDA, as the “*quality that the model does not call for the support of a platform of a particular type [or relying on particular features]*” (Miller, 2003, p. 31);
- Platform: in MDA, the notion of platform is the most floating due to the existence of myriad different frameworks that can be considered as such. That is why according to (Miller, 2003), the OMG did not include a deliberate definition of platform in MDA standard. However, there were a number of attempts to define the term such as (Beydeda, Book et Gruhn, 2005) who considers a platform as “*a set of subsystems and technologies that provide the capabilities needed to support the execution of a software application*” (p. 121);
- System: it is often defined as “*a set of parts, connected and interrelated, forming a complex whole*” (Miller, 2003, p. 12). In software domain, a system may be defined as one or many applications supported by one or many (hardware and/or software) platforms.

As previously mentioned, the four MDA views/viewpoints result in four key models that represent the fundamental ingredients of the software design approach:

1. Computational-Independent Model (CIM): it expresses business-/domain-specific concerns and often uses an expert vocabulary to express the system’s specifications without any reference to platform and technology information (Almeida, 2008). It is considered as a contractual reference that is elaborated to capture high-level client requirements (Almeida, 2008; Baudry, Nebut et Le Traon, 2007);
2. Platform-Independent Model (PIM): it deals with the constraints that a system requires to be properly implemented. The PIM remains independent from the underlying technology (e.g., OS, programming frameworks, middleware, etc.) (Almeida, 2008);

3. Platform-Specific Model (PSM): it describes the system with regard to platform- and language-specific elements (e.g., class model, schema model, interface code model, database model, etc.) (Almeida, 2008);
4. Platform Model (PM): it is also called physical model. It provides physical artifacts and resources used during runtime (e.g., source code, executable, libraries, etc.) (Frankel, 2003).

As shown in Figure 4.23, these four models correspond to four distinct abstraction levels. The CIM and PM are considered respectively as the highest and lowest levels of abstraction. For each CIM (i.e., requirements/domain-specific model), a PIM is defined. From each PIM, multiple PSMs and PMs (i.e., implementations) can be derived. MDA considers the automated generation of models at a given abstraction level from the upper (and/or lower) ones using a mechanism of model-to-model transformation. Relevant tools use this mechanism to automate as much as possible the software development process.

- **Transformations and Mappings**

As explained in the previous section, MDA divides software development process into two main areas: (i) platform-independent, including CIM and PIM where models are meant to be independent from technology information and (ii) platform-specific, including PSMs and PMs, where models target specific execution platforms and runtime environments. MDA uses model-to-model transformations to enable the transition between the various types of models and thus move the system design from one abstraction level to another (i.e., from specification to implementation) (Fernandes).

A model-to-model transformation is the process of converting a source model conforming to a given meta-model to a target model conforming to a given meta-model as well, either at the same abstraction level or at a different one (Miller, 2003). This process relies on a transformation mechanism composed of two main elements (Pastor et Molina, 2007):

1. Mappings: establish relationships between elements in the source model and their counterparts in the target model. Their goal is to characterize how elements in the latter

can be derived from elements in the former. Generally, mappings are not bijective functions which reflects that the target model is not unique and can be derived in various ways;

2. Transformation rules and/or flow: consists of a set of rules that use mappings in order to generate the elements of the target model from those of the source model.

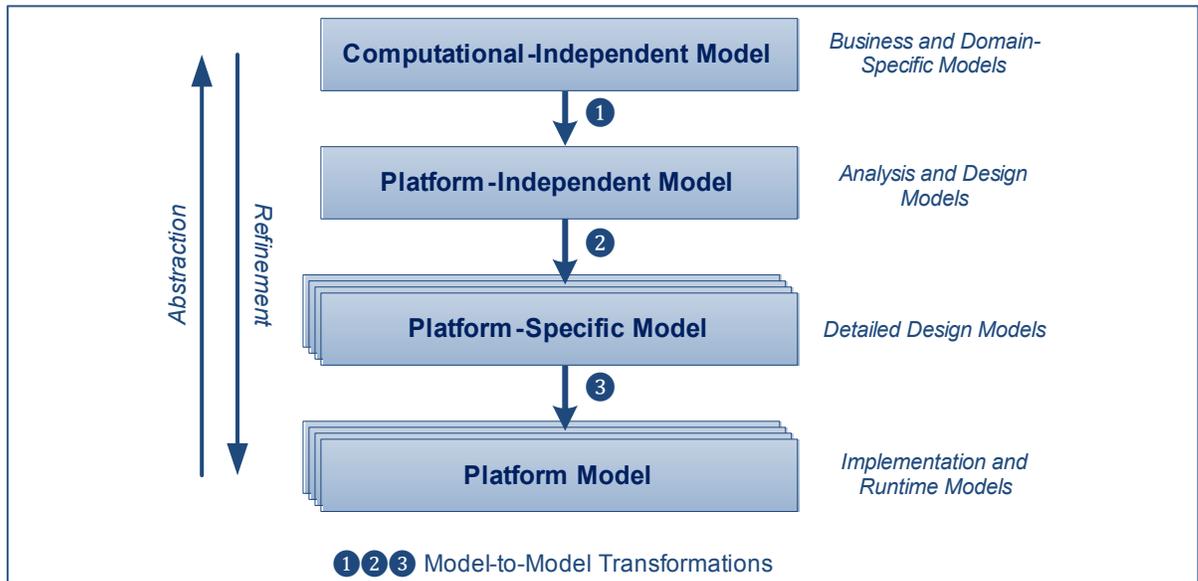


Figure 4.23 Automation process in MDE/MDA framework encompasses four abstraction levels and three model-to-model transformations

The transformation process takes as input a source model that is compiled to derive a target model and a transformation record (see Figure 4.24). The transformation record is a kind of chart that logs which source model elements were mapped to which target model elements and indicate the mapping rules that were used for each part of the transformation (Truyen, 2006).



Figure 4.24 Model-to-Model transformation in MDE/MDA

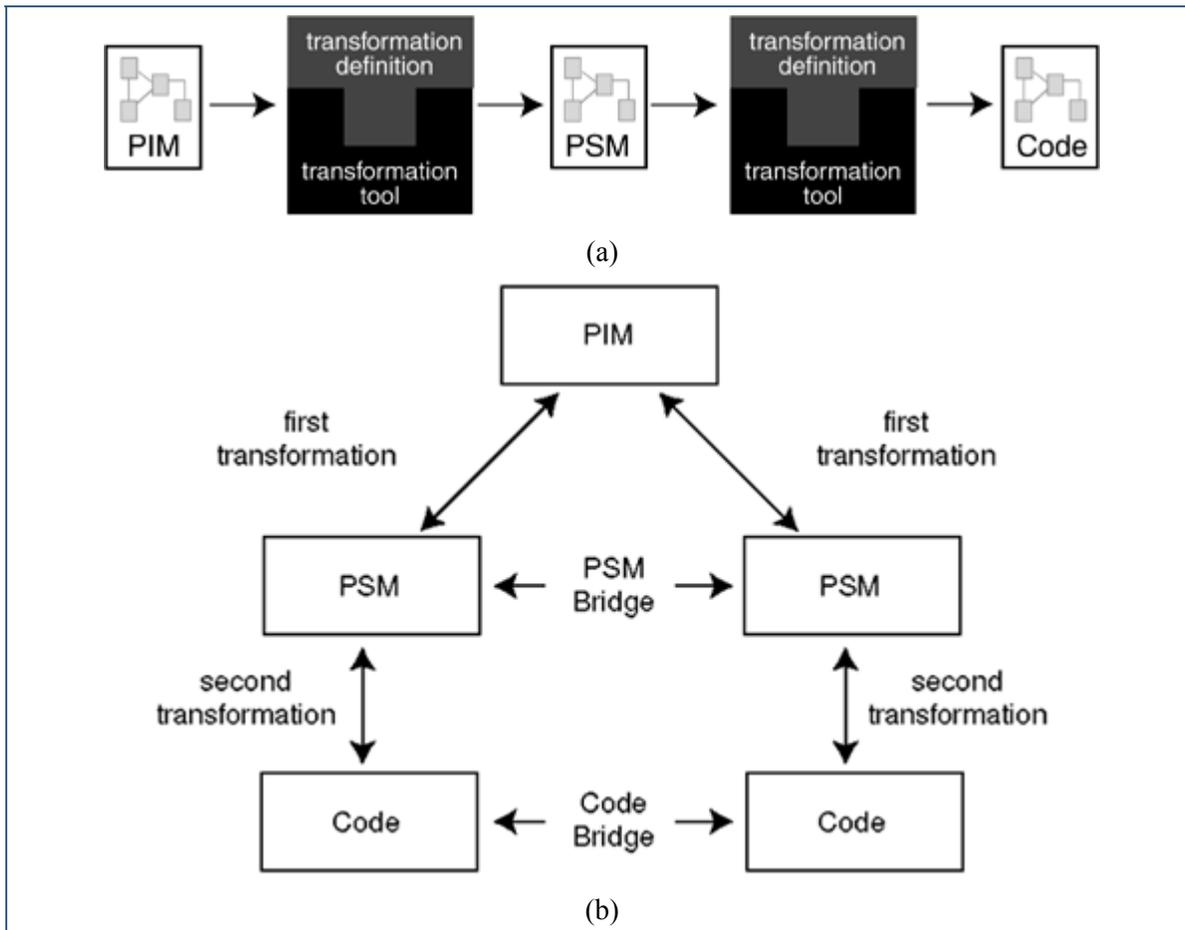


Figure 4.25 Model-to-Model transformation: (a) PIM to PSM transformation and  
(b) transformation bridges

Taken from Kleppe, Warmer et Bast (2003)

Mappings and transformation rules/flow are sometimes referred to as transformation definition. Transformations should be fully defined in order to enable the generation of the target model (Pastor et Molina, 2007). This mechanism is expected to improve automation capability since appropriate tools can be used to automatically process models given the relevant transformation definitions. Currently, most transformation definitions are still manually adjusted.

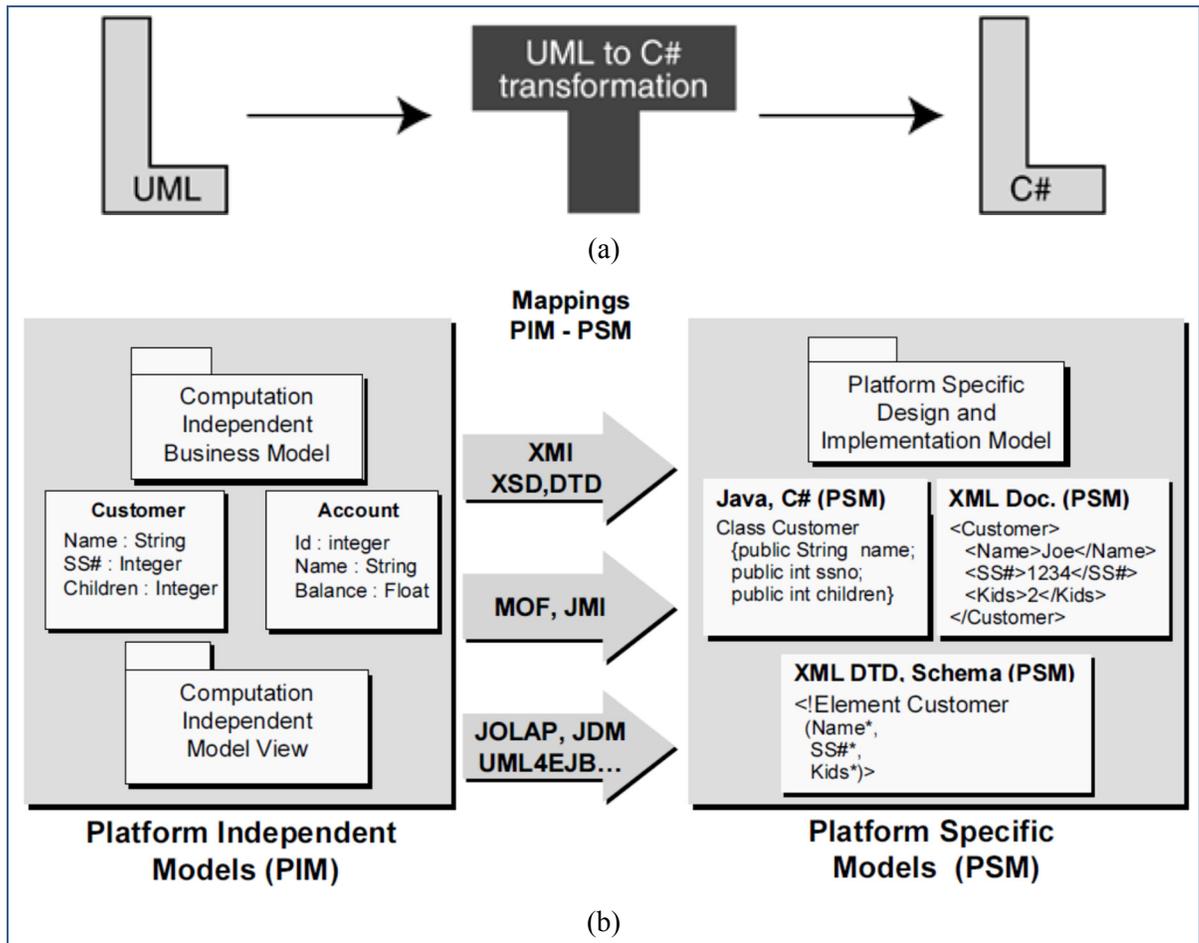


Figure 4.26 An example of PIM to PSM mapping: (a) UML to C# Transformation  
Taken from Kleppe, Warmer et Bast (2003)

(b) The same PIM (i.e., UML models) is transformed into three PSMs (corresponding to three different source code representations) given the relevant platform specifications  
Taken from Beydeda, Book et Gruhn (2005)

In addition, most current transformations are unidirectional in a sense that the source model cannot reverse-engineered from the target one. Nevertheless, bidirectional transformations are more powerful, amenable for automation and allow better traceability than unidirectional ones. Figure 4.25.a shows how a combination of the transformation definition and tool can be used to derive PSM from PIM and source code (i.e., an implementation, platform model) from a PSM.

Moreover, transformations are not used only for the compilation of models at different levels of abstraction. It is possible to generate a model (e.g., PIM, PSM, and PM) from another one

which often serves for the refinement of that model (Fernandes). The transformation used for this purpose is commonly called a “*bridge*” (Kleppe, Warmer et Bast, 2003). Transformation bridges (see Figure 4.25.b) enable interoperability (i.e., a major goal of MDA) because they allow the creation of multiple PSMs (respectively PMs) for different platforms from a single PIM (respectively PSM) (Kleppe, Warmer et Bast, 2003).

#### 4.2.5 Hardware Abstraction in Other Domains

We have studied so far how hardware abstraction applies to digital and analog/mixed-signal design, some computer-based systems (e.g., operating systems, databases, networking) and software engineering. It is worth noting that this concept was not limited to these domains but was adopted in a myriad of other domains. In the following, we briefly present two examples of recent hardware abstraction strategies that were used for the development of software-defined radios systems and applications.

##### a) Software Communication Architecture (SCA) and its Modem Hardware Abstraction Layer (MHAL)

The Software Communication Architecture (SCA) is a core framework that was developed by the Joint Tactical Radio System<sup>83</sup> (JTRS) to standardize the development of software-defined radios for both military and civil applications (Aguayo Gonzalez, Portelinha et Reed, 2007). It was designed to provide standard application-layer interfaces and services that allow waveforms to run on different hardware platforms (Lind et Littke, 2004). It particularly implements CORBA-based services in order to enable the portability of software code among hardware platforms and the interoperability between heterogeneous systems. In fact, hardware platforms addressed by SCA are mostly limited to GPPs and does not extend this service to digital signal processing platforms (such as DSP and FPGA) (Dackenberg, 2010). For this reason, it was augmented with a special abstraction layer, namely Modem Hardware Abstraction Layer (MHAL) (JTRS, 2010), which implements a standard messaging structure

---

<sup>83</sup> The Joint Tactical Radio System is a US defense program for the development and acquisition of next-generation voice-and-data radio for military use.

and architectural model to enable communications between all hardware MHAL-capable platforms (Pucker, 2007).

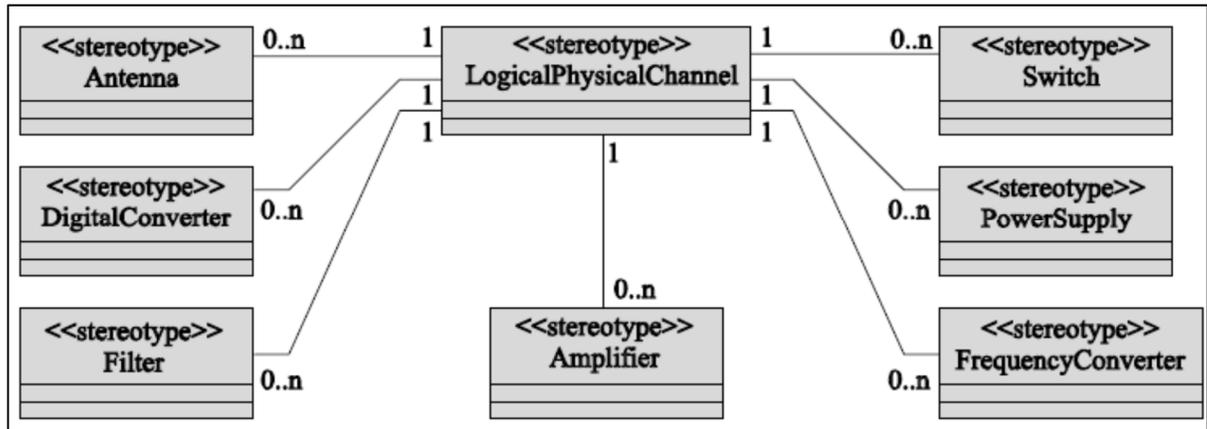


Figure 4.27 An excerpt of the UML profile for software radios: a logical-physical channel stereotype abstracts devices that provide analog communications (e.g., RF)  
Taken from OMG (2007); Vivier (2013)

#### b) OMG's UML Profile for Software Radios

The OMG has proposed a UML profile for software radios, namely “*UML Profile for SWRadio*” (OMG, 2007). It is an extension of UML whose purpose is the development of UML tools to support the creation of software-defined radio applications and systems. It was thought to provide infrastructure/middleware providers, application/device developers and SDR-platform providers with artifacts that facilitate the modeling, validation and manipulation of SDR systems and applications (OMG, 2007). Based on OMG's MDA, this UML profile was structured into two main parts: (i) a PIM that defines a set of interfaces appropriate for building SDR components, and (ii) a PSM that implements the PIM in CORBA and XML. Its various concepts were specified with emphasis on automation (OMG, 2007). This includes the use of the defined models to perform simulations as well as the automated generation of code for SDR applications (OMG, 2007).

Each part of the UML profile defines key concepts required to describe aspects performing a specific role within the SDR product. Particularly, the chapter entitled “*Communication Equipment*” of this UML profile defines a set of stereotypes that can be used to describe the basic elements of a software-defined radio, waveform components and radio environment

(Vivier, 2013). It allows for example the description of the SDR building blocks and the relationships between them (OMG, 2007; Vivier, 2013). For instance, RF devices are modeled using stereotypes such as the *LogicalPhysicalChannel* (see Figure 4.27).

The UML profile for software radios was developed with intent to be independent from the underlying middleware and platform technologies in order to enable its use in other domains besides SDR design (OMG, 2007).

### **4.3 Proposed RF and Microwave Hardware Abstraction Strategy**

We presented in the previous section a comprehensive overview of outstanding hardware abstraction strategies that were adopted in some engineering domains. We have particularly outlined the issues that led to the adoption of these abstraction strategies. We have also emphasized their respective contributions to the resolution of these issues and particularly their impact on complexity management and automation enhancement. In the light of this study, we propose in this section a hardware abstraction strategy for RF systems that aims primarily at simplifying their representations and enabling better manipulation of these representations. We focus particularly on basics of the RF functionality modeling, the definition of related abstraction levels and viewpoints as well as the transition process between the different models and representations.

#### **4.3.1 Scope and Objectives**

The abstraction strategy depicted henceforth applies to RF systems. The objectives of this abstraction strategy are:

1. Identification of an effective modeling manner of RF systems,
2. Definition of a hierarchy of abstraction levels and corresponding design perspectives applicable to RF systems, and
3. Definition of adequate mechanisms for the manipulation of models and transition between the different abstraction levels.

### 4.3.2 Basic Definitions

To foster better understanding of the proposed abstraction strategy, these alphabetically ordered terms and definitions apply in the following:

- Abstraction: the process of representing a RF system at a given level of detail and with respect to a given design viewpoint.
- Abstraction View: an extent in which models result from an association of an abstraction level and an abstraction viewpoint.
  - **Examples:** Requirements, platform-independent, platform-specific, and platform models.
- Abstraction level: a reasonable characterization related to the complexity and details in a representation of a RF system.
  - **Examples:** Component, circuit, module, and system.
- Abstraction viewpoint: a representation of a RF system from a design perspective that focuses on particular concerns within that system.
  - **Examples:** Functional, architectural, structural, electrical, and physical.
- Coherence: the quality of a model, a specification or a functionality of being composed of mutually consistent and non-contradictory elements (and/or attributes).
- Formal model: a model that is semantically consistent in a sense that it complies with the semantic rules of a given modeling language.
- Functionality: a field of operation related to a RF system which can be modeled using a given response function (or/and physical or logical description).
- Granularity: a specification that characterizes the number of parts composing a RF/microwave system with the guarantee that each part among them represents a coherent functionality.
- Independence: the quality of a model of being usable without specifying any technology information or platform-related attributes.
- Model: a formal representation of the functionality, structure, behavior or/and physics of a RF system.

- Platform: a set of radiofrequency/microwave technologies (or physical infrastructure) that is either required or can be used to implement a given functionality.
  - **Examples:** FR-4 microstrip lines, thin-film resistors, etc.
- Platform-independent model: a RF system model that does not specify any technology information or platform-related attributes.
- Platform-specific model: a RF system model that includes technology information or platform-related attributes to be utilized in the implementation of that system.
- Platform model (implementation): a RF system model that describes the physics and/or the detailed implementation of that system.
- Refinement: the process of adding more details to an existing model.
- System: a RF entity that is characterized by a coherent (i.e., deterministic) and identifiable functionality and a set of ports (or interfaces) enabling the interaction with its environment.
  - **Examples:** Component (i.e., device), circuit, building block (i.e., subsystem, module), system, system of systems, etc.
- Technology mapping: the process of associating a physical platform (i.e., technology data or information) to a platform-specific RF system model.
- Transformation: a process that translates a source model to another one given eventually a set of specifications, rules, flows, specific data or tools.

### 4.3.3 Functional Description of RF and Microwave Systems: Black-Box Model

As previously detailed, modeling is the art of representing a complex reality while abstraction is the art of simplifying the resulting representation. Since abstraction and modeling are interrelated, the first question to answer is how to uniformly model RF systems? It is worth noting that the term “RF system” is generic in a sense that characterizes any RF coherent and identifiable functionality (with no predetermined viewpoint). Thus, we require a unified (ideally simple and expressive) representation that captures the different RF systems’ functionalities. In addition, this representation should be amenable for formal expression meaning that it can be expressed using semantically consistent languages (i.e., modeling languages, DSL, etc.).

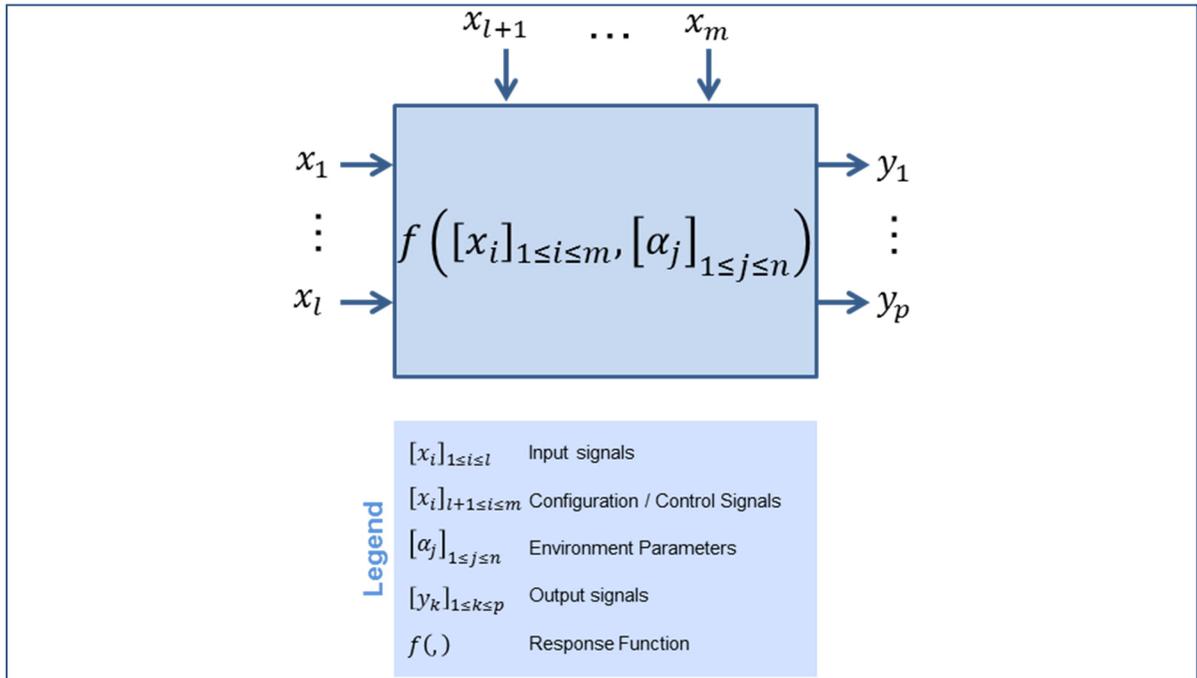


Figure 4.28 A black-box view considers a RF system as an entity which is defined by its inputs/outputs and its response function

### a) Mathematical modeling of RF systems

In the previous chapter, we have already defined the concept of functional description to capture the specifications of RF systems. In this section, we propose to adopt the same functional perspective in modeling process of these systems. For this purpose, we consider a RF system as a black box that is defined by a set of inputs and outputs along with its functionality. Figure 4.28 illustrates this concept with an entity whose functionality can for example be captured using a given mathematical formalism and three sets of inputs and outputs. The advantage of this definition is its genericity. This definition remains applicable despite the mix of functions that a RF system may have and the need to capture its functionality at different levels of abstraction.

#### 1. System inputs and outputs

A RF/microwave system interacts with its environment using input and/or output ports whose propagating signals of different types (e.g., DC, AC, and RF). The black-box model we are proposing captures this behavior by considering the inputs (if existing) as ingredients that are used by the model's response function to produce the outputs. This definition does not specify

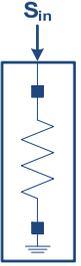
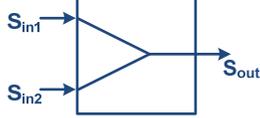
in prior the directionality of ports which allows to describe situations where inputs and outputs may interchange their roles during system's operation. At this regard, we define two types of inputs:

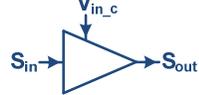
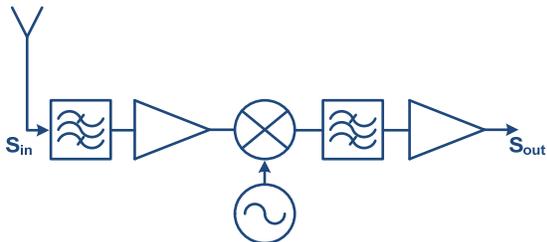
- Regular inputs: (designated by  $S_{in}$  and  $S_{out}$  in Table 4.2) represent a typical AC or RF signal, and
- Control inputs: (designated by  $V_{in_c}$  in Table 4.2) represent a signal (typically DC) that is used to drive the RF/microwave system (e.g., input voltage in a voltage-controlled oscillator and an automatic-gain control);
- Environment parameters: (designated by  $\alpha_i$  in Figure 4.28) represent variables that are not regular signal inputs to the system but characterize the environment and the context of operation (e.g. time, temperature, frequency, reference impedance, etc.).

This said, it might be sometimes useful, from abstraction perspective, to ignore some inputs (respectively outputs) in the modeling of some RF systems. In this case, there is generally a “hidden” input (respectively output) that is not considered in the model. For instance, biasing input voltages may be ignored in oscillators and amplifiers. The reflected RF signal is generally neglected in a termination device. These cases are represented in Table 4.2 by a void symbol ( $\emptyset$ ).

As shown in Figure 4.28, the model's response function takes as input two vectors of  $m$  and  $n$  elements (i.e., signal and environment inputs respectively) and produces a vector of  $p$  elements (i.e., outputs). The examples of Table 4.2 suggest that input and output signals (i.e.,  $S_{in}$ ,  $V_{in_c}$  and  $S_{out}$ ) are assumed to be single voltage or power magnitudes. This is true for this case. But in general, a regular input  $x_i$  (respectively output  $y_j$ ) can be a list of parameters characterizing different measurements and/or constants related to a given port (e.g., power, frequency, impedance, etc.) and this is regardless of environment inputs. In this case,  $x_i$  (respectively output  $y_j$ ) is represented as  $x_i(P_i, F_i, Z_i, \dots)$  (respectively  $y_j(P_i, F_i, Z_i, \dots)$ ).

Table 4.2 RF systems can be viewed as black-boxes with inputs and outputs

RF/Microwave Functionality	Device View	Input Parameters	Output Parameters
Oscillator	 <p><math>S_{out}</math>: output signal</p>	$\emptyset$	$Y = [S_{out}]$
Termination	 <p><math>S_{out}</math>: input signal</p>	$X = [S_{in}]$	$\emptyset$
Voltage-Controlled Oscillator	 <p><math>V_{in\_c}</math>: control signal <math>S_{out}</math>: output signal</p>	$X = [V_{in\_c}]$	$Y = [S_{out}]$
Filter	 <p><math>S_{in}</math>: input signal <math>S_{out}</math>: output signal</p>	$X = [S_{in}]$	$Y = [S_{out}]$
Mixer	 <p><math>S_{in1}</math>: input signal #1 <math>S_{in2}</math>: input signal #2 <math>S_{out}</math>: output signal</p>	$X = \begin{bmatrix} S_{in1} \\ S_{in2} \end{bmatrix}$	$Y = [S_{out}]$
Combiner	 <p><math>S_{in1}</math>: input signal #1 <math>S_{in2}</math>: control signal #2 <math>S_{out}</math>: output signal <math>Z_0</math>: 50 <math>\Omega</math></p>	$X = \begin{bmatrix} S_{in1} \\ S_{in2} \\ Z_0 \end{bmatrix}$	$Y = [S_{out}]$

RF/Microwave Functionality	Device View	Input Parameters	Output Parameters
Amplifier	 <p> <math>S_{in}</math>: input signal  <math>S_{out}</math>: output signal  <math>Z_0</math>: 50 <math>\Omega</math>  <math>T_{ref}</math>: 25° C                 </p>	$X = \begin{bmatrix} S_{in} \\ Z_0 \\ T_{ref} \end{bmatrix}$	$Y = [S_{out}]$
Automated-Gain Control	 <p> <math>S_{in}</math>: input signal  <math>V_{in,c}</math>: control signal  <math>S_{out}</math>: output signal                 </p>	$X = \begin{bmatrix} S_{in} \\ V_{in,c} \end{bmatrix}$	$Y = [S_{out}]$
Coupler	 <p> <math>S_{in}</math>: input signal  <math>S_{out1}</math>: output signal #1  <math>S_{out2}</math>: output signal #2  <math>S_{out3}</math>: output signal #3                 </p>	$X = [S_{in}]$	$Y = \begin{bmatrix} S_{out1} \\ S_{out2} \\ S_{out3} \end{bmatrix}$
Direct-Conversion Receiver	 <p> <math>S_{in}</math>: input signal  <math>S_{out}</math>: output signal                 </p>	$X = [S_{in}]$	$Y = [S_{out}]$

## 2. System functionality

Each RF/microwave system is characterized by a response function that expresses the way it behaves towards input stimulants. In the proposed black-box model, this response function is may be represented by a:

- Mathematical transfer function: which uses an elaborated mathematical formalism to model the system’s response (e.g., rows 1 through 4 in Table 4.3),
- Data-based response function: which captures the system’s functionality using a data file resulting from either simulations or measurements (e.g., row 6 in Table 4.3),

- Expression-based response function: which uses mathematical equations along with datasets to characterize the system’s functionality (e.g., rows 5 in Table 4.3), and
- Hybrid response function: that uses a mix of the previous types to characterize the system’s functionality.

In the first four rows of Table 4.3, “first-order” mathematical functions (i.e., equations (4.1) through (4.4)) were defined to model the frequency response of four RF building blocks (i.e., Class-A amplifier, bandpass filter, mixer and oscillator). These examples of response functions are intended only to illustrate how a system’s functionality can be mathematically described. In fact, the mathematical modeling of RF systems is more complex than what is presented in these trivial examples. For instance, it should characterize the device’s response in different operation scenarios (e.g., large vs. small signal) and domains (e.g., frequency vs. time domain).

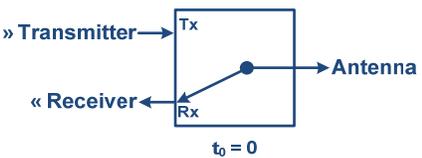
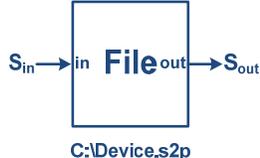
The last two rows of Table 4.3 present the response function of a switch and a typical linear file-based component. The first one is defined by a table that gives the switch states every 10 milliseconds (i.e., switching speed). The second is captured using a Touchstone file (i.e., scattering parameters). It is worth noting that the response function is not unique. Therefore, a RF system can be modeled for example using two response functions: one is mathematical and the other is file-based. It is for instance the case of a bandpass RF filter which is also a linear device. Then, its response function can be either as given in equation (4.2) or as presented in row 6 of Table 4.3. This said, the major advantage of all these response function representations is their independence from technology that makes them good candidates for high-level abstraction in RF domain.

### **b) Formal modeling of RF systems**

Since the black-box model allows to capturing individual RF system in terms of functionality and inputs/outputs (i.e., interfaces), we need to extend the usability of this definition in order to: (i) describe complex systems (i.e., composed of multiple parts and building blocks) and (ii) capture the different aspects pertaining to the composition, the interaction and the attributes of these complex systems as well as the various relationships that may exist between them.

Table 4.3 RF and microwave systems can be modeled using response functions

No.	RF/Microwave Functionality	Response Function
1	Class-A Amplifier	<p><b>Functionality:</b> a class-A amplifier increases the input signal power with a <math>\alpha_{dB}</math> dB and conducts over the entire range of the input cycle (delimited by the frequencies <math>F_L</math> and <math>F_H</math> where <math>F_L \leq F_H</math>).</p> $\forall f \in [F_L..F_H], \begin{cases} A_o(f) = A_i(f) + \alpha_{dB} \\ \varphi_o(f) = \varphi_i(f) + \pi \end{cases} \quad (4.1)$ <p>where:</p> <ul style="list-style-type: none"> <li>• <math>A_i</math> and <math>A_o</math> are input and output signal magnitude in dB,</li> <li>• <math>\alpha_{dB}</math> is amplifier gain in dB,</li> <li>• <math>\varphi_i</math> and <math>\varphi_o</math> are input and output signal phase (in radians).</li> </ul>
2	Bandpass Filter	<p><b>Functionality:</b> a bandpass filter selects a range of frequencies between frequencies <math>F_L</math> and <math>F_H</math> (where <math>F_L \leq F_H</math>) and rejects the frequencies outside this range.</p> $\begin{cases} A_o(f) = A_i(f) - \alpha_{3dB} \quad \forall f \in [F_L..F_H] \\ A_o(f) = A_i(f) - \alpha_{dB}^{(f)} \quad \forall f \notin [F_L..F_H] \\ \varphi_o(f) = \varphi_i(f) \pm \theta_k^{(f)} \quad \forall f, k \in \mathbb{N} \end{cases} \quad (4.2)$ <p>where:</p> <ul style="list-style-type: none"> <li>• <math>A_i</math> and <math>A_o</math> are input and output signal magnitude in dB,</li> <li>• <math>\alpha_{3dB}</math> and <math>\alpha_{dB}^{(f)}</math> are passband and stopband attenuations in dB,</li> <li>• <math>\varphi_i</math> and <math>\varphi_o</math> are input and output signal phase (in radians),</li> <li>• <math>\theta_k^{(f)}</math> is phase delay at frequency <math>f</math> (in radians).</li> </ul>
3	Mixer (Up-conversion mode)	<p><b>Functionality:</b> a mixer produces new signal frequencies (sum (up-conversion): <math>f_1 + f_2</math> and difference (down-conversion): <math>f_1 - f_2</math>) from two input frequencies <math>f_1</math> and <math>f_2</math>.</p> $\begin{cases} A_o(f_1 + f_2) = \frac{A_i(f_1) \cdot A_i(f_2)}{2} \\ \varphi_o(f_1 + f_2) = \varphi_i(f_1) + \varphi_i(f_2) + \phi \end{cases} \quad (4.3)$ <p>where:</p> <ul style="list-style-type: none"> <li>• <math>A_i</math> and <math>A_o</math> are input and output signal magnitude in dB,</li> <li>• <math>\varphi_i</math> and <math>\varphi_o</math> are input and output signal phase (in radians),</li> <li>• <math>\phi</math> is an additional signal phase (in radians).</li> </ul>
4	Oscillator	<p><b>Functionality:</b> an oscillator produces a RF signal at frequency <math>F_0</math> whose power is <math>P_{ref}</math> dBm.</p>

No.	RF/Microwave Functionality	Response Function										
		$\begin{cases} \forall f \neq F_0, A_o(f) \ll 10^{\frac{P_{ref}}{20}} \\ A_o(F_0) = 10^{\frac{P_{ref}}{20}} \end{cases} \quad (4.4)$ <p>where:</p> <ul style="list-style-type: none"> <li>• <math>A_o</math> is output signal magnitude in dBm,</li> <li>• <math>P_{ref}</math> is a reference output power.</li> </ul>										
5	Switch	<p><b>Functionality:</b> a switch routes RF signals through transmission paths.</p>  <table border="1" data-bbox="1242 766 1404 945"> <thead> <tr> <th>Time</th> <th>State</th> </tr> </thead> <tbody> <tr> <td>0</td> <td>Rx</td> </tr> <tr> <td>10 ms</td> <td>Tx</td> </tr> <tr> <td>20 ms</td> <td>Rx</td> </tr> <tr> <td>30 ms</td> <td>Tx</td> </tr> </tbody> </table>	Time	State	0	Rx	10 ms	Tx	20 ms	Rx	30 ms	Tx
Time	State											
0	Rx											
10 ms	Tx											
20 ms	Rx											
30 ms	Tx											
6	Linear File-based Component	<p><b>Functionality:</b> a linear file-based component captures generally frequency response of a linear RF component in a data file resulting from either simulation or measurements.</p> 										

First, a complex system is typically composed of a set of identifiable subsystems. A black-box model may capture each one among these systems. The combination of all these black-box models results naturally in another black-box model that characterizes the complex system itself. For instance, its response function is a nested combination of the individual subsystems' response functions. If identifying the links between a system and its subsystems were possible, formal expression of these links would require complex and tricky reasoning. As far as this thesis is concerned, we made the choice to leave this research activity to future works. Consequently, the definition of a rigorous mathematical formalism that expresses the mathematical conditions and relationships linking the system's response function to those of its subsystems falls beyond the scope of this thesis.

Moreover, the black-box model was proposed mainly to simplify as much as possible the representation of a RF system. That is why all the details related to the internal building blocks (e.g., composition, organization, interactions, etc.) were removed. Thus, this model is capable to describe an individual or a set of interrelated RF systems in terms of response function and inputs/outputs. Nevertheless, it delivers little information about how these subsystems are organized (i.e., structure) and interact (i.e., behavior). To capture these aspects, a mechanism of strong semantics is required. We have already faced this issue in the previous chapter when we had to define mechanisms for functional description of RF systems. The solution we have proposed is the use of a modeling language (i.e., SysML<sup>84</sup>) in order to express not only the design structural and behavioral aspects but also capturing its requirements and specifications. Therefore, we will make use again of modeling languages in order to “formally” express the requirements, structural and behavioral aspects of RF systems. It is worth to note that the word “*formal*” used in this context does not denote rigorous mathematical construction but rather compliance with semantic rules and constraints of a given modeling language.

Regarding SysML, it dedicates three main types of diagrams for the structural description of a system:

- Block definition diagram (bdd): it is used for the description of system’s components and hierarchy,
- Internal definition diagram (ibd): it is used for the depiction of internal structure of the system and its components, and
- Package diagram (pkg): it gathers system models in logical collections whose describing a given view of the system.

SysML dedicates four additional types of diagrams for the description of system’s dynamic behavior:

- Activity diagram (act): it is used to captures the evolution of the system in terms of activities,

---

<sup>84</sup> The reader may refer to APPENDIX II (p. 439) for more detailed overview of SysML.

- Sequence diagram (sd): it describes the flow of messages and interactions between the different system components,
- State machine diagram (stm): it describe the system status at each state and its transitions between two different states, and
- Use case diagram (uc): it captures how external actors use the system and how it is expected to react towards external actions.

In addition, SysML has introduced two new diagrams to help designers expressing domain-specific artefacts:

- Requirements diagram (req): it is used for the definition of constraints and rules (including mathematical formulas, physical laws, mechanical constraints, etc.) that are associated to the system properties of to those related to its building blocks. Thus, it helps integrating system models with relevant engineering tools to carry out various system analyses and simulations (e.g., performance, reliability, etc.), and
- Parametric diagram (par): it provides modeling constructs to capture text-based requirements into graphical, tabular or tree structure format and associate them with the system's structural and/or behavioral model elements using predefined relationships.

The structure of a black-box model of a RF system (as depicted in Figure 4.28) can be captured using a block definition diagram (bdd) as shown in Figure 4.29. The system is described by a block, namely RF system, whose environment parameters are captured in the section “*values*” and its response function is captured in the section “*constraints*”. This block is composed of  $m$  blocks, namely input ports (respectively  $p$  blocks, namely output ports). The environment parameters related to each port can be captured in the section “*values*”.

In general, real-world RF systems (e.g. receivers, transmitters, etc.) are not described as single blocks. Designers need to architect the internals of such systems at different levels of granularity (depending on the adopted topology) and from different design perspectives (e.g. electrical, mechanical, thermal, etc.). Then, is it possible to use SysML to capture the internal architecture and behavior of such complex systems?

To illustrate this, we consider a typical heterodyne architecture of a UMTS Terrestrial Radio Access/Frequency Division Duplex (UTRA/FDD) compliant mobile transceiver (see Figure 4.30). This transceiver is a radio whose RF front-end is composed of three parts: (i) duplex filter, (ii) transmitter and (iii) receiver. We have already attempted to model this transceiver using SysML in some detail (see (Lafi et al., 2008)).

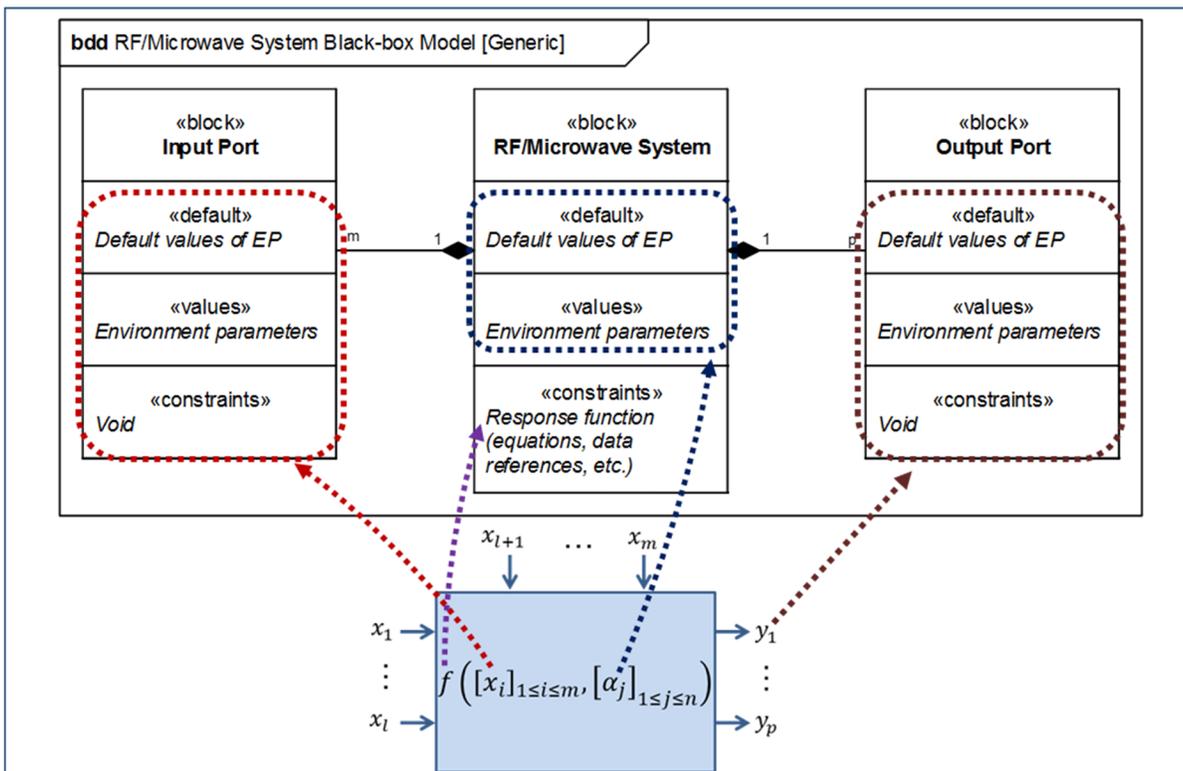


Figure 4.29 SysML black-box model of a RF system

In Figure 4.31.a, we use a package diagram to capture the design perspectives we are considering in the design of the transceiver. Three main packages are presented:

1. Package 1 (Transceiver Structure): gathers models that capture the transceiver architecture and internal topology,
2. Package 2 (Transceiver Behavior): groups the models that describe both the internal and external behavior of the transceiver, and
3. Package 3 (Transceiver Requirements): assembles the models capturing the text-based transceiver requirements.

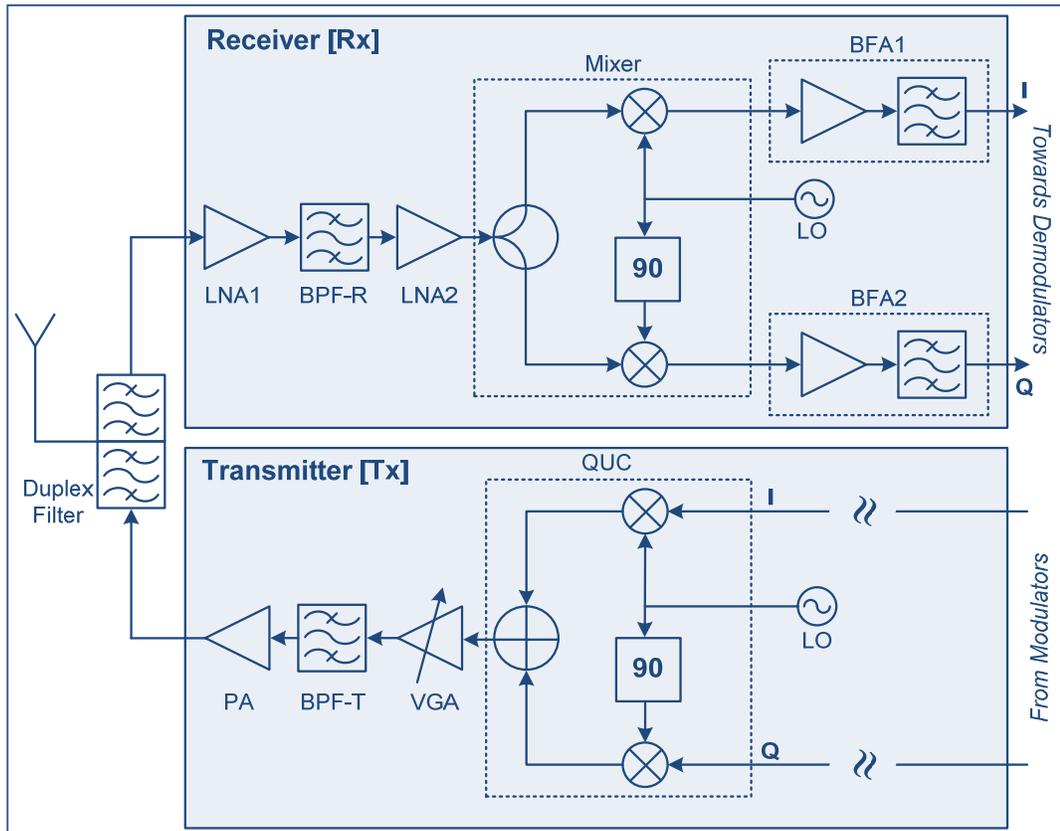


Figure 4.30 The block diagram of a UMTS FDD transceiver

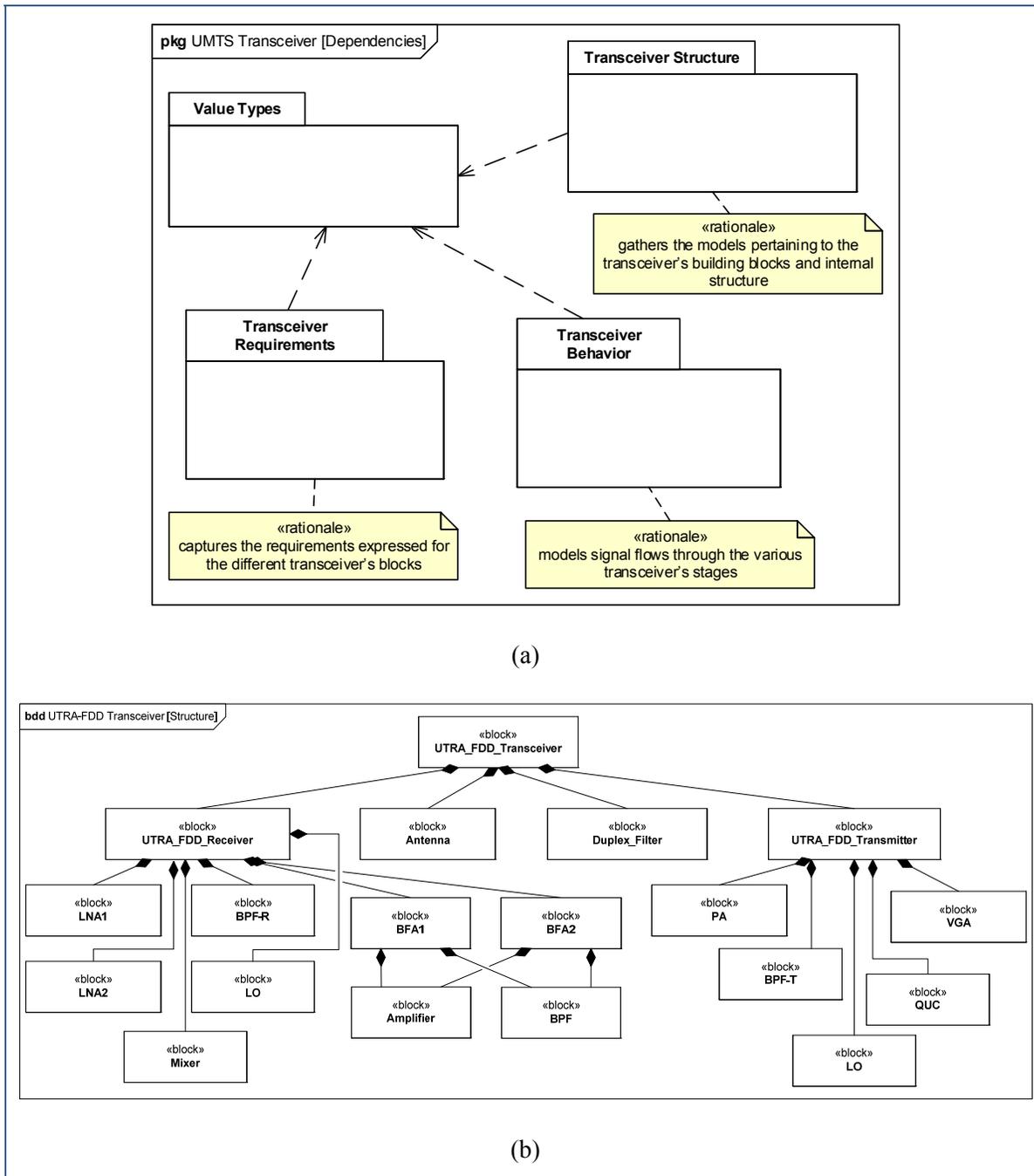


Figure 4.31 SysML allows the expression of different aspects in RF systems: (a) package diagram (b) the transceiver’s associated block definition diagram

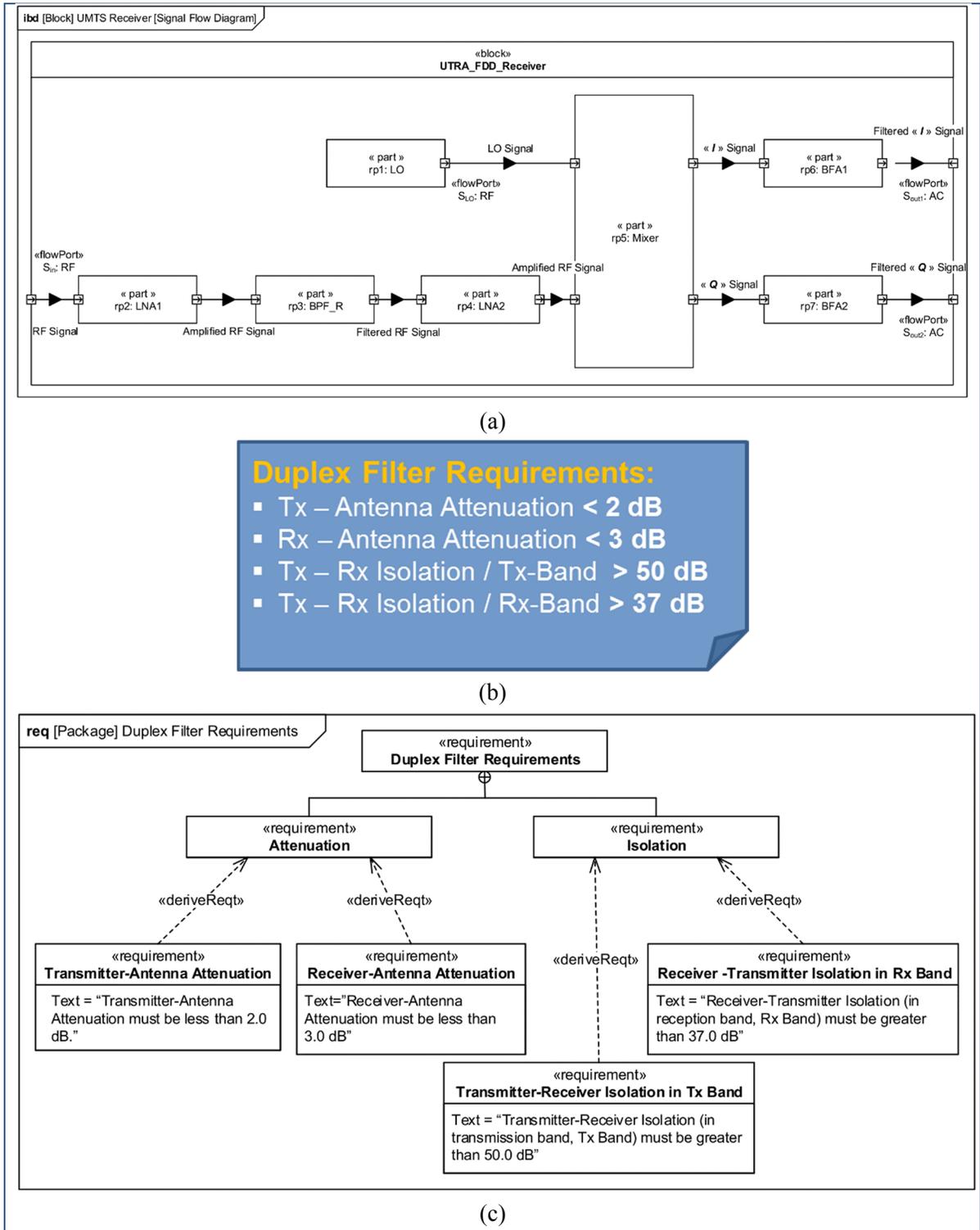


Figure 4.32 SysML allows the expression of different aspects in RF systems (cont'd):  
 (a) the receiver's internal block diagram (b) the duplex filter specifications  
 (c) the duplex filter requirements diagram  
 Adapted from Lafi et al. (2008)

All three packages are associated to a fourth package, namely “*values types*” (using a “*dependency*” relationship). In this package, we capture the measurements units (e.g., [Frequency, MHz], [Chip rate, Mcps], [bit rate, Kbps], etc.) and dimensions that characterize the signals and flows travelling through the different transceiver blocks and parts. The package diagram of Figure 4.31.a shows the highest abstraction level we have considered in (Lafi et al., 2008).

The block definition diagram (bdd) of Figure 4.31.b and the internal block definition diagram of Figure 4.32.a are among of the models contained in package 1. The former depicts the internal hierarchy of the transceiver while the latter shows the flow of signals within the receiver. In addition, Figure 4.32.b depicts a piece from the written specifications of the duplex filter composing the UMTS transceiver. We used a requirement diagram to capture these specifications (as presented Figure 4.32.c). It is always possible to associate these requirements to the structure and behavior models in which the duplex filter is depicted either for the purpose of design verification and validation or for improving traceability. In this case, the models we have developed are only for illustrative purposes and small enough to be easily understood.

#### **4.3.4 Abstraction Levels, Viewpoints and Views**

In the previous section, we elaborated a general model for a RF system that is a black box described only by its functionality and its input/output parameters. We also established that this assumption remains applicable when considering a RF system as a combination of other RF “sub-”systems whose functionalities and inputs/outputs are fully identifiable. Then, we learned how to use a modeling language (i.e., SysML) to capture, particularly the black-box model associated to a RF system as well as the common design aspects (i.e., structure, behavior and requirements) of a complex system.

In this section, we address three main abstraction issues pertaining to common design aspects of a RF system:

1. Which abstraction levels can be considered for the description of RF systems? and how are they tied each to others?

2. How a RF/microwave system can be described from different design perspectives (i.e., viewpoints)?
3. Which modeling views can be derived to describe a RF system from each design perspective (i.e., viewpoint)?

#### **a) Abstraction Levels**

The UMTS transceiver of Figure 4.30 is a RF system that can be subdivided into three main subsystems: (i) transmitter, (ii) receiver and (iii) duplex filter. The transmitter and the receiver are also RF systems that can be subdivided into a number of building blocks (e.g., amplifier, quadrature up-converter, filter, etc.) while the duplex filter can be derived into a network of electrical elements. Each building block of the transmitter (respectively the receiver) is similar to the duplex filter in a sense that it can also be derived into a network of electrical elements. In general, each of these elements is conceptually represented by an electrical component (e.g., transistor, diode, lumped component, distributed line, etc.) that is intended to perform a basic (i.e., low-level) functionality. This conceptual representation was meant to abstract the physical structure required to accomplish that functionality. Three observations may be concluded from the analysis of this example:

1. It is possible to subdivide a given RF system into groupings that characterize not only an identifiable functionality but also a level of complexity,
2. The number of these groupings is limited because each one of them corresponds to a unique aspect of the RF system, and
3. If the level of complexity changes from different neutral standpoints while the functionality and the inputs/outputs remain the same, it is not possible to define a new grouping because only the granularity of the original grouping is changing.

Generalizing these observations to all RF systems may be successful if (i) a grouping is defined as an “*abstraction level*” and (ii) the aspects to be considered are design-dependent. From the RF designer’s point of view, a RF system can be considered as a physical implementation, a conceptual circuit, a modular topology, and an architecture of individual functionalities. For each design perspective, the number of elements composing the RF system may differ depending on how the designer subdivides it for the purpose of a solution. This characteristic,

related to the number of elements in a RF system at a given abstraction level, is called “*granularity*”. The change of granularity level alters the solution domain (i.e., how the solution is constructed) but does not impact the abstraction level. Considering these assumptions, we can define four distinct abstraction levels in RF systems (see Figure 4.33):

1. Atomic Layer: On the contrary to digital design where the lowest abstraction level (i.e., physical) is represented by a “*device*” (i.e., typically a silicon-based transistor), RF/microwave systems physical implementation cannot be represented by a single device due to the predominant mix of technologies<sup>85</sup>. For this reason, we consider the lowest abstraction level in RF system (that is conceptually representing the physical design perspective) as a “*layer*” of atomic components. The term “*layer*” denotes that many individual devices may represent the physical design perspective of RF systems. The term “*atomic*” indicates that each component of this layer cannot be subdivided further from RF design perspective. Otherwise, it can no longer be subdivided into elements that might be captured using a black-box model. For instance, we have identified four groups of atomic components that can be considered as parts of the atomic layer: transmission lines, lumped components, nonlinear devices and sources (see examples in Table 4.4 and Figure 4.34). Obviously, if a RF system is represented as a tree hierarchy, these atomic components lie down at the “*leaf*” level;
2. Circuit: Traditionally, atomic components are assembled to build a physical implementation. This assembly can also be regarded from the electrical viewpoint. If so, the physical details are ignored while the electrical properties are emphasized. This new design perspective defines a higher level of abstraction, namely “*circuit*”. A circuit is simply a network composed of electrical elements that are connected by a media through which electrical signals flow (e.g., current, wave). At the circuit level, it is obvious that the atomic components lose virtually their physical properties. They become represented by electrical functions (that may be described for example by mathematical formulas) as well as their respective input/output flows (e.g., current, voltage, etc.);

---

<sup>85</sup> The topic of technology predominance in RF systems and its impact on design was thoroughly detailed in section 1.4 of chapter 1 and section 2.3.3 of chapter 2.

3. **Module:** One or many circuits can be assembled in a given topology to construct a self-contained entity. The design perspective is no longer electrical but structural. The corresponding abstraction level is “*module*”. This entity can be defined as an individual, independent and interchangeable unit that can be used to build more complex structures. At this level of abstraction, the internal electrical properties of a module are hidden. It is defined by its functionality and inputs/outputs;
4. **System:** As interchangeable units, modules can be used to construct complex structures. From this design viewpoint, the internal structure of each module is not the primary concern of the designer who focuses more on how to organize the modules to achieve a specified functionality regardless of how the internals of each module were structured. Thus, the design perspective is more architectural/functional rather than structural. This new abstraction level, namely “*system*”, is all about arranging individual subsystems (i.e., modules) into an architecture that accomplishes a predefined functionality. A system is trivially an assembly of interconnected modules to form a complex and unitary whole achieving a given functionality.

The four abstraction levels are arranged as shown in Figure 4.33. The atomic layer (i.e., composed of atomic components) is the lowest abstraction level. The circuit level lies on the top of the atomic layer while the module level lies between the former and the system level. This makes the system is the highest abstraction level. When moving up from a lower to higher abstraction level, this is called “*abstraction*”. Inversely, moving down from a higher to a lower abstraction level is “*refinement*”.

Since a RF system can be regarded from different viewpoints, it is always possible to change the abstraction level. The action of lowering or raising the abstraction level implies:

1. An increase or a decrease in the level of detail (i.e., complexity),
2. A change in the design perspective (i.e., viewpoint), and
3. The nature of at least one among the functionality and the inputs/outputs changes.

In general, the number of atomic components is limited (i.e., countable) because it depends on the available technologies. However, it is virtually possible to build an infinite number of

circuits using these atomic components. Circuits can also be combined to form a number of modules that can be used to construct numerous systems. The number of possibilities for building a RF system constitutes what is generally referred to as “*design space*”. RF design consists at looking for the “best” solution that meets the requirements of a given RF system inside this design space. In practice, all the encountered combinations are not all solutions. That is why RF designers start with “*design space exploration*” looking for an initial design solution that can be refined and optimized all over the design cycle.

When looking at “*system*”, considered as the highest abstraction level in our proposal, one can argue that it is always possible to build a “super-system” which includes any system regardless of its complexity. This assumption is valid. Nevertheless, it is not in contradiction with considering “*system*” as the highest level of abstraction in RF systems. This is because the design perspective does not change. It remains focused on the development of an architecture to accomplish a given functionality. Considering a system as a super-system (i.e., system of systems) is just the definition of another level of granularity within the same level of abstraction, i.e., system.

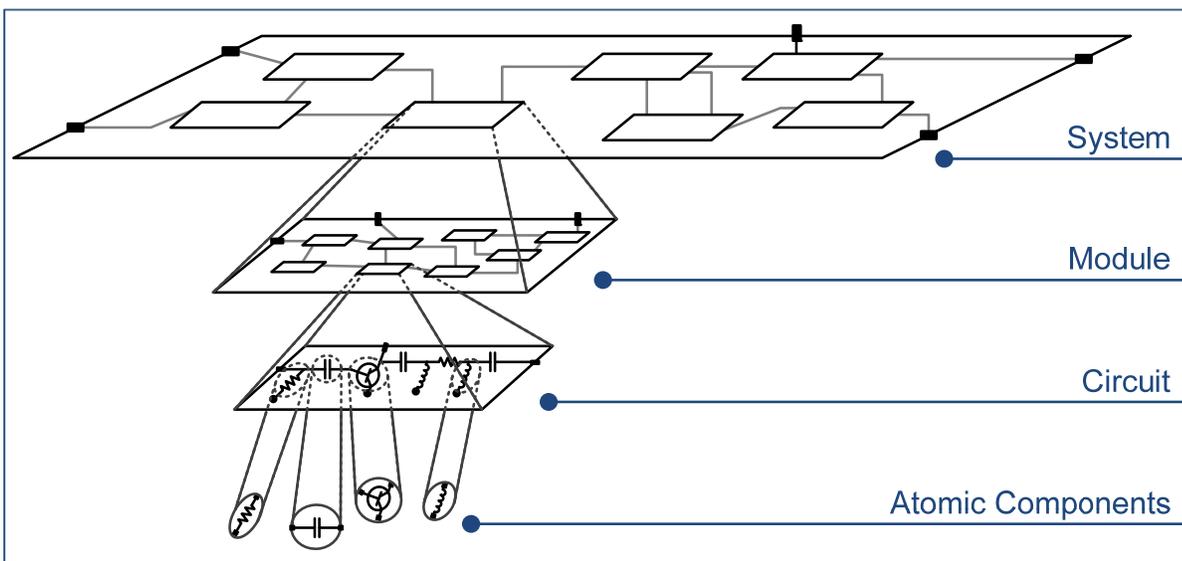


Figure 4.33 Four abstraction levels are considered in the proposed RF hardware abstraction strategy: System, module, circuit and atomic components

Table 4.4 Atomic components' layer is composed of atomic components (i.e., RF indivisible devices)

Category	Type	Functionality	Examples
Transmission lines	Lines	Signal transmission and routing	Distributed lines (e.g., microstrip, stripline, etc.), coaxial cables, waveguides, etc.
	Discontinuities		Tee, cross, step, slit, gap, bend, curve, open-end, etc.
Lumped components	Discrete	Provision of basic passive functions (e.g., impedance matching)	Inductors, capacitors, resistors
Nonlinear devices	Transistors	Signal amplification and switching, frequency oscillation, etc.	Transistors
	Junctions	Single-direction switch	PN junctions, diodes
Sources	Voltage	Fixed and/or alternate voltage maintainability	AC voltage source
	Current	Current delivery	Current source
	Power	Power supply	Power source
	Noise	Noise generation	Noise source

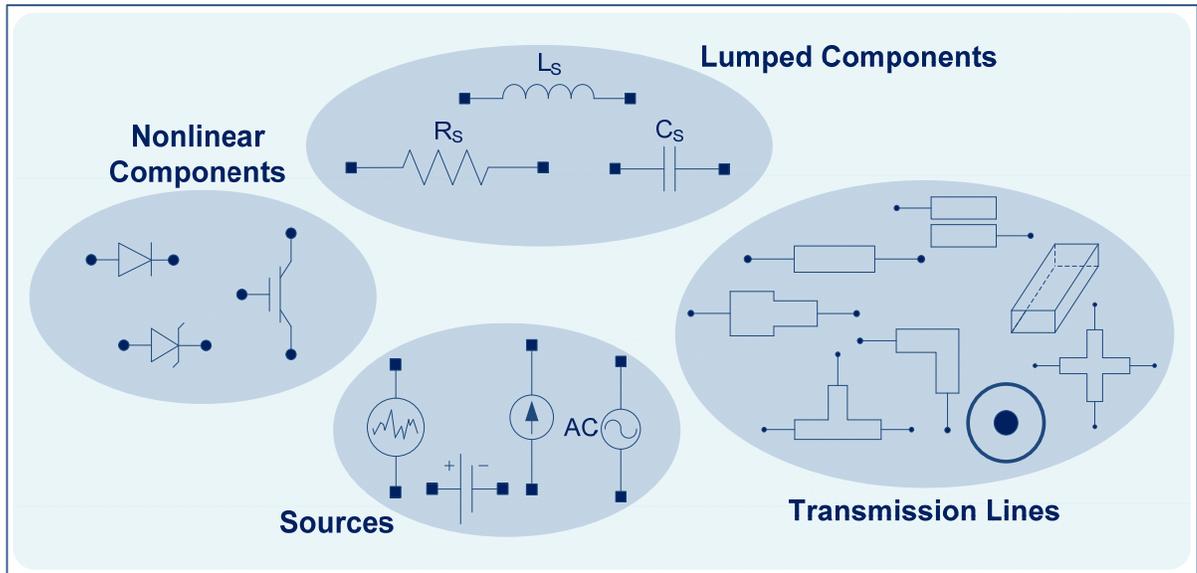


Figure 4.34 The atomic layer is composed of "leaf" electrical devices whose functions are not indivisible

In summary, the four abstraction levels (i.e., atomic layer, circuit, module and system) proposed in this section are meant to describe the level of complexity of a RF system from a given design perspective (i.e., viewpoint). For illustration, Figure 4.35 shows a typical architecture of a direct-conversion receiver RF front-end. At system level, the receiver is perceived as a unitary whole. It receives all radio spectrum signals and outputs a specific signal that corresponds to one or many radio channels. At module level, the level of complexity increases. It can be decomposed for example into seven individual building blocks (i.e., modules). Each one of these building blocks is in charge of a given functionality. For example, the antenna receives the RF signals and routes them to the filter which selects the desired radio channel(s). The resulting output signal is amplified using a low-noise amplifier (LNA). The amplified signal is then merged with the signal produced by the local oscillator using the mixer. The following filter selects the down-converted signal and removes its up-converted counterpart as well as the subsequent intermodulation products. Finally, an amplifier amplifies the resulting signal before it is delivered to the demodulator (i.e., in digital stage). At circuit level, each building block is described by an electrical circuit. For example, the LNA may be derived into a typical Class-C amplifier while the oscillator is implemented using a Colpitts<sup>86</sup> architecture. It is obvious that the complexity at this abstraction level is greater than the upper one. At the lowest abstraction level (i.e., atomic-component layer), the individual components which are abstracted in each circuit by their electrical parameters (including their schematic) are handled at the physical level. For instance, a PNP transistor is not represented at this level by its electrical schematic but rather its physical layout (i.e., composed of different metal and insulator layers).

### b) Abstraction Viewpoints

An effective way to design a complex system is to separately focus on a particular set of similar aspects within that system at each design step. This is the concept of separation of concerns.

---

<sup>86</sup> Colpitts oscillator was invented by Edwin H. Colpitts in 1918. It uses a combination of inductors and capacitors to form a feedback loop to the active device (i.e., typically a transistor). The oscillation frequency is determined by  $f_0 = \frac{1}{2\pi \sqrt{L \parallel (\frac{C_1 C_2}{C_1 + C_2})}}$ .

For example, the designer focuses only on tuning the electrical parameters of an amplifier circuit before figuring out which physical dimensions the transistors should have to get the same frequency response. Focusing on the electrical and the physical aspects separately gives better results than searching a design space considering both electrical and physical parameters at the same time. The concept of separation of concerns is an abstraction mechanism that defines clear, separate and complementary design perspectives. Each of them embodies from the designer's point of view (i.e., viewpoint), a specific set of issues to address within the system in order to figure out a potential solution. A design perspective corresponds to a designer viewpoint. A viewpoint is a neutral observation position of a RF system where only particular design concerns are highlighted. In simple words, an abstraction viewpoint is like a camera that films the system from a specific direction. As shown in Figure 4.36, several aspects can be emphasized in a typical RF system. For example, it can be described as black box where the functionality is defined by a set of user-defined requirements. It can also be observed as a circuit where only the electrical properties are underlined. In addition, it can be viewed as a physical structure where its intrinsic physical attributes are highlighted.

In this thesis, we consider five abstraction viewpoints from which RF systems can be observed and described:

1. **Physical:** from this viewpoint, the system is described exclusively by its physical attributes. For example, a simple device such as a transistor is described by its dimensions (e.g., length, width), the number of layers as well as the type of materials and substrates used for its implementation, etc. When a whole system is involved, other physical information may be added to this description (e.g., the system's layout, devices placement, devices wiring and signals routing, etc.);
2. **Electrical:** the system is regarded from this point of view as a circuit that is exclusively specified by its electrical characteristics. For instance, a device (e.g., resistor) is defined by the electrical voltage between its ends, the current flowing through it and its characteristic impedance. In addition to devices electrical characteristics, a system is specified by a circuit that allows the application of electrical laws (e.g., Kirchhoff law, superposition law, etc.). This implies the existence of a connectivity plan (e.g., netlist) that defines how devices are wired as well as reference nodes (e.g., ground, sources, loads, etc.);

3. Structural: from this viewpoint, the designer's interest is neither physical nor electrical. The focus is on how to arrange basic parts (e.g., circuits, devices, etc.) in order to build a system's topology. These parts may or may not be self-contained and interchangeable. For example, a phase-locked loop is structured from this point of view as control system where phase detectors, filters, dividers, voltage-controlled oscillators and other parts are arranged in the main and the loop paths. It is worth noting that the structural viewpoint is not purely mechanical, as the term may suggest, but denotes especially system assembly and integration aspects;
4. Architectural: from this viewpoint, the designer is interested in how a system is structured using self-contained and interchangeable parts. This viewpoint expresses generally a contractual architecture that is predefined by the high-level specifications. For example, a radio system (e.g., receiver) may be architected in compliance to a given reference architecture (e.g., homodyne, super-heterodyne, etc.). In some cases, this viewpoint is not considered because the system's complexity is reduced in a way that the structural viewpoint is enough to characterize its structure;
5. Functional: this viewpoint is mostly interested in the system's functionality and operation. It aims to define the purpose of a RF system and how it is expected to work. Thus, it defines for example its operation constraints as well as the specific role of each actor or building part within that system (if a given reference architecture is already contracted).

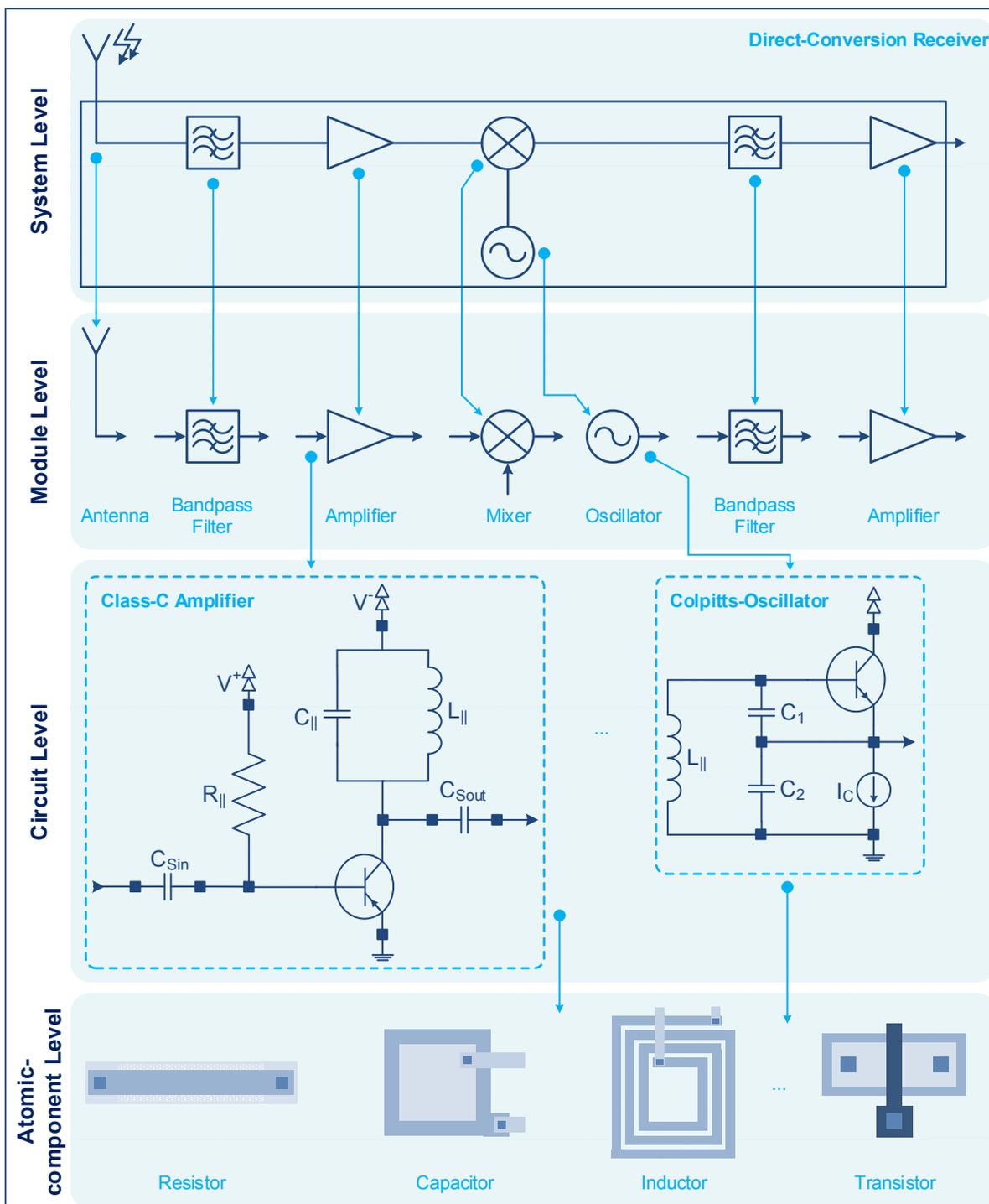


Figure 4.35 An example of how the different abstraction levels are considered in a typical RF system

This said, a design flow of RF systems is all about the transition between different design viewpoints. It starts with the functional description that is derived into system's architecture. The structure of each of its building blocks is then developed. Then, these structures are derived from an electrical viewpoint into circuits that are later translated into physical layouts.

### **c) Abstraction Views**

As seen in the previous sections, a RF system can be abstracted into four levels (i.e., atomic layer, circuit, module and system) and can be viewed from four different design perspectives (i.e., physical, electrical, structural and functional/architectural). A design perspective expresses a set of concerns that are interesting from the designer's viewpoint. These concerns may be related to system's functionality, implementation, structure, operation, etc. They are generally expressed as design requirements. It is worth noting that the terms "concerns" and "requirements" are not equivalent since the former is generic design areas of interest and the latter underlines specific exigencies within those design areas. The question is: how to translate these requirements into a system representation which is associated to an abstraction level from a given design viewpoint? Such representation is called an abstraction view. As shown in Figure 4.36, a view is simply a picture of the system that is constructed from a viewpoint.

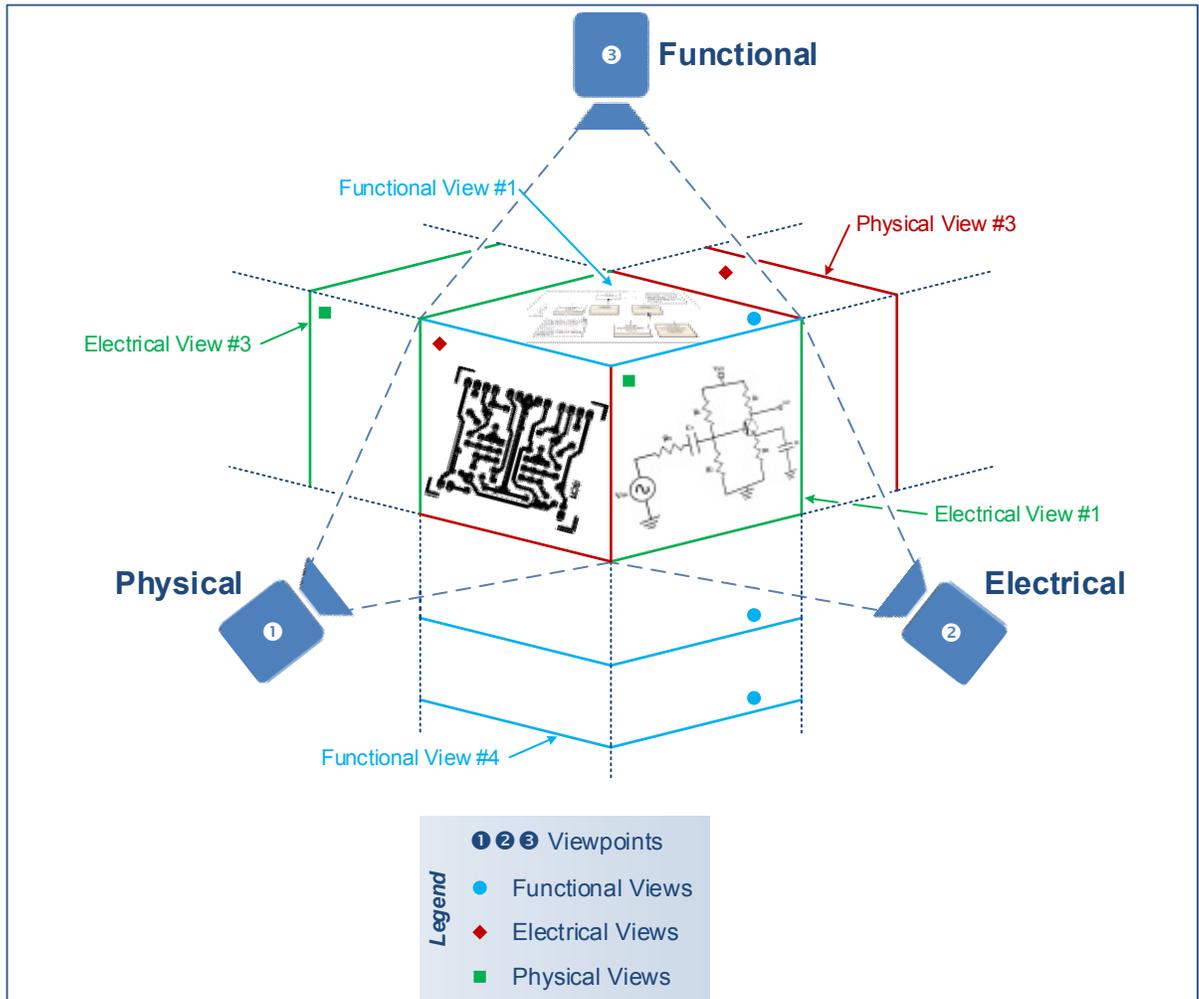


Figure 4.36 A viewpoint corresponds to an abstract design perspective while a view specifies a representation (i.e., model) which complies with that design perspective

A view is a specific representation of the system (i.e., usually partial) while a viewpoint is the perspective from which this representation is constructed. For instance, the transceiver of Figure 4.35 can be represented from architectural viewpoint as a hierarchy of blocks (using for example a SysML block definition diagram). The *bdd* is constructed from this viewpoint (i.e., architectural) to emphasize the relationships between the blocks as well as their own properties. It can also be represented from the same viewpoint as a hierarchy of parts where the signal flows are highlighted (using a SysML internal block diagram). In this case, the *ibd* emphasizes the signals travelling between the various parts. The *bdd* and *ibd* models are two views of the system from an architectural viewpoint. This stresses the fact that a system may have multiple views (i.e., pictures / photographs) from the same viewpoint.

In this thesis, we express views using four different types of models. These models are constructed from one among the previously-enumerated viewpoints and associated to one of the four defined abstraction levels. Therefore, we consider the following models for the expression of a RF system view (see Figure 4.37):

1. Platform Model (PM): it is a representation that is developed from physical viewpoint. The platform model expresses physical specificities of system implementation which may include (but not limited to) layout, ports, interconnections, substrates, fabrication materials, etc. For instance, physical properties of components (e.g., dimensions, shape, layers, etc.) are captured using a platform model;
2. Platform-Specific Model (PSM): it describes the system from an electrical viewpoint. A PSM expresses platform-specific artefacts using electrical abstractions. For example, lumped components may be represented using standard schematics (see Figure 4.34). Their behavior may be captured using mathematical equations or file-based data;
3. Platform-Independent Model (PIM): it captures the aspects pertaining to how the system should be built. These aspects include architectural and/or structural guidelines, design and operation constraints, etc. This model remains independent from the implementation technology because it is not intended to carry any physical or electrical information that is specific to a given platform;
4. Requirement Model (RM): it describes the system from functional viewpoint. It expresses the requirements that are related to different design concerns. This model is not only used to capture high-level system specifications. It may also serve to map the system requirements to the other models for traceability, validation and verification purposes.

The Figure 4.37 depicts a coarse mapping between the abstraction levels, viewpoints and views (i.e., models) defined for the representation of a RF system. Architectural / functional and structural viewpoints correspond to system and module abstraction levels respectively. The views associated to these two levels of abstraction are captured using platform-independent and/or requirement models. There is no clear distinction between these two models for a practical reason. In fact, most RMs are used in conjunction with PIMs that are practically associated to architectural and structural viewpoints. It is worth reminding that these two viewpoints may not be present simultaneously in all design cases. However, this does not affect

the abstraction hierarchy among these levels, viewpoints and models. The circuit abstraction level is mapped to the electrical viewpoint. The views within this viewpoint are captured using platform-specific models. The atomic layer (constructed of atomic components) is mapped to the physical viewpoint. The views described from the physical viewpoint are captured using platform models.

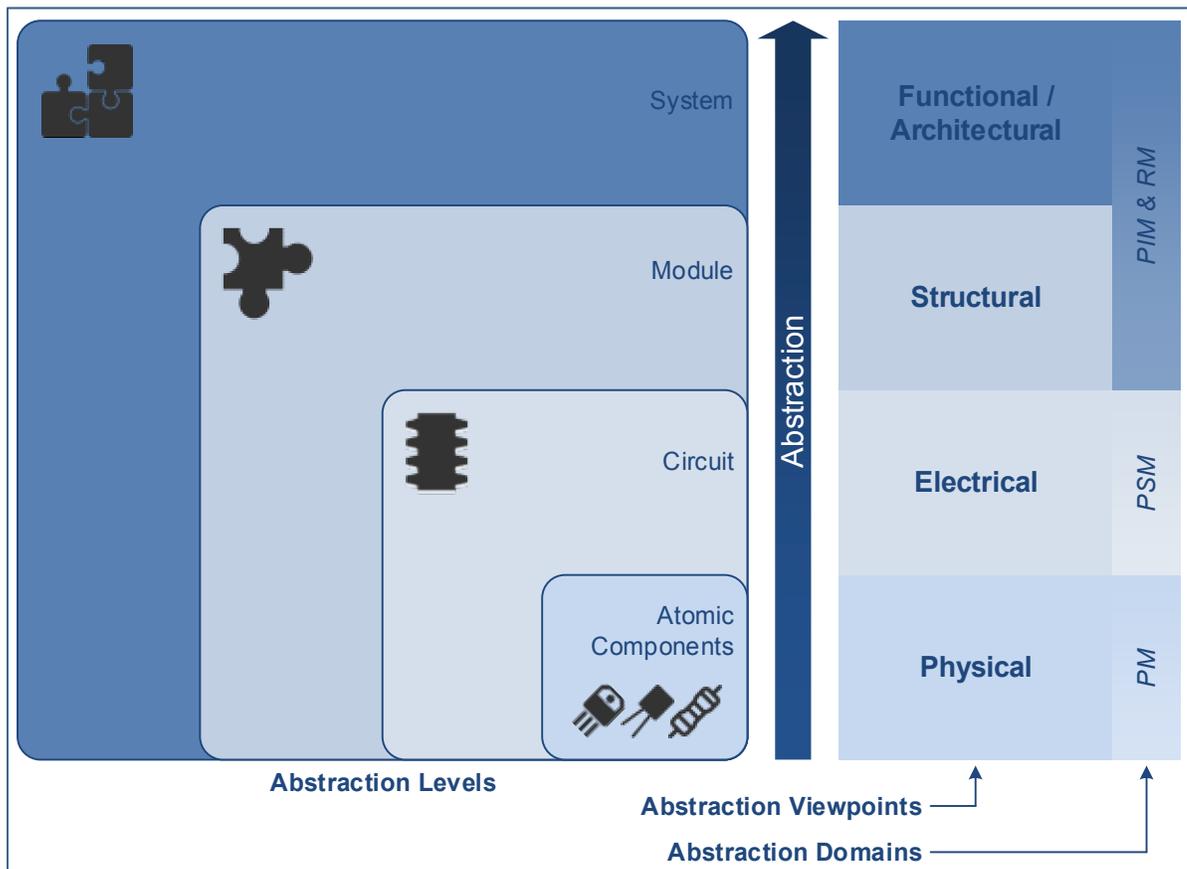


Figure 4.37 Four abstraction views are associated to four abstraction viewpoints and four abstraction levels

In summary, the abstraction hierarchy was defined to provide multiple representations of a RF system at different levels of complexity. The viewpoints allow the definition of relevant design perspectives. The definition of views and the models used to capture them provide a practical mechanism to construct system models from the defined viewpoints and at a given level of abstraction.

### 4.3.5 Transition between Abstraction Levels

In the previous sections, we defined four types of views to model a RF system from different design perspectives and at different levels of abstraction. The next step is the definition of adequate mechanisms for the manipulation and the transition between these different design perspectives and abstraction levels. Since endorsing design productivity is one of the objectives addressed by the proposed abstraction strategy, these mechanisms are not only meant to make RF/microwave design model-centric but also improve automation capability by allowing automated models translation. For this purpose, we reuse a concept adopted in MDE/MDA, namely transformations. The generation of a target from a source model in the case of RF/microwave design may be carried out using either an algorithm or a predefined tool. Algorithms may be defined based on mathematical equations or a set of design rules.

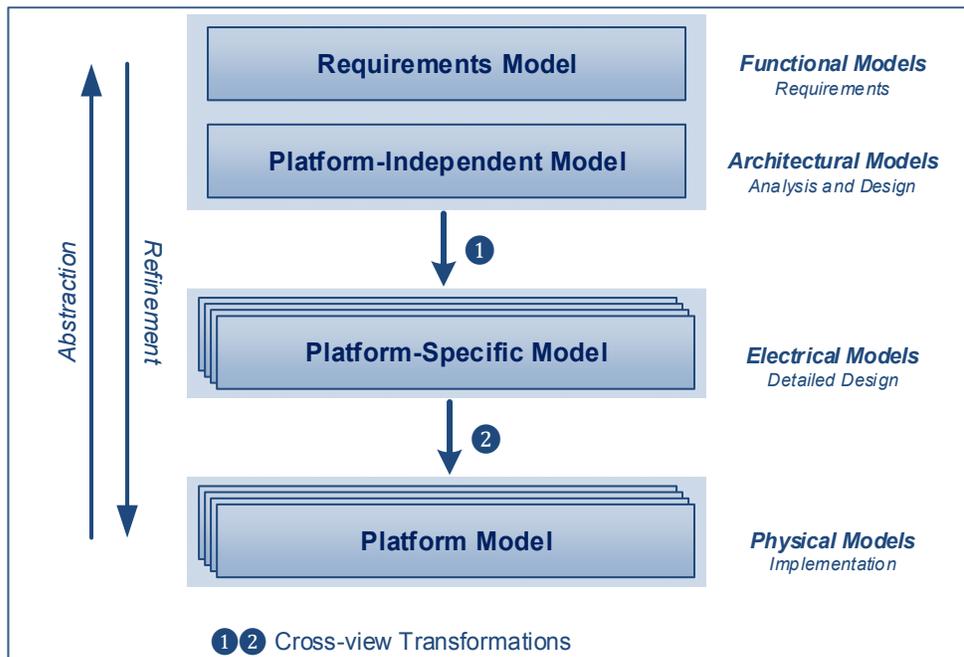


Figure 4.38 Two transformations are defined to move from system requirements throughout implementation

In this thesis, we consider the use of two types of transformations. The first derives a view model into another (e.g. transformations ① and ② in Figure 4.38, transformations ① and ③ in Figure 4.39). We call it *cross-view transformation*. The second derives a view model into

another of the same type (e.g., transformations ② and ④ in Figure 4.39). We name it *intra-view transformation*.

### a) Cross-view transformations

A cross-view transformation converts a view model (i.e., RM, PIM, PSM and PM) to another. It is similar to model-to-model transformations adopted in MDE/MDA. In the following, we will use only two cross-view transformations. The first translates RMs and/or PIM into one or many PSMs. The second translates a PSM into one or many platform models. For simplicity, we will not consider a transformation that translates a requirements model into a platform-independent model despite the fact that the former is defined at a higher level of abstraction than the latter. The main reason behind this is purely practical: as it will be discussed in the next sections, we use requirement models in RF/microwave design as part of the functional description process, which is completed by the definition of a PIM (i.e., often manually constructed). The main interest behind the RMs is particularly addressing the concerns of specifications capture and visualization, validation and verification as well as traceability within the RF/microwave design cycle. Consequently, there is a close relationship between RMs and PIM, which makes the construction of both models, interrelated. This said, it is always possible (theoretically speaking) to consider a transformation that converts a RM to a PIM.

To distinguish the cross-view transformations shown in Figure 4.38, we consider:

#### 1. The high-level cross-view transformation (no. ①)

It derives functional and/or architectural models into one or many electrical models. The former models are expressed using SysML diagrams and semantics. The latter are represented using electrical schematics and abstractions. This transformation generates platform-specific information from functional and architectural artefacts without specifying any physical information about the target platform. In Figure 4.39, the requirements model (i.e., *Req* SysML diagram) captures some requirements pertaining to an attenuator while the PIM defines that attenuator's structure and properties (using a SysML *bdd* diagram). The transformation (no. ①) converts these models into two electrical models (represented using two circuits). The first

implements a T-pad attenuator circuit while the second implements a  $\pi$ -pad. In both cases, the platform-specific information includes the circuits' topologies and the values of the resistive elements used within these circuits. A typical transformation to derive the T-pad (respectively  $\pi$ -pad) attenuator network may be based on the algorithm and mathematical formalism presented in Table 4.5. In addition to the possibility of deriving multiple PSMs for multiple platforms, this example shows that a transformation can also derive more than one PSM for the same platform;

## 2. The low-level cross-view transformation (no. 2)

It generates one or many physical models from the electrical ones. The physical models may be captured using a ready-to-manufacture layout. This transformation uses technology input pertaining to the target platform in order to derive the physical models. It acts into steps: (i) technology mapping that consists of associating each PSM element with the relevant technology information, and (ii) physical model generation which derives the corresponding implementation (e.g., layout). As depicted in Figure 3.12, technology input may include substrate and material characteristics, real lumped-component realizations, etc. In the example of Figure 4.39, the T-pad (respectively  $\pi$ -pad) attenuator physical model is represented by its subsequent layout. The layout shows the resistive discrete elements (i.e., thin-film resistors) which are linked using distributed transmission lines. The transformation of the electrical to physical models may be carried out using appropriate tools. For example, a commercial design package such ADS may be used to derive the PSMs of Figure 4.39 into layouts.

In addition, a cross-view transformation may be reversible. In this case, it is composed of two sub-transformations: one is direct which converts model A into model B, and the other is reverse which performs the opposite conversion. Reversible transformations are difficult to develop because they require a rigorous mapping between the artefacts of both source and target models. However, automated reversible transformations are powerful because they allow fast design re-spins.

**b) Intra-view transformations**

The second type of transformations converts a model to another model of the same kind. This means that both the source and target models share the same level of abstraction and are developed from the same abstraction viewpoint. Then, it is possible to convert a functional (respectively architectural, structural, electrical and physical) model to another one. For example, a T-pad attenuator PSM can be converted into a  $\pi$ -pad attenuator PSM (see transformation ② in Figure 4.39). A T-pad attenuator PM can be converted to a  $\pi$ -pad attenuator platform model (see transformation ④ in Figure 4.39).

Depending on the granularity level within the considered abstraction view, intra-view transformations may be classified into two main categories: (i) view-model bridges and (ii) granularity refinement transformations. The former transforms a source to a target model without changing the granularity level of the original one while the latter one does. Before presenting these two categories of transformations, we first review the concept of granularity refinement (already presented in section 3.3.3 of chapter 3) in the light of the proposed abstraction strategy.

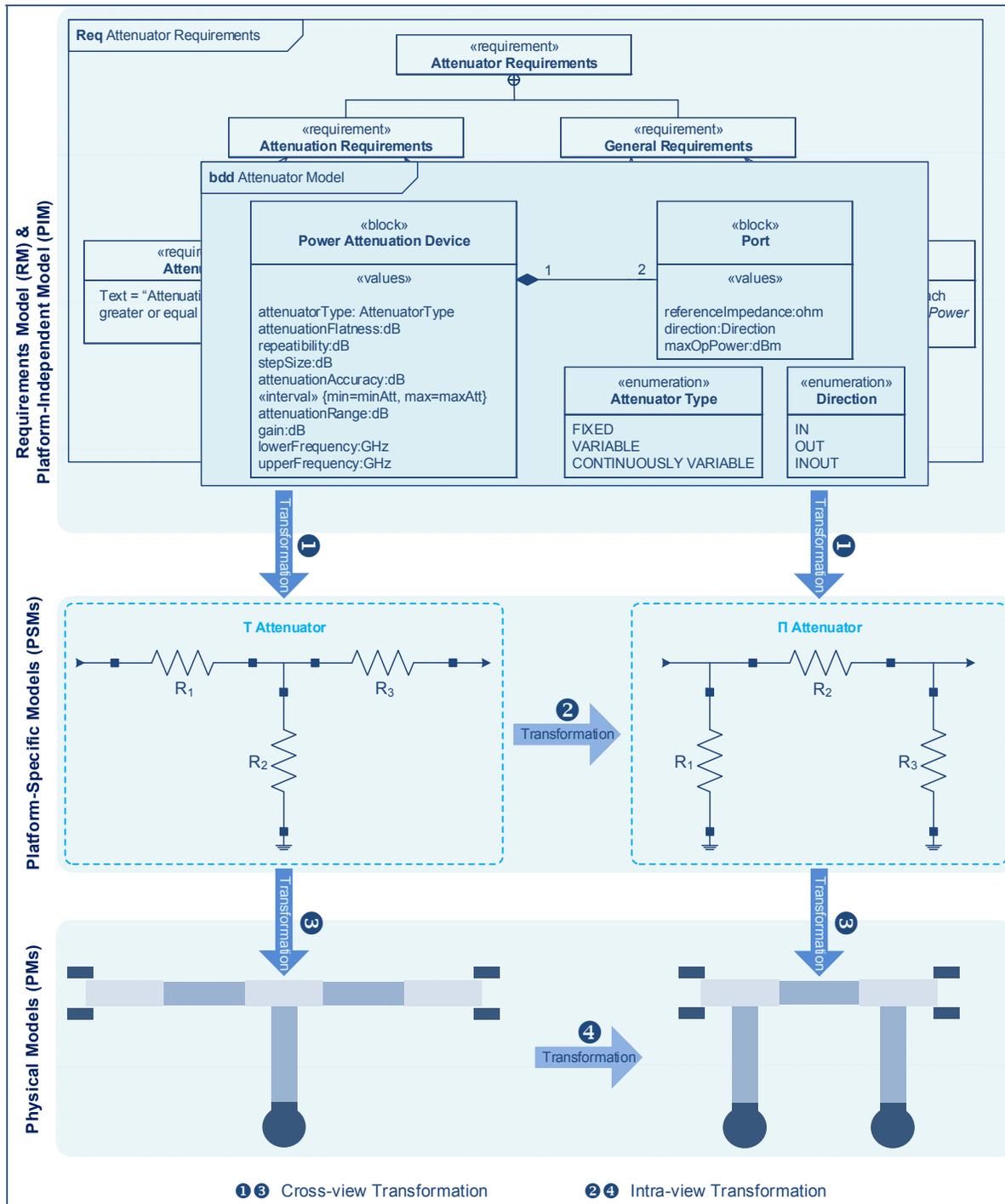
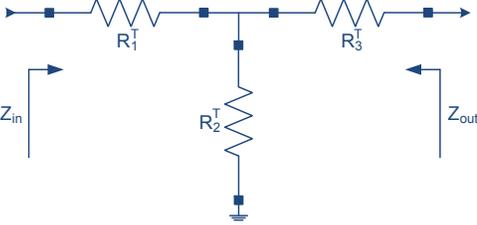
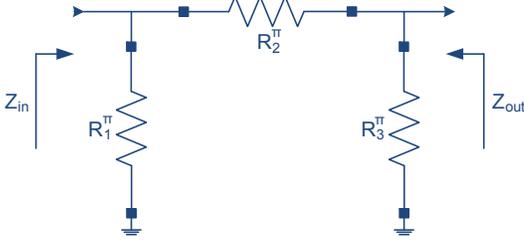


Figure 4.39 Cross- and intra-view transformations  
Layouts taken from Sun et al. (2008)

Table 4.5 Examples of equation-based transformations for T- and  $\pi$ -pad attenuators design  
Design equations taken from Vizmuller (1995)

Attenuator Platform-Specific Model	Simplified Mathematical Transformation
 <p style="text-align: center;">T-pad resistive attenuator</p>	<p><b>Algorithm</b></p> <ol style="list-style-type: none"> <li>1. <b>If Attenuation &gt; 0 Then</b></li> <li>2. Calculate <math>(R_1^T, R_2^T, R_3^T)</math> using equation (4.5)</li> <li>3. <b>Else</b></li> <li>4. Error</li> <li>5. <b>End Transformation</b></li> </ol> $\begin{cases} A = 10^{Attenuation/10} \\ R_2^T = \frac{2\sqrt{Z_{in} \cdot Z_{out} \cdot A}}{A - 1} \\ R_1^T = \left(\frac{A + 1}{A - 1}\right) Z_{in} - R_2 \\ R_3^T = \left(\frac{A + 1}{A - 1}\right) Z_{out} - R_2 \end{cases} \quad (4.5)$ <p>where:</p> <ul style="list-style-type: none"> <li>• <i>Attenuation</i> is the required attenuation in dB,</li> <li>• <math>Z_{in}</math> and <math>Z_{out}</math> are respectively the input and output impedances in ohms.</li> </ul>
	<p><b>Algorithm</b></p> <ol style="list-style-type: none"> <li>1. <b>If Attenuation &gt; 0 Then</b></li> <li>2. Calculate <math>(R_1^\pi, R_2^\pi, R_3^\pi)</math> using equation (4.6)</li> <li>3. <b>Else</b></li> <li>4. Error</li> <li>5. <b>End Transformation</b></li> </ol>

Attenuator Platform-Specific Model	Simplified Mathematical Transformation
<p style="text-align: center;"><math>\pi</math>-pad resistive attenuator</p>	$\left\{ \begin{array}{l} A = 10^{Attenuation/10} \\ R_2^\pi = \frac{1}{2}(A - 1) \sqrt{\frac{Z_{in} \cdot Z_{out}}{A}} \\ R_1^\pi = \frac{1}{\frac{A + 1}{Z_{in}(A - 1)} - \frac{1}{R_2}} \\ R_3^\pi = \frac{1}{\frac{A + 1}{Z_{out}(A - 1)} - \frac{1}{R_2}} \end{array} \right. \quad (4.6)$ <p>where:</p> <ul style="list-style-type: none"> <li>• <i>Attenuation</i> is the required attenuation in dB,</li> <li>• <math>Z_{in}</math> and <math>Z_{out}</math> are respectively the input and output impedances in ohms.</li> </ul>

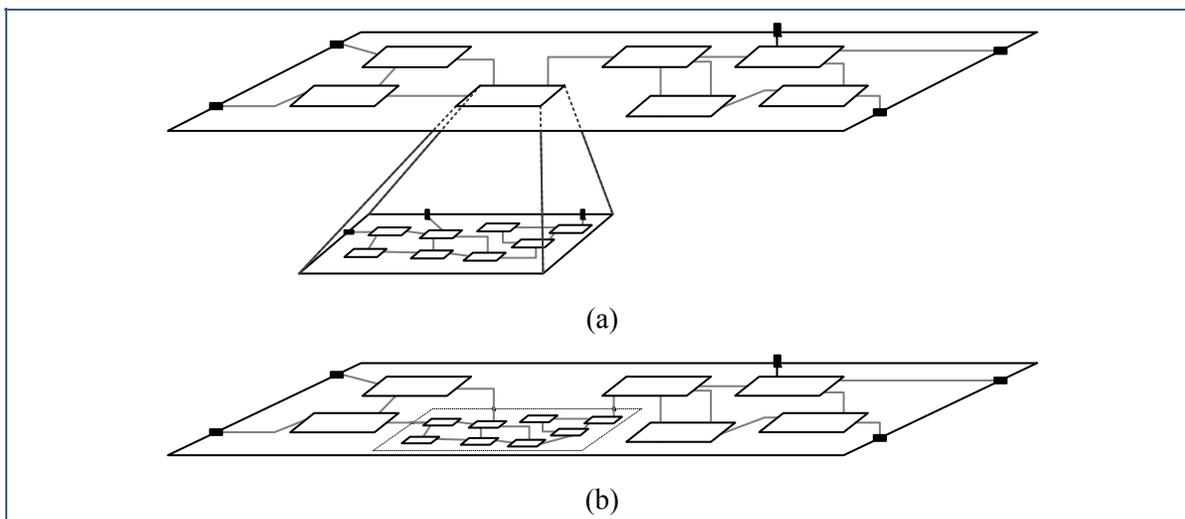


Figure 4.40 Granularity is all about the level of detail within an abstraction view: (a) the system is composed of seven blocks (b) one of these seven blocks can be broken up into eight other parts

Granularity is a characterization of how the RF system is partitioned. It may be related to the number of parts of which is composed and considered as self-contained blocks. For instance, the system shown in Figure 4.40.a is composed of seven parts. One of them can be partitioned

further to eight other parts. This new subdivision results in much granular system composed of fifteen parts (see Figure 4.40.b).

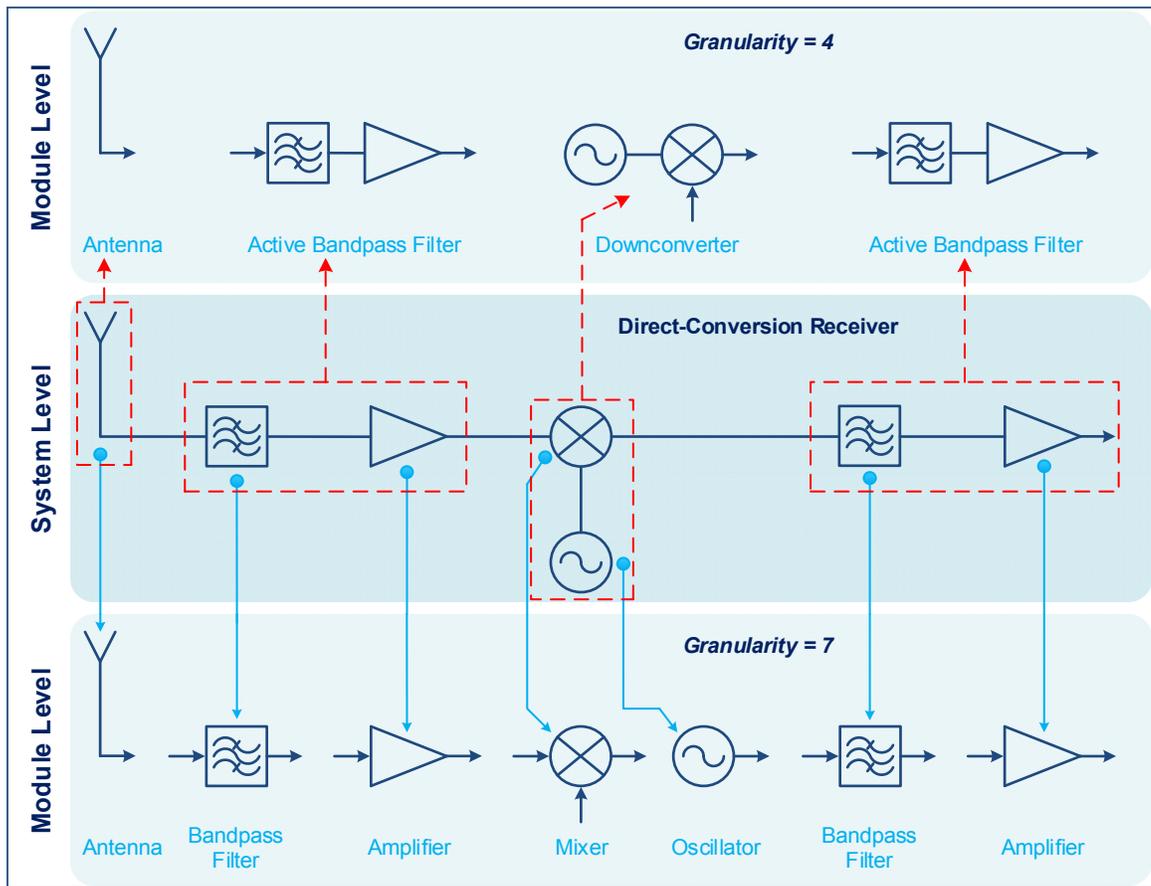


Figure 4.41 A system-level model of a direct-conversion receiver can be partitioned in modules in different ways of different granularity levels

In the case of RF systems, the granularity refinement concept may be applied as shown in Figure 4.41. This example presents a system-level model of a direct-conversion receiver which can be broken down into seven self-contained modules (i.e., antenna, two passive filters, oscillator, mixer and two amplifiers). The receiver may be partitioned differently. So, the amplifiers and filters are associated together to form active filters and the oscillator and the mixer are considered as building blocks of a down-converter. The resulting granularity level is four instead of seven. In both cases, the abstraction viewpoint is the same (i.e., structural) and the abstraction level (i.e., module) as well. However, we changed how the view is constructed. In the second case, we considered more complex modules (i.e., active filters, down-converter)

rather than considering all parts individually as in the first case. As far as abstraction is concerned, the less granular view is the less complex the system representation is (at a given abstraction level). However, there is no universal rule that judges what level of granularity results in the lowest complexity of design (i.e., means the whole design process). It depends mainly on the nature of the target system. For example, it is more suitable in the case of a radio system that uses a shared oscillator for both transmission and reception paths to consider a granular partitioning approach. This allows the reuse of the oscillator signals and reduces the complexity of the overall design. In addition, technology constraints may impose some partitioning choices. For instance, some technologies are not suitable for the implementation of active filters (due to integration problems) which imposes the separation of these filters into passive filters and amplifiers.

In summary, granularity is all about the definition of the detail level within an abstraction view (i.e., model). A high level of granularity corresponds to a fine-partitioned view while a low level of granularity is associated to a coarse-partitioned one. A view can be constructed with different levels of granularity. Moving from a low level to higher level of granularity within the same view is granularity refinement. To illustrate how different granularity levels can be captured using SysML, we reuse the amplifier examples already depicted in Figure 3.10.a and Figure 3.10.b. The *bdd* of Figure 4.42.a captures the amplifier properties when it is considered as whole unity (granularity level equal to 1). In Figure 4.42.b, the *bdd* represents an amplifier is derived into a biasing network, an amplification circuit and two matching networks. In addition, this example shows that SysML structural diagrams can easily capture different granularity levels pertaining to a given system. It is even possible to link the representations of different granularity levels for the same system in the purpose of visualization, communication or design reuse.

- **View model bridge**

A view model bridge is an intra-view transformation that converts a view model to another one of the same granularity level. The view model bridge acts on models constructed from the same abstraction viewpoint and at the same level of abstraction. In practice, it maps the elements within the source model to other elements within the target one. A view model bridge may or

may not be a reversible transformation. The major advantage of view model bridges is the automation of model transformation at the same level of abstraction. This allows to quickly deriving new models that can enhance the design space exploration. This is particularly useful at PSM and PM levels (i.e., electrical and physical viewpoints).

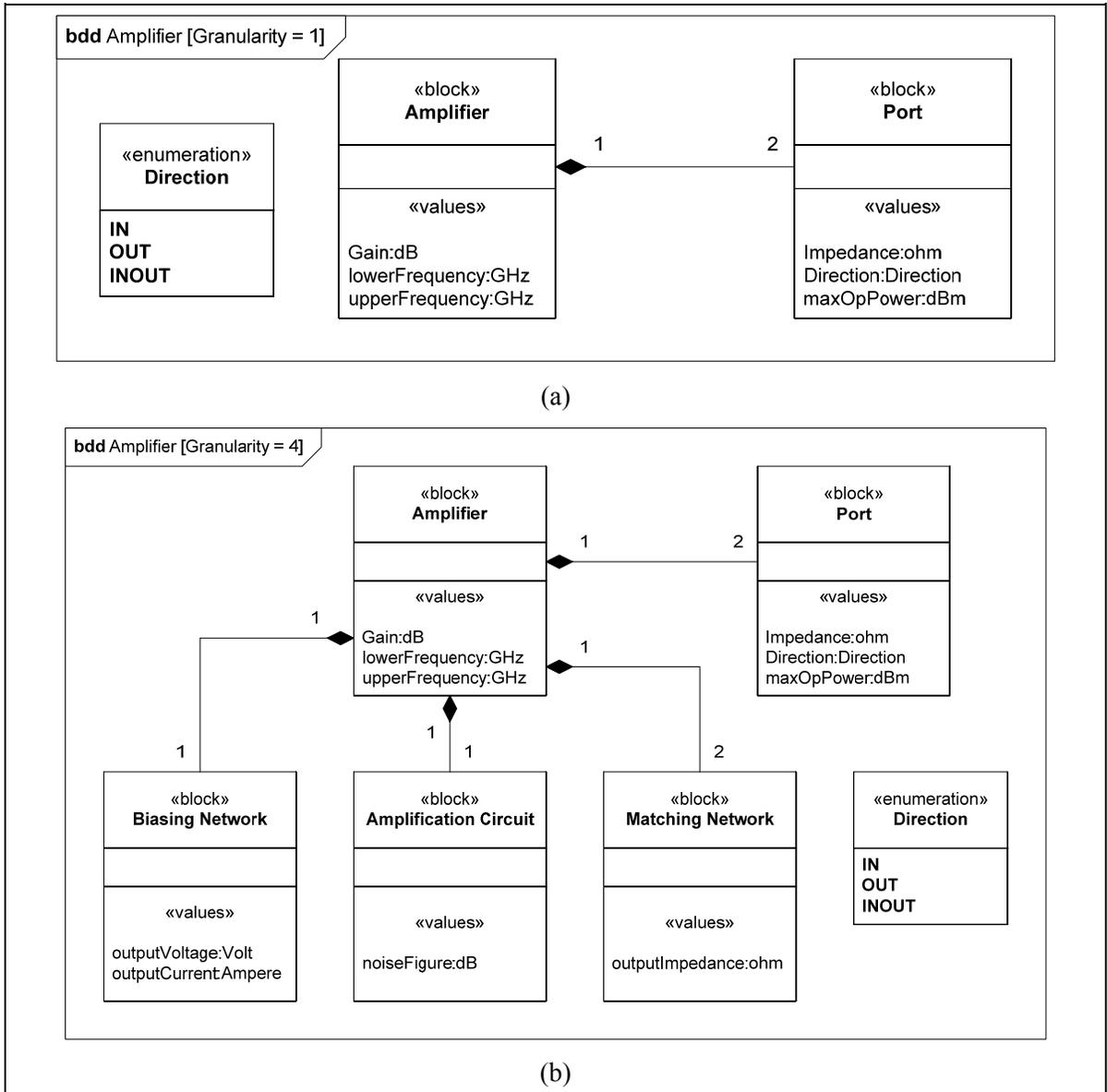


Figure 4.42 Two examples of granularity level expressed using SysML block definition diagram: (a) An amplifier is considered as whole [Granularity level = 1]  
 (b) An amplifier is considered as an assembly of amplification, matching, and biasing networks [Granularity level = 4]

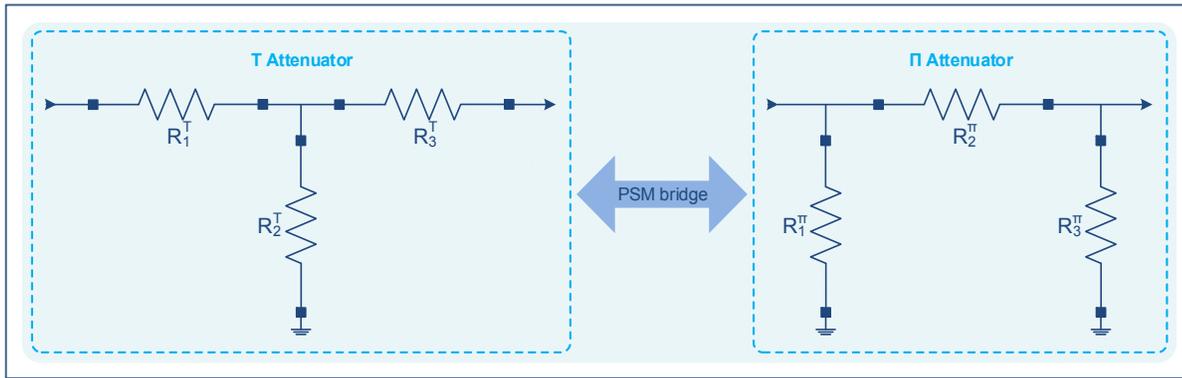


Figure 4.43 Reversible platform-specific model for resistive attenuators

In RF design, this concept is particularly useful when PIM, PSM and PM models are involved. For example, an attenuator PSM implemented using a T-pad network may be converted to an equivalent  $\pi$ -pad network using a PSM bridge (as illustrated in Figure 4.43). This PSM bridge makes an association between the resistive elements of T- and  $\pi$ -pad networks respectively. The elements of the latter may be derived from those of the former using the equation (4.7). Inversely, the elements of the T-pad network may be derived from those of  $\pi$ -pad network using the equation (4.8). The combination of these two equations results in a reversible PSM bridge that can be used to transform a T-pad to  $\pi$ -pad resistive attenuator network and vice-versa.

$$\begin{cases} R_1^\pi = \frac{R_1^T R_2^T + R_1^T R_3^T + R_2^T R_3^T}{R_1^T} \\ R_2^\pi = \frac{R_1^T R_2^T + R_1^T R_3^T + R_2^T R_3^T}{R_2^T} \\ R_3^\pi = \frac{R_1^T R_2^T + R_1^T R_3^T + R_2^T R_3^T}{R_3^T} \end{cases} \quad (4.7)$$

$$\begin{cases} R_1^T = \frac{R_1^\pi R_2^\pi + R_1^\pi R_3^\pi + R_2^\pi R_3^\pi}{R_1^\pi} \\ R_2^T = \frac{R_1^\pi R_2^\pi + R_1^\pi R_3^\pi + R_2^\pi R_3^\pi}{R_2^\pi} \\ R_3^T = \frac{R_1^\pi R_2^\pi + R_1^\pi R_3^\pi + R_2^\pi R_3^\pi}{R_3^\pi} \end{cases} \quad (4.8)$$

- **Granularity refinement transformation**

Granularity refinement transformation converts a source view model into another one of different granularity level. By opposition to model bridges, this type of transformations does not necessarily map each element in the source model to another one in the target model. However, an element within the source model (respectively the target model) might be mapped to one or many elements within the target model (respectively source model). To illustrate this concept, a traditional unbalanced T-pad attenuator network may be converted into a balanced one as shown in Figure 4.44.a. In this case, the source model has a granularity level equal to three while the target model has a granularity level equal to five. The input and output resistors in the unbalanced attenuator were respectively derived into two resistors elements in the balanced attenuator. Similarly, a balanced  $\pi$ -pad attenuator may be derived from an unbalanced configuration. The granularity level changes from three in the latter to four in the former (see Figure 4.44.b). Based on the equations (4.9) and (4.10), relevant granularity refinement transformations can be implemented to derive both balanced T- and  $\pi$ -pad attenuator circuits from unbalanced structures.

$$\left\{ \begin{array}{l} R_1^{BT} = R_4^{BT} = \frac{R_1^{UT}}{2} \\ R_2^{BT} = R_2^{UT} \\ R_3^{BT} = R_5^{BT} = \frac{R_3^{UT}}{2} \end{array} \right. \quad (4.9)$$

$$\left\{ \begin{array}{l} R_1^{B\pi} = R_1^{U\pi} \\ R_2^{B\pi} = R_4^{B\pi} = \frac{R_2^{U\pi}}{2} \\ R_3^{B\pi} = R_3^{U\pi} \end{array} \right. \quad (4.10)$$

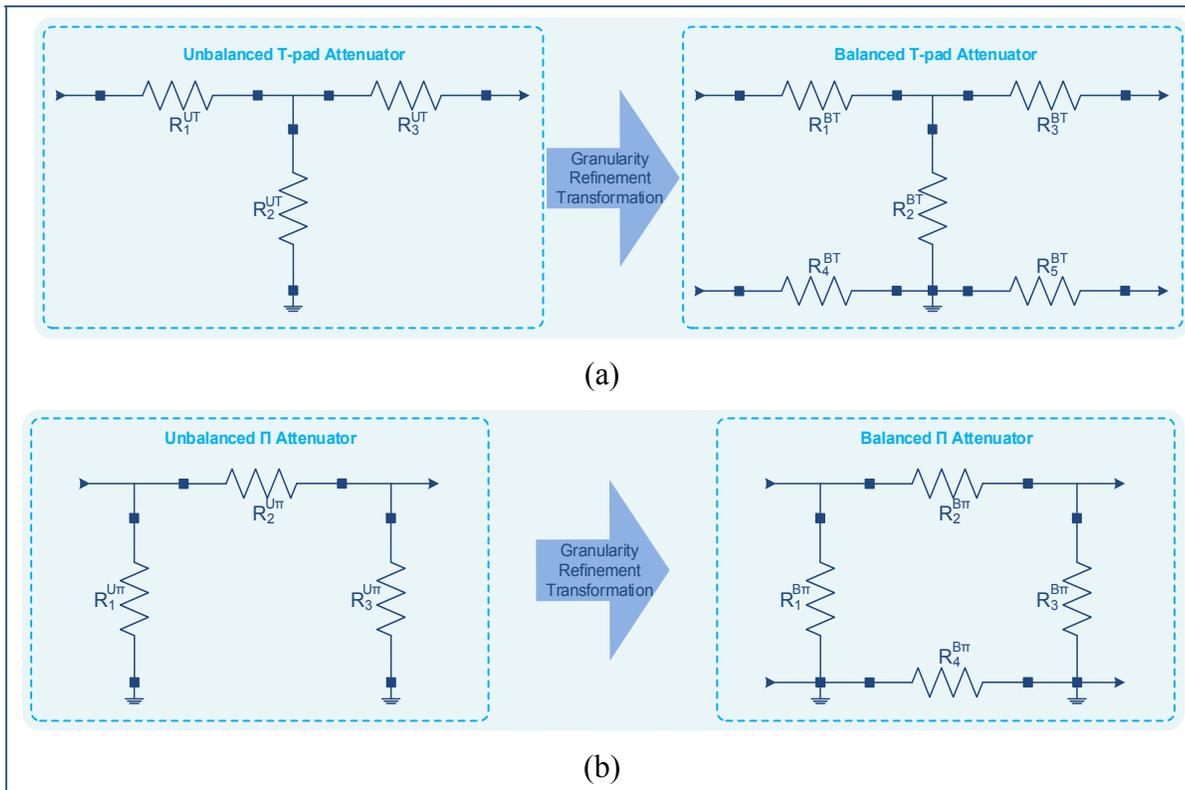


Figure 4.44 Granularity refinement: (a) Unbalanced to balanced T and (b)  $\pi$  attenuator transformations

### c) Decision Making

The use of model-to-model transformations (either intra- or cross-view) aims at enhancing the design automation level within the proposed framework. Thus, multiple transformations can be used in a concurrent manner to enhance design space exploration and design solutions' optimization. This way, several design solutions are attempted in parallel in the purpose of figuring out the best one among them. Thus, we need an automated decision making strategy, which examines and compares all the design solutions and decides which ones will be either retained or discarded. For this purpose, we propose in the following the use of objective functions in order to automate the decision making process.

- **Objective function**

An objective function is mathematical formula that expresses the constraints related to a given optimization problem. The solution to this problem is often related to the either maximization or minimization of that objective function. Mathematically speaking, an objective function  $F(n)$  is expressed as given in equation (4.11):

$$F(n) = \sum_{i=1}^n C_i X_i = C_1 X_1 + C_2 X_2 + \dots + C_n X_n \quad (4.11)$$

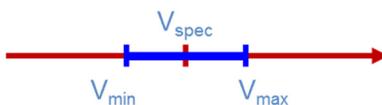
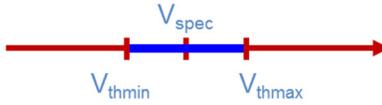
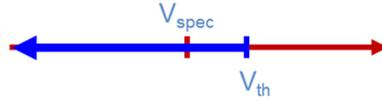
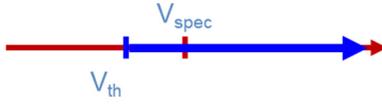
where  $C_i$  represents the objective function coefficient, or weights, corresponding to  $X_i$  which is the  $i^{\text{th}}$  decision variable.

- **Coefficients and decision variables calculation**

The next issue is the definition of how design constraints are expressed using an objective function. For this reason, we define two types of decision variables:

- Designer preferences: a designer indicates in the RM/PIM models which model value properties (i.e., design parameters) are important design metrics. This takes place by assigning a constant weight  $C_i$  to each value property according to its importance;
- Performance metrics: the weight of a design parameter varies from a design solution to another. Some weights are closer to the specification than others are. To differentiate these solutions, variable weights  $X_i$  depending on the design solution(s) performance are calculated. Table 4.6 shows an example of how to estimate the variable weight from the gap separating the specified and obtained values of each design parameter (i.e.,  $V_{spec}$  and  $V_{sim}$  respectively). This estimation varies also depending on the property constraint that specifies the acceptable range of values in which the value property is considered. For instance, if the value property belongs to a list of enumerations or considered as an absolute specification, the variable weight is binary. For interval, maximization (also minimization) and relative specifications, upper and/or lower limits (called maximum/minimum acceptable values  $V_{th}$ ) are considered. Depending on the position of the obtained value  $V_{sim}$  (in Table 4.6, blue line delimits the acceptable range of values), the formula to calculate the distance (i.e., variable weight  $X_i$ ) between  $V_{spec}$  and  $V_{sim}$  changes accordingly. The idea behind this is to favor performance values close to the specified value while penalizing those situated farther.

Table 4.6 Variable weights  $X_i$  are estimated based on property constraints

Property Constraint	Decision variable $X_i$	Observation
Enumeration list	$\begin{cases} X_i = 1 \text{ if } V_{sim} = V_{spec} \\ X_i = 0 \text{ otherwise} \end{cases}$	
Interval $[V_{min}, V_{max}]$	$\begin{cases} X_i = 1 \text{ if } V_{sim} \in [V_{min}, V_{max}] \\ X_i = \frac{- V_{min} - V_{sim} }{V_{spec}} \text{ if } V_{sim} < V_{min} \\ X_i = \frac{- V_{max} - V_{sim} }{V_{spec}} \text{ if } V_{sim} > V_{max} \end{cases}$	 <p><math>V_{min}</math>: lower border of the interval <math>V_{max}</math>: upper border of the interval</p>
Absolute specification	$\begin{cases} X_i = 1 \text{ if } V_{sim} = V_{spec} \\ X_i = 0 \text{ otherwise} \end{cases}$	
Relative specification	$\begin{cases} X_i = \frac{V_{sim}}{V_{spec}} \text{ if } V_{sim} \in [V_{thmin}, V_{thmax}] \\ X_i = \frac{- V_{thmin} - V_{sim} }{V_{spec}} \text{ if } V_{sim} < V_{thmin} \\ X_i = \frac{- V_{thmax} - V_{sim} }{V_{spec}} \text{ if } V_{sim} > V_{thmax} \end{cases}$	 <p><math>V_{thmin}</math>: minimum accepted value for <math>V_{spec}</math> <math>V_{thmax}</math>: maximum accepted value for <math>V_{spec}</math></p>
Variable minimization	$\begin{cases} X_i = \frac{V_{spec}}{V_{sim}} \text{ if } V_{sim} \leq V_{th} \\ X_i = \frac{- V_{th} - V_{sim} }{V_{spec}} \text{ if } V_{th} < V_{sim} \end{cases}$	 <p><math>V_{th}</math>: maximum accepted value for <math>V_{spec}</math></p>
Variable maximization	$\begin{cases} X_i = \frac{V_{sim}}{V_{spec}} \text{ if } V_{th} \leq V_{sim} \\ X_i = \frac{- V_{th} - V_{sim} }{V_{spec}} \text{ if } V_{sim} < V_{th} \end{cases}$	 <p><math>V_{th}</math>: minimum accepted value for <math>V_{spec}</math></p>

where  $V_{spec}$  and  $V_{sim}$  are respectively the specified and obtained solution performance values.

The Table 4.6 lists some common but not unique property constraints. In addition, it is always possible to associate to any among these properties another mathematical equation for the calculation of a variable weight. For illustration, the equations for variable minimization used

for the calculation of the variable weight related to the filter’s order property value are overridden by the equation shown in Figure 4.45. Then, the variable weight is calculated using the new equation instead of the default ones. In this example, the weight assigned for each value of “order” decreases faster than the default equations. So, the new equation favors the low values leading to small form factors while penalizing higher ones.

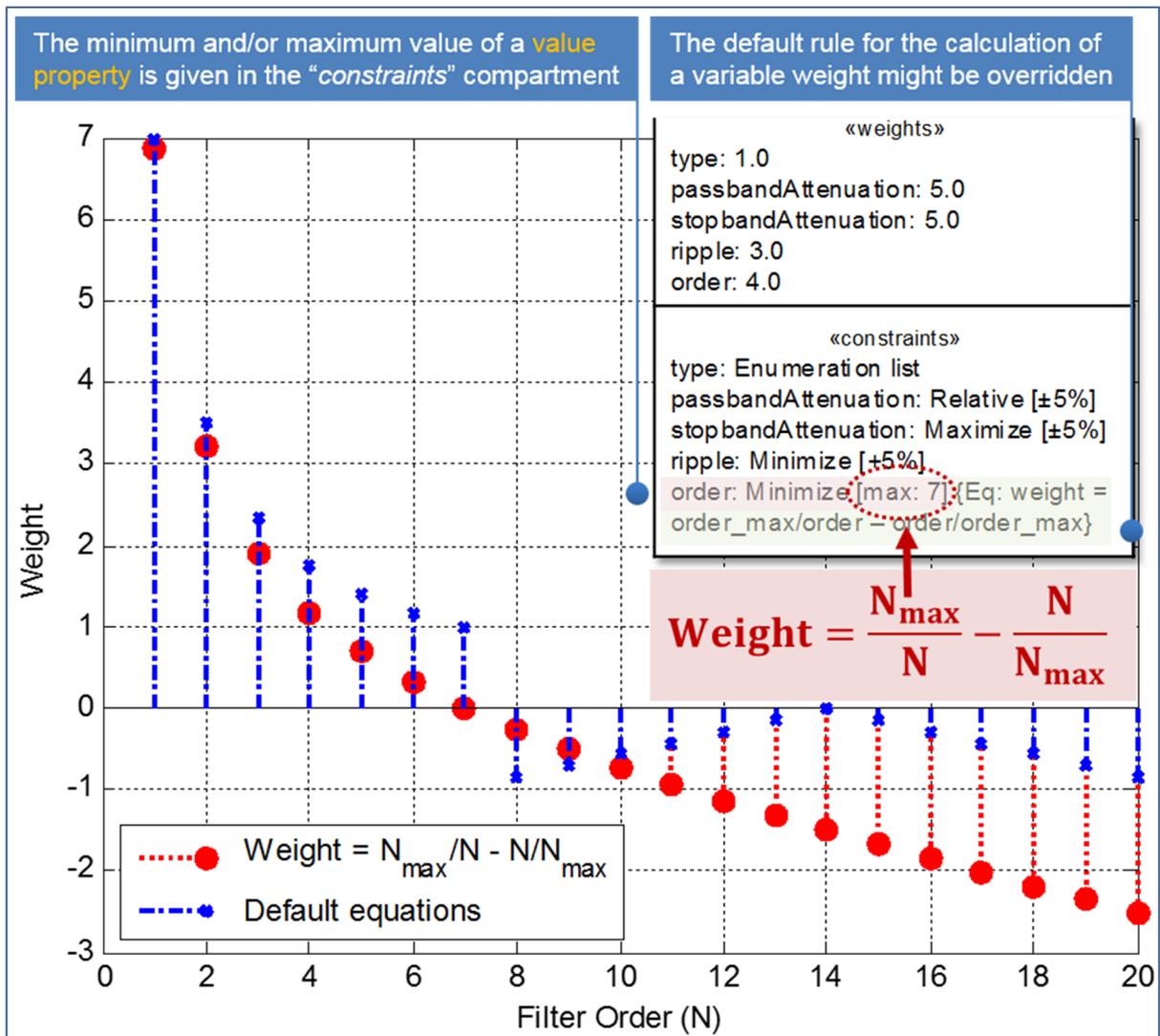


Figure 4.45 An example of overriding a default constraint property using a new equation for the calculation of variable weights

Both constant weights and property constraints expressing respectively the designer’s preferences and the performance metrics are included in the RM/PIM. This scheme enhances automation throughout the design process by allowing to automatically evaluating a candidate

design solution against specifications. However, it is possible to use default schemes (e.g., template-based) if these rules are not explicitly included within the RM/PIM. Moreover, it is always possible for the designer to intervene at any design stage and select the best solution manually.

- **Application example**

To illustrate the concept of using objective functions for the automated selection of the best model-to-model transformation output (i.e., design solution), we consider in the following the PIM shown in Figure 3.4 and capturing the specifications of a GPS L1 bandpass filter. The constant weights and the property constraints are included in this PIM (respectively in « weights » and « constraints » compartments of each SysML block). Based on the filter's specifications captured by this PIM, we find out two candidate design solutions. The first is a filter model estimated using a Butterworth approximation while the second is calculated using another one (i.e., Chebyshev Type I). Considering the constant weights and property constraints defined in the PIM of Figure 3.4, the performance of each candidate solution is presented in Table 4.7.

Table 4.7 Performance details of two candidate design solutions for the GPS bandpass filter of Figure 3.4

	<b>Value Property / Decision variable (X)</b>	<i>i</i>	<b>Butterworth</b>	<b>Chebyshev Type I</b>	<b>Property Constraint</b>
<b>Filter order</b>	N	1	2	2	Variable minimization (i.e., due to small form factor requirement)
<b>Attenuation (dB)</b>	A <sub>s</sub> @ 1520.42 MHz	2	41.944	44.534	Variable maximization
	A <sub>p</sub> @ 1570.42 MHz	3	3.004	3.025	Relative specification
	A <sub>p</sub> @ 1580.42 MHz	4	3.004	3.025	Relative specification
	A <sub>s</sub> @ 1630.42 MHz	5	41.342	43.931	Variable maximization
<b>Ripple (dB)</b>	<i>r</i>	6	N/A (0)	0.504	Variable minimization

	<b>Value Property / Decision variable (X)</b>	<i>i</i>	<b>Butterworth</b>	<b>Chebyshev Type I</b>	<b>Property Constraint</b>
<b>Passband Bandwidth (MHz)</b>	<i>BW</i>	7	10	10	Absolute specification
<b>Central Frequency (MHz)</b>	<i>F<sub>0</sub></i>	8	1575.42	1575.42	Absolute specification
<b>Reference Impedance (Ω)</b>	<i>Z<sub>ref</sub></i>	9	50	50	Absolute specification
<b>Filter Type</b>	Type	10	Butterworth	Chebyshev Type I	Enumeration list

Based on the filter's PIM (see Figure 3.4) and rules defined in Table 4.6 for the calculation of variable weights, ten decision variables are identified and estimated as shown in Table 4.8.

Table 4.8 Calculation of the objective function for each candidate design solution

<b>Decision variables</b>	<b>Constant weights <i>C<sub>i</sub></i></b>	<b>Variable weights <i>X<sub>i</sub></i></b>		<b>Weights <i>C<sub>i</sub> · X<sub>i</sub></i></b>	
		<b>Butterworth</b>	<b>Chebyshev Type I</b>	<b>Butterworth</b>	<b>Chebyshev Type I</b>
<i>X<sub>1</sub></i> ♦	4.0	$\frac{1}{2}$	$\frac{1}{2}$	2	2
<i>X<sub>2</sub></i>	5.0	$\frac{41.944}{30} = 1.39813$	$\frac{44.534}{30} = 1.48446$	6.99065	7.4223
<i>X<sub>3</sub></i>	5.0	$\frac{3.004}{3} = 1.00133$	$\frac{3.025}{3} = 1.00833$	5.00665	5.04165
<i>X<sub>4</sub></i>	5.0	$\frac{3.004}{3} = 1.00133$	$\frac{3.025}{3} = 1.00833$	5.00665	5.04165
<i>X<sub>5</sub></i>	5.0	$\frac{41.342}{30} = 1.37806$	$\frac{43.931}{30} = 1.46436$	6.8903	7.3218

Decision variables	Constant weights $C_i$	Variable weights $X_i$		Weights $C_i \cdot X_i$	
		Butterworth	Chebyshev Type I	Butterworth	Chebyshev Type I
$X_6^*$	3.0	0	$\frac{-0.5}{0.504} = -0.99206$	0	-2.9762
$X_7$	5.0	1	1	5	5
$X_8$	5.0	1	1	5	5
$X_9$	2.0	1	1	2	2
$X_{10}$	1.0	1	0	1	0
$F(n) = \sum_{i=1}^{10} C_i X_i$				<b>38.89425</b>	<b>35.8512</b>

$$^\diamond V_{th} = 7$$

$$^* V_{th} = 0$$

In this example, the optimization problem expressing the ten decision variables of Table 4.8 is a maximization one. Since the value of the objective function corresponding to the Butterworth model (i.e.,  $F(n)|_{Butterworth} = 38.89425$ ) is greater than the one corresponding to the Chebyshev Type I approximation (i.e.,  $F(n)|_{Chebyshev} = 35.8512$ ), the Butterworth design solution is retained while the Chebyshev is discarded. Furthermore, this example corresponds to an inband ripple-sensitive application. Despite that the Chebyshev model performs better in terms of pass- and stopband attenuation, the constant weight attributed to the ripple (i.e.,  $C_6 = 3.0$ ) has highly disadvantaged that design solution because of its ripple (i.e.,  $r = 0.504$  dB).

In general, the number of design candidates is greater or equal to one. For a single candidate design solution, the designer can impose a threshold value for the objective function (i.e.,  $F(n)_{th}$ ) which expresses the minimum (or maximum) acceptable performance. If a single candidate solution is examined, its objective function is compared to this threshold value to decide if it will be either retained or excluded. This principle can also be applied to multiple candidate solutions. In this case, more than one candidate solution may be automatically retained. The designer may manually select the most appropriate among them or choose to submit all of them to the next design stage for more performance assessment.

### 4.4 Application to RF and Microwave Design

In the previous section, we presented in some detail the theoretical basis of a new abstraction strategy for RF design. We considered black-box model as the basic entity to be used for the description of RF systems. Then, we specified five abstraction levels along with the corresponding abstraction viewpoints (i.e., design perspectives) suitable for the description of these systems at different levels of granularity. We also specified how the abstraction levels and viewpoints may be associated to construct usable system views. These views are captured using four types of models which capture requirements, specify platform-independent and platform-specific artefacts and also represent the physical implementation of the system. Then, we defined two types of transformations that may be used to move back and forth from one model to another (with or without respect to abstraction levels). We demonstrated that SysML can be optimally used to capture all the aspects of the proposed abstraction strategy (e.g., abstraction levels, viewpoints, black-box model, views, granularity level, etc.).

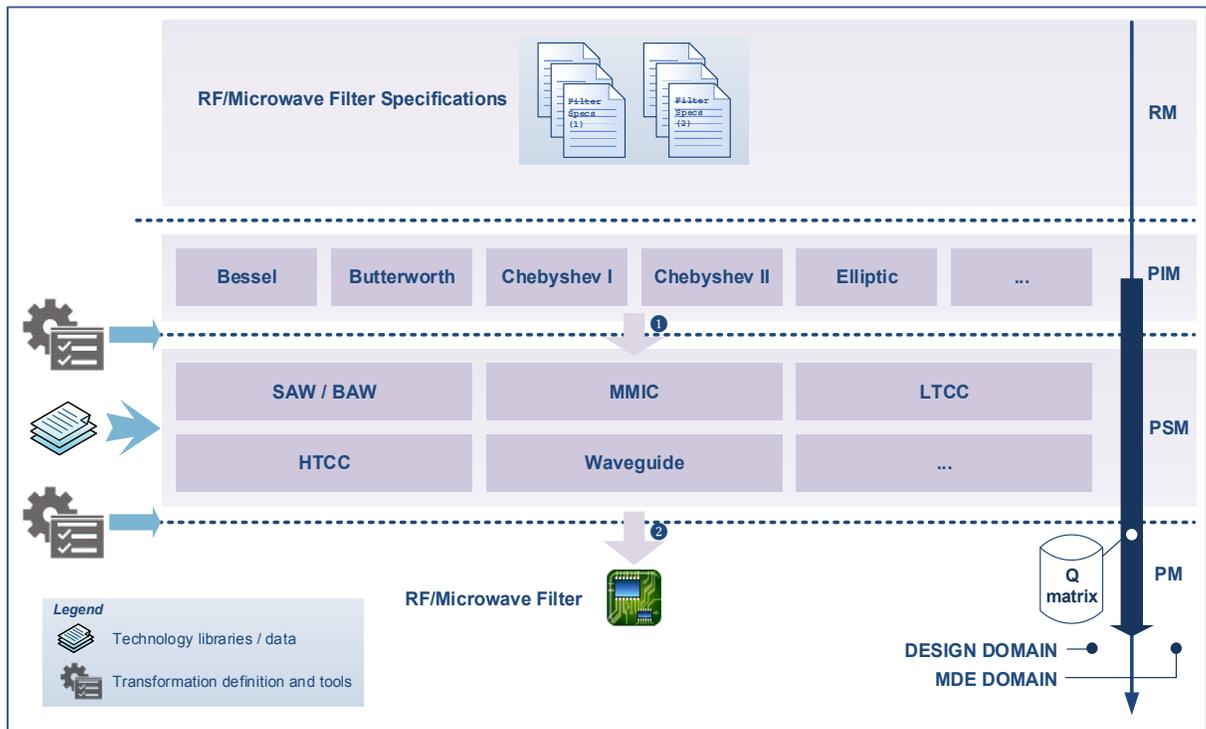


Figure 4.46 The four abstraction views can be mapped to traditional passive RF filters design steps

In this section, we briefly investigate how the key concepts of the proposed abstraction strategy may be applied to real RF systems. Two examples will be examined: passive filters and operational amplifiers. It is worth noting that detailed case studies will be presented in chapter 5 for the purpose of validating the proposed approach.

#### **a) RF passive filters**

The traditional design approach for RF passive filters starts with specifications. Several models of filters (e.g., Chebyshev, maximally flat, elliptic and Bessel) are thoroughly detailed in literature. In general, these models are endorsed by appropriate mathematical formalisms that allow the design of ideal filter prototypes which meet the initial specifications. Then, the ideal filter elements are converted into real implementations in different technologies (i.e., waveguides, lumped components, LTCC, distributed lines, etc.).

As shown in Figure 4.46, the filter specifications may be captured using requirements models (RMs). Since the ideal filter prototypes are equation-based and deliver ideal LC networks, they can be considered as platform-independent models. If the specifications cannot be met by the traditional filter models, a custom filter network (even approximate) may be constructed and considered as a PIM. Given technology information, the resulting platform-independent model may be converted into a platform-specific model using an appropriate transformation. Ideal LC elements are replaced by real lumped-component electrical models or derived into equivalent distributed lines. Finally, the final filter implementation (e.g., layout) is derived from the PSM using a relevant tool or transformation. This results in a platform model that can be manufactured and tested. Figure 4.46 maps the traditional design scheme with the different abstraction views. It depicts also the regions where transformation rules and tools are required as well as the technology input.

#### **b) Operational Amplifiers**

If we consider the design of a typical CMOS device such as an operational amplifier (OpAmp), the main models to be developed using the proposed abstraction strategy are as follows:

- OpAmp Requirement and Platform-independent models: expressed in SysML, The resulting models capture not only the functional parameters of an OpAmp but also can

- include its specific requirements, constraints, behavior and internal structure. The top part of Figure 4.47 shows various SysML diagrams describing the OpAmp specifications. For example, the top diagram is the block definition diagram (*bdd*) and captures some key parameters of the OpAmp such as the open loop gain and slew rate;
- OpAmp Platform-specific model: as mentioned above, the OpAmp PSM includes technology considerations. For this case study, we chose CMOS as a reference technology. This PSM, represented by a circuit schematic in which transistors are MOS devices generated using the proper transformation from the OpAmp PIM is a proper technology-dependent model (see middle part of Figure 4.47). One of the advantages of this representation is the immediate use of available CAD tools, e.g., Cadence with a proper technology file, to simulate and validate the PSM's performance;
  - OpAmp Implementation (i.e., platform model): an implementation of the OpAmp is a ready-to-manufacture design. It is generally captured using a conventional layout that captures all the relevant information needed for the fabrication of the OpAmp (see bottom part of Figure 4.47). It can be subject of various performance assessments and optimizations before it is submitted to fabrication process for final device manufacturing.

As shown in Figure 4.47, two transformations may be defined to move from PIM to PSM and PSM to implementation respectively:

- PIM to PSM Transformation: as previously discussed, a transformation may be a set of design rules, an algorithm or a tool that is able to interpret the PIM and then generate a PSM that relates to a given fabrication technology. One of the reasons to choose the OpAmp as an application example in this section is the abundance of OpAmp design tutorials and procedures in the literature. For example, an OpAmp can be designed on the basis of a differential folded cascode structure (Bako, Butkovic et Baric, 2010). A custom CMOS OpAmp design methodology is presented in (Khare, Khare et Sethiya, 2008). Detailed step-by step design tutorials of CMOS OpAmps are also thoroughly presented in (Comer, 1985; Kao, Wei et Kuo, 2001). Accordingly, such a transformation can be developed based on the existing body of literature and the OpAmp's PIM description;

- PIM to Implementation Transformation: to obtain the final layout of the OpAmp, a PSM to implementation view transformation is needed. One can use a dedicated tool able to generate a ready-to-manufacture layout from a circuit schematic. While most layouts are currently handcrafted and CAD tools offer little support for automated layout generation, tools such as Cadence are available in commercial applications and significantly help designer in the layout phase.

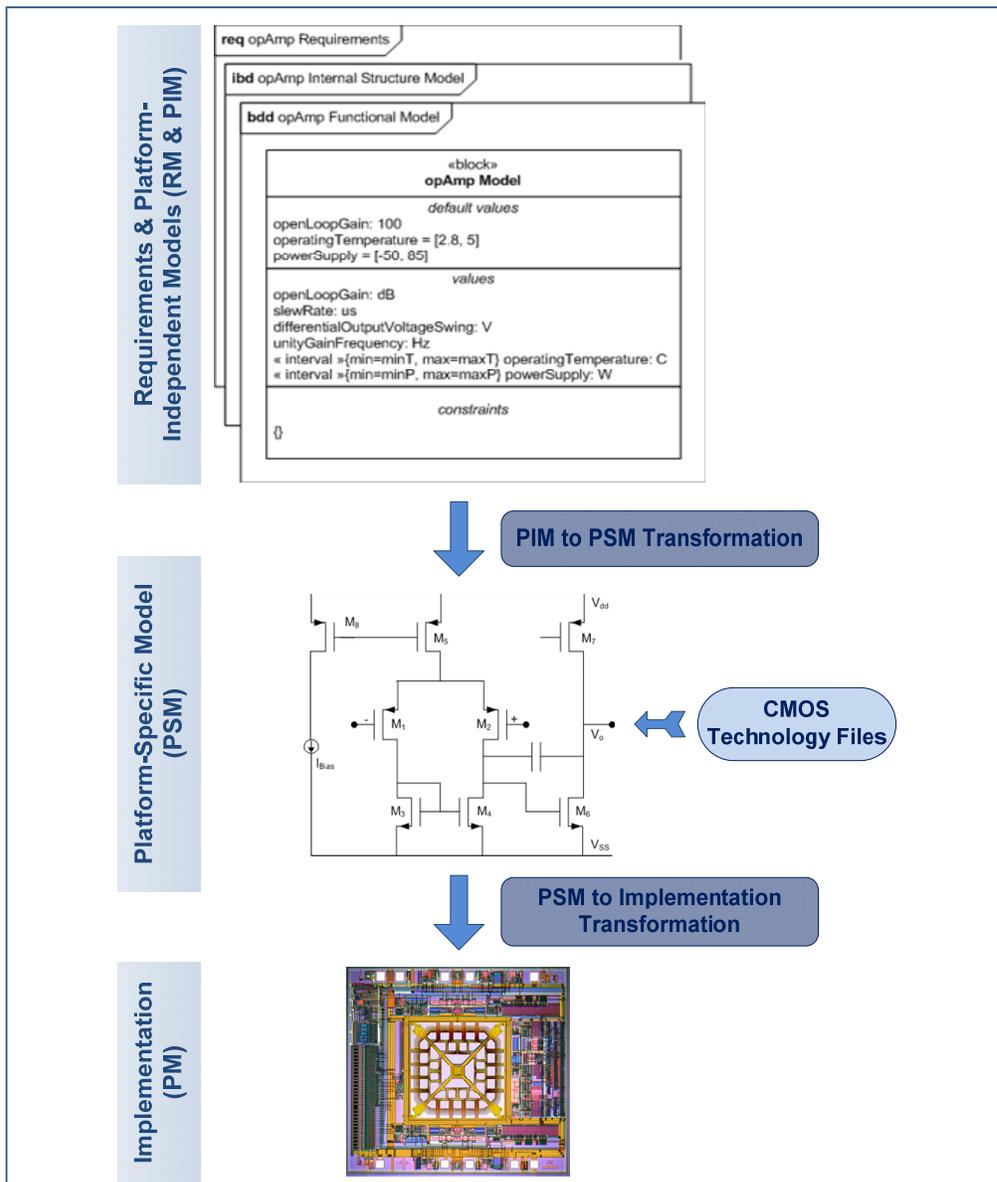


Figure 4.47 An example of transformation scheme for operational amplifier design

The examples of passive filters and operational amplifiers presented in this section show that the main aspects of the proposed abstraction strategy are applicable to RF design. However, we still need to streamline the developed abstraction concepts with the design scheme already discussed in chapter 3. The ultimate goal is obtaining a relatively complete design framework to endorse modern design practice of RF systems.

#### 4.5 SysML Profile for RF Devices

In the previous sections (e.g., 4.3.3) we illustrated how SysML could be used for the modeling of RF devices and the elaboration of high-level functional description. In this section, we develop comprehensive constructs to facilitate such tasks. As shown in Figure 4.48, we use the mechanism of profiling<sup>87</sup> to extend the SysML standard with constructs adapted for the RF domain. The elaboration of a “*SysML Profile for RF Devices*” aims at providing a basic modeling infrastructure that can serve as a generic template for the development of SysML models for RF devices and systems.

The proposed SysML profile uses the constructs (e.g., blocks, parts and relationships), notations, semantics and diagrams in order to define a new meta-model which allows to model the various aspects of RF devices and systems. As shown in the package diagram of Figure 4.49, the proposed SysML profile consists of four main meta-models:

- RF stereotypes: in modeling languages, a stereotype is construct that allows extending the languages vocabulary by adding new modeling elements derived from existing ones but having their own properties, attributes and constraints. The package « RF stereotypes » defines specific blocks capturing the properties, structure and particularities of RF devices;
- Requirements: the package « Requirements » uses SysML requirement diagram and constructs in order to capture common RF requirements in a set of template models;

---

<sup>87</sup> “Profile” is an extension mechanism used to extend a reference meta-model (such as a modeling language, e.g., UML) with custom constructs that are specific to a particular domain.

- Coherence rules: this package extends the SysML parametric diagram with constructs intended to capture the coherence rules and various constraints that may apply to a given RF device or system;
- Value types: this package uses the Value Types constructs defined in the SysML standard in order to capture the common value types encountered in RF domain such as units, enumerations and constants.

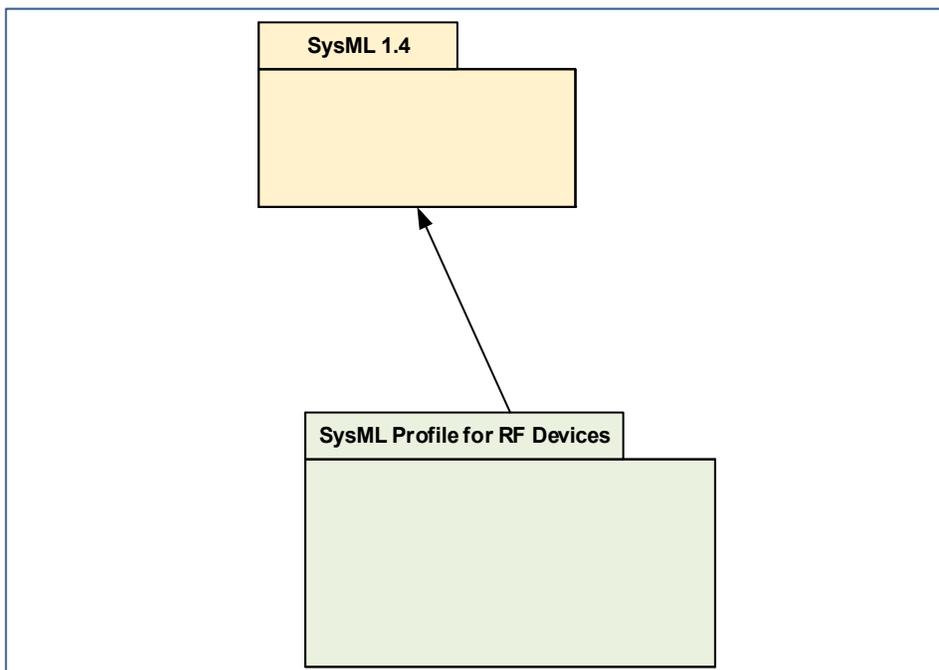


Figure 4.48 The proposed profile extends SysML standard (version 1.4) with specific constructs that are intended for RF domain

#### 4.5.1 RF Stereotypes

The first step is the definition of stereotypes and constructs that can be used for the modeling of the structure, hierarchy and internal parts of a RF device or system. To do so, we extended the basic SysML block with properties particular to RF domain and specified a generic hierarchy of the blocks that can be used as a modeling template.

**a) Basic stereotype**

A RF stereotype is a basic SysML block that is enriched with different compartments. Each compartment, among the following, captures some attributes, properties and artifacts of a typical RF device.

- Values: it captures the various attributes of a RF device or system;
- Default values: it is dedicated to default values that can be assigned to some attributes (e.g., operating temperature = 25 °C);
- Weights: the designer uses this compartment to assign a constant weight for some or all block attributes. Each weight represents the importance of that attribute from the designer's point of view. Model-to-model transformation and optimization tools use these weights to enable automated decision making throughout the design process;
- Constraints: similarly to weights in the previous compartment, constraints are used for the calculation of variable weights for each decision variable (as illustrated in section 4.3.5.c);
- Coherence rules: the designer can include the coherence rules for each block in this compartment. This is useful when a small SysML model is required. In this case, it is not mandatory to complete a coherence rules package and use only coherence rules provided with each block;
- Parts: this compartment enables the designer to enumerate the internal parts for each block. It may be useful because it specifies from the beginning the granularity level required for the block and provides an architectural view of it;
- Data: some blocks can be specified using data files (e.g., Touchstone for scattering parameters). This compartment allows embedding reference for each data file that is related to that block;
- Equations: In addition to data files, a block (or some of its building parts) may be defined using mathematical equations and/or algorithms. This compartment captures such information;
- Requirements: specific requirements related to each block can be added in this compartment;
- Testcases: if the block requires particular testcases to validate its behavior, these testcases can be enumerated in this compartment.

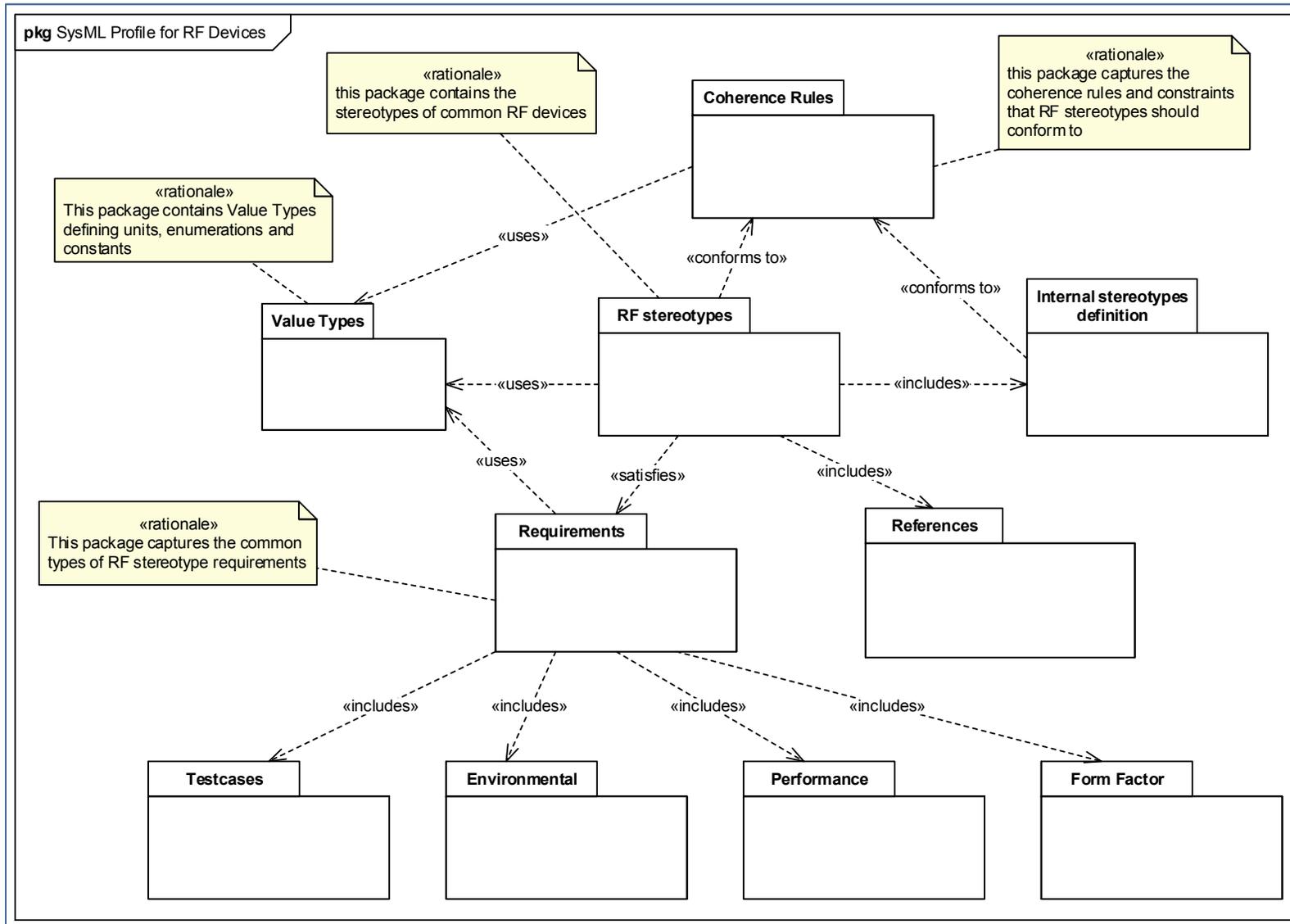


Figure 4.49 The package diagram describing the structure of and the relationships within the proposed SysML profile

All the previous compartments are shown in Figure 4.50. It is worth mentioning that it is possible to add new compartments to hold other types of information. It is also not mandatory to use all the compartments in functional description. In most cases, the first four ones (i.e., values, default values, weights and constraints) are used. Moreover, the use of some compartments such as coherence rules, parts, requirements and testcases does not often replace other similar packages (e.g., coherence rules and requirements packages) because it does not capture the relationships between multiple blocks.

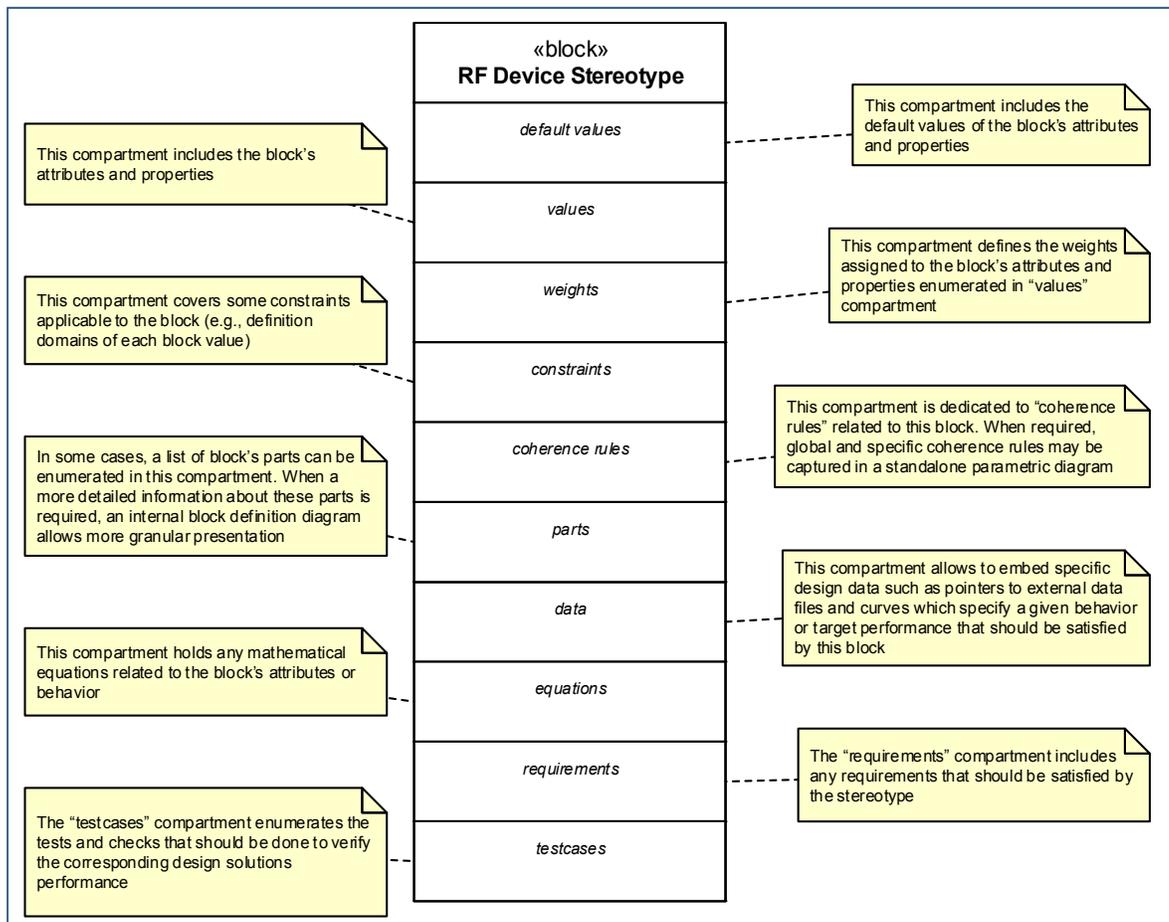


Figure 4.50 The stereotype of a RF device is a basic SysML block having specific compartments for RF modeling

## b) Hierarchy of stereotypes

Using the definition of the basic RF stereotype presented in the previous section, the next step is to define a hierarchy of stereotypes that describes common devices and components used in RF domain. In general, RF devices can be classified in two ways:

- Passive versus active: this classification subdivides RF devices in two groups: the first is passive while the second is active. On the contrary to active devices, passive ones do not amplify RF signals and do not need any DC drive signals. In absence of amplification, they cause a given amount of attenuation for RF signals;
- Linear versus nonlinear: this classification takes into account the RF devices' behavior. Some of them are linear while others may cause impairments and distortions to RF signals.

From a modeling viewpoint, which classification is better to consider? Since the RM/PIM focus primarily on functional description of RF devices and systems, the stereotypes should represent coherent and distinct functionalities. Accordingly, the former classification (passive versus active) is less interesting than the latter because some RF devices may exist in both versions. For instance, a mixer, which is functionally a frequency converter, may be implemented using passive structures (e.g., diode mixer) and active structures (e.g., Gilbert cell mixer).

To build a reference template for RF stereotypes, we aim to elaborate a hierarchy of RF stereotypes that functionally represent RF devices. As shown in Figure 4.51, the basic RF stereotype is the « *N-Port Network* » (at level 0). This complies with the black-box model we considered in section 4.3.3. Then, the « *N-Port Network* » acquires the properties of a « *Linear* » or « *Nonlinear* » device. That is the second level of specialization. At the next level, several functionalities are derived from each stereotype (e.g., frequency selection, frequency multiplication, power amplification, etc.).

For each functionality more specialized stereotypes are derived. In general, these ones represent common RF devices (e.g., up-converter, down-converter, etc.). The hierarchy of stereotypes shown in Figure 4.51 is not limited to few levels. It is possible to extend the existing stereotypes by adding new ones which either generalize or specialize them. If a new stereotype

is created as a specialization to existing ones. It inherits their properties. On the contrary, if it is a generalization, the daughter stereotypes inherit its properties.

The concepts shown in Figure 4.51 are implemented in the block definition diagram of Figure 4.52 which captures the common RF devices. The « *N-Port Network* » stereotype is composed of *N* port. A « *Port* » stereotype is a particular SysML “block” capturing the properties of the ports encountered in RF devices and systems. Each derivative stereotype from the « *N-Port Network* » stereotype owns the same ports. It can redefine some of them or create new ones. The Figure 4.52 shows a generic view of the RF stereotypes. It focuses on their hierarchy and relationships rather than the attributes of each stereotype. The latter are presented in Figure 4.53, Figure 4.54 and Figure 4.55. In these block definition diagrams, the value properties of each stereotype are presented. Since the RM/PIM models are used for high-level functional description, technology-dependent attributes are not considered.

Furthermore, the nature of each value property (e.g., unit, dimension, type, size, etc.) is captured in the value types’ diagram of Figure 4.56. This avoid any ambiguity regarding the interpretation of each value property. This diagram is part of the « Value Types » package used by its « RF stereotypes » counterpart. In addition to units and dimensions, this package may also include any mathematical constants, enumeration lists, data structures and other tools that can be used in modeling.

### c) Stereotypes’ internal structure and external references

As shown in Figure 4.49, the « RF stereotypes » package includes two other packages:

- Internal definition stereotypes: it includes the models detailing the internals of each stereotype. The topology, structure, signals routing, granularity level and flow ports can be modeled using the SysML internal definition diagram. New semantics can be also supported. In the proposed SysML profile for RF devices the internals of each RF stereotype are not defined because these artifacts are not unique and may change according to the designer’s preferences and expertise;
- References: in addition to functional/architectural considerations captured in SysML structural diagrams, external resources may be useful to be referenced in RM/PIM for

better traceability. These external resources include but not limited to design data, tools and specific files (e.g., schematics, workspaces, etc.). The « References » package does not compromise the highest level of abstraction required for a RM/PIM. It links this abstract functional description to resources that are useful for throughout the design cycle.

#### **4.5.2 Coherence Rules and Requirements**

To capture the text requirements, the structural packages (i.e., the « RF stereotypes » and its included packages) are accompanied with the « Requirements » package. If these packages should satisfy certain preset rules, the « Coherence rules » package provides constructs to capture them. Both packages are depicted in Figure 4.49.

##### **a) Coherence rules**

The « Coherence rules » package reuses the SysML parametric diagram to capture the coherence rules used in the validation process of the functional description (including structural diagrams and requirements). These rules (commonly mathematical) are not only limited to RF stereotypes but can also be extended to their relationships and their internal parts. In addition, this package includes any design constraints expressed in the specifications.

##### **b) Requirements**

The « Requirement » package is intended to provide an infrastructure that allows capturing the common requirements related to RF design. This package makes use of the various SysML requirements constructs (e.g., the requirement diagram) in order to meet this goal. In the proposed SysML profile, we suggest an infrastructure composed of three main composite requirement constructs:

- Performance: this construct holds the requirements related to RF device's performance. At this regard, we consider requirements in terms of linear, nonlinear and noise performance. For each category, we also consider appropriate testcases;
- Form factor: this construct captures the requirements related to the device's physical and mechanical aspects and appearance (e.g., size, weight, shape, etc.).

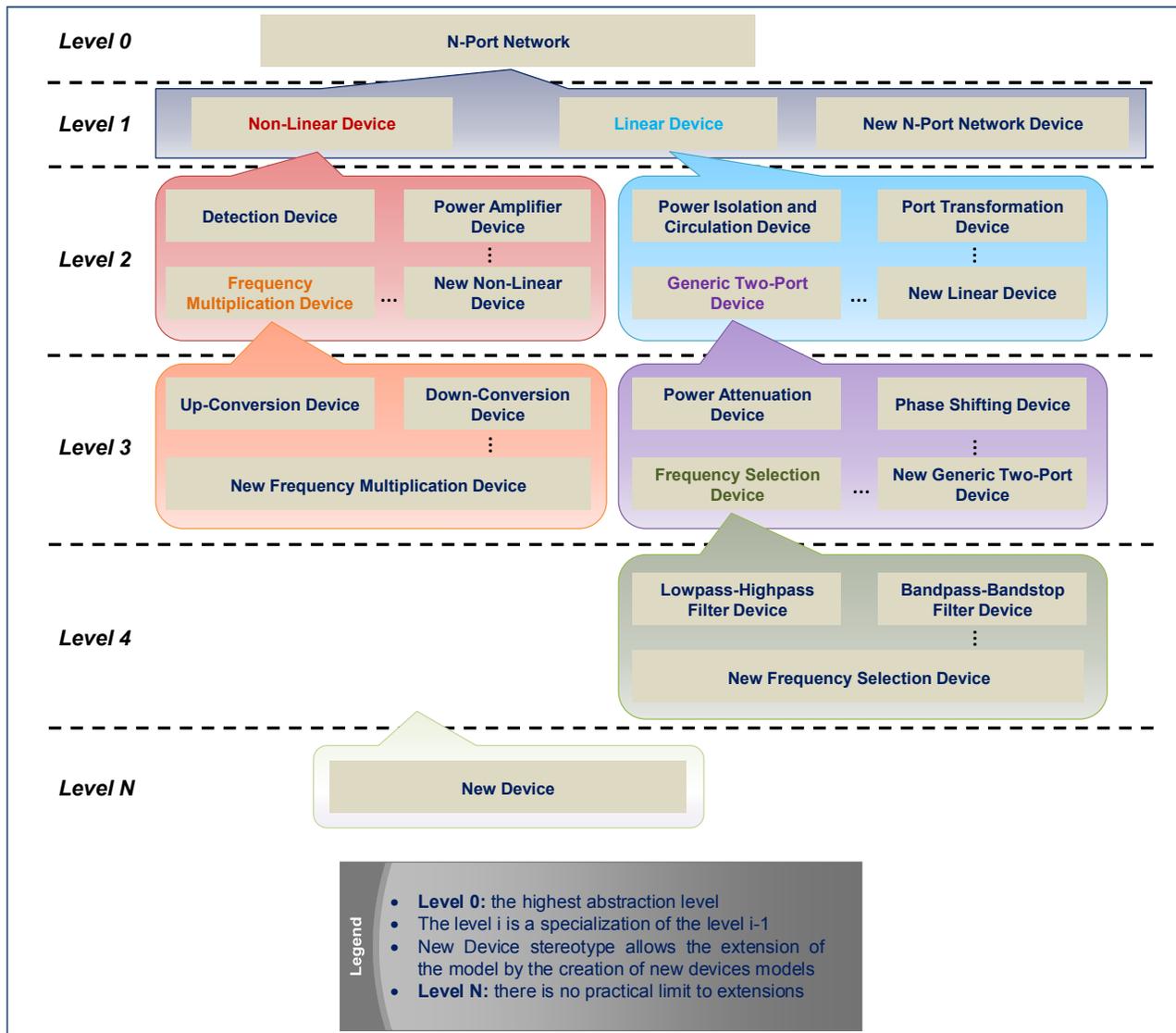


Figure 4.51 At the functional level, RF stereotypes are hierarchically structured

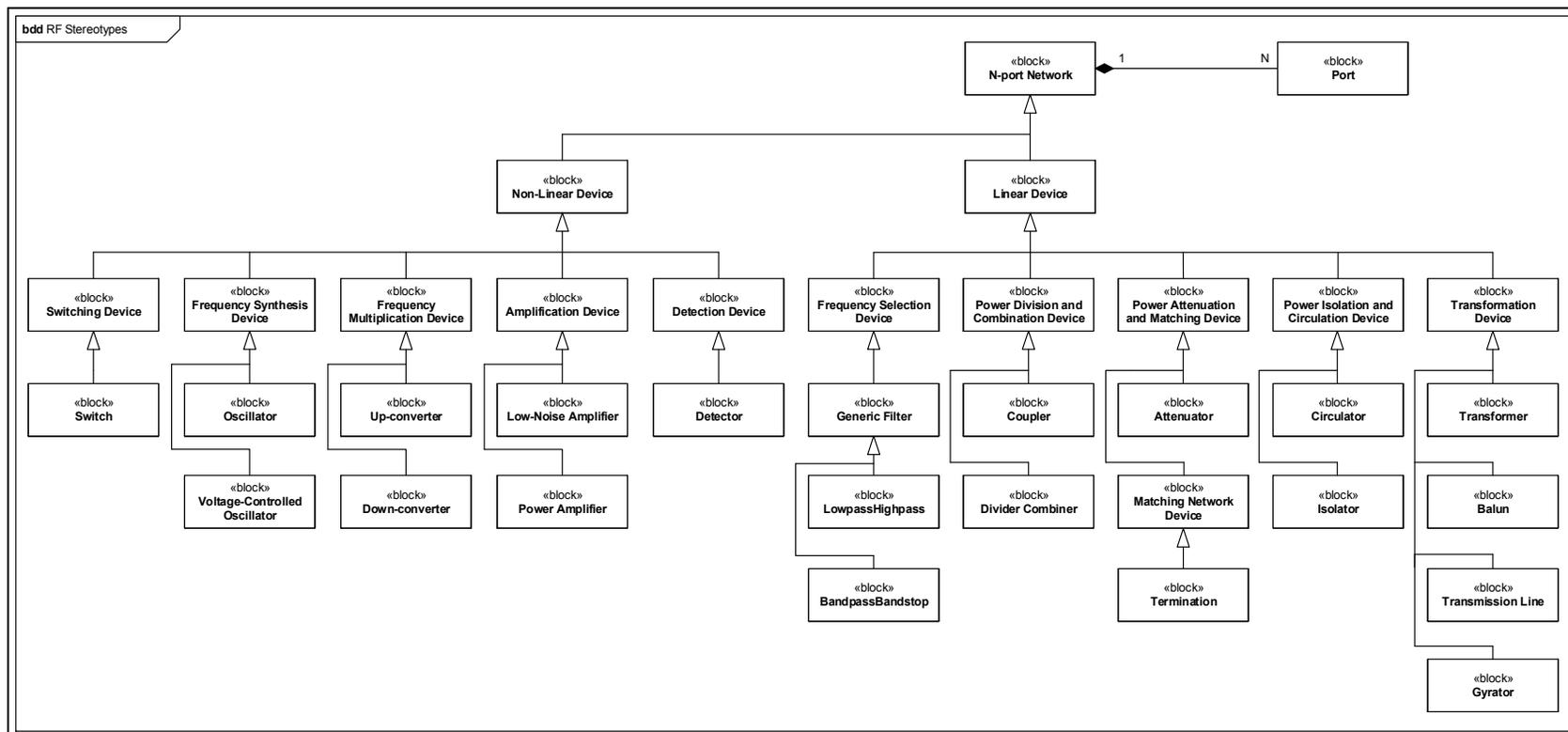


Figure 4.52 A SysML bdd depicting a generic view of RF stereotypes

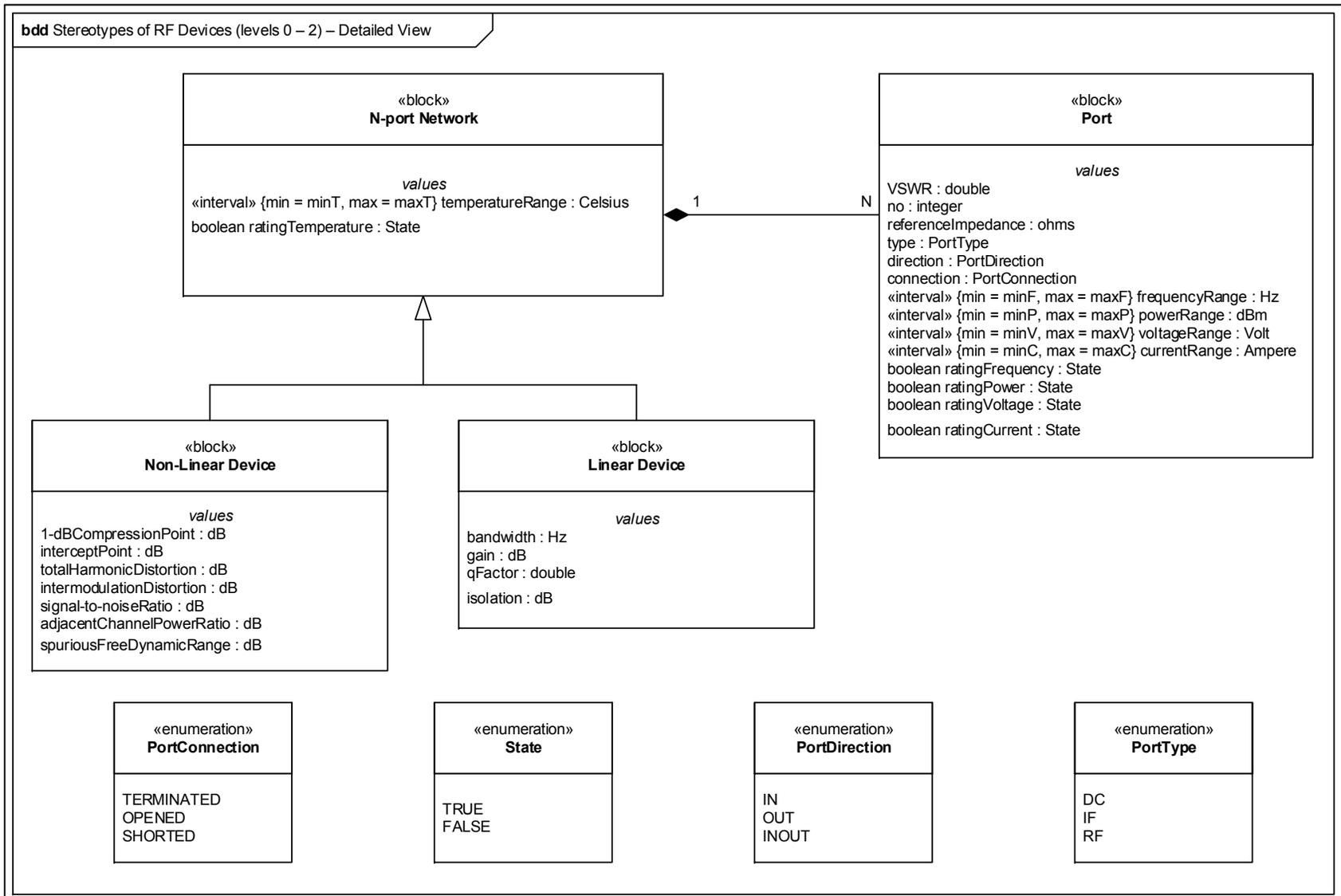


Figure 4.53 N-port network stereotype

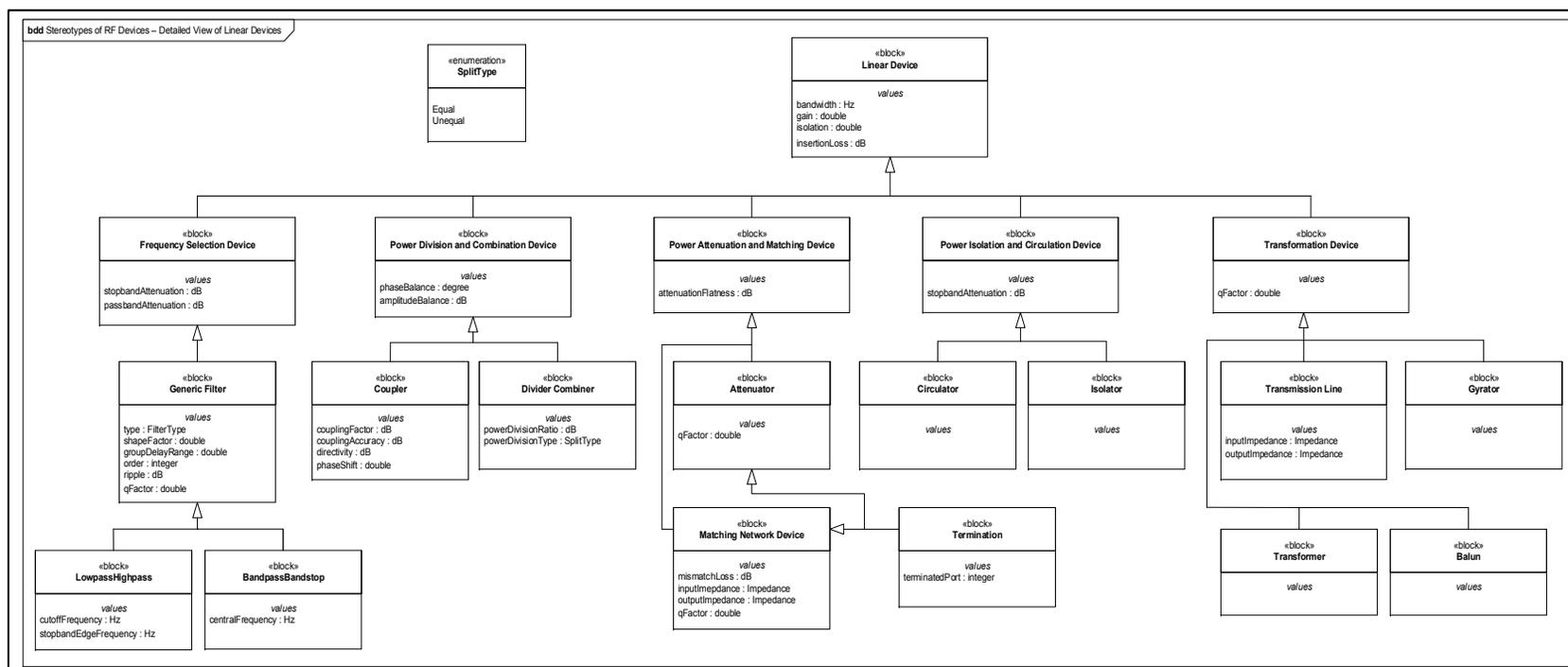


Figure 4.54 Value properties of linear devices

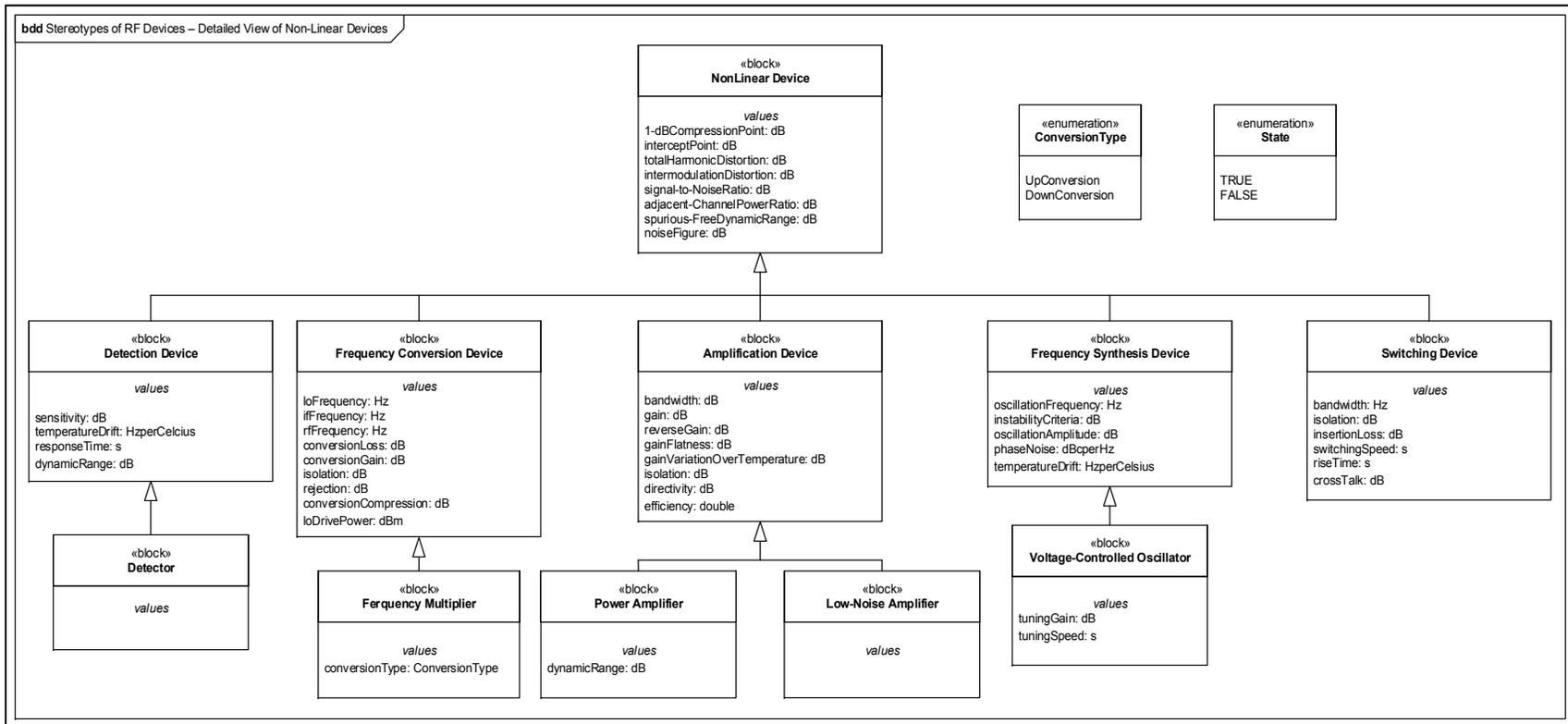


Figure 4.55 Value properties of nonlinear devices

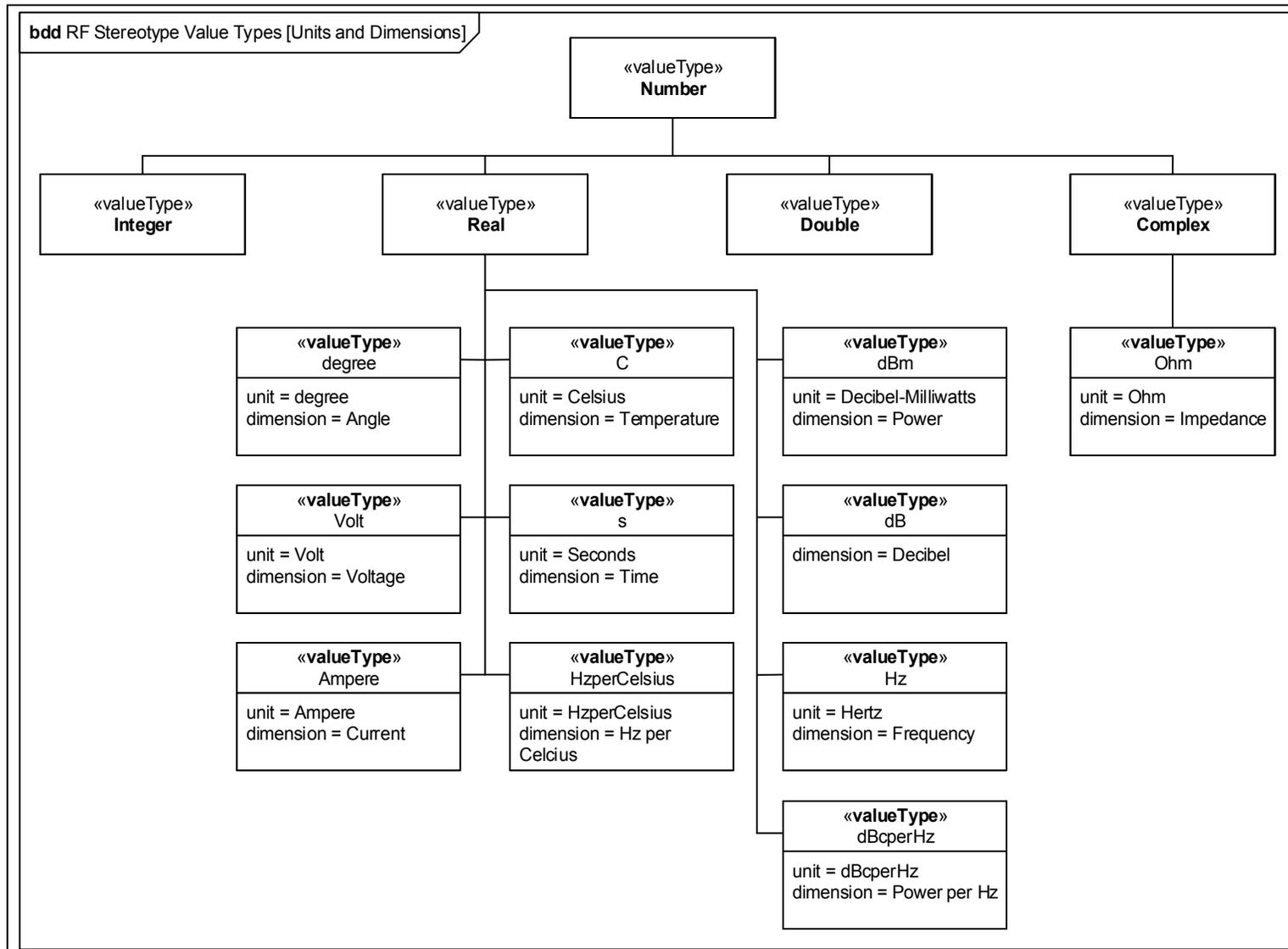


Figure 4.56 Common units and dimensions used in RF design are part of the Value Types package to avoid ambiguity

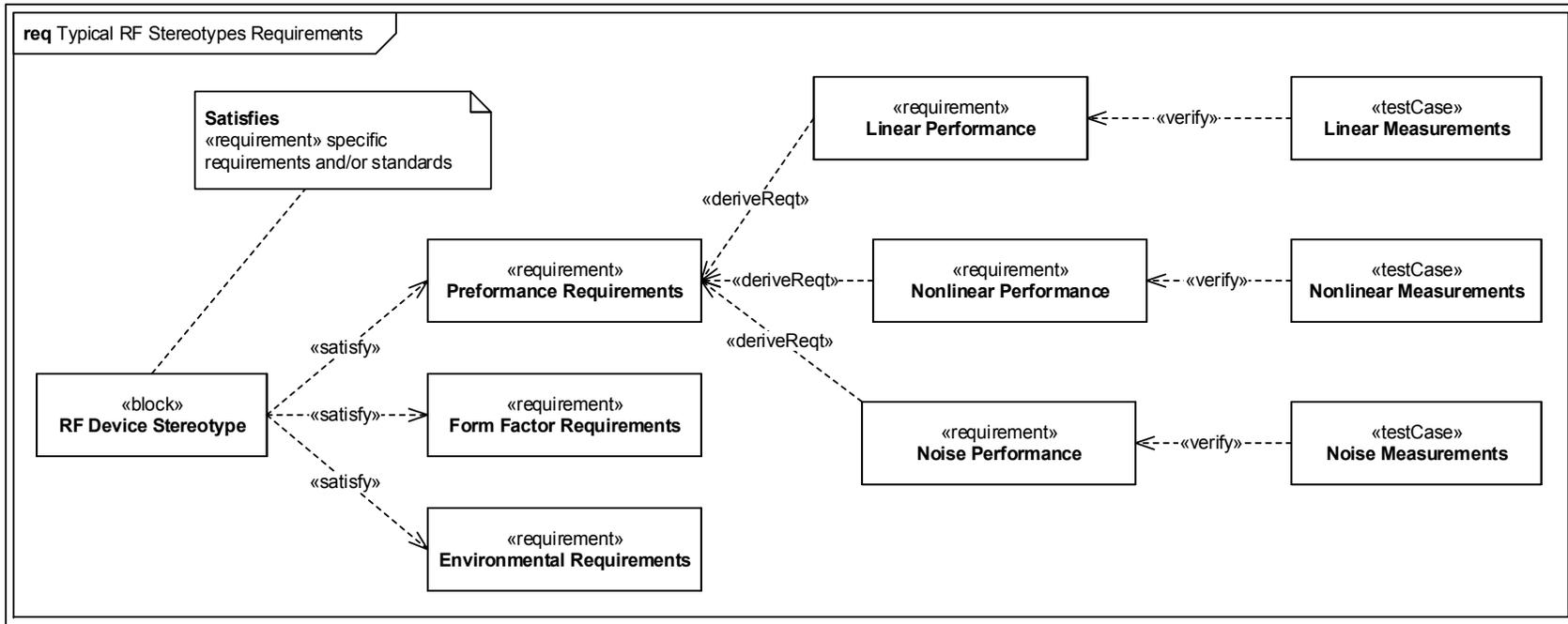


Figure 4.57 Common requirements and testcases required for RF devices design

- Environmental: the environmental requirements include radiation, shielding and other metrics measuring the device’s effect on its environment. This type of requirements is captured using the environmental requirement construct.

The Figure 4.57 depicts the previous requirement constructs and their related testcases.

### 4.5.3 Profile Extension and Usage

The proposed SysML profile aims at enabling a design template to help beginners coping with functional description of RF devices and systems using the Systems Modeling Language. For this reason, it intentionally provides simple constructs and reuses the same semantics of SysML. That is why it does not cover necessarily all the existing RF devices. The proposed packages (including stereotypes attributes and relationships) are not exhaustive. Nevertheless, it is always possible to enrich this profile with new design constructs to model more complicated RF devices and systems.

#### a) Altering the proposed constructs

Using SysML constructs (such as blocks, parts and diagrams), it is always possible to modify the proposed profile. These modifications include the alteration of the attributes, relationships and semantics related to each construct (e.g., adding or removing attributes form an existing RF stereotype). It also includes the redefinition, deletion or replacement of existing ones (e.g., adding or removing stereotypes or packages). Existing constructs can also be rearranged.

To illustrate these principles, we altered the RF stereotypes of Figure 4.52 as depicted in Figure 4.58 in order to model linear two-port devices. For this purpose, we first created a new stereotype named « Generic Two-Port Device » (red-colored in Figure 4.58). The new stereotype is a generalization of existing ones (i.e., « Transformation Device », « Power Attenuation and Matching Device » and « Frequency Selection Device »). Since all the daughter stereotypes of the « Transformation Device » one (e.g., transformers and baluns) are not two-port devices, we rearranged the remaining stereotypes in a new hierarchy (as depicted in the green rectangle of Figure 4.58). The retained stereotypes (i.e., « Transmission Line »

and « Gyrtator ») are functionally similar. Both of them operate a phase shifting of the input signal. For this reason, we renamed their mother stereotype as « Phase Shifting Device » (instead of « Transformation Device ») to better express their functionality (see yellow-colored stereotype in Figure 4.58).

**b) Use of profile constructs**

Let us assume that we would like to structurally model both an active and tunable bandpass filter using the proposed profile constructs.

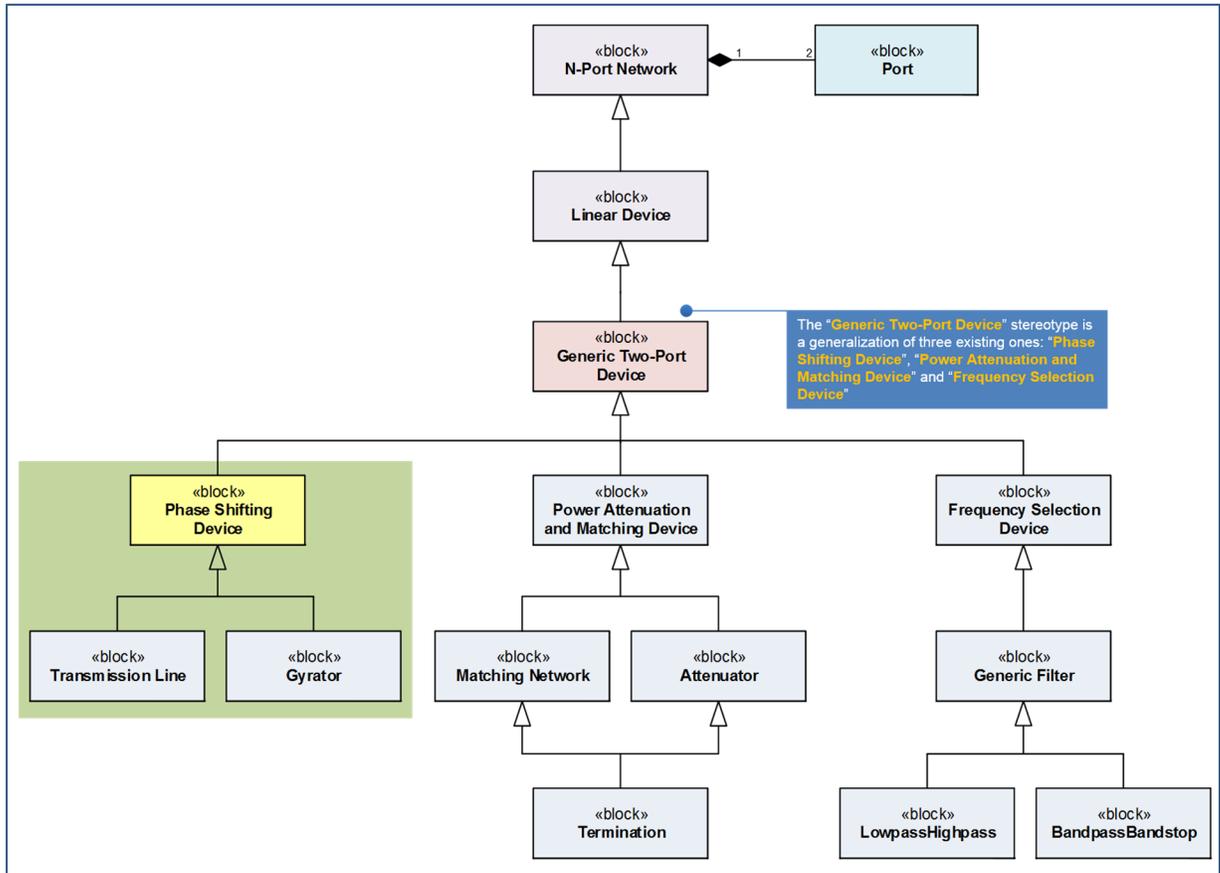


Figure 4.58 The constructs of the proposed SysML profile are subject to extension and modification

We first verify if the target devices can be functionally described using the existing stereotypes. If this is cannot be fulfilled, the proposed profile should be extended to provide the required constructs for this purpose.

- Active bandpass filter: it is a frequency selection device that adds a given amount of gain to the input signal. On the functional level, it gathers the properties of a bandpass filter and a low-noise amplifier. In addition, it has its own properties and attributes (such as dumping ratio). On the functional level, it can be a specialization of two existing stereotypes (i.e., « Low-noise Amplifier » and « BandpassBandstop »). Accordingly, the resulting block « Active Filter » inherits all the attributes of these stereotypes (as shown in Figure 4.59);
- Tunable bandpass filter: similarly to the previous case, the functional-level model of this device is derived from the « BandpassBandstop » stereotype as depicted in Figure 4.60. Its specific properties and their related constructs (e.g., enumeration) are also considered.

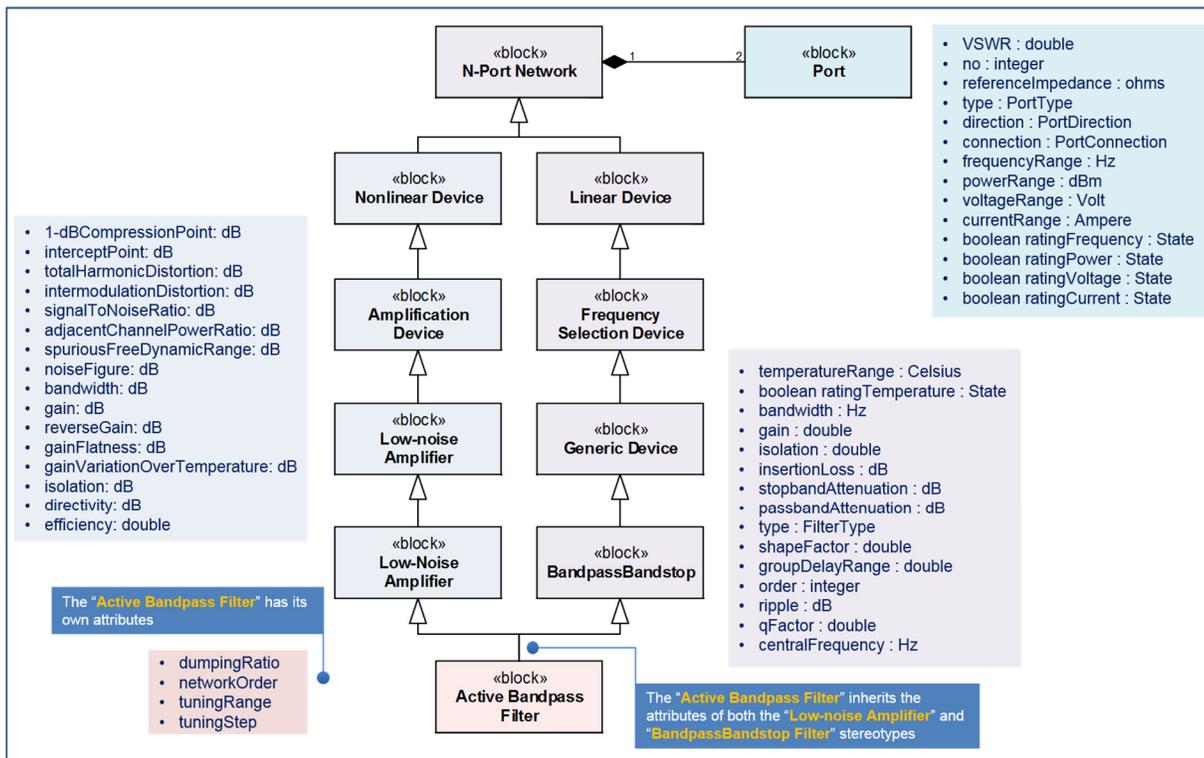


Figure 4.59 An active bandpass filter block extends and reuses “Low-noise Amplifier” and “BandpassBandstop” stereotypes

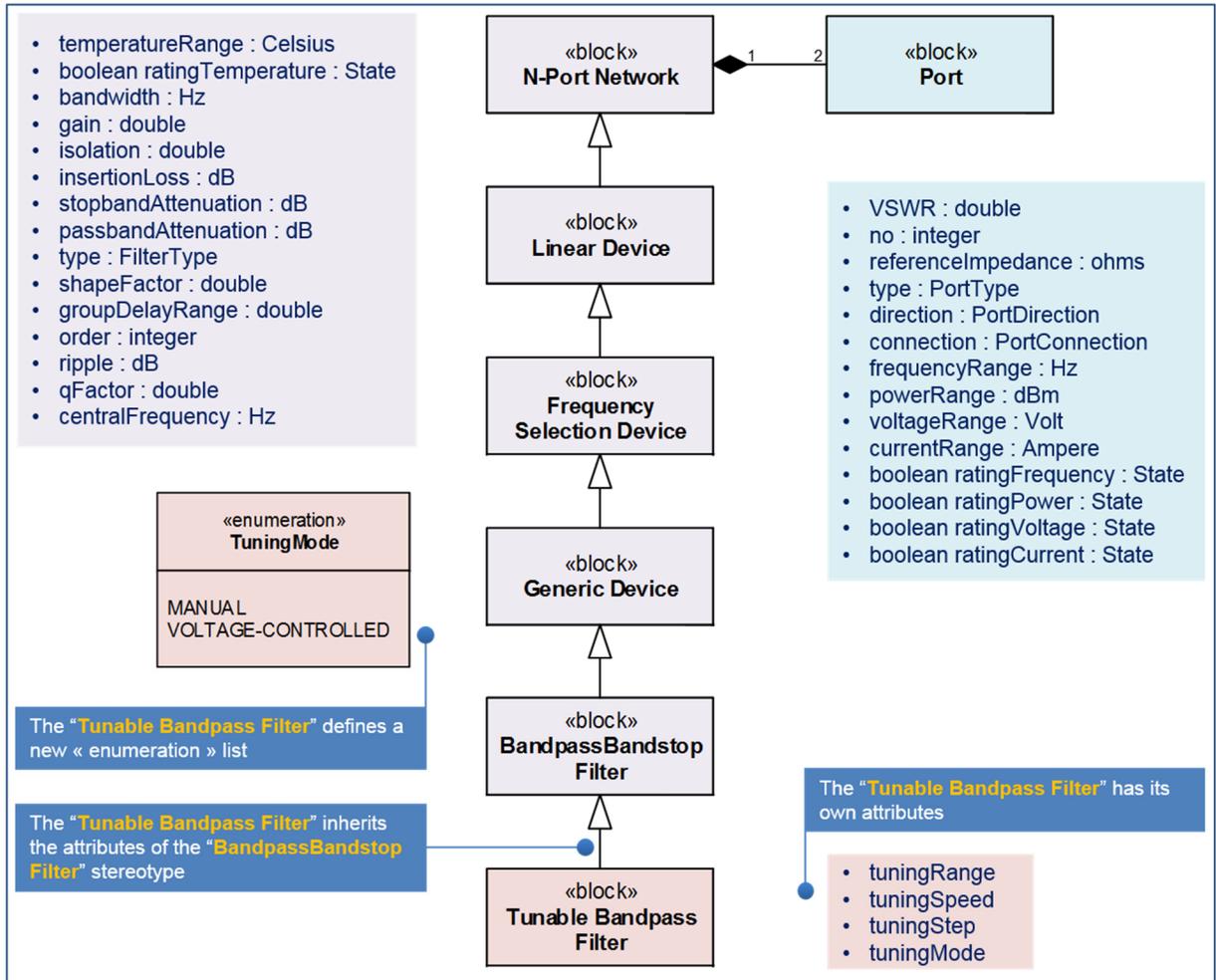


Figure 4.60 A tunable bandpass filter extends and reuses the block “BandpassBandstop”

#### 4.6 Integration of RF and Microwave Hardware Abstraction Strategy in the Proposed Design Framework

As mentioned at the end of the previous chapter, the proposed design scheme had some shortcomings related particularly to the issues of models development and use as well as technology independence.

In this chapter, we proposed a hardware abstraction strategy that defines some concepts to effectively ensuring the development of technology-independent high-level models. This strategy is inspired by the key MDE abstraction concepts (such as abstraction levels and model-to-model transformations depicted in Figure 4.23). At this step, we propose to adopt the

abstraction concepts of the proposed strategy to the RF design cycle and to incorporate it into the original framework.

For the proposed scheme to be streamlined along with the concepts adopted in the proposed hardware abstraction strategy, the first task is to delimit its various stages in accordance with four-level approach, as depicted in Figure 4.38. To this end, we continue to consider the Q-matrix in a central position accessible at various steps be they in the RM/PIM, the PSM or PM (i.e., implementation) phases. The resulting mapping of the design scheme to the different abstraction models is captured in Figure 4.61.

Under this scheme, the RM/PIM domain covers the functional description of the system, the coherence verification and system-level performance simulation. In this domain, the system is presented at a level that is totally independent from any technology details or platform. At this level, the abstraction is very high in a way that even an unrealistic system may be functionally described but rejected through coherence verification and/or performance simulation. Next, the PSM domain may include system simulation and covers the steps of the synthesis process, which is composed of three sub-steps, namely granularity refinement, technology mapping and performance simulation. In this domain, the system model is enriched with technology details and the abstraction level is lowered in order to take in consideration the physical constraints and information related to the implementation platform. On the first hand, technology limitations, if any, that may prevent the realization of the stated specifications are generally discovered and feedback to the previous stages can be given so the design process may be restarted or re-iterated. On the other hand, if no technology limitations are met, then the design will be feasible and can be moved on to the PM/implementation domain, which encompasses the manufacturing and testing, steps.

It is worth noting that the border between RM/PIM and PSM domains is floating. This is because some system-level performance simulations may result in some cases, in a circuit model that can be used as a PSM. This said, specialized tools and/or algorithms might be used to implement cross-view transformations from RF/PIM to PSM domains as well as from the latter and PM/implementation domain. In practice, cross-view transformations do not impose

any changes of the design scheme since it is always possible to convert a source model to another model (i.e., move from a domain to another either forward or backward) without facing any discontinuities in the design flow. However, intra-view transformations many need a change of granularity when applied. If changing the granularity level during the phases of “*Functional Description*” and “*Synthesis*” is possible, it is not the case in “*Analysis*”. For this reason, we added a new sub-step to this phase in order to allow granularity refinement when required. We also renamed some sub-steps in both “*Analysis*” and “*Synthesis*” design stages in order to emphasize the model-centric approach we are adopting. These changes are depicted in Figure 4.62. The modified design scheme is then streamlined to the proposed hardware abstraction strategy as reflected in Figure 4.63.

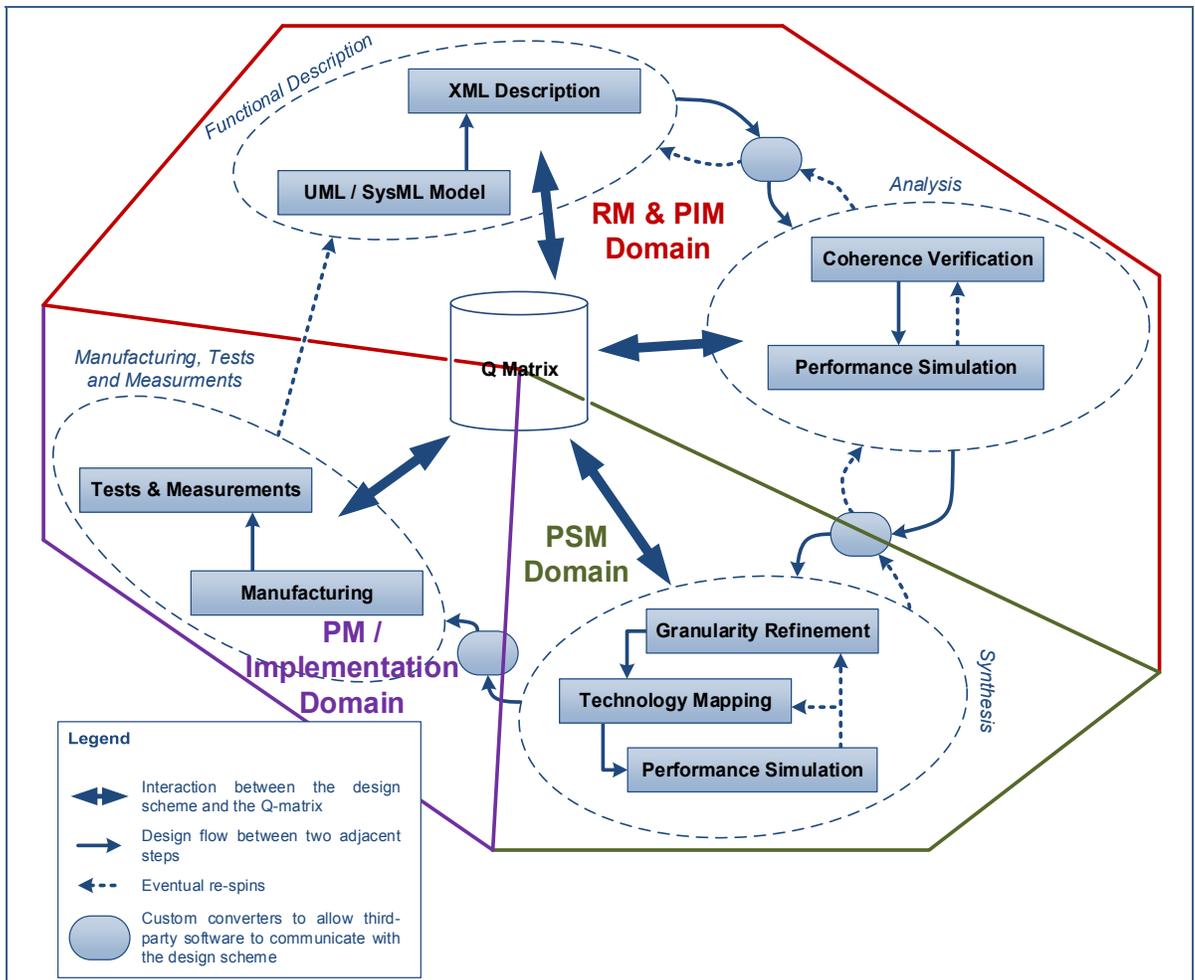


Figure 4.61 Streamlining the proposed design framework with the RF/microwave abstraction strategy

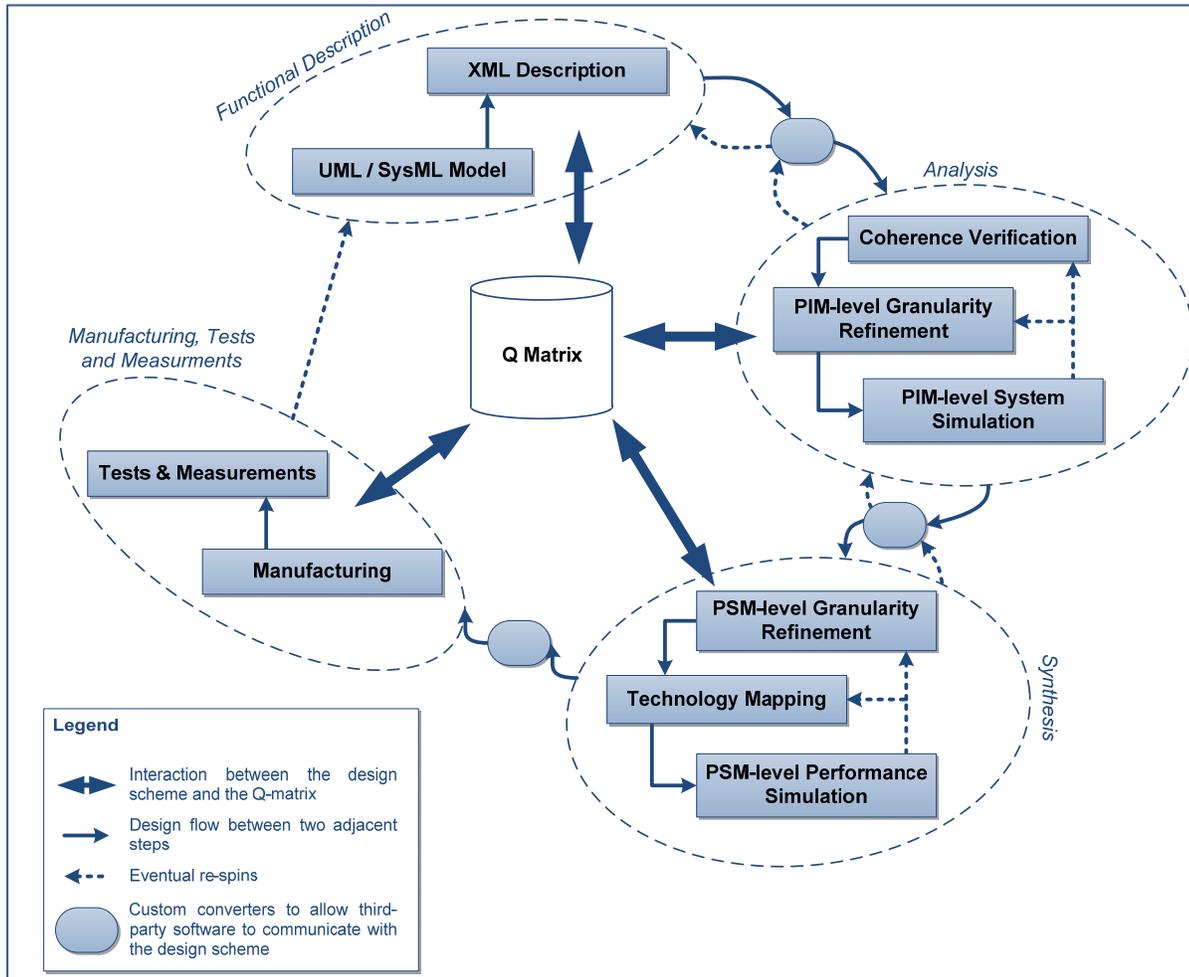


Figure 4.62 Introducing granularity refinement at PIM-level to enhance design space exploration and at PSM-level to improve physical implementation

#### 4.7 Provision of the RF and Microwave Hardware Abstraction Strategy within the Proposed Design Framework

The first provision of the proposed abstraction strategy is the definition of a complete set of abstraction concepts for RF/microwave domain. The basic modeling entity adopted in this strategy is the black-box model. Four abstraction levels are considered, namely atomic layer, circuit, module and system. Four viewpoints are also considered (i.e., physical, electrical, structural and functional/architectural) to which four views were associated (i.e., platform,

platform-specific, platform-independent/requirements models). In addition, cross- and intra-view transformations were established to move from one view (i.e., model) to another. As shown in Table 4.9, these basic concepts and mechanisms are comparable to those defined in other domains such as software development (i.e., MDE/MDA), digital and analog/mixed-signal design.

Similarly to Table 3.7 which summarizes how the initial design scheme addresses the various challenges in RF/microwave design, Table 4.10 recapitulates the contribution of the abstraction strategy to the design scheme. Changes are highlighted using bold face.

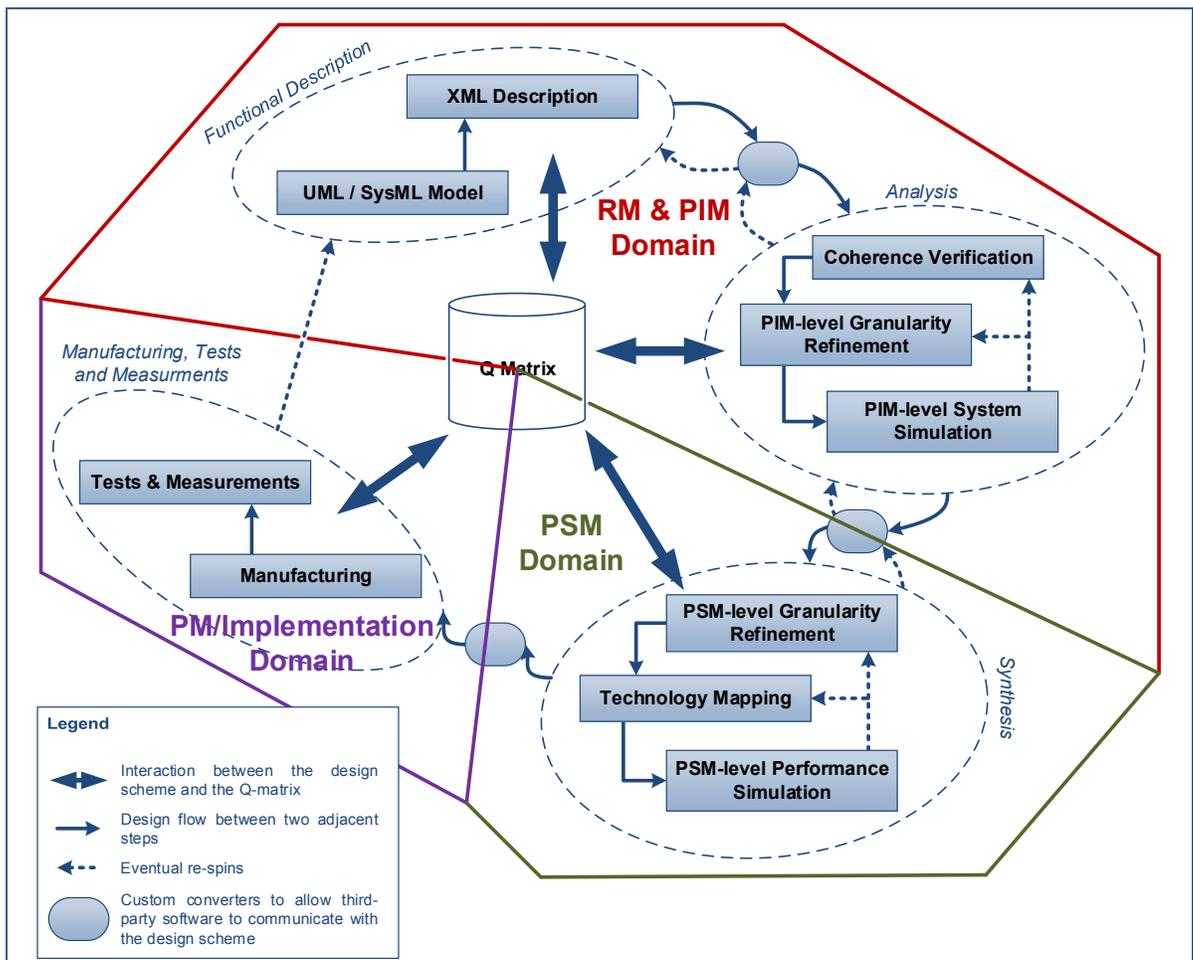


Figure 4.63 Streamlining the proposed design framework with the RF/microwave abstraction strategy

Table 4.9 Comparison between the proposed abstraction strategy for RF/microwave design and those adopted for MDE/MDA, digital, analog and mixed-signal design

<b>Abstraction Strategy</b>	<b>RF/Microwave design (proposed)</b>	<b>MDE/MDA</b>	<b>Digital design</b>	<b>Analog and Mixed-signal design</b>
<i>Basic Entity</i>	Black-box Model	Object Model	Entity Model	
<i>Abstraction Levels</i>	System Module Circuit Atomic Layer	Business Logic Computation Platform	System Module Gate Circuit Device	System Module Circuit Device
<i>Viewpoints</i>	Functional Architectural Structural Electrical Physical	Business Logical Computational Physical	Architectural Functional Logical Electrical Physical	Behavioral Ideal Functional Non-ideal Functional Electrical
<i>Views</i>	Requirements Model Platform-independent Model Platform-specific Model Platform Model	Computational-independent Model Platform-independent Model Platform-specific Model Platform Model	Behavioral Model Register Transfer Level Model Gate Model Circuit Model Layout Model	Behavioral Model Ideal Functional Model Non-ideal Functional Model Layout Model
<i>Transition Mechanisms</i>	Cross-view Transformations Intra-view Transformations	Model-to-model Transformations Model Bridges	Hardware Compilation and Synthesis Tools	
<i>Modeling Languages</i>				



The model-to-model transformations concept adopted in the proposed hardware abstraction strategy paves the way for increasing automation. Given the appropriate tools and/or algorithms, the conversion of models becomes highly automated (or at least semi-automated, especially if the designer wants to have more control of the design process). Better automation comes also with better design concurrency because models can always be used in various contexts (e.g., co-design, distributed computation tools, etc.). Being model-centric, tools interaction improves gradually as well. Tasks such as coherence verification, system-level analysis and synthesis take part of growing automation which significantly enhances designer productivity. In addition, the control of abstraction levels associated to the Q-matrix contributes to better productivity. This is because the design and simulation effort required at high levels is smaller than at lower ones. Since the Q-matrix is always able to hold data design related to different contexts, the designer can have access to data of different abstraction levels. This gives the designer the ability of comparing the design performance at different levels of complexity. This data may also serve for future designs as initial design solutions.

The definition of views and viewpoints allows for easier design collaboration since models become more comprehensive and traceable. At this regard, design reuse is also enhanced particularly at “*Analysis*” and “*Synthesis*” design stages.

#### **4.8 Conclusion**

The fourth chapter of this thesis begins with an overview of the strategies of hardware abstraction in use in different engineering domains. We started with the abstraction concepts applied in digital and analog/mixed-signal design. At this regard, we focused on abstraction levels and concepts and how they fit within the design approaches in use in these domains. Then, we broaden our survey of existing hardware abstraction strategies in other engineering domains (e.g., software engineering). We learned from this survey which abstraction concepts to elaborate for an effective abstraction strategy as well as how to implement and use models at different abstraction levels and from various design standpoints. These observations helped us in the elaboration of a hardware abstraction strategy for RF devices and systems.

The proposed abstraction strategy defines a set of abstraction mechanisms. First, it defines a basic entity, namely black-box model, which serves as a generic model functionally characterizing RF/microwave devices and circuits. Then, we define five abstraction levels, viewpoints and views, which enable the designer to develop models from different design perspectives and at various levels of abstraction. Next, we define the transition mechanisms (i.e., intra- and cross-view transformations) that allow deriving a target model from another one. These transformations are not only intended to provide practical ways to move from an abstraction level to another (or changing the design viewpoint within the same abstraction level) but also to automate that transition. We completed the proposed abstraction strategy with a SysML profile for RF devices, a modeling infrastructure enabling designers to use SysML for the functional description of RF devices and systems. This SysML extension adapting the constructs of SysML to RF domain does not only support the key abstraction mechanisms (e.g., viewpoints, abstraction levels, granularity, etc.) but also provides visual diagrams for the expression of design requirements and constraints. Finally, we streamlined the proposed hardware abstraction strategy with the design cycle proposed in the previous chapter. The combination of both resulted in a design framework that provides model-centric design stages and a set of mechanisms to validate, optimize and automate the design solution search and implementation.

This chapter concludes the second section of this thesis. The next chapter focuses on the practical usage of the design framework. Through selected case studies, the various design concepts and mechanisms are questioned in the purpose of validating the proposed design framework.



## CHAPTER 5

### VALIDATION OF THE PROPOSED FRAMEWORK THROUGH SELECTED CASE STUDIES

#### 5.1 Introduction

In the previous section, we proposed a new design framework for RF and microwave devices. This framework consists of a five-step design cycle along with an adapted hardware abstraction strategy. We introduced in this proposal diverse concepts to address the major challenges (especially those related to productivity, collaboration and technology insertion) facing today's design practice. Since we have been so far limited to examples illustrating how the presented mechanisms and concepts work, we aim in this chapter to validate the framework's applicability and coherence. Unfortunately, the formal validation of this framework falls beyond the scope of this thesis for two main reasons. First, the originality of the framework made it very difficult to develop appropriate tools for an end-to-end design process. That is why we attempted to adapt some existing design packages and use them in our case studies. Then, formal validation of the framework requires the elaboration of rigorous mathematical models for each concept in order to validate the overall framework's construction. This task requires a huge effort and a focused expertise that is worth providing in future phases of the framework development (e.g., eventual adoption in commercial applications).

The validation method we choose to adopt in this chapter is through selected design case studies of both linear and nonlinear RF devices. We start with a reminder of the framework's design stages and concepts. Then, we present three design case studies. The first is a detailed step-by-step design tutorial of RF bandpass filters using the proposed framework. The second shows how to use multiple model-to-model transformations in PSM generation. The third demonstrates concurrent design of attenuators. Additional but less detailed case studies of nonlinear devices and system-level systems are presented at the end of the chapter. For each case study, the role of the Q-matrix is underlined. Finally, we summarize the advances provided by the framework in the light of the current design practice.

## 5.2 Practical Implementation of the Proposed Framework

As shown in Figure 4.59, the proposed framework consists of five-stage design scheme that is built around the Q-matrix. This design scheme is streamlined with a hardware abstraction strategy that defines three modeling views: Requirements and Platform-Independent Models, Platform-Specific Models and Platform Models (see Figure 4.60). Each view expresses a given design viewpoint that can be associated to a given abstraction level. These theoretical concepts need to be implemented from a practical standpoint in a set of comprehensive steps where inputs and outputs of each step are clear. Figure 5.1 depicts a flat representation of the design framework from the designer's perspective. The design process goes step-by-step through the five-stage design cycle as illustrated in the flowchart of Figure 5.2:

### a) UML/SysML Models

This step starts the design process. It requires a mandatory input, namely specifications. These specifications may be in text format, spreadsheets, etc. The designer uses a model creation tool to capture these specifications in SysML models (other standard modeling languages can also be used). The models can be created from scratch or using existing modeling templates (e.g., modeling profiles). If the latter solution is adopted, the designer's derives the required functionality from the existing constructs (e.g., describing predefined functionalities). Depending on that functionality, default parameters' values are used to define the device's models. It is worth noting that both requirements and platform-independent models are produced in this step. As SysML/UML standard languages are concerned, there is a number of commercial software packages that can be used to capture specifications and produce visual RM/PIM models. Most of these software tools are standalone packages that were mainly optimized to be used in software engineering. Thus, they require some modifications to be used in RF design. Ideally, any integrated design environment that is intended to make this framework effective requires a dedicated software tool or plugin that is fully optimized for RF modeling using standard modeling languages. At the end of UML/SysML modeling, the output of this step is a set of files which holds the visual UML/SysML models representing the device's RM/PIM models.

**b) XML Description**

The RM/PIM models produced in the previous step are used at this level to generate corresponding XML description. For this purpose, the designer uses a XML generation tool to convert visual models into XML markup language files that can be automatically processed, updated and exchanged between different tools, designers and design environments. Similarly to modeling packages, there are currently existing tools mostly originating from software engineering domain that fulfill this task. They can be adapted to RF design as well. The generation of XML files is accompanied with the creation of the Q-matrix. At this level, it is populated only with a subset of the data captured in RM/PIM models. Since these models are not yet verified, they may contain errors and incoherencies and subsequently contaminate the Q-matrix.

**c) Coherence Verification**

In this step, the RM/PIM models and XML files along with the associated Q-matrix are validated to ensure the coherence of the models' parameters and data. To this end, the designer uses a model validation tool that checks the RM/PIM models based on a set of coherence verification rules which are provided also as input. The tool produces a validation report where any potential inconsistencies and validation errors are outlined. If errors reported, the designer proceeds to the revision and correction of the RM/PIM models before it attempts to generate again the corresponding XML description and Q-matrix and carry out another coherence verification test. If all models and the related Q-matrix are proven to be coherent, the designer can proceed to the next step where a design solution can be searched and optimized. Unfortunately, there are no existing tools that can be used with no or at least minor modifications to carry out the task of coherence verification. To overcome this weakness, we used scripting languages to accomplish this process. Some specialized software libraries can also be used for the same purpose (e.g., analog filter libraries).

**d) PIM-level Granularity Refinement**

Based on the RM/PIM models, the designer undertakes a space exploration process to look for a solution that satisfies the initial requirements. If a promising design solution is found, this step may be skipped. If no satisfactory solution is found, the designer proceeds to the

refinement of the PIM models in order to relax the design constraints. For example, if there are any parameters that are overestimated, they might be given more reasonable values. If any key design parameters were assigned to default values (particularly when design templates are used), these defaults may be subject to review in order to make design solution search more efficient. In all these cases, another coherence verification test is mandatory to keep the RM/PIM models consistent and be sure that the new modifications did not compromise their coherence. Having done this and no satisfactory design solution is found, the next action is PIM-level granularity refinement that consists of changing the design view without changing neither the abstraction level nor the design viewpoint. This is practically demonstrated by the derivation of additional information within the models in the purpose of reducing the design space search area. For every granularity refinement iteration, a new QBlock is added to the Q-matrix to hold the data related to the RM/PIM models corresponding to that iteration. To succeed the granularity refinement process, the designer uses jointly two main tools: a model refiner and a model optimizer. Among the existing design tools, we noticed that scripting languages may be used as refinement (and optimization) tools at a reasonable time and effort cost. Some specialized commercial packages might also be used for the optimization of certain models (often with significant overhead). In fact, an effort of manual models conversion should be carried out in order to transform them into an acceptable input to these tools.

#### **e) PIM-level Simulation**

In this step, the designer carries out different simulations in order to ensure that the design solution meets the requirements expressed by the RM/PIM models. Generally, it consists of iterative performance evaluations (based on metrics mostly depending on the selected functionality) and optimizations. Designers can use scripting and programming languages as well as available APIs to carry out the required simulations for performance assessment. Most system-level tools can be used but require an overhead due to manual adaptation of RM/PIM models to the target design environment. During the PIM-level simulations, the Q-matrix is regularly updated. At every iteration, one or many new QBlocks can also be added. Feeding continuously the Q-matrix with data is useful for various purposes (e.g., conducting a performance comparison between multiple candidate design solutions). Using a relevant model-to-model transformation, one or many PSMs are synthesized from the best PIM-level

candidate design solution. Therefore, the output of this step is one or many platform-specific design solutions (i.e., PSM). In addition, an up-to-date Q-matrix which holds the history of the design process so far is also obtained. The original models (especially RMs often used for validation and traceability) are frequently attached to the resulting PSMs for the next design steps.

#### **f) PSM-level Granularity Refinement**

It is the first step in the synthesis design stage. The platform-specific design solution (i.e., PSM) already created using a PIM-to-PSM transformation is augmented with platform-specific information only (e.g., target implementation technology such as distributed lines). Nevertheless, it does not necessarily encompass detailed platform information (e.g., substrate data, technology constraints, etc.). That is why technology input is required to complete the model information. Before technology mapping, the PSM is assessed against the requirements. If the PSM does not satisfy the requirements, granularity refinement attempts to enhance the quality of that design solution. For example, a new QBlock is added to the Q-matrix in order to capture the corresponding design data.

#### **g) Technology Mapping**

At this step, the resulting PSM is augmented with detailed technology information. In practice, this means that each PSM element is enriched with corresponding technology features and items (e.g., substrate, physical characteristics and constraints, physical shapes and dimensions, etc.). Technology information may be provided using component libraries, electrical models or some existing tools (such as ADS LineCalc) that can be used to synthesize the physical properties of each PSM element. Ideally, this process is fully automated which implies the use of specialized tools that can automatically map each PSM component to the corresponding technology details. For the following case studies, we used scripting and programming languages for this purpose.

#### **h) PSM-level Performance Simulation**

Given a PSM with detailed technology information, the designer conducts at this level several performance simulations in order to evaluate the PSM's response against the requirements. At

this step, the performance assessment of the PSM is more accurate than its predecessor (i.e., PIM) due to the availability of technology platform information. If the PSM's performance is judged not satisfactory, several optimization iterations might be conducted in order to enhance the PSM's quality. Once the requirements are met, the PSM can be converted using a PSM-to-PM transformation into a platform model. In practice, this consists to accurately replace PSM elements by their detailed physical artwork artifacts (e.g., layers, materials, physical connections, etc.). The resulting layout is submitted after verification to the manufacturing step. Tools such as layout editors, design rules checkers and layout versus schematic tools can be used to ensure the absence of defects and design constraints violations in the final PM model (i.e., layout).

#### **i) Manufacturing**

Given the final PM, the RF circuit is manufactured, packaged and integrated using the suitable machinery.

#### **j) Tests and Measurements**

The fabricated circuit is then submitted to several tests and measurements in order to validate its actual performance. This takes place using commercial software and hardware tools (such as VNAs). All the measurements are reported and stored in the Q-matrix.

As shown in Figure 5.1, the Q-matrix lifecycle starts at the end of the functional description. Following its initial validation, the Q-matrix can be queried and modified at any design step by several parties (including involved designers and tools). This makes the Q-matrix a central piece of the framework that centralizes design data and allows an effective use of it (not only during the design process but also even after manufacturing).

Currently, the practical use of the framework is hindered by the lack of appropriate tools as well as the limitations of the existent commercial design packages. In fact, the latter has almost no support for standard modeling languages. Some of them support poorly few markup languages (e.g., SystemVue and Genesys have limited support to XML). Most of the predominant design environments use proprietary tools and file formats. Their support to

interactive application programming interfaces<sup>88</sup> (APIs) is limited. Accordingly, we had to use complex and manually implemented workarounds in order to use some popular design tools and packages for the implementation of the following case studies.

### 5.3 Case Studies

To validate the proposed design framework, we proceed in this section to the implementation of four case studies. In each case study, we address a particular RF functionality. As detailed in Table 5.1, the following case studies include:

1. Linear devices: frequency selection and power attenuation devices are implemented;
2. Nonlinear devices: a frequency translation functionality is developed.

We also experimented few other non-documented case studies (e.g., power division device, system-level analysis of a direct-conversion receiver). However, we chose not to include them in this thesis for text clarity and space considerations.

#### 5.3.1 Frequency Selection Device

A filter is a RF component that is used within a RF front-end to operate frequency selection. It suppresses signals at undesired frequencies and attempts to accept the wanted signals with the least possible attenuation. Various types of filters exist and can be built using several technologies. Generally, two prevalent approaches are used to design RF filters: Image parameter and insertion loss methods<sup>89</sup>. In this section, we consider the traditional filter synthesis process that consists of three main steps:

1. Lowpass prototype design according to the insertion loss method,
2. Filter network transformation (including frequency and impedance scaling), and
3. Filter network realization using lumped elements and/or distributed lines.

---

<sup>88</sup> An Application Programming Interface (API) is a set of software routines, libraries, protocols or tools which express the operation and inputs/outputs related to a software component. An API is intended to facilitate the interaction with existing software components or build new components on the top of them.

<sup>89</sup> The study of these methods falls beyond the scope of this thesis. For in-depth information, the reader may refer to the list of references given in section 5 of APPENDIX III (p. 460).

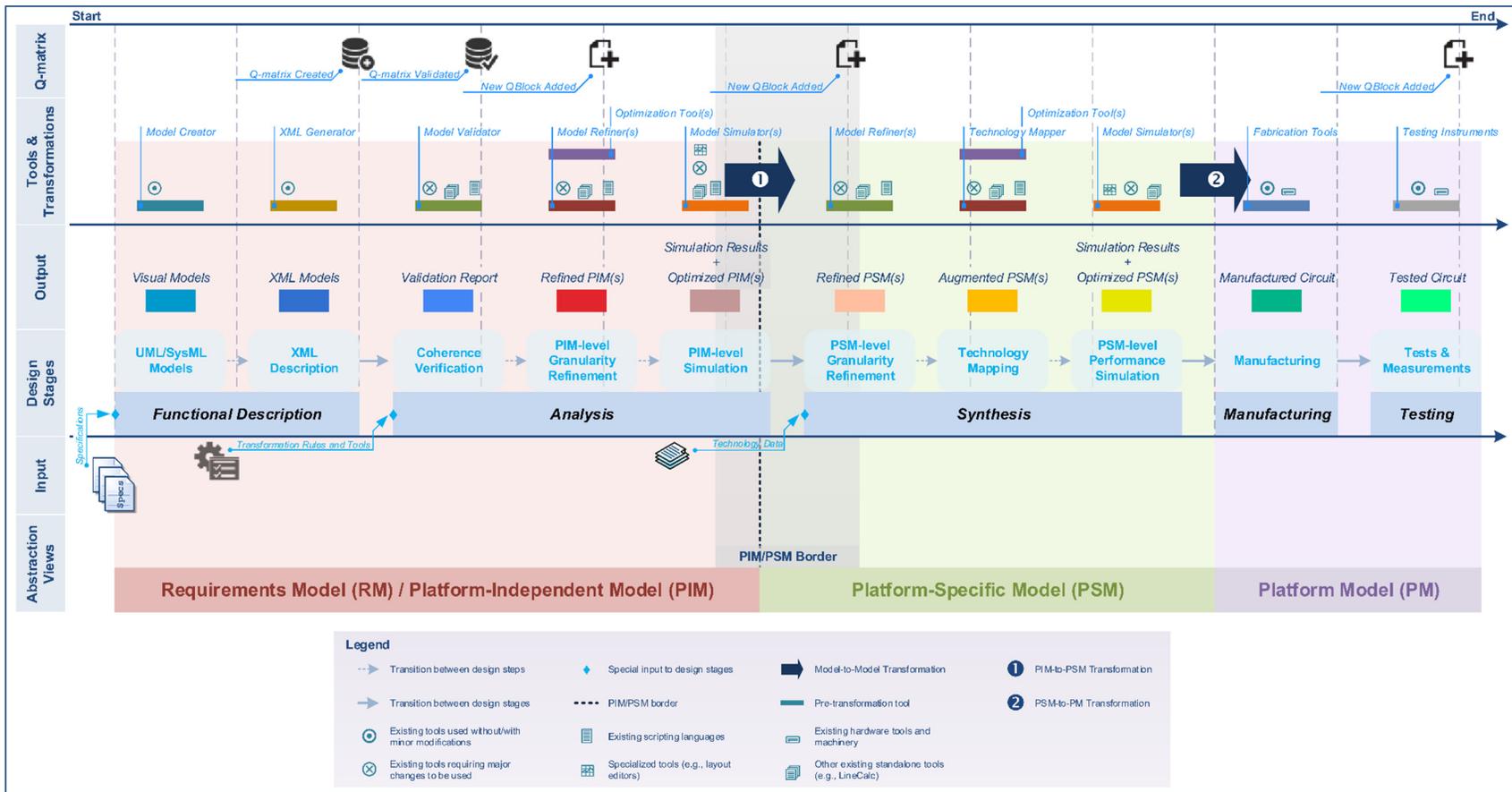


Figure 5.1 Detailed flowchart of the proposed design framework

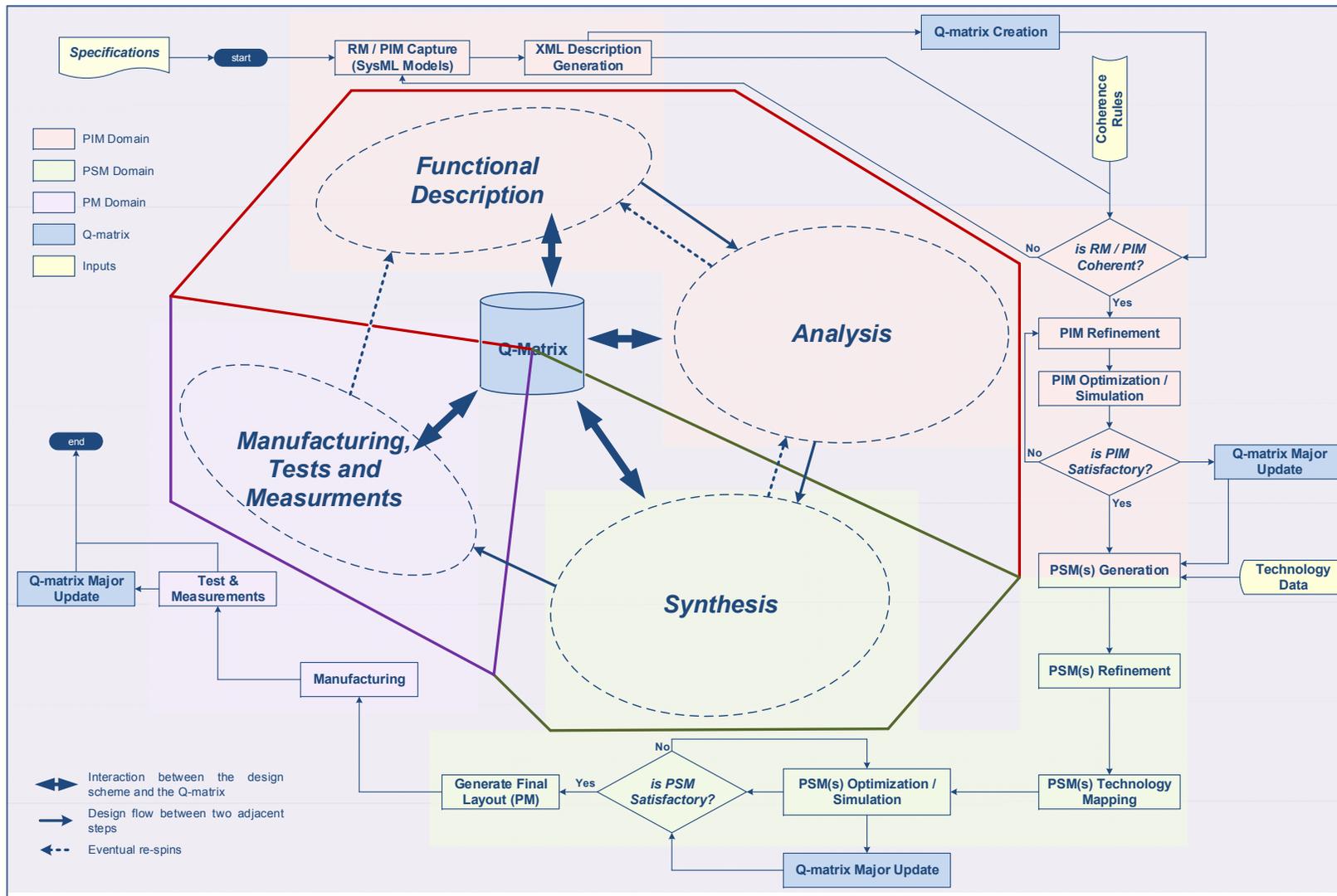


Figure 5.2 A detailed filter design flowchart extracted from the design framework

Table 5.1 List of case studies

Case Study	Objective	PSM Abstraction Level	PM Target Technology	Q-matrix
RF Bandpass Filter	<p>Presentation of a step-by-step tutorial demonstrating the major aspects of the framework including:</p> <ul style="list-style-type: none"> <li>– Functional description</li> <li>– Coherence verification</li> <li>– System-level analyses</li> <li>– Model-to-model transformation</li> <li>– Granularity change</li> <li>– Automated decision making</li> <li>– Automated technology mapping</li> </ul>	Circuit	LC/Microstrip	Q-matrix creation and evolution throughout the design cycle
RF Lowpass Filter	Presentation of the framework's capability of using multiple PIM-to-PSM transformations in order to create many PSMs from the PIM	Circuit	Microstrip	Q-matrix support for noise data
RF Attenuator	Presentation of the framework's concurrent design capability	Circuit	LC/Microstrip	Q-matrix support for concurrent design data
RF Passive Mixer	Summary of a passive mixer design using the design framework from two design perspectives	Circuit / Module	PSM only	Q-matrix support for nonlinear design data

We have already presented a generic process for filter design using the proposed design framework in section 4.4 (see Figure 4.44). In the following, we use the SysML profile for RF devices (see section 4.5) to implement the filter RM/PIM models.

An acceptable initial design solution satisfying the filter's PIM is then derived using a traditional filter approximation (e.g., Chebyshev, inverse Chebyshev, maximally flat, elliptic, Bessel, etc.). Based on this approximation, an ideal network of resonators (see Figure 5.4) which meets the initial specifications is then easily derived using a relevant PIM-to-PSM transformation. This network represents the filter PSM which is subsequently transformed into an adequate implementation (i.e., PM) given the appropriate technology data. At this regard, a filter can be realized using different technologies (i.e., waveguides, lumped components, LTCC, distributed lines, etc.). Accordingly, technology input can be of various formats. For illustration, see Figure 5.5 shows a distributed-line implementation of a RF frequency.

As shown in Figure 4.44 and Figure 5.1, each transformation may require external tools to conduct in part or in whole, PIM-to-PSM and PSM-to-PM transformations (e.g., a tool to generate a distributed-line layout from the corresponding PSM). Ideal resonators' networks are derived from SysML RM/PIM models and filter layout artworks are derived for each PSM. The electrical data are stored in the Q-matrix throughout the design process. Both models and transformations are depicted in Figure 5.6.

Based on the detailed design flowchart of Figure 5.2, the inputs to the functional description and synthesis stages are specifications and technology data respectively. Furthermore, the coherence verification rules are implicitly considered as an input to the coherence verification condition (i.e., entitled "is RM/PIM coherent?"). In addition to the RM/PIM models and XML description, the Q-matrix coherence is checked at the same flowchart condition. The task "Q-matrix Major Update" indicates that a new QBlock might be created to hold data from a new source (e.g., design stage, other designers or tools, etc.).

To put this design process into application, we implement in this section, two filters. The first is 450-MHz lumped-component bandpass filter for satellite communications. The second is a 1-GHz microstrip lowpass filter for intermediate frequency applications.

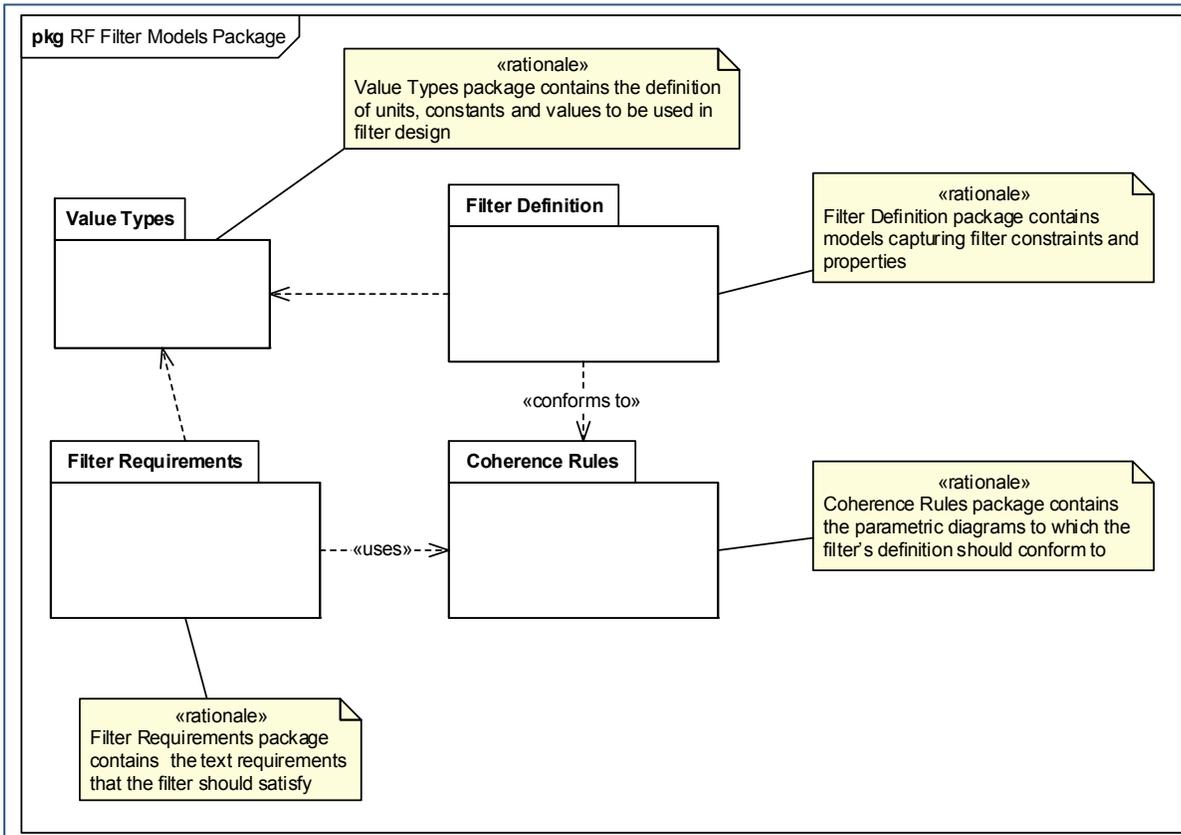


Figure 5.3 This package diagram gives an overview of the filter's SysML RM/PIM models

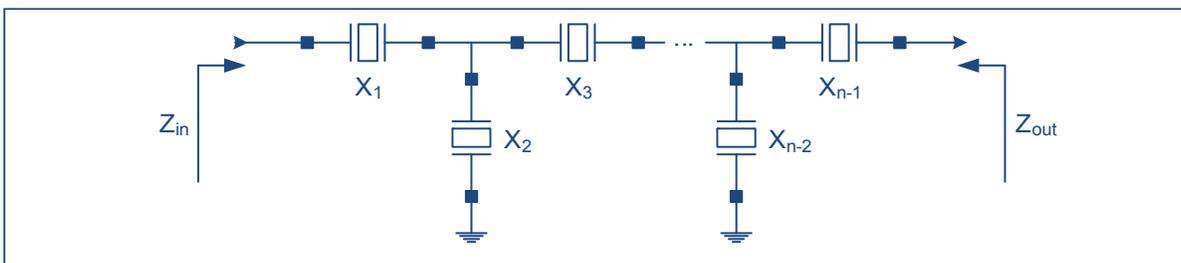


Figure 5.4 The filter's PSM consists of an ideal resonators' network

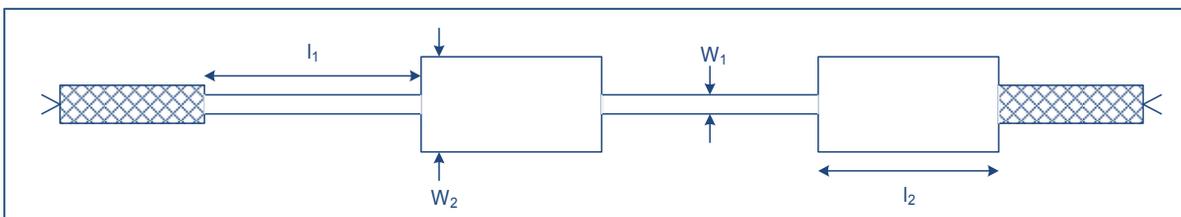


Figure 5.5 A distributed-line layout artwork is a potential filter PM model

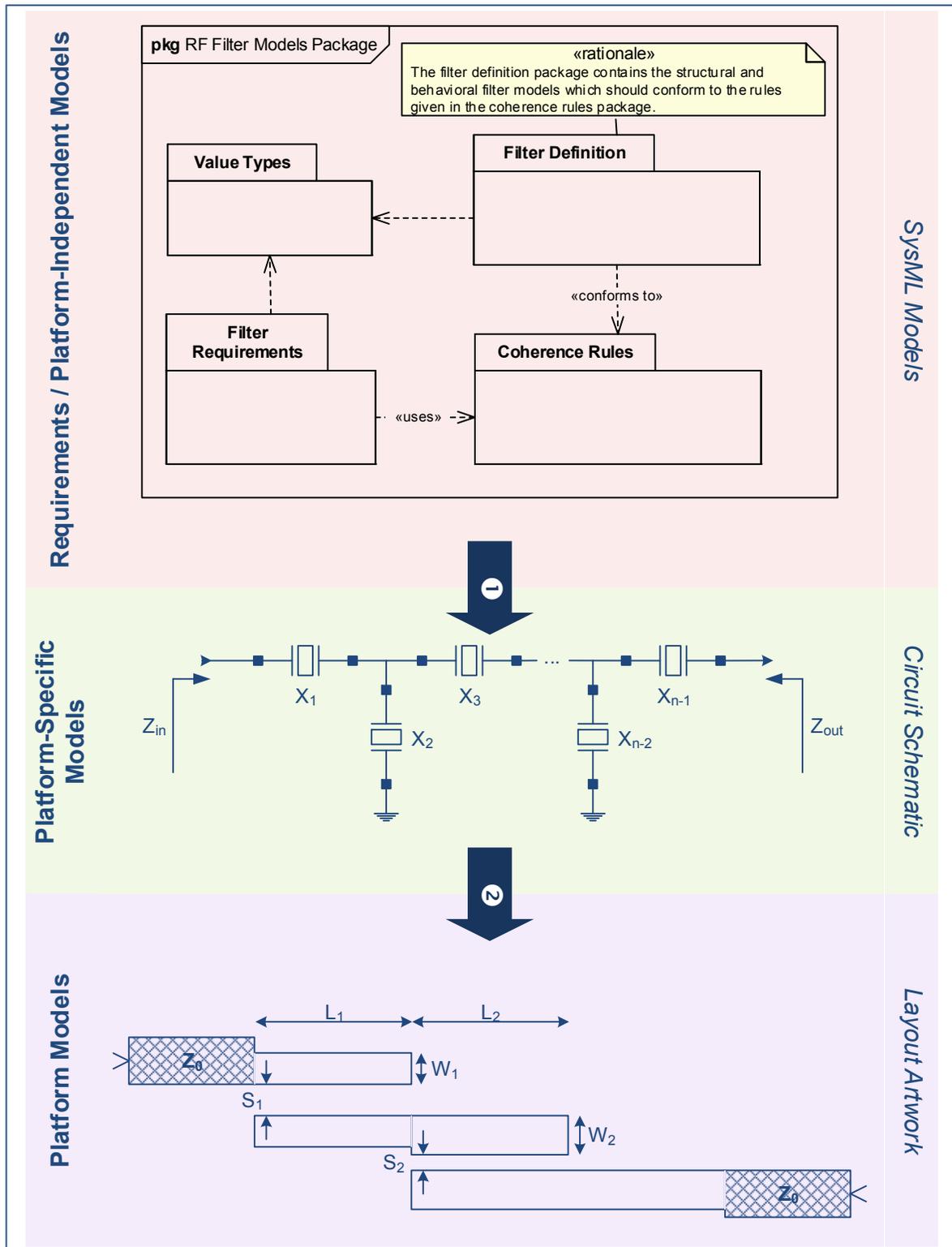


Figure 5.6 Model-to-model transformations convert RM/PIM to PSMs and PSMs into PMs

**a) A 450-MHz lumped-component bandpass filter**

In this first example, we aim to design a bandpass filter for satellite communications. We attempt to detail as much as possible the framework’s design steps.

**1. Design steps**

**a) Specifications**

A bandpass filter enables the selection of a given frequency band while it suppresses all the remaining lower and higher frequencies (see Figure 5.7). Traditionally, the specifications consist to assign a value to the filter parameters. In this case study, Table 5.2 shows the specifications of the desired bandpass filter.

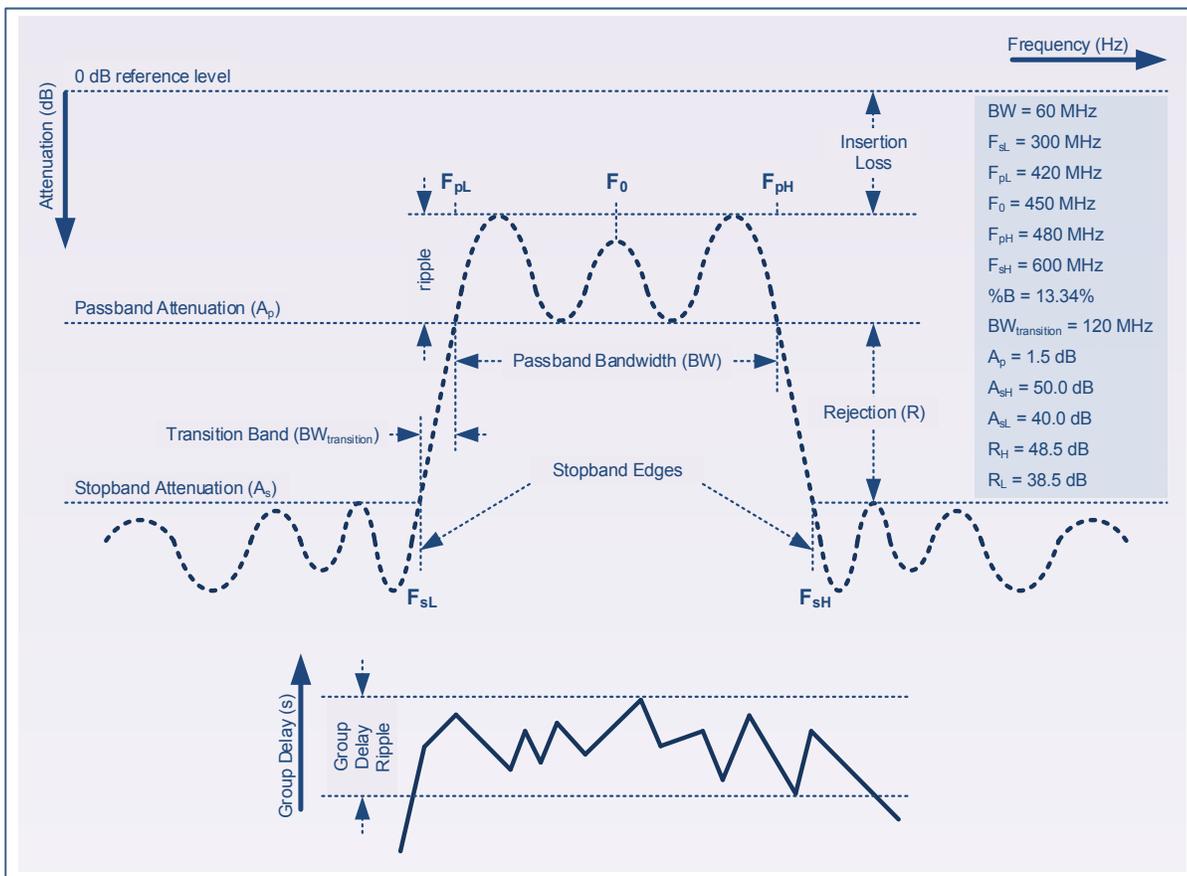


Figure 5.7 The main parameters of a RF bandpass filter

### b) Functional description: UML/SysML Models

Given the specifications of Table 5.2, the first design stage is the functional description of the desired bandpass filter. It consists of elaborating the RM/PIM models and generating the corresponding XML description.

Table 5.2 Typical bandpass filter requirements for a 450-MHz satellite radio

<b>Filter Type</b>	Bandpass
<b>Passband Attenuation (dB)</b>	< 1.5
<b>Stopband Attenuation (dB)</b>	> 40.0 @ 300 MHz
	> 50.0 @ 600 MHz
<b>Upper Passband Edge Frequency (MHz)</b>	480
<b>Lower Passband Edge Frequency (MHz)</b>	420
<b>Upper Stopband Edge Frequency (MHz)</b>	600
<b>Lower Stopband Edge Frequency (MHz)</b>	300
<b>Termination Impedance (ohm)</b>	50
<b>Other Requirements</b>	<ul style="list-style-type: none"> <li>– Small form factor</li> <li>– Lightning protection</li> <li>– Small radiation fingerprint (MIL-STD-461)</li> <li>– Operating non-condensing humidity up to 80%</li> </ul>

- **SysML Models (RM/PIM)**

Using SysML and based on the “SysML profile for RF devices” of section 4.5, we capture the specifications of Table 5.2 in RM/PIM models. These models do not only capture the filter parameters, structure and behavior but also other requirements. To capture all these design aspects, we define four main SysML packages:

- Filter Definition: contains the models which describe the filter properties and hierarchy,
- Filter Requirements: captures other text requirements related to the filter,
- Coherence verification rules: assembles the design constraints and the coherence rules that should be satisfied by the other packages (particularly the filter definition), and
- Value Types: defines the units, constants, values and other domain-specific artifacts related to filter design.

The package diagram of Figure 5.8 presents an overview of the relationships between the four packages. Both filter “Definition” and “Requirements” packages are associated to the “Value Types” package with a *dependency* relationship denoting that the models of the former packages use the definitions introduced within the latter. Furthermore, the models contained in the “Filter Definition” package should satisfy the rules and constraints captured in the “Coherence Rules” package. This is expressed by the *association* “conforms to” linking both packages. Similarly, the *association* “uses” indicates that the “Filter Requirements” models use the models within the “Coherence Rules” package.

- **Filter properties and constraints**

From a functional viewpoint, a filter is a frequency selection device. Its frequency response is traditionally of four types: lowpass, highpass, bandpass or bandstop. A custom filter can also be defined by combining two or more among these traditional frequency responses.

From an architectural viewpoint, a filter is a two-port linear network. It is composed of two ports through which RF signals come in and go out of the filtering circuit. The SysML block definition diagram (bdd) of Figure 5.9 presents a hierarchy of blocks that derives the bandpass filter functionality. Starting at the “Generic Filter” block, this diagram indicates that inherits the properties of a “Two-Port Network” (including its two ports) and “Linear Device” blocks. In addition, the “Generic Filter” block functionally and semantically representing a frequency selection device can be specialized in three other devices. The first is “Mid-Band Filter” representing bandpass and bandstop filters. The second is “Single-Side Filter” representing highpass and lowpass filters. The third is “Custom” block that captures complex-response filters (e.g., a dual-band filter).

The bdd of Figure 5.9 is detailed in the bdds of Figure 5.10 and Figure 5.11. The blocks of each of these diagrams are expanded. Except the leaf blocks (i.e., lowpass, highpass, bandpass and bandstop filter) having no specific value properties, the other blocks have four compartments:

- Values: It contains the block’s value properties. Each among these parameters has a given type that is defined in the “Value Types” package (illustrated in Figure 5.12);

- Default values: Some outstanding value properties are assigned to default values. These defaults are overridden by the values given in the specifications. If no values are specified, the defaults are considered in the design only if they do not cause any inconsistencies in coherence verification;
- Weights: The value properties to be considered in the selection process of a candidate design solution are assigned constant weights. Each weight indicates the importance of the corresponding value property (see section 4.3.5.c for theoretical background);
- Constraints: It is a set of rules that defines how the variable weights are calculated for each value property considered in the previous compartment.

It is worth noting that the generic bdd of Figure 5.9 is expanded in two detailed bdds (see Figure 5.10 and Figure 5.11) only for clarity.

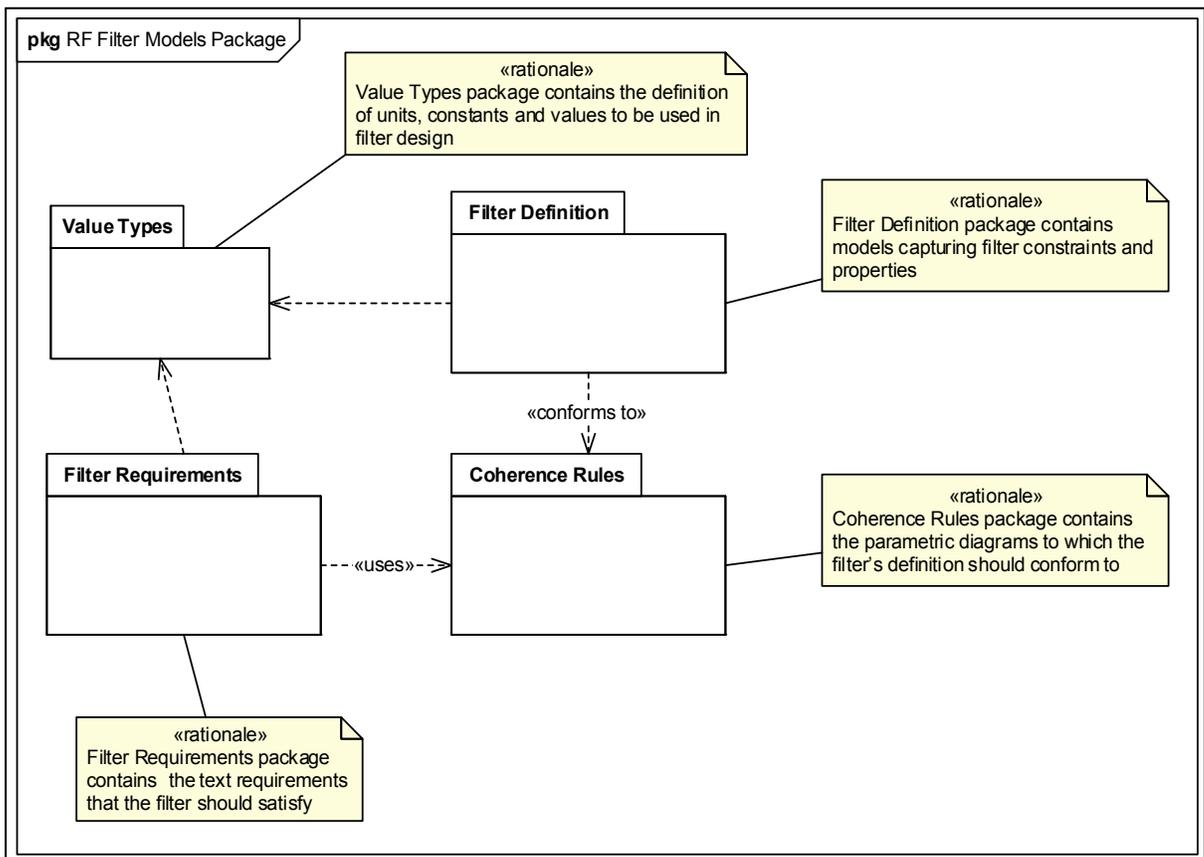


Figure 5.8 An overview of filter RM/PIM models developed in SysML

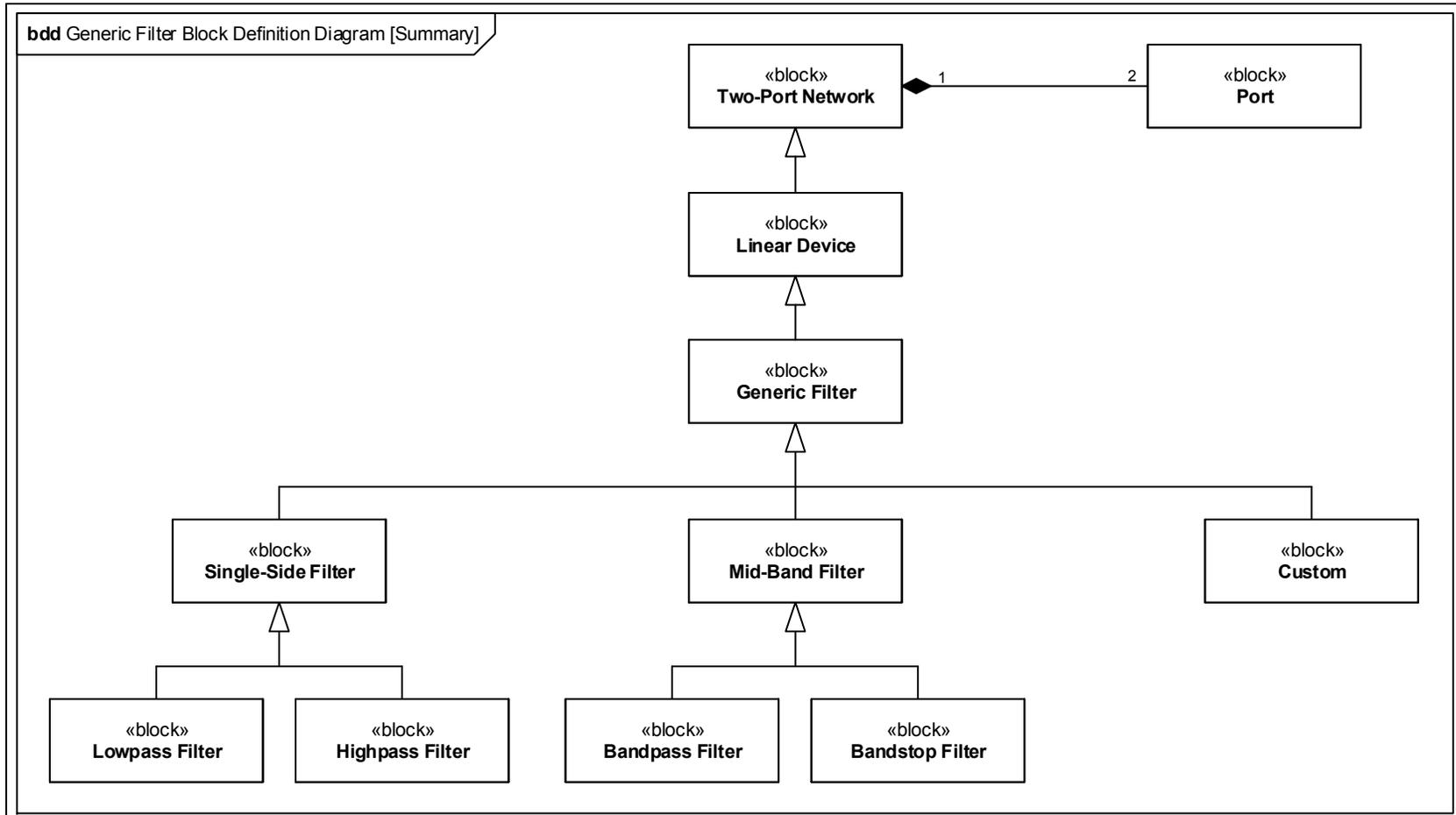


Figure 5.9 A filter is a two-port linear device

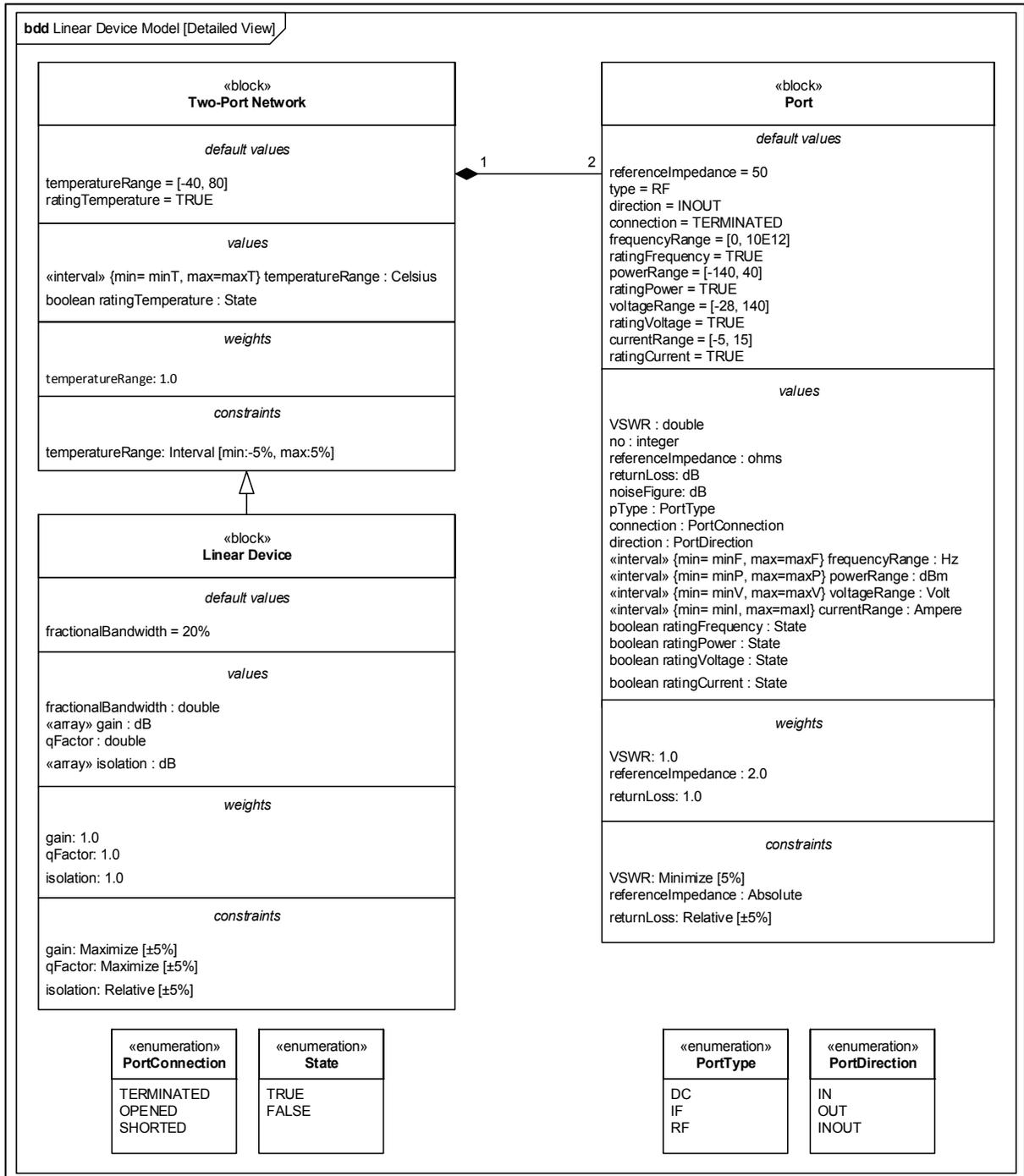


Figure 5.10 Linear device detailed block definition diagram

As previously mentioned, any block which represents a specialization of another one inherits its properties (i.e., values, default values, weights and constraints) including those constructed by a specific relationship with other blocks (e.g., composition relationship relating the “Two-

Port Network” block to its two ports). The complete list of a bandpass filter value properties are enumerated in Table 5.3 and Table 5.4.

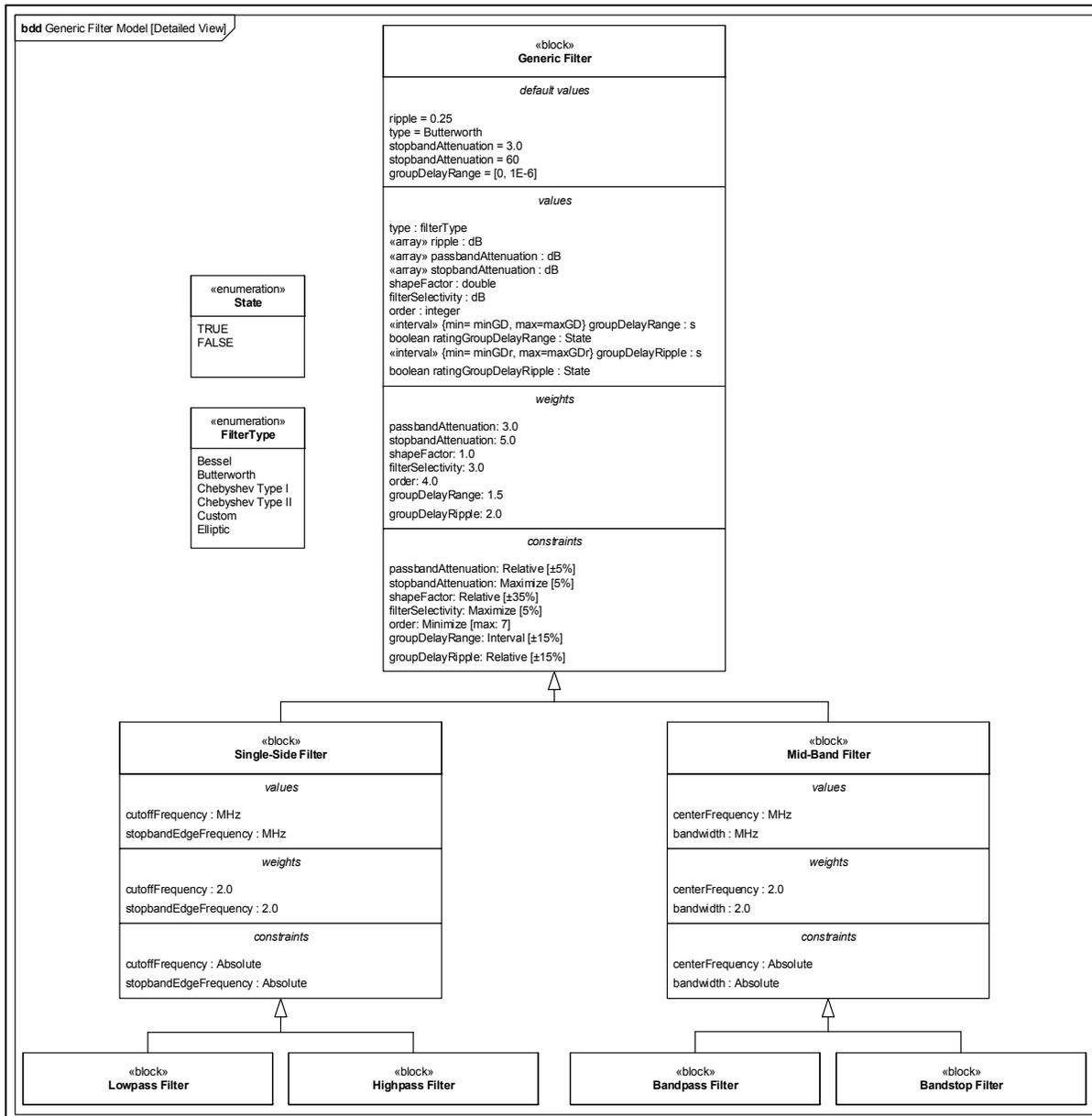


Figure 5.11 Generic filter detailed block definition diagram

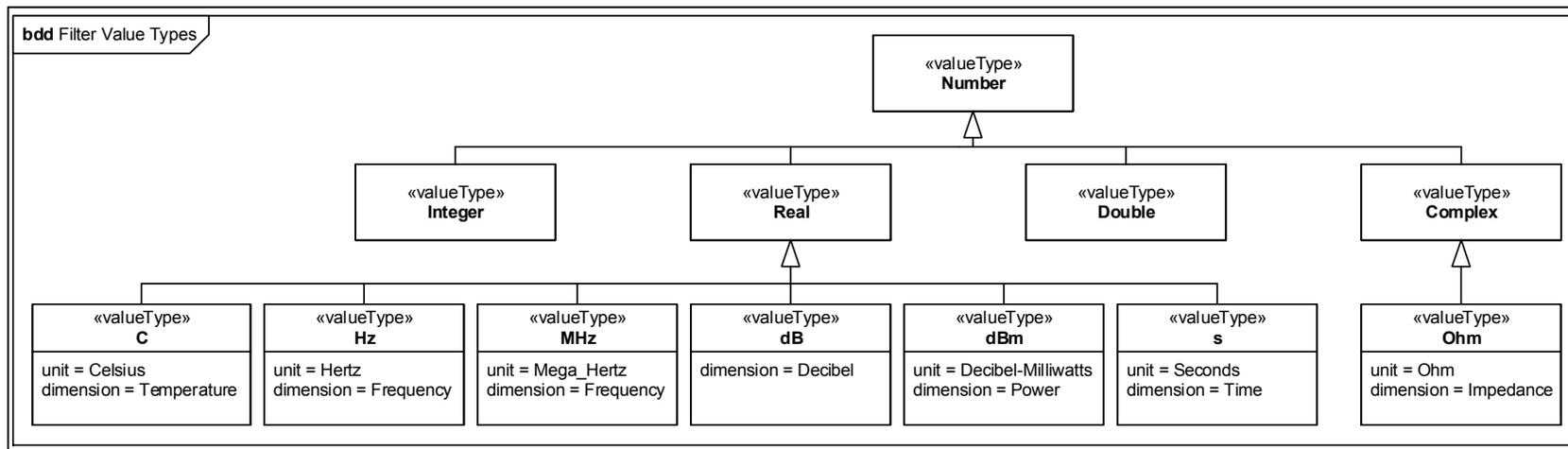


Figure 5.12 Value types captured in a bdd for the filter's RM/PIM models

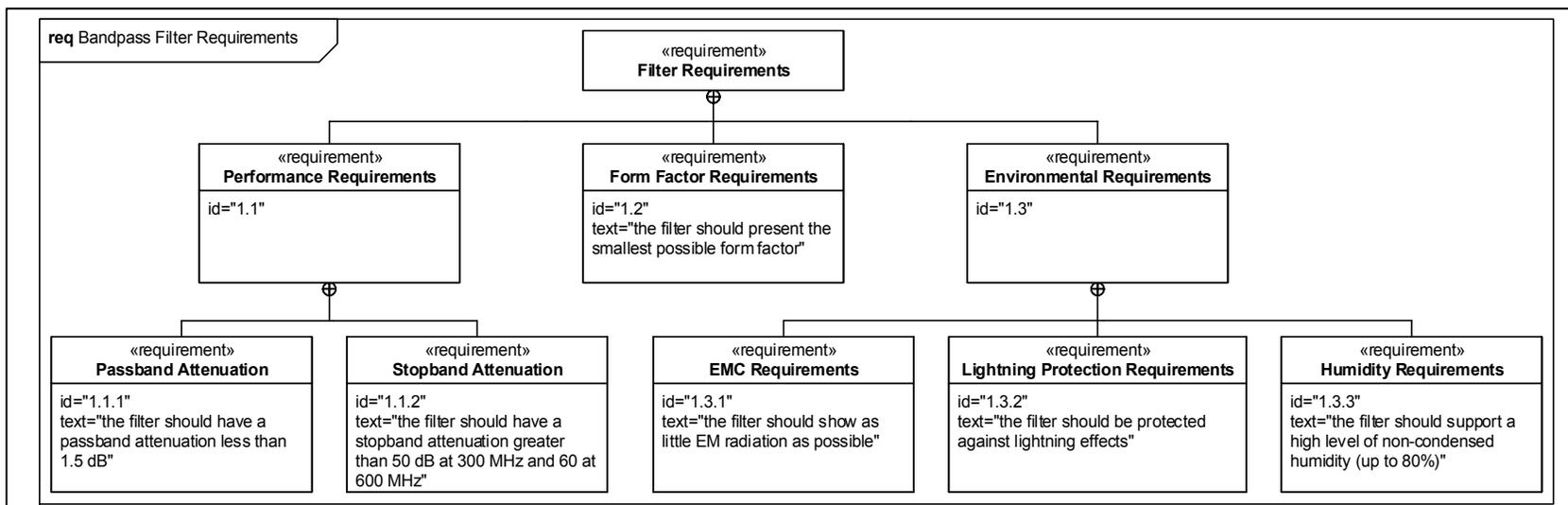


Figure 5.13 Detailed filter requirements diagram

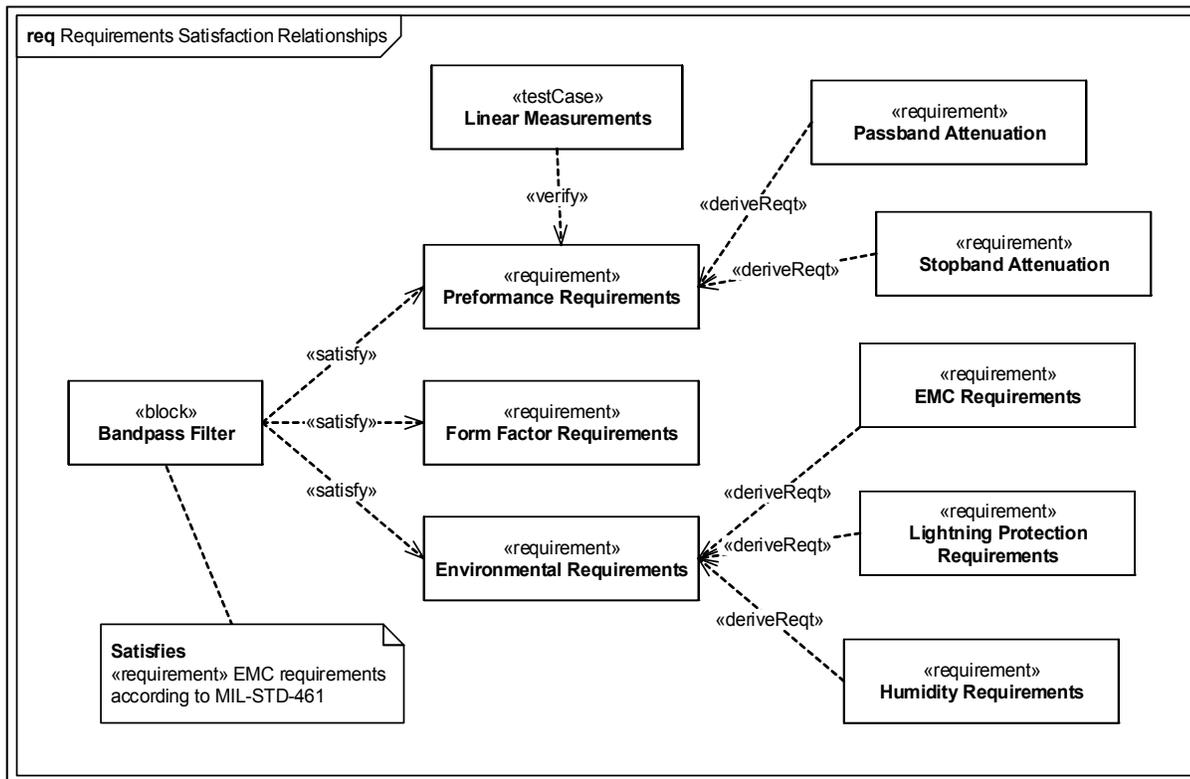


Figure 5.14 The bandpass filter might be explicitly associated to its requirements and testcases

Table 5.3 List of bandpass filter value properties as presented in the bdds of Figure 5.10 and 5.11

Value Property	Type	Default Value	Remarks	Specifications Value
temperatureRange	interval (Celsius)	[-40, 80]		
ratingTemperature	Boolean	TRUE	TRUE FALSE	
portList	Object (Port)			
portsNo	integer	2		
fractionalBandwidth	double	20%		13.34%
gain	array (dB)			Overridden by <i>passbandAttenuation</i> and <i>stopbandAttenuation</i>
qFactor	double			

Value Property	Type	Default Value	Remarks	Specifications Value
isolation	dB			Overridden by <i>filterSelectivity</i>
type	filterType	Butterworth	Bessel Butterworth Chebyshev Type I Chebyshev Type II Custom Elliptic	
ripple	array (dB)	0.25		
passbandAttenuation	array (dB)	3.0		
stopbandAttenuation	array (dB)	60.0		40.0 @300 MHz 50.0 @600 MHz
groupDelayRange	interval (seconds)	[0, 5E-6]		
ratingGroupDelay	Boolean		TRUE FALSE	
groupDelayRipple	interval (seconds)			
ratingGroupDelayRipple	Boolean			
order	integer			
shapeFactor	double			
filterSelectivity	dB			
centerFrequency	MHz			450.0
bandwidth	MHz			60.0

Table 5.4 List of bandpass filter port value properties as presented in the bdd of Figure 5.10

Value Property	Type	Default Value	Remarks	Specifications Value
VSWR	double			
no	integer			1 (2)
referenceImpedance	double (ohms)	50.0		50.0 (50.0)
returnLoss	dB			
noiseFigure	dB			

Value Property	Type	Default Value	Remarks	Specifications Value
pType	PortType	RF	DC IF RF	
direction	PortDirection	INOUT	IN OUT INOUT	
connection	PortConnection	TERMINATED	TERMINATED OPENED SHORTED	
frequencyRange	interval (Hz)	[0, 10E12]		
ratingFrequency	Boolean	TRUE	TRUE FALSE	
powerRange	interval (dBm)	[-140, 40]		
ratingPower	Boolean	TRUE	TRUE FALSE	
voltageRange	interval (Volts)	[-28, 140]		
ratingVoltage	Boolean	TRUE	TRUE FALSE	
currentRange	interval (Amperes)	[-5, 15]		
ratingCurrent	Boolean	TRUE	TRUE FALSE	

- **Filter requirements**

The specifications of the filter are not exclusively composed of properties that can be captured in the PIM structural models. It might also have additional requirements that cover other aspects of the filter operation (e.g., operation environment). These requirements (mostly text-based) can be captured using the SysML requirements diagram. For instance, the last row of Table 5.2 enumerates requirements related to the form factor of the bandpass filter and its operation environment conditions. The SysML requirements diagram allows visualizing these requirements in a comprehensive graphical hierarchy (see Figure 5.13). It enables also to associate the requirements as well as the corresponding testcases to each block using the

relevant relationships (see Figure 5.14). Such diagrams contribute significantly to better communication between designers and requirements traceability. All these diagrams are gathered in a SysML package (see Figure 5.15).

The requirements diagram of Figure 5.13 subdivides the filter requirements into three categories:

- Performance requirements: including passband and stopband attenuation specifications,
- Form Factor requirements: representing form factor constraints, and
- Environmental requirements: covering radiation and humidity operating conditions as well as lightning protection.

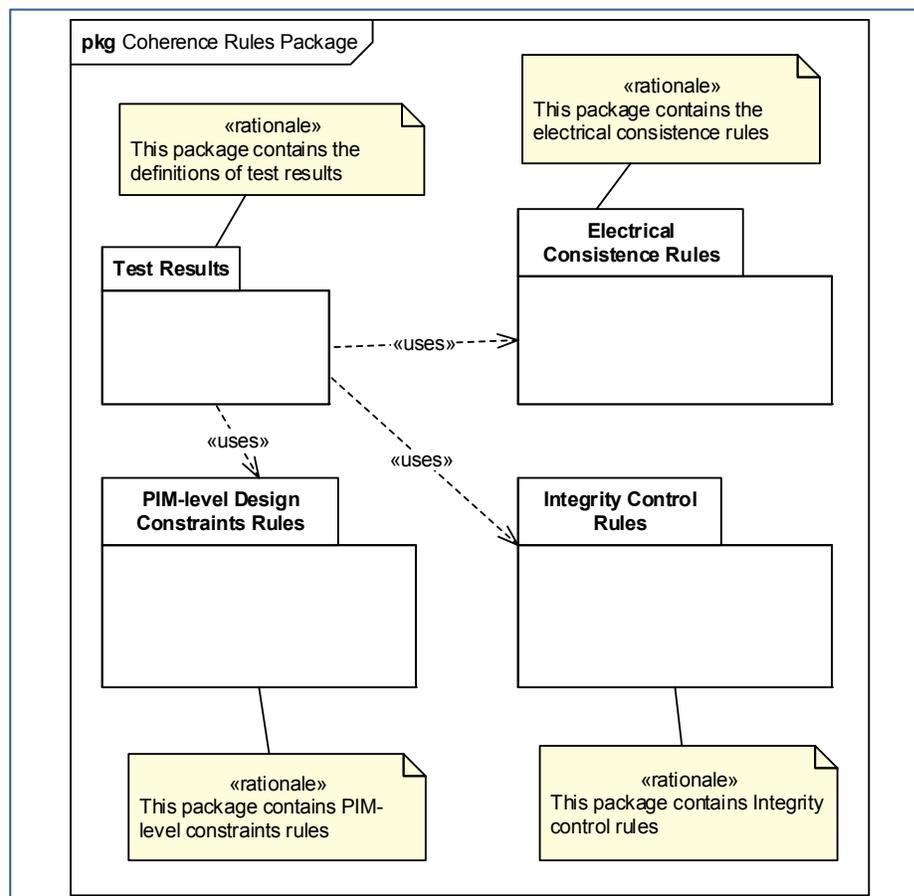


Figure 5.15 The bandpass filter coherence rules package consists of four interrelated sub-packages

As shown in Figure 5.14, the requirements can be associated to the filter blocks with specific relationships for validation and verification purposes. For example, the “*satisfy*” relationship means that the filter block should satisfy the indicated requirements. However, the “*verify*” relationship associates a testcase to a requirement.

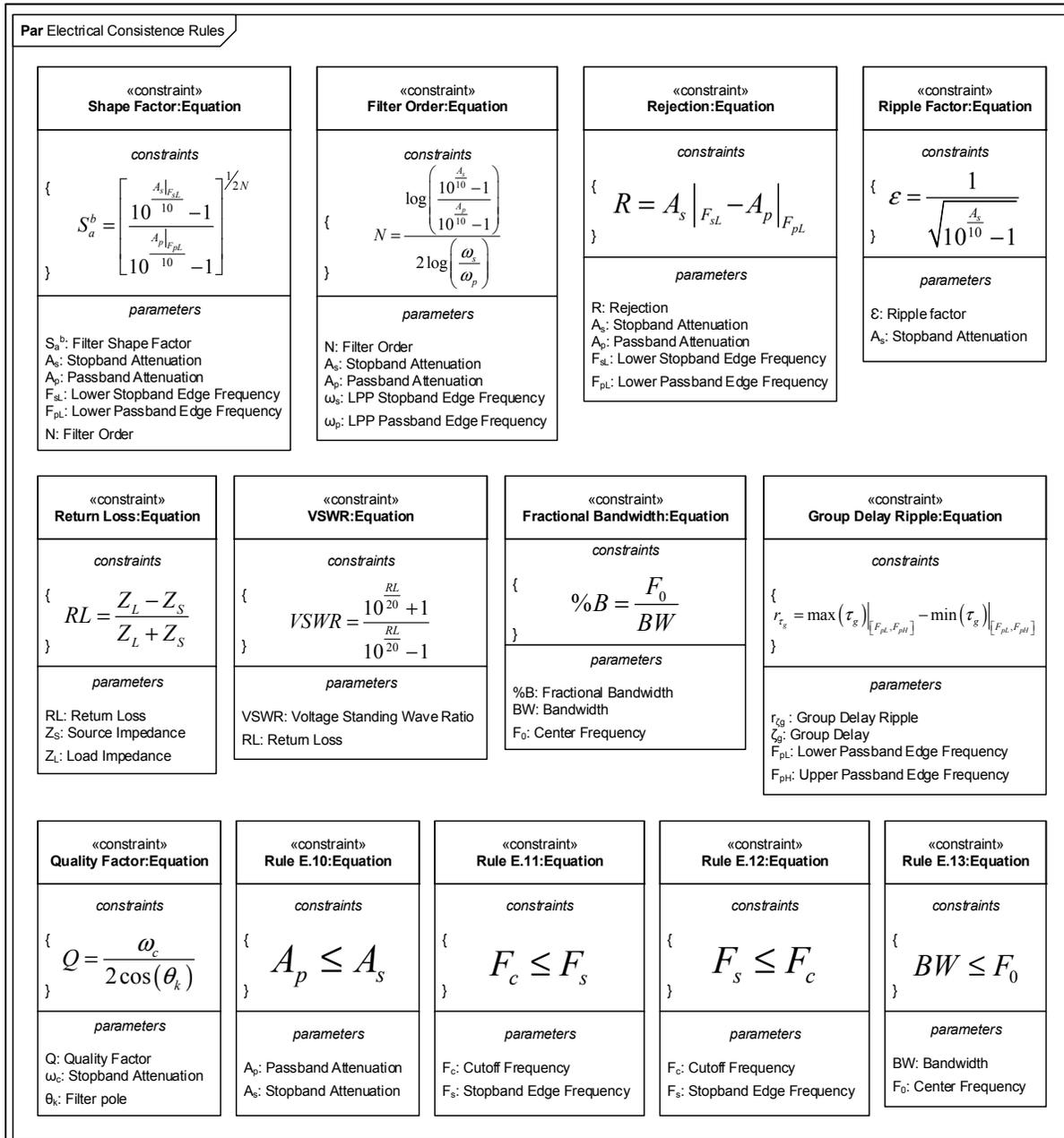


Figure 5.16 Electrical consistence rules illustrated in a parametric diagram

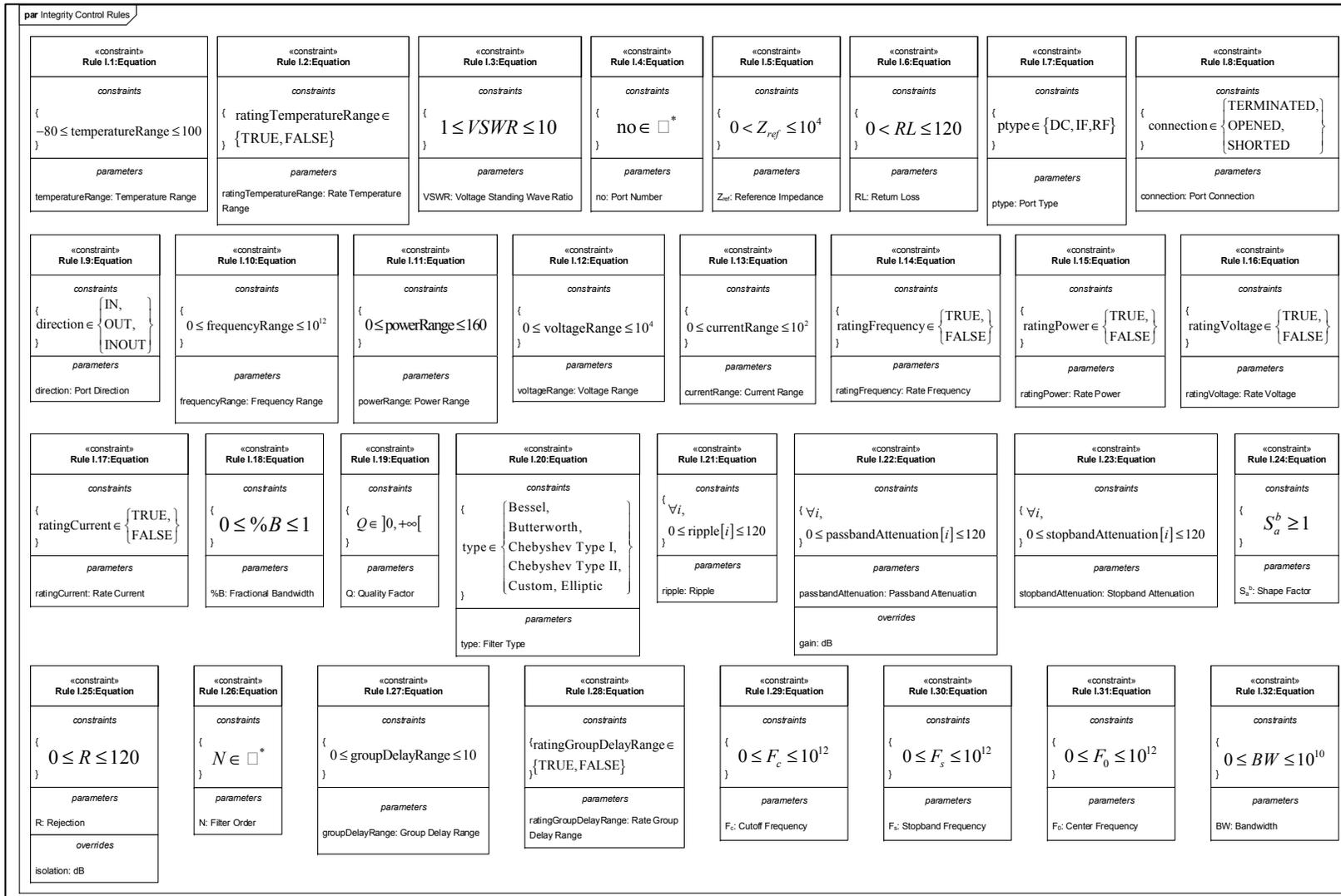


Figure 5.17 Integrity control rules captured using in a parametric diagram

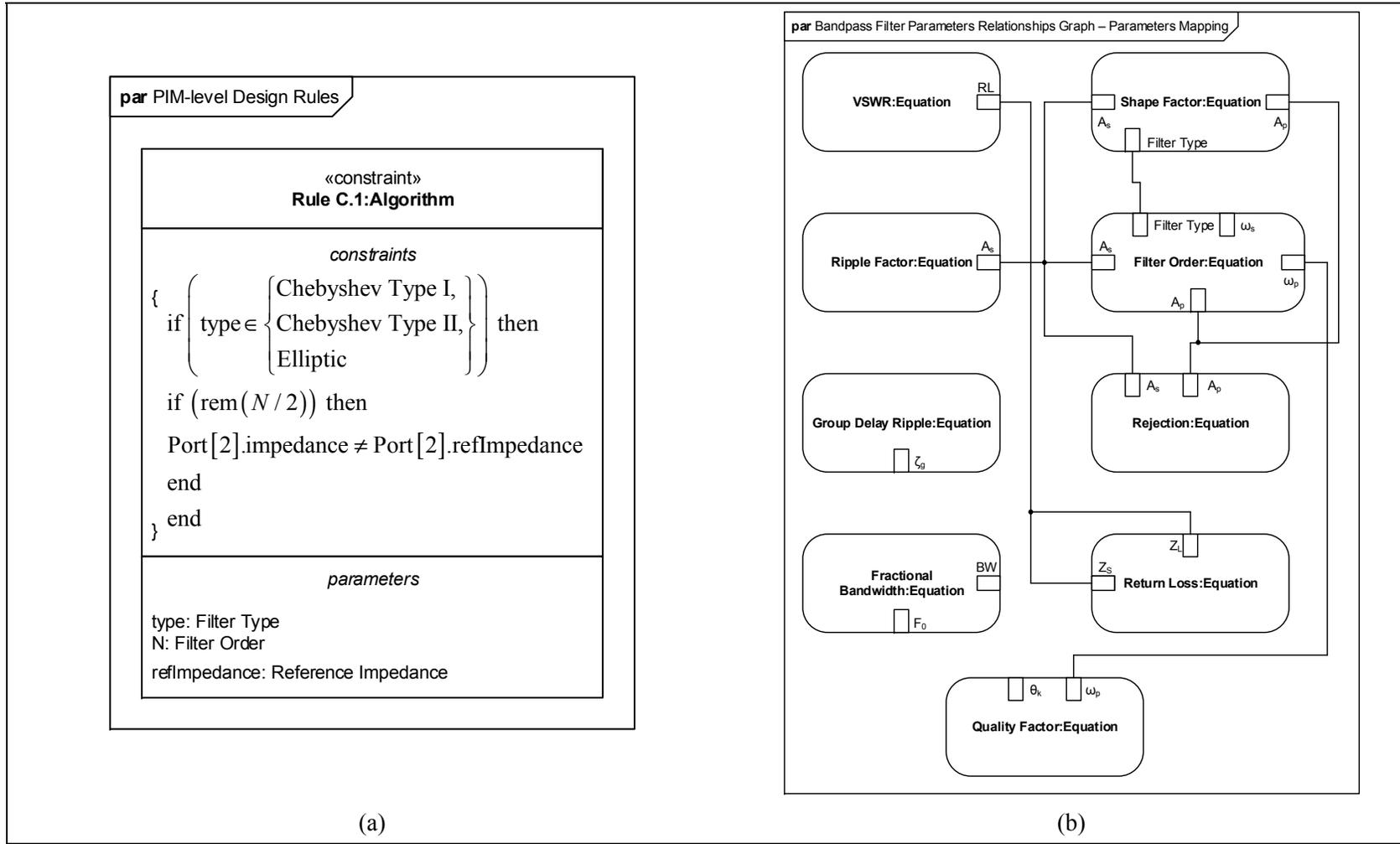


Figure 5.18 Parametric diagram has multiple uses (a) PIM-level design constraints, (b) Mapping of equations' parameters

- **PIM coherence rules**

The coherence rules are used to verify the consistency of the functional description. This input can either be provided within the RM/PIM or separately. In the case study, we include the coherence rules in SysML models. For this purpose, we use the parametric diagram to capture the various equations, algorithms and constraints.

The coherence rules captured in the parametric diagrams of Figure 5.16, Figure 5.17 and Figure 5.18 will be detailed in the next design stage.

**c) Functional Description: XML description**

SysML models developed in the previous design step are ideal for visualization but require to be saved in a comprehensive file format for exchange and automated processing. As discussed in sections 3.3.2 and 3.3.4, we use the standard language XML to format both models and design data.

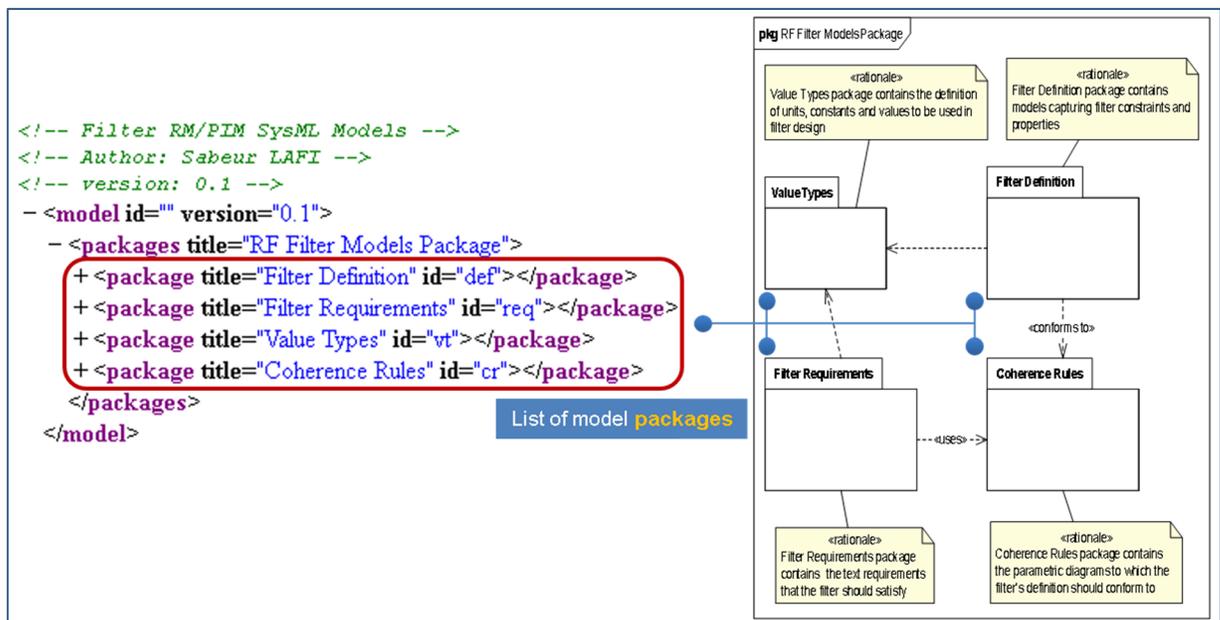


Figure 5.19 Overview of the RM/PIM's XML description file

- **RM/PIM description**

The models developed for the functional description of the bandpass filter are formatted in XML. The Figure 5.19 shows the resulting XML file. A branch of the XML tree is dedicated

to each modeling package (e.g., filter definition, filter requirements, coherence rules and value types).



Figure 5.20 The XML description corresponding to the “Filter Definition” package

As illustrated in Figure 5.20, the “Filter Definition” package is captured in the XML tag “package” whose title is “Filter Definition”. The hierarchy of blocks, their relationships and their multiplicity are transcribed using XML.

Figure 5.21 shows the XML structure capturing the “Filter Requirements” including the entire hierarchy of the requirements and their relationships. The color-shaded sections are mapped to

their corresponding blocks in the SysML model. Similarly, value types and coherence rules are faithfully transliterated using XML (see Figure 5.22 and Figure 5.23).

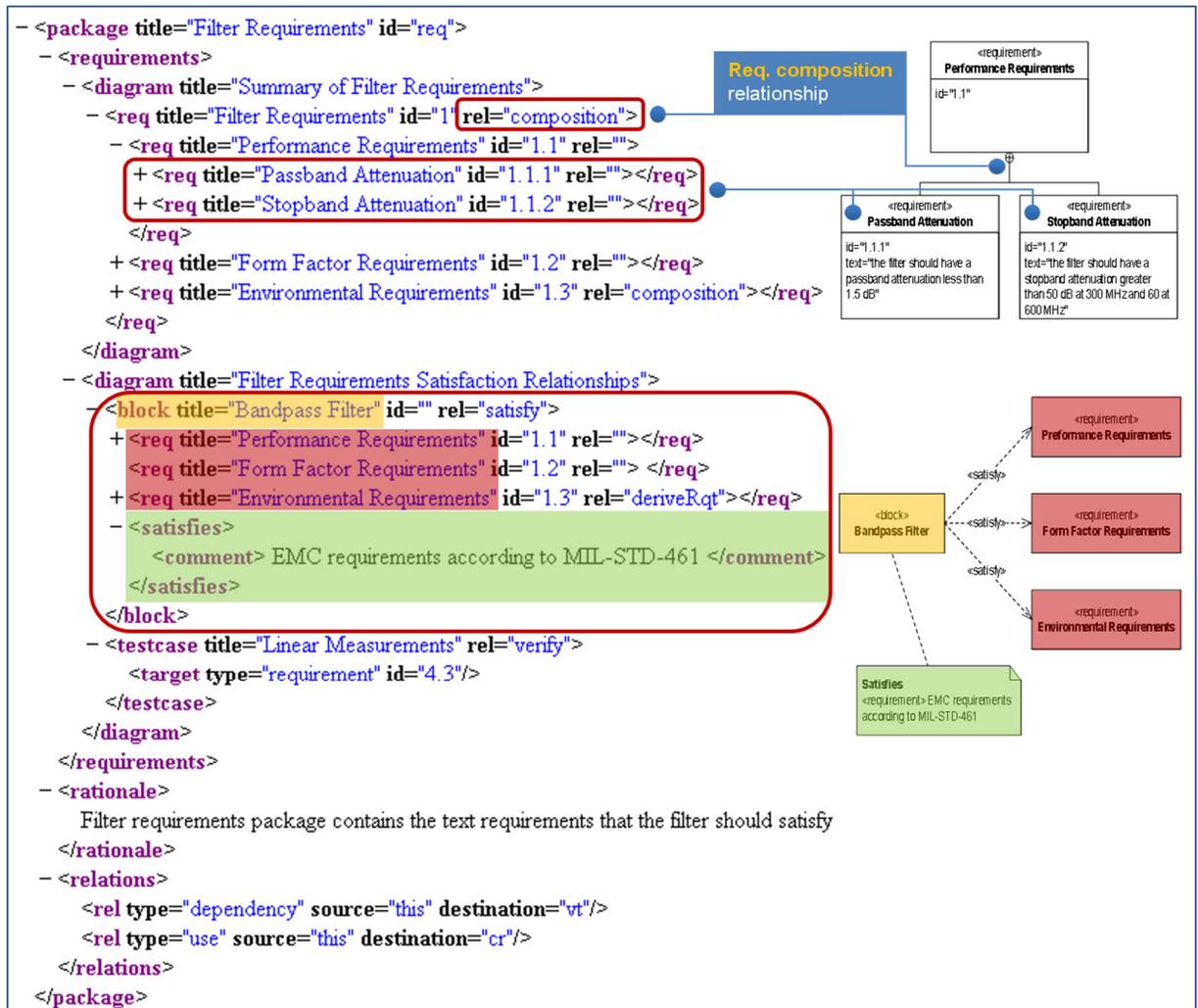
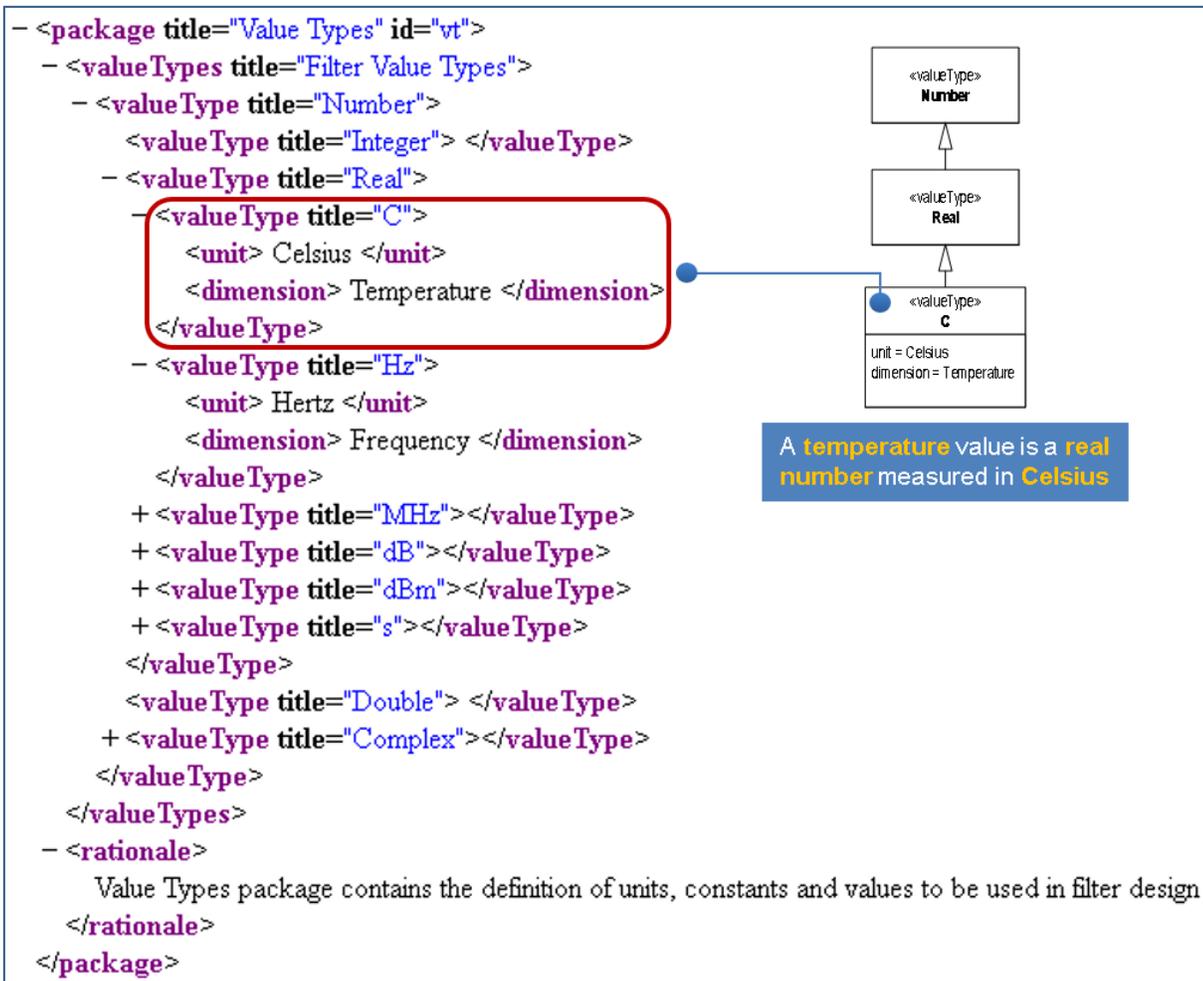


Figure 5.21 The XML description corresponding to the “Filter Requirements” package

- **Q-matrix creation**

Once the XML description is generated, the Q-matrix is created. Its initial version contains a QBlock that is populated with the electrical parameters captured in the functional description. At this level, there is no guarantee that the Q-matrix is coherent because the RM/PIMs are not yet submitted to coherence verification. That is why the Q-matrix should be also verified and updated if any errors are detected later in the stage of coherence verification.

As discussed in section 3.3.4, we use XML for the storage and exchange of the Q-matrix data. In general, the file resulting from Q matrix manipulation is voluminous because it is augmented at each design step with many data points. In this case, we show only some outstanding snippets of that file in order to illustrate how the Q-matrix evolves throughout the design cycle.



As illustrated in the equations (3.2)-(3.4) introducing the Q-matrix mathematical formalism, the data captured by the functional description should be streamlined in order to fit within that mathematical construction before it is inserted in the right QBlock. This is relatively easy to do for linear passive circuits (such as filters) because these devices are always characterized using the scattering parameters which fit directly within the Q-matrix definition.

```

- <package title="Coherence Rules" id="cr">
- <package title="Electrical Consistence Rules" id="cr1">
- <rationale>
  This package contains the electrical consistence rules
</rationale>
- <rulesList title="Electrical Consistence Rules">
- <rule name="Ripple Factor" id="E.1">
  <equation> epsilon = 1 / sqrt(10^(A_s/10)-1) </equation>
- <params>
  <parameter name="epsilon"> Ripple factor </parameter>
  <parameter name="A_s"> Stopband attenuation </parameter>
</params>
</rule>
+ <rule name="Rejection" id="E.2"></rule>
+ <rule name="Filter Order" id="E.3"></rule>
+ <rule name="Group Delay Ripple" id="E.4"></rule>
+ <rule name="Shape Factor" id="E.5"></rule>
+ <rule name="Fractional Bandwidth" id="E.6"></rule>
+ <rule name="Quality Factor" id="E.7"></rule>
+ <rule name="Return Loss" id="E.8"></rule>
+ <rule name="VSWR" id="E.9"></rule>
+ <rule name="Rule E.10" id="E.10"></rule>
+ <rule name="Rule E.11" id="E.11"></rule>
+ <rule name="Rule E.12" id="E.12"></rule>
+ <rule name="Rule E.13" id="E.13"></rule>
</rulesList>
</package>
+ <package title="PIM-level Design Constraints Rules" id="cr2"></package>
+ <package title="Integrity Control Rules" id="cr3"></package>
+ <package title="Test Results" id="cr4"></package>
- <rationale>
  Coherence Rules package contains the parametric diagrams to which the filter's definition should conform to
</rationale>
- <relations>
  <rel type="use" source="cr4" destination="cr1"/>
  <rel type="use" source="cr4" destination="cr2"/>
  <rel type="use" source="cr4" destination="cr3"/>
</relations>
</package>

```

$$\epsilon = \frac{1}{\sqrt{10^{\frac{A_s}{10}} - 1}}$$

Ripple Factor Equation

Relationships between packages

Figure 5.23 The XML description corresponding to the “Coherence Rules” package

In the XML snippet shown in Figure 5.24, a first QBlock named “bpf\_specs” is created. It holds the design data already provided in the specifications. In the configuration sub-block (i.e., “config”), the data type is assigned to “S” (i.e., scattering parameters) and format to “MA” (which stands for Magnitude/Angle). Then, the configuration related to each port (i.e., two ports for filters) is inserted as defined in the RM/PIM. In this case, some configuration parameters (e.g., port type and direction) are assigned to the default values given in the RM/PIM because the specifications do not provide explicit values for them. The next sub-block to be created is the data block. The time and temperature dimensions are set to “U” (i.e., unknown / unspecified) because both of them are still indefinite.

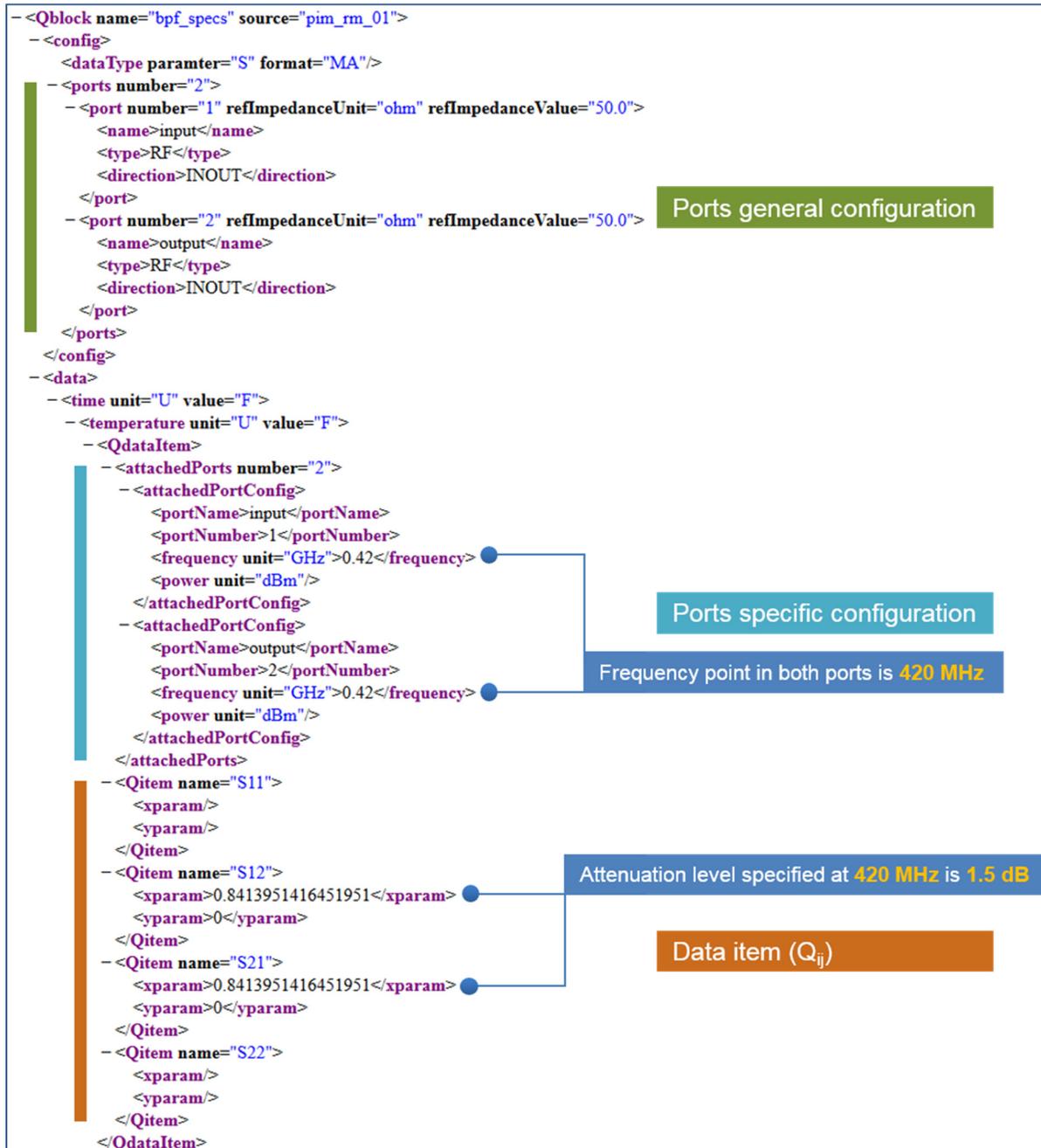


Figure 5.24 A snippet from the created Q-matrix showing initial electrical data item at 420 MHz

The sub-block “attached ports” captures the configuration of every port for each data item (i.e.,  $q_{ij}$ ). The XML snippet of Figure 5.24 shows only one data item. It specifies the filter’s frequency response at the lower passband edge (i.e., 420 MHz). For this reason, the frequency

parameter of input and output ports is set to 0.42 GHz. No power level was specified in the RM/PIM at this frequency for both ports, which explains why this parameter is void.

The attenuation level required at 420 MHz corresponds to the passband attenuation (i.e., equal to 1.5 dB<sup>90</sup>). That is why the transmission coefficients  $q_{12}$  and  $q_{21}$  (named “S12” and “S21” respectively) have a value equal to (0.841395, 0). The first refers to the magnitude while the second is the angle. Since the value of the required attenuation is real, the imaginary part of both coefficients is set zero. However, the reflection coefficients  $q_{11}$  and  $q_{22}$  (i.e., “S11” and “S22”) are void because there is no data specified for them. In case of the return loss value property in the port block is specified or assigned to a default value, it becomes mandatory to calculate  $q_{11}$  and  $q_{22}$  at this step.

This initial Q-matrix reflects only the electrical data already captured by the functional description (i.e., RIM/PIM). At this step, the Q-matrix is not complete and may be not coherent. It is mandatory to review the Q-matrix at the coherence verification step in order to avoid any errors. In the following design steps and stages, the Q-matrix continues to be populated with additional data from various sources.

#### **d) Analysis: Coherence verification**

The functional description and the Q-matrix have not been submitted so far to any kind of verification. Before starting the analysis step in order to find out an initial design solution meeting the requirements, a coherence verification test should take place. This process uses a set of coherence rules that are used to validate the consistency of the functional description. In this case study, these rules are part of the RM/PIM and not provided as a separate input. We used SysML parametric diagram to capture three types of coherence rules.

Let us first consider the following notations:

$N$      Filter order  
 $BW$     Bandwidth

---

<sup>90</sup> Mathematically speaking, an attenuation of 1.5 dB corresponds to a gain equal to -1.5 dB.

$\%B$	Fractional Bandwidth
$F_0$	Central Frequency
$F_c$	Cutoff Frequency
$F_s$	Stopband Edge Frequency
$S_a^b$	Shape Factor
$r$	ripple
$\tau_g$	Group Delay
$A_p$	Passband Attenuation
$A_s$	Stopband Attenuation
$R$	Filter Selectivity or Rejection
$Z_{ref}$	Reference Impedance
$Q$	Quality Factor
$RL$	Return Loss
$NF$	Noise Figure

- **Electrical consistence rules**

The electrical consistence rules check out the validity of the specified values regarding the relationships linking them. For the bandpass filter, we developed the parameters relationships graph (PRG) of Figure 5.25 in order to determine the links between its value properties. The equations of Table 5.5 illustrate these links. The parametric diagram of Figure 5.18.b illustrates how to map the same parameters in different equations for each rule. Such mapping avoids ambiguity when complex mathematical formalisms are involved. It is worth noting that the relationships given in Table 5.5 are not exhaustive. We enumerate the remaining ones in Table 5.6. The SysML parametric diagram of Figure 5.16 captures all these rules.

Table 5.5 Relationships between bandpass filter parameters given in Figure 5.24

Arrow Color	Mathematical Relationship	Parameter
●	$R = A_s _{F_{sL}} - A_p _{F_{pL}}$	Rejection (filter selectivity)
●	$N = \frac{\log\left(\frac{10^{\frac{A_s}{10}} - 1}{10^{\frac{A_p}{10}} - 1}\right)}{2\log\left(\frac{\omega_s}{\omega_p}\right)}$	Filter Order (Butterworth)
●	$\varepsilon = \frac{1}{\sqrt{10^{\frac{A_s}{10}} - 1}}$	Ripple Factor (Chebyshev)
●	$r_{\tau_g} = \max(\tau_g) _{[F_{pL}, F_{pH}]} - \min(\tau_g) _{[F_{pL}, F_{pH}]}$	Group Delay Ripple
●	$S_a^b = \left[ \frac{10^{A_s _{F_s}/10} - 1}{10^{A_p _{F_p}/10} - 1} \right]^{1/2N}$	Shape factor (Butterworth)
●	$Q = \frac{\omega_c}{2 \cos \theta_k}$	Quality Factor (Butterworth)
●	$\%B = \frac{F_0}{BW}$	Fractional Bandwidth
●	$VSWR = \frac{10^{\frac{RL}{20}} + 1}{10^{\frac{RL}{20}} - 1}$	Voltage Standing Wave Ratio
●	$RL = \frac{Z_L - Z_S}{Z_L + Z_S}$	Return Loss

Table 5.6 Main filter electrical consistence rules

No	Rule	if test fails
E.1	$A_p \leq A_s$	Error
E.2	For lowpass filter: $F_c \leq F_s$	Error
E.3	For highpass filter: $F_s \leq F_c$	Error
E.4	For bandpass and bandstop filters: $BW \leq F_0$	Warning

- **PIM-level design constraints**

These rules verify if the functional description leads to a non-feasible design solution. For this bandpass filter, a single PIM-level design constraint is considered. This rule is expressed by the algorithm of Table 5.7 that is captured in the parametric diagram Figure 5.18.a.

- **Integrity control rules**

This type of rules ensures that the RM/PIM value properties are within a predefined range in order to prevent errors. A set of 35 rules are considered to control the bandpass filter RM/PIM. These rules are enumerated in Table 5.8 and captured in the parametric diagram of Figure 5.17. The rules that are effectively used for the coherence verification of the bandpass filter are I.1 through I.31, I.34 and I.35. The rules I.32 and I.33 are used only for single-side filters.

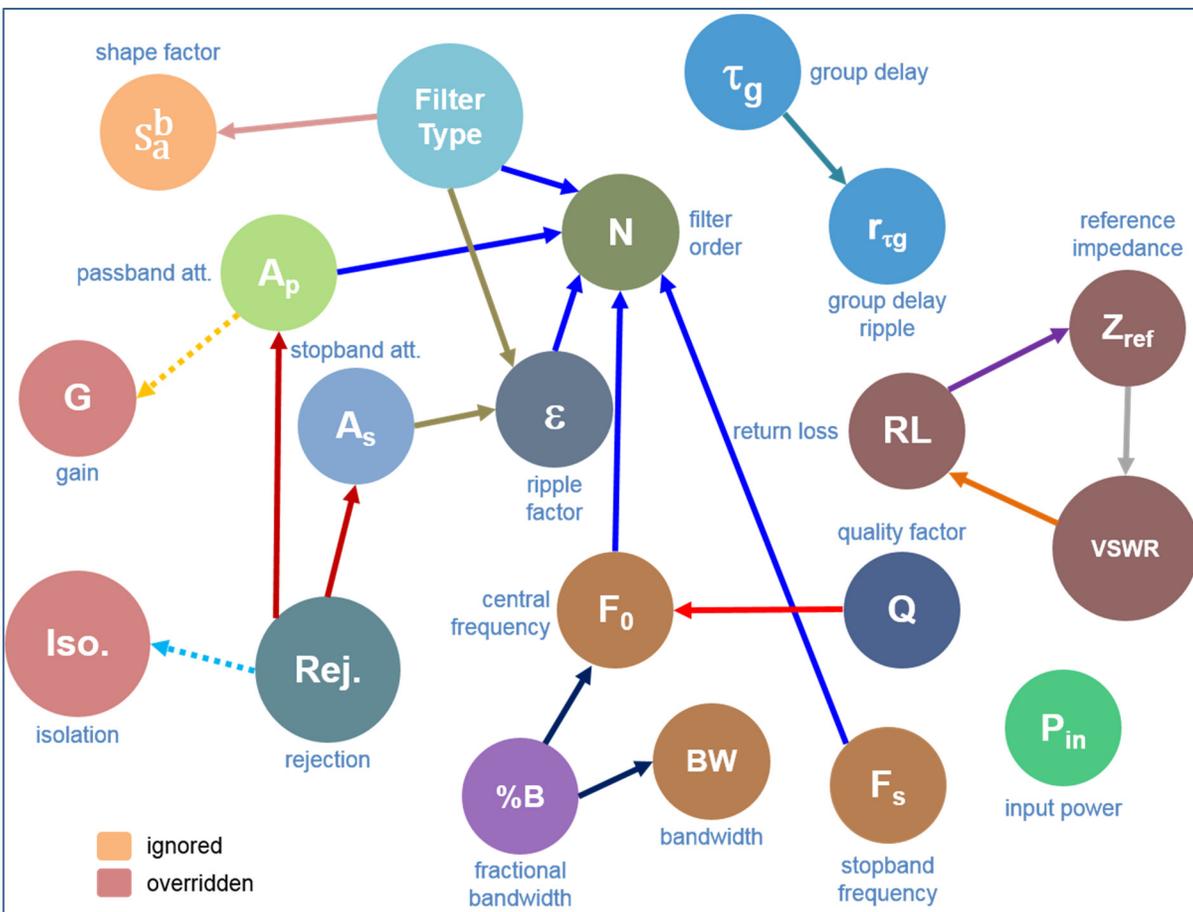


Figure 5.25 Bandpass filter parameters relationships graph

- **Coherence verification report**

After developing the functional description and the coherence rules of the bandpass filter, we made the test. As shown in Figure 5.26, the RM/PIM passes the coherence verification test. Consequently, there is no need to alter the RM/PIM and recreate the corresponding Q-matrix. The next step is the PIM analysis where one or many candidate design solutions should be figured out.

Table 5.7 Bandpass filter PIM-level design constraints rules

No	Rule	if test fails
C.1	if type $\in$ {Chebyshev Type I, Chebyshev Type II, Elliptic} then if rem(order/2) then Port[2].impedance $\neq$ Port[2].refImpedance end end	Error or Warning

Table 5.8 Bandpass filter integrity control rules

No.	Rule	if test fails
I.1	$-80 \leq \text{temperatureRange} \leq 100$	Error or/and Warning
I.2	ratingTemperatureRange $\in$ {TRUE,FALSE}	Error
I.3	$1 \leq \text{VSWR} \leq 10$	Error or/and Warning
I.4	no $\in \mathbb{N}^*$	Error
I.5	$0 < Z_{ref} \leq 10^4$	Error or/and Warning
I.6	$0 < RL \leq 120$	Error or/and Warning
I.7	$0 < NF \leq 100$	Error or/and Warning
I.8	pctype $\in$ {DC,IF,RF}	Error
I.9	connection $\in$ {TERMINATED,OPENED,SHORTED}	Error
I.10	direction $\in$ {IN,OUT,INOUT}	Error
I.11	$0 \leq \text{frequencyRange} \leq 10^{12}$	Error or/and Warning
I.12	$0 \leq \text{powerRange} \leq 160$	Error or/and Warning
I.13	$0 \leq \text{voltageRange} \leq 10^4$	Error or/and Warning
I.14	$0 \leq \text{currentRange} \leq 10^2$	Error or/and Warning
I.15	ratingFrequency $\in$ {TRUE,FALSE}	Error

No.	Rule	if test fails
I.16	ratingPower $\in$ {TRUE,FALSE}	Error
I.17	ratingVoltage $\in$ {TRUE,FALSE}	Error
I.18	ratingCurrent $\in$ {TRUE,FALSE}	Error
I.19	$0 \leq \%B \leq 1$	Error
I.20	$Q \in ]0, \infty[$	Error or/and Warning
I.21	type $\in$ {Bessel, Butterworth, Chebyshev Type I, Chebyshev Type II, Custom, Elliptic}	Error
I.22	$\forall i, 0 \leq \text{ripple}[i] \leq 120$	Error or/and Warning
I.23	$\forall i, 0 \leq \text{passbandAttenuation}[i] \leq 120$	Error or/and Warning
I.24	$\forall i, 0 \leq \text{stopbandAttenuation}[i] \leq 120$	Error or/and Warning
I.25	$S_a^b \geq 1$	Error
I.26	$0 \leq R \leq 120$	Error or/and Warning
I.27	$N \in \mathbb{N}_+^*$	Error
I.28	$0 \leq \text{groupDelayRange} \leq 10$	Error or/and Warning
I.29	ratingGroupDelayRange $\in$ {TRUE,FALSE}	Error
I.30	$0 \leq \text{groupDelayRipple} \leq 10$	Error or/and Warning
I.31	ratingGroupDelayRipple $\in$ {TRUE,FALSE}	Error
I.32	$0 \leq F_c \leq 10^{12}$	Error or/and Warning
I.33	$0 \leq F_s \leq 10^{12}$	Error or/and Warning
I.34	$0 \leq F_0 \leq 10^{12}$	Error or/and Warning
I.35	$0 \leq BW \leq 10^{10}$	Error or/and Warning

```

***** Coherence Verification Test *****
TARGET PIM: 450-MHz BANDPASS FILTER (C:\Users\slafi\Documents\Design\bpf450_pim.xml)

-> Electrical Consistence Rules (11 found)
..... PASS
-> PIM-level Design Constraints Rules (1 found)
..... PASS
-> Integrity Control Rules (33 found)
..... PASS
Summary: (0) Warnings (0) Errors
    
```

Figure 5.26 Bandpass filter coherence verification report

**e) Analysis: PIM-level granularity refinement and simulation**

At this step, the functional description passed the coherence verification test. We need to find out design solutions that meet the requirements of that functional description.

**• Design space exploration**

To figure out a candidate design solution that fits with the filter's functional description, we associate a black-box model to it (see section 4.3.3). This black-box model is mathematically defined by the equation (A III-1, p. 451) in APPENDIX III. Hence, the functional description provides an abstract representation of the filter functionality while the black-box model provides a theoretical realization of that functionality. From this viewpoint, the relationship between the functional description and the associated black-box model is similar (but not identical) to the relationship between a class and an object (i.e., an instantiation of that class) in object-oriented programming<sup>91</sup>.

We consider four traditional approximations for the filter transfer function on which the black-box model is based. These approximations are:

- Butterworth,
- Chebyshev Type I,
- Elliptic (aka Cauer), and
- Bessel.

The equations (A III-5, p. 452) and (A III-8, p. 452) in APPENDIX III give the transfer functions related to Butterworth and Chebyshev Type I approximations. The reader can refer to (Wanhammar, 2009) for a thorough dissertation about the mathematical background of all these approximations.

Based on the PIM, the analysis of the black-model (i.e., four filter prototypes) gives the frequency and group delay responses shown in Figure 5.27. The Table 5.9 shows a detailed comparison between the performances of these prototypes. This comparison is based on the

---

<sup>91</sup> See section 4.2.4.b.

requirements already captured in the filter's RM (see Figure 5.13) as well as the detailed block definition diagram capturing the filter's value properties, their weights and constraints (see Figure 5.10 and Figure 5.11). The metrics we consider in the following are:

- Form factor: expressed by the filter order,
- Performance: expressed by passband and stopband attenuation, rejection, group delay, frequency characteristics, output impedance and shape factor.

Based on the results reported in Figures 5.27, 5.28, 5.29, 5.30 and Table 5.9, the performance of some prototypes considered in the black-box model is relatively satisfactory. Then, we proceed directly to the selection of the best candidate design solution without performing granularity refinement.

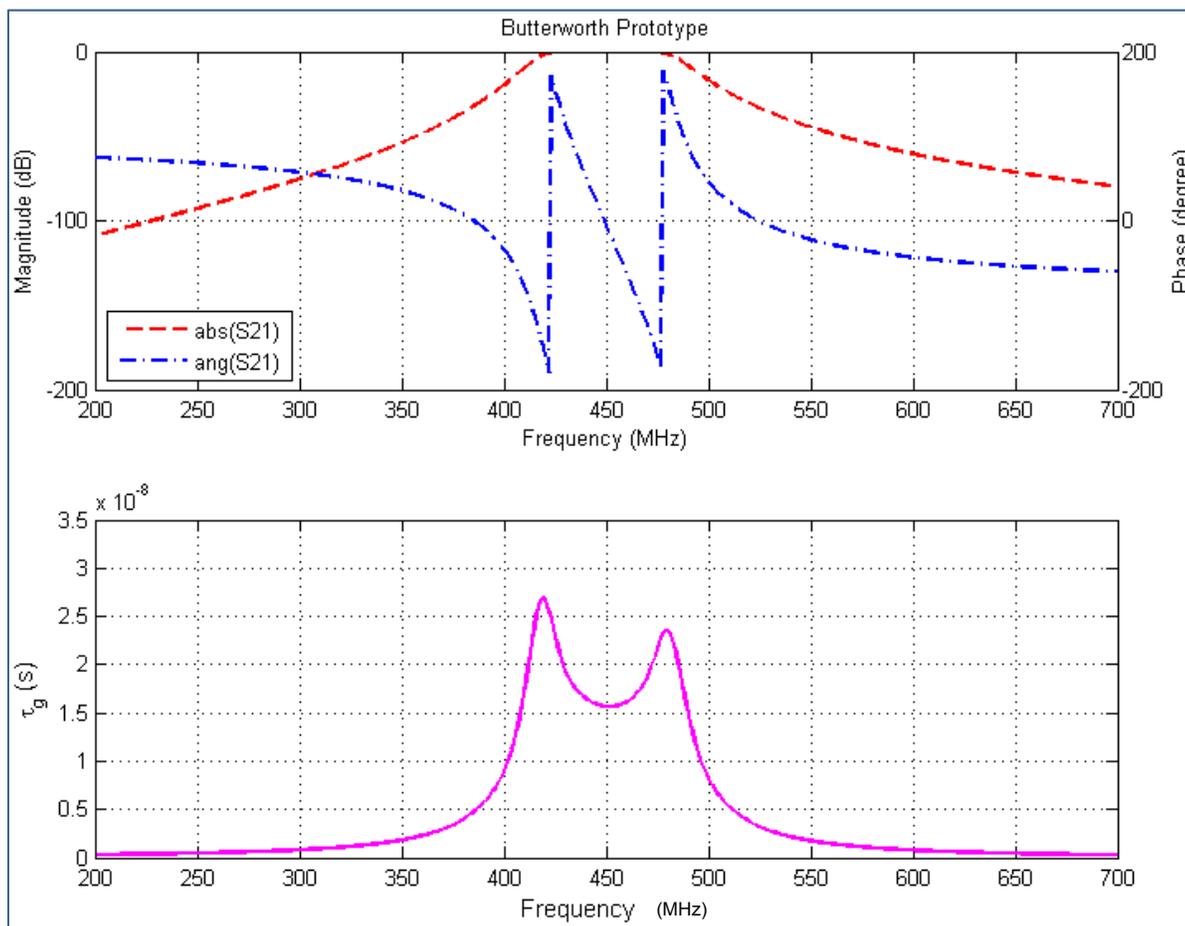


Figure 5.27 PIM analysis: Attenuation and group delay for Butterworth prototype

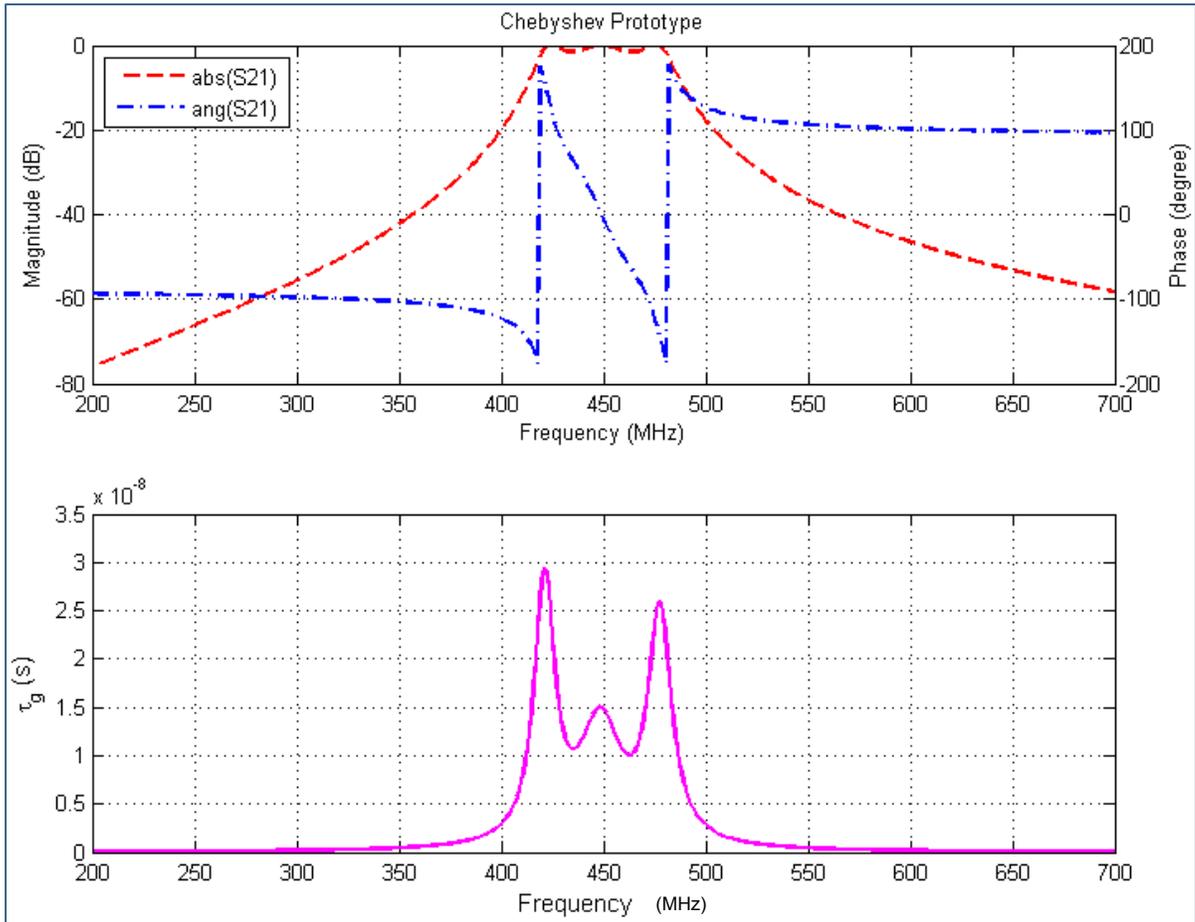


Figure 5.28 PIM analysis: Attenuation and group delay for Chebyshev type I prototype

- **Decision making: design solution selection**

Given the four candidate design solutions (i.e., filter prototypes), we proceed to the selection of the best one that fits with the filter's requirements. To do so, we use an objective function as discussed in section 4.3.5.c. The constant weight of each value property is already given in the "Generic Filter" bdd of Figure 5.11. The variable weights are calculated based on the property constraints given in the same bdd. The Table 5.10 summarizes the constant weights and property constraints of each decision variable while the Table 5.11 details the calculations of the objective function of each filter prototype.

As shown in Table 5.11, each filter prototype has its own objective function. Since we look for the maximum objective function, the best candidate solution found is the Butterworth approximation. Then, the Chebyshev Type I and Elliptic are respectively ranked second and

third with a small difference. This is because both approximations have similar response characteristics in the passband for the same filter order. The worst design solution is the Bessel prototype. It is the only prototype that has negative variable weights for stopband attenuation and rejection decision variables (i.e.,  $X_4$ ,  $X_5$ ,  $X_{12}$  and  $X_{13}$ ). This is mainly due to the significant gap between the prototype performance and the filter requirements.

This example shows that careful modeling of the functional description (such as providing weights and constraints) enables the automation of the decision making process and contributes to the enhancement of the automation level in the overall design cycle.

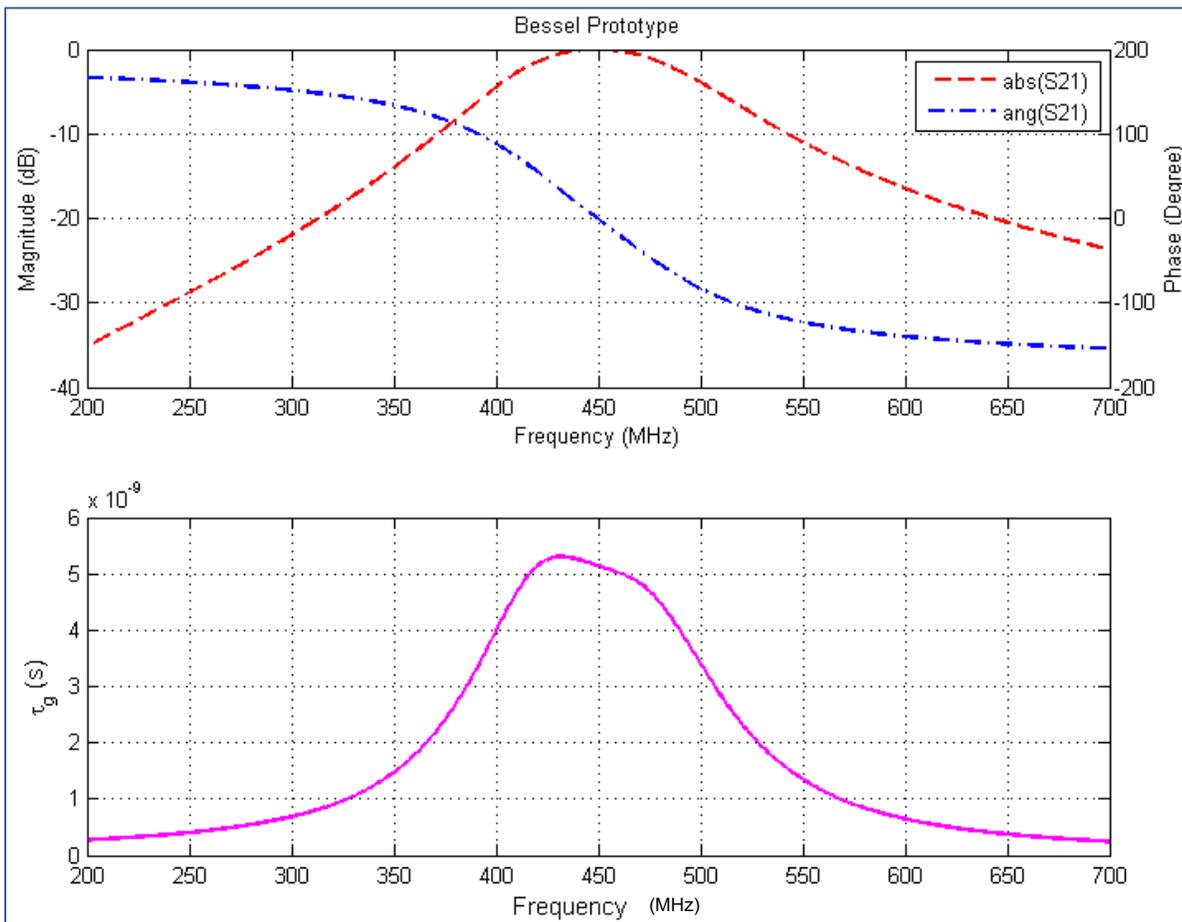


Figure 5.29 PIM analysis: Attenuation and group delay for Bessel prototype

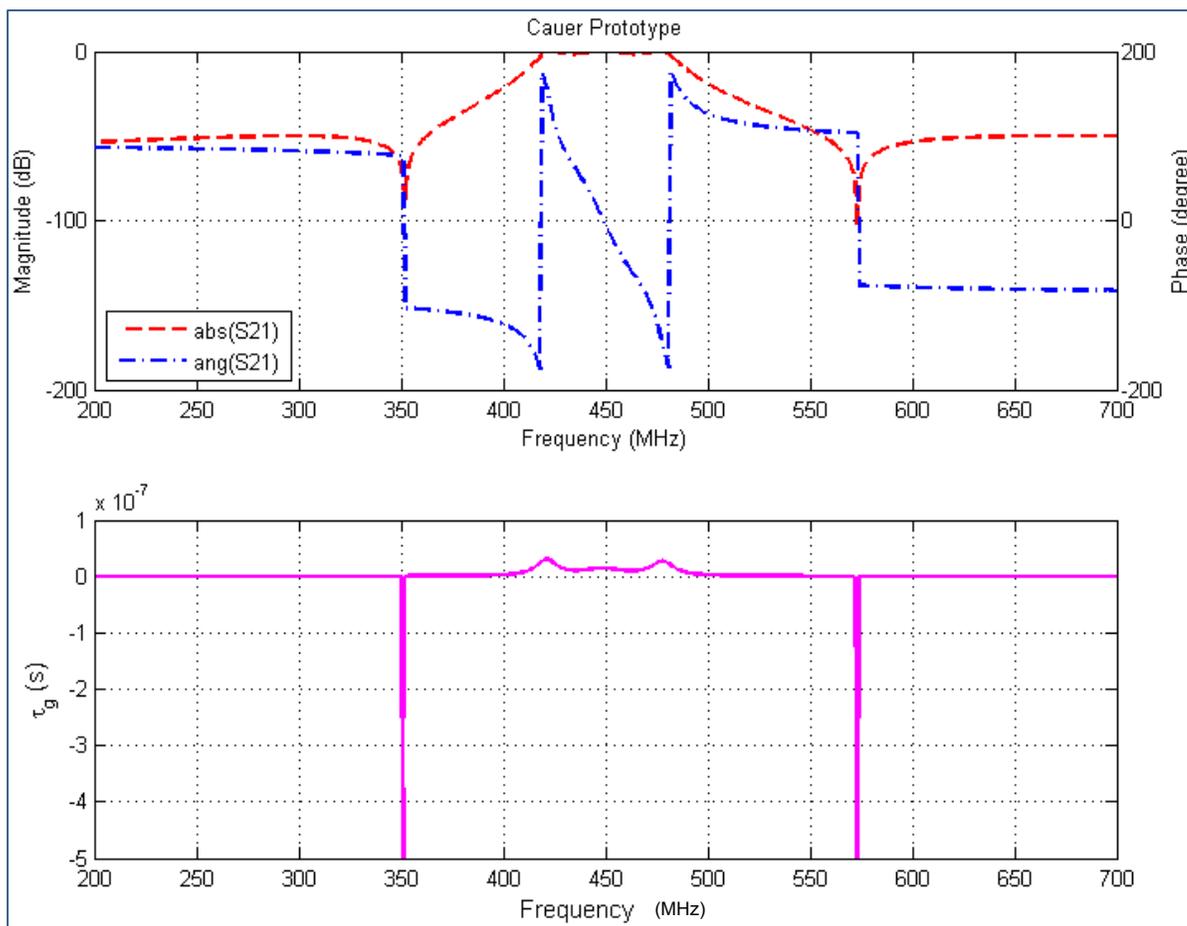


Figure 5.30 PIM analysis: Attenuation and group delay for Elliptic prototype

Table 5.9 Black-box model: performance summary of the four filter prototypes

		Butterworth	Chebyshev Type I	Bessel	Elliptic (Cauer)
<b>Filter Order (N)</b>		5	3	6	3
<b>Attenuation (dB)</b>	<b>300 MHz</b>	-75.394	-55.569	-22.006	-50.004
	<b>420 MHz</b>	-1.501	-1.501	-1.5	-1.501
	<b>450 MHz</b>	$-385.2 \cdot 10^{-6}$	-0.018	-0.002	$-356.5 \cdot 10^{-6}$
	<b>480 MHz</b>	-1.501	-1.501	-1.5	-1.501
	<b>600 MHz</b>	-60.5	-46.46	-16.437	-53.586
<b>Group Delay (s)</b>	<b>300 MHz</b>	$805.4 \cdot 10^{-12}$	$195.3 \cdot 10^{-12}$	$6.868 \cdot 10^{-10}$	$194.1 \cdot 10^{-12}$
	<b>420 MHz</b>	$26.73 \cdot 10^{-9}$	$28.31 \cdot 10^{-9}$	$5.132 \cdot 10^{-9}$	$29.62 \cdot 10^{-9}$
	<b>450 MHz</b>	$15.67 \cdot 10^{-9}$	$14.82 \cdot 10^{-9}$	$5.137 \cdot 10^{-9}$	$14.35 \cdot 10^{-9}$

		Butterworth	Chebyshev Type I	Bessel	Elliptic (Cauer)
	480 MHz	$23.48 \cdot 10^{-9}$	$22.88 \cdot 10^{-9}$	$4.49 \cdot 10^{-9}$	$23.97 \cdot 10^{-9}$
	600 MHz	$769.4 \cdot 10^{-12}$	$190.4 \cdot 10^{-12}$	$6.457 \cdot 10^{-10}$	$189 \cdot 10^{-12}$
	Maximum group delay ripple over passband	$11.07 \cdot 10^{-9}$	$19.35 \cdot 10^{-9}$	$8.125 \cdot 10^{-10}$	$20.74 \cdot 10^{-9}$
Rejection (dB)	$R_L = A_s _{F_{sL}} - A_p _{F_{pL}}$	73.893	54.068	20.506	48.503
	$R_H = A_s _{F_{sH}} - A_p _{F_{pH}}$	58.999	44.959	14.937	52.085
Passband Bandwidth (MHz)	$BW$	60	60	60	60
Central Frequency (MHz)	$F_0$	450	450	450	450
Reference Impedance ( $\Omega$ )	$Z_{ref}$	50	50	50	50
Shape Factor	$S_a^b = \frac{\Delta BW_{60dB}}{\Delta BW_{6dB}}$	3.53	6.38	109.26	6.64

#### f) Analysis: PSM generation

After the selection of the best PIM-level design solution among the four filter prototypes (i.e., black-box model), we proceed to the transformation of that solution into a PSM-level solution.

Table 5.10 Constant weights and property constraints for each decision variable

	Value Property (X)	$i$	Constant weights $C_i$	Property Constraint
Filter order	N	1	4.0	Variable minimization (i.e., due to small form factor requirement)
Passband Attenuation (dB)	$A_p @ 420 \text{ MHz}$	2	3.0	Relative specification
	$A_p @ 480 \text{ MHz}$	3	3.0	Relative specification
Stopband Attenuation (dB)	$A_s @ 300 \text{ MHz}$	4	5.0	Variable maximization
	$A_s @ 600 \text{ MHz}$	5	5.0	Variable maximization
Group Delay (s)	$g_d @ 300 \text{ MHz}$	6	1.5	Relative specification
	$g_d @ 420 \text{ MHz}$	7	1.5	Relative specification
	$g_d @ 450 \text{ MHz}$	8	1.5	Relative specification
	$g_d @ 480 \text{ MHz}$	9	1.5	Relative specification
	$g_d @ 600 \text{ MHz}$	10	1.5	Relative specification
	$r_{g_d} = \max(g_d) _{[F_{pL}, F_{pH}]}$	11	2.0	Relative specification
Rejection (dB)	$R_L = A_s _{F_{sL}} - A_p _{F_{pL}}$	12	3.0	Variable minimization
	$R_H = A_s _{F_{sH}} - A_p _{F_{pH}}$	13	3.0	Variable maximization
Passband Bandwidth (MHz)	$BW$	14	2.0	Absolute specification
Central Frequency (MHz)	$F_0$	15	2.0	Absolute specification

	Value Property (X)	$i$	Constant weights $C_i$	Property Constraint
Reference Impedance ( $\Omega$ )	$Z_{ref}$	16	2.0	Absolute specification
Shape Factor	$S_a^b = \frac{\Delta BW_{60dB}}{\Delta BW_{6dB}}$	17	1.0	Relative specification

- **PIM-to-PSM transformation**

To transform the PIM-level Butterworth filter prototype into a PSM-level lumped-component filter circuit, we use a model-to-model (i.e., PIM-to-PSM) transformation. For this purpose, Table 5.12 suggests a cross-view transformation that consists of three consecutive steps:

- 1. Step 1: Calculation of the normalized values for filter resonators**

The first task is the calculation of the lowpass prototype normalized values. To do so, a frequency transformation should take place in order to determine the lowpass prototype frequency characteristics based on their bandpass filter counterparts. Then, the normalized values  $g_k$  for each resonator (i.e.,  $N$ ) are calculated using the equations (A III-6, p. 452) and (A III-7, p. 452) in APPENDIX III for Butterworth approximation. The resonators  $X_k$  are calculated using the equations (A III-12, p. 454) and (A III-13, p. 454).

- 2. Step 2: Calculation of lumped elements values**

Given the values of resonators, the corresponding lumped components are computed after impedance and frequency scaling (using equations (A III-14, p. 455) and (A III-15, p. 455)). This results in a lowpass lumped-component filter that requires a lowpass to bandpass frequency transformation (as given in equation (A III-16, p. 456) and Table-A III-1, p. 454). Thus, we obtain a first PSM that is an ideal lumped-component bandpass filter. Its circuit schematic is shown in Figure 5.31.a. The corresponding performance assessment (in terms of attenuation and group delay responses) is illustrated in Figure 5.31.b.

### **3. Step 3: Synthesis of transmission lines and circuit topology**

The PSM generated in step 2 satisfies the requirements of the functional description. However, it is still not practically realizable because there are no physical connections between the lumped components. In step 3 of the PIM-to-PSM transformation, we alter the topology of each resonator (as illustrated in Figure 5.32.a and Figure 5.32.b) in order to physically connect each lumped component to the others. This takes place by adding several sections of planar transmission lines. The final PSM circuit is shown in Figure 5.33.

Table 5.11 Objective function calculations for each filter prototype

Decision variables	Constant weights $C_i$	Variable weights $X_i$				Weights $C_i \cdot X_i$			
		Butterworth	Chebyshev Type I	Bessel	Elliptic	Butterworth	Chebyshev Type I	Bessel	Elliptic
$X_1$	4.0	0.2	0.3334	0.1667	0.3334	0.8	1.3336	0.6668	1.3336
$X_2$	3.0	1.0007	1.0007	1	1.0007	3.0021	3.0021	3	3.0021
$X_3$	3.0	1.0007	1.0007	1	1.0007	3.0021	3.0021	3	3.0021
$X_4$	5.0	1.88485	1.389225	-0.39985	1.2501	9.42425	6.946125	-1.99925	6.2505
$X_5$	5.0	1.21	0.9292	-0.62126	1.07172	6.05	4.646	-3.1063	5.3586
$X_6$	1.5	1	1	1	1	1.5	1.5	1.5	1.5
$X_7$	1.5	1	1	1	1	1.5	1.5	1.5	1.5
$X_8$	1.5	1	1	1	1	1.5	1.5	1.5	1.5
$X_9$	1.5	1	1	1	1	1.5	1.5	1.5	1.5
$X_{10}$	1.5	1	1	1	1	1.5	1.5	1.5	1.5
$X_{11}$	2.0	0	0	0	0	0	0	0	0
$X_{12}$	3.0	1.9193	1.4044	-0.4174	1.2598	5.7579	4.2132	-1.2522	3.7794
$X_{13}$	3.0	1.2165	0.927	-0.642	1.0739	3.6495	2.781	-1.926	3.2217
$X_{14}$	2.0	1	1	1	1	2	2	2	2
$X_{15}$	2.0	1	1	1	1	2	2	2	2
$X_{16}$	2.0	1	1	1	1	2	2	2	2
$X_{17}$	1.0	0	0	0	0	0	0	0	0
Objective Function $F(n) = \sum C_i X_i$						<b>45.18585</b>	<b>39.424125</b>	<b>11.88305</b>	<b>39.448</b>

Table 5.12 PIM-to-PSM transformation (target platform: LC/distributed lines)

<p><b>Step 1: Calculation of resonators normalized values</b></p> <p>1.1. Calculate lowpass prototype (LPP) normalized values (<math>g_k</math>) for the response approximation</p> <p>1.2. Calculate corresponding resonator values (<math>X_k</math>)</p> <p><b>Step 2: Calculation of corresponding lumped elements' values</b></p> <p>2.1. Perform impedance scaling</p> <p>2.2. Perform frequency scaling</p> <p>2.3. Perform frequency transformation</p> <p><b>Step 3: Synthesis of transmission lines and circuit topology</b></p> <p>3.1.a. For each series resonator: Create topology as depicted in Figure 5.32.a</p> <p>3.2.b. For each parallel resonator: Create topology as depicted in Figure 5.32.b</p> <p>3.3. For each transmission line: Consider the properties given in the following:</p> $\begin{cases} Z_{ci} = Z_{reference} \\ E_i = E_{default} \\ F_i = F_0 \\ A_i = A_{default} \end{cases}$ <p>where <math>Z_{ci}</math> is the characteristic impedance of the transmission line, <math>E_i</math> is its electrical length, <math>F_i</math> is the frequency at which the electrical length is calculated and <math>A_i</math> is the transmission line loss (in dB).</p>
---

- **PSM performance assessment**

The step 3 of the PIM-to-PSM transformation generates a physically realizable PSM (see circuit schematic in Figure 5.33.a). After linear simulation, the PSM's frequency response is shown in Figure 5.34. It is obvious that this frequency response does not satisfy the functional description requirements. This is because of the transmission-line sections added to connect the lumped components together. The physical properties of these sections already not accounted at the PIM level while considered at the PSM level degraded the solution's overall performance. Despite the several optimization iterations carried out to enhance the obtained PSM's performance, we did not succeed to enhance significantly its frequency response.

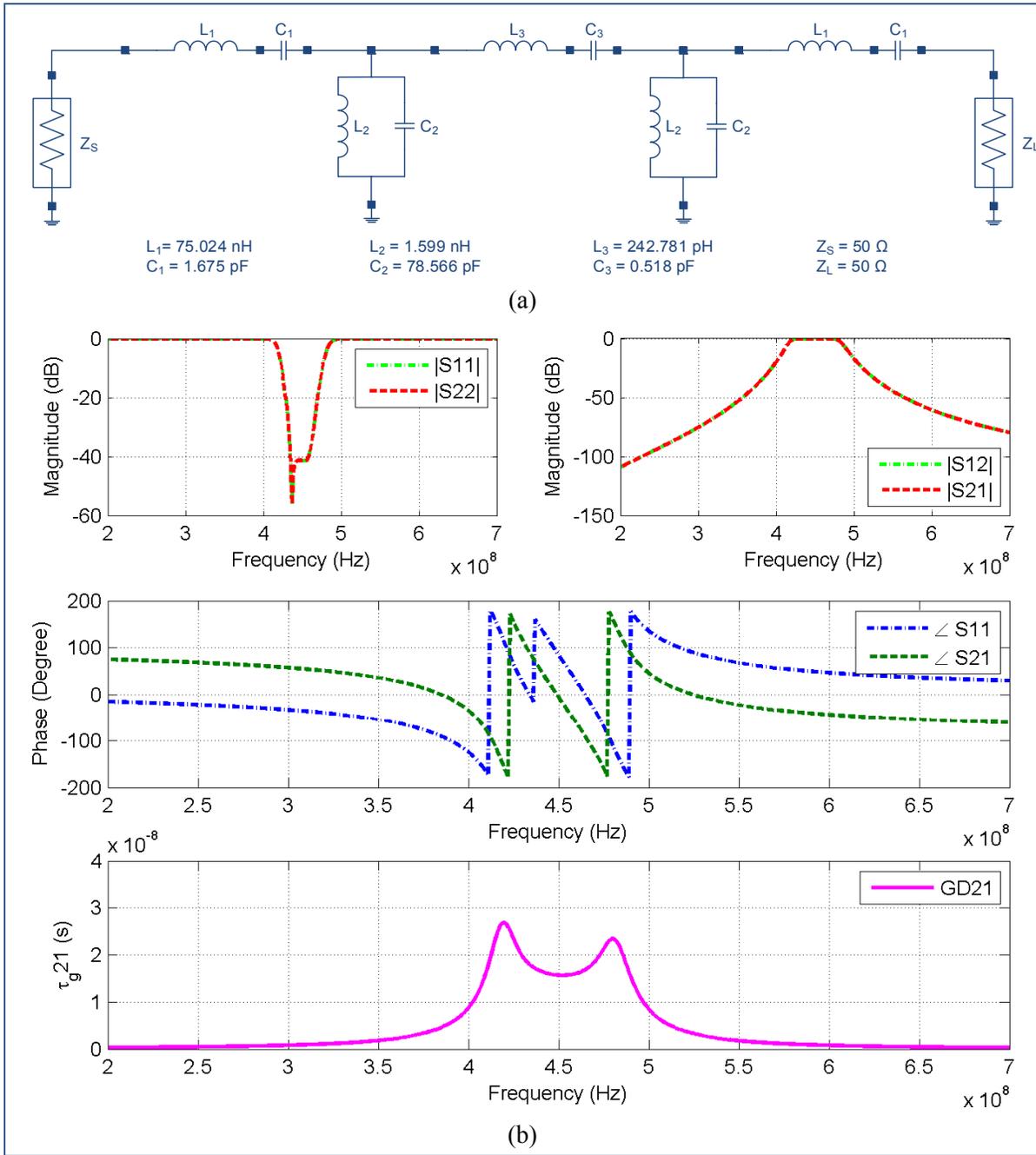


Figure 5.31 Transformation (step 2): (a) the LC model and its (b) frequency response

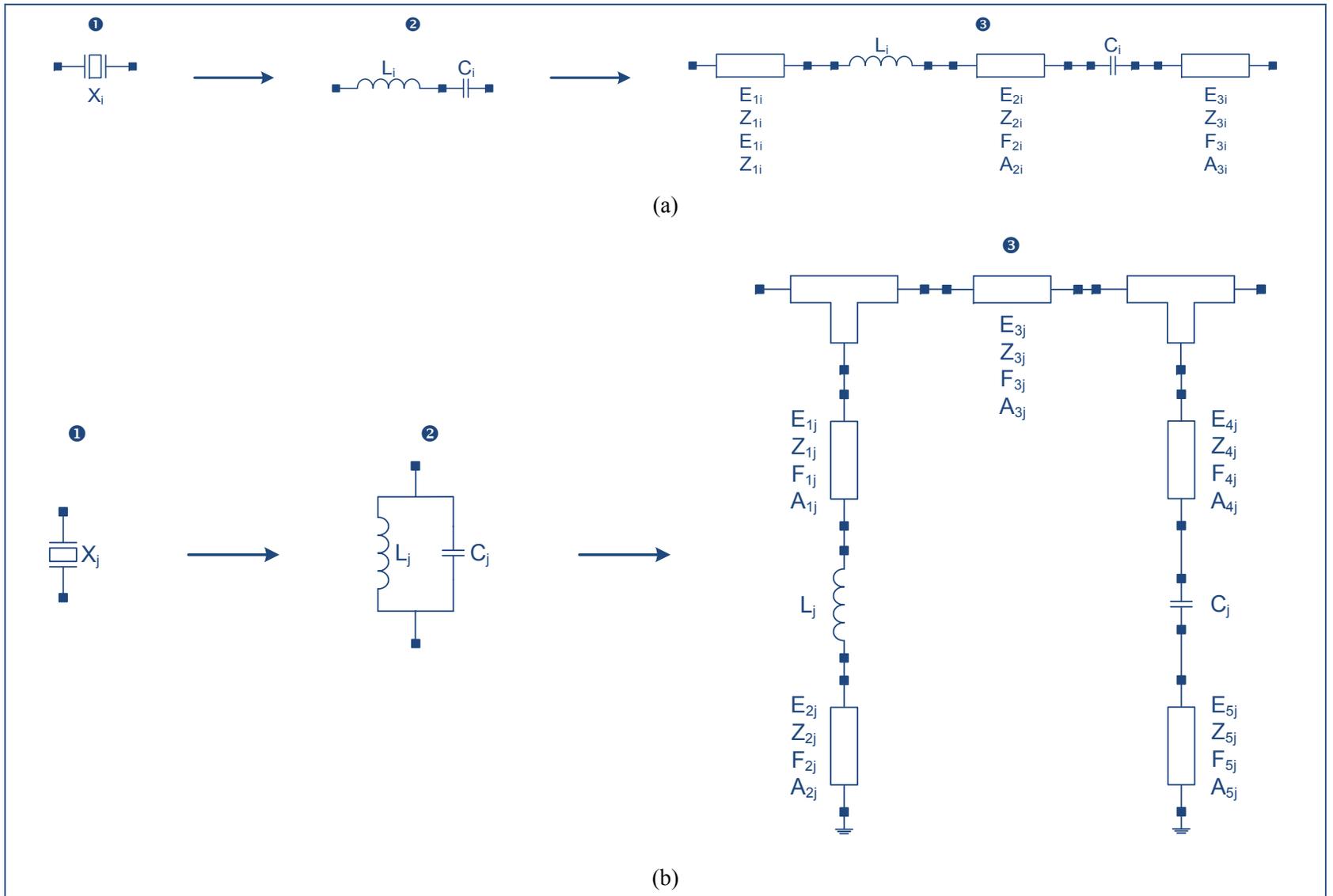


Figure 5.32 Generation of lumped-component filter circuit topology: (a) series and (b) parallel resonators

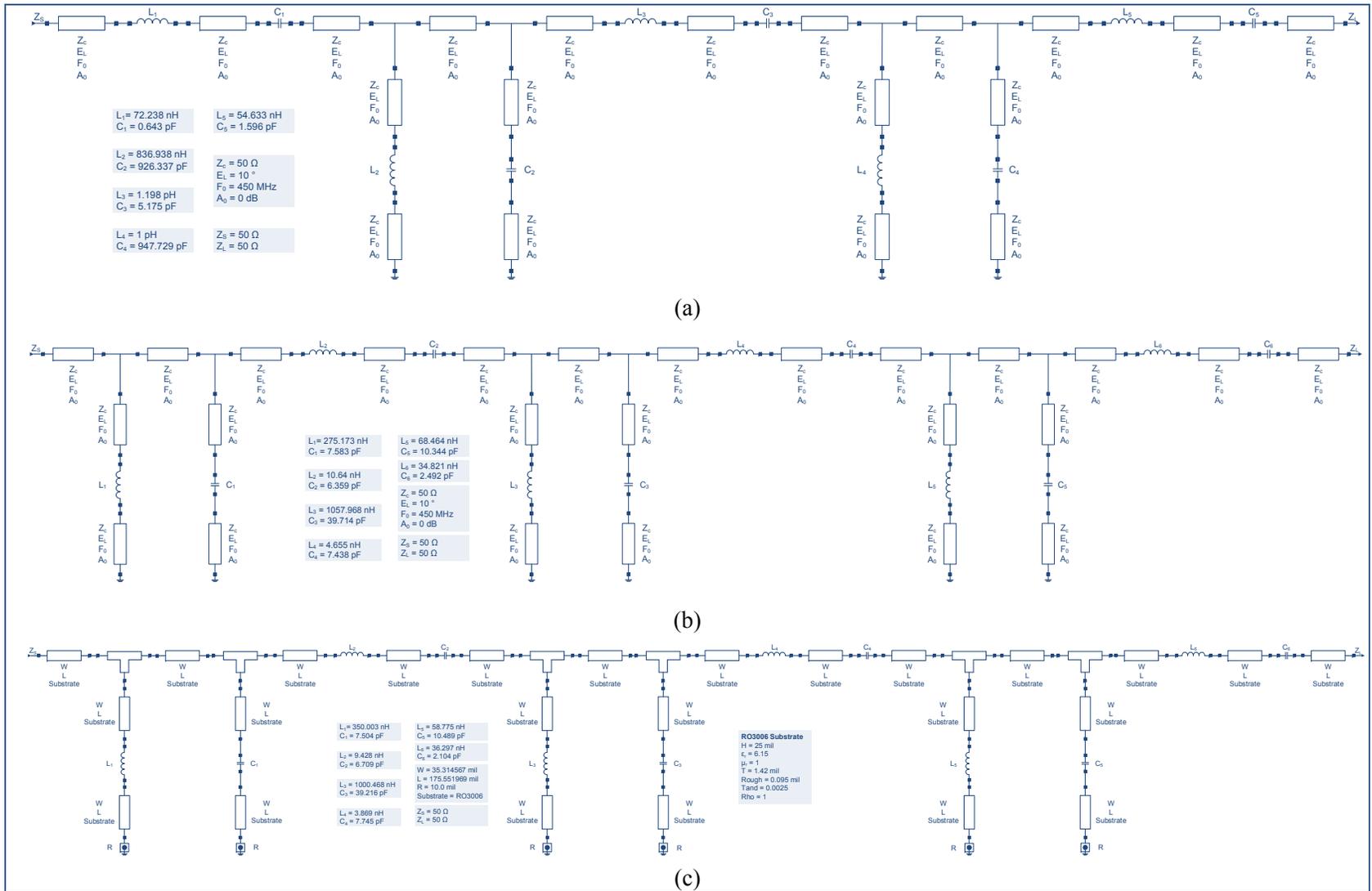


Figure 5.33 PSM evolution: (a) transformation output ( $N = 5$ ) (b) refined ( $N = 6$ ) and (c) technology-mapped ( $N = 6$ )

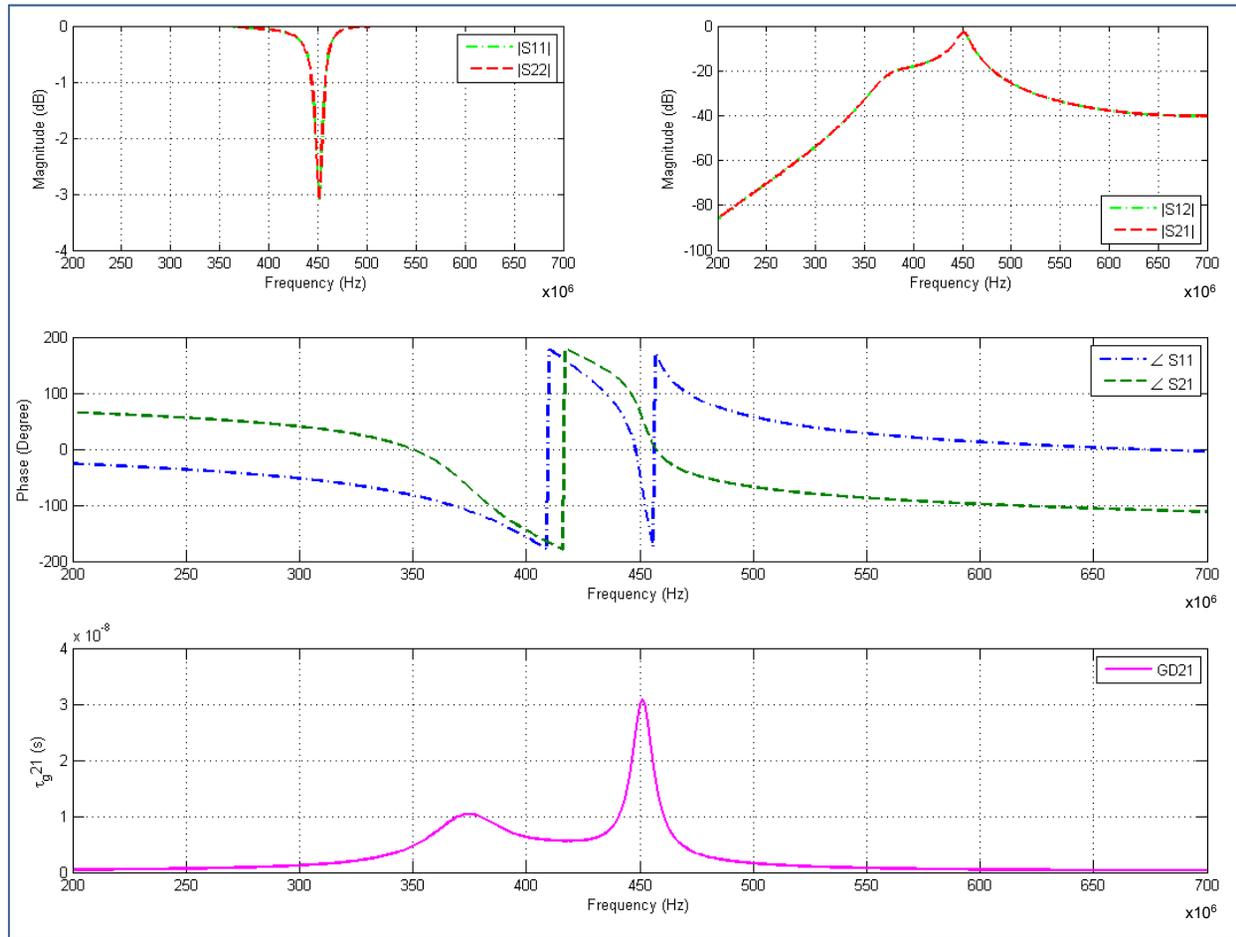


Figure 5.34 The frequency response of the PSM resulting from step 3 of the PIM-to-PSM transformation ( $N = 5$ )

### g) Synthesis: PSM granularity refinement

Since the obtained PSM (even after several optimization iterations) does not satisfy the requirements, we need to use the granularity refinement process in order to enhance its quality. To change the PSM's granularity level, we must define an intra-view transformation that alters the number of resonators and relaxes the design constraints to satisfy the requirements.

#### • Intra-view transformation

The minimum number of resonators that meets the requirements at the PIM level is five (i.e., Butterworth prototype). After connecting the resonators using transmission-line sections, the PSM's performance is no longer satisfactory. To enhance its frequency response, we define the intra-view transformation of Table 5.13. Depending on the PSM's topology, this intra-view transformation adds a new resonator as depicted in Figure 5.35. That resonator corresponds to the immediate higher order (i.e.,  $N + 1$ ). Its properties are defined as given in step 2 of the granularity refinement transformation. Figure 5.33 illustrates the resulting PSM schematic.

Table 5.13 Overview of the intra-view transformation for granularity refinement

<p><b>Step 1: Topology refinement</b></p> <ul style="list-style-type: none"> <li>• In case of <math>n^{\text{th}}</math> series resonator: Add series resonator structure as depicted in Figure 5.35.a.</li> <li>• In case of <math>n^{\text{th}}</math> parallel resonator: Add parallel resonator structure as depicted in Figure 5.35.b.</li> </ul> <p><b>Step 2: Resonator properties</b></p> <p>Consider the resonator properties given in the following:</p> $\left\{ \begin{array}{l} Z_{ci} = Z_{reference} \\ E_i = E_{default} \\ F_i = F_0 \\ A_i = A_{default} \\ L_i = L_N  _{N=N+1} \\ C_i = C_N  _{N=N+1} \end{array} \right.$ <p>where <math>Z_{ci}</math> is the characteristic impedance of the transmission line, <math>E_i</math> is its electrical length, <math>F_i</math> is the frequency at which the electrical length is calculated and <math>A_i</math> is the transmission line loss (in dB). <math>L_i</math> and <math>C_i</math> are the <math>n^{\text{th}}</math> lumped components corresponding to the immediate higher order <math>N + 1</math>.</p>
---

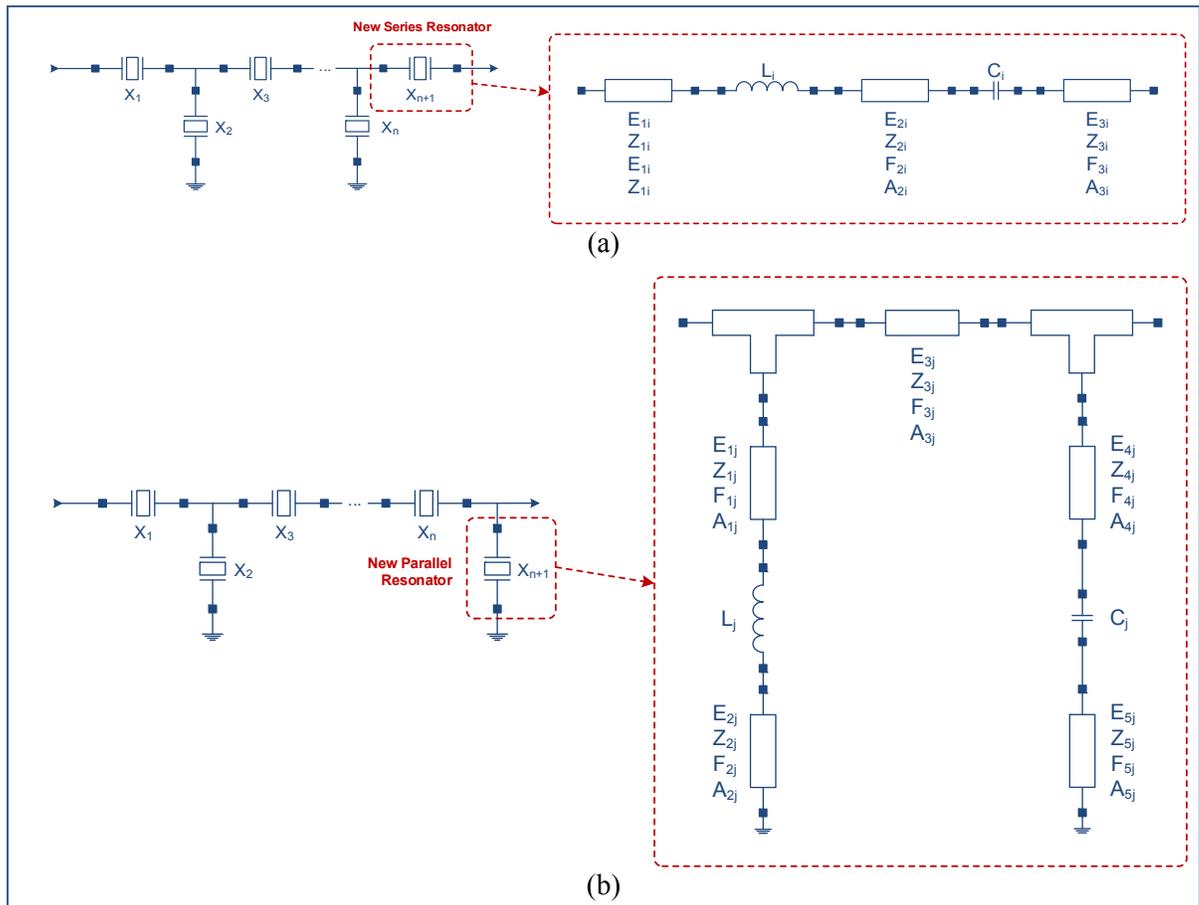


Figure 5.35 Granularity refinement: transformation of (a) series and (b) parallel resonators

The PIM-to-PSM and the granularity refinement transformations of Table 5.12 and Table 5.13 respectively illustrate the difference between intra- and cross-view transformations already discussed in section 4.3.5. The first implies a change of the abstraction level (in this case, from functional to circuit). However, the second changes only the design viewpoint within the same abstraction level (represented here by the change of the circuit's granularity level).

- **Refined PSM performance optimization**

The PSM circuit schematic of Figure 5.33 is submitted to many optimization iterations. In this case study, we rapidly come up with a design solution that satisfies the functional description requirements (see frequency response in Figure 5.36). In general, it is possible to get no satisfactory solution, which suggests attempting more granularity refinement iterations.

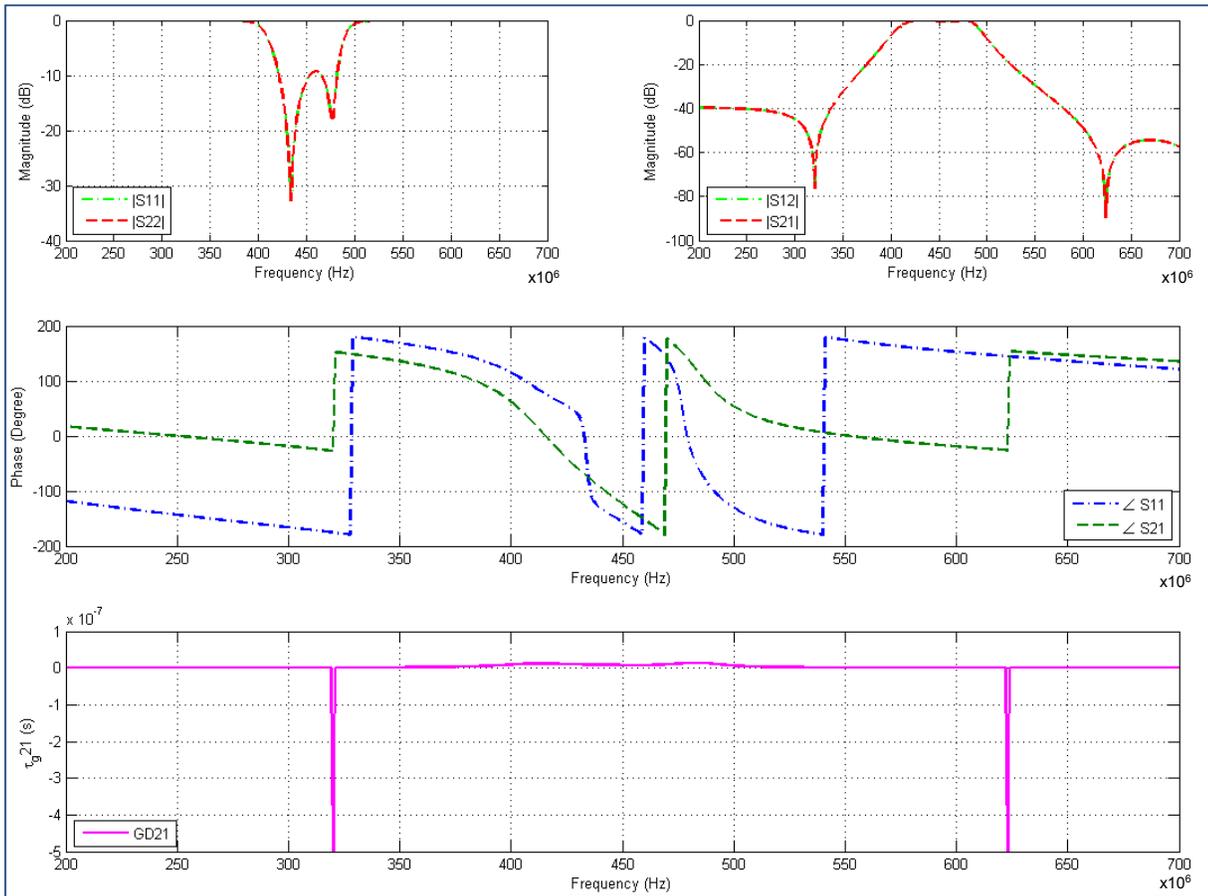


Figure 5.36 The frequency response of the optimized design solution after PSM granularity refinement

## h) Synthesis: Technology mapping

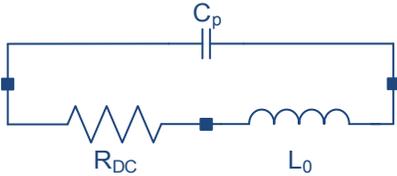
The PIM-to-PSM transformation considered ideal circuit components at the PSM generation due to the absence of detailed technology data. That is why we used so far ideal lumped components and transmission lines. However, ideal components do not reflect the real circuit performance. To bridge this gap, the technology mapping stage allows augmenting the PSM with detailed information about the target technology platform for each component.

- **Target technologies**

As previously mentioned, the PIM is implemented using lumped components (i.e., capacitors and inductors) to be connected together through distributed lines. Lumped components such as capacitors and inductors are non-ideal devices. In fact, a real capacitor (respectively inductor) is not fully capacitive (respectively inductive). Depending on their manufacturing

technology, these components suffer from various parasitic effects (such as series and/or shunt resistances). For the characterization of each component, electrical models are developed in order to take into account these parasitics. For instance, Table 5.14 shows two electrical models for non-ideal inductors and capacitors. In addition to capacitors and inductors, we use microstrip<sup>92</sup> transmission lines to route signals between resonators. This type of transmission lines consists of a conducting strip separated from a ground plane by a dielectric layer (i.e., the substrate).

Table 5.14 Electrical models for non-ideal inductors and capacitors

Ideal Device	Real Electrical Model	Remarks
 <p style="text-align: center;">L</p>		<p><b>L<sub>0</sub></b>: nominal inductance value (measured in Henri)</p> <p><b>R<sub>DC</sub></b>: DC Resistance (measured in ohm)</p> <p><b>C<sub>p</sub></b>: parallel capacitance value (measured in Farad), estimated using the formula:</p> $C_p = \frac{1}{(2\pi F_0)^2 L_0}$ <p>where F<sub>0</sub> is the inductance's self-resonant frequency</p>
 <p style="text-align: center;">C</p>		<p><b>C<sub>0</sub></b>: nominal capacitance value (measured in Farad)</p> <p><b>ESR</b>: Equivalent Series Resistance (measured in Ohm)</p>

The technology mapping process requires a technology library that provides the electrical characteristics of real components and transmission lines. It searches in this library the components that approaches the most the ideal ones already included in the PSM. Various metrics might be considered for the selection of real components.

<sup>92</sup> For more information about microstrip transmission lines, the reader might refer to Hong, J.S., et M.J. Lancaster. 2001. *Microstrip Filters for RF/Microwave Applications*. John Wiley and Sons., Pozar, David M. (732). 2012. *Microwave Engineering*, Fourth. John Wiley and Sons.

```

- <!--
  Lumped-Component Database - version 1.0 @ 2012-02-17 21:52:54 - Author: Sabeur Lafi
-->
- <database>
- <tech type="RLC">
- <kit provider="Digikey">
+ <Resistors></Resistors>
+ <Capacitors></Capacitors>
- <Inductors>
  <Inductor unit="nH">30</Inductor>
  <Inductor unit="nH">32</Inductor>
  <Inductor unit="nH">37</Inductor>
  <Inductor unit="nH">38</Inductor>
  <Inductor unit="nH">40</Inductor>
  <Inductor unit="nH">41</Inductor>
  <Inductor unit="nH">48</Inductor>
  <Inductor unit="nH">50</Inductor>
  <Inductor unit="nH">59</Inductor>
  <Inductor unit="nH">60</Inductor>
  <Inductor unit="nH">67</Inductor>
  <Inductor unit="nH">68</Inductor>
  <Inductor unit="nH">70</Inductor>
  <Inductor unit="nH">72</Inductor>

```

(a)

```

- <tech type="Microstrip">
- <package>
- <substrate name="RO3006">
  <er>6.15</er>
  <mur>1.0</mur>
  <h unit="mil">25</h>
  <ht unit="mil">1e20</ht>
  <t unit="mil">0.7</t>
  <cond>4.1e7</cond>
  <tand>0.002</tand>
  <rough>0</rough>
</substrate>
- <constraints>
  <manufacturingUpperLimit unit="mil">400</manufacturingUpperLimit>
  <manufacturingLowerLimit unit="mil">8</manufacturingLowerLimit>
</constraints>
</package>
</tech>

```

(b)

Figure 5.37 Technology files: (a) Lumped components (b) Microstrip substrate

Depending on the available technology information, these metrics might include (but not limited to) the nominal value, parasitic effects, physical dimensions, operating temperature, power consumption and packaging type. In this case study, we could not use proprietary technology libraries. Therefore, we built our own one that is composed of two XML files: the first gathers few thousands of lumped devices (i.e., resistors, capacitors and inductors) while the second provides the technological properties of common microstrip substrates. Figure 5.37.a shows a snippet of Digi-Key<sup>93</sup> inductors included in the lumped components technology file while Figure 5.37.b shows the properties of Rogers 3006 (aka RO3006) substrate, which is a part of the microstrip technology file.

- **PSM augmentation with technology data**

We developed a script to search the devices in the technology library corresponding to ideal PSM lumped components (already listed in Figure 5.33.c). We search inductors in three kits (i.e., fixed, common-mode choke and adjustable). Figure 5.38.a summarizes the findings in each kit as well as their number. The list of selected inductors is detailed in Table 5.15.

Then, we search capacitors in five kits already included in the technology library (i.e., ceramic, aluminum, film, tantalum and polymer). The results are illustrated in Figure 5.38.b and detailed information about the selected capacitors is given in Table 5.16. Finally, we choose the RO3006 substrate for the implementation of the microstrip transmission lines. We synthesized the required sections as illustrated in Figure 5.39.

For the purpose of simplification, we use in this case study only the nominal value of the lumped component as a selection criterion. In general, many selection criteria can be considered. Using an objective function, it becomes possible to automatically select the best devices corresponding to the PSM components.

---

<sup>93</sup> Digi-Key is one of the largest electronic-component distributors in North America and worldwide.

Searching in available inductors libraries...

- > Fixed Inductors Library: (910 components)
- > Common-Mode-Choke Inductors Library: (367 components)
- > Adjustable Inductors Library: (62 components)

Findings Summary:

No.	Ideal (H)	Fixed Lib.	CMC Lib.	Adjustable Lib.	Selected (#)
L1	3.500030e-7	3.50e-7	3.00e-7	3.50e-7	3.50e-7 (3)
L2	9.428000e-9	9.40e-9	NaN	NaN	9.40e-9 (2)
L3	1.000468e-6	1.00e-6	1.0e-6	6.80e-7	1.00e-6 (3)
L4	3.869000e-9	3.90e-9	NaN	NaN	3.90e-9 (3)
L5	5.877500e-8	5.90e-8	NaN	5.90e-8	5.90e-8 (1)
L6	3.629700e-8	3.60e-8	NaN	3.70e-8	3.60e-8 (3)

NaN: no coherent value found

(a)

Searching in available capacitors libraries...

- > Ceramic Capacitors Library: (387 components)
- > Aluminium Capacitors Library: (399 components)
- > Film Capacitors Library: (309 components)
- > Tantalum Capacitors Library: (112 components)
- > Polymer Capacitors Library: (47 components)

Findings Summary:

No.	Ideal (F)	Ceramic	Aluminium	Film	Tantalum	Polymer	Selected (#)
C1	7.5040e-12	7.50e-12	NaN	NaN	NaN	NaN	7.5e-12 (2)
C2	6.7090e-12	6.70e-12	NaN	NaN	NaN	NaN	6.7e-12 (2)
C3	3.9216e-11	3.90e-11	NaN	NaN	NaN	NaN	3.9e-11 (2)
C4	7.7450e-12	7.70e-12	NaN	NaN	NaN	NaN	7.7e-12 (2)
C5	1.0489e-11	1.00e-11	NaN	NaN	NaN	NaN	1.0e-11 (2)
C6	2.1040e-12	2.10e-12	NaN	NaN	NaN	NaN	2.1e-12 (2)

NaN: no coherent value found

(b)

Figure 5.38 Technology mapping report: (a) Inductors (b) Capacitors

```

Synthesizing transmission lines...

TLine properties:
  Characteristic Impedance (Zc): 50.0 ohm
  Electrical Length (L): 5.0 deg.
  Frequency (F): 450.0 MHz

Found technologies: (1)
  (1) Microstrip - R03006
      Substrate Name: Rogers 3006
      Dielectric Constant (Er): 6.15
      Magnetic Constant (Ur): 1
      Loss Tangent (Tand): 0.0025
      Resistivity (Rho): 1
      Substrate Height (H): 25.0 mil
      Metal Thickness (T): 1.42 mil
      Metal Roughness (Sr): 0.095 mil

TLines' properties:
  Width: 35.314567 mil
  Length: 175.551969 mil
  Effective dielectric constant: 4.305
  Total attenuation of the structure: 0.004 dB
  Skin Depth: 0.145

Tees' properties:
  Width (W1): 35.314567 mil
  Width (W2): 35.314567 mil
  Width (W3): 35.314567 mil

Ground connections: via ground (default)
  Radius: 10.0 mil
  Height: (Substrate.H) 25.0 mil
  Thickness: (Substrate.T) 1.42 mil

```

Figure 5. 39 Technology mapping report: Transmission lines synthesis

If quite detailed and complete technology libraries are available, the technology mapping process contributes significantly to the automation of the design scheme. Concretely, this process allows to:

- Bridge a gap in existent design tools: most popular commercial design packages do not provide the automated selection of technology devices. Some design environments allow the automated synthesis of distributed lines for limited number of circuits (e.g., planar filters in Genesys and Microwave Office);
- Enable fully automated multi-criteria devices selection: given detailed characterization of technology elements, objective functions can be used to select the best components fitting to the PSM circuit;

- Operate in multi-technology design environment: the selection process does not only work with lumped components. It is also possible to automatically synthesize complex planar transmission lines, coaxial cables and multi-layer structures. Specialized tools can be used to handle multi-technology issues (e.g., packaging, connections, discontinuities, etc.);
- Open the door for new types of analyses: the availability of detailed technology data covering not only the electrical but also mechanical, environmental aspects, etc., which enables to carry out different analyses uncommon at this abstraction level. In addition to area estimation, other analyses such as power consumption, carbon fingerprint, and heat dissipation can take place.

In addition, the use of standard formats (such as XML) for technology libraries instead of the prevalent proprietary file formats is another provision that enhances data exchange and communication between concurrent design environments.

#### **i) Synthesis: PSM performance assessment and optimization**

During technology mapping, we choose the real capacitors and inductors to replace ideal PSM lumped components (see the row entitled “selected?” in Table 5.15 and Table 5.16). We have also synthesized the microstrip sections to connect the lumped devices as well as the suitable via holes to ensure ground connectivity. The resulting circuit PSM schematic is shown in Figure 5.33.c.

After linear simulation, we illustrate its frequency response in Figure 5.40. It is obvious that the PSM’s overall performance has decreased if compared to the ideal PSM frequency response of Figure 5.36. The reason behind this performance degradation is not only due to the small difference in nominal values between ideal and non-ideal lumped devices but also caused by their parasitic effects as well as the imperfections of microstrip sections (e.g., the effect of discontinuities, fringing fields, via holes, substrate, etc.).

To meet the requirements, we carried out several optimization iterations in order to minimize the effects due to the imperfections of lumped devices and microstrip sections. We succeed to find out two PSM configurations that meet the requirements. The first is characterized by a relatively constant group delay over a wide range of frequencies but it suffers from a disturbed

roll-off in the upper transition band (see Figure 5.41). The second design solution shows interesting reflection and transmission characteristics (see Figure 5.42). We use both candidate solutions to generate two distinct PMs in the next design stage.

It is worth noting that if the optimization effort fails at this step in the search of a PSM that meets the initial requirements, a design re-spin becomes inevitable. Thus, the design will restart at the step of PSM granularity refinement in the purpose of figuring out a new design solution. The new PSM is submitted again to technology mapping and performance assessment respectively.

Table 5.15 List of inductors found in the technology library during automated technology mapping

Ideal Value (nH)	Real Value (nH)	L <sub>0</sub> (nH)	R <sub>DC</sub> (Ω)	F <sub>0</sub> (MHz)	C <sub>p</sub> (pF)	Tolerance	Manufacturer Part Number	Size Dimensions (mm)			Selected?
								Length	Width	Thickness	
350.003	350	350	0.04	120	5.03	±20%	GLFR1608TR35M-LR <sup>◇</sup>	1.6	0.8	1	
		350	0.039	98	7.54	±20%	SPM5030T-R35M <sup>◇</sup>	5.2	5	3	✓
		350	0.08	300	0.804	±20%	BRC1608TR35M <sup>♥</sup>	1.3	0.8	1	
9.428	9.4	9.4	0.081	6000	0.0749	±2%	LQW15AN9N4G80 <sup>♣</sup>	1	0.6	0.6	✓
		9.4	0.081	6000	0.0749	±5%	LQW15AN9N4J80 <sup>♣</sup>	1	0.6	0.6	
1000.468	1000	1000	0.078	150	1.13	±20%	LB3218T1R0M <sup>♥</sup>	3.2	1.8	2	
		1000	0.00295	147	1.17	±20%	7443340100 <sup>♣</sup>	8.4	7.9	7.5	✓
		1000	0.34	120	1.76	±20%	NLCV25T-1R0M <sup>◇</sup>	2.5	2	1.9	
3.869	3.9	3.9	0.18	6000	0.18	±0.3nH	LQG15HS3N9S02 <sup>♣</sup>	1	0.5	0.55	
		3.9	0.07	10000	0.0649	±0.1nH	LQW15AN3N9B00 <sup>♣</sup>	1	0.5	0.6	✓
		3.9	0.25	9800	0.0676	±0.3nH	MLK0603L3N9ST000 <sup>◇</sup>	0.6	0.3	0.33	
58.775	59	59	0.2	150	0.191	±10%	WW1008R-59NK <sup>*</sup>	2.92	2.79	2.03	✓
36.297	36	36	0.26	2900	0.0837	±2%	LQW18AN36NG00 <sup>♣</sup>	1.6	0.8	1	✓
		36	1.6	1800	0.217	±5%	ELJ-QF36NGF <sup>♣</sup>	1	0.5	0.55	
		36	0.2	2080	0.163	±5%	744761136C <sup>♣</sup>	1.65	1.15	1.1	

<sup>◇</sup> TDK Corporation

<sup>♥</sup> Taiyo Yuden

<sup>♣</sup> Murata Electronics

<sup>♣</sup> Würth Electronics

<sup>\*</sup> API Delevan Inc.

<sup>♣</sup> Panasonic Electronic Components

Table 5.16 List of capacitors found in the technology library during automated technology mapping

Ideal Value (pF)	Real Value (pF)	C <sub>0</sub> (pF)	ESR (Ω)	Tolerance	Manufacturer Part Number	Size Dimensions (mm)			Selected?
						Length	Width	Thickness	
7.504	7.5	7.5	0.1	±0.25pF	GRM0335C1H7R5CA01*	0.6	0.3	0.33	
		7.5	0.1	±0.25pF	GRM0225C1C7R5WA02*	0.4	0.2	0.22	✓
6.709	6.7	6.7	0.1	±0.25pF	GRM0335C1H6R7CA01*	0.6	0.3	0.33	
		6.7	0.1	±0.1pF	GRM0332C1H6R7BA01*	0.6	0.3	0.33	✓
39.216	39.0	39.0	0.16	±2%	GRM0332C1H390GA01*	0.6	0.3	0.33	✓
		39.0	0.15	±5%	GRM0335C1H390JA01*	0.6	0.3	0.33	
7.745	7.7	7.7	0.2	±0.1pF	GRM0332C1H7R7BA01*	0.6	0.3	0.33	
		7.7	0.2	±0.05pF	GRM0332C2A7R7WA01*	0.6	0.3	0.33	✓
10.489	10.0	10.0	0.2	±2%	GRM0332C1H100GA01*	0.6	0.3	0.33	
		10.0	0.15	±5%	GRM1552C1H100JA01*	0.6	0.3	0.33	✓
2.104	2.1	2.1	0.28	±0.1pF	GRM0333C1H2R1BA01*	0.6	0.3	0.33	✓
		2.1	0.29	±0.05pF	GRM0335C1H2R1WA01*	0.6	0.3	0.33	

\* Murata Electronics

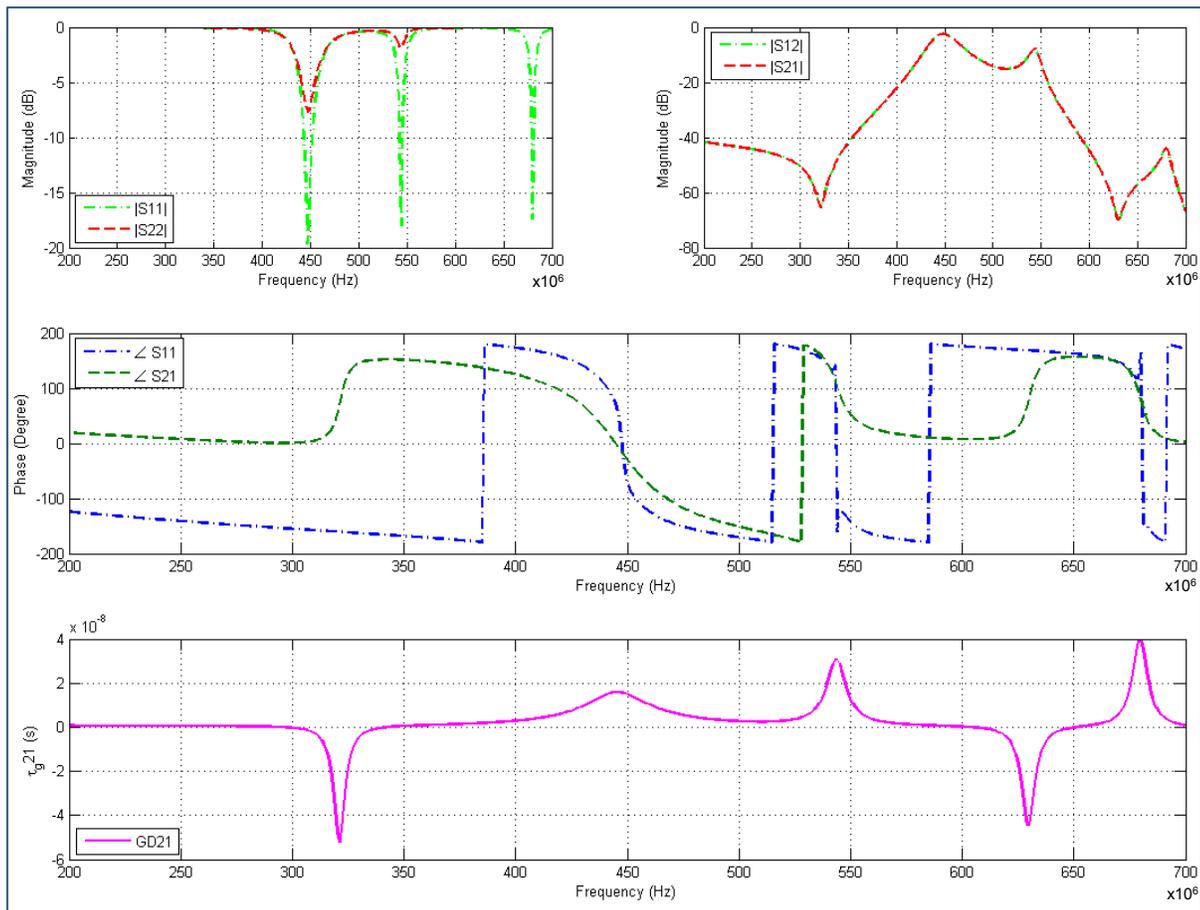


Figure 5.40 The PSM's frequency response after technology mapping

### j) Synthesis: Platform model generation

Having two PSM candidate solutions (with enough technology data) that relatively meet most of the requirements captured in the initial functional description, we proceed henceforth to the generation of the corresponding platform model in the purpose of the physical implementation of the target filter.

- **Platform models**

To generate the platform models corresponding to both PSMs, we need a PSM-to-PM transformation that converts the PSM circuit-level artifacts (e.g., schematic, technology models and constraints, etc.) into a PM physical-level layout. So, the PM should reflect at physical level (e.g., layers, shapes, routes, etc.) what the PSM captures at circuit level (e.g., types and order of elements, connectivity, etc.).

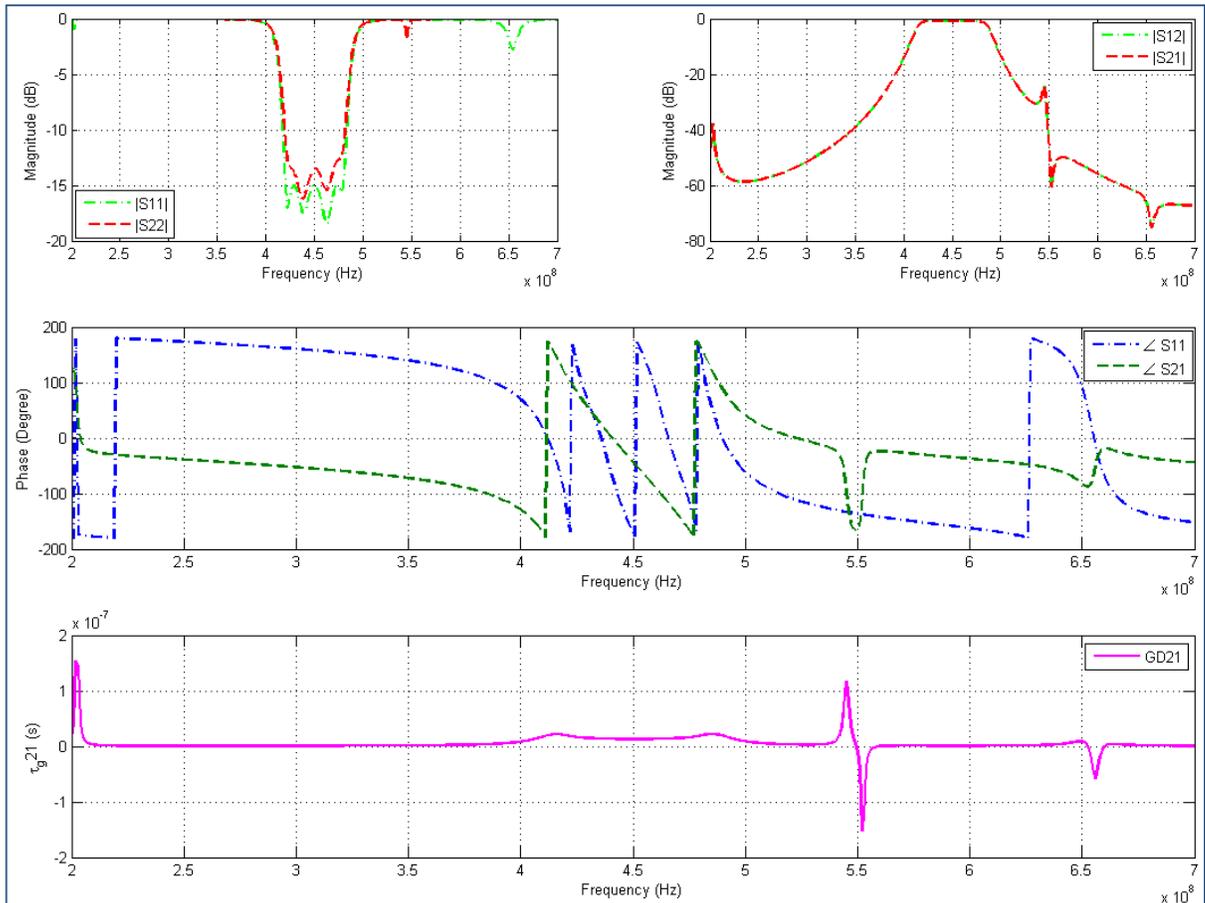


Figure 5.41 First candidate solution (optimization round 1)

Given the detailed PSM components and technology information, the next step is the generation of the corresponding layouts (i.e., PM). For simplicity, we use a commercial layout generation tool (e.g., Genesys) as PSM-to-PM transformation. The platform models corresponding to the first and second PSMs are shown in Figure 5.43 and Figure 5.44 respectively. These figures show a single 2D and three 3D views of each layout. Microstrip sections and via holes are fully captured in 3D view. Nevertheless, the lumped components visible on 2D layouts are not shown on 3D ones. The reason behind this is that the software tool has no information about their three-dimensional representations because these components are off-the-shelf (i.e., available technology data is limited to 2D aspects). To be considered in the 3D layout view, the designer should manually import each device's layout. This said, the spacing between the microstrip sections takes into account the dimensions of each lumped device.

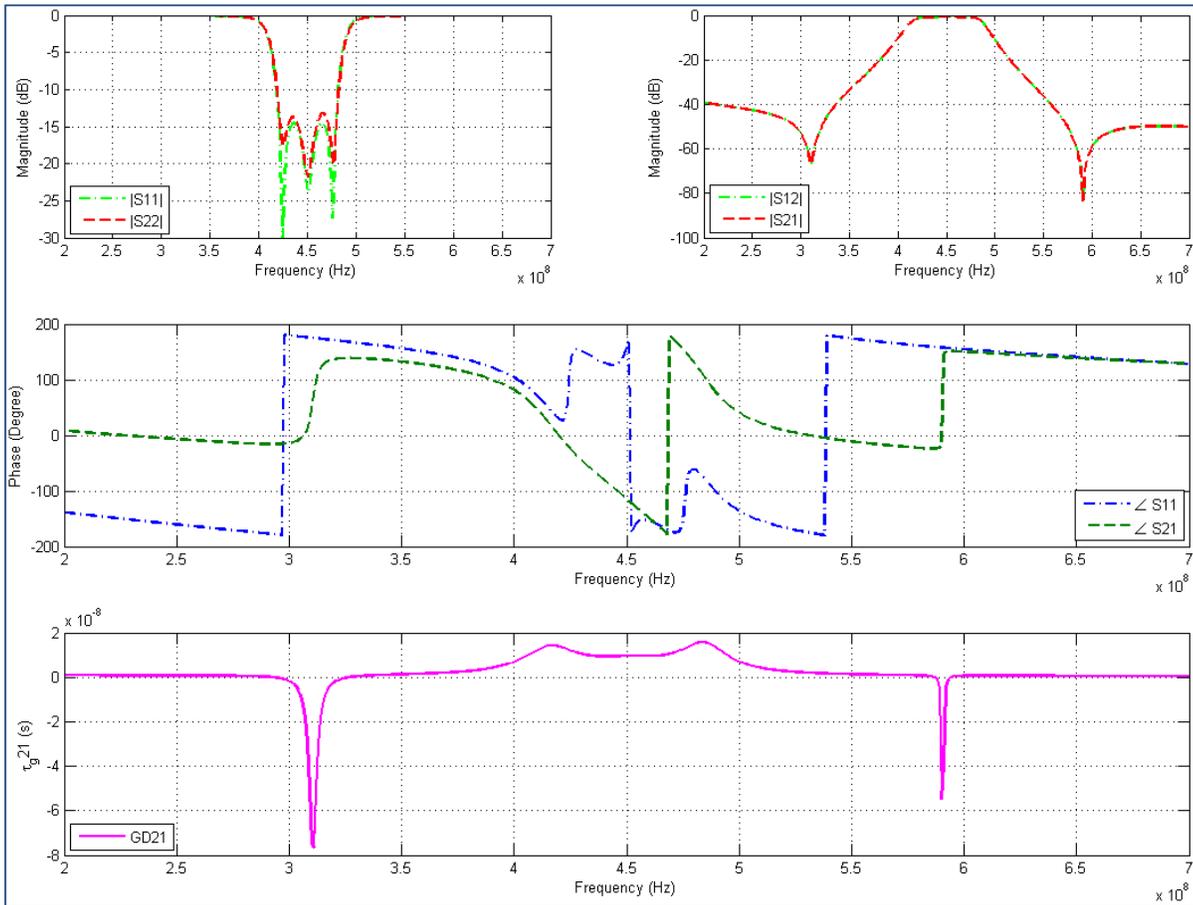


Figure 5.42 First candidate solution (optimization round 2)

- **PM selection and performance assessment**

After PSM-to-PM generation, we should validate both PMs against the initial functional description not only in terms of electrical performance (e.g., frequency response) but also considering the other requirements captured in the diagram of Figure 5.13 (e.g., form factor, lightning protection, EMC requirements and humidity resistance).

In this case study, the available technology data are limited and provided us only with thorough information about the filter's form factor. Knowing the physical dimensions and the size of each PM component, the area and volume of the PM can be estimated with good accuracy. Hence, Table 5.17 presents the maximum length, width and PCB area required for the manufacturing of each platform model. The first PM needs more than twice the area occupied by the second one. For a comparable frequency response, the first PM can be discarded since

the filter is required to be as small as possible. The advantage of making such estimation early enough before prototype manufacturing is preventing additional development costs.

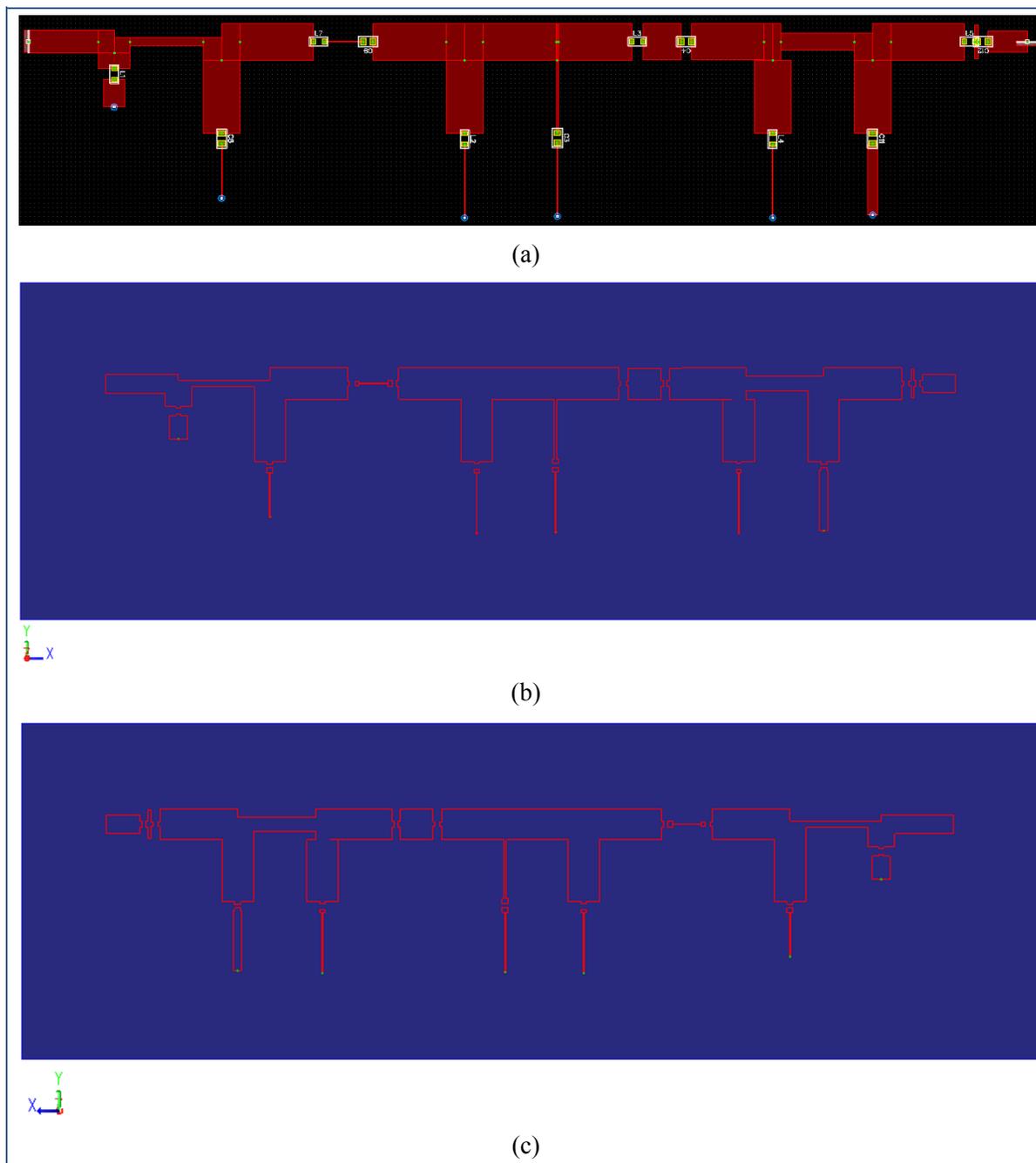


Figure 5.43 Platform model (first optimized PSM): (a) 2D layout (b) 3D layout top and (c) bottom views

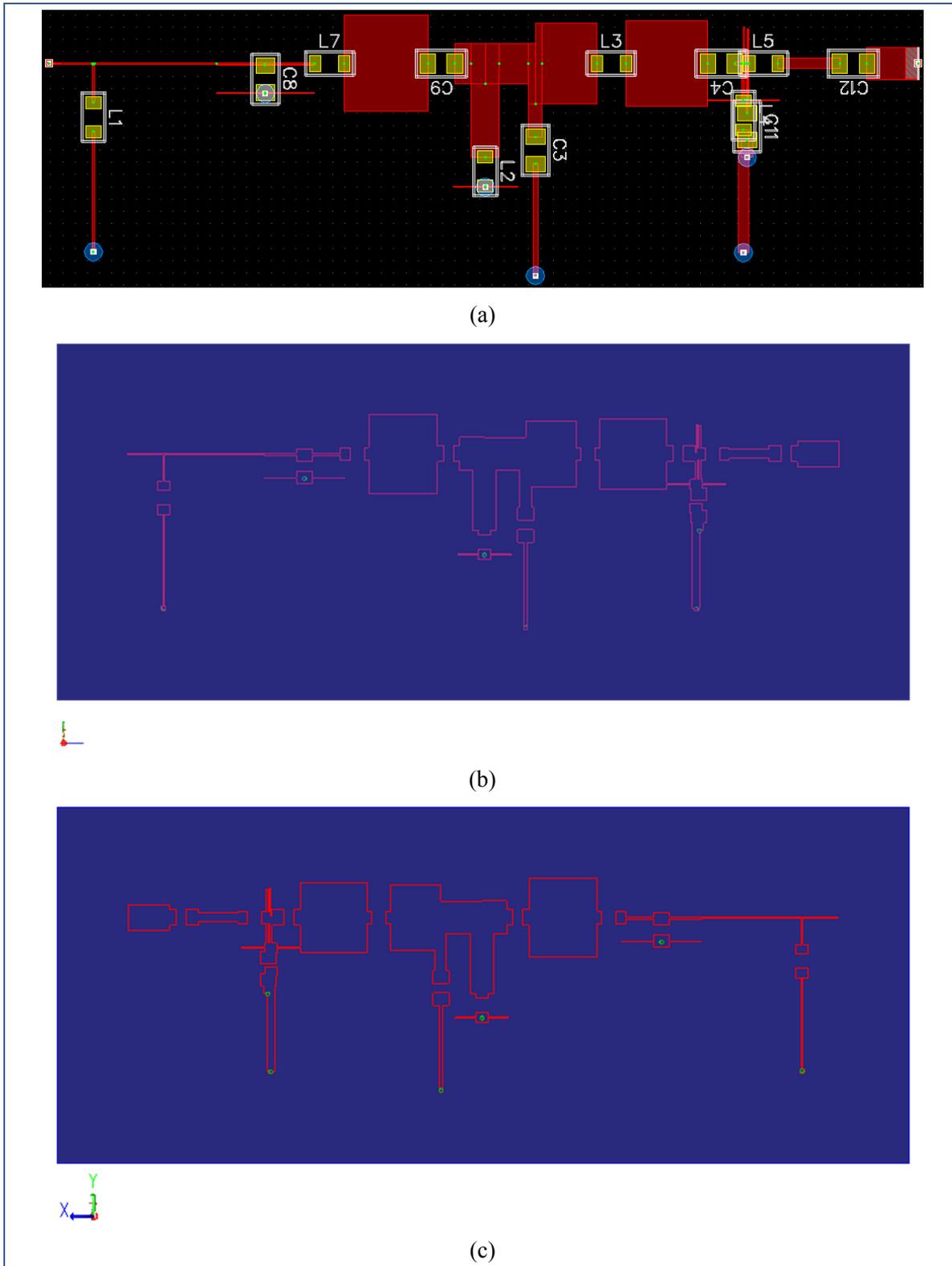


Figure 5.44 Platform model (second optimized PSM): (a) 2D layout (b) 3D layout top and (c) bottom views

Unfortunately, we are not able at this step to evaluate the PM against the other requirements (i.e., lightning protection, EMC and humidity resistance requirements). So, it becomes mandatory to postpone these assessment tasks to the test and measurements stage. This lack is not inherent to the design framework but is related to:

- The quality of technology data: the provision of comprehensive physical, electrical and mechanical data as input to the technology mapping step enables thorough characterization of both PSM and PM at circuit and device levels. If some characterization aspects are missing, it is generally not possible to evaluate PSMs and PMs regarding that specific aspect;
- The availability of highly specialized tools: to validate particular behavior of both PSMs and PMs, specialized tools are required. For example, an EM solver uses the PM's structure information (e.g., mechanical data, materials' properties, etc.) in order to assess the PM's response against EM excitation (e.g., electrical and magnetic fields distribution and strength, signal attenuation levels, etc.).

Table 5.17 Comparison of PCB areas required to hold the generated platform models

	<b>Maximum Length (cm)</b>	<b>Maximum Width (cm)</b>	<b>Maximum Area (cm<sup>2</sup>)</b>
<b>PM 1 (PSM opt. 1)</b>	26.5710328	5.1156499	135.9281
<b>PM 2 (PSM opt. 2)</b>	8.0287038	7.5807504	60.8636

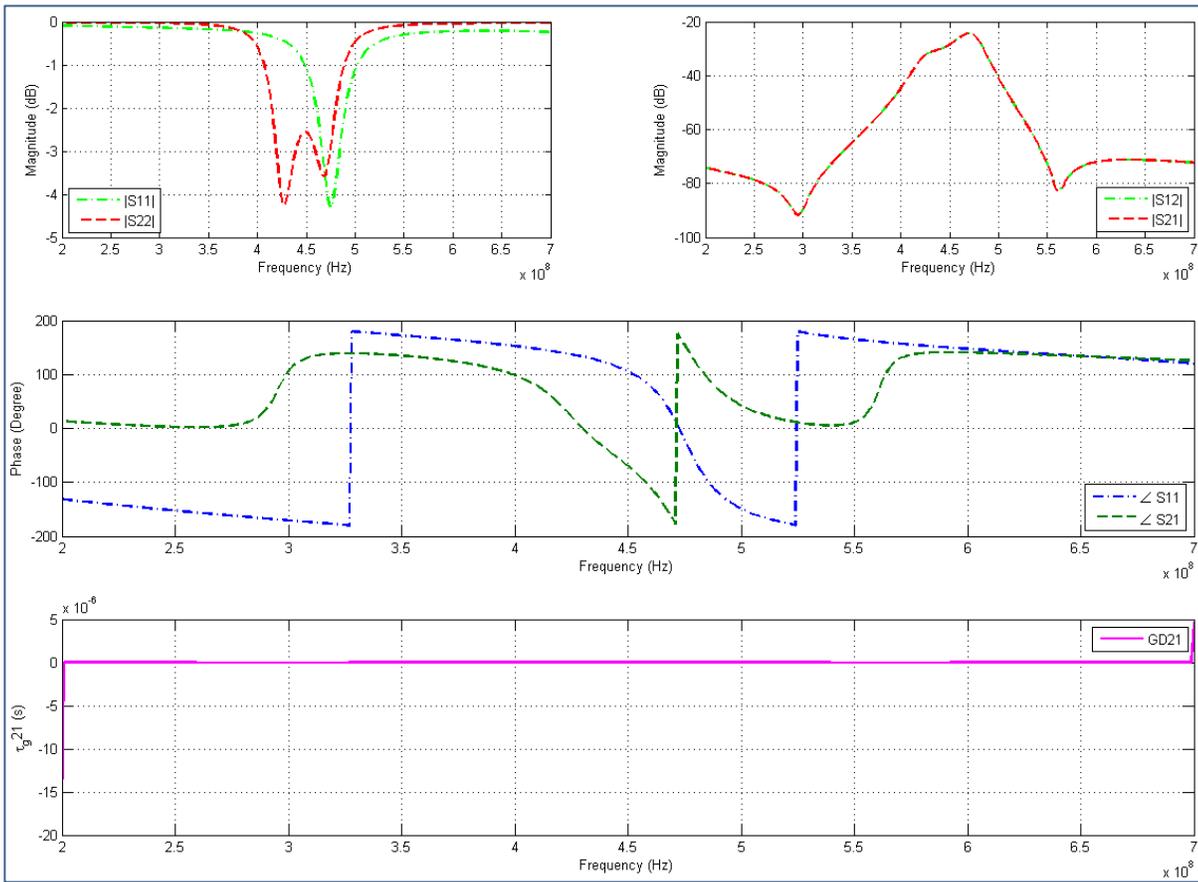


Figure 5.45 Frequency response of the PM model (PSM-to-PM transformation output)

Before the PM manufacturing, we carry out a hybrid simulation (EM/circuit) to evaluate its frequency response. As illustrated in Figure 5.45, the attenuation levels in the passband are poor. This performance decrease is mainly due to the tools accuracy at both circuit- and device-levels. The PSM performance is evaluated using circuit-level tools based on electrical models while the PM frequency response is obtained after EM simulation. On the contrary to the former, the latter takes into account physical-level artefacts such as the layout structure properties. The EM solver simulating the physical structure of the PM is more accurate than the electrical models used at circuit-level for the evaluation of the PSM. Before fabrication, this PM requires layout-level optimizations. However, manufacturing is not the main purpose of this case study. Therefore, we give up the design process at this step.

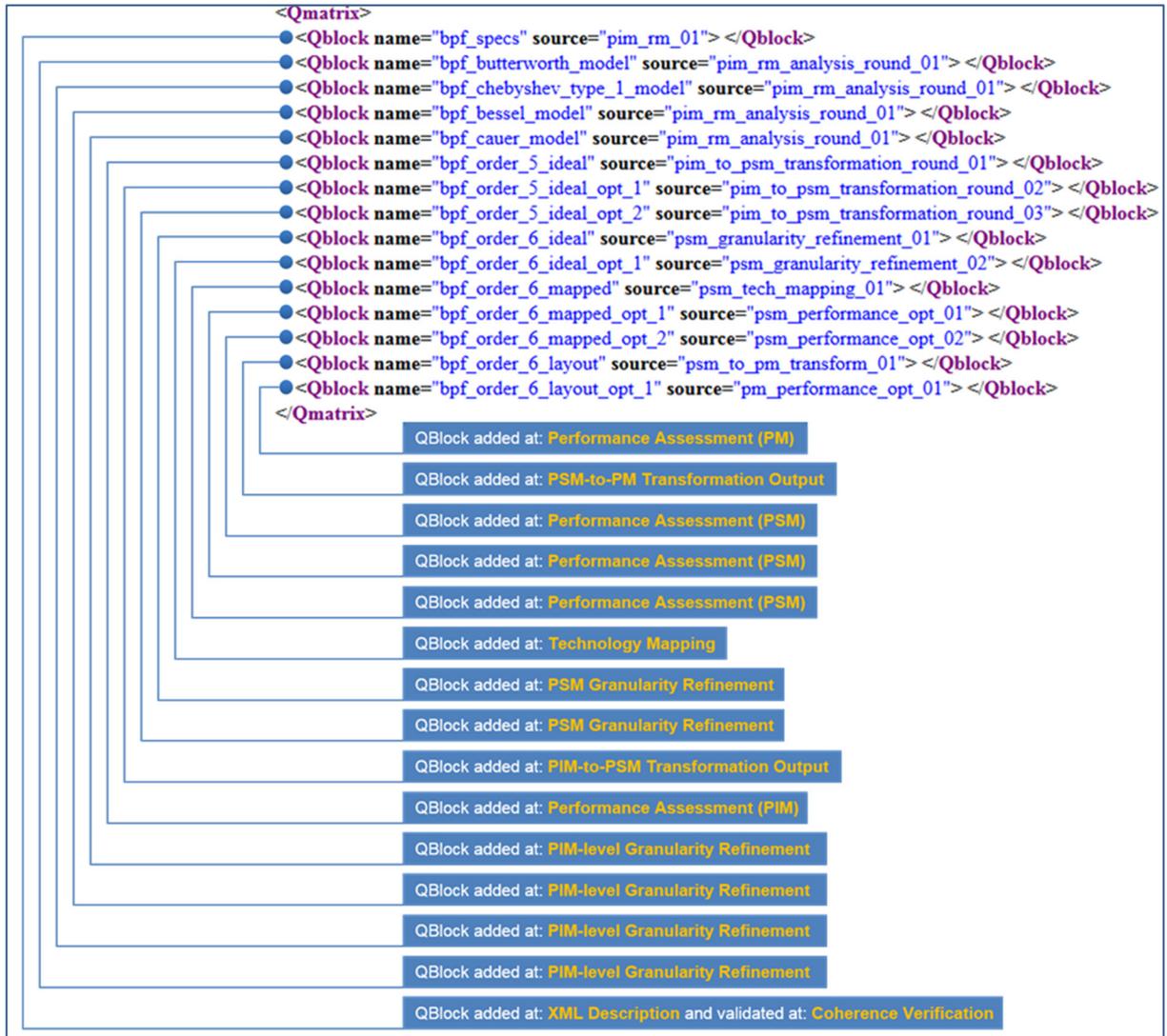


Figure 5.46 Overview of the QBlocks added to the Q-matrix throughout the filter's design process

## 1. Q-matrix evolution

In this first case study, we illustrated in Figure 5.24 the Q-matrix created at the end of the functional description stage (i.e., XML description step). However, we did not so far comment its role and practical use in the design scheme. This choice is deliberate to prevent ambiguity and confusion between the design scheme stages and Q-matrix. In this section, we focus on the construction and evolution of the Q-matrix used for the previous bandpass filter design.

The design cycle of the bandpass filter required three model-to-model transformations, several analyses and optimization iterations. Each of these mechanisms added new design data that were held in new QBlocks of the Q-matrix. At this regard, Figure 5.46 shows the most important QBlocks added throughout the design process. Each of these QBlocks has its own name and data source. It gathers the electrical data that resulted from a given design step. In this Q-matrix, all design data originated from either functional description or simulations.

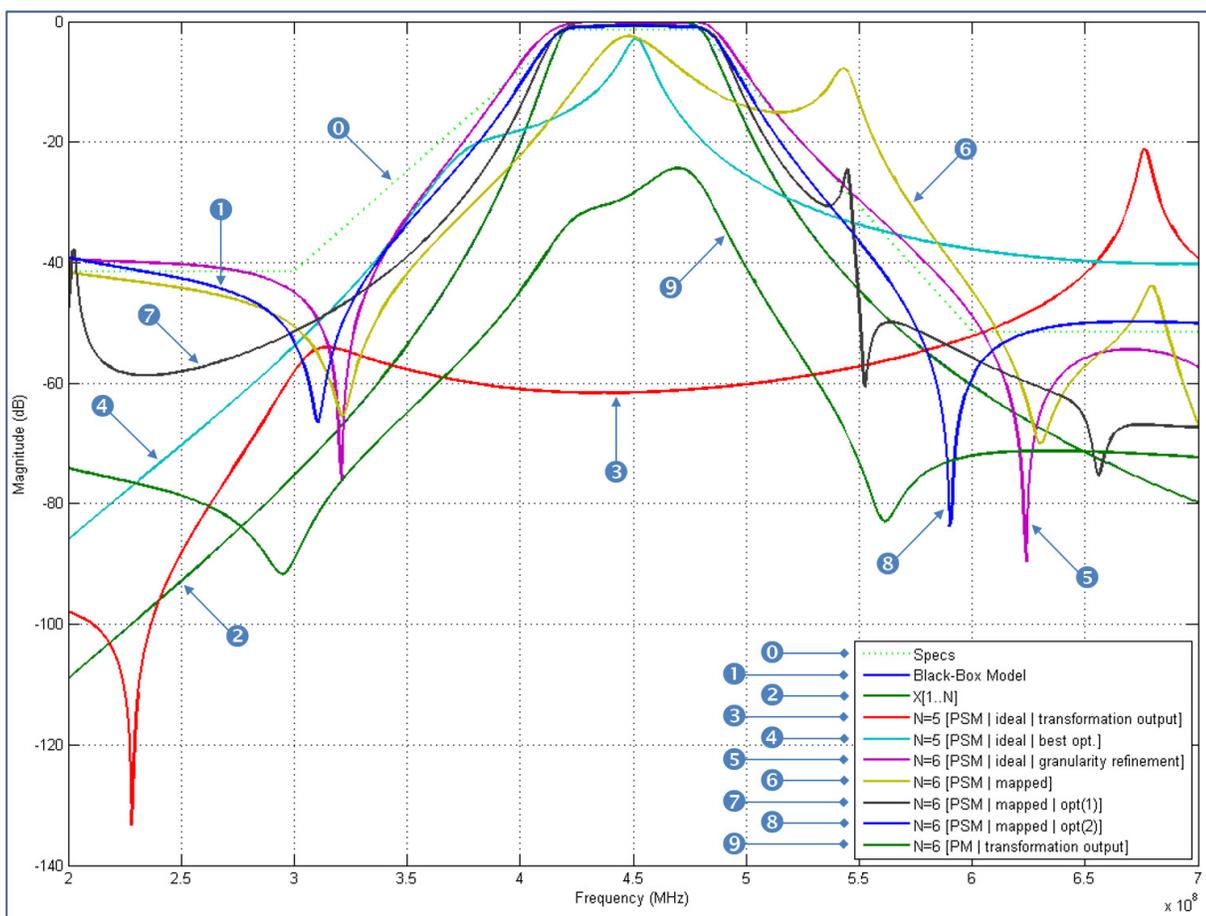


Figure 5.47 The Q-matrix centralizes design data, which allows for example to make performance comparisons throughout the design process

As discussed in section 3.3.4, the Q-matrix centralizes and enables concurrent sharing of design data between tools and designers. For instance, this feature is useful when comparisons between multiple design solutions are required. As illustrated in Figure 5.47, we used the Q-matrix to compare the performance of the bandpass filter at different design steps. Since the

data is available in the same XML file, it is easy to select and plot the attenuation response of the filter in some key design steps. Using a popular commercial design package such as ADS, the Figure 5.47 requires at least ten different datasets (or/and data files) to be plotted. To export such data using the same tool, ten different Touchstone files are generated. With the proposed Q-matrix structure, this effort is minimized since all the data is available in the same file.

Another interesting feature of the Q-matrix is the possibility of storing fragmented data. For example, no data is stored for frequency points having no attached information. This is not possible in most commercial tools. To do so, the designer should carry out complicated operations in order to discard all the frequency points where no data is available. For illustration, Figure 5.48 shows a single frequency point (i.e., 420 MHz) in different QBlocks added at different design stages. In the QBlock (no. 2) resulting from the coherence verification, there is no data about the reflection levels needed at 420 MHz. This is expected because the specifications and the functional description do not provide that information. In the following step (i.e., analysis), the filter approximations (i.e., Butterworth, Chebyshev Type I, Elliptic and Bessel) associated to the black-box model provided both transmission and reflection coefficients at 420 MHz. The associated QBlocks (no. 3) stored this information. Another example is the temperature considered for simulations. The black-box model does not consider the temperature parameter. That is why the temperature value (in QBlock no. 3) is set to “F” (i.e., “Forget” which literally means “do not consider”). On the contrary, the LC model (in QBlock no. 4) computed in the second step of the PIM-to-PSM transformation takes into account the standard temperature (i.e., 16.85°C). Thus, the temperature information becomes available in the QBlocks of following design steps.

## **2. Additional remarks**

Throughout the design cycle, we developed various filter prototypes and used different assessment techniques to validate each of them against the initial requirements.

- **Models evolution throughout the design cycle**

This case study started with the functional description that consisted of developing high-level models for the description of the filter properties, structure and requirements. Then, we

associated a black-box model to this functional description in the purpose of deriving a platform-independent model. Using appropriate model-to-model (cross- and intra-view) transformations, we generated circuit- and device-level models that implement the bandpass filter. An overview of the main models developed at each design stage is already shown in Figure 5.49.

It is worth noting the transition between the high-level functional description and the physical-level layout artwork that resulted from an abstraction level raise. The gap between both types of models is larger than what is actually available in the current design practice. This is due to the abstraction strategy that defined concepts and mechanisms allowing to:

- a. Develop high-level platform independent models for functional description,
- b. Associate appropriate black-box models to each functional description, and
- c. Derive platform-specific and implementation models from their high-level counterparts using relevant model-to-model transformations.

- **Assessment techniques**

Raising the abstraction level and subdividing the design space into three contiguous domains (i.e., RM/PIM, PSM and PM) arranged assessment and simulation techniques into three categories:

1. PIM-level simulation techniques: In RM/PIM domain, models are evaluated using coherence verification rules for the functional description and mathematical equations for black-box models. These formalisms do not take into account any platform-specific details;
2. PSM-level simulation techniques: In PSM domain, more accurate simulation techniques (e.g., circuit) are used because some platform specifications are known;
3. PM-level simulation techniques: In PM domain, the physical-level validation requires more specialized techniques that take into account the physical aspects at device level.



Figure 5.48 An overview of Q-matrix QBlocks evolution throughout the design cycle

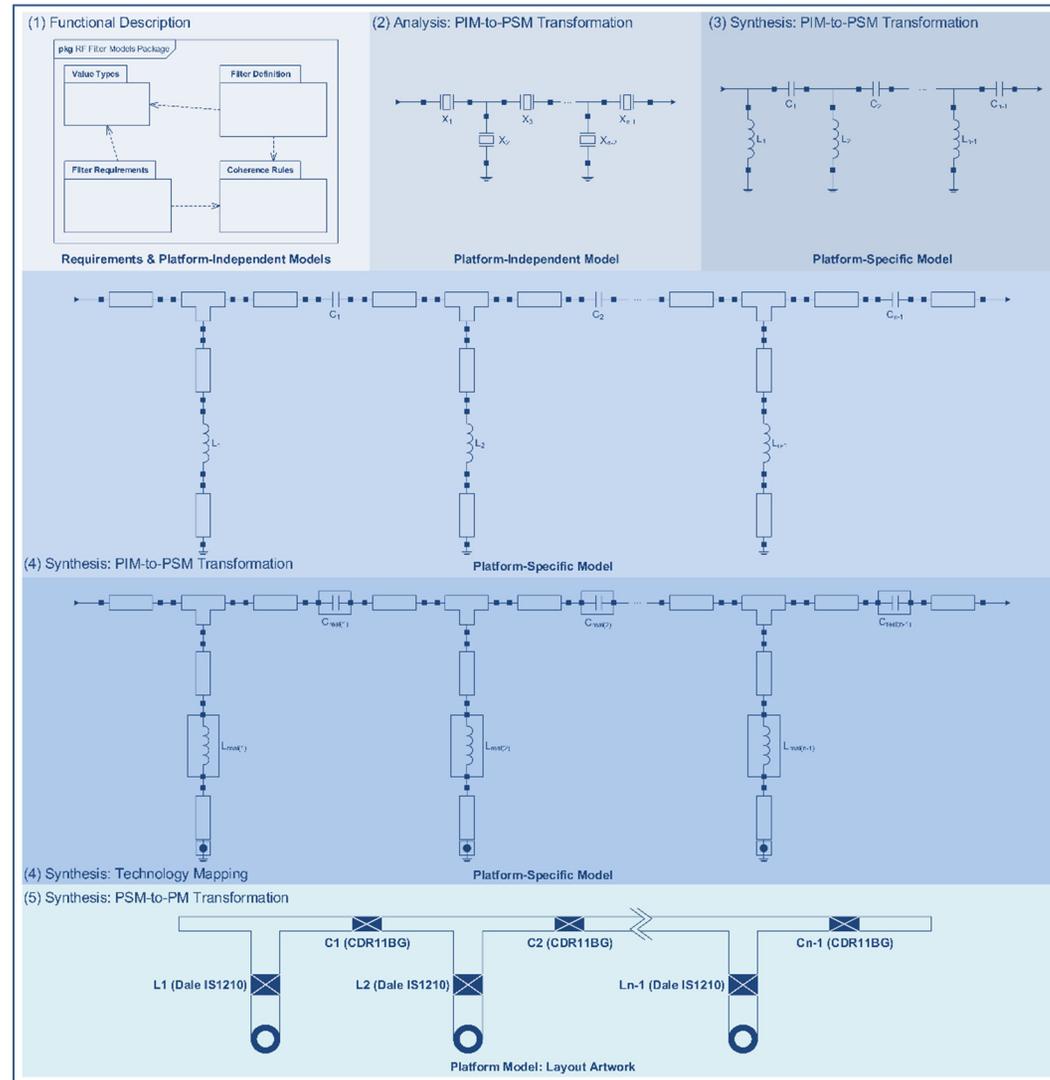


Figure 5.49 The evolution of the filter models throughout the design cycle

To illustrate this observation, Figure 5.50 maps the simulation techniques we used in this case study to the different filter models and design viewpoints. However, this mapping remains relative because some simulation and validation techniques of an upper-level domain might be used in an underlying one. For example, the frequency response of the filter's PM (see Figure 5.45) was obtained after using a hybrid simulation: an EM solver computed the frequency response of the microstrip sections while the lumped components one was determined using a circuit-level simulation. The EM simulation could not compute the entire structure frequency response because the physical layout of lumped components is missing.

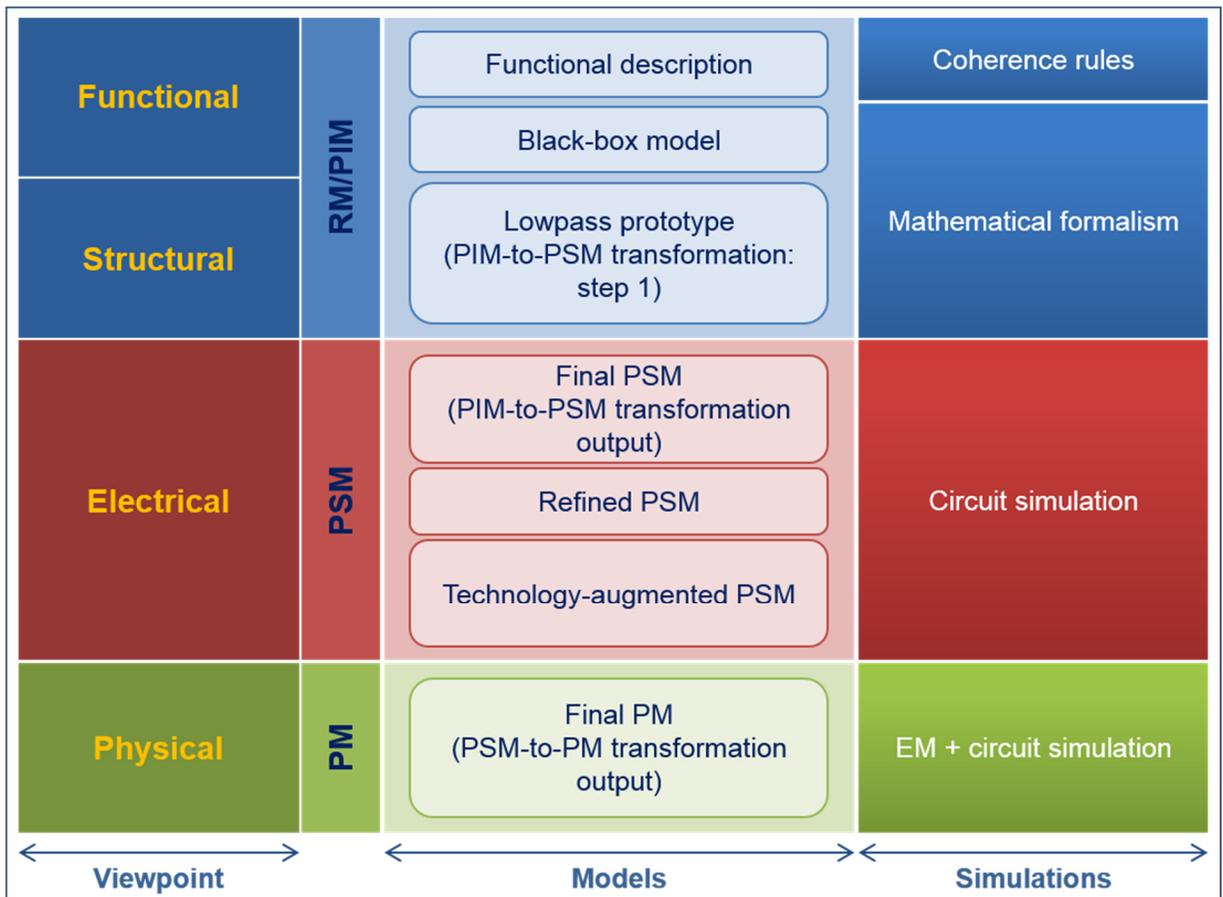


Figure 5.50 Simulation techniques versus filter models and design viewpoints

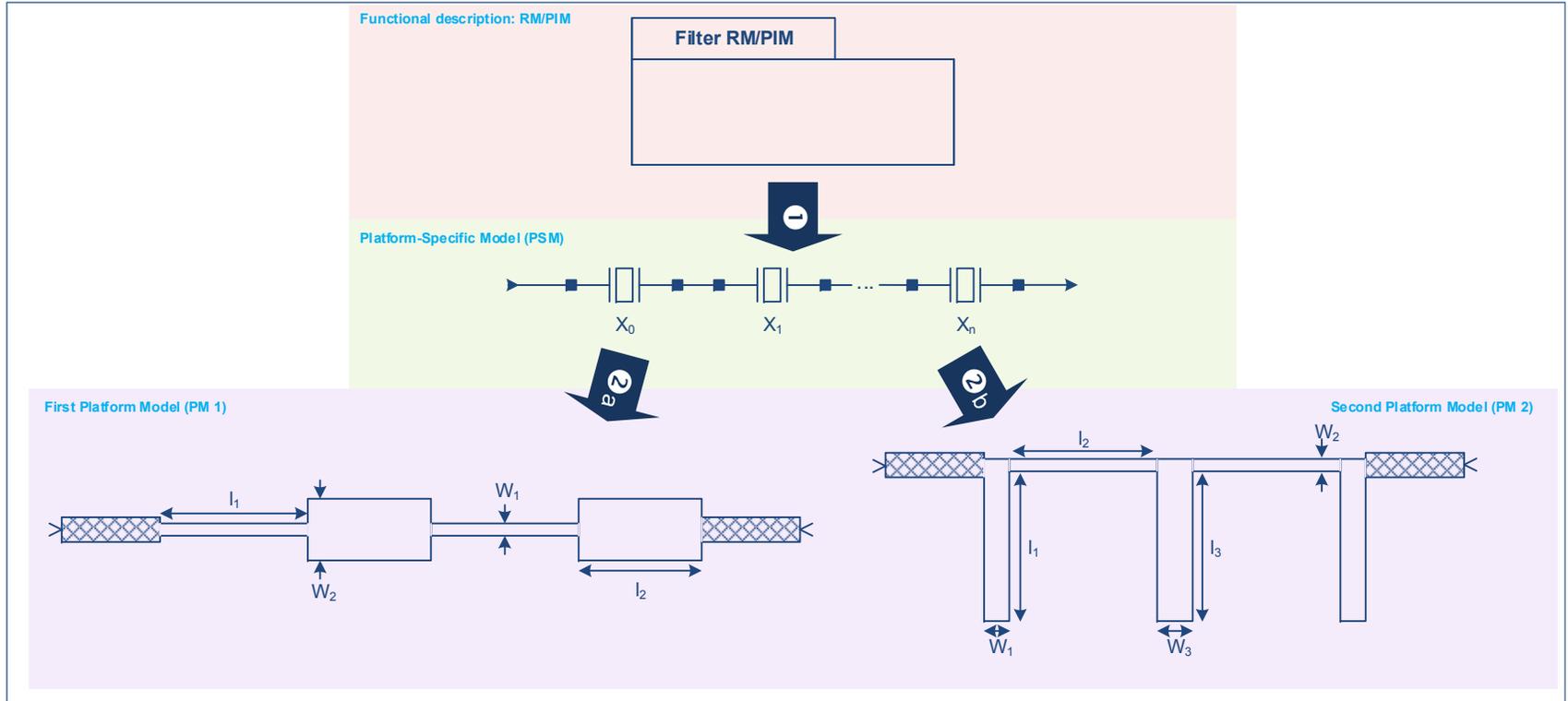


Figure 5.51 Using two cross-view transformations, the same lowpass filter PSM is derived into two separate platform models

## b) A 1-GHz microstrip lowpass filter

In this section, we attempt to illustrate how the proposed framework can be used for the design of a lowpass filter where multiple transformations are involved. As shown in Figure 5.51, we will use two PSM-to-PM transformations in order to derive two physical implementations of the lowpass filter. Unlike the previous case study, we will not detail all the design steps in the following. Only the most important design stages are presented.

- **Specifications**

We aim at designing a lowpass filter that meets the specifications enumerated in Table 5.18. A lowpass filter is a frequency selection device that passes the signals lower than a certain cutoff frequency ( $F_c$ ) while it attenuates those higher than  $F_c$ . Figure 5.52 illustrates the main parameters of a typical lowpass filter.

Table 5.18 Lowpass filter specifications

<b>Filter Type</b>	Lowpass
<b>Passband Attenuation (dB)</b>	< 0.1
<b>Stopband Attenuation (dB)</b>	> 25.0 @ 1800 MHz
<b>Cutoff Frequency (MHz)</b>	1000
<b>Termination Impedance (ohm)</b>	50
<b>Other Requirements</b>	Small form factor

- **Functional Description: SysML requirements and platform-independent models**

Using the same SysML models developed for the functional description of the bandpass filter and presented in the previous section, the lowpass filter functional description is developed alike. The resulting RM/PIM models are elaborated as given in the package diagram of Figure 5.8.

The RM/PIM consists of four main package:

- Filter definition: similarly to the bandpass, the lowpass filter is a two-port network that is hierarchically structured as illustrated in Figure 5.9 (see detailed bdd in Figure 5.10). On

the contrary to the bandpass, the lowpass device is a single-side filter. Thus, it inherits the properties of a single-side instead of a mid-band filter (see Figure 5.11). This difference is illustrated in Table 5.19 where the properties “*centerFrequency*” and “*bandwidth*” are replaced by their counterparts “*cutoffFrequency*” and “*stopbandEdgeFrequency*” (see gray-colored rows in Table 5.19). In addition, the value property belonging to the bandpass bdd, namely “*fractionalBandwidth*” is ignored in the lowpass case because it has no definition;

- Filter requirements: the lowpass requirements include performance and form factor specifications (see requirement diagram of Figure 5.49);
- Filter coherence rules: the lowpass coherent rules consist of the PIM-level design constraints, the electrical consistence rules, and the integrity control rules. The first rules are the same as for the bandpass filter while the second and the third ones are slightly different.

- **Analysis: Coherence verification**

As previously mentioned, the lowpass filter functional description include three types of coherence rules:

1. PIM-level design constraints: are the same as in Table 5.7;
2. Electrical consistence rules: include two sets of rules. The first is represented in the parameters relationships graph of Figure 5.54 and the corresponding equations are enumerated in Table 5.20. The second set consists of equations E.1 and E.2 of Table 5.6;
3. Integrity control rules: include the rules I.1 through I.32 of Table 5.8. The rules I.34 and I.35 are used only with mid-band (such as bandpass filters).

The functional description elaborated in the previous steps is checked using the coherence verification rules. The resulting coherence verification report is given in Figure 5.55.

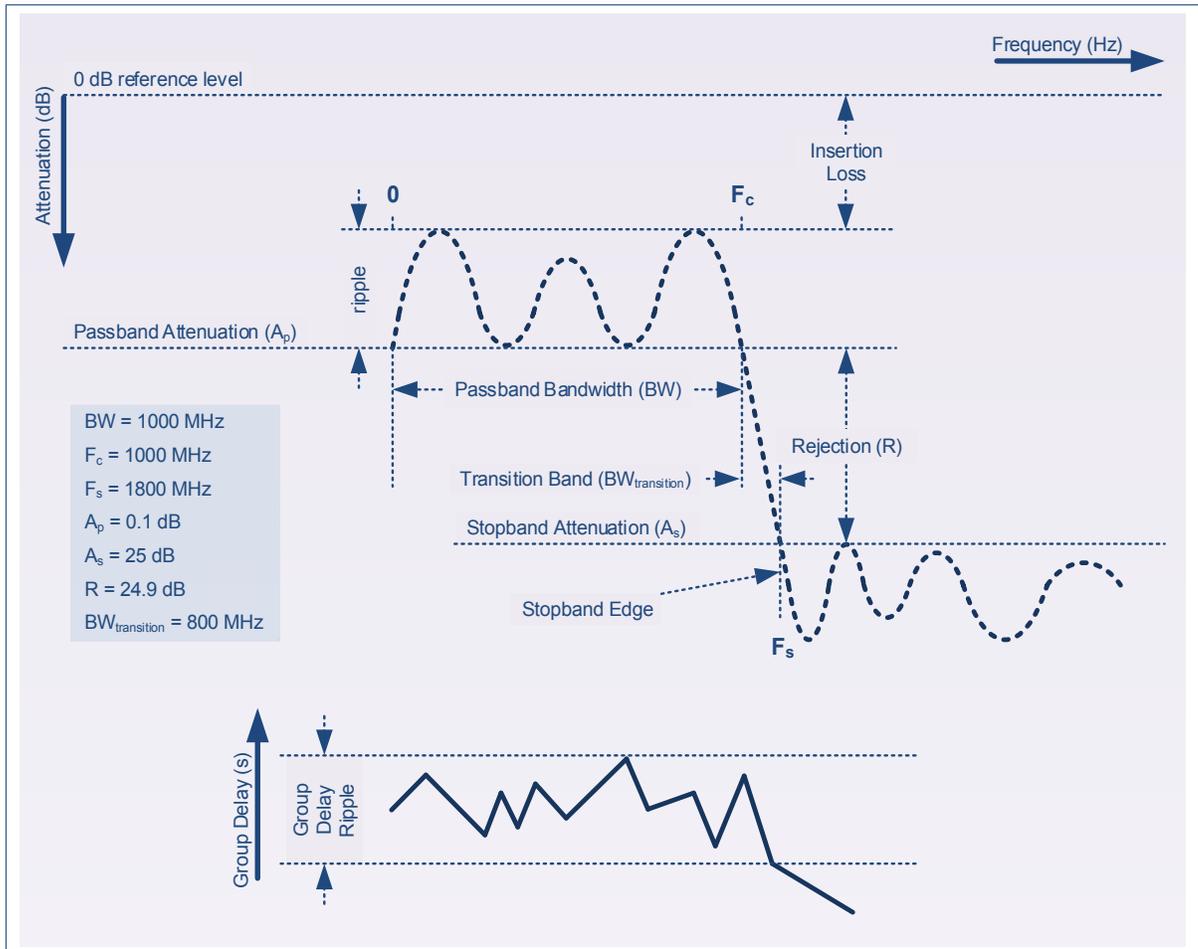


Figure 5.52 Typical parameters of a lowpass filter

- **Analysis: Design space exploration**

After submitting the functional description to the coherence verification, it is associated to a black-box model. In this case, we choose a Chebyshev Type I filter approximation as a black-box model (as given in equations A III-8, A III-9 and A III-10 in APPENDIX III, pp. 452-453). The design space exploration finds out an initial candidate design solution that satisfies the filter requirements. The black-box model has a frequency response as illustrated in Figure 5.56.

- **Analysis: PIM-to-PSM transformations**

As initially specified, we aim at using two separate PIM-to-PSM transformations in order to derive two different filter PSMs. This exercise is intended to verify the capacity of the design framework to enable concurrent design.

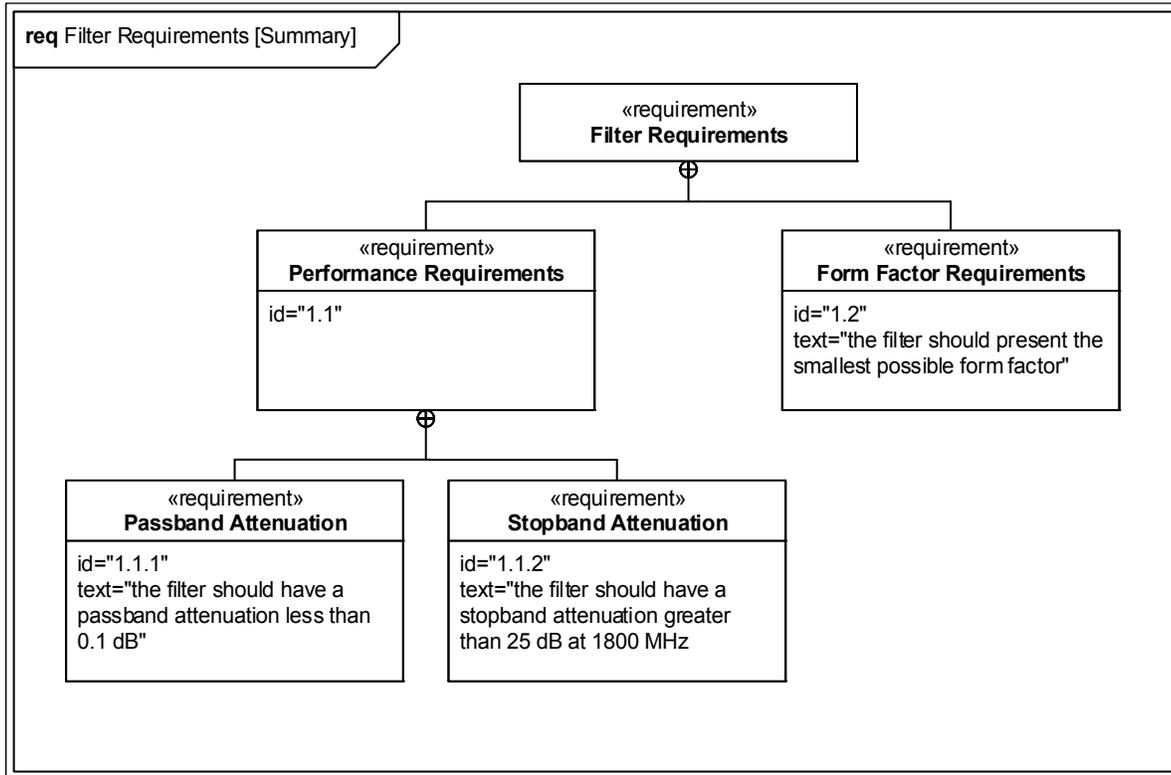


Figure 5.53 The requirements diagram of the lowpass filter

Table 5.19 List of lowpass filter value properties (port value properties are not considered)

Parameter Value	Type	Default Value	Remarks	Specifications Value
temperatureRange	interval (Celsius)	[-40, 80]		
ratingTemperature	Boolean	TRUE	TRUE FALSE	
portList	Object (Port)			
portsNo	integer	2		
fractionalBandwidth	double	20%		ignored
gain	array (dB)			Overridden by <i>passbandAttenuation</i> and <i>stopbandAttenuation</i>
qFactor	double			

Parameter Value	Type	Default Value	Remarks	Specifications Value
isolation	dB			Overridden by <i>filterSelectivity</i>
type	filterType	Butterworth	Bessel Butterworth Chebyshev Type I Chebyshev Type II Custom Elliptic	
ripple	array (dB)	0.25		
passbandAttenuation	array (dB)	3.0		
stopbandAttenuation	array (dB)	60.0		25.0 @1800 MHz
groupDelayRange	interval (seconds)	[0, 5E-6]		
ratingGroupDelay	Boolean		TRUE FALSE	
groupDelayRipple	interval (seconds)			
ratingGroupDelayRipple	Boolean			
order	integer			
shapeFactor	double			
filterSelectivity	dB			
cutoffFrequency	MHz			1000.0
stopbandFrequency	MHz			1800.0

We choose that the first PIM-to-PSM transformation generates a stepped-impedance-based lowpass filter PSM while the second derives another PSM that is based on open-end distributed lines:

1. Stepped-impedance lines transformation: it uses very high and very low characteristic impedance distributed lines to derive the inductive and capacitive sections of the filter PSM (see Table A III-2 in APPENDIX III, p. 456). The characteristic impedances depend on the type of distributed lines. In this case study, we use the mathematical formalism described in (Pozar, 2012, p. 470) to calculate each section properties but other formalisms can also

be considered (e.g., Hong et Lancaster, 2001, pp. 112-115). Table 5.21 presents the three main steps of the transformation;

- Open-end stub-based transformation: it uses large open-end circuit stubs to approximate capacitive elements while it considers thin distributed-line sections for inductive ones. To do so, it takes part of Richard's transformation that allows converting a capacitive (respectively inductive) lumped element into a distributed-line section approximating the same capacitive (respectively inductive) effect. In addition, it uses Kuroda's identities to separate the resulting filter elements using distributed-line sections (see Table A III-4 and Figure A III-1 in APPENDIX III, pp. 457-458). For simplicity, we use in this transformation steps the calculation method given in (Pozar, 2012, pp. 462-469). Other computation techniques are also available (e.g., Hong et Lancaster, 2001, pp. 115-119). The transformation consists of four key steps as illustrated in Table 5.22.

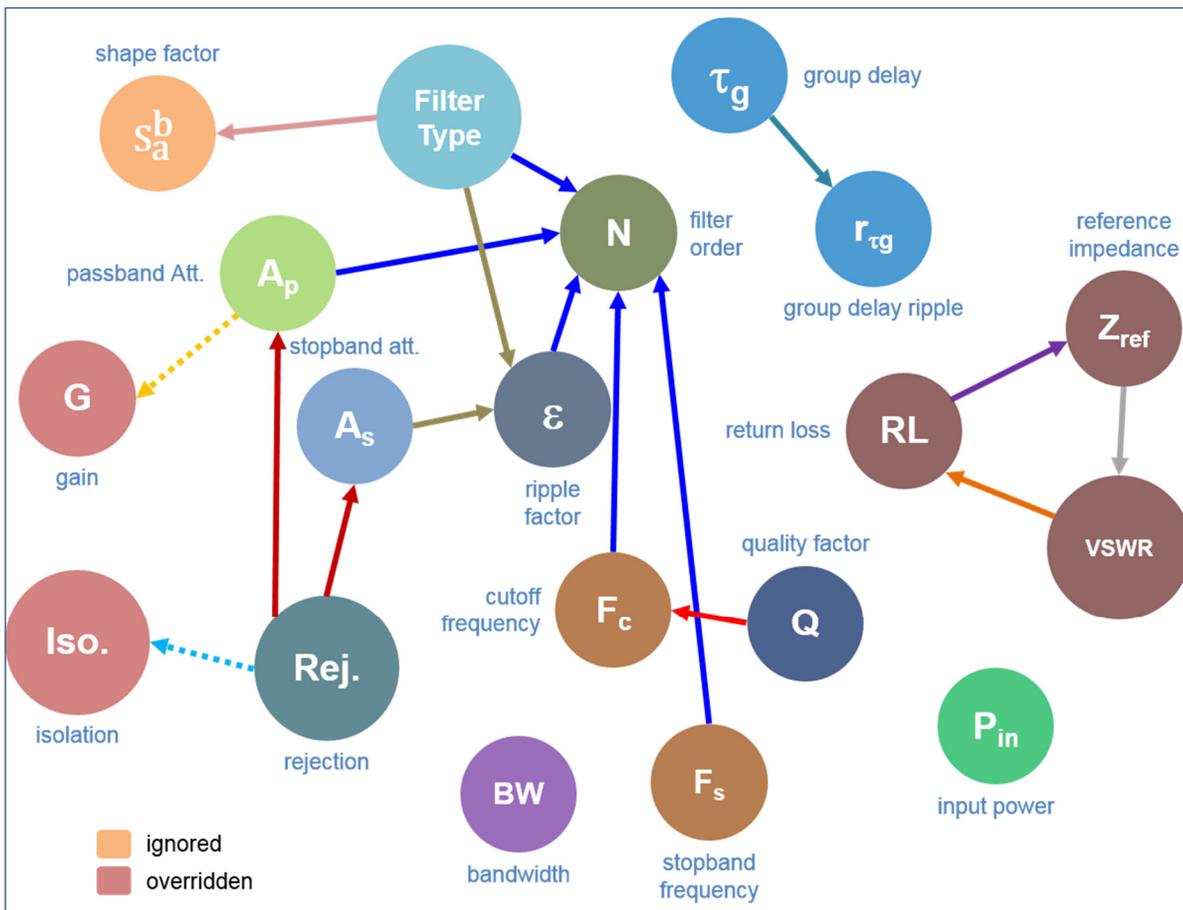


Figure 5.54 Lowpass filter parameters relationships graph

Table 5.20 Relationships between lowpass filter value properties given in Figure 5.54

Arrow Color	Mathematical Relationship	Parameter
●	$R = A_s _{F_s} - A_p _{F_p}$	Rejection (filter selectivity)
●	$N = \frac{\log\left(\frac{10^{\frac{A_s}{10}} - 1}{10^{\frac{A_p}{10}} - 1}\right)}{2\log\left(\frac{\omega_s}{\omega_p}\right)}$	Filter Order (Butterworth)
●	$\varepsilon = \frac{1}{\sqrt{10^{\frac{A_s}{10}} - 1}}$	Ripple Factor (Chebyshev)
●	$r_{\tau_g} = \max(\tau_g) _{[0,F_p]} - \min(\tau_g) _{[0,F_p]}$	Group Delay Ripple
●	$S_a^b = \left[ \frac{10^{A_s _{F_s}/10} - 1}{10^{A_p _{F_p}/10} - 1} \right]^{1/2N}$	Shape factor (Butterworth)
●	$Q = \frac{\omega_c}{2 \cos \theta_k}$	Quality Factor (Butterworth)
●	$VSWR = \frac{10^{\frac{RL}{20}} + 1}{10^{\frac{RL}{20}} - 1}$	Voltage Standing Wave Ratio
●	$RL = \frac{Z_L - Z_S}{Z_L + Z_S}$	Return Loss
●	$A_p = \textit{isolation}$	Passband Attenuation overrides Isolation property
●	$R = G$	Rejection (filter selectivity) overrides Gain property

In practice, the framework tools allow the parallel use of both transformations to derivate target PSMs from a unique source PIM. For clarity, we present hereafter each transformation separately.

```

***** Coherence Verification Test *****
TARGET PIM: 1-GHz LOWPASS FILTER (C:\Users\slafi\Documents\Design\lpf1GHz_pim.xml)

-> Electrical Consistence Rules (12 found)
..... PASS
-> PIM-level Design Constraints Rules (1 found)
..... PASS
-> Integrity Control Rules (33 found)
..... PASS
Summary: (0) Warnings (0) Errors

```

Figure 5.55 Lowpass filter coherence verification report

### a) Stepped-impedance lines transformation

- **Analysis: PSM generation**

The first transformation composed of three steps derives distributed-line sections to approximate capacitive and inductive components.

#### 1. Step 1: Determination of high and low characteristic impedances depending on target distributed lines

The low and high characteristic impedances for capacitive and inductive line sections are chosen at this step with respect to the following considerations (already enumerated in Hong et Lancaster, 2001, p. 113):

- System reference impedance: The reference impedance (commonly  $Z_0 = 50\Omega$ ) is higher (respectively lower) than the low (respectively high) characteristic impedance (i.e.,  $Z_{Low} < Z_0 < Z_{High}$ ).
- Feasible dimensions of capacitive sections: The lowest  $Z_{Low}$  is, the better the lumped-element capacitor approximation is. The lowest  $Z_{Low}$  is, the largest the corresponding line width  $W_C$  is. However,  $W_C$  is limited by  $W_{Cmax}$  causing transverse resonance to occur at operation frequencies.
- Feasible dimensions of inductive sections: The highest  $Z_{High}$  is, the better the lumped-element inductor approximation is. The highest  $Z_{High}$  is, the thinnest the corresponding line width  $W_L$  is. The practical implementation of the line section becomes dependent on the smallest feasible line width  $W_{Lmin}$ .

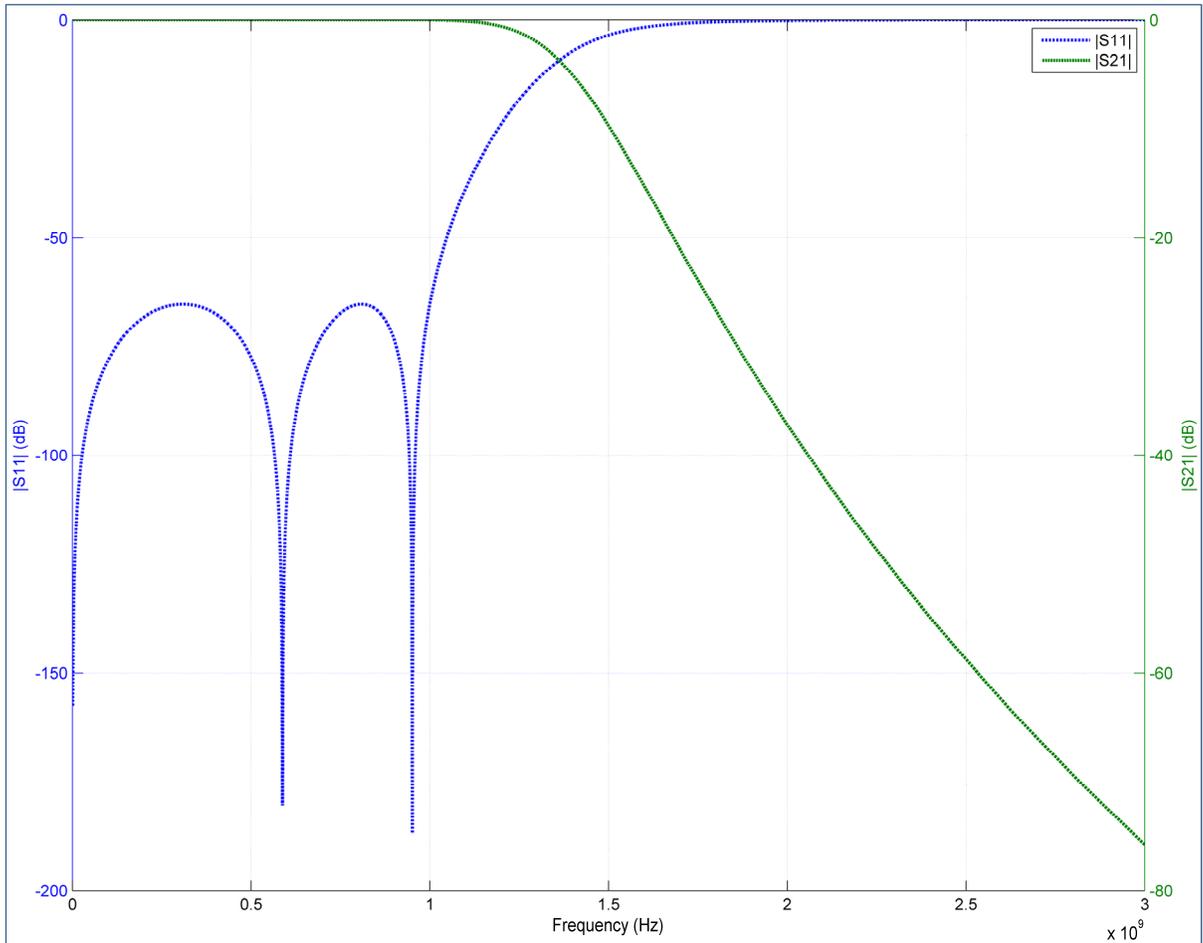


Figure 5.56 Black-box model frequency response: Chebyshev Type I approximation

The first step of PIM-to-PSM transformation is carried out in “Analysis” stage (i.e., RM/PIM domain). The target platform is known (i.e., distributed lines). Nevertheless, it is possible that there are little information about the implementation technology that are available at this stage. If so, default values may be used and adjusted later.

For this case study, we choose low and high characteristic impedances as following:

$$\begin{cases} Z_{Low} = 10\Omega \\ Z_{High} = 93\Omega \end{cases}$$

## 2. Step 2: Calculation of resonators normalized values

The normalized element values of the Chebyshev Type I lowpass filter prototype are calculated using the equations A III-8, A III-9 and A III-10 (APPENDIX III, pp. 452-453). The resulting

filter is an order 5 lowpass prototype whose normalized element values are listed in the second column of Table 5.23. Using the equations of Table A III-3 (p. 457), the electrical length of each section can be computed (see column 2 in Table 5.23).

Table 5.21 A PIM to PSM transformation for stepped-impedance lowpass filters

**Step 1: Determination of high and low characteristic impedances depending on target distributed lines (see considerations in Hong et Lancaster, 2001, p. 113)**

- 1.1. Specify low characteristic impedance ( $Z_{Low}$ ) for capacitive sections
- 1.2. Specify high characteristic impedance ( $Z_{High}$ ) for inductive sections

**Step 2: Calculation of resonators normalized values**

- 2.1. Calculate lowpass prototype (LPP) normalized values ( $g_k$ ) for Chebyshev Type I response approximation (see equations A III-8, A III-9 and A III-10, pp. 452-453)
- 2.2. Calculate corresponding electrical lengths ( $\beta l_k$ ) (see Table A III-3 in APPENDIX III, p. 457)

**Step 3: Synthesis of transmission lines and circuit topology**

- 3.1. For each capacitive resonator ( $\forall p \leq \frac{N}{2}$ ):

Consider the properties given in the following:

$$\begin{cases} Z_{ci} = Z_{Low} \\ E_i = \beta l_{2p} \\ F_i = F_c \\ A_i = A_{default} \end{cases}$$

- 3.2. For each inductive resonator ( $\forall p \leq \frac{N+1}{2}$ ):

Consider the properties given in the following:

$$\begin{cases} Z_{ci} = Z_{Low} \\ E_i = \beta l_{2p+1} \\ F_i = F_c \\ A_i = A_{default} \end{cases}$$

where  $Z_{ci}$  is the characteristic impedance of the distributed line,  $E_i$  is its electrical length,  $F_i$  is the frequency at which the electrical length is calculated and  $A_i$  is the transmission line loss (in dB).

**3. Step 3: Synthesis of transmission lines and circuit topology**

At this step, line sections are ideal. For each capacitive (respectively inductive) one, the assigned characteristic impedance is  $Z_{Low}$  ( $Z_{High}$  respectively). The electrical length is assigned as given in Table 5.23. The cutoff frequency  $F_c$  is assigned to the operation frequency. The resulting PSM is depicted in Figure 5.57.

Table 5.22 A PIM-to-PSM transformation based on open-end circuit stubs

<p><b>Step 1: Calculation of resonators normalized values</b></p> <p>1.1. Calculate lowpass prototype (LPP) normalized values (<math>g_k</math>) for Chebyshev Type I response approximation (see equations A III-8, A III-9 and A III-10, pp. 452-453)</p> <p><b>Step 2: Conversion of capacitive and inductive resonators using Richard's transformation (see Table A III-4, p. 457)</b></p> <p>2.1. Consider electrical length <math>\beta l = \frac{\lambda}{8}</math> for all filter prototype sections</p> <p>2.2. Convert shunt capacitive elements (<math>g_{2p}</math>) to shunt stubs</p> <p>2.3. Convert series inductive elements (<math>g_{2p+1}</math>) to series stubs</p> <p>2.4. Add unit elements (<math>Z_c = 1\Omega</math>)</p> <p><b>Step 3: Transformation of the filter sections using Kuroda identities</b></p> <p>3.1. Convert iteratively shunt into series stubs (and vice-versa) until getting a practically realizable filter sections (see Figure A III-1 in APPENDIX III, p. 454)</p> <p>3.2. Frequency and impedance scaling of all sections</p> <p><b>Step 4: Synthesis of transmission lines and circuit topology</b></p> <p>4.1. For each capacitive resonator (<math>\forall p \leq \frac{N}{2}</math>):</p> <p>Consider the properties given in the following:</p> $\left\{ \begin{array}{l} Z_{ci} = Z_{2p} \\ E_i = \frac{\lambda}{8} \\ F_i = F_c \\ A_i = A_{default} \end{array} \right.$ <p>4.2. For each inductive resonator (<math>\forall p \leq \frac{N+1}{2}</math>):</p> <p>Consider the properties given in the following:</p> $\left\{ \begin{array}{l} Z_{ci} = Z_{2p+1} \\ E_i = \frac{\lambda}{8} \\ F_i = F_c \\ A_i = A_{default} \end{array} \right.$ <p>where <math>Z_{ci}</math> is the characteristic impedance of the distributed line, <math>E_i</math> is its electrical length, <math>F_i</math> is the frequency at which the electrical length is calculated and <math>A_i</math> is the transmission line loss (in dB).</p>
---

- **Synthesis: Technology mapping**

After performance assessment, the obtained PSM goes through PSM granularity refinement if required. Then, the PSM is submitted to technology. In this case study, we choose microstrip transmission lines as implementation technology. We also use Rogers 3006 as a substrate (see its properties in Table 5.24). Having no off-the-shelf components to consider, technology mapping consists in this case study of synthesizing a microstrip line for each filter section.

Using a dedicated tool (e.g., LineCalc) and the calculations resulting from the PIM-to-PSM transformation as well as the technology input given in Table 5.24, we determine the physical dimensions (i.e., width and length) of each filter section. The results are reported in the last two columns of Table 5.23 and the resulting filter’s PSM is illustrated in Figure 5.58.

Table 5.23 Calculations resulting from the stepped-impedance-based (PIM-to-PSM) transformation

Step Impedance ( $\Omega$ )	Normalized Values ( $g_i$ )	Electrical Length ( $^\circ$ )	Physical Dimensions (mil)	
			Width	Length
$Z_{\text{high}} = 93.0$	1.146837827800645	13.141793	8.117520	218.300394
$Z_{\text{low}} = 10.0$	1.371209987510143	42.239003	324.938976	592.850394
$Z_{\text{high}} = 93.0$	1.975027577855714	22.632149	8.117559	375.946457
$Z_{\text{low}} = 10.0$	1.371209987510143	42.239003	324.938976	592.850394
$Z_{\text{high}} = 93.0$	1.146837827800645	13.141793	8.117520	218.300394

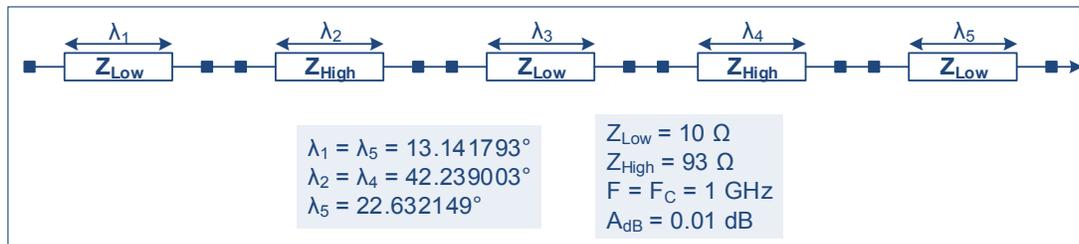


Figure 5.57 First PSM: The stepped-impedance lowpass filter

Table 5.24 Main properties of the RO3006 substrate

Dielectric Constant ( $\epsilon_r$ )	6.15	
Magnetic Constant ( $\mu_r$ )	1	
Loss Tangent ( $\tan \delta$ )	0.0025	
Resistivity ( $\sigma_1$ )	1	
Metal Thickness (t)	0.71 mil	
Metal Roughness (Sr)	0.075 mil	
Substrate Height (h)	25 mil	

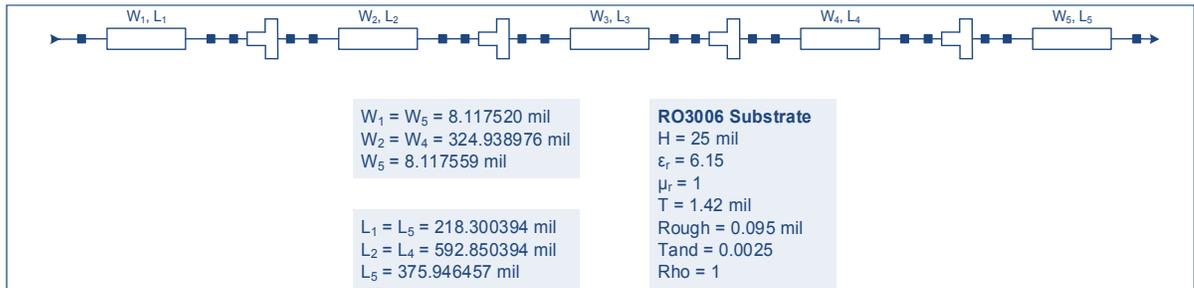


Figure 5.58 First PSM after technology mapping

If the default platform considerations were used in the first step of the PIM-to-PSM transformation (i.e., low and high characteristic impedances), it is possible to adjust values in the technology mapping step and make the PSM more accurate.

Table 5.25 Lowpass stepped-impedance filter PM form factor

PM	Width (mm)	Length (mm)	Average Area (mm <sup>2</sup> )
Transformation output	54.9783	6.84878	376.53427
Optimization (round 1)	58.16422	5.08	295.47425
Optimization (round 2)	42.45915	22.86	970.61613

- **Synthesis: PM generation**

After eventual PSM optimization (including through granularity refinement) and performance assessment, the final PSM is transformed into a platform model. For this purpose, we use a commercial design package to derive the filter PM (i.e., layout) directly from the PSM. Using Keysight ADS, we obtain the platform model illustrated in Figure 5.59.a. Then, the physical structure of the filter is simulated using an EM solver to evaluate its performance. We carried out several optimization iterations for the purpose of enhancing the frequency response of the obtained PM. In each iteration, the physical properties of the PM (such as the length and width of the microstrip sections) were altered. Figure 5.59.b and 5.59.c depict the best optimizations of the obtained PM. The form factor of each PM was also estimated in the Table 5.25. In addition, Figure 5.60 illustrates the evolution of the lowpass filter frequency response throughout the design cycle. In addition to the black-box model (PIM level) and layout (PM

level) performance, the PSM frequency response after PIM-to-PSM transformation, technology and optimization is also illustrated.

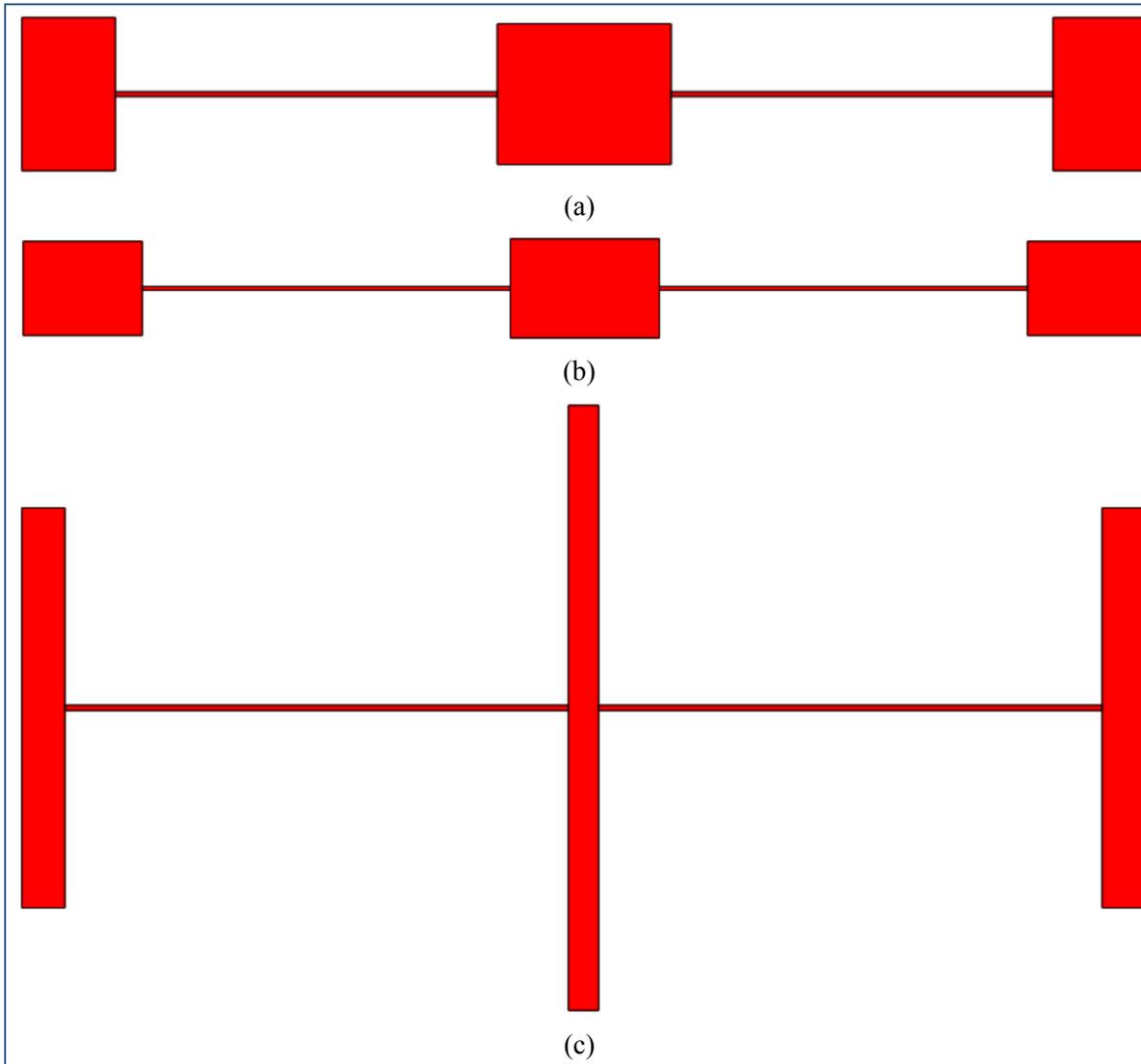


Figure 5.59 Lowpass filter stepped-impedance platform model: (a) transformed, (b) first- and (c) second-round optimizations

## b) Open-end stub-based transformation

- **Analysis: PSM generation**

The second transformation generates open-end stubs sections for the lowpass filter. It consists of four steps:

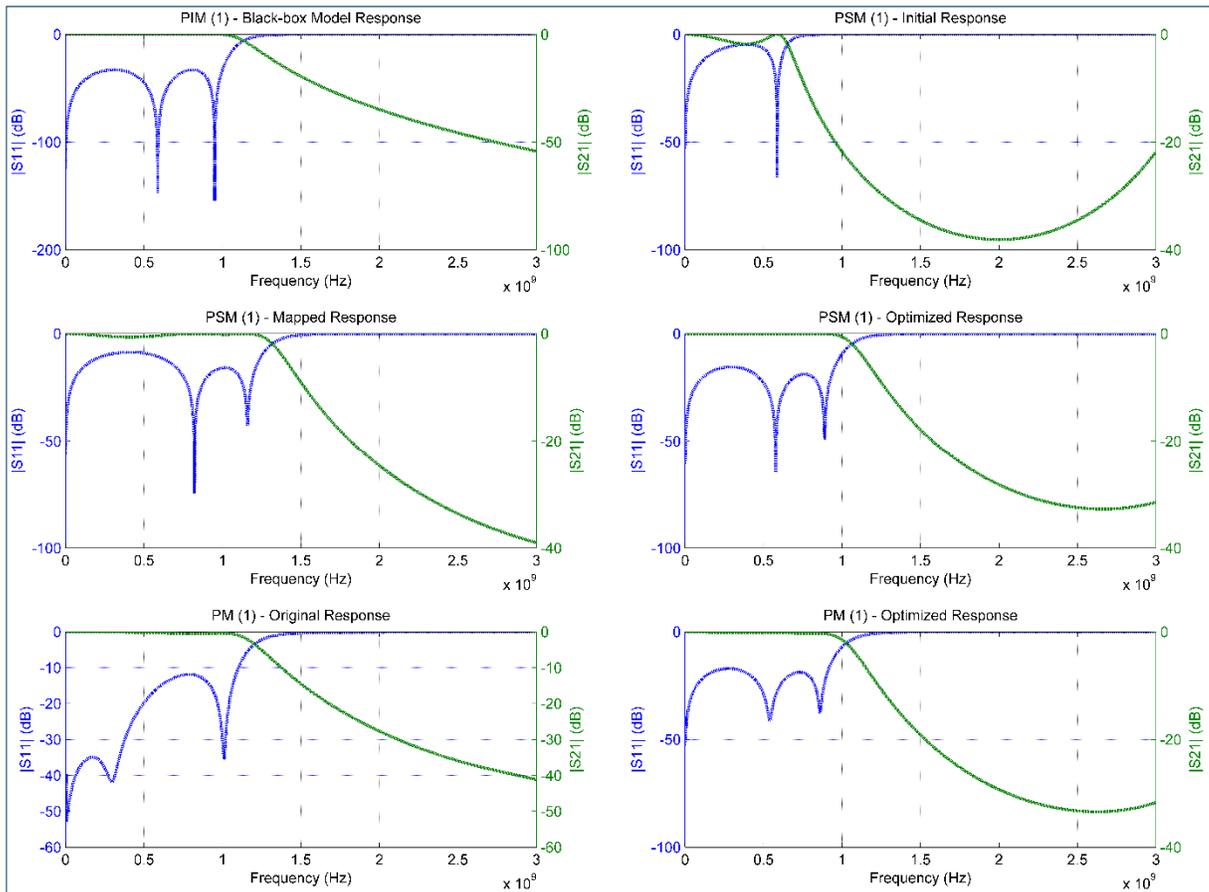


Figure 5.60 Frequency response of the stepped-impedance lowpass prototype in key design steps

### 1. Step 1: Calculation of resonators normalized values

In the first step, we use the equations A III-8, A III-9 and A III-10 (in APPENDIX III, pp. 452-453) to calculate the normalized element values of the lowpass filter prototype (see column one in Table 5.26).

### 2. Step 2: Conversion of capacitive and inductive resonators using Richard's transformation (see Table A III-4, p. 457)

The prototype normalized element values correspond to the capacitive and inductive filter components. Using the Richard's transformation given in Table A III-4 (APPENDIX III, p. 457), the series inductors (respectively shunt capacitors) are converted to series subs (respectively shunt stubs).

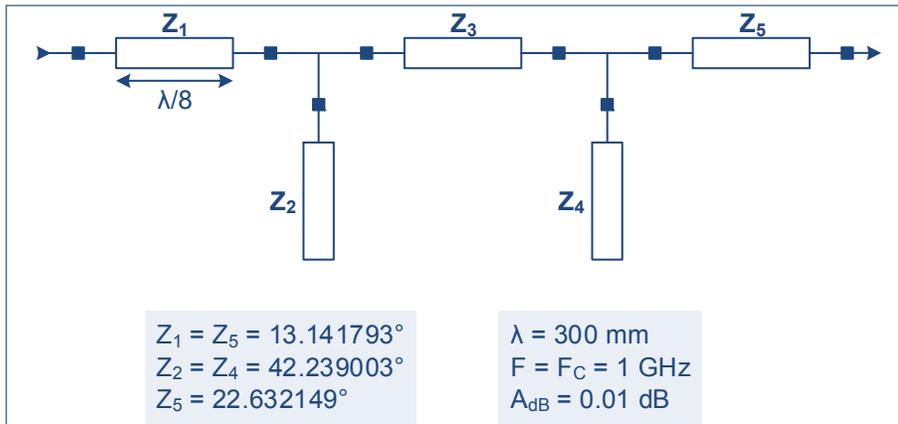


Figure 5.61 Second PSM: The open-end stub lowpass filter

### 3. Step 3: Transformation of the filter sections using Kuroda identities

Since the series stubs are very difficult to realize in practice, we should convert them into feasible structures. We use Kuroda identities given in Figure A III-1 (p. 458) to iteratively derive new transmission line sections from these stubs. We get the normalized characteristic impedances listed in the second column of Table 5.26. After frequency and impedance scaling, we get the true characteristic impedance of each stub (see third column of Table 5.26).

### 4. Step 4: Synthesis of transmission lines and circuit topology

In the last step, we create the PSM circuit topology. We assign an operation frequency, an electrical length and a characteristic impedance to each line section. The resulting PSM is illustrated in Figure 5.61.

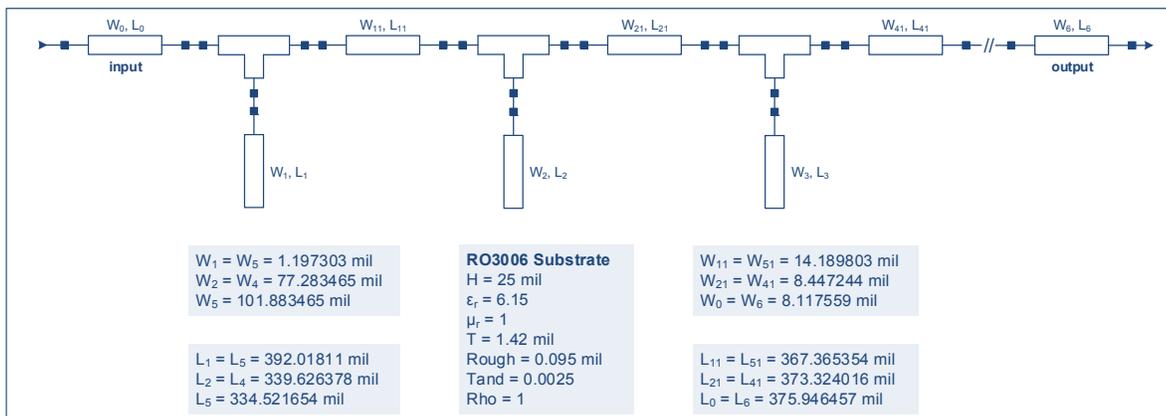


Figure 5.62 Second PSM after technology mapping

- **Synthesis: Technology mapping**

After performance assessment and the eventual granularity refinement, the technology mapping is carried out. The resulting PSM (composed so far of ideal elements) is enriched with the appropriate technology information. In this case, the technology input to consider is the type of technology (i.e., microstrip) and associated substrate (i.e., RO3006). Using a commercial line synthesis tool (i.e., LineCalc), we synthesized the physical dimensions that fit with the characteristic impedance and electrical length at the operation frequency (i.e.,  $\beta l = \frac{\lambda}{8} = 22.5^\circ$ ). The length and width of each line section is given in the last two columns of Table 5.26.

Table 5.26 Calculations resulting from the open-end stub-based transformation

Normalized Values ( $g_i$ )	Normalized Line Impedance ( $\Omega$ )	Line Impedance ( $\Omega$ )	Physical Dimensions (mil)*	
			Width	Length
1.146837827800645	2.864	143.2	1.197303	392.01811
	1.5342	76.71	14.189803	367.365354
1.371209987510143	0.624	31.2	77.283465	339.626378
	1.837	91.85	8.447244	373.324016
1.975027577855714	0.5128	25.64	101.883465	334.521654
1.371209987510143	1.837	91.85	8.447244	373.324016
	0.624	31.2	77.283465	339.626378
1.146837827800645	1.5342	76.71	14.189803	367.365354
	2.864	143.2	1.197303	392.01811

(\*) Associated Electrical Length:  $22.5^\circ$  ( $\lambda/8$ )

- **Synthesis: PM generation**

To derive the final layout of the open-end stub-based lowpass filter, we use a PSM-to-PM transformation that consists of a commercial design package. Using Keysight ADS, we generate the filter's layout depicted in Figure 5.63.a. After many optimization iterations, we obtained the final layout illustrated in Figure 5.63.b. Regarding the form factor requirement, Table 5.27 gives an estimation of the final dimensions of both the original and optimized layouts.

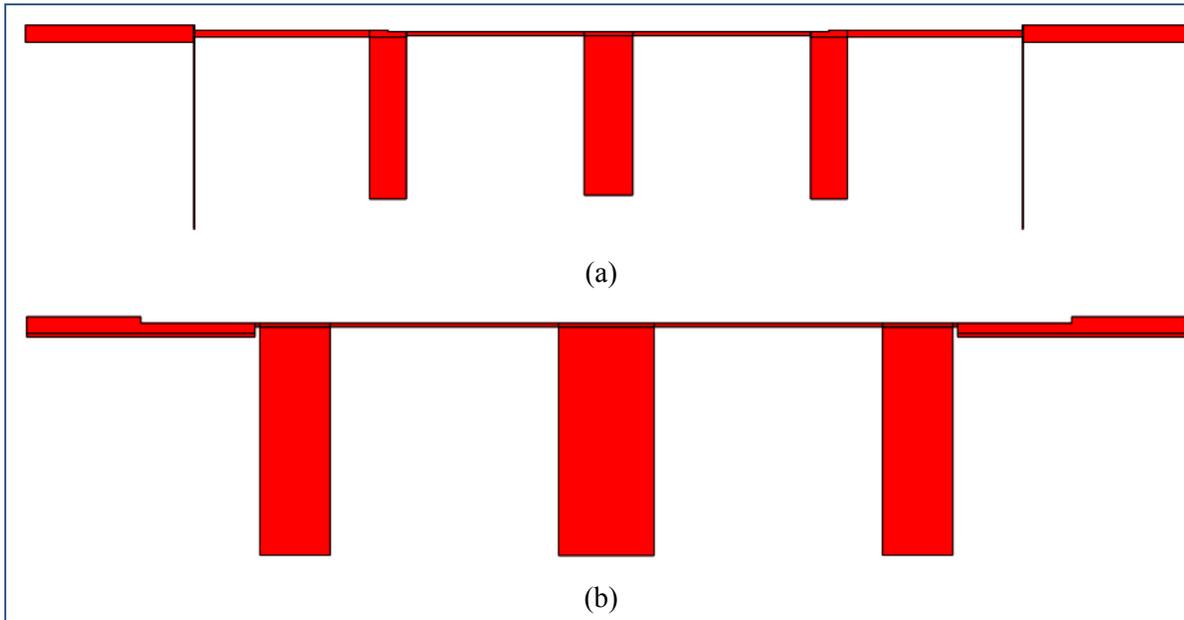


Figure 5.63 Lowpass filter open-end stub-based platform model: (a) transformed, (b) best optimization round

Table 5.27 Lowpass open-end stub-based filter PM form factor

PM	Width (mm)	Length (mm)	Average Area (mm <sup>2</sup> )
Transformation output	13.335	56.5404	753.966234
Best optimization	13.208	64.4906	851.7918448

The lowpass filter was submitted to several rounds of performance assessment and optimization from the RM/PIM through PM domains. Figure 5.64 illustrates the filter's frequency response at the PIM level (i.e., the black-box model). In the PSM domain, the frequency response of the filter are illustrated after PIM-to-PSM transformation, technology mapping and optimization. Then, it is illustrated after PSM-to-PM transformation and best optimization iteration.

Finally, the Q-matrix of Figure 5.65 depicts the design data stored in each design step for both techniques (i.e., stepped-impedance lines, open-end stubs). Each Qblock includes the data for a design iteration. Having all this data in the same file, it becomes easier to make performance comparisons between design techniques. For instance, Figure 5.66 shows a comparison between the stepped-impedance and open-end stub-based filter prototypes. The frequency

response (particularly within the transition band) of the latter is better than the former. This result is expected because the coarse approximations involved in the stepped-impedance filter degrade the overall performance (Pozar, 2012, p. 470).

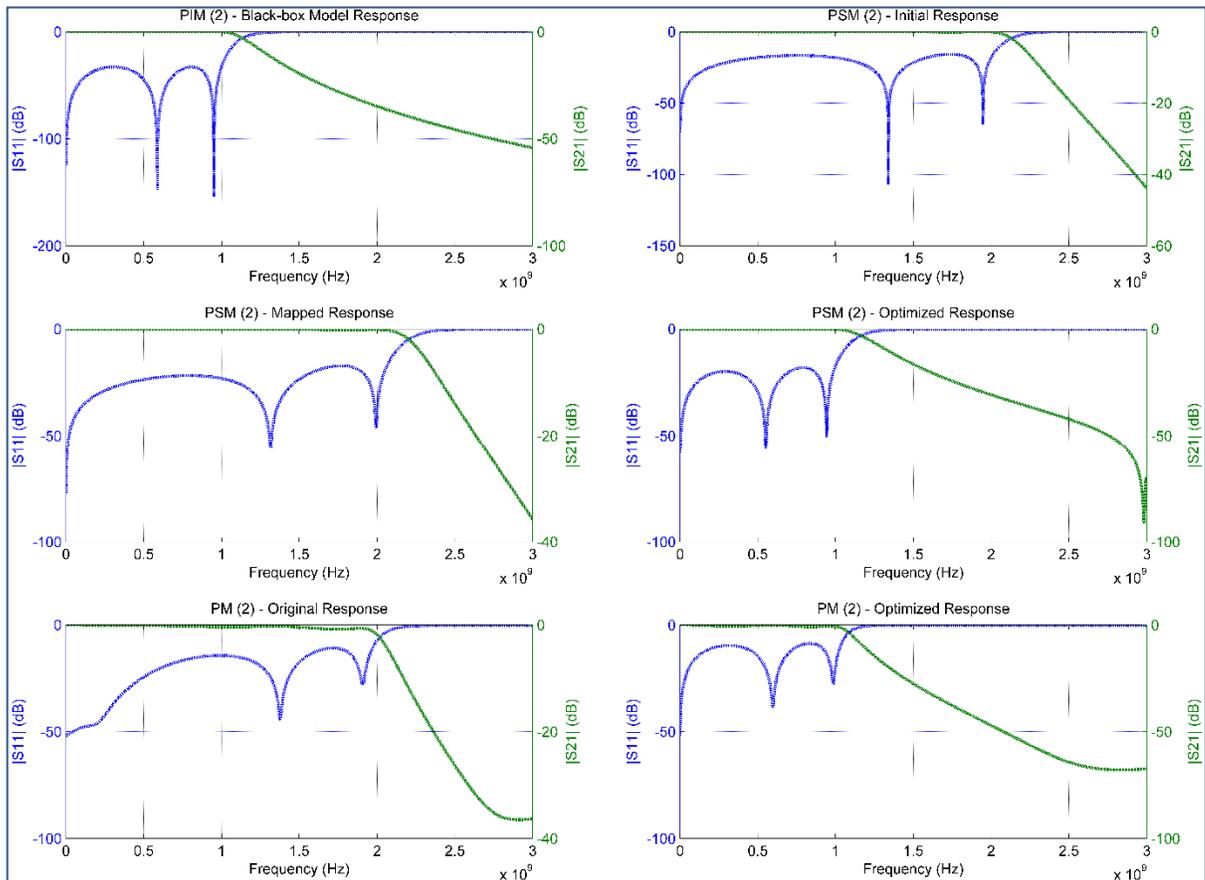


Figure 5.64 Frequency response of the open-end stubs lowpass prototype in key design steps

### 5.3.2 Power Attenuation Device

In this case study, we attempt to use the proposed framework for concurrent design. We undertake the design of a power attenuation device, an attenuator. We develop in parallel two prototypes that are optimized, validated and compared throughout the design cycle.

```

<Qmatrix>
  <Qblock name="lpf_specs" source="pim_rm_01"></Qblock>
  <Qblock name="lpf_bb_model" source="pim_round_01"></Qblock>
  <Qblock name="lpf_stepped_ideal" source="pim_rm_analysis_round_01"></Qblock>
  <Qblock name="lpf_stepped_ideal_opt_1" source="pim_rm_analysis_round_02"></Qblock>
  <Qblock name="lpf_stepped_mapped_original" source="pim_to_psm_transformation_round_01"></Qblock>
  <Qblock name="lpf_stepped_mapped_opt_1" source="pim_to_psm_transformation_round_02"></Qblock>
  <Qblock name="lpf_stepped_mapped_opt_2" source="pim_to_psm_transformation_round_03"></Qblock>
  <Qblock name="lpf_stepped_mapped_opt_3" source="pim_to_psm_transformation_round_04"></Qblock>
  <Qblock name="lpf_stepped_mapped_opt_4" source="pim_to_psm_transformation_round_04"></Qblock>
  <Qblock name="lpf_stepped_pm_original" source="psm_to_pm_transformation_round_01"></Qblock>
  <Qblock name="lpf_stepped_pm_opt_1" source="psm_to_pm_transformation_round_02"></Qblock>
  <Qblock name="lpf_stepped_pm_opt_2" source="psm_to_pm_transformation_round_03"></Qblock>
  <Qblock name="lpf_open_end_ideal" source="pim_rm_analysis_round_01"></Qblock>
  <Qblock name="lpf_open_end_ideal_opt_1" source="pim_rm_analysis_round_02"></Qblock>
  <Qblock name="lpf_open_end_mapped_original" source="pim_to_psm_transformation_round_01"></Qblock>
  <Qblock name="lpf_open_end_mapped_opt_1" source="pim_to_psm_transformation_round_02"></Qblock>
  <Qblock name="lpf_open_end_mapped_opt_2" source="pim_to_psm_transformation_round_03"></Qblock>
  <Qblock name="lpf_open_end_mapped_opt_3" source="pim_to_psm_transformation_round_04"></Qblock>
  <Qblock name="lpf_open_end_mapped_opt_4" source="pim_to_psm_transformation_round_04"></Qblock>
  <Qblock name="lpf_open_end_pm_original" source="psm_to_pm_transformation_round_01"></Qblock>
  <Qblock name="lpf_open_end_pm_opt_1" source="psm_to_pm_transformation_round_02"></Qblock>
  <Qblock name="lpf_open_end_pm_opt_2" source="psm_to_pm_transformation_round_03"></Qblock>
  <Qblock name="lpf_open_end_pm_opt_3" source="psm_to_pm_transformation_round_04"></Qblock>
  <Qblock name="lpf_open_end_pm_opt_4" source="psm_to_pm_transformation_round_05"></Qblock>
</Qmatrix>

```

Figure 5.65 Overview of the Qblocks added to the filter's Q-matrix through the design cycle

- **Specifications**

On the contrary to filters, an attenuator is a radiofrequency device that degrades intentionally the signal level in a wide frequency band and beyond. Various types of attenuators (e.g., fixed, switched or continuously variable) are used for either circuit protection from high-signal levels or to provide accurate impedance matching. Among the key properties of an attenuator, we count the attenuation level, frequency range to which that attenuation applies and the input / output impedances. For this case study, we consider the specifications listed in Table 5.28.

Table 5.28 Typical specifications of a 3-dB RF attenuator

<b>Attenuation level (dB)</b>	3.0
<b>Frequency Range (MHz)</b>	0 – 2000 MHz
<b>Noise Figure (dB)</b>	< 0.5
<b>Termination Impedance (ohm)</b>	50
<b>Other Requirements</b>	Small form factor

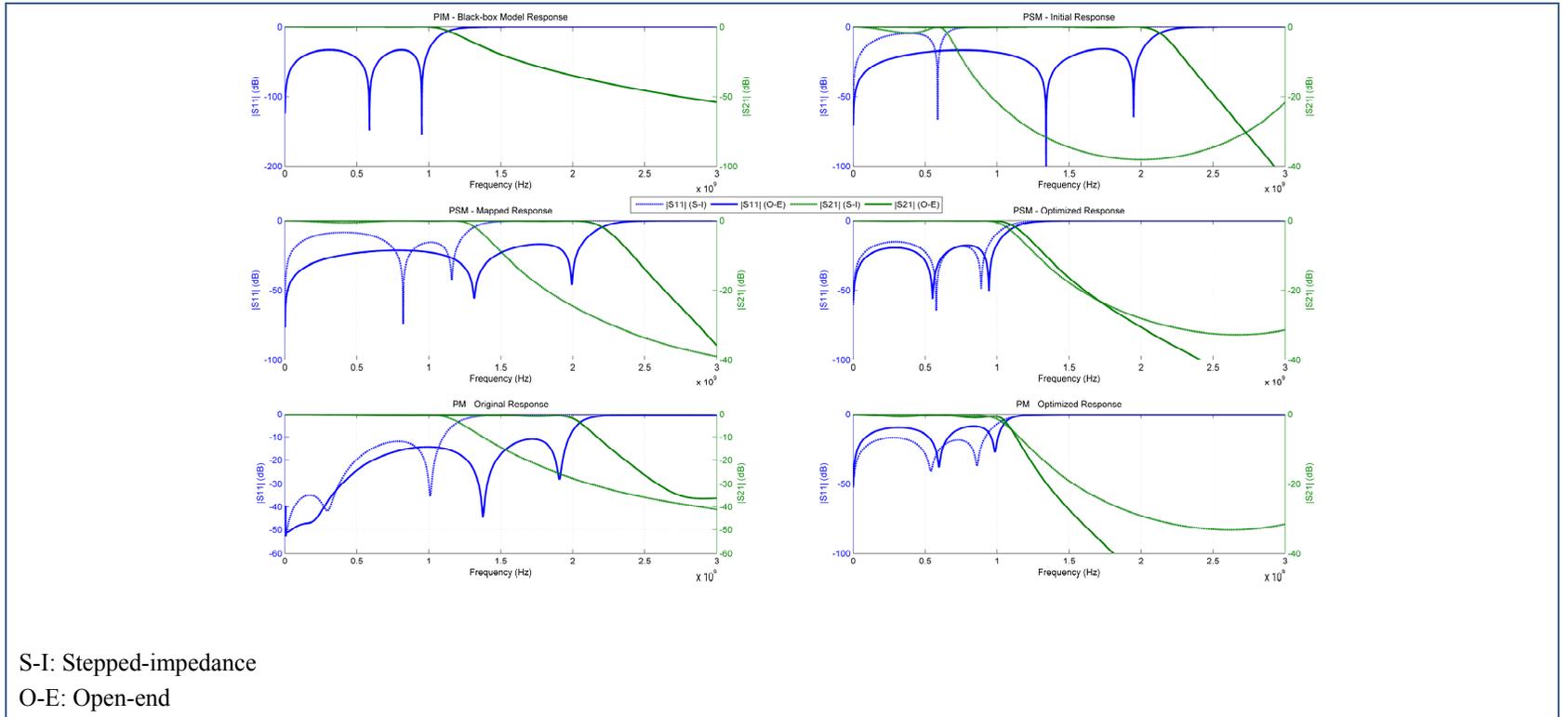


Figure 5.66 Comparison between the performance of the stepped-impedance and open-end stub-based filter prototypes in different design stages

- **Functional Description: SysML requirements and platform-independent models**

The SysML diagrams used for the attenuator's functional description are similar to those elaborated for bandpass and lowpass filters. The package diagram of Figure 5.67 depicts the main constituents of the functional description:

- Attenuator definition: this package defines the functional and structural aspects of the attenuator. Its general organization is inspired from the RF stereotypes bdd illustrated in Figure 4.50. For example, the bdd of Figure 5.68 shows the properties of the attenuator block as well as the hierarchy of blocks related to it. Thus, an attenuator inherits the properties of the « Power Attenuation and Matching Device », which is itself a linear two-port network. The complete list of attenuator values are given in Table 5.29. The values of « Port » block are provided separately in Table 5.30;
- Attenuator requirements: as shown in Figure 5.69, the requirements related to the attenuator design are similar to those depicted in Figure 4.55. In this case, the attenuator requirements can be subdivided into two major categories: performance and form factor. The first includes the required attenuation level and its associated frequency range. The second summarizes the requirements related to the form and size of the device;
- Attenuator coherence rules: the functional description of the attenuator is submitted in the next design stage, namely « Analysis ». The related rules are assembled in « Coherence Rules » package (see Figure 5.67) that is detailed in the next design stage;
- Value types: this package defines the units, constants and other modeling artifacts used in the other packages. As illustrated in Figure 5.70, the units used in attenuator definition bdds to define values' types are reported.

It is worth noting that the SysML diagrams shown in this section are part of the attenuator functional description but not exhaustive and presented for illustration purposes only.

- **Analysis: Coherence verification**

The attenuator's functional description should be submitted to coherence verification at this step in order to figure out any eventual errors. The set of rules used for this process is composed of electrical consistence and integrity controls rules. No PIM-level design constraints' rules are defined for this case study.

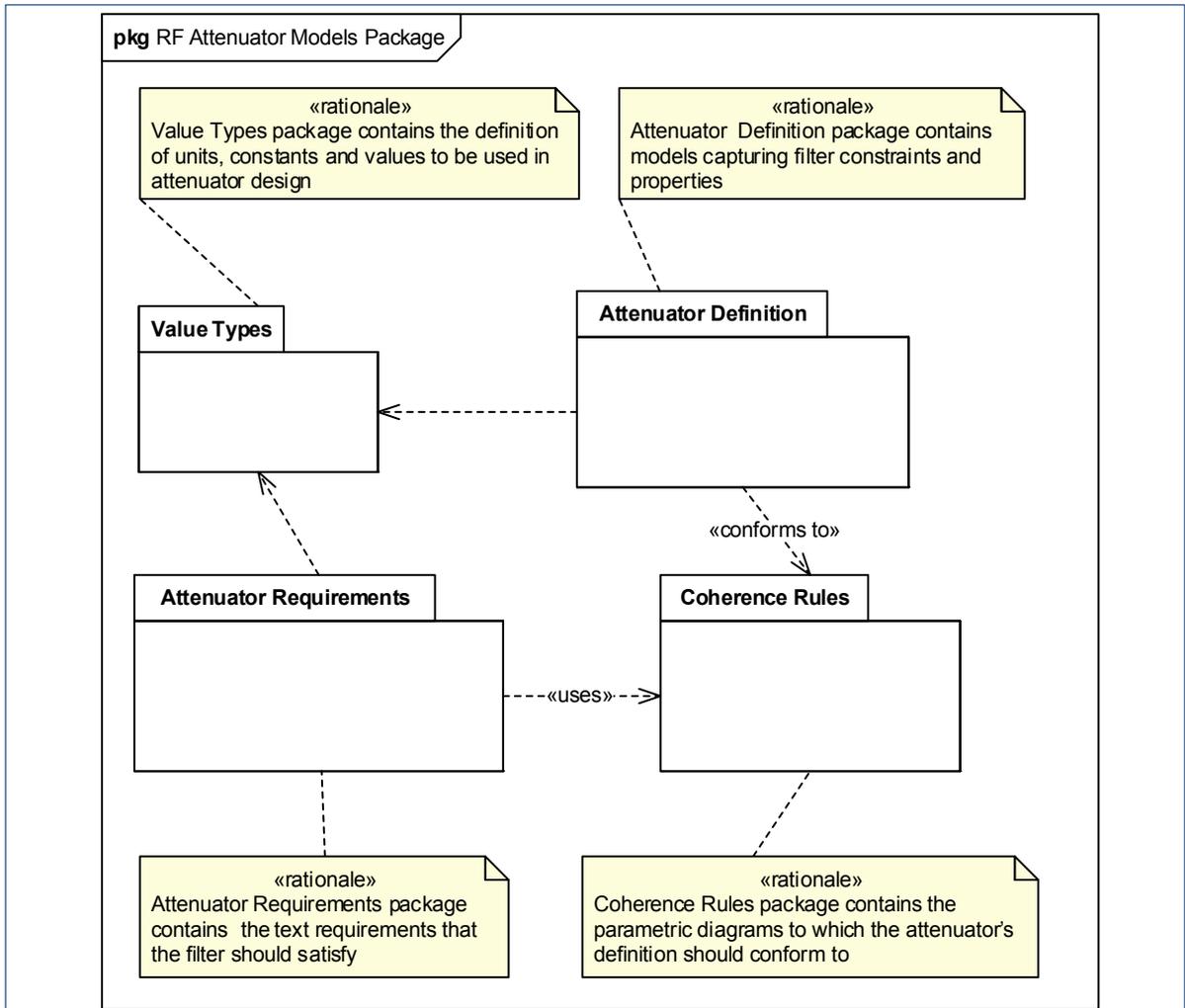


Figure 5.67 Attenuator functional description overview: RM/PIM packages

- The electrical consistence rules: the goal of these rules is to check the coherence between the various attenuator value properties. We defined a set of rules based on the equations of Table 5.31. These rules are mapped to the attenuator parameters as depicted in Figure 5.71;
- The integrity controls rules: the attenuator value properties must be defined within a predefined range. The integrity rules listed in Table 5.32 check if each value property is unusually sized.

Using a dedicated algorithm, the attenuator's functional description is checked against the 43 rules (i.e., eleven for electrical consistence and thirty two for integrity control tests). The resulting coherence verification report is depicted in Figure 5.72.

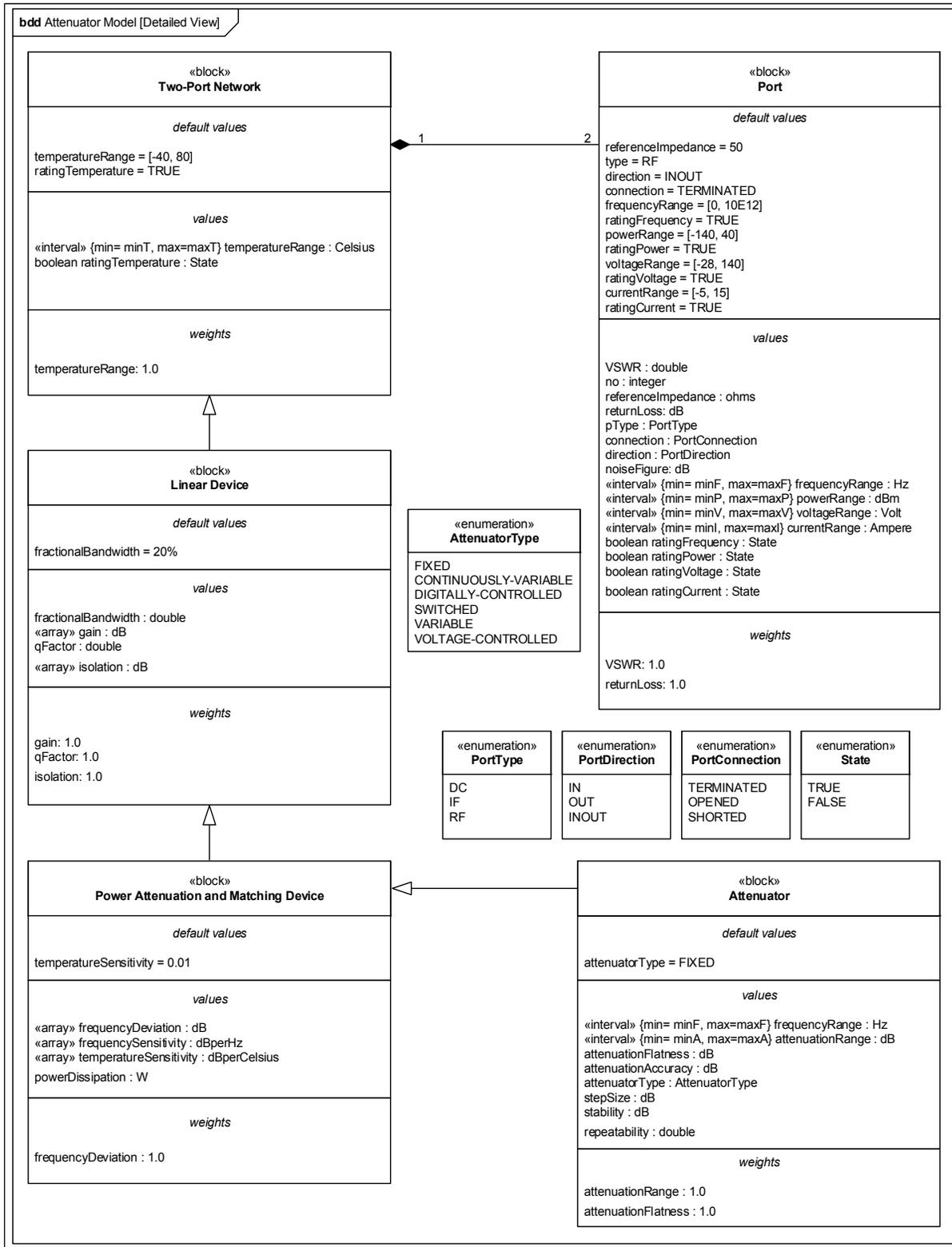


Figure 5.68 The detailed attenuator’s block definition diagram

Table 5.29 List of values of « Attenuator » block

Parameter Value	Type	Default Value	Remarks	Specifications Value
temperatureRange	interval (Celsius)	[-40, 80]		
ratingTemperature	Boolean	TRUE	TRUE FALSE	
portList	Object (Port)			
portsNo	integer	2		
fractionalBandwidth	double	20%		ignored
gain	array (dB)			Overridden by <i>attenuationRange</i>
qFactor	double			
isolation	dB			Overridden by <i>attenuationRange</i>
temperatureSensitivity	dBperCelsius	0.01		
frequencyDeviation	dB			
frequencySensitivity	dBperHz			
powerDissipation	W			
attenuatorType	AttenuatorType	FIXED	FIXED CONTINUOUSLY-VARIABLE DIGITALLY-CONTROLLED SWITCHED VARIABLE VOLTAGE-CONTROLLED	
frequencyRange	Hz			min.: 0 max.: 2000 MHz
attenuationRange	dB			3.0
attenuationFlatness	dB			
attenuationAccuracy	dB			
stepSize	dB			
stability	dB			
repeatability	double			

Table 5.30 List of values of each « Port » block

Parameter Value	Type	Default Value	Remarks	Specifications Value
VSWR	double			
no	integer			1 (2)
referenceImpedance	double (ohms)	50.0		50.0 (50.0)
returnLoss	dB			
noiseFigure	dB			max. 0.5 (max. 05)
pType	PortType	RF	DC IF RF	
direction	PortDirection	INOUT	IN OUT INOUT	
connection	PortConnection	TERMINATE D	TERMINATED OPENED SHORTED	
frequencyRange	interval (Hz)	[0, 10E12]		
ratingFrequency	Boolean	TRUE	TRUE FALSE	
powerRange	interval (dBm)	[-140, 40]		
ratingPower	Boolean	TRUE	TRUE FALSE	
voltageRange	interval (volts)	[-28, 140]		
ratingVoltage	Boolean	TRUE	TRUE FALSE	
currentRange	interval (amperes)	[-5, 15]		
ratingCurrent	Boolean	TRUE	TRUE FALSE	

After coherence verification comes design exploration where a black-box model is associated to the functional description in the purpose of finding out a suitable design solution. The black-box model is given by the equation (A III-17, p. 458) of APPENDIX III. A first assessment of the black-box model results in the curves given in Figure 5.73.

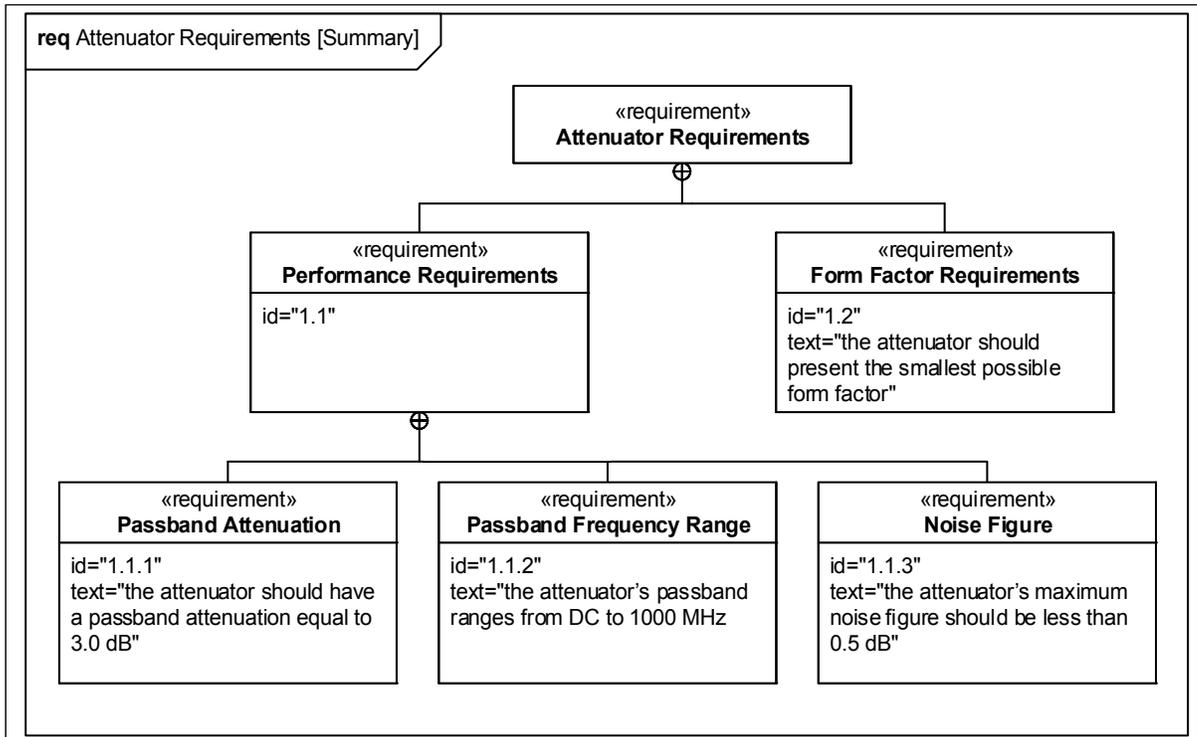


Figure 5.69 The main attenuator requirements depicted in the associated SysML diagram

- **Analysis: PSM generation**

Given the satisfactory performance of the black-box model, no refinement is required. The following task is the PSM generation using a relevant PIM-to-PSM transformation. In this case study, we present a transformation that results in two different prototypes of the PSM. This is because we aim at testing the concurrent design using the proposed framework. The PIM-to-PSM transformation of Table 5.33 develops two PSMs (i.e., T- and  $\pi$ -pad symmetric attenuators). Each PSM is implemented in two successive steps:

- 1. Step 1: Calculation of T- (respectively  $\pi$ -pad) resistive elements**

The first transformation step consists of the computation of resistive elements corresponding to the T-pad (respectively  $\pi$ -pad) attenuator. The values of these elements (already listed in Table 5.34) are structured into a T (respectively  $\Pi$ ) attenuator topology. Given the topology and the resistive elements of each attenuator, it becomes possible to simulate and compare the frequency response and the noise levels in both PSMs (see Figure 5.74). It is worth noting that the resistive elements are ideal and no physical connections between them are considered.

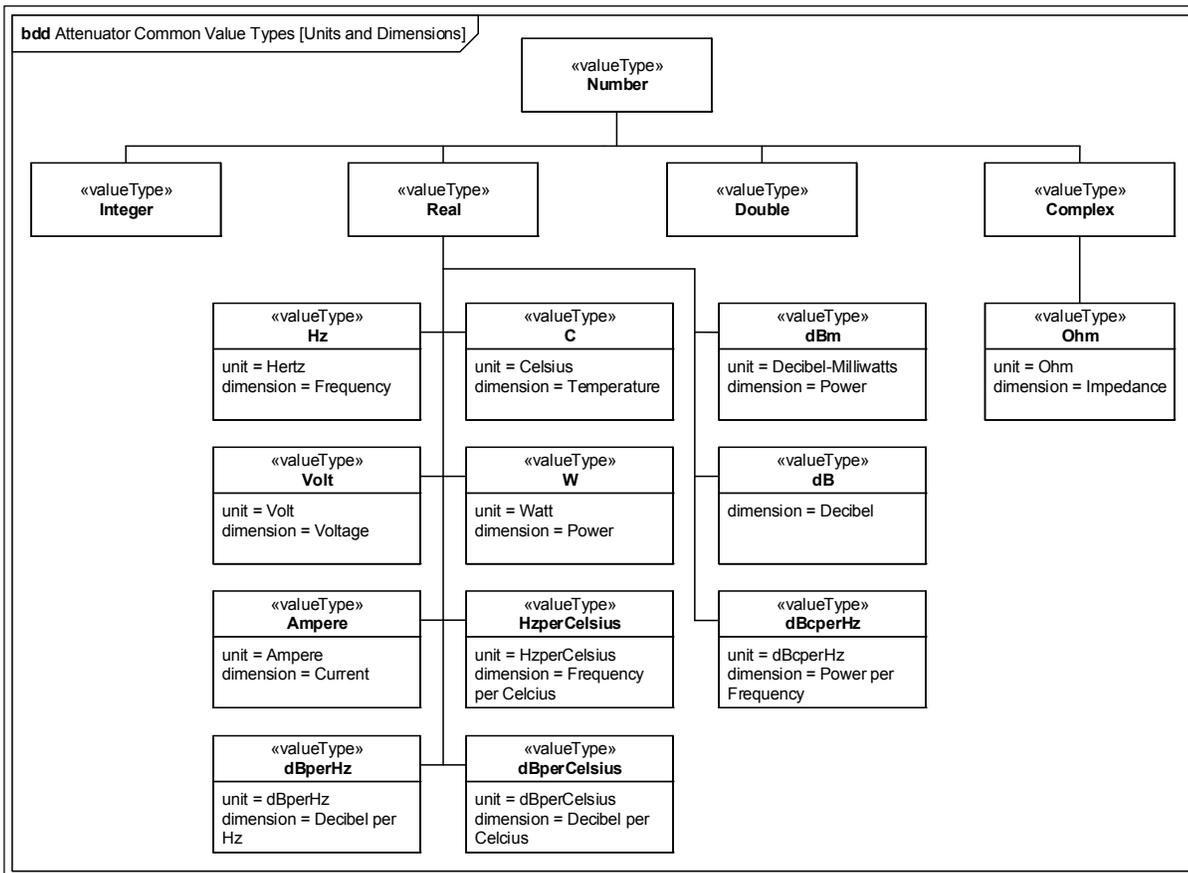


Figure 5.70 Value Types package

## 2. Step 2: Synthesis of transmission lines and circuit topology

The attenuator topologies resulting from the previous step cannot be physically implemented because the resistive elements are not connected using physical structures. That is why transmission lines are synthesized in the second step of the transformation. Depending on topology, the resistive elements are connected together using ideal transmission line sections (see Figure 5.75.a and Figure 5.75.b). The performance of both attenuators is depicted in Figure 5.77. As expected, a slight degradation in frequency response as well as an increase of noise levels for both topologies are observed due to the effects of transmission-line sections.



is 35.980472 mil (respectively 39.238622 mil) when  $\beta l = E_i = 5^\circ$ ,  $Z_{ci} = 50 \Omega$  and  $F_i = 1$  GHz. The technology-mapped T-pad (respectively  $\pi$ -pad) attenuator is depicted in Figure 5.76.a (respectively Figure 5.76.b).

Table 5.31 Relationships between attenuator parameters given in Figure 5.71

Arrow Color	Mathematical Relationship	Parameter
●	$A_{flat} = \max(A_p) - \min(A_p)$	Attenuation flatness
●	$A_{acc} = average(A_p^{specified}) - average(A_p^{measured})$	Attenuation accuracy
●	$S_{tab} = average(A_p^{specified}) - average(A_p^{measured}) _{Scale}$ $Scale \in \{T, F, P, t\}$	Stability
●	$P_{dissipated} = \frac{(V_{ref})^2}{Z_{ref}}$	Dissipated power
●	$T_{sen} = average(A_p _{T+\Delta T} - A_p _T)$	Temperature sensitivity
●	$F_{sen} = average(A_p _{F+\Delta F} - A_p _F)$	Frequency sensitivity
●	$F_{dev} = A_p$	Frequency deviation
●	$VSWR = \frac{10^{\frac{RL}{20}} + 1}{10^{\frac{RL}{20}} - 1}$	Voltage Standing Wave Ratio
●	$RL = \frac{Z_L - Z_S}{Z_L + Z_S}$	Return loss
●	$A_p = isolation$	Attenuation range overrides Isolation property
●	$R = G$	Attenuation range overrides Gain property

Table 5.32 Attenuator integrity control rules

No.	Rule	if test fails
I.1	$-80 \leq temperatureRange \leq 100$	Error or/and Warning
I.2	$ratingTemperatureRange \in \{TRUE, FALSE\}$	Error
I.3	$1 \leq VSWR \leq 10$	Error or/and Warning

No.	Rule	if test fails
I.4	$no \in \mathbb{N}^*$	Error
I.5	$0 < Z_{ref} \leq 10^4$	Error or/and Warning
I.6	$0 < RL \leq 120$	Error or/and Warning
I.7	$ptype \in \{DC,IF,RF\}$	Error
I.8	$connection \in \{TERMINATED,OPENED,SHORTED\}$	Error
I.9	$direction \in \{IN,OUT,INOUT\}$	Error
I.10	$0 \leq frequencyRange \leq 10^{12}$	Error or/and Warning
I.11	$0 \leq powerRange \leq 160$	Error or/and Warning
I.12	$0 \leq voltageRange \leq 10^4$	Error or/and Warning
I.13	$0 \leq currentRange \leq 10^2$	Error or/and Warning
I.14	$ratingFrequency \in \{TRUE,FALSE\}$	Error
I.15	$ratingPower \in \{TRUE,FALSE\}$	Error
I.16	$ratingVoltage \in \{TRUE,FALSE\}$	Error
I.17	$ratingCurrent \in \{TRUE,FALSE\}$	Error
I.18	$0 \leq \%B \leq 1$	Error
I.19	$Q \in ]0,\infty[$	Error or/and Warning
I.20	$0 \leq frequencyDeviation \leq 120$	Error
I.21	$0 \leq frequencySensitivity \leq 120$	Error or/and Warning
I.22	$0 \leq temperatureSensitivity \leq 120$	Error or/and Warning
I.23	$0 \leq powerDissipation \leq 120$	Error or/and Warning
I.24	$0 \leq F_{min} \leq 10^{12}$	Error or/and Warning
I.25	$0 \leq F_{max} \leq 10^{12}$	Error or/and Warning
I.26	$\forall i, 0 \leq attenuation[i] \leq 120$	Error or/and Warning
I.27	$0 \leq attenuationFlatness \leq 120$	Error or/and Warning
I.28	$0 \leq attenuationAccuracy \leq 120$	Error or/and Warning
I.29	$attenuatorType \in \{FIXED, CONTINUOUSLY-VARIABLE, DIGITALLY-CONTROLLED, SWITCHED, VARIABLE, VOLTAGE-CONTROLLED\}$	Error
I.30	$0 \leq stepSize \leq 120$	Error or/and Warning
I.31	$0 \leq stability \leq 120$	Error or/and Warning
I.32	$0 \leq repeatability \leq 120$	Error or/and Warning

```

***** Coherence Verification Test *****
TARGET PIM: 2-GHz RESISTIVE SYMMETRIC ATTENUATOR (C:\Users\slafi\Documents\Design\2ghz_att.xml)

-> Electrical Consistence Rules (11 found)
    ..... PASS
-> PIM-level Design Constraints Rules (0 found)
    ..... N/A
-> Integrity Control Rules (32 found)
    ..... PASS
Summary: (0) Warnings (0) Errors
    
```

Figure 5.72 Attenuator coherence verification report

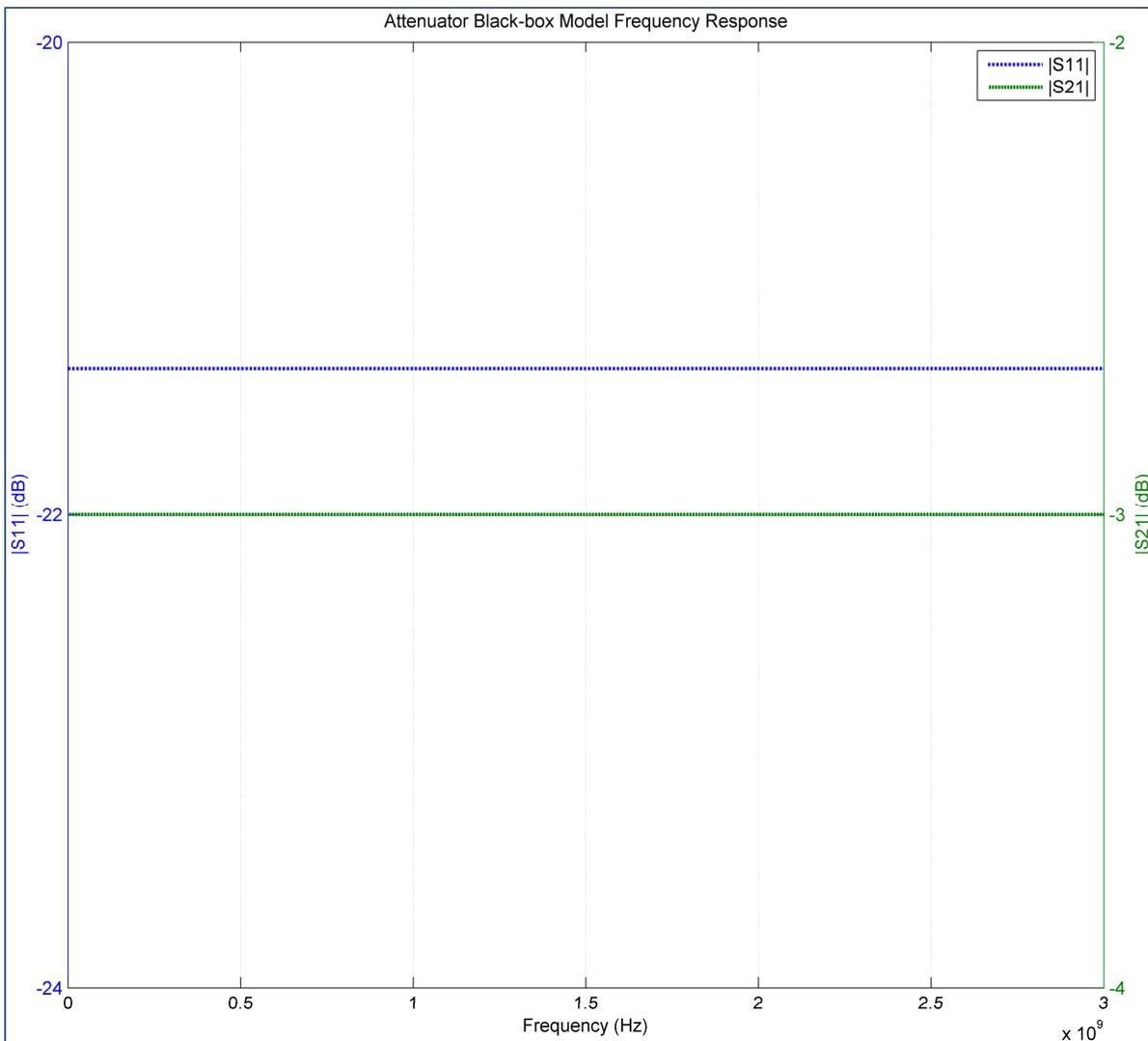


Figure 5.73 Attenuator black-box model frequency response

Table 5.33 PIM-to-PSM transformation for T and  $\Pi$  resistive attenuators

<p><b>Step 1: Calculation of T- and <math>\pi</math>-pad elements</b></p> <p>1.1. Calculate T-pad attenuator resistor values (<math>R_k^T</math>) as given in Figure A III-18</p> <p>1.2. Calculate <math>\pi</math>-pad attenuator resistor values (<math>R_k^\pi</math>) as given in Figure A III-19</p> <p><b>Step 2: Synthesis of transmission lines and circuit topology</b></p> <p>2.1.a. For each series resistor: Create topology depicted in Figure 5.71.a (step ❶).</p> <p>2.2.b. For each parallel resistor: Create topology depicted in Figure 5.71.b (step ❶).</p> <p>2.3. For each transmission line: Consider the properties given in the following:</p> $\begin{cases} Z_{ci} = Z_{reference} \\ E_i = E_{default} \\ F_i = F_0 \\ A_i = A_{default} \end{cases}$ <p>where <math>Z_{ci}</math> is the characteristic impedance of the transmission line, <math>E_i</math> is its electrical length, <math>F_i</math> is the frequency at which the electrical length is calculated and <math>A_i</math> is the transmission line loss (in dB).</p>
--

Table 5.34 Values of resistors for T and  $\Pi$  attenuators

Resistor value ( $\Omega$ )	T Attenuator	$\Pi$ Attenuator
<b>R1</b>	8.549868	292.40218
<b>R2</b>	141.926156	17.614794
<b>R3</b>	8.549868	292.40218

The performance assessment after technology mapping is depicted in Figure 5.74. The T-pad attenuator in terms of frequency response is better than its  $\pi$ -pad counterpart.

The resistors selected during technology mapping from a first technology library (see Table 5.35 and Table 5.36) use a 0603 package (1.63×0.81×0.46 mm). When searching a second technology library (i.e., Panasonic Components Library version 3.1), resistors packaging is provided in three different formats: 0201 (0.6×0.3×0.26 mm), 0402 (1.63×0.81×0.46 mm), and 0603. The smallest is 0201 but it is too small for handcrafted assembly. The packaging 0402 offers a better form factor. However, it is not possible to find out resistance values that approach better the ideal values given in Table 5.34 without combining two or more resistors. The second technology-mapping round resulted in the values listed in Table 5.37 and 5.38. For

the T-pad attenuator, the best approximation of the ideal resistance value  $141.9 \Omega$  is the combined use of two resistors whose values are  $120 \Omega$  and  $22 \Omega$  respectively. Similarly, the  $\pi$ -pad attenuator requires a combination of two resistors from Panasonic library to approximate as much as possible the PSM ideal values (i.e.,  $270 \Omega + 22 \Omega \rightarrow 292.4 \Omega$  and  $12 \Omega + 5.6 \Omega \rightarrow 17.6 \Omega$ ).

The increase of the resistors number requires the PSM-level granularity to increase alike in order to keep the PSM coherent with its associated viewpoint. For this reason, it is mandatory to make a viewpoint change in order to increase the granularity level within the PSM. This takes place in the step of PSM-level granularity refinement using a relevant intra-view transformation. Thus, the design is sent back from « Technology Mapping » to « PSM-level Granularity Refinement » in order to change its granularity.

Using the intra-view transformation given in Table 5.40, both PSMs granularity level is altered. An additional resistor is added to the T-pad attenuator while three are added to its  $\pi$ -pad counterpart. After the use of resistors given in Table 5.37 and 5.38 as well as the synthesis of microstrip-line sections as explained above, the results of performance assessment of the new PSMs is depicted in Figure 5.80.

It is worth noting that the PSM-level granularity refinement process was launched in the bandpass filter case study due to the poor performance of the obtained design solution. In this case study, this process was provoked in the purpose of satisfying another requirement: small form factor. As explained in chapter 4, the granularity refinement process helps extending the limits of design space in a controlled fashion. Thus, it is always possible to proceed to granularity refinement to satisfy one or many design requirements and enhance the quality of the obtained design solution.

- **Synthesis: PM generation**

The candidate design solutions whose frequency response is depicted in Figure 5.79 and 5.80 respectively are relatively satisfying. To move forward towards manufacturing stage, we use a PSM-to-PM transformation in order to generate the PM corresponding to each PSM.

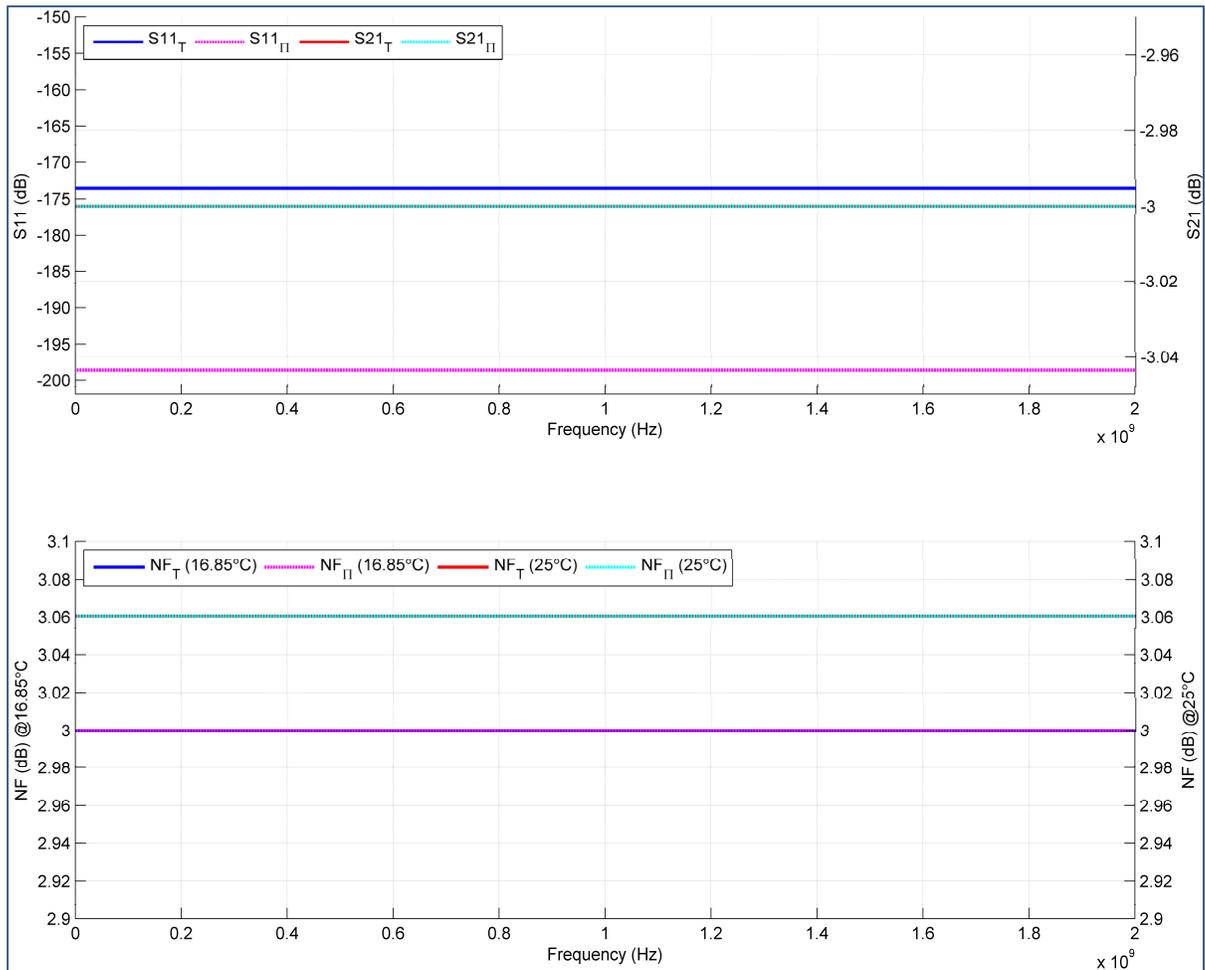


Figure 5.74 A comparison between the T and  $\Pi$  attenuators in terms of frequency response and noise levels (at the end of step 1 of the PIM-to-PSM transformation)

Using a commercial design package (i.e., ADS), we transform both PSMs into physical layouts. The PM corresponding to the PSM resulting from the initial technology mapping is illustrated in Figure 5.81. The PM corresponding to the PSM resulting from granularity refinement is depicted in Figure 5.82. It is trivial to note the effect of PSM-level granularity refinement between both PMs. For instance, an additional resistor (green colored) and an extra microstrip section (red colored) are observed in the T-pad attenuator of Figure 5.82.a which brings the total number of resistors to four (against three in the original attenuator PM illustrated in Figure 5.81.a). This observation is also valid to the  $\pi$ -pad attenuator PMs (Figure 5.82.b versus Figure 5.81.b). In addition, the frequency response of the generated PMs is illustrated in Figure 5.83 (original PSM) and 5.84 (PSM resulting from granularity refinement).

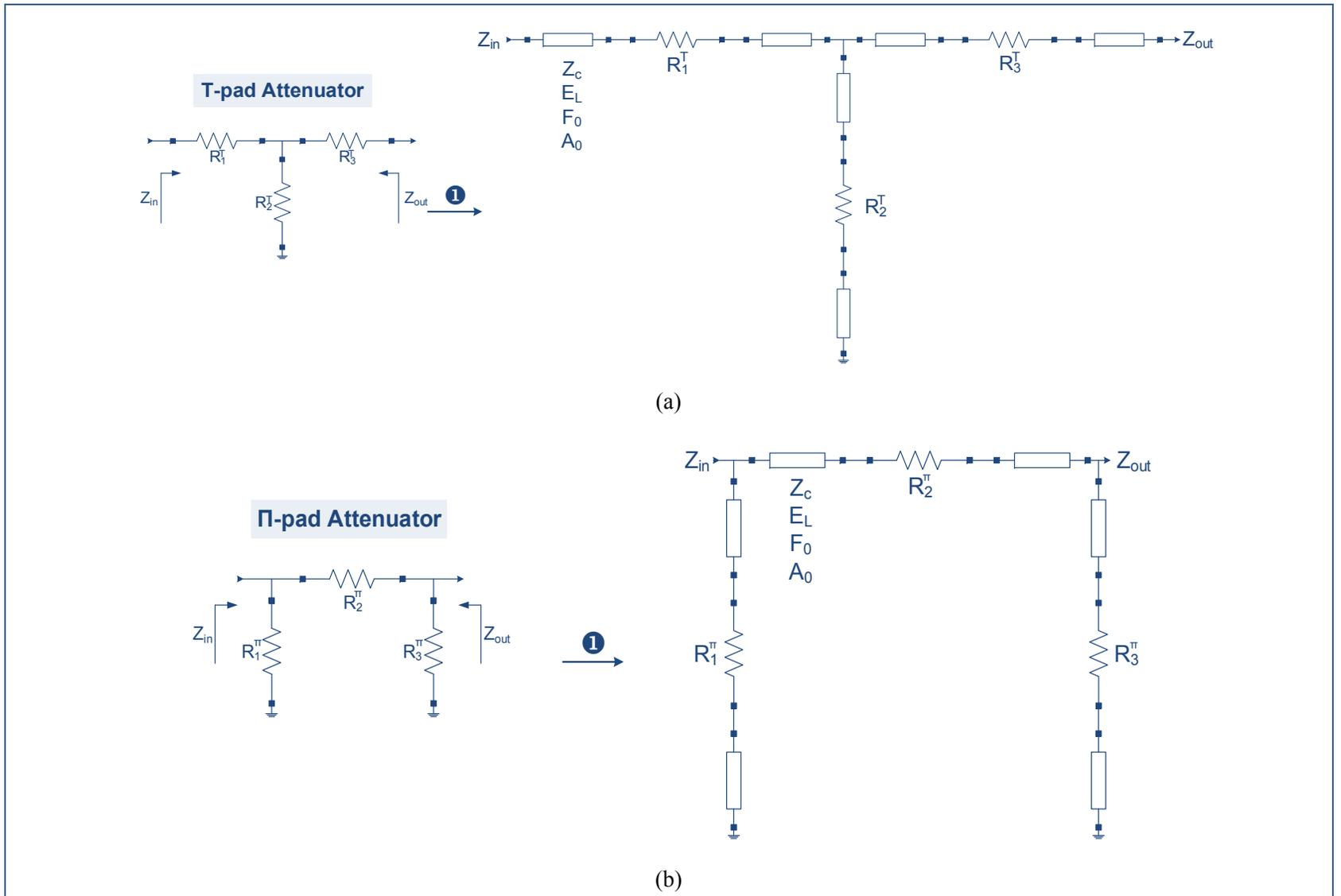


Figure 5.75 PIM-to-PSM transformation: (a) T and (b) Π attenuators

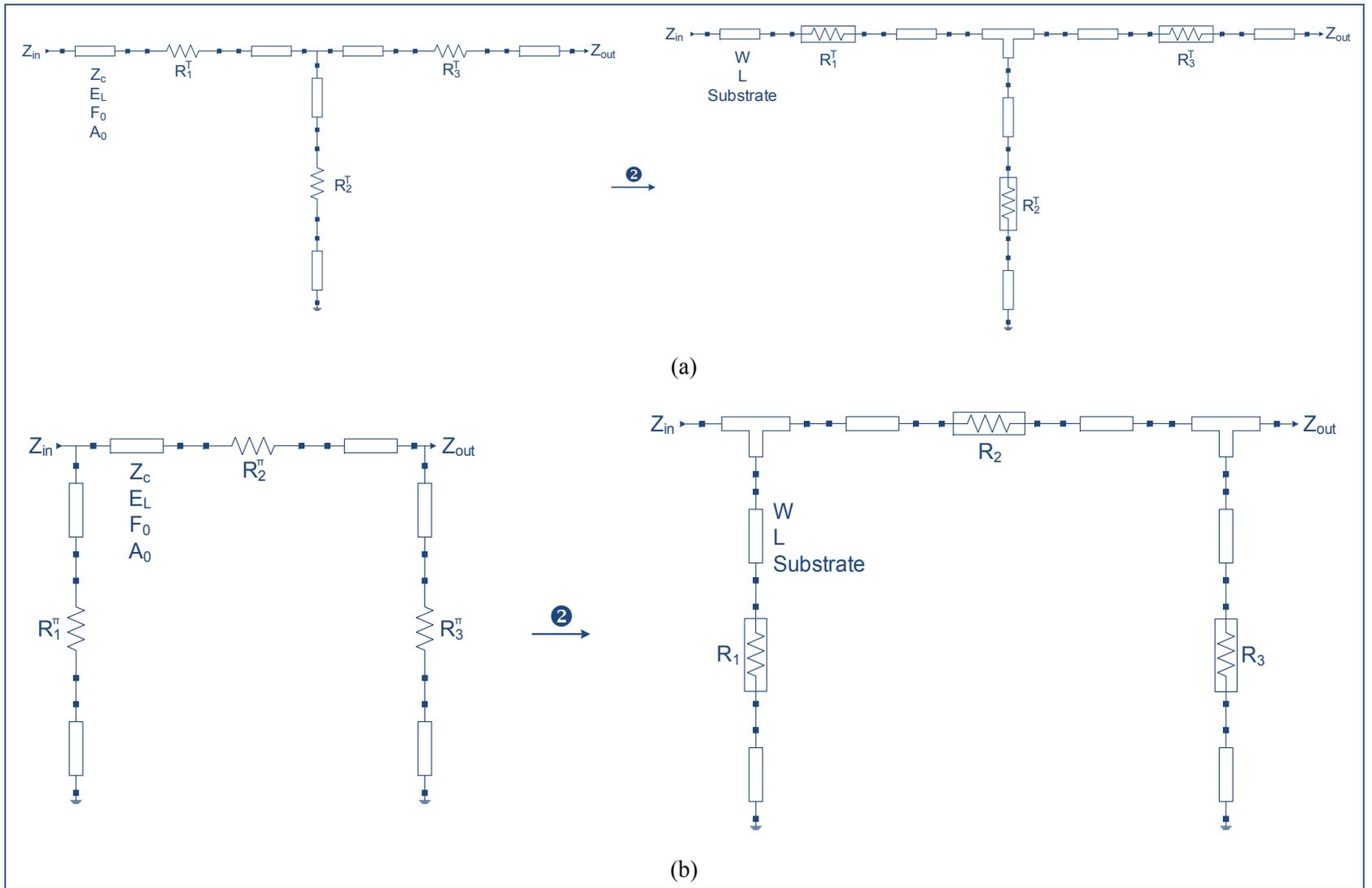


Figure 5.76 Technology mapping: (a) T and (b)  $\Pi$  attenuators

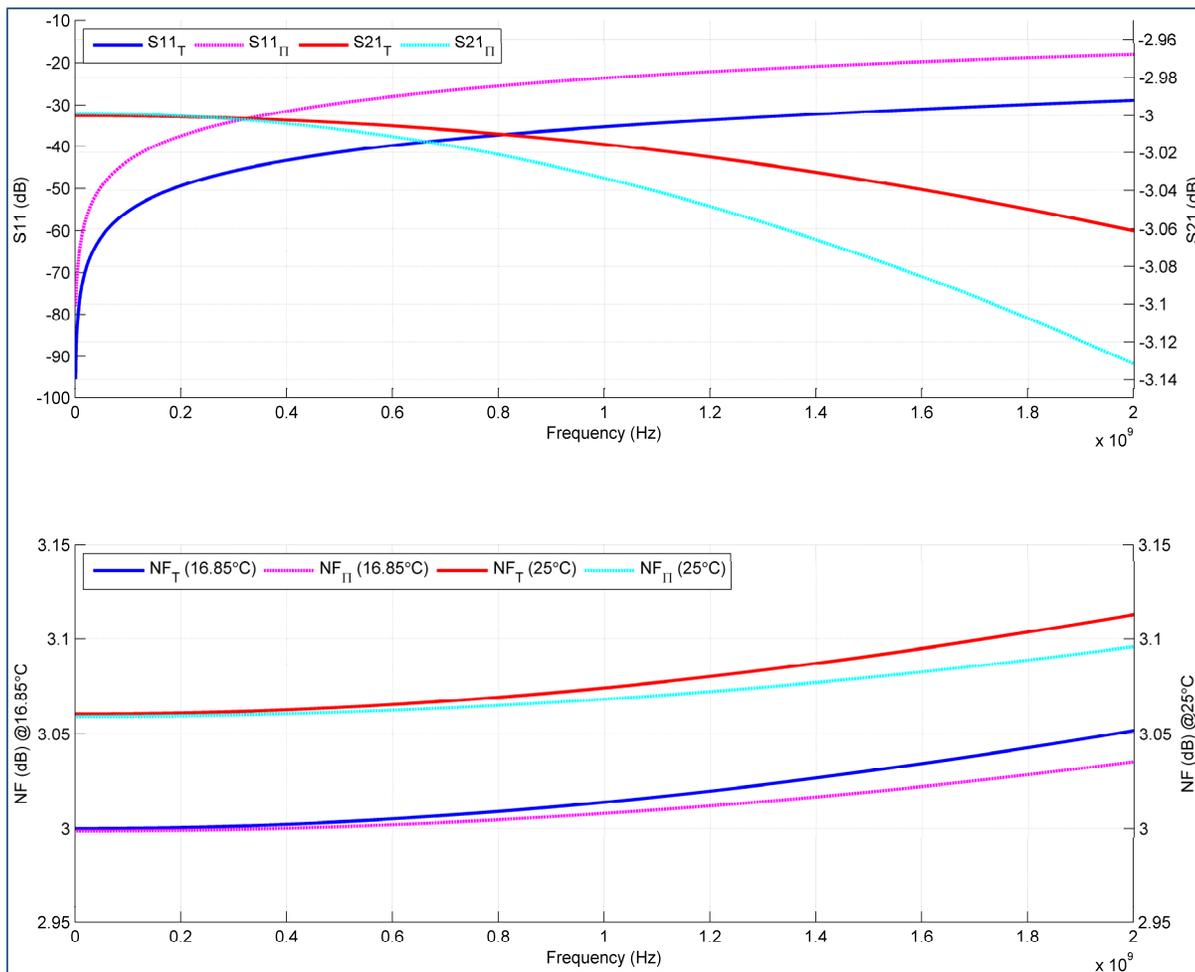


Figure 5.77 A comparison between the T and  $\Pi$  attenuators in terms of frequency response and noise levels (at the end of step 2 of the PIM-to-PSM transformation)

- **Using Q-matrix for noise data storage**

In this case study, we chose to include the evaluation of the noise level in the performance assessment plan of each design solution. This information is part of electrical design data. However, it does not comply with the mathematical formalism of the Q-matrix (see section 3.3.4 and equations (3.2)-(3.4)). Thus, the noise data is not natively supported by the Q-matrix. Nevertheless, we used the Q-matrix XML data structure to include noise data as metadata. As illustrated in Figure 5.85, a dataset is created in metadata section where each noise point is included along with the relevant data. The frequency, temperature and data format are also provided.

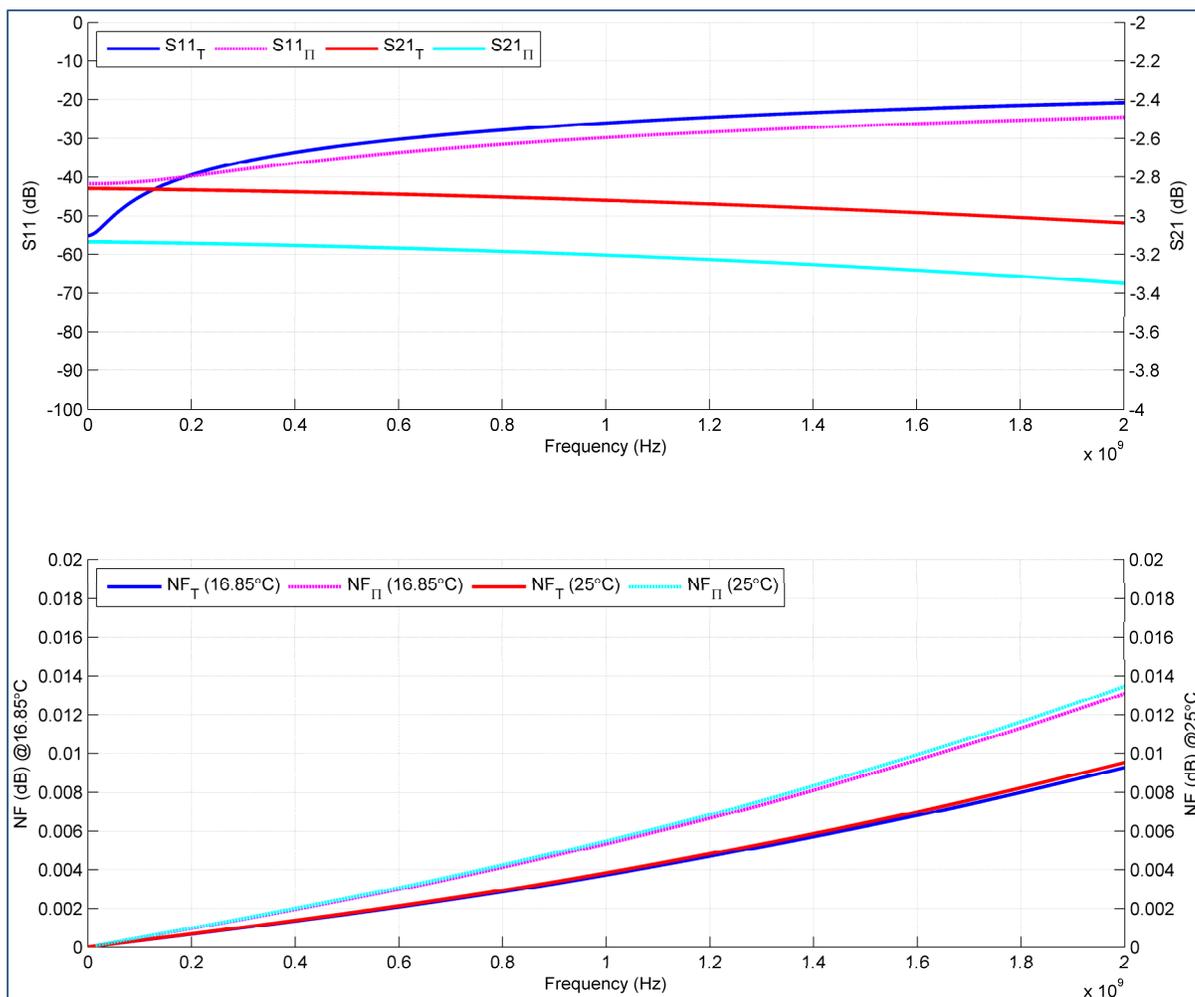


Figure 5.78 A comparison between the T and  $\Pi$  attenuators in terms of frequency response and noise levels (initial technology mapping)

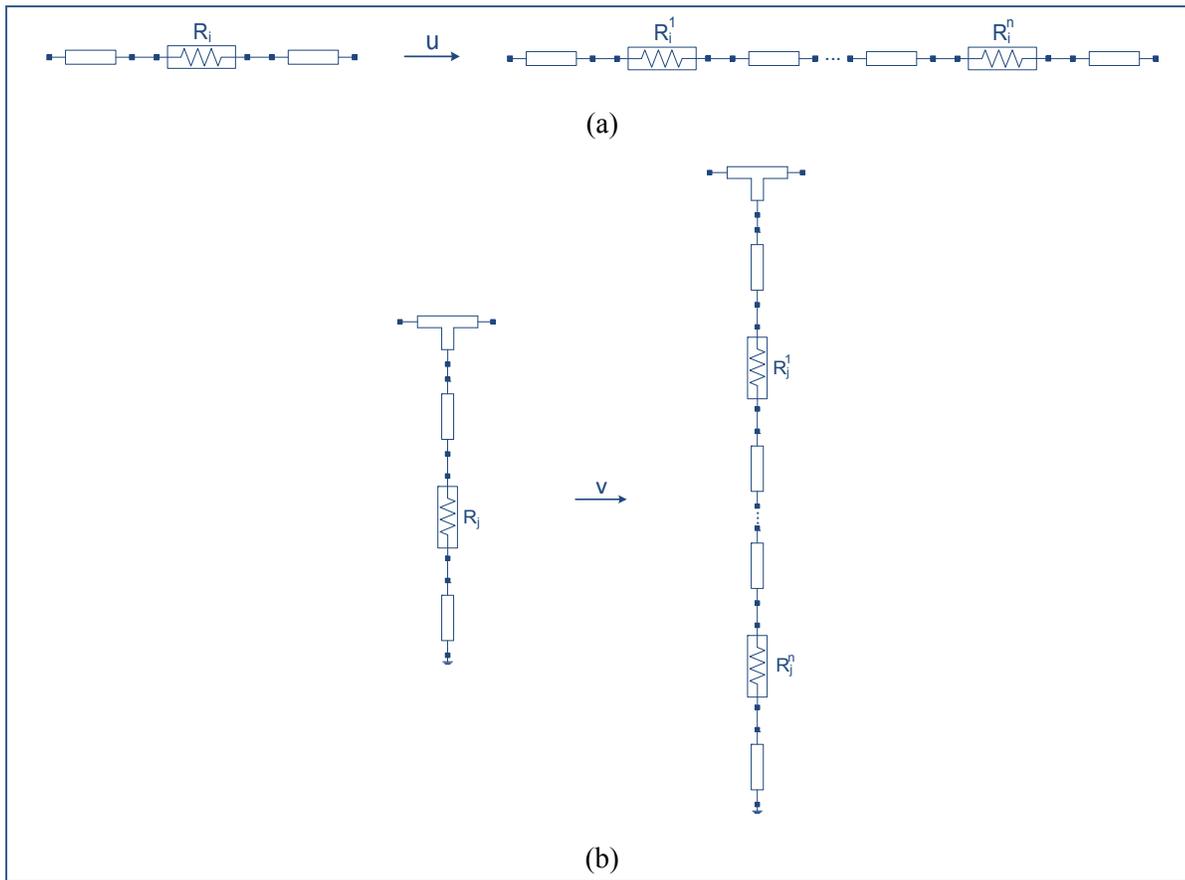


Figure 5.79 Intra-view transformation: (a) series (b) shunt

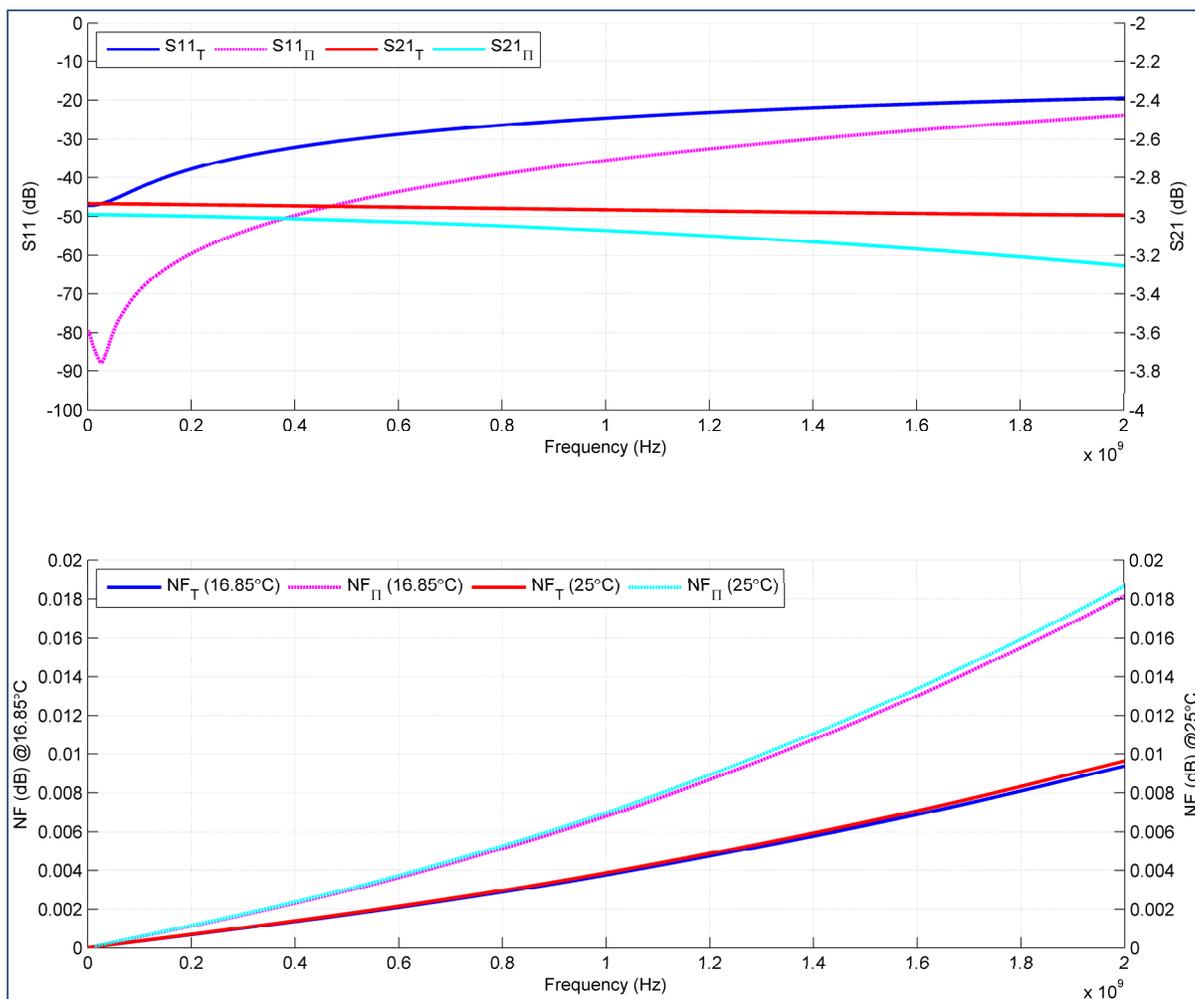


Figure 5.80 A comparison between the T and  $\Pi$  attenuators in terms of frequency response and noise levels (after granularity refinement)

Table 5.35 T attenuator initial resistors

Manufacturer Part Number	Resistance ( $\Omega$ )	Tolerance	Power (W)	Package	Dimensions			Endurance
					Length	Width	Height	
PATT0603K8R45FGT1 $\diamond$	8.45	$\pm 1\%$	0.15	0603	1.63	0.81	0.46	70°C, 1000h: $\pm(1\% R + 0.05\Omega)$ 70°C, 8000h: $\pm(2\% R + 0.1\Omega)$
MCT06030D1400BP500 $\heartsuit$	140	$\pm 0.1\%$	0.1	0603	1.55	0.85	0.55	
PAT0603E1400BST1 $\diamond$	140	$\pm 0.1\%$	0.15	0603	1.63	0.81	0.46	

$\diamond$  Vishay Thin Film

$\heartsuit$  Vishay BC Components

Table 5.36 II attenuator initial resistors

Manufacturer Part Number	Resistance ( $\Omega$ )	Tolerance	Power (W)	Package	Dimensions (mm)			Endurance
					Length	Width	Height	
Y149617R6000C0W $\blacklozenge$	17.6	$\pm 0.25\%$	0.15	1206	3.2	1.57	0.64	70°C, 1000h: $\pm(0.05\% R + 0.01\Omega)$ 70°C, 8000h: $\pm(0.1\% R + 0.02\Omega)$
TNPW060317R4BEEN $\blacklozenge$	17.4	$\pm 0.1\%$	0.1	0603	1.6	0.85	0.55	70°C, 1000h: $\pm(0.05\% R + 0.01\Omega)$ 70°C, 8000h: $\pm(0.1\% R + 0.02\Omega)$
PHP00603E2910BST1 $\diamond$	291	$\pm 0.1\%$	0.375	0603	1.63	0.81	0.51	70°C, 2000h: $\pm(R + 0.1\%)$
PLT0603Z2910LBTS $\diamond$	291	$\pm 0.01\%$	0.15	0603	1.63	0.81	0.51	70°C, 2000h: $\pm(R + 0.1\%)$

$\heartsuit$  Vishay BC Components

$\blacklozenge$  Vishay Foil Resistors

$\blacklozenge$  Vishay Dale

$\diamond$  Vishay Thin Film

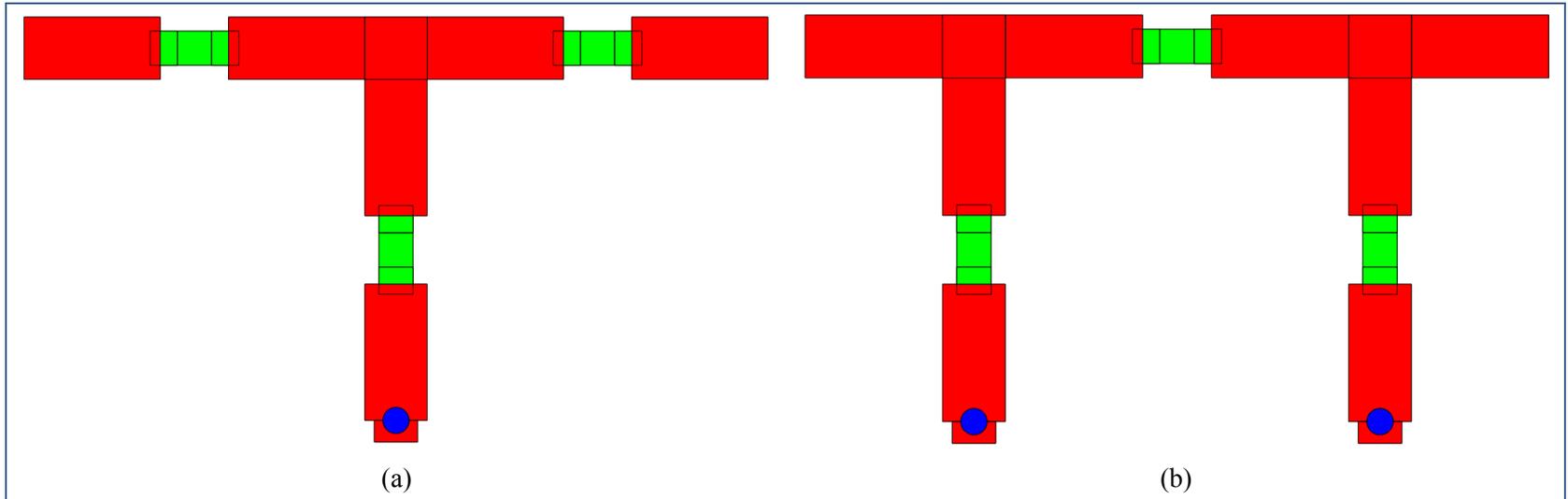


Figure 5.81 Resulting PM: (a) T and (b)  $\Pi$  attenuator layouts

Table 5.37 T attenuator alternative resistors

Manufacturer Part Number	Resistance ( $\Omega$ )	Tolerance	Power (W)	Package	Dimensions			Selected?
					L (mm)	W (mm)	H (mm)	
ERJ3GEYJ8R2V*	8.2	$\pm 5\%$	0.1	0603	1.6	0.8	0.55	
ERJ2GEJ8R2*	8.2	$\pm 5\%$	0.063	0402	1.0	0.5	0.4	✓
ERJ3GEYJ121*	120	$\pm 5\%$	0.1	0603	1.6	0.8	0.55	
ERJ2GEJ121*	120	$\pm 5\%$	0.063	0402	1.0	0.5	0.4	✓
ERJ3GEYJ220*	22	$\pm 5\%$	0.1	0603	1.6	0.8	0.55	
ERJ2GEJ220*	22	$\pm 5\%$	0.063	0402	1.0	0.5	0.4	✓

\* Panasonic Electronic Components

Table 5.38  $\Pi$  attenuator alternative resistors

Manufacturer Part Number	Resistance ( $\Omega$ )	Tolerance	Power (W)	Package	Dimensions			Selected?
					L (mm)	W (mm)	H (mm)	
ERJ3GEYJ180*	18	$\pm 5\%$	0.1	0603	1.6	0.8	0.55	
ERJ2GEJ120*	12	$\pm 5\%$	0.063	0402	1.0	0.5	0.4	✓
ERJ2GEJ5R6*	5.6	$\pm 5\%$	0.063	0402	1.0	0.5	0.4	✓
ERJ3GEYJ271*	270	$\pm 5\%$	0.1	0603	1.6	0.8	0.55	
ERJ2GEJ271*	270	$\pm 5\%$	0.063	0402	1.0	0.5	0.4	✓
ERJ3GEYJ220*	22	$\pm 5\%$	0.1	0603	1.6	0.8	0.55	
ERJ2GEJ220*	22	$\pm 5\%$	0.063	0402	1.0	0.5	0.4	✓

\* Panasonic Electronic Components

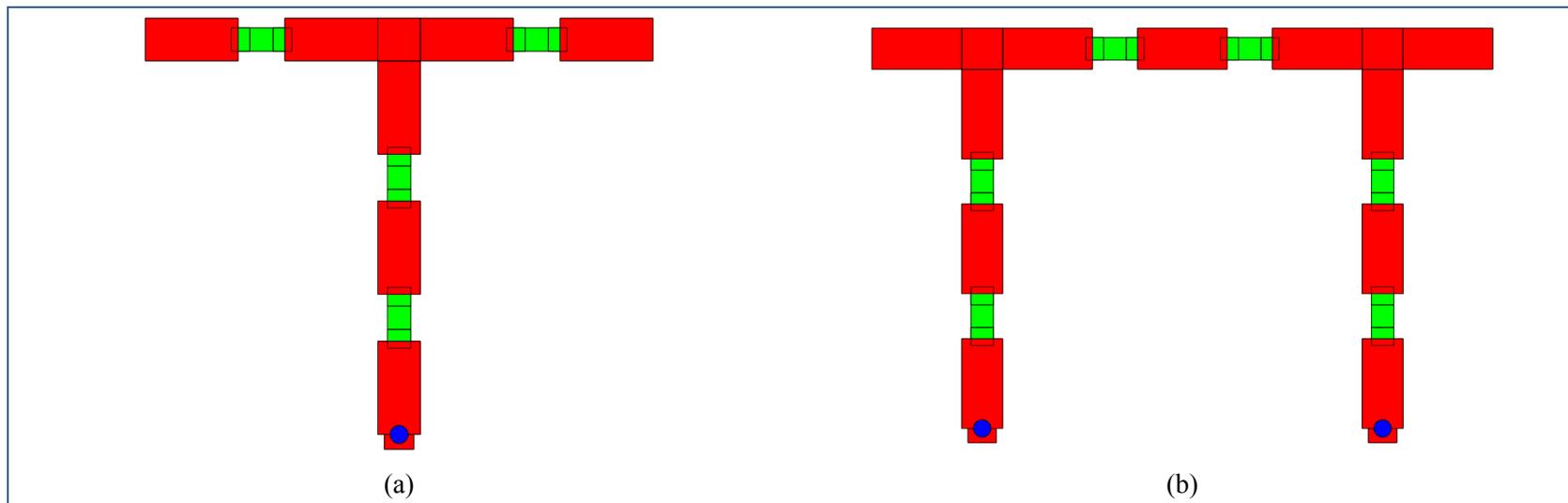
Figure 5.82 Resulting PM after granularity refinement: (a) T and (b)  $\Pi$  attenuator layouts

Table 5.39 Form factor of initial and refined PIMs for both T and  $\Pi$  attenuators

	Initial PIM			Refined PIM		
	Length (mm)	Width (mm)	Area (mm <sup>2</sup> )	Length (mm)	Width (mm)	Area (mm <sup>2</sup> )
<b>T attenuator</b>	10.8966	6.223	67.80954	10.8966	9.2202	100.46883
<b><math>\Pi</math> attenuator</b>	10.8204	6.223	67.33534	13.7922	9.2202	127.16684

Table 5.40 Intra-view transformation used for the attenuators' PSM granularity refinement

Consider  $R_{old}$  a vector of the old resistors to replace

Consider  $R_{new}$  a vector of the new resistors to replace the old ones with

Consider  $k$  a vector containing the number of new resistors

**Step 1: Replacement of resistors**

1.1. For each series resistor  $i$  in  $R_{old}$ , replace with  $k(i)$  resistors in  $R_{new}$  according to the topology depicted in Figure 5.79.a

1.2. For each shunt resistor  $j$  in  $R_{old}$ , replace with  $k(j)$  resistors in  $R_{new}$  according to the topology depicted in Figure 5.79.b

**Step 2: Synthesis of transmission lines and circuit topology**

2.1. For each transmission line:

Consider the properties given in the following:

$$\begin{cases} Z_{ci} = Z_{reference} \\ E_i = E_{default} \\ F_i = F_0 \\ A_i = A_{default} \end{cases}$$

where  $Z_{ci}$  is the characteristic impedance of the transmission line,  $E_i$  is its electrical length,  $F_i$  is the frequency at which the electrical length is calculated and  $A_i$  is the transmission line loss (in dB).

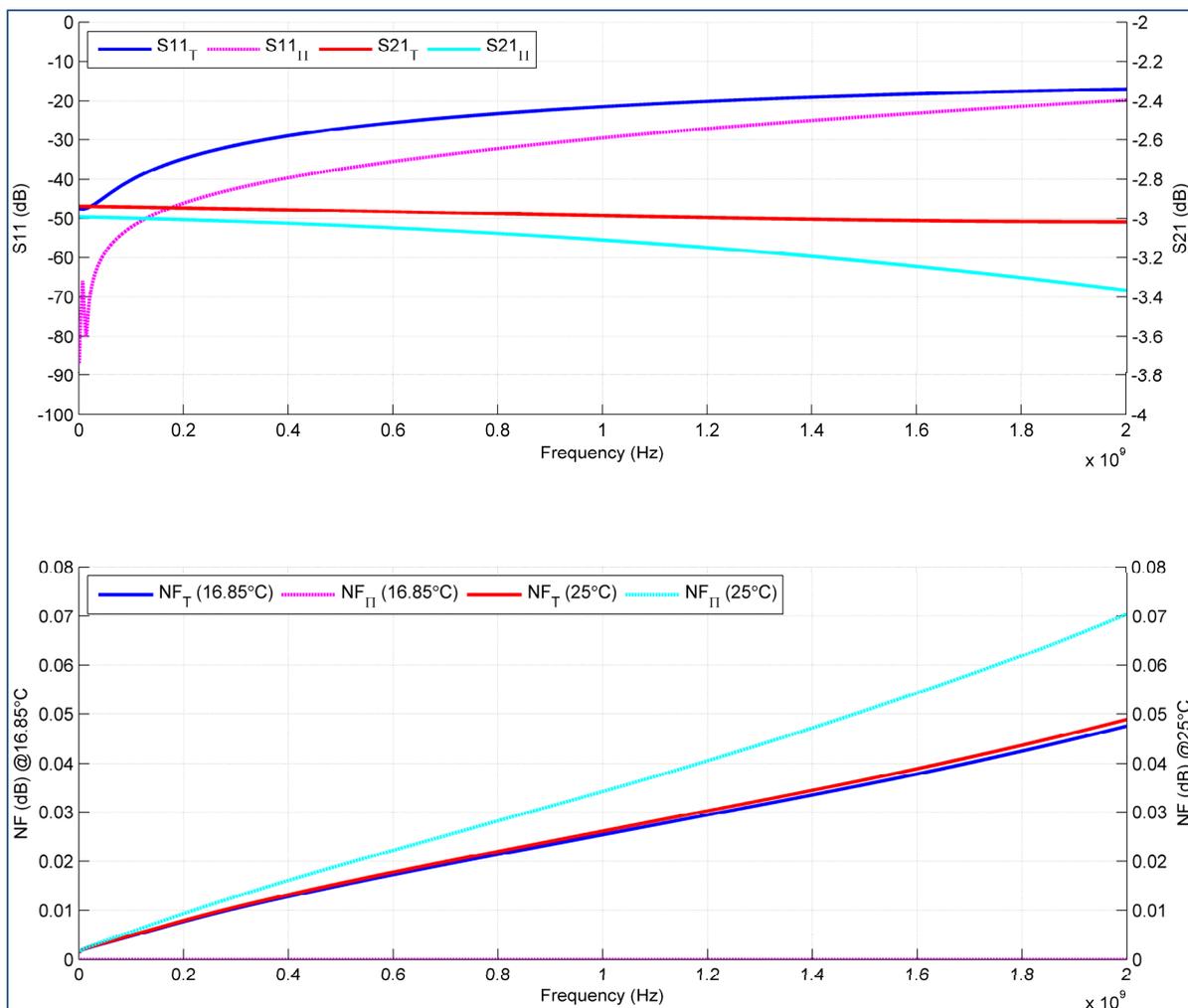


Figure 5.83 A comparison between the T and  $\Pi$  attenuators in terms of frequency response and noise levels (Final PM 1)

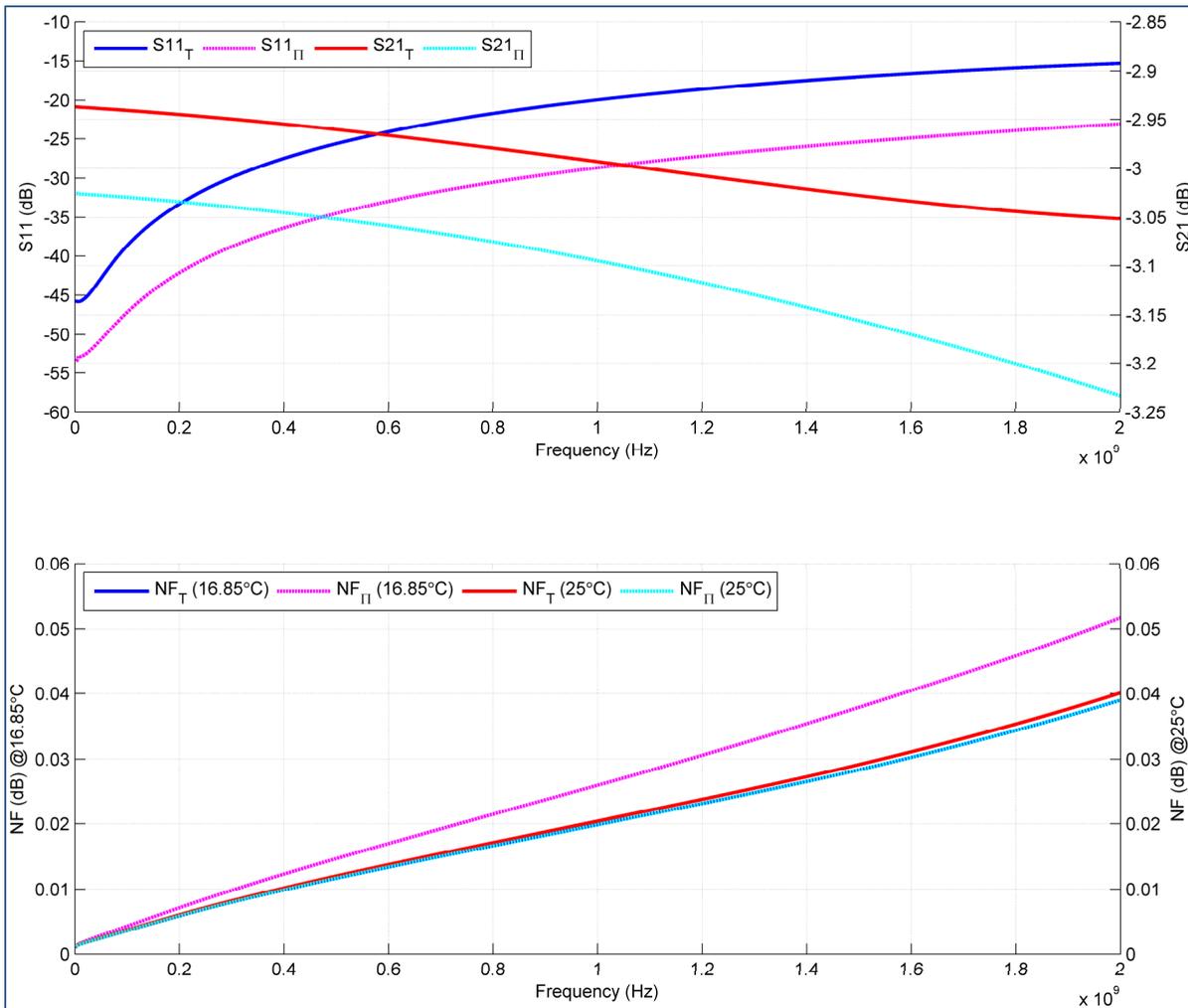


Figure 5.84 A comparison between the T and Π attenuators in terms of frequency response and noise levels (final PM after granularity refinement)

```

- <Qmatrix>
  <!-- 3-dB Resistive Attenuator -->
  <!-- Author: Sabeur LAFI -->
  <!-- version: 0.1 -->
  <Qblock name="T_att_specs" source="pim_rm_cv_01"> </Qblock>
- <Qblock name="T_att_lumped" source="pim_rm_bbx_model_01">
  + <config></config>
  + <data></data>
  - <misc>
    <meta name="description" content="attached noise data"/>
    <dataset name="noise data" size="10" data-format="dB" temp="16.85" tempUnit="C">
      - <datapoint>
        <freq unit="Hz">1000000 </freq>
        <minNF>8.83091945e-006 </minNF>
        <GammaS data-format="MA">0.607172002 </GammaS>
        <Phase unit="deg">-179.953593 </Phase>
        <effNoiseRes unit="ohm">1.43704347e-007 </effNoiseRes>
      </datapoint>
      + <datapoint></datapoint>
      + <datapoint></datapoint>
    </dataset>
    + <dataset name="noise data" size="3000" data-format="dB" temp="25" tempUnit="C"></dataset>
  </misc>
</Qblock>
<Qblock name="T_att_LC_Mic_ideal" source="psm_trans_output_01"> </Qblock>
<Qblock name="T_att_LC_Mic_mapping" source="psm_tech_mapping_01"> </Qblock>
<Qblock name="T_att_LC_Mic_mapping_ref" source="psm_gran_ref_01"> </Qblock>
<Qblock name="T_att_hybrid_sim_1" source="pm_perf_assess_01"> </Qblock>
<Qblock name="PI_att_specs" source="pim_rm_cv_01"> </Qblock>
<Qblock name="PI_att_lumped" source="pim_rm_bbx_model_01"> </Qblock>
<Qblock name="PI_att_LC_Mic_ideal" source="psm_trans_output_01"> </Qblock>
<Qblock name="PI_att_LC_Mic_mapping" source="psm_tech_mapping_01"> </Qblock>
<Qblock name="PI_att_LC_Mic_mapping_ref" source="psm_gran_ref_01"> </Qblock>
<Qblock name="PI_att_hybrid_sim_1" source="pm_perf_assess_01"> </Qblock>
</Qmatrix>

```

Additional noise data section

Mandatory Qblock data sections (config, data)

Noise temperature

Figure 5.85 Noise data is supported in the Qmatrix through metadata

### 5.3.3 Frequency Translation Device

In the previous sections, we studied how the proposed design framework can be applied to the design of linear components such as filters and attenuators. In this section, we use this framework for the design of a nonlinear component, namely mixer.

- **Specifications**

A radiofrequency mixer is a nonlinear frequency translation device that creates the sum and the difference from input frequencies (see Figure 5.86). A local oscillator is generally used to generate the signal frequency that mixes with the RF one.

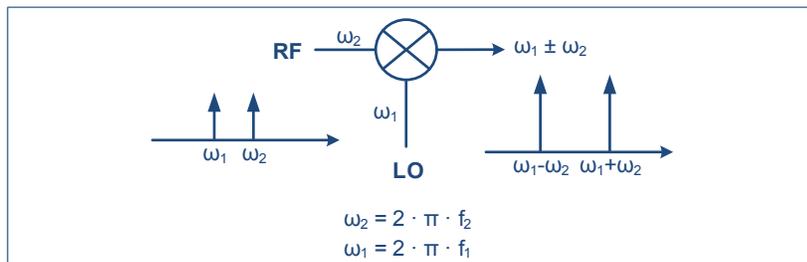


Figure 5.86 A mixer makes a frequency translation

Table 5.41 Mixer specifications

<b>Conversion Gain (dB)</b>	> -9.5
<b>RF Frequency (MHz)</b>	2400 – 2485
<b>LO Frequency (MHz)</b>	2302.5
<b>IF Frequency (MHz)</b>	140
<b>IF Bandwidth (MHz)</b>	5
<b>LO Power (dBm)</b>	max. 8
<b>RF Power (dBm)</b>	-20
<b>IF Power (dBm)</b>	0
<b>LO-RF Rejection (dB)</b>	> 20 dB
<b>LO-IF Rejection (dB)</b>	> 30 dB
<b>Termination Impedance (ohm)</b>	50

The common specifications of RF mixers include the input frequencies, the signal power rates and the port-to-port isolations. Table 5.41 enumerates the specifications we consider for this design case study.

- **Functional Description: SysML requirements and platform-independent models**

Similarly to the previous case studies, the first step is the mixer functional description. The package diagram of Figure 5.87 illustrates the main SysML models used to capture the mixer's specifications. The mixer structure is detailed in the « Mixer Definition » package. The mixer requirements are captured in the « Mixer Requirements » package while the coherence verification rules are comprised in the « Mixer Coherence Rules » one. All packages use the definitions given in « Value Types ».

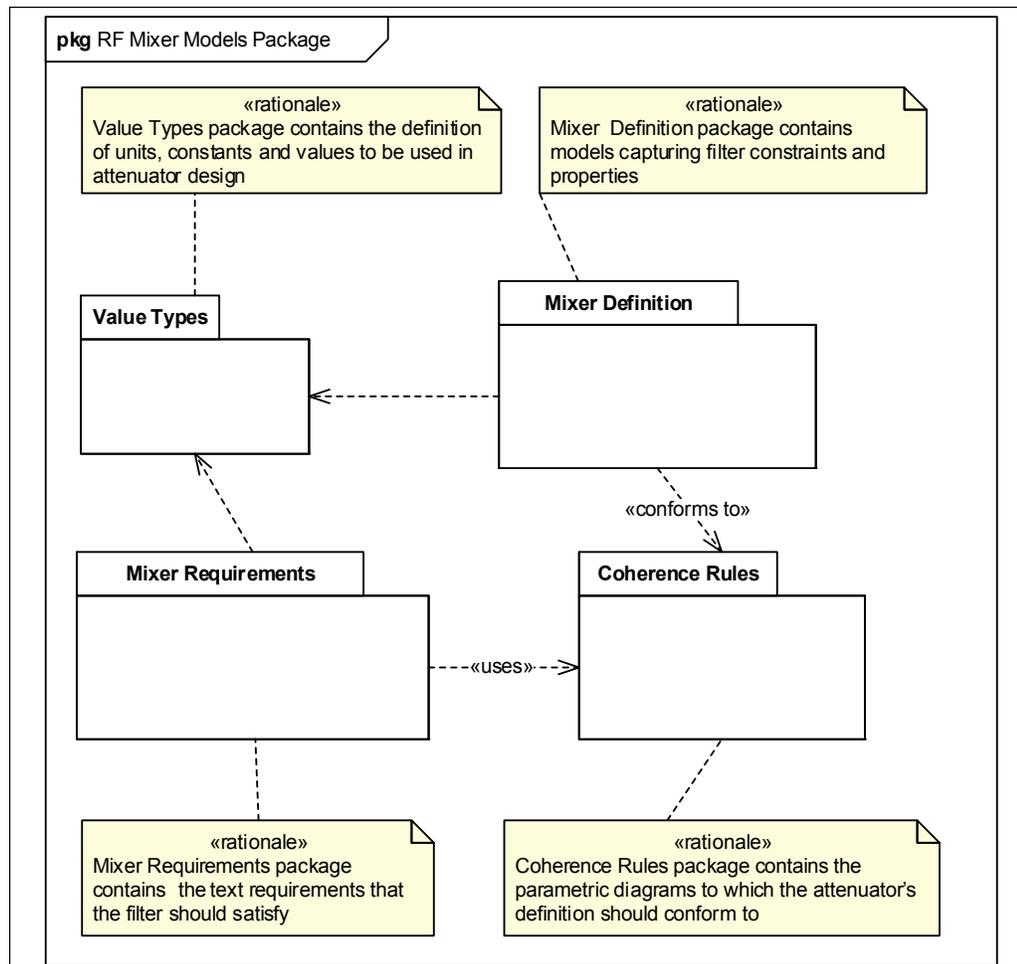


Figure 5.87 Mixer package diagram

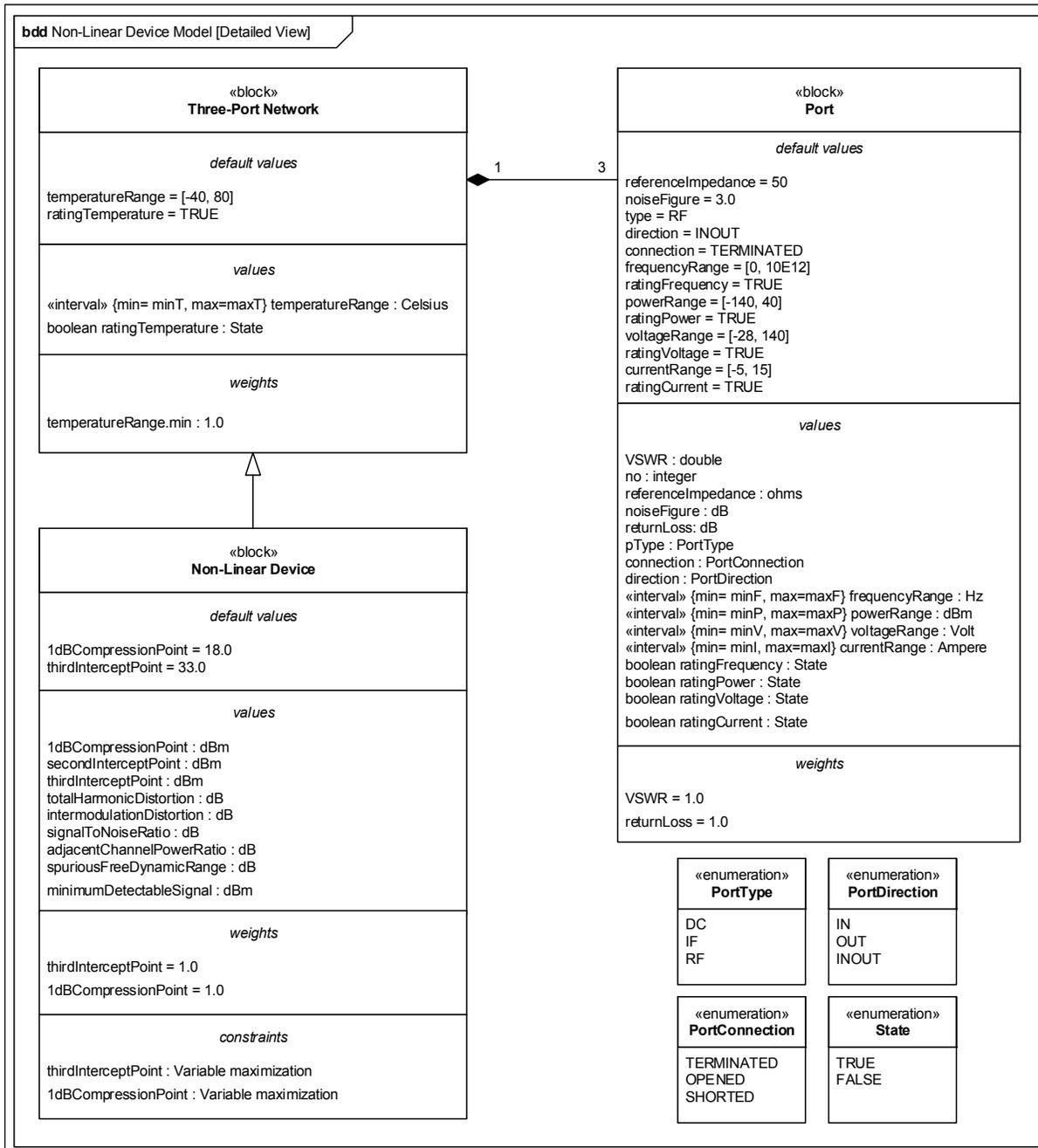


Figure 5.88 Three-port network detailed block definition diagram

- Mixer structure: a mixer is a nonlinear three port network for frequency translation. This definition is captured in the hierarchy illustrated in the bdds of Figure 5.88 and Figure 5.89. The « Three-Port Network » block is composed of three « Ports ». Its properties are inherited from the « Nonlinear Device » block. The « Frequency Translation Device » is a specialization of « Nonlinear Device » and a generalization of « Mixer Device » blocks.

The specifications of Table 5.41 are captured in the properties of each block. Tables 5.42 and 5.43 show the value of each of these properties.

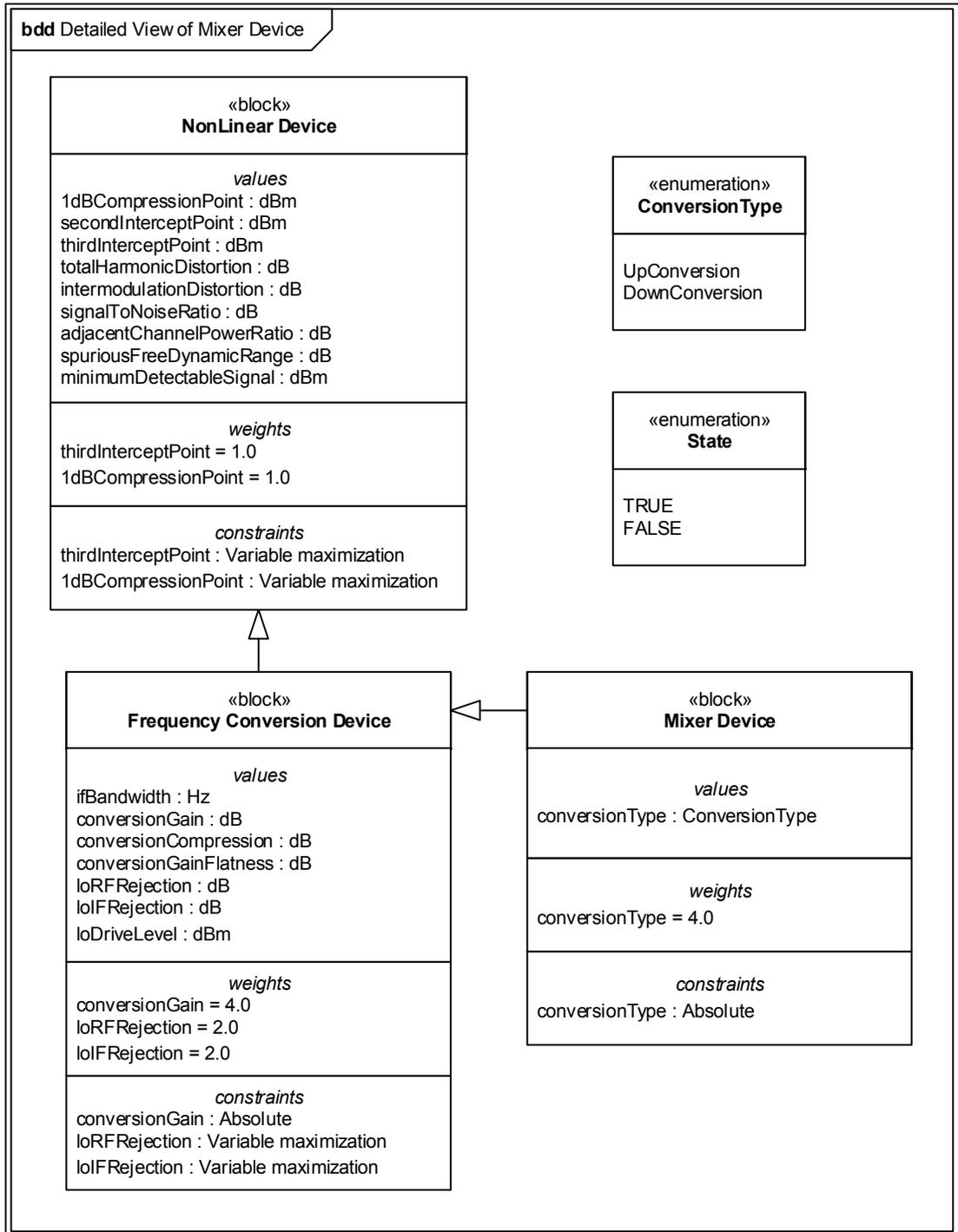


Figure 5.89 Mixer is a nonlinear frequency conversion device (Figure 5.88 cont'd)

- Mixer requirements: the bdd of Figure 5.90 depicts a generic hierarchy of the mixer requirements. In this example, the performance requirements which include conversion gain and port-to-port isolation, are considered.

Table 5.42 List of mixer value properties as presented in the corresponding bdds

Parameter Value	Type	Default Value	Remarks	Specifications Value
temperatureRange	interval (Celsius)	[-40, 80]		
ratingTemperature	Boolean	TRUE	TRUE FALSE	
noiseFigure	dB	3		
portList	Object (Port)			3
portsNo	integer	2		
1dBCompressionPoint	dBm	18.0		
secondInterceptPoint	dBm			
thirdInterceptPoint	dBm	33.0		
totalHarmonicDistortion	dB			
intermodulationDistortion	dB			
signalToNoiseRatio	dB			
adjacentChannelPowerRatio	dB			
spuriousFreeDynamicRange	dB			
minimumDetectableSignal	dBm			
ifBandwidth	Hz			5E6
conversionGain	dB			max. -9.5
conversionCompression	dB			
conversionGainFlatness	dB			
loRFRejection	dB			min. 20
loIFRejection	dB			min. 30
loDriveLevel	dBm			max. 8.0
conversionType	ConversionType		UPCONVERSION DOWNCONVERSION	DOWNCONVERSION

Table 5.43 List of mixer port value properties as enumerated in the SysML models

Value Property	Type	Default Value	Remarks	Specifications Value
VSWR	double			
no	integer			1 (2) (3)
referenceImpedance	double (ohms)	50.0		50 (50) (50)
returnLoss	dB			
noiseFigure	dB	3.0		
pType	PortType	RF	DC IF RF	
direction	PortDirection	INOUT	IN OUT INOUT	
connection	PortConnection	TERMINATED	TERMINATED OPENED SHORTED	
frequencyRange	interval (Hz)	[0, 10E12]		2.4425E9 (2.3025E9) (140E6)
ratingFrequency	Boolean	TRUE	TRUE FALSE	
powerRange	interval (dBm)	[-140, 40]		-20 (8.0) (0)
ratingPower	Boolean	TRUE	TRUE FALSE	
voltageRange	interval (Volts)	[-28, 140]		
ratingVoltage	Boolean	TRUE	TRUE FALSE	
currentRange	interval (Amperes)	[-5, 15]		
ratingCurrent	Boolean	TRUE	TRUE FALSE	

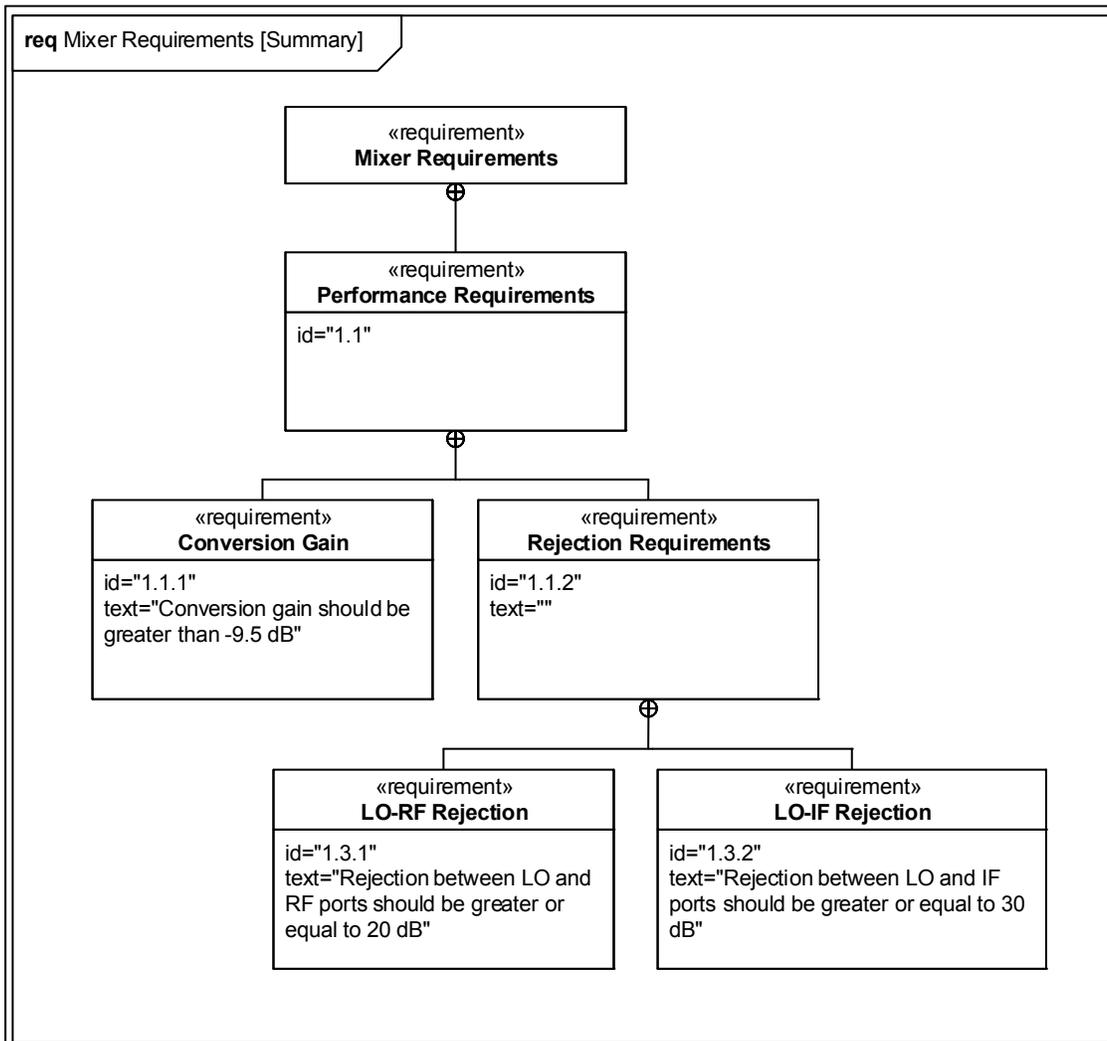


Figure 5.90 Summary of mixer requirements

- Mixer coherence rules: the coherence verification rules that are used at the step of coherence verification are included in the « Coherence Rules » package. The Figure 5.91 depicts the PIM-level design rules.
- Value types: all the packages use the definitions included in « Value Types » package comprising for example units (see Figure 5.92).
- **Analysis: Coherence verification**

The next step after functional description is the coherence verification test. The coherence rules for a nonlinear device (such as a mixer) are similar to those enumerated in the previous case studies.

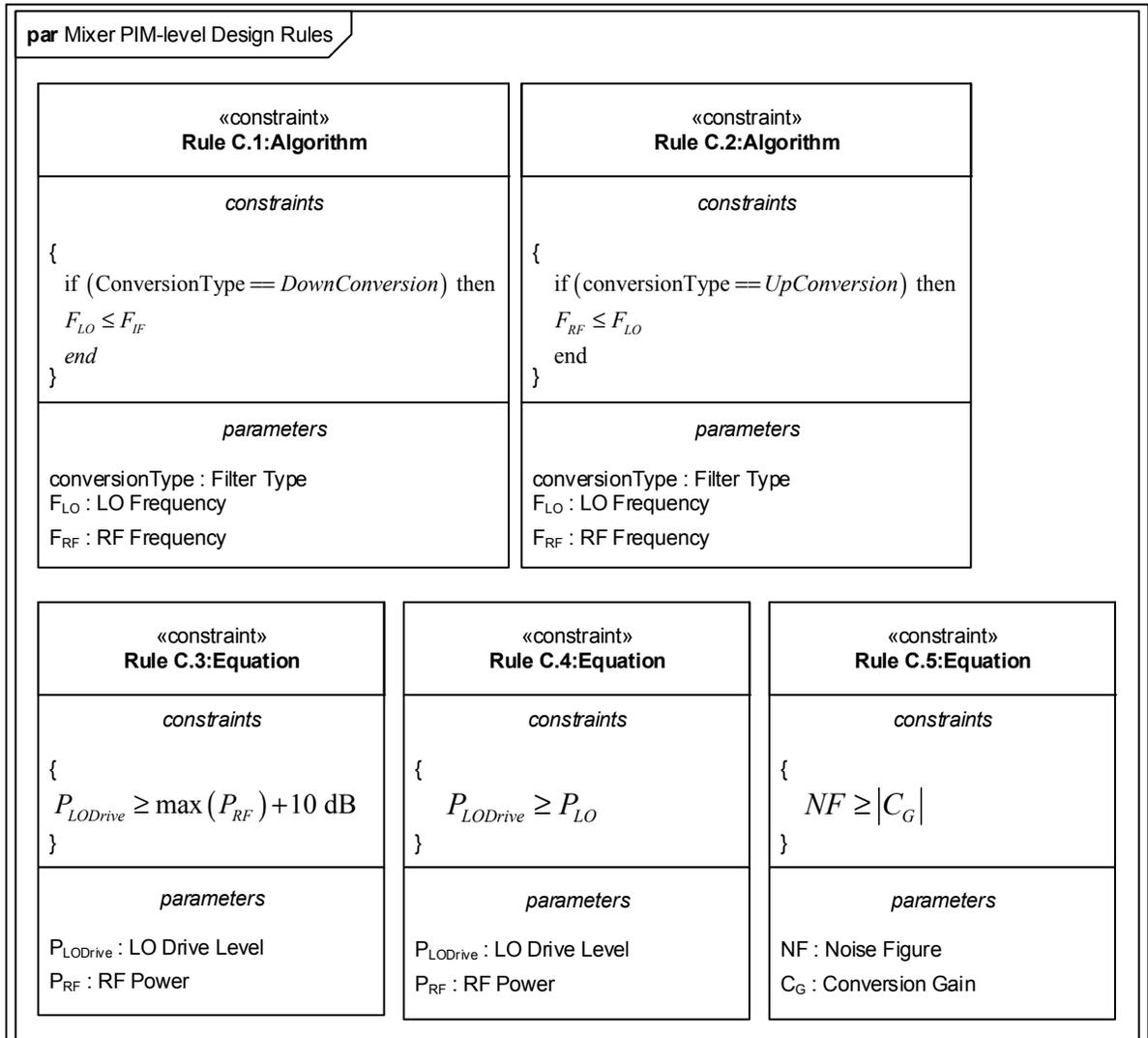


Figure 5.91 Coherence rules: PIM-level design rules

Let us consider the following notations:

$C_G$	Conversion gain
$C_{Gcomp}$	Conversion gain compression
$C_{Gflat}$	Conversion gain flatness
$F_{IF}$	Frequency at IF port
$F_{LO}$	Frequency at LO port
$F_{RF}$	Frequency at RF port
$P_{1dB}$	1-dB compression point
$P_{IF}$	Power at IF port

$P_{LO}$	Power at LO port
$P_{LOdrive}$	LO drive level
$P_{RF}$	Power at RF port
$R_{LOIF}$	LO-IF rejection
$R_{LORF}$	LO-RF rejection
$Z_{ref}$	Reference impedance
$ACPR$	Adjacent channel power ratio
$BW$	Bandwidth
$IMD$	Intermodulation distortion
$IP2$	Second-intercept point
$IP3$	Third-intercept point
$MDS$	Minimum detectable signal
$NF$	Noise figure
$RL$	Return loss
$SFDR$	Spurious-free dynamic range
$THD$	Total harmonic distortion
$VSWR$	Voltage standing wave ratio

The mixer coherence rules are of three types:

- PIM-level design constraints' rules: these rules ensure that the PIM-level design candidate is feasible. The rules C.1 through C.5 in Table 5.44 ensure that the mixer properties are within a feasible design extent;
- The electrical consistence rules: these rules ensure that the relationships between the mixer properties are valid. The parameters relationships graph (PRG) depicted in Figure 5.89 and the corresponding equations given in Table 5.45 allow to figure out if there are any contradictory mixer specifications;
- The integrity control rules: this type of rules ensure that the mixer properties are within a predefined acceptable range. Table 5.46 enumerates 35 rules which ensure the integrity of the mixer properties.

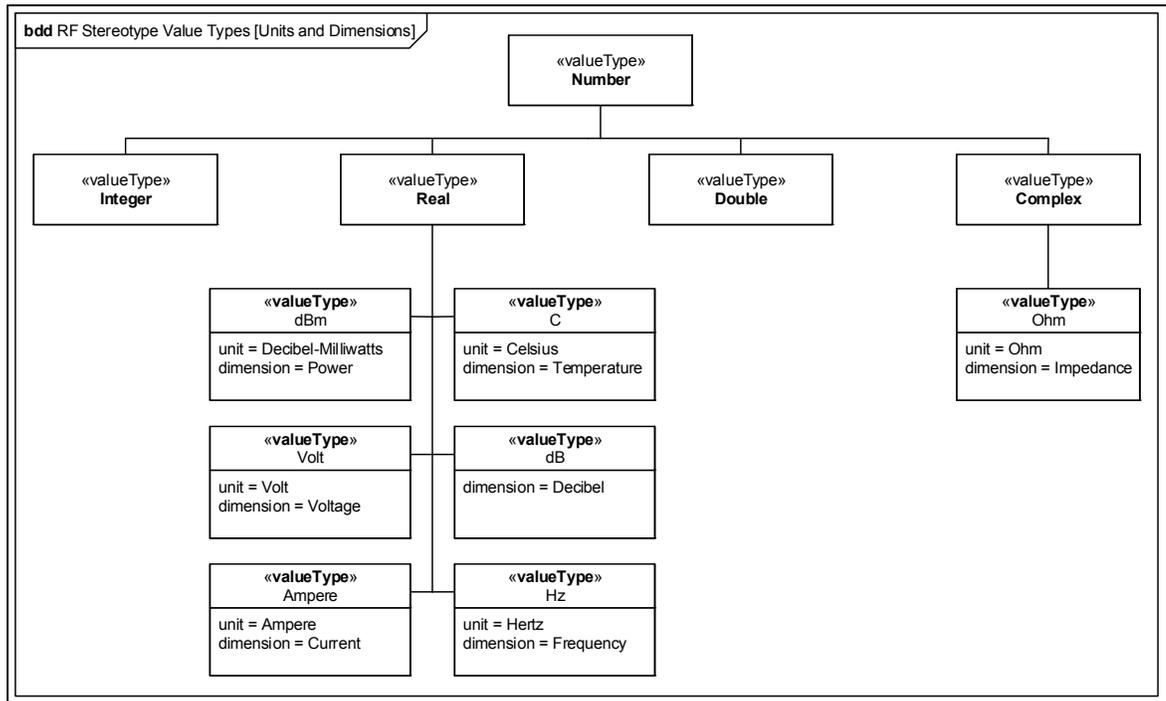


Figure 5.92 Mixer value types package

Table 5.44 Mixer PIM-level design constraints rules

No	Rule	if test fails
C.1	if <i>ConversionType</i> = <i>DownConversion</i> then $F_{LO} \leq F_{RF}$ end	Error
C.2	if <i>ConversionType</i> = <i>UpConversion</i> then $F_{LO} \geq F_{RF}$ end	Error
C.3	$P_{LODrive} \geq \max(P_{RF}) + 10 \text{ dB}$	Warning
C.4	$P_{LODrive} \geq P_{LO}$	Error
C.5	$NF \geq  C_g $	Warning

The mixer functional description was submitted to the coherence verification test. The results are depicted in the coherence verification report of Figure 5.94. As illustrated in this report, the rule C.5 throws a warning message. In fact, the noise figure should be greater or equal to the conversion gain. If the conversion gain was given (i.e.,  $C_G \leq -9.5 \text{ dB}$ ), the noise figure was not specified in the mixer specifications. For calculations, the default property value (i.e.,  $NF =$

3.0 dB) was considered. However, the default value violates this rule. To keep the specifications coherent, the noise figure property is either defined by the user or overridden by the conversion gain one.

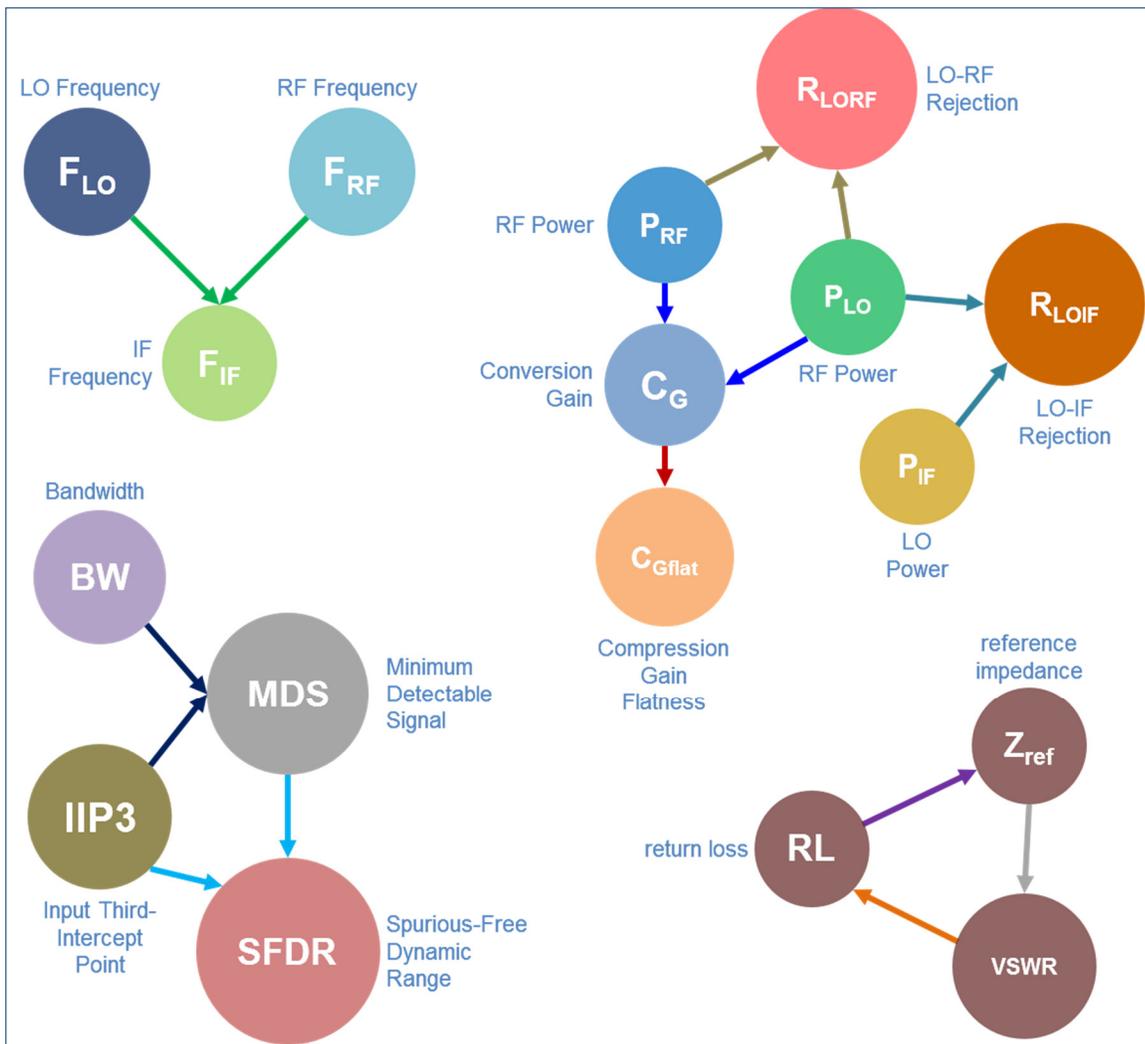


Figure 5.93 Mixer parameters relationships graph

- **Analysis: PIM-level granularity refinement and simulation**

After coherence verification test, we proceed to the search of a PIM-level design solution. At this level, we consider as black-box model the mathematical expression for RF frequency mixing given in the equation A III-20 (APPENDIX III, p. 459). The analysis of the mixer RM/PIM models using this black-box model allow a preliminary design solution. This one provides an output spectrum as illustrated in Figure 5.95.

The black-box model performance is not satisfactory. It requires more adjustments for better performance results. This can be done using a PIM-level granularity refinement process. However, we choose to skip this step in this case study.

Table 5.45 Common relationships between mixer parameters given in Figure 5.87

Arrow Color	Mathematical Relationship	Parameter
●	$C_G = P_{IF} - P_{RF}$	Compression Gain
●	$C_{Gflat} = \max( C_g ) - \min( C_g )$	Compression Gain Flatness
●	$F_{IF} = F_{RF} \pm F_{LO}$	IF Frequency
●	$R_{LORF} = P_{LO} - P_{RF}$	LO-RF Rejection
●	$R_{LOIF} = P_{LO} - P_{IF}$	LO-IF Rejection
●	$MDS = \frac{2}{3}[IIP3 - 10 \cdot \log(k \cdot T \cdot BW)]$	Minimum Detectable Signal
●	$SFDR = \frac{2}{3}[IIP3 - MDS]$	Spurious-Free Dynamic Range
●	$VSWR = \frac{10^{\frac{RL}{20}} + 1}{10^{\frac{RL}{20}} - 1}$	Voltage Standing Wave Ratio
●	$RL = \frac{Z_L - Z_S}{Z_L + Z_S}$	Return Loss

Table 5.46 Mixer integrity control rules

No.	Rule	if test fails
I.1	$-80 \leq \text{temperatureRange} \leq 100$	Error or/and Warning
I.2	$\text{ratingTemperatureRange} \in \{\text{TRUE}, \text{FALSE}\}$	Error
I.3	$1 \leq VSWR \leq 10$	Error or/and Warning
I.4	$\text{no} \in \mathbb{N}^*$	Error
I.5	$0 < Z_{ref} \leq 10^4$	Error or/and Warning
I.6	$0 \leq NF \leq 10^2$	Error or/and Warning
I.7	$0 < RL \leq 120$	Error or/and Warning
I.8	$\text{ptype} \in \{\text{DC}, \text{IF}, \text{RF}\}$	Error

No.	Rule	if test fails
I.9	connection $\in$ {TERMINATED,OPENED,SHORTED}	Error
I.10	direction $\in$ {IN,OUT,INOUT}	Error
I.11	$0 \leq \text{frequencyRange} \leq 10^{12}$	Error or/and Warning
I.12	$0 \leq \text{powerRange} \leq 160$	Error or/and Warning
I.13	$0 \leq \text{voltageRange} \leq 10^4$	Error or/and Warning
I.14	$0 \leq \text{currentRange} \leq 10^2$	Error or/and Warning
I.15	ratingFrequency $\in$ {TRUE, FALSE}	Error
I.16	ratingPower $\in$ {TRUE, FALSE}	Error
I.17	ratingVoltage $\in$ {TRUE, FALSE}	Error
I.18	ratingCurrent $\in$ {TRUE, FALSE}	Error
I.19	$-100 \leq P_{1dB} \leq 100$	Error or/and Warning
I.20	$-100 \leq IP2 \leq 100$	Error or/and Warning
I.21	$-100 \leq IP3 \leq 100$	Error or/and Warning
I.22	$0 \leq \text{THD} \leq 120$	Error or/and Warning
I.23	$0 \leq \text{IMD} \leq 120$	Error or/and Warning
I.24	$0 \leq \text{SDR} \leq 120$	Error or/and Warning
I.25	$0 \leq \text{ACPR} \leq 120$	Error or/and Warning
I.26	$0 \leq \text{SFDR} \leq 120$	Error or/and Warning
I.27	$0 \leq \text{MDS} \leq 120$	Error or/and Warning
I.28	$0 < BW \leq 10^{12}$	Error or/and Warning
I.29	$-100 \leq C_G \leq 100$	Error or/and Warning
I.30	$-100 \leq C_{Gcomp} \leq 100$	Error or/and Warning
I.31	$0 \leq C_{Gflat} \leq 120$	Error or/and Warning
I.32	$0 \leq R_{LORF} \leq 120$	Error or/and Warning
I.33	$0 \leq R_{LOIF} \leq 120$	Error or/and Warning
I.34	$-200 \leq P_{LOdrive} \leq 120$	Error or/and Warning
I.35	conversionType $\in$ {UPCONVERSION, DOWNCONVERSION}	Error

```

***** Coherence Verification Test *****
TARGET PIM: 2.4425-GHz PASSIVE MIXER (C:\Users\slafi\Documents\Design\2.4425ghz_mix.xml)

-> Electrical Consistence Rules (9 found)
..... PASS
-> PIM-level Design Constraints Rules (5 found)
    RULE C.5..... WARNING
        Desc.: Noise Figure property (Default Value: 3.0)
               must be greater or equal to Abs(Conversion
               Gain) (User-Defined: 9.5)!
-> Integrity Control Rules (35 found)
..... PASS
Summary: (1) Warnings (0) Errors

```

Figure 5.94 Mixer coherence verification report

- **Analysis: PSM generation**

The PIM-level solution (i.e., black-box model) is then submitted to a suitable transformation to generate one or many PSMs for each target platform. We consider in the following two PIM-to-PSM transformations which derive a couple of design solutions for traditional PCB platform (both transformations are based on the design procedures of passive diode mixers in (Sayre, 2008, pp. 383-388):

**a) Passive diode mixer PIM-to-PSM transformation**

This first transformation is detailed in Table 5.47. It produces a passive single-ended diode mixer in three steps:

**1. Step 1: Selection of input and output capacitors and inductors**

In the first step, we select suitable capacitors' and inductors' values for the input and output sections of a traditional single-ended diode mixer topology.

**2. Step 2: Selection of diode**

In the second step, we select a diode model (either ideal or semi-ideal) for best possible operation (e.g., power rating). It is important to notice that no technology characteristics are considered yet. The diode is considered as an electrical model that has a mathematically-computable electrical behavior.

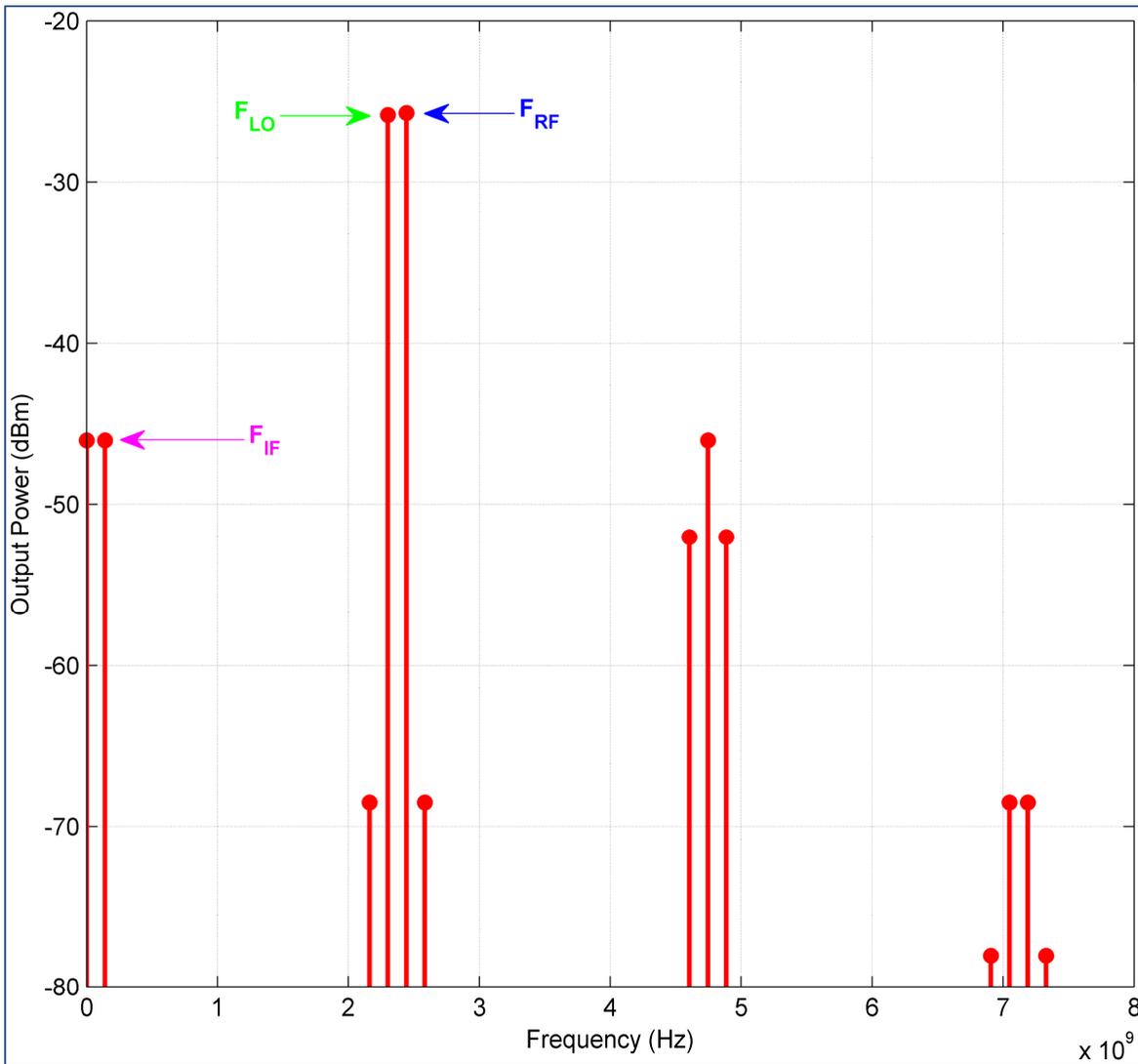


Figure 5.95 Black-box model frequency response

### 3. Step 3: Synthesis of circuit topology

Finally, the transformation derives the topology of Figure 5.96.a by connecting the discrete elements and diodes as required.

#### b) Rat-race Mixer PIM to PSM transformation

The second transformation is detailed in Table 5.48. This transformation generates a PSM in three steps. The first one is dedicated to the selection of the suitable operation diodes. Next, an output IF filter is designed as detailed in the transformation of Table 5.10. Finally, it generates the PSM topology as illustrated in Figure 5.96.b.

Table 5.47 Passive diode mixer PIM-to-PSM transformation

<p><b>Step 1: Selection of input and output capacitors and inductors</b></p> <p>1.1. Select the values of input capacitor <math>C_1</math> and inductor <math>L_1</math> in a way that the ratio <math>r_1 = \frac{C_1}{L_1} \gg 1</math> (<math>r_1</math> should be as large as possible).</p> <p>1.2. Select the values of input capacitor <math>C_2</math> and inductor <math>L_2</math> in a way that the ratio <math>r_2 = \frac{C_2}{L_2} \gg 1</math> (<math>r_2</math> should be as large as possible).</p> <p><b>Step 2: Selection of diode</b></p> <p>2.1. Select a suitable operation passive diode <math>D_1</math>.</p> <p><b>Step 3: Synthesis of circuit topology</b></p> <p>3.1. Generate the circuit topology as depicted in Figure 5.92.a.</p>
---

Table 5.48 Rat-race Mixer PIM to PSM transformation

<p>Consider the properties for each transmission-line section:</p> $\begin{cases} Z_{ci} = Z_{reference} \\ E_i = E_{default} \\ F_i = F_0 \\ A_i = A_{default} \end{cases}$ <p>where <math>Z_{ci}</math> is the characteristic impedance of the transmission line, <math>E_i</math> is its electrical length, <math>F_i</math> is the frequency at which the electrical length is calculated and <math>A_i</math> is the transmission line loss (in dB).</p> <p><b>Step 1: Selection of diodes</b></p> <p>1.1. Select suitable operation passive diodes <math>D_1</math> and <math>D_2</math>.</p> <p><b>Step 2: Design of output IF filter</b></p> <p>2.1. Design an LC bandpass filter centered at <math>F_{IF}</math> and bandwidth <math>BW</math> as given in the transformation of Table 5.10.</p> <p><b>Step 3: Synthesis of transmission lines and circuit topology</b></p> <p>3.1. Generate the circuit topology as depicted in Figure 5.96.b.</p> <p>3.2. For transmission-line sections A, consider the following properties:</p> $\begin{cases} Z_{ci} = 70.7 \Omega \\ E_i = 90^\circ \\ F_i = \frac{F_{RF} + F_{LO}}{2} \\ A_i = A_{default} \end{cases}$ <p>3.3. For transmission-line section B, consider the following properties:</p> $\begin{cases} Z_{ci} = 70.7 \Omega \\ E_i = 270^\circ \\ F_i = \frac{F_{RF} + F_{LO}}{2} \\ A_i = A_{default} \end{cases}$
--

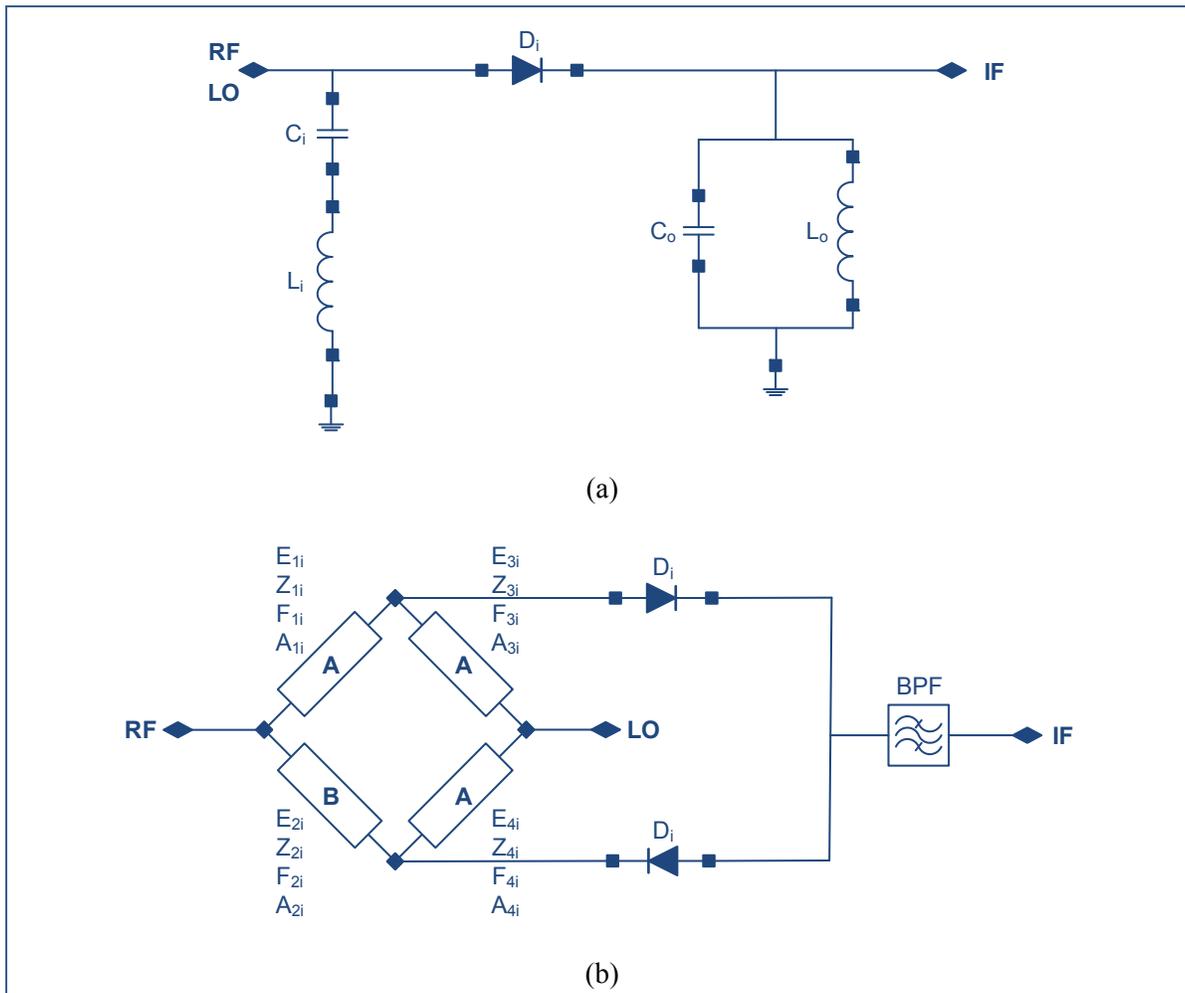


Figure 5.96 PSM topology: passive (a) single-ended diode and (b) rat-race mixer

On the opposite of the PIM-to-PSM transformations used in the previous case studies, the transformations applied to the mixer PIM do not directly generate the PSM artefacts from their PIM counterparts. The relationship between the PIM and the PSM entities is implicit. However, this procedure does not violate the definition of a « model-to-model transformation » because there is still a strong semantic relationship between the source and destination models. In this case, the relationship is established mathematically where the PSM is a topology whose frequency response is an approximate function which approaches the equation-based black-box model.

The use of both PIM-to-PSM transformations results in two distinct PSMs. Figure 5.97, 5.98, 5.99 and 5.100 depict a comparison of their performance.

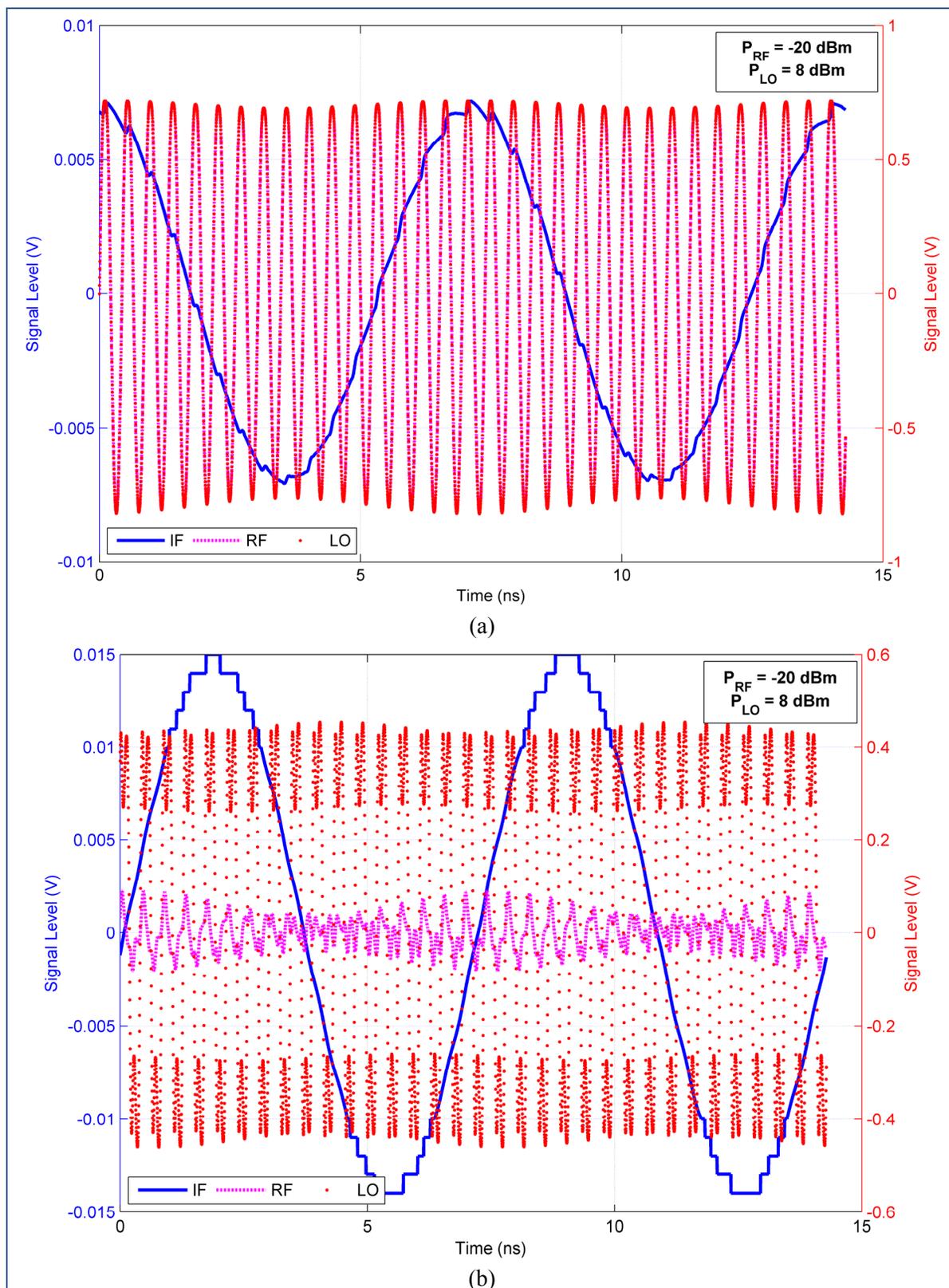


Figure 5.97 Voltage waves: (a) Single-ended and (b) rat-race diode mixer

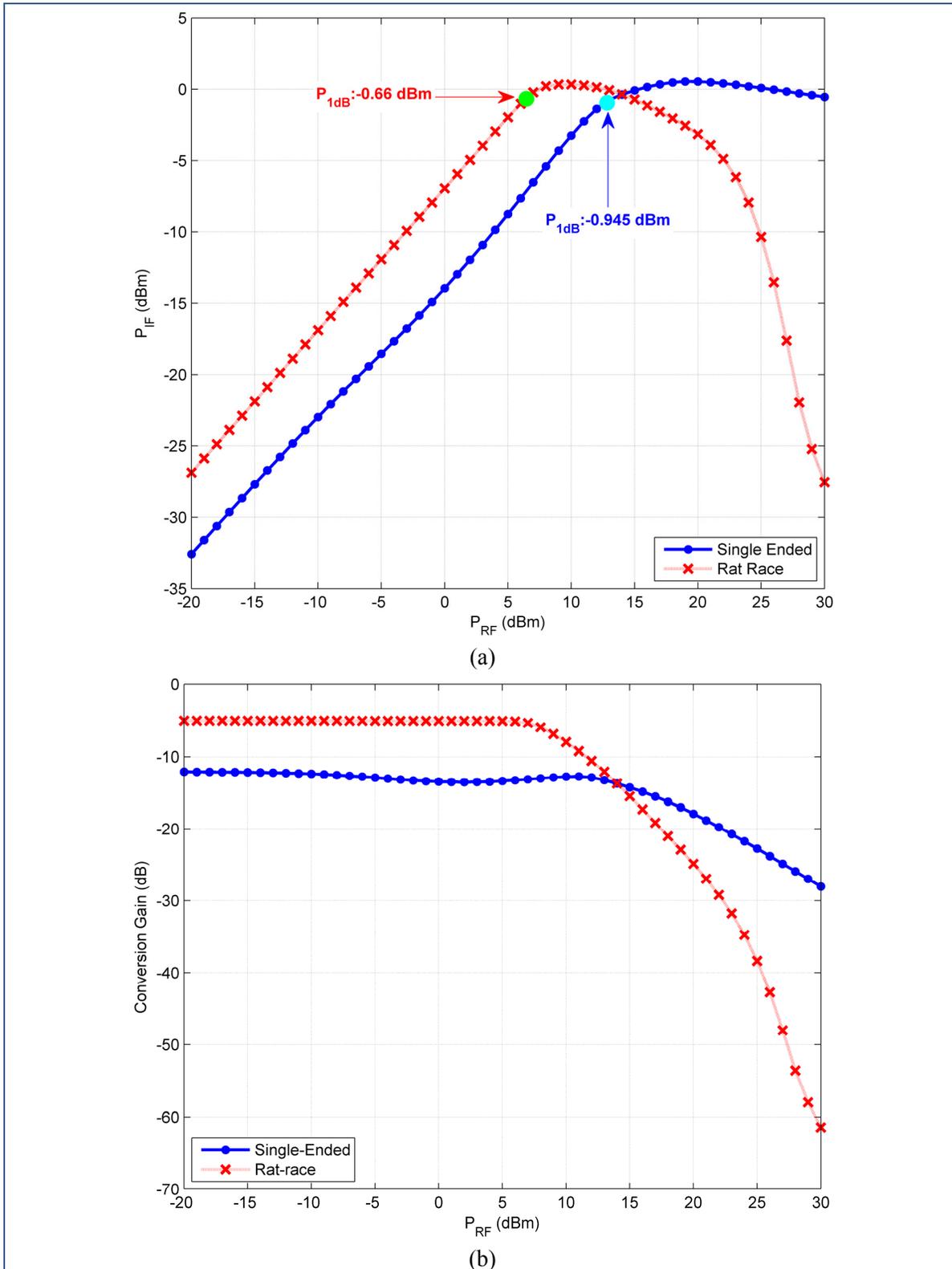


Figure 5.98 (a) Output versus input power and (b) conversion gain of both mixers

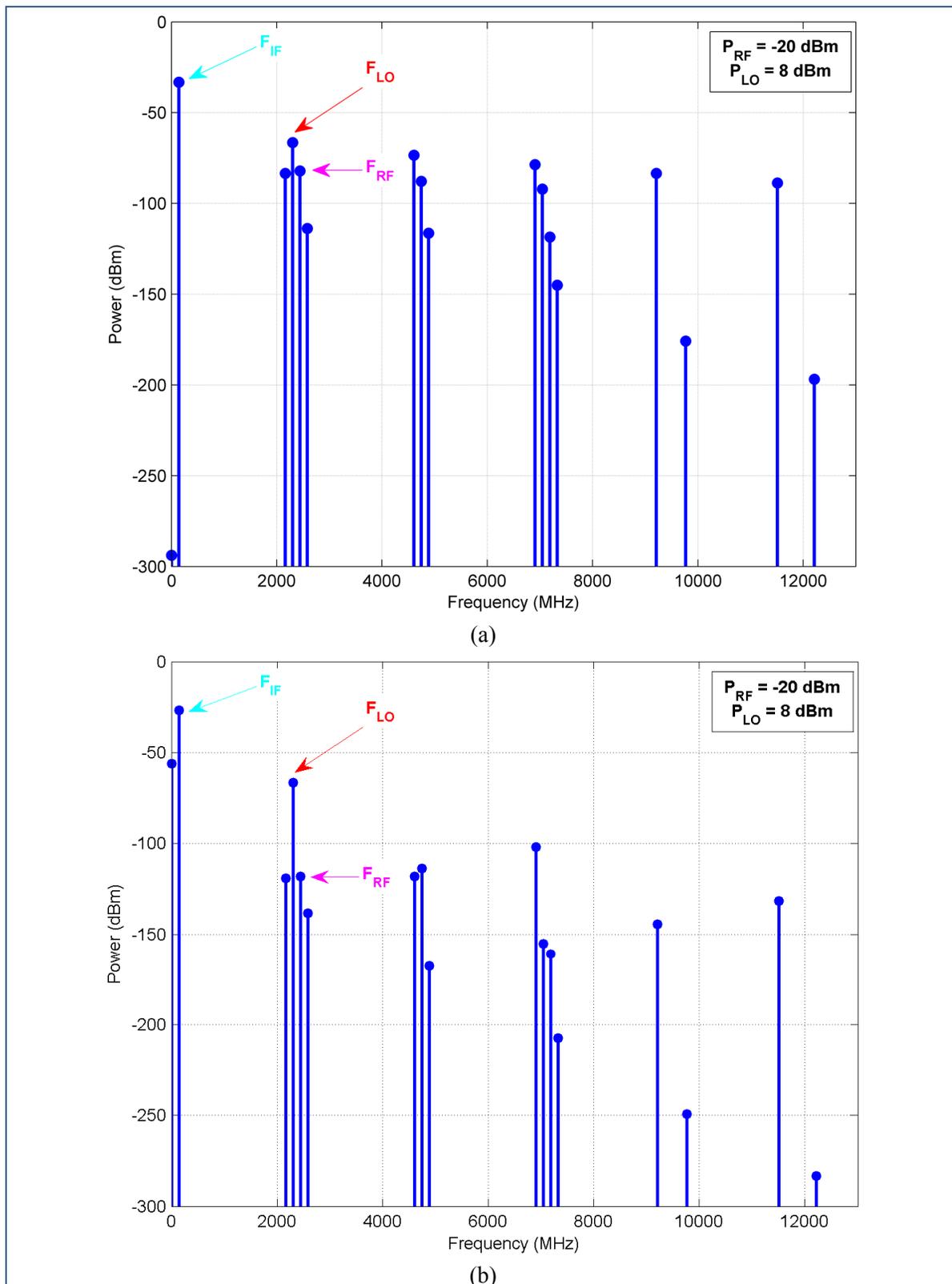


Figure 5.99 Output Spectrum: (a) Single-ended and (b) rat-race diode mixer

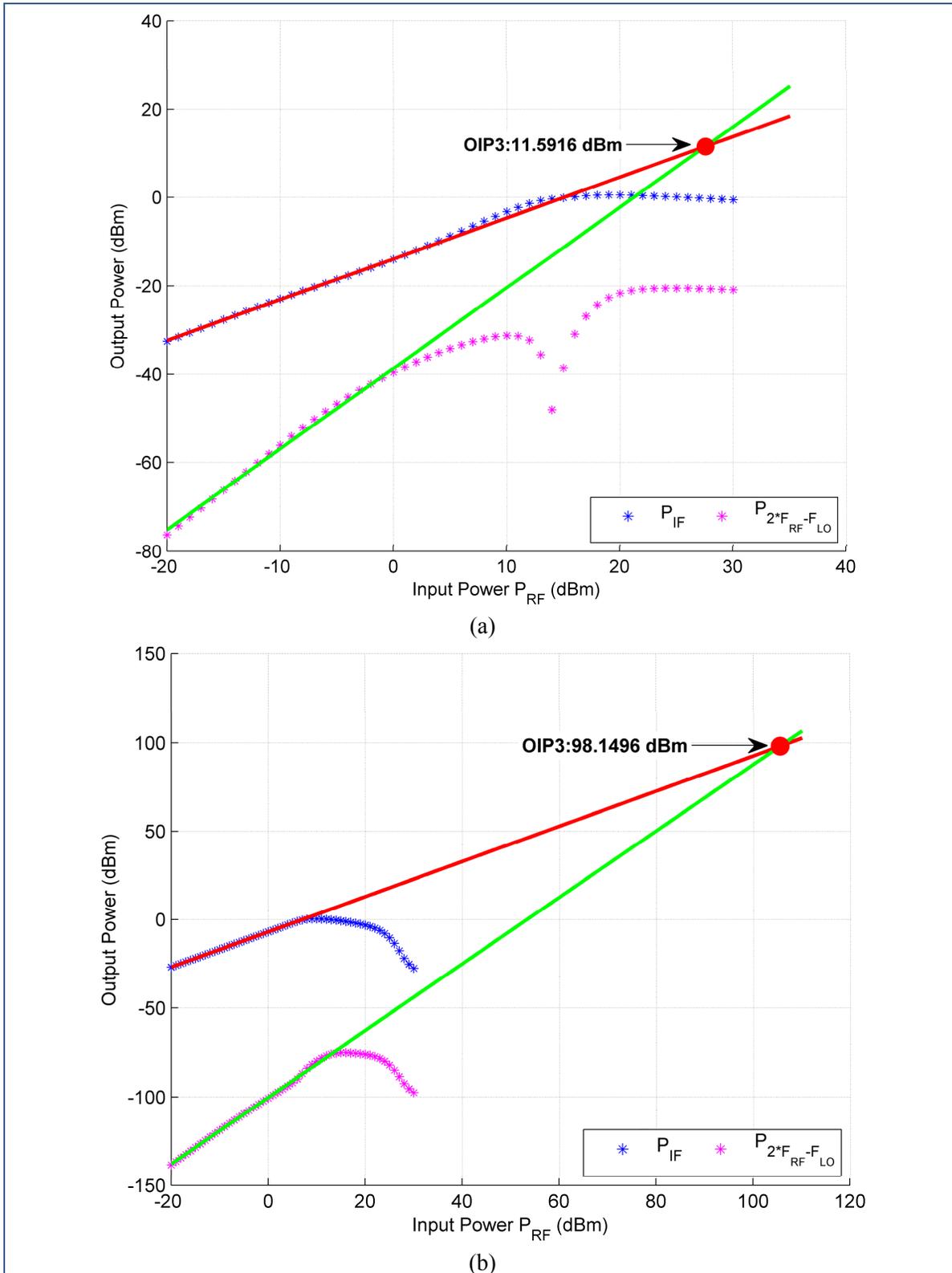


Figure 5.100 Output Third-Intercept Point: (a) Single-ended and (b) rat-race diode mixer

At this point, we need to figure out what is the best PSM in terms of performance. Table 5.49 compares the performance of each PSM against specifications. The retained metrics are conversion gain, LO-RF and LO-IF rejections as well as the 1-dB compression and the third-intercept points. The first three metrics are mandatory because they are included in the requirement diagrams. The latter ones are optional.

Table 5.49 Generated PSMs: Summary of both mixer PSMs performance characteristics

	Specifications	Single-Ended Mixer	Rat-Race Mixer
<b>Conversion Gain (dB)</b>	> -9.5	-12.745	-5.0965
<b>LO-RF Rejection (dB)</b>	> 20 dB	15.653	51.565
<b>LO-IF Rejection (dB)</b>	> 30 dB	33.276	39.633
<b>1-dB Compression Point (dBm)</b>	18*	-0.945	-0.66
<b>Third-Intercept Point (dBm)</b>	33*	11.5916	98.1496

(\*) Due to the absence of a user-defined value, default values in PSM/RM models were considered.

Table 5.50 Generated PSMs: Objective function calculations for each filter prototype

	Constant Weights $C_i$	Variable Weights $X_i$	
		Single-Ended Mixer	Rat-Race Mixer
<b>Conversion Gain (dB)</b>	4.0	0	1
<b>LO-RF Rejection (dB)</b>	2.0	$\frac{15.653}{20} = 0.78265$	$\frac{51.565}{20} = 2.57825$
<b>LO-IF Rejection (dB)</b>	2.0	$\frac{33.276}{30} = 1.1092$	$\frac{39.633}{30} = 1.3211$
<b>1-dB Compression Point (dBm)</b>	1.0	$\frac{ -0.945 }{18} = 0.0525$	$\frac{ -0.66 }{18} = 0.03667$
<b>Third-Intercept Point (dBm)</b>	1.0	$\frac{ 11.5916 }{33} = 0.3512$	$\frac{ 98.1496 }{33} = 2.9742$
$\sum C_i X_i$		<b>2.29555</b>	<b>7.91022</b>

Using the automated decision making process detailed in section 4.3.5(c), the calculations of the objective functions for both PSMs are reported in Table 5.50. The rat-race mixer PSM

yields a higher score than its single-ended counterpart. This result is in accordance with the comparison performance curves already shown in Figure 5.97-5.100.

- **Synthesis: technology mapping**

After the performance assessment of both PSMs, we retain the rat-race mixer one. We also consider at this stage that its performance is relatively satisfactory. Thus, there is no need to undertake a PSM-level granularity refinement process in the purpose of enhancing the quality of that design solution. Next, we should augment the selected PSM with the appropriate technology information. We consider the implementation of this PSM using microstrip transmission lines (see RO3006 substrate properties in Table 5.24) and lumped components. Then, the technology mapping process results in:

- 1- The synthesis of transmission-line sections of the rat-race mixer PSM using the substrate RO3006,
- 2- A search for appropriate diode parts, and
- 3- A search of capacitors and inductors for the output IF bandpass filter.

Using a commercial package (i.e., LineCalc), the microstrip sections are synthesized and the results are reported in Table 5.51.

Table 5.51 Properties of the synthesized rat-race microstrip sections (RO3006 substrate)

Transmission Line	Properties					
	Width (mil)	Length (mil)	Radius (mil) (Angle (°))	Effective Dielectric Constant	Total Structure Attenuation (dB)	Skin Depth
<b>Section A</b>	17.423425	-	586.69462 (60°)	4.097	0.064	0.063
<b>Section B</b>	17.423425	-	586.69462 (60°)	4.097	0.064	0.063
<b>Section C</b>	17.423425	-	586.69462 (60°)	4.097	0.064	0.063
<b>Section D</b>	17.423425	-	586.69462 (180°)	4.097	0.192	0.063
<b>Port sections</b>	35.984449	66.122441	-	4.367	0.005	0.063

We also made a search in the technology library in order to figure out the best diode parts for the selected PSM. Three candidate diodes were identified. Their properties are listed in Table 5.52.

Table 5.52 List of suitable diode parts found in the technology library

Diode Parameter	Unit	Manufacturer Part Name		
		HSCH-5310*	HMPS-2820*	HSMP-5332*
$B_v$	V	5	15	5
$C_{JO}$	pF	0.09	0.7	0.13
$E_G$	eV	0.69	0.6	0.69
$I_{BV}$	A	$10^{-5}$	$10^{-4}$	$10^{-5}$
$I_S$	A	$3 \cdot 10^{-10}$	$2.2 \cdot 10^{-8}$	$4 \cdot 10^{-8}$
$N$		1.08	1.08	1.08
$R_S$	$\Omega$	13	8	9
$P_B$	V	0.65	0.65	0.5
$P_T$		2	2	2
$M$		0.5	0.5	0.5
Frequency range		1 GHz – 26 GHz	10 MHz – 6 GHz	1 GHz – 26 GHz
Description		Low to medium barrier beam lead Schottky diode	Low barrier beam lead Schottky diode	Medium barrier beam lead Schottky diode

\* Avago Technologies

**Legend:**

- $B_v$  Reverse breakdown voltage
- $C_{JO}$  Zero-bias junction capacitance
- $E_G$  Activation energy
- $I_{BV}$  Reverse breakdown current
- $I_S$  Saturation current (diode equation)
- $N$  Emission coefficient, 1 to 2
- $R_S$  Parasitic resistance (series resistance)
- $P_B$  Contact potential at periphery junction
- $P_T$  Junction periphery
- $M$  Junction grading coefficient

For IF bandpass filter inductors and capacitors, we made an automated search in the same custom technology library that we used in the previous case studies (see Figure 5.101). We found out several parts whose properties are respectively reported in Table 5.53. and 5.54.

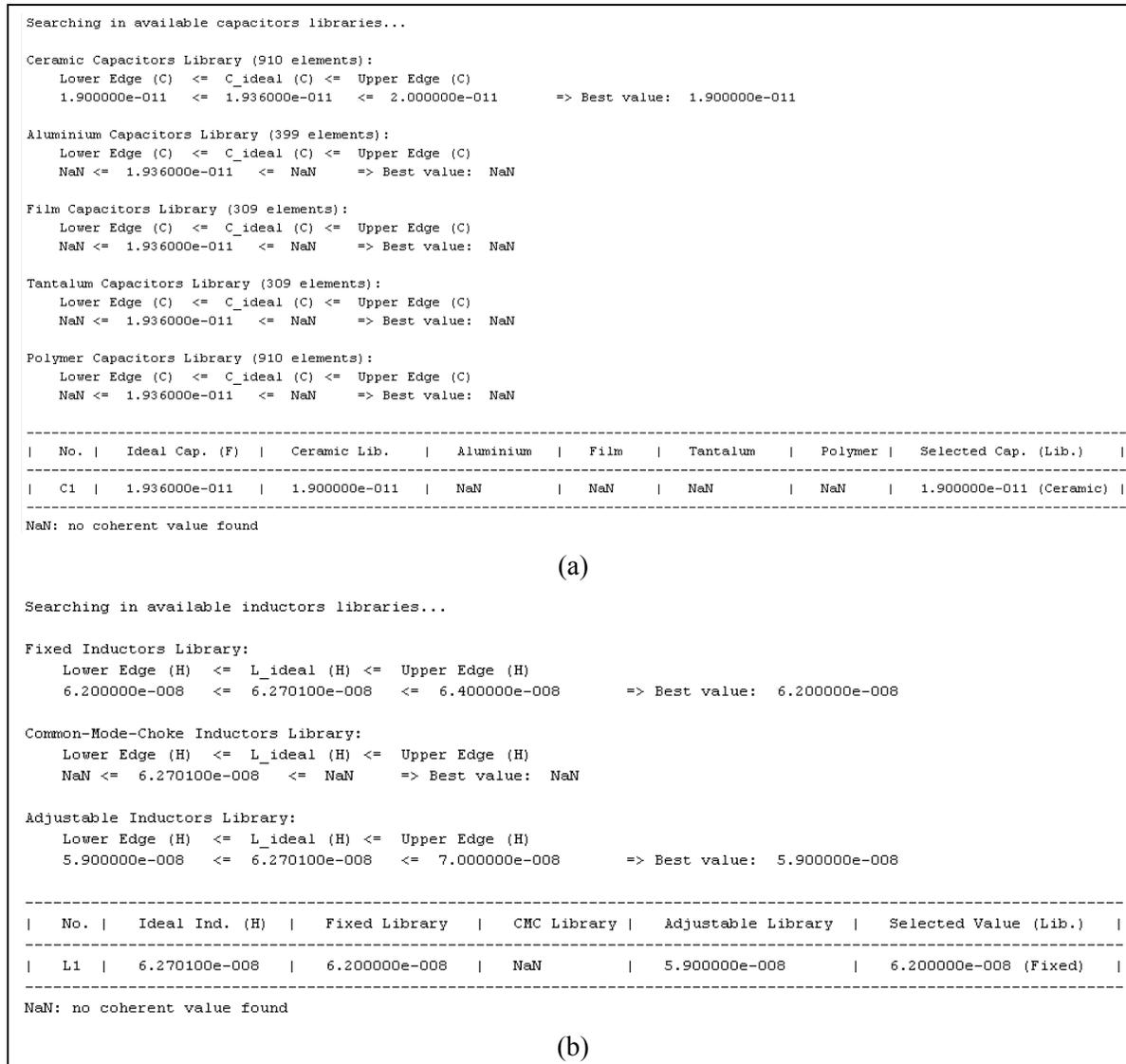


Figure 5.101 Technology mapping results for (a) capacitor and (b) inductor elements

Table 5.53 List of inductor parts found in the technology library during automated technology mapping

Ideal Value (nH)	Real Value (nH)	Manufacturer Part Number	Tolerance	Max. DC Resistance ( $\Omega$ )	Frequency Self-Resonance (GHz)	Q @ 200 MHz	Package	Dimensions (mm)		
								L	W	H
62.701	62	LQW15AN62NG00D*	$\pm 2\%$	1.82	2.6	20	0402	1	0.5	0.6
62.701	62	LQW18AN62NG00D*	$\pm 2\%$	0.51	2.3	38	0603	1.6	0.8	1
62.701	62	MLG0603S62NJT000*	$\pm 5\%$	1.4	1.1	5	0603	0.6	0.3	0.33
62.701	62	LQW15AN62NJ00D*	$\pm 5\%$	1.82	2.6	20	0402	1	0.5	0.6

\* Murata Electronics North America

\* TDK Corporation

Table 5.54 List of capacitor parts found in the technology library during automated technology mapping

Ideal Value (pF)	Real Value (pF)	Manufacturer Part Number	Family	Tolerance	Dimensions (mm)		
					L	W	H
19.36	19	AQ137M190FA1BE*	Ceramic	$\pm 1\%$	0.11	0.11	0.102
19.36	18	0402ZK180GBSTR*	Thin Film	$\pm 2\%$	1	0.55	0.5
19.36	18	0402ZK180FBSTR*	Thin Film	$\pm 1\%$	1	0.55	0.5
19.36	20	08055J200FBTTR*	Thin Film	$\pm 1\%$	2.01	1.27	1.13
19.36	20	12101K220JBTTR*	Thin Film	$\pm 5\%$	3.02	2.5	1.13

\* AVX Corporation

Since we obtained three candidate diode parts with different operation properties, we derived three prototypes from the selected PSM. After the simulation of each prototype, we compared their performance using the same metrics of Table 5.49. The results are listed in Table 5.55. Then, we calculated the objective function for each prototype. As illustrated in Table 5.56, the gap between the prototypes is relatively narrow. As expected, the prototype using the low to medium barrier beam lead Schottky diode, namely HSCH-5310, performs better than the others. This observation is confirmed by its flat conversion gain for an input RF power level up to 5 dBm, as shown in Figure 5.102. On the contrary, the other diode parts show less flat conversion gain when  $P_{RF} \geq 0$  dBm. This indicates that the HSCH-5310 rat-race mixer prototype is more linear and provides a safe margin for high input power levels.

Table 5.55 Comparison of the performance of the three PSM prototypes

	Specifications	HSCH-5310	HMPS-2820	HSCH-5332
<b>Conversion Gain (dB)</b>	> -9.5	-7.4281	-9.1535	-7.6307
<b>LO-RF Rejection (dB)</b>	> 20 dB	53.239	42.093	55.382
<b>LO-IF Rejection (dB)</b>	> 30 dB	36.359	33.182	33.525
<b>1-dB Compression Point (dBm)</b>	18*	-2.511	-4.24	-4.08
<b>Third-Intercept Point (dBm)</b>	33*	89.141237	80.415848	83.358509

(\*) Due to the absence of a user-defined value, default values in PSM/RM models were considered.

- **Synthesis : PM generation**

We selected the technology-mapped PSM using the HSCH-5310 diode part of platform-model generation. Using a commercial design package (i.e., ADS), we generated the PM as shown in Figure 5.103.

Table 5.56 Technology mapped PSM: Objective function calculations for each rat-race mixer prototype

	Constant Weights $C_i$	Variable Weights $X_i$		
		HSCH-5310	HMPS-2820	HSCH-5332
Conversion Gain (dB)	4.0	1	1	1
LO-RF Rejection (dB)	2.0	$\frac{53.239}{20} = 2.66195$	$\frac{42.093}{20} = 2.10465$	$\frac{55.382}{20} = 2.7691$
LO-IF Rejection (dB)	2.0	$\frac{36.359}{30} = 1.212$	$\frac{33.182}{30} = 1.106$	$\frac{33.525}{30} = 1.1175$
1-dB Compression Point (dBm)	1.0	$\frac{ -2.511 }{18} = 0.1395$	$\frac{ -4.24 }{18} = 0.2355$	$\frac{ -4.08 }{18} = 0.02267$
Third-Intercept Point (dBm)	1.0	$\frac{ 89.141237 }{33} = 2.7012$	$\frac{ 80.415848 }{33} = 2.4368$	$\frac{ 83.358509 }{33} = 2.526$
	$\sum C_i X_i$	<b>7.71465</b>	<b>6.88295</b>	<b>7.43527</b>

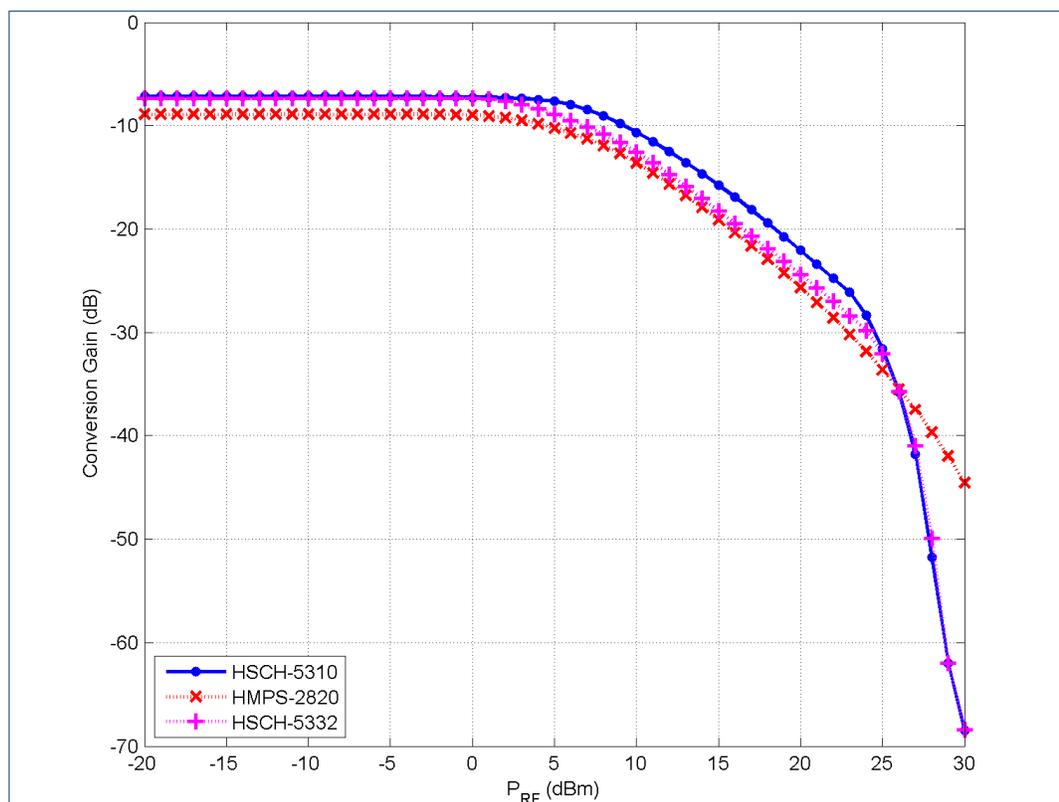


Figure 5.102 Conversion gain of the generated PSMs after technology mapping



## 1. The storage of both linear and nonlinear data from different sources

As illustrated in Figure 5.104, it is possible to populate the Q-matrix with linear data (e.g., scattering parameters) and nonlinear data (resulting for example from harmonic balance simulations). For instance, Figure 5.104 shows a sample of scattering parameters (i.e.,  $S_{12}$  and  $S_{21}$ ) calculated at the frequency point 2442.5 MHz. At the same frequency, the output spectrum is computed at different frequencies including the IF located at 140 MHz.

## 2. The use of stored data for the interpretation of various parameters without additional overhead

The « *attachedPortConfig* » XML structure stores the frequency and power levels for each port. This information can be used to calculate some properties of the circuit. For instance, it is possible to calculate the mixer's conversion gain and the output spectrum as illustrated in Figure 5.104. The conversion gain is computed using the values of the power level at input and output ports respectively. The single data point of Figure 5.104 allows to draw two spectrum rays at the input and output frequencies since the power levels are known.

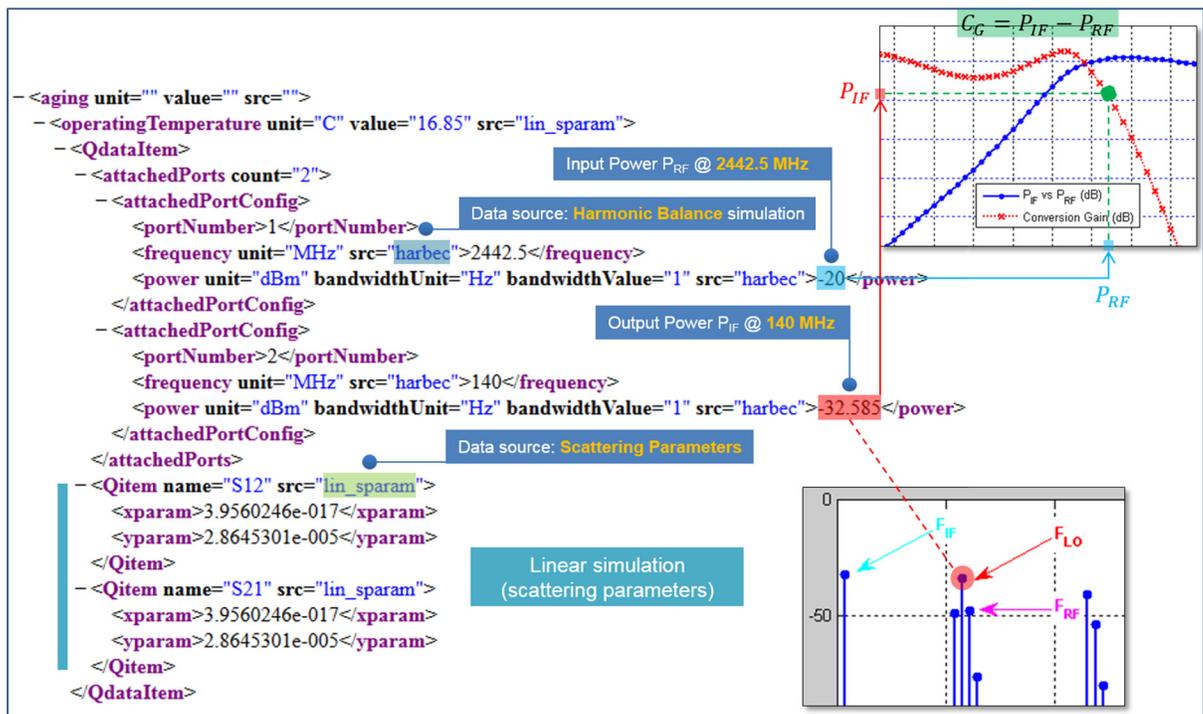


Figure 5.104 The Q-matrix stores both linear and nonlinear data

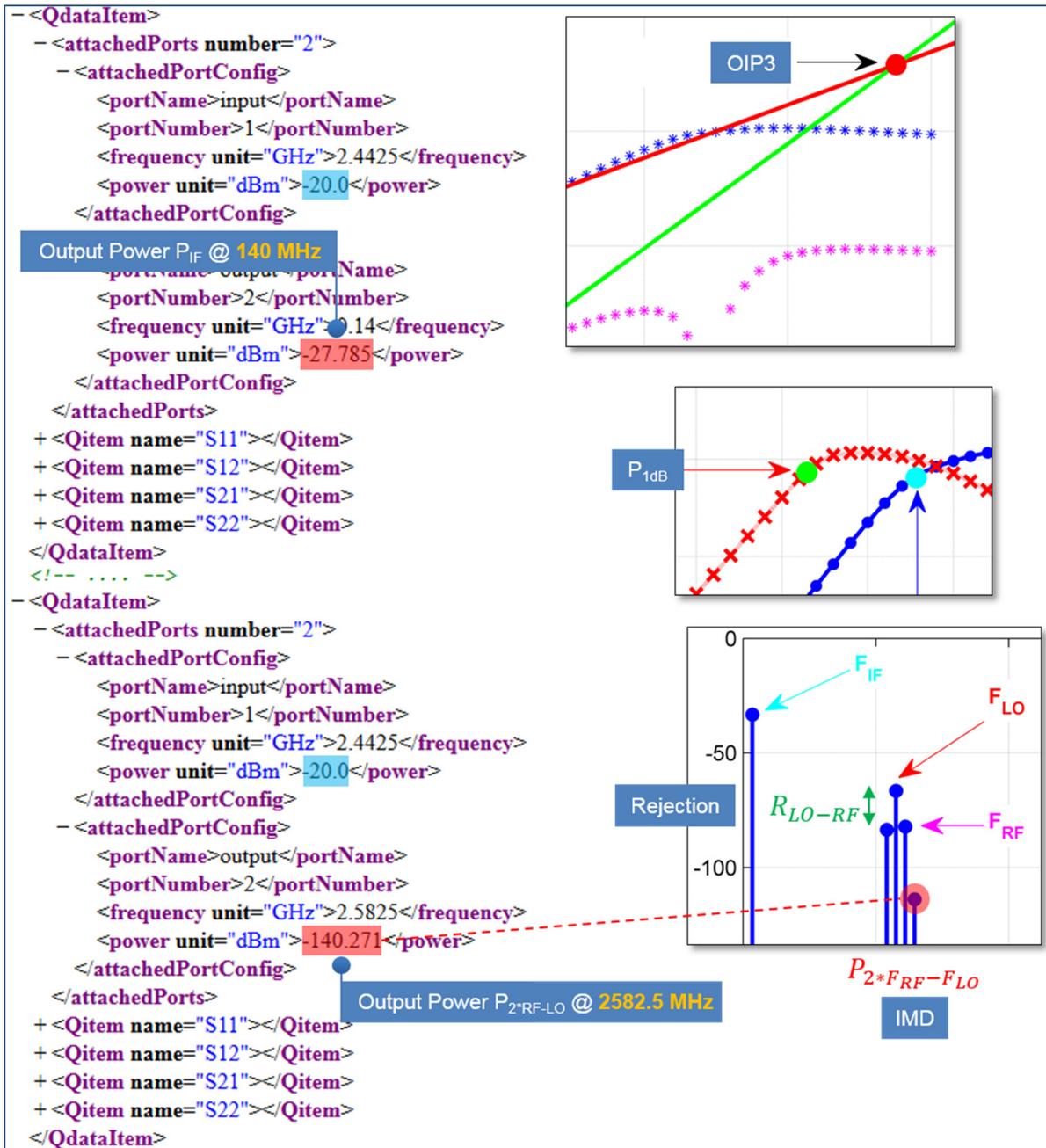


Figure 5.105 The Q-matrix stores data that can be interpreted in different ways

It is also possible to compute other parameters by cascading the information stored in different data points. For example, the LO-RF rejection  $R_{LO-RF}$  can be computed using the information given in two QdataItems where the output ports frequencies are respectively  $F_{LO}$  and  $F_{RF}$  (see Figure 5.105). The computation of parameters such as the output 1-dB compression and third-

intercept points require relatively more complex computations of several cascaded data points (i.e., *QdataItem*).

## 5.4 Conclusion

In this chapter, we attempted to validate the design framework already detailed in the previous two chapters. For this purpose, we started by reminding the basics of the design framework which we attempted to simplify in the form of a flowchart. Then, we selected five case studies that consisted of linear, nonlinear and system-level devices. In linear case studies, we detailed the design process of a lumped-component bandpass filter. Then, we showed how multiple transformations can be used to design a microstrip lowpass filter. We also demonstrated the concurrent design of a RF attenuator using the proposed framework. In nonlinear and system-level case studies, we designed a RF mixer and a direct-conversion receiver. For the mixer, we presented how the framework supports nonlinear design. In direct-conversion receiver, we showed that the framework enables the system-level analysis and design of complex front ends using PIM-level granularity refinement. We attempted in all the previous case studies to underline the role of the Q-matrix and how it supports linear, nonlinear and system-level design data.

In summary, the selected case studies showed that the proposed design framework provides:

- A complete end-to-end design flow enabling concurrent design,
- A set of concepts and mechanisms that address the key design issues hampering productivity and enhancing automation and tools interaction, and
- Foundations of an integrated design environment suitable for highly specialized tools (electrical and beyond).

Nevertheless, there are certain gaps in tools that should be bridged in order to make the proposed framework deployable. The required tools address various design issues:

- Functional description: intuitive tools for high-level models development (e.g., using SysML) and visualization as well as XML generation are needed.

- Coherence verification: tools to handle the functional description, the definition and the use of coherence rules are required.
- Black-box analyses: each functional description is associated in the PIM domain to one or many black-box models. Appropriate tools are required for the definition and use of black-box models for each functional description.
- Model-to-model transformations: the transition between models (either cross-domains or within the same domain) is carried out using model-to-model transformations. This requires specialized tools or/and APIs that enable the definition of transformation rules and derive target models from source ones. The granularity refinement requires also similar tools in both PIM and PSM domains.
- Technology mapping: the selection of technology artifacts for each model element requires not only technology input but also automated tools to accomplish the mapping operation.

In addition to tools used for the automation of design tasks, the framework relies on the quality of technology input required especially in PSM and PM domains. The current technology libraries are limited and underused. The proposed framework requires technology input that surpasses the performance and physical characterization of devices and circuits. It requires additional data about each technology component (e.g., 3D layouts, mechanical information, heat dissipation, power consumption and radiation profiles, etc.) in order to enable the use of advanced techniques of assessment and specialized analysis/synthesis tools.

The selected case studies have shown that the proposed design framework is useful and coherent. The abstraction concepts and the design mechanisms introduced by this framework contribute to the enhancement of the RF design practice (especially in terms of productivity and collaboration). To assure a wide adoption of this design framework, the future works should focus on:

- The definition of an integrated design environment that implements the foundations of this framework (especially in terms of abstraction strategy, design scheme, Q-matrix, etc.),
- The definition of a profile for the required technology input,
- The enumeration and integration of specialized tools to be used at each design step, and
- The formal validation of the Q-matrix.

## CONCLUSION

This thesis is the result of a research work conducted in the context of « Intelligent RF Project ». It aimed at the exploration of new methodologies for RF circuits design. In the light of the research activity results, this thesis intended to investigate the existing design approaches in digital, analog/mixed-signal and RF/microwave domains. The objective was to figure out the weaknesses and shortcomings of RF design practice considering the advances observed in similar design domains (mainly digital and analog). Following this critical review, the objective was to propose a new design methodology for RF devices that addresses primarily the issues and limitations of the current design methodologies. Next, suitable mechanisms and concepts to raise the abstraction level in RF design were proposed as well as they were integrated within a coherent framework. Finally, the final step was the validation of the proposed framework using selected design case studies for real applications.

In the purpose of achieving the objectives presented in the previous paragraph, this thesis was structured into five chapters. In the first one, we focused on the background of modern RF design practice. Thus, we briefly highlighted the evolution of wireless and mobile communications from both historical and economic perspectives. Then, we discussed the future trends in that domain and their expected impact on both manufacturing technologies and design approaches. Accordingly, we investigated the challenges in both fields and discussed the efforts being deployed to address them. We concluded that most attention of both industry and academia is dedicated to resolving technological issues rather than contributing to enhance RF/microwave design approaches and reducing the disparities between the design practice in this domain and other domains (i.e., digital and mixed-signal).

In the second chapter, we focused on the review of common design approaches used for mobile and wireless communications design. We elaborated a comparative study of common design approaches currently in use throughout three main domains: digital, analog/mixed-signal and RF/microwave. This comparative study resulted in the following main observations:

- The technology homogeneity and hierarchical design observed in digital (and to some extent, analog) domain allowed affordable design of complex chips. However, the

technology mix made it difficult to RF designers to come up with comparable achievements within the same timeframe;

- While the abstraction level in digital (and to some extent, analog/mixed-signal) domain is continuously raising, no clear abstraction levels are established in RF/microwave domain;
- Per transistor, RF designers spend several times more time than their digital counterparts. The time-to-market and the cost of RF devices remains higher than digital chips despite their reduced complexity.

We concluded that the disparities between digital (and analog/mixed-signal) and RF/microwave design in terms of tools sophistication, productivity and design reuse are mostly due to the absence of enough design abstraction in the latter.

In the third chapter, we proposed a five-step design scheme built around a multi-dimensional data structure, namely the Q-matrix, to address the major issues we noted in the previous chapters. This design scheme introduces new design stages such as functional description, in the purpose of raising the abstraction level in RF design. However, the proposed design scheme does not yet provide a complete abstraction strategy.

Consequently, we investigated in the fourth chapter the hardware abstraction strategies adopted in various domains ranging from digital/analog design to computer systems and software engineering. For each abstraction strategy, we particularly highlighted the impact of abstraction on automation and complexity management. Especially, we have outlined the main abstraction concepts recently adopted in model-driven engineering. Then, we proposed the abstraction strategy we elaborated for RF domain. Therefore, we started with the black-box model that we adopted for functional description. We showed that common RF devices and systems can be modeled as black-boxes whose inputs, outputs and functionality are only known. We demonstrated also that the black-box model can be captured using high-level modeling languages such as SysML. Next, we introduced four distinct abstraction levels (i.e., atomic layer, circuit, module and system) along with five different viewpoints (i.e., physical, electrical, structural and functional). The abstraction levels and design viewpoints are expressed using four abstraction views (called also domains). Each view is represented by a

distinct model (i.e., platform, platform-specific, platform-independent and requirement models). Each model represents the RF system at a given level of detail (abstraction level) and from a given design viewpoint (which is a design perspective expressing a set of design considerations).

In the following step, we focused on the mechanisms allowing the transition between the different design views. At this regard, we introduced the concept of model-to-model transformation (i.e., inspired from MDE) to convert a source model into another one. A model-to-model transformation can be either cross- or intra-view depending on whether the abstraction level is changing in the destination model or not. In addition, we defined particular types of intra-view transformations (e.g., model bridge, granularity refinement transformation) to enable the change of the design view without changing the design viewpoint neither the abstraction level. The advantage of such transformations is their ability to globally enhancing the design space exploration process without altering the abstraction level. Furthermore, we proposed a decision making process which takes part of view model artifacts in order to automate as much as possible the selection of the « best » design solution at each abstraction level. Finally, we presented the SysML profile for RF devices which is a set of specialized SysML constructs dedicated to RF design. These constructs are meant to help the designer using SysML for functional description of RF devices and systems.

In the fifth and last chapter, we attempted to demonstrate the applicability of the theoretical concepts presented in the third and fourth chapters. Due to the absence of formal ways for the validation of the proposed design framework, we selected four design case studies covering both linear and nonlinear devices. We started with recalling the main design stages of the proposed framework and sketching a step-by-step design flowchart in order to ease the understanding of the design process. Then, we presented the design case studies of two linear (i.e., frequency selection and attenuation) and nonlinear (i.e., frequency translation) devices. In each design case study, we focused particularly on the key concepts of the framework such as functional description, coherence verification, granularity refinement and technology mapping. The role of the Q-matrix was also underlined.

At the end of this thesis, it seems important to underline the following observations:

- The methodology we used to conduct this research work brings proven concepts and techniques used in other engineering disciplines (e.g., software development) to the RF domain. Unlike the limited proposals found in literature about the abstraction of RF devices and already discussed in the fourth chapter, the construction of the proposed RF abstraction strategy is original because it mixed in part, concepts from software domain with others already adopted in digital and analog design. The subsequent challenge is to show that this mix does not hinder the practical usability and the usefulness of the overall design framework;
- In practice, the main limitation that faced the proposed framework remains the lack of appropriate design tools;
- In addition to the case studies presented in this thesis, we tested the proposed framework in other design scenarios (e.g., power division and combination device). The results are encouraging and meet our expectations. However, we cannot definitely establish that this methodology is fully functional in all design scenarios since our validation approach was not formal.

## **Contributions**

The conducted research work and this thesis contributed in various ways to the academic effort looking at making RF design faster and easier:

- We made a recent critical review of the modern RF design practice and a comparative study with digital, analog/mixed-signal domains. Thus, we could assess the weaknesses and shortcomings of RF domain by putting into perspective the design practice in all these design domains. Such up-to-date review might complete the few outdated and limited literature reviews dealing with this topic;
- The absence of comprehensive literature review of hardware abstraction not only in RF domain but also in other engineering domains was one of the major difficulties that we faced in this research work. We elaborated a documented review of abstraction strategies in various domains. This effort might be useful for any future studies in this topic;

- We proposed a new design scheme that reproduces the main design stages found in modern RF design practice but raises also the design abstraction levels higher than what exists in both industry and academia. This proposal might be a first and modest contribution to the next-generation RF design environments;
- We built an abstraction strategy for RF hardware which includes a clear subdivision between abstraction levels, design perspectives and representations as well as the appropriate mechanisms to manage complexity (i.e., detail level) and moving from a source to a destination model without compromising the design coherence. We also augmented this strategy with a modeling platform allowing to express each aspect and a decision making process to enhance the automation of all the design steps;
- The proposed design framework allowed to redefine RF devices and systems with respect to their functionality, inputs and outputs. This definition allowed to categorize components in a new fashion. The immediate advantage of this new classification is the ability to cover almost all existing devices and systems, even those in the border between RF and other domains;
- We introduced the Q-matrix as a multi-dimensional structure which captures electrical data from various sources throughout different dimensions (i.e., power, frequency, temperature and aging). The Q-matrix might be a serious candidate to replace famous data standards such as Touchstone, citifile and P2D files;
- From practical standpoint, the proposed design framework is tool- and environment-independent. For instance, it is possible to use any structured modeling language for functional description. However, the efficiency of modeling activity depends on that choice since modeling languages (either general-purpose or domain-specific) do not define necessarily all the constructs required to capture all the aspects of RF devices. In our approach, we chose to use open and widespread standard languages such as XML and SysML in the aim of not only enhancing the interoperability with other environments supporting the same languages but also to allow the integration of the framework within a super-system design environment (e.g., in aerospace systems design, radio-communication devices are considered as small parts of a larger system). Hence, the proposed design

framework may be useful to bridge the gap between RF designers and their counterparts from other disciplines;

- The proposed framework opened the door to the automation of useful design features. For instance, the technology mapping process allows the automated selection of devices considering non electrical parameters (e.g., physical dimensions) to evaluate non electrical requirements (e.g.; form factor). The availability of detailed technology information enables the assessment of various interesting aspects (e.g., EMC, form factor, etc.) of the design in addition to its traditional electrical performance.

### **Future Work**

This thesis presented a preliminary work in the purpose of building a new flexible design methodology for RF and microwave systems. We particularly highlighted the proposed design framework's foundations from both theoretical and practical standpoints. However, there are still numerous enhancements that can take place. There are also several concepts that require in-depth study in future works. We enumerate hereafter a non-exhaustive list of some outstanding research and development topics that would be accomplished in order to bring the proposed framework to real-world design practice:

- Extended validation work: As previously mentioned, the case studies we carried out are probably not sufficient to prove the completeness and the suitability of the framework to all design scenarios. Thus, there is still a need to evaluate the framework mechanisms in more complex and varied design cases. The framework gains more maturity with more validation effort because each of the case studies we carried out has unveiled some weaknesses in the framework and helped us to gradually fix them. Among the case studies that would be developed, we count multi-level analysis of complete transceiver front-ends;
- Q-matrix mathematical formalism enhancement: As illustrated in the third chapter, the Q-matrix is a super dataset that is intended to be a compact and coherent structure to hold the design data during and after design activity. It is based on a broad mathematical definition that extended for instance, the definition of ports to DC domain. Currently, this definition causes some holes in the multi-dimensional matrix (e.g., existing design tools do not compute the signal ratio between some mixed ports such as RF and DC). The Q-matrix

- mathematical formalism should evolve in such a way that it becomes easier to define such ratios and fill out the existing holes. The Q-matrix requires also to be interfaced to existing measurement instruments;
- Elaboration of an experimental design environment: Among the major challenges that faced the elaboration of the design framework is the lack of suitable tools. We estimate that the proposed framework cannot be fully effective unless a suitable set of tools is implemented to give thorough guidelines to designers and support the development effort of the entire framework. In fact, the framework requires tools for high-level modeling, coherence rules capture and analysis, model-to-model transformation elaboration and execution, technology mapping, decision making, data import, export and conversion, etc. In addition, a new technology library should be architected to support the new features such multi-criteria component search and mapping. The Q-matrix requires also a set of tools for data interpretation and capture from concurrent design sources. All these tools should be combined in a modern, interactive and easy-to-use integrated design environment;
  - Investigation of domain-specific modeling: We elaborated the “*SysML profile for RF devices*” to introduce guidelines for high-level modeling of RF systems and devices using SysML. The latter is a generic modeling language that was conceived for the modeling of engineering systems. It was not exclusively dedicated to electrical systems. It would be interesting to build up a new domain-specific modeling language that is fully dedicated to RF and microwave systems. Such language should be lightweight, straightforward and may be based on some salient modeling constructs already defined in SysML and other existing languages;
  - Support of non-electrical design features: We showed in the fifth chapter that the new framework not only allows the evaluation of electrical performance of the candidate design solutions but also other non-electrical features (e.g., form factor, EMC, etc.). A future study may investigate which tools and which non-electrical assessments could be included in the framework. For example, is it possible to evaluate the carbon footprint of the system under design? Naturally, this requires the development of a specific tool that calculates the circuit carbon footprint based on its electrical performance.



## **APPENDIX I**

### **HISTORY AND ADVANTAGES OF MODERN ELECTRONIC DESIGN AUTOMATION TOOLS**

#### **I.1 Introduction**

EDA tools have been evolving during decades. Today, these tools become essential for almost all designers. In this appendix, we briefly review EDA tools history and summarize their salient advantages in modern radio design practice.

#### **I.2 EDA History**

Historically, the EDA era started in the early 1960s by the emergence of the Design Automation Conference in 1964. It aimed to unite industry and academia efforts for the creation of new tools to speed up the design process (Wang, Chang et Cheng, 2009). EDA history can be subdivided to three main eras:

1. The first generation (1964 – 1978): Until the mid-1970s, electronic design was handcrafted. However, during this decade significant research results were published. Advances covered various topics including circuit simulation, logic simulation and testing, wire routing, etc. The first EDA companies appeared at the late 1960s and early 1970s (e.g., Applicon in 1969, Calma in 1970 and Computervision in 1972) (Sangiovanni-Vincentelli, 2003; Wang, Chang et Cheng, 2009). The Electronics Research Laboratory of the University of California, Berkeley released in 1973 an analog electronic circuit simulator called SPICE (Simulation Program with Integrated Circuit Emphasis). The first release namely SPICE1, was derived from a less-famous simulator called CANCER (Computer Analysis of Nonlinear Circuits, Excluding Radiation). SPICE1 included modified nodal analysis technique and inspired several commercial circuit simulators (e.g., PSPICE of Cadence Design Systems);
2. The second generation (1979 – 1993): During this period, the EDA domain has known a remarkable growth. Prominent research results covered verification and testing, layout

manipulation and artwork edition, logic synthesis, high-level design and hardware description languages (HDL), etc. On the business side, many EDA companies were founded (e.g., Daisy, Mentor and Valid in 1980-1981, Cadence in 1988) (Chen, 2009b; Sangiovanni-Vincentelli, 2003). The first public foundry, namely MOSIS (Metal Oxide Semiconductor Implementation Service) was created in 1981. It processed since then more than 50000 chip designs for both industry and academia (MOSIS, 2010). The hardware description languages VHDL (Very High-Speed Integrated Circuits Hardware Description Language) and Verilog were respectively standardized<sup>94</sup> in 1987 and 1995. The most famous EDA tools emerged during the 1980s. For instance, Agilent ADS, Cadence and Ansoft HFSS were introduced in 1985, 1988 and 1989 respectively;

3. The third generation (since 1993): From 1993, the EDA tools are being progressively mature (Sangiovanni-Vincentelli, 2003). Tools became more efficient and ergonomic. The design flows started to be collaborative and modular. By opposition to the first- and second-generation tools which were respectively running on mainframes and dedicated workstations, the third-generation EDA tools are mostly intended for individual desktop computers. Technically, behavioral-level techniques were enhanced and system-level design techniques were introduced. For instance, System-C emerged and C++ became attractive for system-level designers. The mixed-signal domain has seen Verilog-AMS and VHDL-AMS standardized in 1993 and 2005 respectively.

### **I.3 Key EDA Advantages**

EDA tools and methodologies have been of prime importance for designers since the late 1960s. Nowadays, the circuit design and manufacturing industry (either digital, analog, RF/microwave or mixed-signal) takes advantage of the various EDA benefits. Depending on the design domain, these benefits include:

---

<sup>94</sup> VHDL and Verilog were introduced for the first time in 1981 and 1983 respectively.

- Completeness: EDA tools cover almost all design stages including specification, modeling, computer-aided design (TCAD), performance simulation, layout, fabrication, integration, packaging, test and validation (Lin et Tong, 2011);
- Automated synthesis: High-level modeling in some domains (e.g., digital) allow automated synthesis and verification of large-scale designs with growing complexity and mix of technologies;
- Availability of libraries: Most design tools include technology libraries and device models that are regularly updated and enhanced allowing designers to keep up with the progress of fabrication processes;
- Availability of multiple simulation techniques: Some EDA tools include multi-aspect simulation features. For example, modern radiofrequency design environments (such as Keysight Advanced Design Systems, ADS and AWR<sup>95</sup> Microwave Office) include electromagnetic solvers, various time- and frequency-domain simulators for small- and large-signal analyses, intermodulation and nonlinearities study as well as noise evaluation. This set of tools provides the designer with valuable capabilities to easily and rapidly come up with a design meeting the initial requirements;
- Advances in system-level design: EDA tools supporting system-level design provide good abstraction levels allowing the masking of technology details and physical complexity. This is useful for designers who can model and analyze several architectures and potential design solutions and rapidly figure out if they are good candidates for a final implementation;
- Enhanced co-simulation: Whether the design platform is the same or different, some EDA tools can actively collaborate on real-time basis. So, a tool can be used to capture the circuit schematic while other tools for example, co-simulate its EM behavior based on its mechanical structure. This enables the leveraging of more circuit aspects and rapidly find out reasonable design trade-offs. For instance, ADS can be combined with the Mathworks

---

<sup>95</sup> AWR stands for Applied Wave Research. AWR is an American EDA tools editor and vendor. It was acquired by National Instruments (NI) in 2011. Nevertheless, most of its EDA products continue to be marketed as AWR products.

Matlab in the linearization of RF amplifiers. While ADS works out the small- and large-signal responses of the amplifier, Matlab is in charge of signal processing related to the linearization scheme (Agilent Technologies, 2008);

- Industry de facto standards: There are various industrial standards and proprietary file formats (which became de facto standards) enabling data exchange between the most known EDA tools. For example, Touchstone and P2D files are respectively used to exchange the small- and large-signal characterization data of circuits and devices. GDSII (Graphic Database System II) and Gerber formats are commonly used to export the circuit physical structure (i.e., artwork);
- Enhanced design verification: EDA tools supporting Electronic System-Level (ESL) modeling include packages for design and test process / verification automation. Accordingly, automated synthesis enable design where a low-abstraction level representation is generated from higher-level models. The verification and test processes aiming to validate the correctness of the design against the specifications can be automated as well (Wang, Chang et Cheng, 2009).

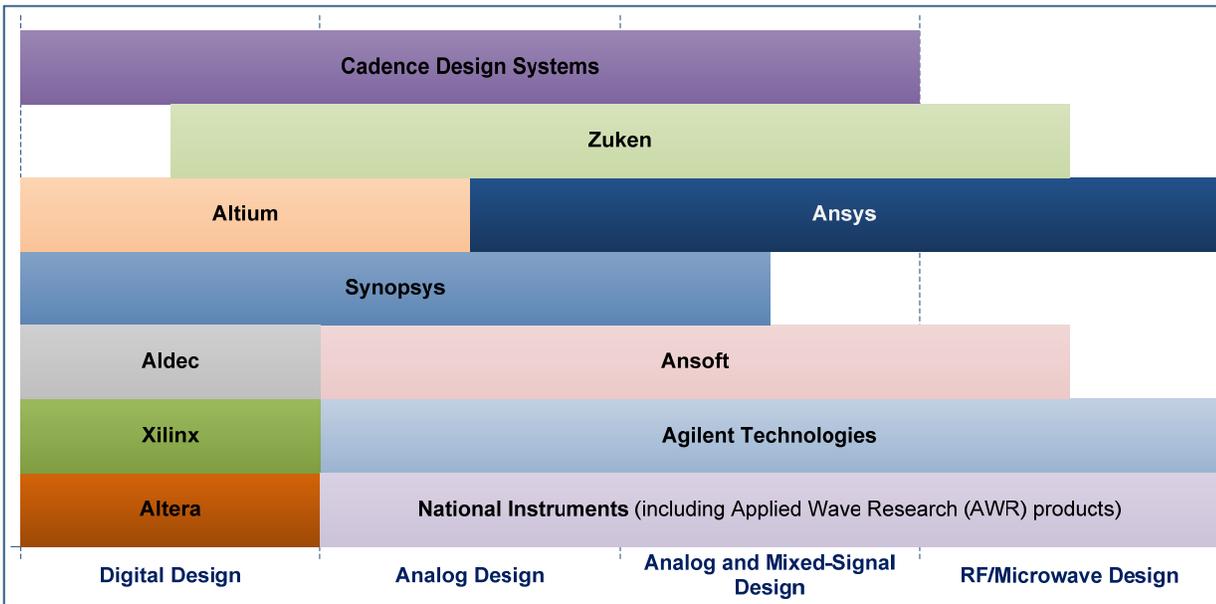


Figure-A I- 1 An overview of key vendors of EDA tools

All these benefits make EDA an essential and necessary investment, required to improve designers' productivity, reduce non-recurrent engineering efforts (especially in terms of time and cost) and manage large design projects with limited human and technical resources.

### **I.3 Common EDA Tool Vendors**

Figure-A I-1 depicts the common EDA tool vendors for digital, analog/mixed-signal and RF/microwave design.



## APPENDIX II

### OVERVIEW OF SYSTEMS MODELING LANGUAGE

#### II.1 Introduction

With the wide adoption of the Unified Modeling Language (UML) as a standard modeling language for software engineering, an increasing interest has emerged for the adoption of a UML-based general-purpose modeling language dedicated to systems engineering. In 2001, the International Council on Systems Engineering (INCOSE) formed with the OMG a special workgroup, namely the Systems Engineering Domains Special Interest Group (SE DSIG). The aim of SE DSIG was drafting a proposal for a new UML profile that becomes “*a standard modeling language for systems engineering to analyze, specify, design, and verify complex systems*” (OMG, 2013b). The new modeling language “*is intended to enhance systems quality, improve the ability to exchange systems engineering information amongst tools, and help bridge the semantic gap between systems, software, and other engineering disciplines*” (OMG, 2013b). The SE DSIG has rapidly seen the involvement of members from industry (e.g., aerospace and aeronautics, defense, communications, etc.), modeling and design tool vendors, and academia who were interested in the definition of the new language. In 2006, the new UML profile, namely Systems Modeling Language (SysML), was officially adopted by OMG. Then, its version 1.0 was released in 2007. As of 2012, the OMG has released version 1.3.

#### II.2 SysML Paradigms

SysML, defined as an UML profile, is a graphical general-purpose modeling language. It is not a methodology, neither a process nor a tool. To support system specification, analysis, design, verification and validation, it was expected to alleviate the software-centric properties of UML and provide strong semantics to express multidisciplinary engineering artefacts. At this regard, it provided several improvements to UML paradigms:

- Strong semantics and engineering-oriented notations: SysML introduces more flexible and expressive semantics than UML as well as new diagrams to capture requirements and

express system's parametrics. This does not only allow modeling a wide range of hybrid systems (including hardware, software, data, facilities, etc.) but also can be used for performance analysis and simulation;

- Engineering-oriented vocabulary: As a subset of UML, SysML is a smaller language that is easier to learn and use. It redefines most UML constructs to adapt to systems engineering. For instance, it introduces the notion of *blocks* instead of *classes*. This kind of vocabulary, more generic and thus more suitable for systems engineering, remains accessible to software designers;
- Enhanced support of requirements and allocations: SysML extends the UML inherited capability of allocations through the support of new allocation formats (e.g., tabular, graphical, tree view, etc.). This does not only empower the capability of requirement, functional and structural allocations but also facilitates the automation of verification and validation processes;
- Enhanced support of domain-specific concerns: Through the adoption of the separation of concerns concept, SysML supports models, views and viewpoints. This capability enables the designers to address specific concerns and focus on particular system aspects that are important from their viewpoint;
- Standard models interchange: In addition to separation of concerns and hierarchical modeling support, SysML allows standardized data and model interchange via its compliance with XMI and AP233 standards.

SysML was developed to enable model-based systems engineering. It was intended to provide designers from different engineering domains with a modeling capability to create static and dynamic models of engineering systems. It covers four main functional areas related to systems engineering:

1. Requirements: allows not only to capture system requirements (in a contractual manner) for different viewpoints but also to use them for verification and validation (V&V) purposes, particularly through automated traceability and allocation mechanisms;
2. Structure: provides thorough constructs for the description of internal and external architecture, parts and blocks of an engineering system;

3. Behavior: allows the description of what an engineering system does and how it interacts internally and externally regardless of how this is fulfilled;
4. Parametrics: captures the physical laws, dimensions, units, mathematical formulas and constraints governing the structure or/and the behavior of an engineering system.

Furthermore, SysML provides engineers with additional capabilities for the analysis, verification and validation of engineering systems:

- Visualization and animation: SysML allows the capture of specifications and requirements in a single language which enables better communication between designers. Additionally, it helps for the production of executable specifications as well as the derivation of domain-specific animations;
- Performance simulation: The rich SysML infrastructure (especially parametric, requirements and behavioral diagrams) allows running performance analysis given suitable tools. This feature makes immediate use of models rather than developing a physical implementation first;
- Verification and validation: Through requirements traceability, the design links the system parts and specifications which allows to verify if the requirements are satisfied. However, requirements allocations allow the designer to check if each system part fulfills its mission as stated in specifications.

As shown in Figure-A II-1, SysML (including its notation, semantics, domain-specific extensions and tools, etc.) stands in the heart of an end-to-end model-based systems engineering (MBSE) process. Additionally, SysML is amenable for further extension for domain-specific languages using the mechanism of profiling.

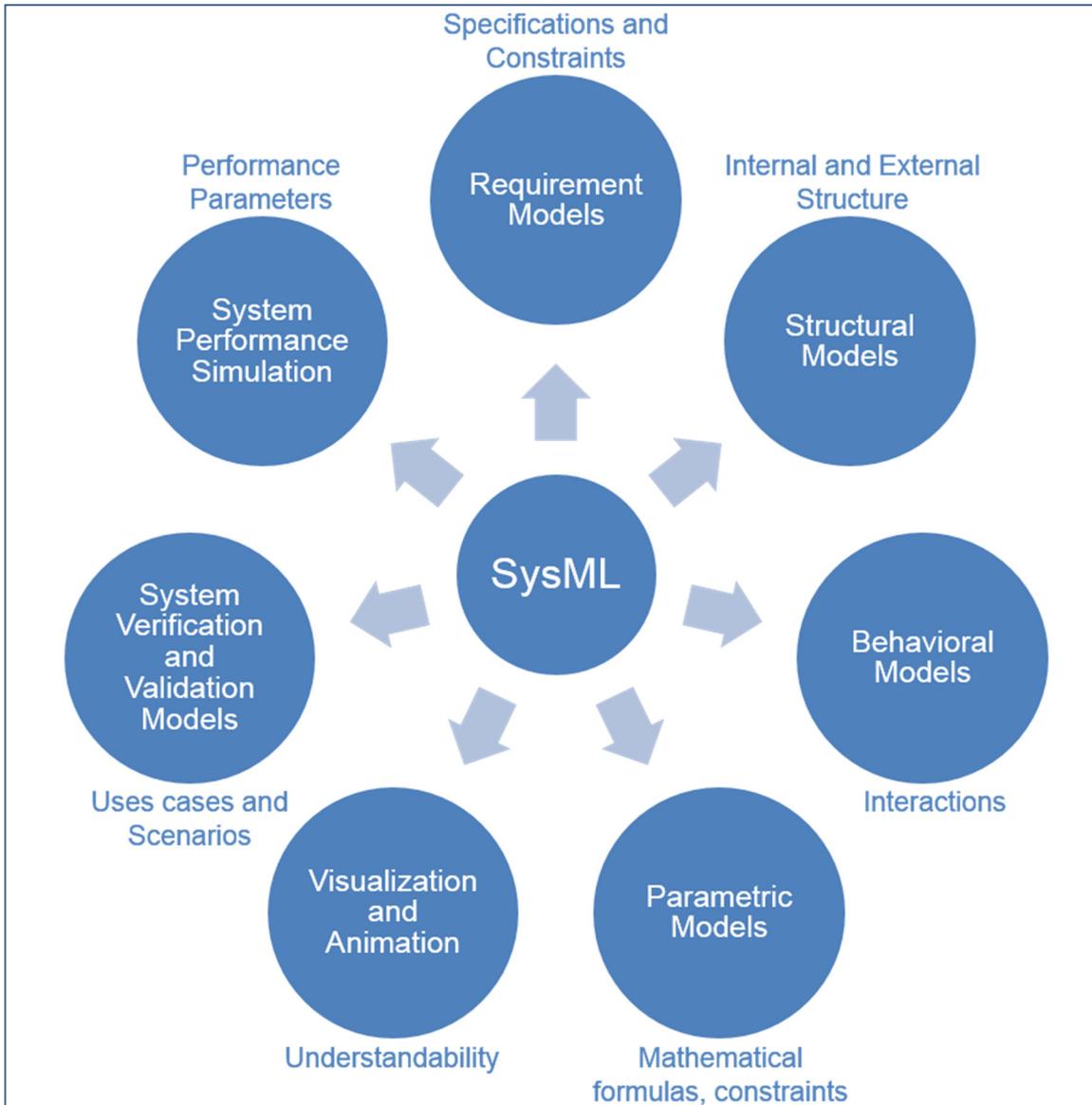


Figure-A II-1 SysML provides engineers with an end-to-end spectrum of modeling and automation capabilities

### II.3 Overview of SysML Diagrams

SysML specifies nine modeling diagrams and a set of constructs to cover the four previously mentioned functional areas (i.e., requirements, structure, behavior and parametrics) pertaining to systems engineering. As shown in Figure-A II-2, SysML defines two new diagrams (i.e., requirements and parametric) while it redefines three existing UML diagrams (i.e., block definition, internal block and activity). Furthermore, it reuses four other UML diagrams (i.e.,

package, use case, sequence and state machine). All these diagrams are structured in the hierarchy depicted in Figure-A II-3. Therefore, SysML dedicates four diagrams for the description of a system's structure (i.e., block definition diagram, internal block diagram, package diagram and parametric diagram). The parametric diagram is closely tied to the internal block diagram in a sense that it depicts the mathematical relationships and/or constraints related to the latter. That is why it is considered by OMG as a structure diagram (OMG, 2014). The behavior diagrams include the use case diagram, sequence diagram, state machine diagram and activity diagram. The requirements are captured using the requirement diagram.

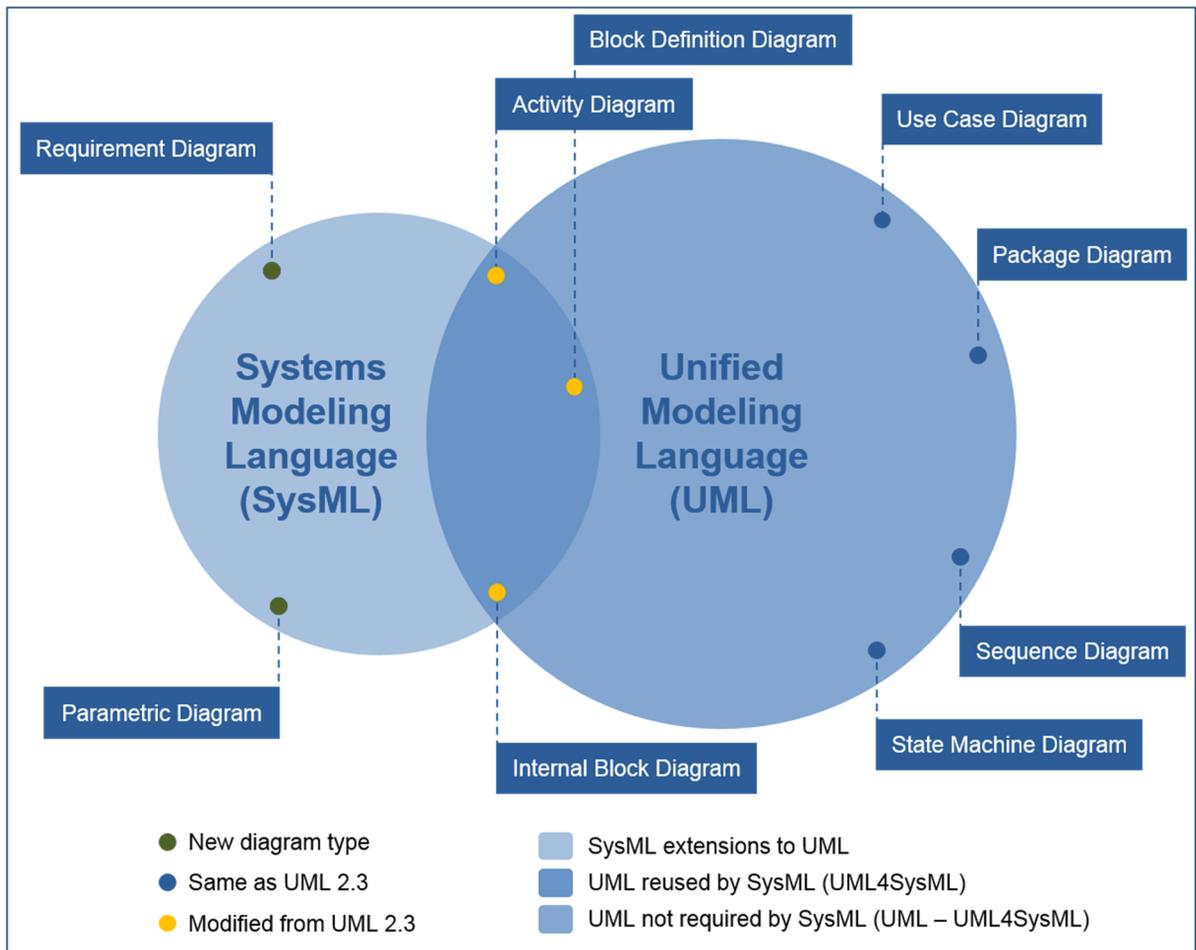


Figure-A II-2 SysML redefines some UML diagrams and extends the software-centric modeling language with new ones  
Adapted from OMG (2014)

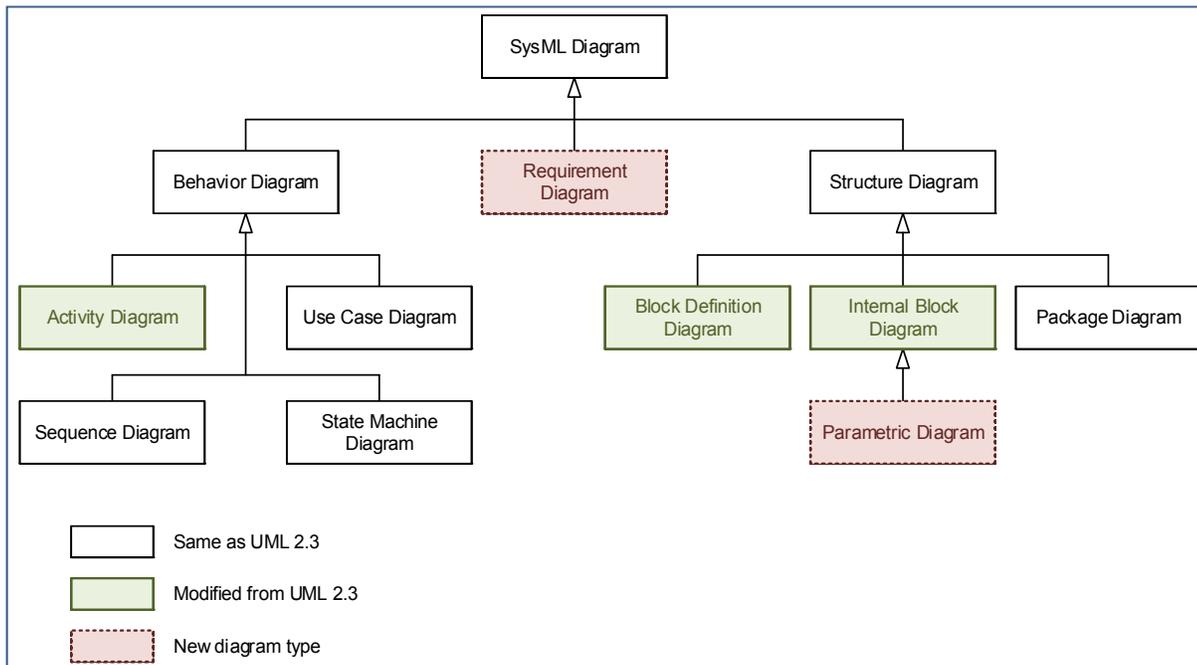


Figure-A II-3 SysML defines a hierarchy of modeling diagrams that covers the four functional areas related to system engineering (i.e., requirements, structure, behavior and parametrics)  
 Taken from OMG (2014)

### II.3.1 Structure Diagrams

SysML structure diagrams are dedicated for the description of internal and external structure of engineering systems as well as depiction of the various constraints to which these systems are submitted. The version 1.3 of SysML considers four structure diagrams:

- Block definition diagram (bdd): it describes the system’s components and hierarchy as well as the relationships between them (e.g., associations, generalizations, and dependencies). Each component is described using a construct called “*Block*” which captures the component’s properties and features. The relationships between the components are captured using a system hierarchy or a system classification tree. The bdd is considered as the richest diagram in terms of syntax (OMG, 2013a);
- Internal block diagram (ibd): it captures the internal structure of a block in terms of properties and connectors between properties. A block can include properties to specify its values, parts, and references to other blocks;

- Package Diagram (pkg): it is a collection of diagram elements. The package diagram is used to organize the system models by partitioning the model elements into (sub-)packages and views and establishing dependencies between them (OMG, 2013a).

### **II.3.2 Behavior Diagrams**

In SysML, behavior diagrams are used for the description of dynamic and behavioral artefacts of an engineering system including the interactions between its components themselves or with their environment. The version 1.3 of SysML considers four behavior diagrams:

- Activity diagram (act): it depicts the control and inputs/outputs (e.g., data, energy, material, etc.) flow among actions and operations (i.e., activities) (OMG, 2013a);
- Sequence diagram (sd): it describes the flow of messages and interactions between collaborating entities (including system parts or blocks and external actors);
- State machine diagram (stm): it describes the state transitions and actions that a system or its blocks/parts should carry out in response to given events;
- Use case diagram (uc): it provides a high-level description of how the system (and its blocks/parts) is being used by its environment actors to accomplish functionality. It is also used to model system usage and context requirements (OMG, 2013a). In practice, it represents the highest-level of abstraction in SysML (Holt et Perry, 2008).

### **II.3.3 Requirement and Parametric Diagrams**

SysML has introduced two new types of diagrams (i.e., parametric and requirement diagrams) to provide designers with mechanisms not only to express domain-specific artefacts but also to facilitate analysis of engineering models.

- Parametric diagram (par): it is used for the definition of constraints and rules associated to the properties of the system blocks/parts. It is also used to integrate both structure and behavior models with engineering tools to carry out various system analyses and simulations (e.g., performance, reliability, etc.) (OMG, 2013a) (The reader may refer to (Peak et al., 2007a; 2007b) to learn more about how parametric diagram can be used in real-world complex engineering systems);

- Requirement diagram (req): it provides modeling constructs to capture text-based requirements into graphical, tabular or tree structure format and associate them with the system's structural and/or behavioral model elements using predefined relationships (Roques, 2015).

Figure-A II-4 illustrates the nine diagrams of SysML. For an in-depth study of SysML diagrams and constructs as well as their definition and usage, the reader may refer to (Delligatti, 2013; Friedenthal, Moore et Steiner, 2008; Holt et Perry, 2008; OMG, 2013a; Weilkiens, 2008).

### II.3.4 Views and Viewpoints

SysML has extended the concepts of “*view*” and “*viewpoint*” from UML to support the paradigm of concerns separation.

- View: it is a representation of a whole system (or subsystem) from the perspective of a set of concerns (The Open Group, 2006);
- Viewpoint: it defines the perspective from which a view is taken. It is a specification of the conventions and rules for constructing and using a view for the purpose of addressing a set of stakeholder concerns (OMG, 2013a). For example, the selection of the information to appear in a view is a viewpoint.

The concepts of “*view*” and “*viewpoint*” are interrelated. A view is what a stakeholder sees. A viewpoint is the direction in which he is looking. Viewpoints are generic but views are specific. Both concepts are important because they help partitioning the system models.

### II.4 Basic Language Constructs

SysML provides a set of constructs for the modeling of engineering systems. These constructs are used within SysML diagrams in order to describe various system aspects such as structure, behavior, requirements, allocations and constraints. For illustration, we briefly present in the following structural, behavioral and some crosscutting constructs.

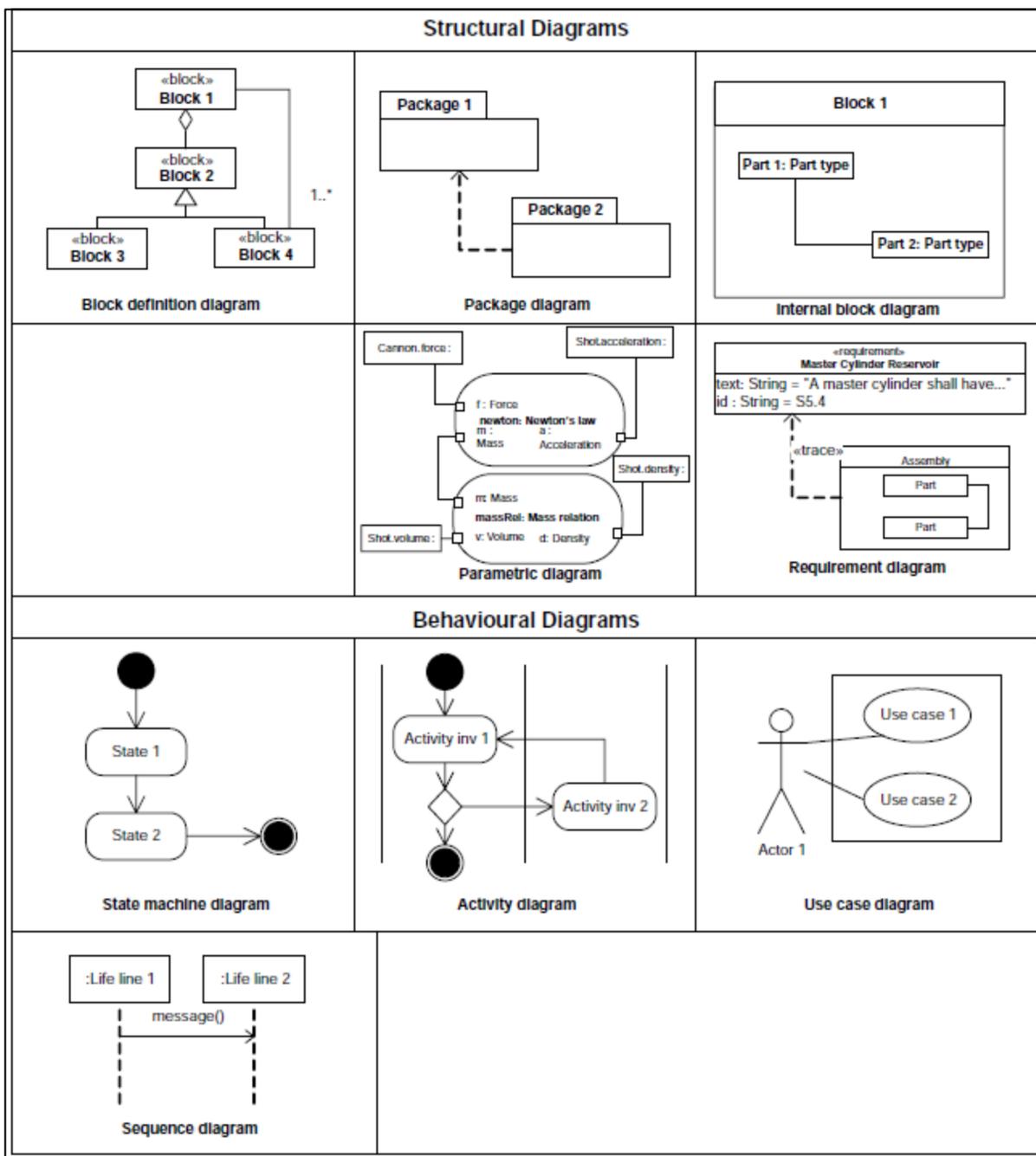


Figure-A II-4 Illustration of structural and behavioral SysML diagrams  
Taken from Holt et Perry (2008)

### II.4.1 Structural Constructs

This type of constructs defines the static and structural elements typically used in structural diagrams (i.e., package, block definition, internal block and parametric diagrams).

- a. Model elements: are general-purpose constructs to express various types of dependencies (e.g., import, refine, access, etc.), constraints and comments;
- b. Blocks: are the basic structure entities used in SysML. Blocks can be used for either the logical or the physical decomposition of a system, and can represent software, hardware, human or any other system element. Each block defines a collection of both structural and behavioral features to describe the system properties (e.g., properties, operations, etc.);
- c. Ports and flows: Ports are interfacing points that an external block uses to connect with owning block. SysML defines two main types of ports: proxy and full ports. Flows specify the kinds of items that a block might exchange with its environment;
- d. Constraint blocks: is a particular type of blocks that was introduced to allow the integration of engineering analysis models. It is used to specify constraints (e.g., mathematical formulas) to which the block properties should conform. Constraint blocks are intended to be used in multiple contexts.

### II.4.2 Behavioral Constructs

This type of constructs defines the dynamic behavioral constructs that are used mainly within behavioral diagrams (i.e., activity, sequence, state machine, and use case diagrams):

- a. Activities: are behavior units commonly attached to a process (can also be defined as execution units that take time and can be interrupted);
- b. Interactions: define constructs for describing message-based interactions between entities;
- c. State machines: describe the constructs used to specify state-based behavior (e.g., system states, transitions between states). A state characterizes the status of a system before making a transition. A transition is a sequence of actions to be carried out when a condition is satisfied or when an event takes place;
- d. Use cases: describe at high level how the system (i.e., subject) is used by its actors (i.e., environment) to achieve a goal or accomplish a mission.

### II.4.3 Crosscutting Constructs

In SysML, these constructs apply to both structure and behavior.

- a. Allocations: define basic allocation relationships (i.e., mappings between elements) that can be used to allocate a set of model elements to others, such as allocating logical resources to physical components. In practice, this ensures that all the blocks/parts within a system are properly integrated;
- b. Requirements: specifies constructs for the description of system requirements and their relationships. A requirement is specified by its unique identifier, text content and a verification status when applicable. Composite requirements are established in a hierarchy of requirements. Various relationships can be defined between two requirements (e.g., “derive”) or a requirement and a model element (e.g., “refine”, “satisfy”, “verify”);
- c. Profiles and model libraries: define the mechanisms and constructs used either to extend SysML using profiles or to develop model libraries.

Table-A II-1 The use of SysML in sample engineering problems

Engineering System	Reference
Hybrid Gas/Electric Powered Sport Utility Vehicle	Annex C in (OMG, 2013a)
Rain Sensing Wiper System	(Balmelli, 2007)
UMTS Terrestrial Radio Access/Frequency Division Duplex (UTRA/FDD) Transceiver	(Lafi et al., 2008)
Air Vehicle Pilot	(Graves et al., 2009)
Telescope System	(Karban et al., 2008)
Wireless Sensor Networks	(Belloir et al., 2008)

### II.5 Sample Problems

Due to the lack of space in this section, which prevents us from presenting a detailed sample problem, we refer the reader to the references given in Table-A II-1. These references describe thoroughly how SysML is used to model the various aspects pertaining to a real-world complex engineering system from different fields (e.g., automotive, aerospace, communication, etc.).



## APPENDIX III

### SUMMARY OF EQUATIONS AND FORMULAS USED IN CASE STUDIES

#### III.1 Case Study 1: Radiofrequency Filter

##### III.1.1 General Definitions

- General linear analog filter transfer function:

$$H(s)|_{s=\sigma+j\omega} = \frac{E(s)}{P(s)} = \frac{\sum_{i=0}^m a_i s^i}{\sum_{j=0}^n b_j s^j} \quad (\text{A III-1})$$

where  $a_i$  and  $b_j$  are real coefficients.

- Analog filter phase shift:

$$\phi(\omega) = \text{arg}(H(j\omega)) \quad (\text{A III-2})$$

where  $H$  is the filter's transfer function and  $\text{arg}$  is the complex argument function.

- Analog filter phase delay:

$$\tau_\phi(\omega) = -\frac{\phi(\omega)}{\omega} \quad (\text{A III-3})$$

where  $\phi$  is the filter's phase shift and  $\omega$  is the angular frequency.

- Analog filter group delay:

$$\tau_g(\omega) = -\frac{d\phi(\omega)}{d\omega} \quad (\text{A III-4})$$

where  $\phi$  is the filter's phase shift and  $\omega$  is the angular frequency.

### III.1.2 Examples of Filter Approximations

#### III.1.2.1 Butterworth Filter Approximation

- Butterworth model transfer function:

$$G_T = |H(j\omega)|^2 = \frac{H_0}{1 + \left(\frac{\omega}{\omega_s}\right)^{2N}} \quad (\text{A III-5})$$

where  $\omega_s$  is the stopband edge angular frequency and  $N$  is the filter order.

- Butterworth filter order:

$$N = \frac{\log\left(\frac{10^{\frac{A_p}{10}} - 1}{10^{\frac{A_s}{10}} - 1}\right)}{2\log\left(\frac{\omega_s}{\omega_c}\right)} \quad (\text{A III-6})$$

where  $A_p$  is the maximum attenuation (in dB) in the passband ( $0 \leq \omega \leq \omega_c$ ),  $A_s$  is the minimum attenuation (in dB) in the stopband ( $\omega_s \leq \omega \leq +\infty$ ),  $\omega_c$  is the passband edge angular frequency and  $\omega_s$  is the stopband edge angular frequency.

- Butterworth lowpass prototype normalized elements:

$$\begin{cases} g_0 = g_{N+1} = 1 \\ g_k = 2 \sin\left(\frac{(2k-1)\pi}{2N}\right), k = 1, 2, \dots, N \end{cases} \quad (\text{A III-7})$$

where  $N$  is the filter order.

#### III.1.2.2 Chebyshev Type I Filter Approximation

- Chebyshev Type I model transfer function:

$$G_T = |H(j\omega)|^2 = \frac{H_0}{1 + \varepsilon^2 T_n^2\left(\frac{\omega}{\omega_s}\right)} \quad (\text{A III-8})$$

where  $\omega_s$  is the stopband edge angular frequency,  $\varepsilon$  is a measure of the passband ripple and  $T_n(x)$  is the Chebyshev function defined as follows:

$$\begin{cases} T_n(x) = \cos[n \cdot \cos^{-1}(x)], & 0 \leq x \leq 1 \\ T_n(x) = \cosh[n \cdot \operatorname{arccosh}(x)], & x > 1 \end{cases} \quad (\text{A III-9})$$

- Chebyshev Type I filter order:

$$N = \frac{\operatorname{arccosh}\left(\frac{1}{\varepsilon} \left(10^{\frac{A_p}{10}} - 1\right)^{-1/2}\right)}{\operatorname{arccosh}\left(\frac{\omega_s}{\omega_c}\right)} \quad (\text{A III-10})$$

where  $A_p$  is the maximum attenuation (in dB) in the passband ( $0 \leq \omega \leq \omega_c$ ),  $\varepsilon$  is a measure of the passband ripple (in dB),  $\omega_c$  is the passband edge angular frequency and  $\omega_s$  is the stopband edge angular frequency.

- Chebyshev Type I lowpass prototype normalized elements:

$$\begin{aligned} g_0 &= 1 \\ g_{N+1} &= \begin{cases} 1, & N \text{ odd} \\ \tanh^2\left(\frac{\beta}{4}\right), & N \text{ even} \end{cases} \\ g_1 &= 2 \frac{a_1}{\gamma} \\ g_k &= \frac{4a_{k-1}a_k}{b_{k-1}g_{k-1}}, \quad k = 2, 3, \dots, N \\ a_k &= \sin\left(\frac{(2k-1)\pi}{2N}\right), \quad k = 1, 2, \dots, N \\ b_k &= \gamma^2 + \sin^2\left(\frac{k\pi}{N}\right), \quad k = 1, 2, \dots, N \\ \beta &= \ln\left[\coth\left(\frac{A_m}{17.32}\right)\right] \\ A_m &= 10 \log(\varepsilon^2 + 1) \\ \gamma &= \sinh\left(\frac{\beta}{2N}\right) \end{aligned} \quad (\text{A III-11})$$

where  $N$  is the filter order.

### III.1.3 Resonators selection

Given that  $N$  is the filter order, then:

- if is  $N$  even:

$$\begin{cases} X_i = g_{2p}, & p \in [0, 1, \dots, \frac{N}{2}] \\ X_j = g_{2p+1}, & p \in [0, 1, \dots, \frac{N-2}{2}] \end{cases} \quad (\text{A III-12})$$

where  $X_i$  and  $X_j$  are respectively series and parallel resonators.

- if is  $N$  odd:

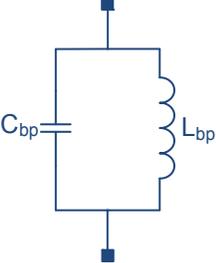
$$\begin{cases} X_i = g_{2p}, & p \in [0, 1, \dots, \frac{N-1}{2}] \\ X_j = g_{2p+1}, & p \in [0, 1, \dots, \frac{N-1}{2}] \end{cases} \quad (\text{A III-13})$$

where  $X_i$  and  $X_j$  are respectively series and parallel resonators.

Given  $\omega_0$  and  $BW$  the center frequency and the bandwidth of the bandpass filter and considering that  $\Delta = \frac{BW}{\omega_0}$ , the bandpass lumped elements can be derived from the lowpass prototype ones as follows :

Table-A III-1 Lowpass to bandpass lumped-element transformations  
Adapted from Pozar (2012, pp. 414)

Lowpass Prototype Element	Bandpass Elements	Transformation Formulas
		$\begin{cases} L_{bp} = \frac{L_{lp}}{\Delta\omega_0} \\ C_{bp} = \frac{\Delta}{\omega_0 L_{lp}} \end{cases}$

Lowpass Prototype Element	Bandpass Elements	Transformation Formulas
		$\begin{cases} L_{bp} = \frac{\Delta}{\omega_0 C_{lp}} \\ C_{bp} = \frac{C_{lp}}{\Delta \omega_0} \end{cases}$
		$R_{bp} = R_{lp}$

### III.1.4 Impedance Scaling

- Impedance scaling of lowpass prototype elements:

Given that  $N$  is the filter order, then:

$$\begin{cases} L = R_L L_p, & p \in [0, 1, \dots, N] \\ C = \frac{C_p}{R_L}, & p \in [0, 1, \dots, N] \\ R = R_L R_p \end{cases} \quad (\text{A III-14})$$

where  $C_p$  and  $L_p$  are respectively the lowpass prototype capacitance and inductance values,  $R_p$  is the LPP output impedance and  $R_L$  is the load impedance.

### III.1.5 Frequency Scaling

- Frequency scaling of lowpass prototype elements:

$$\begin{cases} L' = \frac{L}{\omega_c} \\ C' = \frac{C}{\omega_c} \\ R' = R \end{cases} \quad (\text{A III-15})$$

where  $\omega_c$  is the angular cutoff frequency.

### III.1.6 Frequency Transformation

- Lowpass to bandpass frequency transformation:

$$\omega' = \frac{\omega_0}{\Delta\omega} \left( \frac{\omega}{\omega_0} - \frac{\omega_0}{\omega} \right) \tag{A III-16}$$

where  $\omega_0$  is the angular bandpass filter center frequency and  $\Delta\omega$  is its angular bandwidth.

### III.2 Case Study 2: Transmission Line Lowpass Filter

#### III.2.1 Transmission Line Electrical Models

Table-A III-2 High- and low-impedance transmission line approximations

<p><i>Transmission line</i></p>	<p><i>T-equivalent circuit for a transmission line section having <math>\beta l \ll \frac{\pi}{2}</math></i></p>
	<p>if <math>\beta l &lt; \frac{\pi}{2}</math>:</p> $\frac{X}{2} = Z_0 \tan\left(\frac{\beta l}{2}\right)$ <p>if <math>\beta l &lt; \frac{\pi}{4}</math>:</p> $X \cong Z_0 \beta l$
<p><i>Equivalent circuit for small <math>\beta l</math> and large characteristic impedance <math>Z_0</math></i></p>	
	<p>if <math>\beta l &lt; \frac{\pi}{2}</math>:</p> $B = \frac{1}{Z_0} \sin(\beta l)$ <p>if <math>\beta l &lt; \frac{\pi}{4}</math>:</p> $B \cong 0$
<p><i>Equivalent circuit for small <math>\beta l</math> and small characteristic impedance <math>Z_0</math></i></p>	

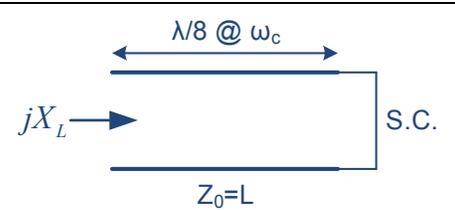
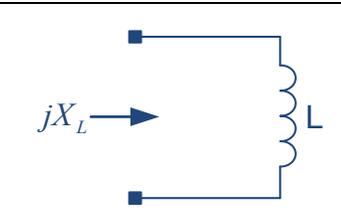
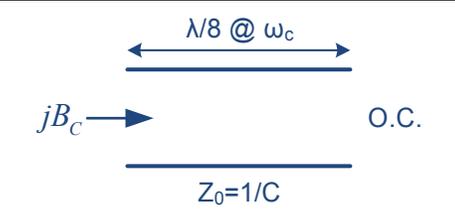
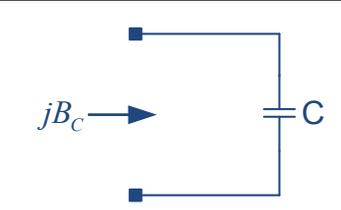
Table-A III-3 Equivalent LC components for high- and low-impedance transmission lines

$Z_0 = Z_{High}$	$Z_0 = Z_{Low}$
if $\beta l < \frac{\pi}{4}$ and $\frac{Z_{High}}{Z_{Low}} \gg 1$ at $\omega = \omega_c$ : $\beta l = \frac{LR_0}{Z_{High}}$	if $\beta l < \frac{\pi}{4}$ and $\frac{Z_{High}}{Z_{Low}} \gg 1$ at $\omega = \omega_c$ : $\beta l = \frac{CZ_{Low}}{R_0}$
Series inductor: $L = \frac{Z_{High}\beta l}{R_0}$	Shunt capacitor: $C = \frac{R_0\beta l}{Z_{Low}}$

### III.2.2 Stub Electrical Models

#### a- Richard's Transformation

Table-A III-4 Richard's transformations for shunt- and open-circuit stubs

Stub Configuration	Electrical Model	Mathematical Model
		$jX_L = jL \tan(\beta l)$
		$jB_C = jC \tan(\beta l)$

S.C.: Shunt circuit

O.C.: Open circuit

**b- Kuroda Identities**

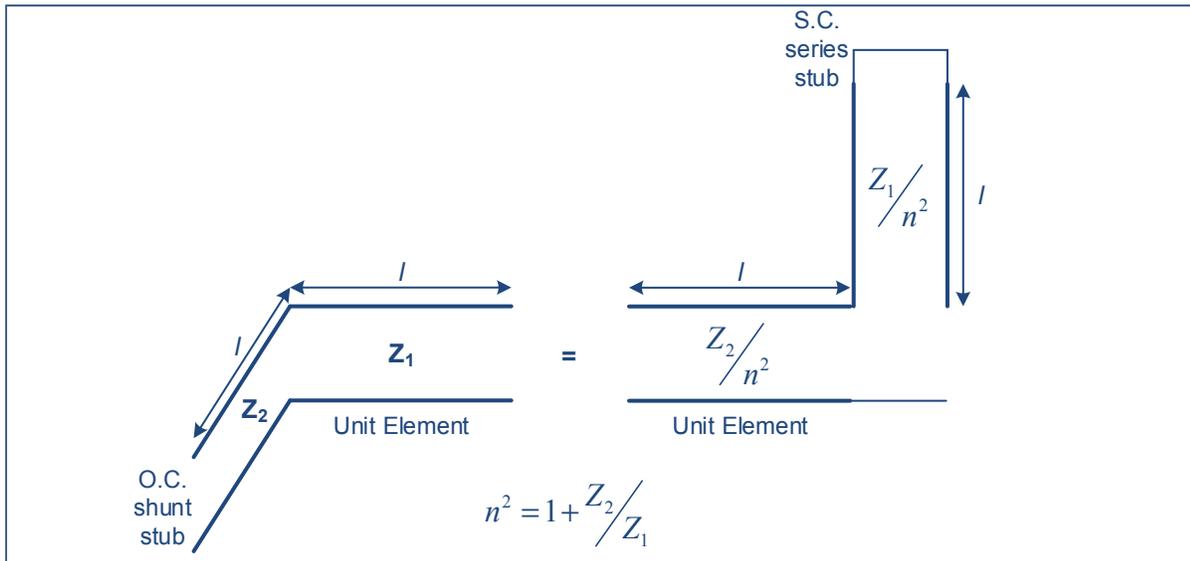


Figure-A III-1 Transformation of transmission lines using Kuroda identities

**III.3 Case Study 3: Radiofrequency Attenuator**

**III.3.1 General Definitions**

- General fixed resistive attenuator transfer function:

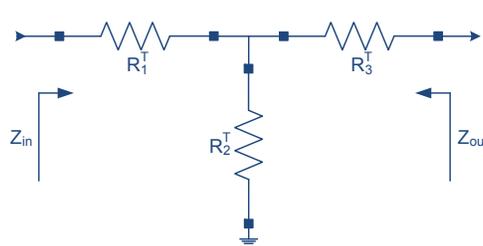
$$H(s)|_{s=\sigma+j\omega} = \frac{V_{out}(s)}{V_{in}(s)} = K \tag{A III-17}$$

where  $K$  is an attenuation factor.

### III.3.2 Examples of Resistive Attenuator Pads

#### III.3.2.1 T-Pad Symmetric Attenuator

- Calculation of T-pad attenuator elements:

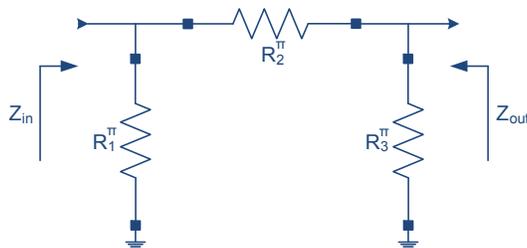


$$\begin{cases} A = 10^{\text{Attenuation}/10} \\ R_2^T = \frac{2\sqrt{Z_{in} \cdot Z_{out} \cdot A}}{A - 1} \\ R_1^T = \left(\frac{A + 1}{A - 1}\right) Z_{in} - R_2^T \\ R_3^T = \left(\frac{A + 1}{A - 1}\right) Z_{out} - R_2^T \end{cases} \quad (\text{A III-18})$$

where  $Z_{in}$ ,  $Z_{out}$  are respectively the input and output reference impedances and *Attenuation* is the required attenuation expressed in dB.

#### III.3.2.2 Π-Pad Symmetric Attenuator

- Calculation of Π-pad attenuator elements:



$$\begin{cases} A = 10^{\text{Attenuation}/10} \\ R_2^{\Pi} = \frac{1}{2}(A - 1) \sqrt{\frac{Z_{in} \cdot Z_{out}}{A}} \\ R_1^{\Pi} = \frac{1}{\frac{A + 1}{Z_{in}(A - 1)} - \frac{1}{R_2^{\Pi}}} \\ R_3^{\Pi} = \frac{1}{\frac{A + 1}{Z_{out}(A - 1)} - \frac{1}{R_2^{\Pi}}} \end{cases} \quad (\text{A III-19})$$

where  $Z_{in}$  and  $Z_{out}$  are respectively the input and output reference impedances and *Attenuation* is the required attenuation expressed in dB.

### III.4 Case Study 4: RF Mixer

- General radiofrequency mixer output function:

$$V_{out} = V_{LO}V_{RF} = \frac{A_1A_2}{2} \cdot [\cos((\omega_1 + \omega_2)t) + \cos((\omega_1 - \omega_2)t)] \quad (\text{A III-20})$$

where  $\omega_1$  (respectively  $\omega_2$ ) is the local oscillator (respectively RF signal) angular frequency.

### III.5 Additional References

The information provided in this appendix is a supplement to support the contents of Chapter 5. It is illustrative and not exhaustive. For an in-depth study of each design topic, the reader may refer to the references enumerated in Table-A III-5.

Table-A III-5 A list of references for a comprehensive study of the thesis design topics

Design Topic		References
RF filters	Fundamentals	(Ludwig et Bretchko, 2000; Rhea, 1994; Wanhammar, 2009)
	Lumped-component filters	(Bowick, 1982; Gilmore et Besser, 2003a; Pozar, 2012)
	Microstrip	(Hong et Lancaster, 2001; Steer, 2010)
RF attenuators	T and II topologies	(Steer, 2010; Vizmuller, 1995)
RF mixers	Single and double-balanced	(Gilmore et Besser, 2003b; Maas, 1998)

## LIST OF REFERENCES

- Abelson, Harold, Gerald Jay Sussman et Julie Sussman. 1996. *Structure and Interpretation of Computer Programs*, Second. MIT Press.
- Agilent. 2005. « Using Circuit Simulators »  
< <http://cp.literature.agilent.com/litweb/pdf/ads2005a/pdf/cktsim.pdf> >.
- Agilent. 2010a. « Exporting Files Using Genesys ».  
< <http://edocs.soco.agilent.com/display/genesys2010/Exporting+Data+Files+Using+Genesys> >. Consulté le 17 April 2014.
- Agilent. 2010b. « Importing Data Files Using SystemVue ».  
< <http://edocs.soco.agilent.com/display/sv201007/Importing+Data+Files+Using+SystemVue#ImportingDataFilesUsingSystemVue-XMLFileImport> >. Consulté le 17 April 2014.
- Agilent Technologies, Inc. 2008. « ADS Ptolemy Simulation ».  
< <http://cp.literature.agilent.com/litweb/pdf/ads2008/pdf/ptolemy.pdf> >.
- Agilent Technologies, Inc. 2013. « Agilent EEsof EDA: Product Overview ».  
< <http://literature.cdn.keysight.com/litweb/pdf/5991-3154EN.pdf?cmpid=zzfindesof-catalog> >. Consulté le 5 September 2013.
- Aguayo Gonzalez, Carlos R., Francisco M. Portelinho et Jeffery H. Reed. 2007. « Part 1: Design and Implementation of an SCA Core Framework for a DSP Platform ». *Military Embedded Systems Magazine*.
- Akretch, Faride. 2012. « Where RF meets analog and digital—the new embedded reality ».  
< <http://www.edn.com/electronics-blogs/scope-guru-on-signal-integrity/4395965/Where-RF-meets-analog-and-digital-the-new-embedded-reality> >. Consulté le January 2014.
- Allen, Phillip E., et Douglas R. Holberg. 2002. *CMOS Analog Circuit Design*, Second Oxford University Press.
- Almeida, Pedro De. 2008. « Model-Driven Architecture – Improving Software Development in Large-Scale Enterprise Applications ». University of Fribourg, Switzerland.
- Anderson, David L. 2009. « An evaluation of current and future costs for lithium-ion batteries for use in electrified vehicle powertrains ». Duke University.
- Andrew, Rufus. 2011. « 2020: The Ubiquitous Heterogeneous Network - Beyond 4G ».  
< [http://www.itu.int/dms\\_pub/itu-t/oth/29/05/T29050000130001PDFE.pdf](http://www.itu.int/dms_pub/itu-t/oth/29/05/T29050000130001PDFE.pdf) >.

- Andriana Voulkidou, Stylianos Siskos et Thomas Noulis. 2012. « Simulation Inaccuracies in Analog/RF Integrated Circuit Design in CMOS Process ». In *Second Pan-Hellenic Conference on Electronics and Telecommunications*.
- Arabi, Eyad, et Sadiq Ali. 2008. « Behavioral Modeling of RF front end devices in Simulink ». *Chalmers University of Technology, Sweden*.
- Archer, Norman P, Milena M Head et Yufei Yuan. 1996. « Patterns in information search for decision making: the effects of information abstraction ». *International Journal of Human-Computer Studies*, vol. 45, n° 5, p. 599-616.
- Ashbaugh, Floyd. 2009. « Meeting the Challenges of RF Wireless Design ». <[http://www.electronicproducts.com/Analog\\_Mixed\\_Signal\\_ICs/Sensors/Meeting\\_the\\_challenges\\_of\\_RF\\_wireless\\_design.aspx](http://www.electronicproducts.com/Analog_Mixed_Signal_ICs/Sensors/Meeting_the_challenges_of_RF_wireless_design.aspx)>. Consulté le 5 January 2014.
- Bahl, Inder Jit. 2003. *Lumped elements for RF and microwave circuits*. Artech house.
- Bako, Niko, Zeljko Butkovic et Adrijan Baric. 2010. « Design of Fully Differential Folded Cascode Operational Amplifier by the gm/ID Methodology ». In *Proceedings of the 33rd International Convention*. (Opatija, 24-28 May 2010 ), p. 89-94. IEEE.
- Baldwin, Douglas, et Greg W. Scragg. 2004. *The Object Primer*. Cambridge University Press.
- Balkir, Sina, Günhan Dünder et A Selcuk Ögrenci. 2003. *Analog VLSI Design Automation*. CRC Press.
- Balmelli, Laurent. 2007. « An Overview of the Systems Modeling Language for Products and Systems Development ». *Journal of Object Technology*, vol. 6, n° 6.
- Baudry, Benoit, Clementine Nebut et Yves Le Traon. 2007. « Model-driven engineering for requirements analysis ». In *Enterprise Distributed Object Computing Conference, 2007. EDOC 2007. 11th IEEE International*. p. 459-459. IEEE.
- Belloir, Nicolas, Jean-Michel Bruel, Natacha Hoang et Congduc Pham. 2008. « Utilisation de SysML pour la modélisation des réseaux de capteurs ». In *14ème Colloque International sur les Langages et Modèles à Objets*. (Montréal), p. 169-184.
- Berkley Design Automation. 2009. « Big Analog/RF Automation: Complex-Block Characterization and Full-Circuit Performance Simulation ».
- Beydeda, Sami, Matthias Book et Volker Gruhn. 2005. *Model-driven software development*, 15. Springer.
- Bézivin, Jean. 2005. « On the unification power of models ». *Software & Systems Modeling*, vol. 4, n° 2, p. 171-188.

- Bizzarri, Federico, Angelo Brambilla et Giancarlo Storti Gajani. 2011. « Phase Noise Simulation in Analog Mixed Signal Circuits: An Application to Pulse Energy Oscillators ». *Ieee Transactions on Circuits and Systems Ii-Express Briefs*, vol. 58, n° 3, p. 154-158.
- Blackburn, Mark R. 2008. *What's Model Driven Engineering (MDE) and how can it impact process, people, tools and productivity*. Tech. Rep. Systems and Software Consortium, Inc.
- Blyler, John. 2006. « Analog-RF IP Integration Challenges SoC Designers ». *Chip Design Magazine*. < <http://chipdesignmag.com/display.php?articleId=435> >. Consulté le 26 February 2014.
- Bowick, Chris 1982. *RF Circuit Design*. Newnes.
- Brambilla, Marco, Jordi Cabot et Manuel Wimmer. 2012. « Model-driven software engineering in practice ». *Synthesis Lectures on Software Engineering*, vol. 1, n° 1, p. 1-182.
- Briand, Lionel, Williams, Clay. 2005. « Model Driven Engineering Languages and Systems ». In *8th International Conference, MoDELS 2005*. (Montego Bay, Jamaica), p. October 2-7, 2005.
- Briggs, Mark. 2010. « Dynamic Frequency Selection (DFS) and the 5-GHz Unlicensed Band ».
- Cadence Design Systems, Inc. 2002. « The Rise of Digital/Mixed-signal Semiconductors and Systems-on-a-Chip ».
- « Cadence Design Tools Tutorial ». 2010.  
< <http://lsmwww.epfl.ch/Education/CadenceTutorial/flow.html> >. Consulté le 1 September 2013.
- Cardinal, Mario. 2013. *Executable Specifications with Scrum: A Practical Guide to Agile Requirements Discovery*. Addison-Wesley.
- Chang, Henry, et Ken Kundert. 2007. « Verification of complex analog and RF IC designs ». *Proceedings of the IEEE*, vol. 95, n° 3, p. 622-639.
- Chapin, John, et William Lehr. 2011. « Mobile broadband growth, spectrum scarcity, and sustainable competition ». In. TPRC.
- Chen, Deming. 2009a. « Design automation for microelectronics ». In *Springer Handbook of Automation*. p. 653-670. Springer.

- Chen, Deming. 2009b. « Springer Handbook of Automation ». In *Design Automation for Microelectronics*, sous la dir. de Nof, Shimon Y., p. 653-667. Springer.
- Chen, Lijun J., Steven H. Low et John C. Doyle. 2011. « Cross-layer design in multihop wireless networks ». *Computer Networks*, vol. 55, n° 2, p. 480-496.
- Cheng, Qingsha S., John W. Bandler, Slawomir Koziel, Mohamed H. Bakr et Stanislav Ogurtsov. 2010. « The state of the art of microwave CAD: EM-based optimization and modeling ». *International Journal of RF and Microwave Computer-Aided Engineering*, vol. 20, n° 5, p. 475-491.
- Chia, Stanley, Trevor Gill, L. Ibbetson, D. Lister, A. Pollard, R. Irmer, D. Almodovar, N. Holmes et S. Pike. 2008. « 3G evolution ». *Ieee Microwave Magazine*, vol. 9, n° 4, p. 52-63.
- Chien, Andrew A., et Vijay Karamcheti. 2013. « Moore's Law: The first ending and a new beginning ». *Computer*, n° 12, p. 48-53.
- Chonoles, Michael Jesse, et James A Schardt. 2011. *UML 2 for Dummies*. John Wiley & Sons.
- CIC. 2003. « Mixed-Signal IC Design Kit Training Manual ». p. 157. < [http://www2.ece.ohio-state.edu/~biky/ece822/MSDK\\_July\\_2003.pdf](http://www2.ece.ohio-state.edu/~biby/ece822/MSDK_July_2003.pdf) >. Consulté le 6 May 2014.
- Cisco. 2013. « Cisco Visual Networking Index: Global Mobile Data Traffic Forecast 2012–2017 ». < [http://www.cisco.com/en/US/solutions/collateral/ns341/ns525/ns537/ns705/ns827/VI-Forecast\\_QA.pdf](http://www.cisco.com/en/US/solutions/collateral/ns341/ns525/ns537/ns705/ns827/VI-Forecast_QA.pdf) >. Consulté le 22 March 2013.
- Cisco. 2015. « Cisco Visual Networking Index: Global Mobile Data Traffic Forecast Update, 2014–2019 ». < [http://www.cisco.com/c/en/us/solutions/collateral/service-provider/visual-networking-index-vni/white\\_paper\\_c11-520862.pdf](http://www.cisco.com/c/en/us/solutions/collateral/service-provider/visual-networking-index-vni/white_paper_c11-520862.pdf) >. Consulté le 15 July 2015.
- Comer, David J. 1985. « A theoretical basis for practical amplifier design using cascaded operational amplifiers ». In *IEE Proceedings G (Electronic Circuits and Systems)*. Vol. 132, p. 161-164. IET.
- Cornell University, Lectures. 2011. « Modular Programming: Modules and Signatures ». < <https://www.cs.cornell.edu/courses/cs3110/2011sp/lectures/lec07-modules/modules.htm> >. Consulté le 19 May 2014.
- Costa-Perez, Xavier, Andreas Festag, Hans-Joerg Kolbe, Juergen Quittek, Stefan Schmid, Martin Stiemerling, Joerg Swetina et Hans van der Veen. 2013. « Latest Trends in Telecommunication Standards ». *Acm Sigcomm Computer Communication Review*, vol. 43, n° 2, p. 64-71.

- Dackenberg, Jens. 2010. « Software Communication Architecture-Waveform Distribution with MHAL ».
- David, Alexandre, et Brian Nielsen. 2008. « Model-Driven Development of Embedded Real-Time Systems ». *ERCIM News*, vol. 2008, n° 75.
- De Smedt, Bart, et Georges Gielen. 1999. « Models for systematic design and verification of frequency synthesizers ». *Circuits and Systems II: Analog and Digital Signal Processing, IEEE Transactions on*, vol. 46, n° 10, p. 1301-1308.
- Delligatti, Lenny (304). 2013. *SysML Distilled: A Brief Guide to the Systems Modeling Language*, First. Addison-Wesley Professional.
- Dewey, Allen. 2000. « Digital and Analog Electronic Design Automation ». In *The Electrical Engineering Handbook*, sous la dir. de Dorf, Richard C.: CRC Press LLC.
- Dunham, William, Rich Kirkham, Doug Stolarz et Juergen Hartung. 2003. « RF Module Design: Requirements and Issues ». *RF Design Magazine*.
- Dutton, Robert W. 1997. « Device Simulation for RF Applications ». In *International Electron Devices Meeting Technical Digest*. p. 301-304.
- El-Khatib, Ziad, Leonard MacEachern et Samy A Mahmoud. 2012. *Distributed CMOS Bidirectional Amplifiers: Broadbanding and Linearization Techniques*. Springer Science & Business Media.
- Embley, David W., et Bernhard Thalheim. 2011. *Handbook of Conceptual Modeling: Theory, Practice, and Research Challenges*. Springer.
- Fernandes, João. « Principles of Model-Driven Software Engineering ». n° 6 June 2014, p. 49. <<http://alba.di.uminho.pt/por/content/download/2667/14015/file/unit7-mdse.pdf>>.
- Ferragina, Vincenzo, Nicola Ghittori, Guide Torelli, Giorgio Boselli, Gabriella Trucco et Valentino Liberali. 2005. « Analysis of Crosstalk Effects on Mixed-Signal CMOS ICs with Different Mounting Technologies ». In *Instrumentation and Measurement Technology Conference, 2005. IMTC 2005. Proceedings of the IEEE*. Vol. 3, p. 1979-1984. IEEE.
- Foster, Harry. 2012. « The 2012 Wilson Research Group Functional Verification Study ». <<http://www.mentor.com/products/fv/multimedia/the-2012-wilson-research-group-functional-verification-studyview>>. Consulté le June 3, 2013.
- Fowler, Martin. 2004. *UML distilled: a brief guide to the standard object modeling language*. Addison-Wesley Professional.

- Frankel, David S. 2003. *Model Driven Architecture: Applying MDA to Enterprise Computing*. John Wiley and Sons.
- Frevert, Ronny, Joachim Haase, Roland Jancke, Uwe Knochel, Peter Schwarz, Ralf Kakerow et Mohsen Darianian. 2006. *Modeling and Simulation for RF System Design*. Springer Science & Business Media.
- Friedenthal, Sanford, Alan Moore et Rick Steiner. 2008. *A Practical Guide to SysML: The Systems Modeling Language*. Morgan Kaufmann.
- Gajski, Daniel D., et Robert H. Kuhn. 1983. « New VLSI Tools ». *Computer*. Vol. 16, n° 12, p. 11-14.
- Gajski, Daniel D., Frank Vahid et Sanjiv Narayan. 1994. « A System-Design Methodology: Executable-Specification Refinement ». In *The European Conference on Design Automation*. (Paris, 28 Feb-3 Mar 1994 ), p. 458-463. IEEE. <<http://ieeexplore.ieee.org/ielx2/946/7755/00326836.pdf?tp=&arnumber=326836&isnumber=7755> >.
- Gerez, Sabih H. 1999. *Algorithms for VLSI design automation*, 8. Wiley New York.
- Gianesello, Fred. 2012. « Analog and RF Requirements for Advanced CMOS Nodes: The SOI Perspective ». In *Lund Circuit Design Workshop*. (October 3, 2012). <<http://cdworkshop.eit.lth.se/fileadmin/eit/group/71/2012/STM-Gianesello.pdf> >.
- Gielen, Georges G.E., et Rob A. Rutenbar. 2000. « Computer-Aided Design of Analog and Mixed-Signal Integrated Circuits ». In *IEEE Proceedings*. Vol. 88, p. 1825-1852. <<http://ieeexplore.ieee.org/ielx5/5/19471/00899053.pdf?tp=&arnumber=899053&isnumber=19471> >.
- Gielen, Georges G.E. 2007. « Design tool solutions for mixed-signal/RF circuit design in CMOS nanometer technologies ». In *Proceedings of the 2007 Asia and South Pacific Design Automation Conference*. p. 432-437. IEEE Computer Society.
- Gilmore, Rowan, et Less Besser. 2003a. *Practical RF Circuit Design for Modern Wireless Systems: Volume I – Passive Circuits and Systems*. Artech House.
- Gilmore, Rowan, et Less Besser. 2003b. *Practical RF Circuit Design for Modern Wireless Systems: Volume II – Active Circuits and Systems*. Artech House.
- Goldstone, Robert L., et Lawrence W. Barsalou. 1998. « Reuniting perception and conception ». *Cognition*, vol. 65, n° 2, p. 231-262.

- González, Delia Rodríguez de Llera, Ana Rusu et Mohammed Ismail. 2007. « EDA for RF and analog front-ends in the 4G Era: Challenges and solutions ». In *Circuit Theory and Design, 2007. ECCTD 2007. 18th European Conference on*. p. 24-27. IEEE.
- Grant, Doug. 2012. « RF, meet Analog; and his friend Digital ». <[http://www.eetimes.com/author.asp?section\\_id=36&doc\\_id=1285742](http://www.eetimes.com/author.asp?section_id=36&doc_id=1285742)>. Consulté le 26 February 2014.
- Graves, Henson, Stephen Guest, Jeff Vermette et Yvonne Bijan. 2009. « Air Vehicle Model-Based Design and Simulation Pilot ». In *Simulation Interoperability Workshop (SIW)*. <[http://www.omgwiki.org/MBSE/lib/exe/fetch.php?media=mbse:09s-siw-056\\_mbds.pdf](http://www.omgwiki.org/MBSE/lib/exe/fetch.php?media=mbse:09s-siw-056_mbds.pdf)>.
- Green, Leslie. 2001. « RF-inductor Modeling for the 21st Century ». *EDN Magazine*, vol. 46, n° 22, p. 67-74.
- Grout, Ian. 2008. *Digital Systems Design with FPGAs and CPLDs*. Newnes.
- Gruner, Daniel, Zihui Zhang, Viswanathan Subramanian, Falk Korndoerfer et Georg Boeck. 2007. « Lumped Element MIM capacitor model for Si-RFICs ». In *Microwave and Optoelectronics Conference, 2007. IMOC 2007. SBMO/IEEE MTT-S International*. p. 149-152. IEEE.
- Guo, Weisi O'Farrell, Tim. 2011. « Reducing Energy Consumption of Wireless Communications ». In *United Kingdom Council Conference on Digital Engagement*.
- Handziski, Vlado, Joseph Polastre, Jan-Hinrich Hauer, Cory Sharp, Adam Wolisz et David Culler. 2005. « Flexible hardware abstraction for wireless sensor networks ». In *Wireless Sensor Networks, 2005. Proceedings of the Second European Workshop on*. p. 145-157. IEEE.
- Hansen, K. 2003. « Wireless RF design challenges ». *2003 Ieee Radio Frequency Integrated Circuits (Rfic) Symposium, Digest of Papers*, p. 3-7.
- Hartin, OL, et Evan Yu. 2006. « RF Physical Device Simulation for Wireless Applications ». In *2006 16th Biennial University/Government/Industry Microelectronics Symposium*.
- Henke, Russ. 2010a. « Agilent EEsof EDA – Part I ». <[http://www10.edacafe.com/nbc/articles/view\\_weekly.php?section=Magazine&articleid=782353](http://www10.edacafe.com/nbc/articles/view_weekly.php?section=Magazine&articleid=782353)>. Consulté le 5 January 2013.
- Henke, Russ. 2010b. « Agilent EEsof EDA – Part II ». <[http://www10.edacafe.com/nbc/articles/view\\_article.php?articleid=803282&page\\_no=1](http://www10.edacafe.com/nbc/articles/view_article.php?articleid=803282&page_no=1)>. Consulté le 5 January 2013.

- Henry, Sallie M, et Mark Lattanzi. 1994. « Measurement of Software Maintainability and Reusability in the Object Oriented Paradigm ».
- Holt, Jon, et Simon Perry. 2008. *SysML for Systems Engineering*. The Institution of Engineering and Technology.
- Hong, Jia-Sheng, et M.J. Lancaster. 2001. *Microstrip Filters for RF/Microwave Applications*. John Wiley and Sons.
- Hsiung, Pao-Ann, Shang-Wei Lin, Yean-Ru Chen, Nien-Lin Hsueh, Chih-Hung Chang, Chih-Hsiung Shih, Chorng-Shiuh Koong, Chao-Sheng Lin, Chun-Hsien Lu et Sheng-Ya Tong. 2009. « Model-driven development of multi-core embedded software ». In *Multicore Software Engineering, 2009. IWMSE'09. ICSE Workshop on*. p. 9-16. IEEE.
- Hu, Chenming. 1993. « Future CMOS scaling and reliability ». *Proceedings of the IEEE*, vol. 81, n° 5, p. 682-689.
- Hubbard, Mathew 2012. « Taming the Smartphone Power Consumption Vicious Cycle ». *Microwave Journal*, vol. 55, n° 11, p. 92-96.
- InetDaemon.Com. 2013. « A Comparison of Network Models ». <[http://www.inetdaemon.com/tutorials/basic\\_concepts/network\\_models/comparison.shtml](http://www.inetdaemon.com/tutorials/basic_concepts/network_models/comparison.shtml)>. Consulté le 28 April 2013.
- Iniewski, Krzysztof. 2007. *Wireless technologies: circuits, systems, and devices*. CRC press.
- Intel. 2013a. « Intel Chips Timeline ». <<http://www.intel.com/content/www/us/en/history/history-intel-chips-timeline-poster.html>>.
- Intel. 2013b. « Transistors to Transformations: From Sand to Circuits - How Intel Makes Chips ». <<http://exploreintel.com/assets/pdf/aloha/museum-transistors-to-transformations-brochure.pdf>>.
- Irmer, R., et S. Chia. 2009. « Signal Processing Challenges for Future Wireless Communications ». *2009 Ieee International Conference on Acoustics, Speech, and Signal Processing, Vols 1- 8, Proceedings*, p. 3625-3628.
- ITU. 2013. « Trends in Telecommunication Reform 2013: Transnational Aspects of Regulation in a Networked Society ». <[http://www.itu.int/dms\\_pub/itu-d/opb/reg/D-REG-TTR.14-2013-SUM-PDF-E.pdf](http://www.itu.int/dms_pub/itu-d/opb/reg/D-REG-TTR.14-2013-SUM-PDF-E.pdf)>. Consulté le 30 may 2013.
- Jiang, Hai, Weihua H. Zhuang et Xuemin M. Shen. 2005. « Cross-layer design for resource allocation in 3G wireless networks and beyond ». *Ieee Communications Magazine*, vol. 43, n° 12, p. 120-126.

- JTRS. 2010. *Joint Tactical Radio System (JTRS) Standard Modem Hardware Abstraction Layer Application Program Interface (API)*. Joint Program Executive Office. < [http://jtnc.mil/sca/Documents/SCA\\_APIs/API\\_3.0\\_20131002\\_Mhal.pdf](http://jtnc.mil/sca/Documents/SCA_APIs/API_3.0_20131002_Mhal.pdf) >.
- Kao, Chia-Hsiung, Yin-Fang Wei et Huan-Chou Kuo. 2001. « A rail-to-rail CMOS operational amplifier design for low voltage systems ». *Proc. AMPC*, vol. 1, p. 276-279.
- Karban, Robert, Michele Zamparelli, Bertrand Bauvir, Bertrand Koehler, Lothar Noethe et A. Balestra. 2008. « Exploring Model Based Engineering for Large Telescopes - Getting Started with Descriptive Models ». *SPIE Astronomical Telescopes and Instrumentation*.
- Kelly, Steven, et Juha-Pekka Tolvanen. 2008. *Domain-Specific Modeling: Enabling Full Code Generation*. John Wiley and Sons.
- Kendal, Simon. 2011. *Object Oriented Programming Using C#*. Simon Kendal & Ventus Publishing.
- Kevenaar, Tom A.M., et E.J.W. ter Maten. 1999. « RF IC Simulation: State-of-the-art and Future Trends ». In *International Conference on Simulation of Semiconductor Processes and Devices*. (Kyoto, 06 Sep 1999-08 Sep 1999 ), p. 7-10. <<http://ieeexplore.ieee.org/ielx5/6469/17293/00799246.pdf?tp=&arnumber=799246&isnumber=17293>>.
- Khare, Kavita, Nilay Khare et Pawan Kumar Sethiya. 2008. « Analysis of low voltage rail-to-rail CMOS operational amplifier design ». In *Electronic Design, 2008. ICED 2008. International Conference on*. p. 1-4. IEEE.
- Kienhuis, Bart, Ed Deprettere, Kees Vissers, Pieter Van der Wolf, Paul Lieverse et Edward Lee. 2000. « Y-chart Methodology and Models of Computation and Architecture ». In *37th Design Automation Conference*.
- Kleppe, Anneke G., Jos Warmer et Wim Bast. 2003. *MDA Explained - The Model-driven Architecture: Practice and Promise*. Addison-Wesley Longman Publishing Co., Inc., Boston, MA.
- Klump, Raymond P. 2001. « Understanding Object-Oriented Programming Concepts ». In *IEEE Power Engineering Society Summer Meeting*. (Vancouver, 15 Jul 2001-19 Jul 2001 ). Vol. 2, p. 1070-1074. <<http://ieeexplore.ieee.org/ielx5/7659/20923/00970207.pdf?tp=&arnumber=970207&isnumber=20923>>.
- Koffman, Elliot B., et Paul A.T. Wolfgang. 2006. *Objects, Abstraction, Data Structures and Design Using C++*. John Wiley and Sons.

- Korhonen, Kaisa. 2011. « Predicting Mobile Device Battery Life ». Aalto University, Finland.
- Koutitas, George, et Panagiotis Demestichas. 2010. « A review of energy efficiency in telecommunication networks ». *Telfor journal*, vol. 2, n° 1, p. 2-7.
- Kundert, Ken, et Henry Chang. 2005. « Top-Down Design and Verification of Mixed-Signal Integrated Circuits ». p. 1-8.
- Kundert, Ken, Henry Chang, David Jefferies, G. Lamant, Enrico Malavasi et F. Sendig. 2000. « Design of mixed-signal systems-on-a-chip ». *Ieee Transactions on Computer-Aided Design of Integrated Circuits and Systems*, vol. 19, n° 12, p. 1561-1571.
- Kundert, Ken. 2005. « Challenges in RF Simulation ». In *RF IC Symposium*.
- Kundert, Ken. 2006. « Principles of Top-Down Mixed-Signal Design ». p. 1-31.
- Lafi, Sabeur, Roger Champagne, Ammar B. Kouki et Jean Belzile. 2008. « Modeling radio-frequency front-ends using sysml: A case study of a umts transceiver ». *ACESMB 2008*, p. 115.
- Lang Tong, et al. 2002. « Future Challenges of Signal Processing and Communications in Wireless Networks ». In *NSF/ONR/ARL Workshop on Future Directions in Signal Processing and Wireless Networking*.
- Lange, Christoph, Dirk Kosiankowski, A. Betker, H. Simon, Nico Bayer, Dirk von Hugo, H. Lehmann et Andreas Gladisch. 2014. « Energy Efficiency of Load-Adaptively Operated Telecommunication Networks ». *Journal of Lightwave Technology*, vol. 32, n° 4, p. 571-590.
- Lange, Christian F.J., Michel R.V. Chaudron et Johan Muskens. 2006. « In practice: UML software architecture and design description ». *Software, IEEE*, vol. 23, n° 2, p. 40-46.
- Lavagno, Luciano, Grant Martin et Louis Scheffer. 2006. *Electronic Design Automation for Integrated Circuits Handbook-2 Volume Set*. CRC Press, Inc.
- Lee, Young, et Kai H Chang. 2000. « Reusability and maintainability metrics for object-oriented software ». In *Proceedings of the 38th annual on Southeast regional conference*. p. 88-94. ACM.
- Leenaerts, Domine; Georges G.E. ; Gielen et Rob A. Rutenbar. 2001. « CAD Solutions and Outstanding Challenges for Mixed-Signal and RF IC Design ». In *IEEE/ACM International Conference on Computer-Aided Design*. (4-8 Nov. 2001 ), p. 270-277. <<http://ieeexplore.ieee.org/ielx5/7652/20895/00968633.pdf?tp=&arnumber=968633&isnumber=20895>>.

- Li, Xin, B. Taylor, Yu Tsun Chien et Lawrence T. Pileggi. 2007. « Adaptive post-silicon tuning for analog circuits: Concept, analysis and optimization ». *Ieee/Acm International Conference on Computer-Aided Design Digest of Technical Papers, Vols 1 and 2*, p. 450-457.
- Lidow, Alex, et Strydom, Johan. 2013. « GaN Transistors for Efficient Power Conversion ». *Power Electronics Europe Magazine*, n° 3, p. 38-40.
- Lin, Jin, et Zhao Tong. 2011. « EDA Technology and its Implementation in Modern Electronic Technology ». In *International Conference on Business Management and Electronic Information*. (Guangzhou, 13-15 May 2011 ). Vol. 2, p. 816-819. IEEE. <<http://ieeexplore.ieee.org/ielx5/5871804/5917827/05920355.pdf?tp=&arnumber=5920355&isnumber=5917827>>.
- Lin, Rung-Bin. 2005. « Electronic Design Automation: Evolution, Education and Profession ». <<http://vlsi.cse.yzu.edu.tw/%E6%96%87%E7%AB%A0/Electronic%20Design%20Automation.pdf>>.
- Lind, Gregg, et Cameron Littke. 2004. « Software Communication Architecture (SCA) for above 2 GHz Satcom ». In *Proceeding of the SDR 04 Technical Conference and Product Exposition*.
- Ludwig, Reinhold, et P. Bretchko (241-253). 2000. *RF Circuit Design: Theory and Application*. Prentice Hall.
- Maas, Stephen A. 1998. *The RF and Microwave Circuit Design Cookbook*. Artech House.
- Maloratsky, Leo G. 2010. « Design and Technology Tradeoffs in Passive RF and Microwave Integrated Circuits ». *High Frequency Electronics*, p. 40-54.
- Markova, Ekaterina. 2009. « Liberalization and Regulation of the Telecommunications Sector in Transition Countries: The Case of Russia ».
- Masoumi, Nasser, M. I. Elmasry, S. Safavi-Naeini et S. J. Kovacic. 2001. « Substrate-coupling noise analysis of a mixed-signal RF IC using an efficient technique for substrate parasitic extraction ». In *Proc. Int. Conference on Circuits, Systems, Communications and Computers*. p. 328-334.
- Masselos K., Blionas S. et Rautio T. 2002. « Reconfigurability Requirements of Wireless Communication Systems ». In *IEEE Workshop on Heterogeneous Reconfigurable Systems on Chip, Chances, Application, Trends*.
- McMahon, Jim. 2009. « Design Tools, Flows and Methodologies for RF and Mixed-Signal ICs ». In *SOI Industry Consortium Design Clinic*.

- Mellor, Stephen, Kendall Scott, Axel Uhl et Dirk Weise. 2004. *MDA Distilled: Principles of Model-Driven Architecture*. Addison-Wesley.
- Mellor, Stephen J., Marc Balcer et Ivar Foreword By-Jacobson. 2002. *Executable UML: A foundation for model-driven architectures*. Addison-Wesley Longman Publishing Co., Inc.
- Micallef, Gilbert. 2013. « Energy Efficient Evolution of Mobile Broadband Networks ». Aalborg University, Denmark.
- Milicev, Dragan. 2009. *Model-Driven Development with Executable UML*. John Wiley and Sons.
- Miller, Joaquin. 2003. « Model-Driven Architecture Tutorial ». < [http://www.joaquin.net/MDA/Model\\_Driven\\_Architecture\\_Tutorial.pdf](http://www.joaquin.net/MDA/Model_Driven_Architecture_Tutorial.pdf) >. Consulté le 2 June 2014.
- Mobile Europe, Blog. 2012. « How the iPhone 5 illustrates the RF complexity facing device vendors ». < <http://www.mobileeurope.co.uk/magazine/blog/how-the-iphone-5-illustrates-rf-complexity-for-device-vendors> >.
- MobileInfo. « 4G - Beyond 2.5G and 3G Wireless Networks ». < <http://www.mobileinfo.com/3G/4GVision&Technologies.htm> >. Consulté le January 3, 2014.
- Moore, Gordon E. 2006. « Cramming more components onto integrated circuits, Reprinted from Electronics, volume 38, number 8, April 19, 1965, pp. 114 ». *IEEE Solid-State Circuits Newsletter*, vol. 3, n° 20, p. 33-35.
- MOSIS. 2010. « What is MOSIS? ». < <https://www.mosis.com/what-is-mosis> >.
- Muck, M., S. ; Buljore, D. ; Bourse, P. ; Martigne, A. ; Lilis, E. ; Patouni, M. ; Stamatelatos, K. ; Tsagkaris et P. Demestichas. 2007. « Reconfigurable Wireless Communication Systems Applying Distributed Decision-Making in a Heterogeneous Radio Environment ». In *16th IST Mobile and Wireless Communications Summit Conference Proceedings*. (1-5 July 2007). 1-5. < <http://ieeexplore.ieee.org/ielx5/4299028/4299029/04299280.pdf?tp=&arnumber=4299280&isnumber=4299029> >.
- National Instruments, Inc. 2013. « Product Overview ». < <http://www.awrcorp.com/product-overview> >. Consulté le 5 September 2013.
- National Instruments, Inc. 2014. « AWR Design User Guide ». < [https://awrcorp.com/download/faq/english/docs/Users\\_Guide/data\\_files.html](https://awrcorp.com/download/faq/english/docs/Users_Guide/data_files.html) >. Consulté le 13 April 2014.

- Nokia Siemens Networks, Corporation. 2011. « 2020 - Beyond 4G Networks Radio Evolution for the Gigabit Experience ». Consulté le January 3, 2014.
- Nortel. 2008. *Long-Term Evolution (LTE): The vision beyond 3G*. Nortel Networks.
- OMG. 1997. « About OMG ». < <http://www.omg.org/gettingstarted/gettingstartedindex.htm> >. Consulté le 24 March 2014.
- OMG. 2001. « Model-Driven Architecture: A Technical Perspective ». < <http://www.omg.org/cgi-bin/doc?ormsc/01-07-01.pdf> >.
- OMG. 2007. *PIM and PSM Specification for Software Radio Components*. Object Management Group. < <http://www.omg.org/spec/SDRP/1.0/> >.
- OMG. 2013a. *OMG Systems Modeling Language Specifications*. < <http://www.omg.org/spec/SysML/1.3/PDF/> >.
- OMG. 2013b. « The Systems Engineering DSIG Info ». < [http://syseng.omg.org/syseng\\_info.htm](http://syseng.omg.org/syseng_info.htm) >.
- OMG. 2014. « OMG Systems Modeling Language ». < <http://www.omgsysml.org/> >.
- Parihar, Rajkumar S., et Anu Gupta. 2009. « Design of a Fully Differential Two-Stage CMOS Op-Amp for High-gain, High Bandwidth Applications ». *IEEE Journal of Microchip Technology*, p. 32-38.
- Parizi, Hooman; Ashfin ; Niktash, Amir Hosein ; Kamalizad et Nader Bagherzadeh. 2006. « A Reconfigurable Architecture for Wireless Communication Systems ». In *Proceedings of the Third International Conference on Information Technology: New Generations*. (10-12 April 2006 ), p. 250-255. <<http://ieeexplore.ieee.org/ielx5/10728/33849/01611602.pdf?tp=&arnumber=1611602&isnumber=33849>>.
- Park, J., J. ; Hartung et H. Dudek. 2007. « Complete Front-to-back RF SiP Design Implementation Flow ». In *Proceedings of 57th Electronic Components and Technology Conference*. (May 29 2007-June 1 2007), p. 986-991. <<http://ieeexplore.ieee.org/ielx5/4249837/4249838/04250003.pdf?tp=&arnumber=4250003&isnumber=4249838>>.
- Pastor, Oscar, et Juan Carlos Molina. 2007. *Model-driven architecture in practice: a software production environment based on conceptual modeling*. Springer Science & Business Media.

- Peak, Russell S., Roger M. Burkhart, Sanford A. Friedenthal, Miyako W. Wilson, Manas Bajaj et Injoong Kim. 2007a. « Simulation-Based Design Using SysML Part 1: A Parametrics Primer ». In *INCOSE International Symposium*.
- Peak, Russell S., Roger M. Burkhart, Sanford A. Friedenthal, Miyako W. Wilson, Manas Bajaj et Injoong Kim. 2007b. « Simulation-Based Design Using SysML Part 2: Celebrating Diversity by Example ». In *INCOSE International Symposium*.
- Pehkonen, K., S. Uskela, K. Kalliojarvi, L. Oksanen et K. Rikkinen. 2001. « Key technologies and concepts for beyond-3G networks ». *Apoc 2001: Asia-Pacific Optical and Wireless Communications: Wireless and Mobile Communications*, vol. 4586, p. 43-57.
- Peterson, Larry L., et Bruce S. Davie. 2003. *Computer Networks: A Systems Approach*. Morgan Kaufmann Publishers.
- Petz, Kathy. 2012. « Overcoming Spectrum Scarcity ». < <http://theinstitute.ieee.org/technology-focus/technology-topic/overcoming-spectrum-scarcity> >.
- Pierce, Benjamin C. 2002. *Types and Programming Languages*. MIT Press.
- Poole, Ian. 2013. « Challenges of Designing RF Test Equipment ». < <http://www.radio-electronics.com/articles/test-measurement/challenges-of-designing-rf-test-equipment-94> >. Consulté le January 2014.
- Poole, John D. 2001. « Model-Driven Architecture: Vision, Standards and Emerging Tools ». In *Workshop on Metamodeling and Adaptive Object Models*. < [http://www.omg.org/mda/mda\\_files/Model-Driven\\_Architecture.pdf](http://www.omg.org/mda/mda_files/Model-Driven_Architecture.pdf) >.
- Pozar, David M. (732). 2012. *Microwave Engineering*, Fourth. John Wiley and Sons.
- Pucker, Lee. 2007. « Trends in DSP ». *Communications Magazine, IEEE*, vol. 45, n° 9, p. 40-42.
- Pulsford, Nick. 2002. « Passive integration technology: Targeting small, accurate RF parts ». *RF design*, vol. 25, n° 11, p. 40-48.
- Rabaey, Jan M., Anantha Chandrakasan et Borivoje Nikolic. 2002. *Digital Integrated Circuits: a Design Perspective*. Prentice Hall.
- Ramakrishnan, Raghu. 1998. *Database Management Systems*. McGraw-Hill.
- Razavi, Behzad. 1997. *RF Microelectronics*, Second Prentice Hall.
- Razavi, Behzad. 1998. *RF microelectronics*, 1. Prentice Hall New Jersey.

- Rhea, R.W. 1994. *HF Filter Design and Computer Simulation*. Noble Publishing Corporation.
- Robertson, I. D. , et S. Lucyszyn. 2009. *RFIC and MMIC Design and Technology*. Circuits, Devices and Systems Series. The Institution of Engineering and Technology
- Roman Friedrich, Gregor Harter, Barry Jeruzelski, Edward Tse. 2006. *A Dozen Trends in Telecommunications: Perspective Paper*. Booz & Company Whitepaper.
- Roques, Pascal. 2015. « How modeling can be useful to better define and trace requirements ». < <http://re-magazine.ireb.org/issues/2015-2-bridging-the-impossible/modeling-requirements-with-sysml/> >.
- Rozenberg, Grzegorz , et Frits Vaandrager. 1998. *Lectures on Embedded Systems*. Springer.
- Rubin, Steven M. 1987. *Computer aids for VLSI design*. Addison-Wesley Reading, Massachusetts, USA.
- Rutenbar, Rob A. 2006. « Design automation for analog: the next generation of tool challenges ». In *Proceedings of the 2006 IEEE/ACM international conference on Computer-aided design*. p. 458-460. ACM.
- Saitta, Lorenza, et Jean-Daniel Zucker. 2013. *Abstraction in artificial intelligence and complex systems*. Springer.
- Saleh, R., S. ; Wilton, Mirabbasi, A. ; S. ; Hu, M. ; Greenstreet, G. ; Lemieux, P.P. ; Pande, C. ; Grecu et A. Ivanov. 2003. « System-on-Chip: Reuse and Integration ». In *Proceedings of the IEEE*. Vol. 94, p. 1050-1069.  
<<http://ieeexplore.ieee.org/ielx5/5/34642/01652898.pdf?tp=&arnumber=1652898&isnumber=34642> >.
- Saleh, Resve A., Shyh-Jye Jou et A. Richard Newton. 1994. *Mixed-Mode Simulation and Analog Multilevel Simulation*. Springer.
- Saleh, Resve A., Shyh-Jye Jou et A. Richard Newton. 2013. *Mixed-mode simulation and analog multilevel simulation*, 279. Springer Science & Business Media.
- Sangiovanni-Vincentelli, Alberto. 2003. « The Tides of EDA ». In *IEEE Design on Test of Computers*. Vol. 20, p. 59-75.  
<<http://ieeexplore.ieee.org/ielx5/54/27925/01246165.pdf?tp=&arnumber=1246165&isnumber=27925> >.
- Sayre, Cotter W. (719). 2008. *Complete Wireless Design*, Second Edition. McGraw Hill.
- Schach, Stephen R. 2002. *Object-oriented and Classical Software Engineering*, 6. McGraw-Hill New York.

- Schmidt, Douglas C. 2006. « Model-driven engineering ». *Computer*, vol. 39, n° 2, p. 25-31.
- Sebesta, Robert W. (816). 2012. *Concepts of Programming Languages*, Tenth. Pearson Education.
- Shakkottai, Sanjay, Theodore S. Rappaport et Peter C. Karlsson. 2003. « Cross-layer design for wireless networks ». *Communications Magazine, IEEE*, vol. 41, n° 10, p. 74-80.
- Sherwani, Naveed. 2002. *Algorithms for VLSI Physical Design Automation*, Third. Kluwer Academic Publishers.
- Sherwani, Naveed A. 2012. *Algorithms for VLSI physical design automation*. Springer Science & Business Media.
- Shi, Qinghai, Uwe Tröltzsch et Olfa Kanoun. 2011. « Analysis of the parameters of a lossy coaxial cable for cable fault location ». In *Systems, Signals and Devices (SSD), 2011 8th International Multi-Conference on*. p. 1-6. IEEE.
- Silberschatz, Abraham, Henry F. Korth et S. Sudarshan. 2011. *Database System Concepts*, Sixth. McGraw-Hill.
- Song, Guocong, et Ye Li. 2005. « Cross-layer optimization for OFDM wireless networks - Part I: Theoretical framework ». *Ieee Transactions on Wireless Communications*, vol. 4, n° 2, p. 614-624.
- Sorrentino, Roberto, et Giovanni Bianchi. 2010. *Microwave and RF Engineering*. John Wiley and Sons.
- Spoto, James, George Chrisikos, Michael Heimlich et Steve Maas. 2006. « The importance and challenges of comprehending circuit and physical phenomena in RF system design and integration ». In *Solid-State and Integrated Circuit Technology, 2006. ICSICT'06. 8th International Conference on*. p. 1825-1828. IEEE.
- Starr, Leon. 2002. *Executable UML: How to Build Class Models*. Prentice-Hall.
- Stenkiste, Peter, Douglas Sicker, Gary Minden et Dipankar Raychaudhuri. 2009. « Future directions in cognitive radio network research ». In *NSF workshop report*. Vol. 4, p. 1-2.
- Steer, Micheal. 2010. *Microwave and RF Design: A Systems Approach*. Scitech Publishing.
- Sun, Yiqin, Lei Li, Han Lin, Zhiyuan Yu, Mian Huang et Lixi Wan. 2008. « Attenuators using thin film resistors for RF application ». In *2008 International Conference on Electronic Packaging Technology & High Density Packaging*. p. 1-3.

- Tanenbaum, Andrew S. 2009. *Modern Operating Systems*, Third Prentice Hall.
- Teppola, S., P. Parviainen et J. Takalo. 2009. « Challenges in the Deployment of Model Driven Development ». In *Fourth International Conference on Software Engineering Advances*. (Porto 20-25 Sept. 2009 ), p. 15-20.  
<<http://ieeexplore.ieee.org/ielx5/5298192/5298193/05298434.pdf?tp=&arnumber=5298434&isnumber=5298193>>.
- The Open Group, Inc. 2006. « Developing Architecture Views ». <<http://pubs.opengroup.org/architecture/togaf8-doc/arch/chap31.html>>.
- Thompson, Marc T. 2010. *Intuitive Analog Circuit Design*. Newnes.
- Trask, Bruce, Dominick Paniscotti, Angel Roman et Vikram Bhanot. 2006. « Using model-driven engineering to complement software product line engineering in developing software defined radio components and applications ». In *Companion to the 21st ACM SIGPLAN symposium on Object-oriented programming systems, languages, and applications*. p. 846-853. ACM.
- Truyen, Frank. 2006. « The Fast Guide to Model Driven Architecture The Basics of Model Driven Architecture ». *Cephas Consulting Corp*.
- Van Deursen, Arie, Paul Klint et Joost Visser. 2000. « Domain-Specific Languages: An Annotated Bibliography ». *Sigplan Notices*, vol. 35, n° 6, p. 26-36.
- Vereecken, W., W. Van Heddeghem, M. Deruyck, B. Puype, B. Lannoo, W. Joseph, D. Colle, L. Martens et P. Demeester. 2011. « Power Consumption in Telecommunication Networks: Overview and Reduction Strategies ». *Ieee Communications Magazine*, vol. 49, n° 6, p. 62-69.
- Verspecht, Jan. 2005. « Large-signal network analysis ». *Microwave Magazine, IEEE*, vol. 6, n° 4, p. 82-92.
- Verspecht, Jan, et David E Root. 2006. « Polyharmonic distortion modeling ». *Microwave Magazine, IEEE*, vol. 7, n° 3, p. 44-57.
- Viklund, Per. 2005. « Managing the Challenges in RF/Microwave Designs ». *Printed Circuit Design & Manufacture*, vol. 22, n° 11.
- Vishay. 2009. « Frequency Response of Thin Film Chip Resistors ». <<http://www.vishay.com/docs/60107/freqresp.pdf>>.
- Vivier, Guillaume. 2013. *Reconfigurable Mobile Radio Systems: A Snapshot of Key Aspects Related to Reconfigurability in Wireless Systems*. John Wiley & Sons.

- Vizmuller, Peter. 1995. *RF design guide: systems, circuits, and equations*, 1. Artech House.
- Völter, Markus, Thomas Stahl, Jorn Bettin, Arno Haase et Simon Helsen. 2006. *Model-Driven Software Development: Technology, Engineering, Management*. John Wiley and Sons.
- W3C. 2013. « Extensible Markup Language (XML) ». < <http://www.w3.org/XML/> >. Consulté le 25 March 2014.
- Wambacq, P.; Gerd ; Vandersteen, J. ; Phillips, J. ; Roychowdhury, W. ; Eberle, Baolin Yang ;, D. ; Long et A. Demir. 2001. « CAD for RF Circuits ». In *Proceedings of Design, Automation and Test in Europe*. (13 Mar 2001-16 Mar 2001), p. 520-527. <<http://ieeexplore.ieee.org/ielx5/7307/19761/00915073.pdf?tp=&arnumber=915073&isnumber=19761>>.
- Wang, Laung-Terng, Yao-Wen Chang et Kwang-Ting Tim Cheng. 2009. *Electronic design automation: synthesis, verification, and test*. Morgan Kaufmann.
- Wang, Laung-Terng, Charles E. Stroud et Nur A. Touba (893). 2008. *System-on-Chip Test Architectures: Nanometer Design for Testability*. Coll. « The Morgan Kaufmann Series in Systems on Silicon ». Morgan Kaufmann Publishers.
- Wanhammar, L. 2009. *Analog Filters Using Matlab*. Springer Science.
- Warwick, Colin, et Mike Mulligan. 2005. « Using behavioral models to drive RF design and verify system performance ». *RF Design, March*.
- Weilkiens, Tim. 2008. *Systems Engineering with SysML/UML: Modeling, Analysis, Design*. Morgan Kaufmann.
- White, Joseph F. 2004. *High frequency techniques: an introduction to RF and microwave engineering*. John Wiley & Sons.
- Williams, Lawrence, Daniel Wu et Albert Yen. 2005. « Advanced Simulation Eases UWB RFIC Design Flow ». *Electrical Engineering Times*. < [http://www.eetimes.com/document.asp?doc\\_id=1273402](http://www.eetimes.com/document.asp?doc_id=1273402) >.
- Wong, Stephen, et Dung Nguyen. 2008. *Principles of Object-Oriented Programming*. Connexions (Rice University).
- Xiu, Liming. 2007. *VLSI circuit design methodology demystified: a conceptual taxonomy*. John Wiley & Sons.
- Yan Zhang, Laurence T. Yang, Jianhua Ma. 2008. *Unlicensed Mobile Access Technology: Protocols, Architectures, Security, Standards and Applications*. CRC Press.

- Yoo, Sungjoo, et Ahmed A Jerraya. 2003. « Introduction to hardware abstraction layers for SoC ». In *Embedded Software for SoC*. p. 179-186. Springer.
- Zhang, Gang, Aykut Dengi, Ronald A Rohrer, Rob A Rutenbar et L Richard Carley. 2004. « A synthesis flow toward fast parasitic closure for radio-frequency integrated circuits ». In *Proceedings of the 41st annual design automation conference*. p. 155-158. ACM.
- Zhiping, Yu, Robert W Dutton, Boris Troyanosky et Sato-Iwanaga Junko. 1999. « Large signal analysis of RF circuits in device simulation ». *IEICE transactions on electronics*, vol. 82, n° 6, p. 908-916.